

TOSHIBA

**64-Bit TX System RISC
TX49 Family
TMPR4927A**

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Preface

Thank you for new or continued patronage of TOSHIBA semiconductor products. This is the 2002 edition of the user's manual for the TMPR4927A 64-bit RISC microprocessor.

This databook is written so as to be accessible to engineers who may be designing a TOSHIBA microprocessor into their products for the first time. No prior knowledge of this device is assumed. What we offer here is basic information about the microprocessor, a discussion of the application fields in which the microprocessor is utilized, and an overview of design methods. On the other hand, the more experienced designer will find complete technical specifications for this product.

Toshiba continually updates its technical information. Your comments and suggestions concerning this and other Toshiba documents are sincerely appreciated and may be utilized in subsequent editions. For updating of the data in this manual, or for additional information about the product appearing in it, please contact your nearest Toshiba office or authorized Toshiba dealer.

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Handling Precautions

1. Using Toshiba Semiconductors Safely

TOSHIBA are continually working to improve the quality and the reliability of their products.

Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsibility of the buyer, when utilizing TOSHIBA products, to observe standards of safety, and to avoid situations in which a malfunction or failure of a TOSHIBA product could cause loss of human life, bodily injury or damage to property.

In developing your designs, please ensure that TOSHIBA products are used within specified operating ranges as set forth in the most recent products specifications. Also, please keep in mind the precautions and conditions set forth in the TOSHIBA Semiconductor Reliability Handbook.

2. Safety Precautions

This section lists important precautions which users of semiconductor devices (and anyone else) should observe in order to avoid injury and damage to property, and to ensure safe and correct use of devices.

Please be sure that you understand the meanings of the labels and the graphic symbol described below before you move on to the detailed descriptions of the precautions.

[Explanation of labels]



Indicates an imminently hazardous situation which will result in death or serious injury if you do not follow instructions.



Indicates a potentially hazardous situation which could result in death or serious injury if you do not follow instructions.



Indicates a potentially hazardous situation which if not avoided, may result in minor injury or moderate injury.

[Explanation of graphic symbol]

Graphic symbol	Meaning
	Indicates that caution is required (laser beam is dangerous to eyes).

2.1 General Precautions regarding Semiconductor Devices

⚠ CAUTION

Do not use devices under conditions exceeding their absolute maximum ratings (e.g. current, voltage, power dissipation or temperature).

This may cause the device to break down, degrade its performance, or cause it to catch fire or explode resulting in injury.

Do not insert devices in the wrong orientation.

Make sure that the positive and negative terminals of power supplies are connected correctly. Otherwise the rated maximum current or power dissipation may be exceeded and the device may break down or undergo performance degradation, causing it to catch fire or explode and resulting in injury.

When power to a device is on, do not touch the device's heat sink.

Heat sinks become hot, so you may burn your hand.

Do not touch the tips of device leads.

Because some types of device have leads with pointed tips, you may prick your finger.

When conducting any kind of evaluation, inspection or testing, be sure to connect the testing equipment's electrodes or probes to the pins of the device under test before powering it on.

Otherwise, you may receive an electric shock causing injury.

Before grounding an item of measuring equipment or a soldering iron, check that there is no electrical leakage from it.

Electrical leakage may cause the device which you are testing or soldering to break down, or could give you an electric shock.

Always wear protective glasses when cutting the leads of a device with clippers or a similar tool.

If you do not, small bits of metal flying off the cut ends may damage your eyes.

2.2 Precautions Specific to Each Product Group

2.2.1 Optical semiconductor devices

⚠ DANGER
<p>When a visible semiconductor laser is operating, do not look directly into the laser beam or look through the optical system. This is highly likely to impair vision, and in the worst case may cause blindness.</p> <p>If it is necessary to examine the laser apparatus, for example to inspect its optical characteristics, always wear the appropriate type of laser protective glasses as stipulated by IEC standard IEC825-1.</p>
⚠ WARNING
<p>Ensure that the current flowing in an LED device does not exceed the device's maximum rated current. This is particularly important for resin-packaged LED devices, as excessive current may cause the package resin to blow up, scattering resin fragments and causing injury.</p> <p>When testing the dielectric strength of a photocoupler, use testing equipment which can shut off the supply voltage to the photocoupler. If you detect a leakage current of more than 100 μA, use the testing equipment to shut off the photocoupler's supply voltage; otherwise a large short-circuit current will flow continuously, and the device may break down or burst into flames, resulting in fire or injury.</p> <p>When incorporating a visible semiconductor laser into a design, use the device's internal photodetector or a separate photodetector to stabilize the laser's radiant power so as to ensure that laser beams exceeding the laser's rated radiant power cannot be emitted.</p> <p>If this stabilizing mechanism does not work and the rated radiant power is exceeded, the device may break down or the excessively powerful laser beams may cause injury.</p>

2.2.2 Power devices

⚠ DANGER
<p>Never touch a power device while it is powered on. Also, after turning off a power device, do not touch it until it has thoroughly discharged all remaining electrical charge.</p> <p>Touching a power device while it is powered on or still charged could cause a severe electric shock, resulting in death or serious injury.</p> <p>When conducting any kind of evaluation, inspection or testing, be sure to connect the testing equipment's electrodes or probes to the device under test before powering it on.</p> <p>When you have finished, discharge any electrical charge remaining in the device.</p> <p>Connecting the electrodes or probes of testing equipment to a device while it is powered on may result in electric shock, causing injury.</p>

⚠ WARNING

Do not use devices under conditions which exceed their absolute maximum ratings (current, voltage, power dissipation, temperature etc.).

This may cause the device to break down, causing a large short-circuit current to flow, which may in turn cause it to catch fire or explode, resulting in fire or injury.

Use a unit which can detect short-circuit currents and which will shut off the power supply if a short-circuit occurs.

If the power supply is not shut off, a large short-circuit current will flow continuously, which may in turn cause the device to catch fire or explode, resulting in fire or injury.

When designing a case for enclosing your system, consider how best to protect the user from shrapnel in the event of the device catching fire or exploding.

Flying shrapnel can cause injury.

When conducting any kind of evaluation, inspection or testing, always use protective safety tools such as a cover for the device. Otherwise you may sustain injury caused by the device catching fire or exploding.

Make sure that all metal casings in your design are grounded to earth.

Even in modules where a device's electrodes and metal casing are insulated, capacitance in the module may cause the electrostatic potential in the casing to rise.

Dielectric breakdown may cause a high voltage to be applied to the casing, causing electric shock and injury to anyone touching it.

When designing the heat radiation and safety features of a system incorporating high-speed rectifiers, remember to take the device's forward and reverse losses into account.

The leakage current in these devices is greater than that in ordinary rectifiers; as a result, if a high-speed rectifier is used in an extreme environment (e.g. at high temperature or high voltage), its reverse loss may increase, causing thermal runaway to occur. This may in turn cause the device to explode and scatter shrapnel, resulting in injury to the user.

A design should ensure that, except when the main circuit of the device is active, reverse bias is applied to the device gate while electricity is conducted to control circuits, so that the main circuit will become inactive.

Malfunction of the device may cause serious accidents or injuries.

⚠ CAUTION

When conducting any kind of evaluation, inspection or testing, either wear protective gloves or wait until the device has cooled properly before handling it.

Devices become hot when they are operated. Even after the power has been turned off, the device will retain residual heat which may cause a burn to anyone touching it.

2.2.3 Bipolar ICs (for use in automobiles)**⚠ CAUTION**

If your design includes an inductive load such as a motor coil, incorporate diodes or similar devices into the design to prevent negative current from flowing in.

The load current generated by powering the device on and off may cause it to function erratically or to break down, which could in turn cause injury.

Ensure that the power supply to any device which incorporates protective functions is stable.

If the power supply is unstable, the device may operate erratically, preventing the protective functions from working correctly. If protective functions fail, the device may break down causing injury to the user.

3. General Safety Precautions and Usage Considerations

This section is designed to help you gain a better understanding of semiconductor devices, so as to ensure the safety, quality and reliability of the devices which you incorporate into your designs.

3.1 From Incoming to Shipping

3.1.1 Electrostatic discharge (ESD)

When handling individual devices (which are not yet mounted on a printed circuit board), be sure that the environment is protected against electrostatic electricity. Operators should wear anti-static clothing, and containers and other objects which come into direct contact with devices should be made of anti-static materials and should be grounded to earth via an 0.5- to 1.0-M Ω protective resistor.



Please follow the precautions described below; this is particularly important for devices which are marked "Be careful of static."

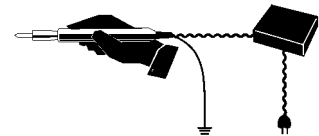
(1) Work environment

- When humidity in the working environment decreases, the human body and other insulators can easily become charged with static electricity due to friction. Maintain the recommended humidity of 40% to 60% in the work environment, while also taking into account the fact that moisture-proof-packed products may absorb moisture after unpacking.
- Be sure that all equipment, jigs and tools in the working area are grounded to earth.
- Place a conductive mat over the floor of the work area, or take other appropriate measures, so that the floor surface is protected against static electricity and is grounded to earth. The surface resistivity should be 10^4 to $10^8 \Omega/\text{sq}$ and the resistance between surface and ground, 7.5×10^5 to $10^8 \Omega$.
- Cover the workbench surface also with a conductive mat (with a surface resistivity of 10^4 to $10^8 \Omega/\text{sq}$, for a resistance between surface and ground of 7.5×10^5 to $10^8 \Omega$). The purpose of this is to disperse static electricity on the surface (through resistive components) and ground it to earth. Workbench surfaces must not be constructed of low-resistance metallic materials that allow rapid static discharge when a charged device touches them directly.
- Pay attention to the following points when using automatic equipment in your workplace:
 - (a) When picking up ICs with a vacuum unit, use a conductive rubber fitting on the end of the pick-up wand to protect against electrostatic charge.
 - (b) Minimize friction on IC package surfaces. If some rubbing is unavoidable due to the device's mechanical structure, minimize the friction plane or use material with a small friction coefficient and low electrical resistance. Also, consider the use of an ionizer.
 - (c) In sections which come into contact with device lead terminals, use a material which dissipates static electricity.
 - (d) Ensure that no statically charged bodies (such as work clothes or the human body) touch the devices.

- (e) Make sure that sections of the tape carrier which come into contact with installation devices or other electrical machinery are made of a low-resistance material.
 - (f) Make sure that jigs and tools used in the assembly process do not touch devices.
 - (g) In processes in which packages may retain an electrostatic charge, use an ionizer to neutralize the ions.
- Make sure that CRT displays in the working area are protected against static charge, for example by a VDT filter. As much as possible, avoid turning displays on and off. Doing so can cause electrostatic induction in devices.
 - Keep track of charged potential in the working area by taking periodic measurements.
 - Ensure that work chairs are protected by an anti-static textile cover and are grounded to the floor surface by a grounding chain. (Suggested resistance between the seat surface and grounding chain is 7.5×10^5 to $10^{12} \Omega$.)
 - Install anti-static mats on storage shelf surfaces. (Suggested surface resistivity is 10^4 to $10^8 \Omega/\text{sq}$; suggested resistance between surface and ground is 7.5×10^5 to $10^8 \Omega$.)
 - For transport and temporary storage of devices, use containers (boxes, jigs or bags) that are made of anti-static materials or materials which dissipate electrostatic charge.
 - Make sure that cart surfaces which come into contact with device packaging are made of materials which will conduct static electricity, and verify that they are grounded to the floor surface via a grounding chain.
 - In any location where the level of static electricity is to be closely controlled, the ground resistance level should be Class 3 or above. Use different ground wires for all items of equipment which may come into physical contact with devices.

(2) Operating environment

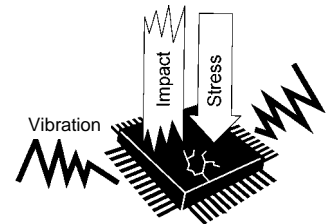
- Operators must wear anti-static clothing and conductive shoes (or a leg or heel strap).
- Operators must wear a wrist strap grounded to earth via a resistor of about $1 \text{ M}\Omega$.
- Soldering irons must be grounded from iron tip to earth, and must be used only at low voltages (6 V to 24 V).
- If the tweezers you use are likely to touch the device terminals, use anti-static tweezers and in particular avoid metallic tweezers. If a charged device touches a low-resistance tool, rapid discharge can occur. When using vacuum tweezers, attach a conductive chucking pat to the tip, and connect it to a dedicated ground used especially for anti-static purposes (suggested resistance value: 10^4 to $10^8 \Omega$).
- Do not place devices or their containers near sources of strong electrical fields (such as above a CRT).



- When storing printed circuit boards which have devices mounted on them, use a board container or bag that is protected against static charge. To avoid the occurrence of static charge or discharge due to friction, keep the boards separate from one other and do not stack them directly on top of one another.
- Ensure, if possible, that any articles (such as clipboards) which are brought to any location where the level of static electricity must be closely controlled are constructed of anti-static materials.
- In cases where the human body comes into direct contact with a device, be sure to wear anti-static finger covers or gloves (suggested resistance value: $10^8 \Omega$ or less).
- Equipment safety covers installed near devices should have resistance ratings of $10^9 \Omega$ or less.
- If a wrist strap cannot be used for some reason, and there is a possibility of imparting friction to devices, use an ionizer.
- The transport film used in TCP products is manufactured from materials in which static charges tend to build up. When using these products, install an ionizer to prevent the film from being charged with static electricity. Also, ensure that no static electricity will be applied to the product's copper foils by taking measures to prevent static occurring in the peripheral equipment.

3.1.2 Vibration, impact and stress

Handle devices and packaging materials with care. To avoid damage to devices, do not toss or drop packages. Ensure that devices are not subjected to mechanical vibration or shock during transportation. Ceramic package devices and devices in canister-type packages which have empty space inside them are subject to damage from vibration and shock because the bonding wires are secured only at their ends.



Plastic molded devices, on the other hand, have a relatively high level of resistance to vibration and mechanical shock because their bonding wires are enveloped and fixed in resin. However, when any device or package type is installed in target equipment, it is to some extent susceptible to wiring disconnections and other damage from vibration, shock and stressed solder junctions. Therefore when devices are incorporated into the design of equipment which will be subject to vibration, the structural design of the equipment must be thought out carefully.

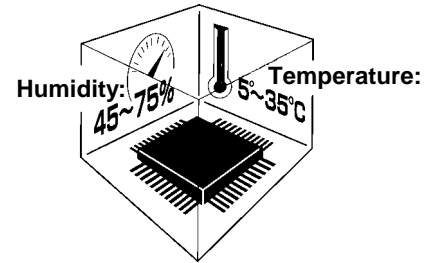
If a device is subjected to especially strong vibration, mechanical shock or stress, the package or the chip itself may crack. In products such as CCDs which incorporate window glass, this could cause surface flaws in the glass or cause the connection between the glass and the ceramic to separate.

Furthermore, it is known that stress applied to a semiconductor device through the package changes the resistance characteristics of the chip because of piezoelectric effects. In analog circuit design attention must be paid to the problem of package stress as well as to the dangers of vibration and shock as described above.

3.2 Storage

3.2.1 General storage

- Avoid storage locations where devices will be exposed to moisture or direct sunlight.
- Follow the instructions printed on the device cartons regarding transportation and storage.
- The storage area temperature should be kept within a temperature range of 5°C to 35°C, and relative humidity should be maintained at between 45% and 75%.
- Do not store devices in the presence of harmful (especially corrosive) gases, or in dusty conditions.
- Use storage areas where there is minimal temperature fluctuation. Rapid temperature changes can cause moisture to form on stored devices, resulting in lead oxidation or corrosion. As a result, the solderability of the leads will be degraded.
- When repacking devices, use anti-static containers.
- Do not allow external forces or loads to be applied to devices while they are in storage.
- If devices have been stored for more than two years, their electrical characteristics should be tested and their leads should be tested for ease of soldering before they are used.



3.2.2 Moisture-proof packing

Moisture-proof packing should be handled with care. The handling procedure specified for each packing type should be followed scrupulously. If the proper procedures are not followed, the quality and reliability of devices may be degraded. This section describes general precautions for handling moisture-proof packing. Since the details may differ from device to device, refer also to the relevant individual datasheets or databook.



(1) General precautions

Follow the instructions printed on the device cartons regarding transportation and storage.

- Do not drop or toss device packing. The laminated aluminum material in it can be rendered ineffective by rough handling.
- The storage area temperature should be kept within a temperature range of 5°C to 30°C, and relative humidity should be maintained at 90% (max). Use devices within 12 months of the date marked on the package seal.

- If the 12-month storage period has expired, or if the 30% humidity indicator shown in Figure 1 is pink when the packing is opened, it may be advisable, depending on the device and packing type, to bake the devices at high temperature to remove any moisture. Please refer to the table below. After the pack has been opened, use the devices in a 5°C to 30°C, 60% RH environment and within the effective usage period listed on the moisture-proof package. If the effective usage period has expired, or if the packing has been stored in a high-humidity environment, bake the devices at high temperature.

Packing	Moisture removal
Tray	If the packing bears the "Heatproof" marking or indicates the maximum temperature which it can withstand, bake at 125°C for 20 hours. (Some devices require a different procedure.)
Tube	Transfer devices to trays bearing the "Heatproof" marking or indicating the temperature which they can withstand, or to aluminum tubes before baking at 125°C for 20 hours.
Tape	Devices packed on tape cannot be baked and must be used within the effective usage period after unpacking, as specified on the packing.

- When baking devices, protect the devices from static electricity.
- Moisture indicators can detect the approximate humidity level at a standard temperature of 25°C. 6-point indicators and 3-point indicators are currently in use, but eventually all indicators will be 3-point indicators.

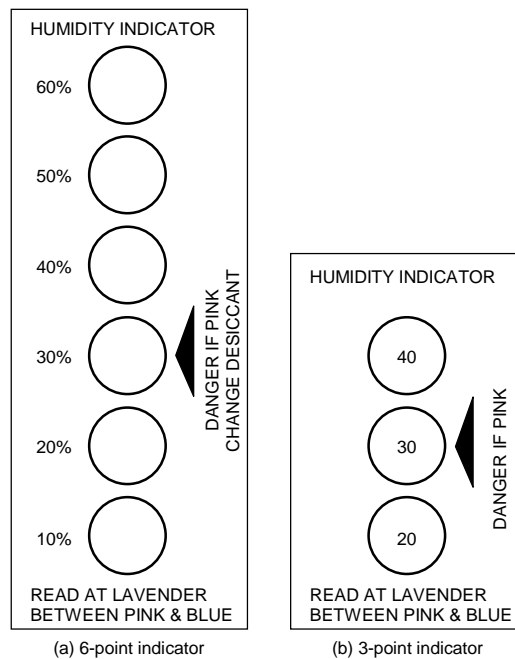


Figure 1 Humidity indicator

3.3 Design

Care must be exercised in the design of electronic equipment to achieve the desired reliability. It is important not only to adhere to specifications concerning absolute maximum ratings and recommended operating conditions, it is also important to consider the overall environment in which equipment will be used, including factors such as the ambient temperature, transient noise and voltage and current surges, as well as mounting conditions which affect device reliability. This section describes some general precautions which you should observe when designing circuits and when mounting devices on printed circuit boards.

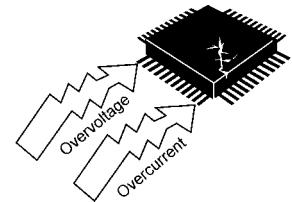
For more detailed information about each product family, refer to the relevant individual technical datasheets available from Toshiba.

3.3.1 Absolute maximum ratings

⚠ CAUTION

Do not use devices under conditions in which their absolute maximum ratings (e.g. current, voltage, power dissipation or temperature) will be exceeded. A device may break down or its performance may be degraded, causing it to catch fire or explode resulting in injury to the user.

The absolute maximum ratings are rated values which must not be exceeded during operation, even for an instant. Although absolute maximum ratings differ from product to product, they essentially concern the voltage and current at each pin, the allowable power dissipation, and the junction and storage temperatures.



If the voltage or current on any pin exceeds the absolute maximum rating, the device's internal circuitry can become degraded. In the worst case, heat generated in internal circuitry can fuse wiring or cause the semiconductor chip to break down.

If storage or operating temperatures exceed rated values, the package seal can deteriorate or the wires can become disconnected due to the differences between the thermal expansion coefficients of the materials from which the device is constructed.

3.3.2 Recommended operating conditions

The recommended operating conditions for each device are those necessary to guarantee that the device will operate as specified in the datasheet.

If greater reliability is required, derate the device's absolute maximum ratings for voltage, current, power and temperature before using it.

3.3.3 Derating

When incorporating a device into your design, reduce its rated absolute maximum voltage, current, power dissipation and operating temperature in order to ensure high reliability.

Since derating differs from application to application, refer to the technical datasheets available for the various devices used in your design.

3.3.4 Unused pins

If unused pins are left open, some devices can exhibit input instability problems, resulting in malfunctions such as abrupt increase in current flow. Similarly, if the unused output pins on a device are connected to the power supply pin, the ground pin or to other output pins, the IC may malfunction or break down.

Since the details regarding the handling of unused pins differ from device to device and from pin to pin, please follow the instructions given in the relevant individual datasheets or databook.

CMOS logic IC inputs, for example, have extremely high impedance. If an input pin is left open, it can easily pick up extraneous noise and become unstable. In this case, if the input voltage level reaches an intermediate level, it is possible that both the P-channel and N-channel transistors will be turned on, allowing unwanted supply current to flow. Therefore, ensure that the unused input pins of a device are connected to the power supply (Vcc) pin or ground (GND) pin of the same device. For details of what to do with the pins of heat sinks, refer to the relevant technical datasheet and databook.

3.3.5 Latch-up

Latch-up is an abnormal condition inherent in CMOS devices, in which Vcc gets shorted to ground. This happens when a parasitic PN-PN junction (thyristor structure) internal to the CMOS chip is turned on, causing a large current of the order of several hundred mA or more to flow between Vcc and GND, eventually causing the device to break down.

Latch-up occurs when the input or output voltage exceeds the rated value, causing a large current to flow in the internal chip, or when the voltage on the Vcc (Vdd) pin exceeds its rated value, forcing the internal chip into a breakdown condition. Once the chip falls into the latch-up state, even though the excess voltage may have been applied only for an instant, the large current continues to flow between Vcc (Vdd) and GND (Vss). This causes the device to heat up and, in extreme cases, to emit gas fumes as well. To avoid this problem, observe the following precautions:

- (1) Do not allow voltage levels on the input and output pins either to rise above Vcc (Vdd) or to fall below GND (Vss). Also, follow any prescribed power-on sequence, so that power is applied gradually or in steps rather than abruptly.
- (2) Do not allow any abnormal noise signals to be applied to the device.
- (3) Set the voltage levels of unused input pins to Vcc (Vdd) or GND (Vss).
- (4) Do not connect output pins to one another.

3.3.6 Input/Output protection

Wired-AND configurations, in which outputs are connected together, cannot be used, since this short-circuits the outputs. Outputs should, of course, never be connected to Vcc (Vdd) or GND (Vss).

Furthermore, ICs with tri-state outputs can undergo performance degradation if a shorted output current is allowed to flow for an extended period of time. Therefore, when designing circuits, make sure that tri-state outputs will not be enabled simultaneously.

3.3.7 Load capacitance

Some devices display increased delay times if the load capacitance is large. Also, large charging and discharging currents will flow in the device, causing noise. Furthermore, since outputs are shorted for a relatively long time, wiring can become fused.

Consult the technical information for the device being used to determine the recommended load capacitance.

3.3.8 Thermal design

The failure rate of semiconductor devices is greatly increased as operating temperatures increase. As shown in Figure 2, the internal thermal stress on a device is the sum of the ambient temperature and the temperature rise due to power dissipation in the device. Therefore, to achieve optimum reliability, observe the following precautions concerning thermal design:

- (1) Keep the ambient temperature (T_a) as low as possible.
- (2) If the device's dynamic power dissipation is relatively large, select the most appropriate circuit board material, and consider the use of heat sinks or of forced air cooling. Such measures will help lower the thermal resistance of the package.

- (3) Derate the device's absolute maximum ratings to minimize thermal stress from power dissipation.

$$\theta_{ja} = \theta_{jc} + \theta_{ca}$$

$$\theta_{ja} = (T_j - T_a) / P$$

$$\theta_{jc} = (T_j - T_c) / P$$

$$\theta_{ca} = (T_c - T_a) / P$$

in which θ_{ja} = thermal resistance between junction and surrounding air ($^{\circ}\text{C}/\text{W}$)

θ_{jc} = thermal resistance between junction and package surface, or internal thermal resistance ($^{\circ}\text{C}/\text{W}$)

θ_{ca} = thermal resistance between package surface and surrounding air, or external thermal resistance ($^{\circ}\text{C}/\text{W}$)

T_j = junction temperature or chip temperature ($^{\circ}\text{C}$)

T_c = package surface temperature or case temperature ($^{\circ}\text{C}$)

T_a = ambient temperature ($^{\circ}\text{C}$)

P = power dissipation (W)

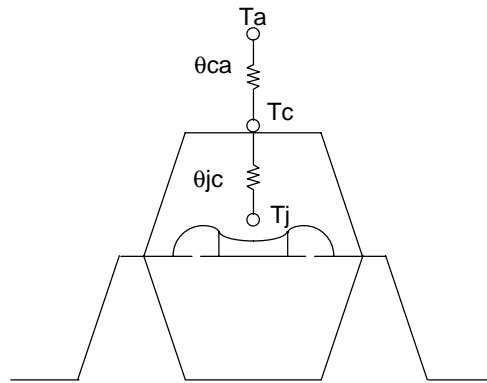


Figure 2 Thermal resistance of package

3.3.9 Interfacing

When connecting inputs and outputs between devices, make sure input voltage (V_{IL}/V_{IH}) and output voltage (V_{OL}/V_{OH}) levels are matched. Otherwise, the devices may malfunction. When connecting devices operating at different supply voltages, such as in a dual-power-supply system, be aware that erroneous power-on and power-off sequences can result in device breakdown. For details of how to interface particular devices, consult the relevant technical datasheets and databooks. If you have any questions or doubts about interfacing, contact your nearest Toshiba office or distributor.

3.3.10 Decoupling

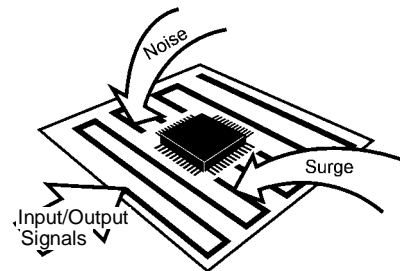
Spike currents generated during switching can cause Vcc (Vdd) and GND (Vss) voltage levels to fluctuate, causing ringing in the output waveform or a delay in response speed. (The power supply and GND wiring impedance is normally 50 Ω to 100 Ω .) For this reason, the impedance of power supply lines with respect to high frequencies must be kept low. This can be accomplished by using thick and short wiring for the Vcc (Vdd) and GND (Vss) lines and by installing decoupling capacitors (of approximately 0.01 μF to 1 μF capacitance) as high-frequency filters between Vcc (Vdd) and GND (Vss) at strategic locations on the printed circuit board.

For low-frequency filtering, it is a good idea to install a 10- to 100- μF capacitor on the printed circuit board (one capacitor will suffice). If the capacitance is excessively large, however, (e.g. several thousand μF) latch-up can be a problem. Be sure to choose an appropriate capacitance value.

An important point about wiring is that, in the case of high-speed logic ICs, noise is caused mainly by reflection and crosstalk, or by the power supply impedance. Reflections cause increased signal delay, ringing, overshoot and undershoot, thereby reducing the device's safety margins with respect to noise. To prevent reflections, reduce the wiring length by increasing the device mounting density so as to lower the inductance (L) and capacitance (C) in the wiring. Extreme care must be taken, however, when taking this corrective measure, since it tends to cause crosstalk between the wires. In practice, there must be a trade-off between these two factors.

3.3.11 External noise

Printed circuit boards with long I/O or signal pattern lines are vulnerable to induced noise or surges from outside sources. Consequently, malfunctions or breakdowns can result from overcurrent or overvoltage, depending on the types of device used. To protect against noise, lower the impedance of the pattern line or insert a noise-canceling circuit. Protective measures must also be taken against surges.



For details of the appropriate protective measures for a particular device, consult the relevant databook.

3.3.12 Electromagnetic interference

Widespread use of electrical and electronic equipment in recent years has brought with it radio and TV reception problems due to electromagnetic interference. To use the radio spectrum effectively and to maintain radio communications quality, each country has formulated regulations limiting the amount of electromagnetic interference which can be generated by individual products.

Electromagnetic interference includes conduction noise propagated through power supply and telephone lines, and noise from direct electromagnetic waves radiated by equipment. Different measurement methods and corrective measures are used to assess and counteract each specific type of noise.

Difficulties in controlling electromagnetic interference derive from the fact that there is no method available which allows designers to calculate, at the design stage, the strength of the electromagnetic waves which will emanate from each component in a piece of equipment. For this reason, it is only after the prototype equipment has been completed that the designer can take measurements using a dedicated instrument to determine the strength of electromagnetic interference waves. Yet it is possible during system design to incorporate some measures for the prevention of electromagnetic interference, which can facilitate taking corrective measures once the design has been completed. These include installing shields and noise filters, and increasing

the thickness of the power supply wiring patterns on the printed circuit board. One effective method, for example, is to devise several shielding options during design, and then select the most suitable shielding method based on the results of measurements taken after the prototype has been completed.

3.3.13 Peripheral circuits

In most cases semiconductor devices are used with peripheral circuits and components. The input and output signal voltages and currents in these circuits must be chosen to match the semiconductor device's specifications. The following factors must be taken into account.

- (1) Inappropriate voltages or currents applied to a device's input pins may cause it to operate erratically. Some devices contain pull-up or pull-down resistors. When designing your system, remember to take the effect of this on the voltage and current levels into account.
- (2) The output pins on a device have a predetermined external circuit drive capability. If this drive capability is greater than that required, either incorporate a compensating circuit into your design or carefully select suitable components for use in external circuits.

3.3.14 Safety standards

Each country has safety standards which must be observed. These safety standards include requirements for quality assurance systems and design of device insulation. Such requirements must be fully taken into account to ensure that your design conforms to the applicable safety standards.

3.3.15 Other precautions

- (1) When designing a system, be sure to incorporate fail-safe and other appropriate measures according to the intended purpose of your system. Also, be sure to debug your system under actual board-mounted conditions.
- (2) If a plastic-package device is placed in a strong electric field, surface leakage may occur due to the charge-up phenomenon, resulting in device malfunction. In such cases take appropriate measures to prevent this problem, for example by protecting the package surface with a conductive shield.
- (3) With some microcomputers and MOS memory devices, caution is required when powering on or resetting the device. To ensure that your design does not violate device specifications, consult the relevant databook for each constituent device.
- (4) Ensure that no conductive material or object (such as a metal pin) can drop onto and short the leads of a device mounted on a printed circuit board.

3.4 Inspection, Testing and Evaluation

3.4.1 Grounding



Ground all measuring instruments, jigs, tools and soldering irons to earth.
Electrical leakage may cause a device to break down or may result in electric shock.

3.4.2 Inspection Sequence

CAUTION

- ① Do not insert devices in the wrong orientation. Make sure that the positive and negative electrodes of the power supply are correctly connected. Otherwise, the rated maximum current or maximum power dissipation may be exceeded and the device may break down or undergo performance degradation, causing it to catch fire or explode, resulting in injury to the user.
 - ② When conducting any kind of evaluation, inspection or testing using AC power with a peak voltage of 42.4 V or DC power exceeding 60 V, be sure to connect the electrodes or probes of the testing equipment to the device under test before powering it on. Connecting the electrodes or probes of testing equipment to a device while it is powered on may result in electric shock, causing injury.
- (1) Apply voltage to the test jig only after inserting the device securely into it. When applying or removing power, observe the relevant precautions, if any.
 - (2) Make sure that the voltage applied to the device is off before removing the device from the test jig. Otherwise, the device may undergo performance degradation or be destroyed.
 - (3) Make sure that no surge voltages from the measuring equipment are applied to the device.
 - (4) The chips housed in tape carrier packages (TCPs) are bare chips and are therefore exposed. During inspection take care not to crack the chip or cause any flaws in it. Electrical contact may also cause a chip to become faulty. Therefore make sure that nothing comes into electrical contact with the chip.

3.5 Mounting

There are essentially two main types of semiconductor device package: lead insertion and surface mount. During mounting on printed circuit boards, devices can become contaminated by flux or damaged by thermal stress from the soldering process. With surface-mount devices in particular, the most significant problem is thermal stress from solder reflow, when the entire package is subjected to heat. This section describes a recommended temperature profile for each mounting method, as well as general precautions which you should take when mounting devices on printed circuit boards. Note, however, that even for devices with the same package type, the appropriate mounting method varies according to the size of the chip and the size and shape of the lead frame. Therefore, please consult the relevant technical datasheet and databook.

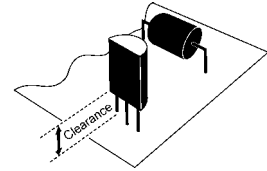
3.5.1 Lead forming

CAUTION

- ① Always wear protective glasses when cutting the leads of a device with clippers or a similar tool. If you do not, small bits of metal flying off the cut ends may damage your eyes.
- ② Do not touch the tips of device leads. Because some types of device have leads with pointed tips, you may prick your finger.

Semiconductor devices must undergo a process in which the leads are cut and formed before the devices can be mounted on a printed circuit board. If undue stress is applied to the interior of a device during this process, mechanical breakdown or performance degradation can result. This is attributable primarily to differences between the stress on the device's external leads and the stress on the internal leads. If the relative difference is great enough, the device's internal leads, adhesive properties or sealant can be damaged. Observe these precautions during the lead-forming process (this does not apply to surface-mount devices):

- (1) Lead insertion hole intervals on the printed circuit board should match the lead pitch of the device precisely.
- (2) If lead insertion hole intervals on the printed circuit board do not precisely match the lead pitch of the device, do not attempt to forcibly insert devices by pressing on them or by pulling on their leads.
- (3) For the minimum clearance specification between a device and a printed circuit board, refer to the relevant device's datasheet and databook. If necessary, achieve the required clearance by forming the device's leads appropriately. Do not use the spacers which are used to raise devices above the surface of the printed circuit board during soldering to achieve clearance. These spacers normally continue to expand due to heat, even after the solder has begun to solidify; this applies severe stress to the device.
- (4) Observe the following precautions when forming the leads of a device prior to mounting.
 - Use a tool or jig to secure the lead at its base (where the lead meets the device package) while bending so as to avoid mechanical stress to the device. Also avoid bending or stretching device leads repeatedly.
 - Be careful not to damage the lead during lead forming.
 - Follow any other precautions described in the individual datasheets and databooks for each device and package type.



3.5.2 Socket mounting

- (1) When socket mounting devices on a printed circuit board, use sockets which match the inserted device's package.
- (2) Use sockets whose contacts have the appropriate contact pressure. If the contact pressure is insufficient, the socket may not make a perfect contact when the device is repeatedly inserted and removed; if the pressure is excessively high, the device leads may be bent or damaged when they are inserted into or removed from the socket.
- (3) When soldering sockets to the printed circuit board, use sockets whose construction prevents flux from penetrating into the contacts or which allows flux to be completely cleaned off.
- (4) Make sure the coating agent applied to the printed circuit board for moisture-proofing purposes does not stick to the socket contacts.
- (5) If the device leads are severely bent by a socket as it is inserted or removed and you wish to repair the leads so as to continue using the device, make sure that this lead correction is only performed once. Do not use devices whose leads have been corrected more than once.
- (6) If the printed circuit board with the devices mounted on it will be subjected to vibration from external sources, use sockets which have a strong contact pressure so as to prevent the sockets and devices from vibrating relative to one another.

3.5.3 Soldering temperature profile

The soldering temperature and heating time vary from device to device. Therefore, when specifying the mounting conditions, refer to the individual datasheets and databooks for the devices used.

(1) Using a soldering iron

Complete soldering within ten seconds for lead temperatures of up to 260°C, or within three seconds for lead temperatures of up to 350°C.

(2) Using medium infrared ray reflow

- Heating top and bottom with long or medium infrared rays is recommended (see Figure 3).

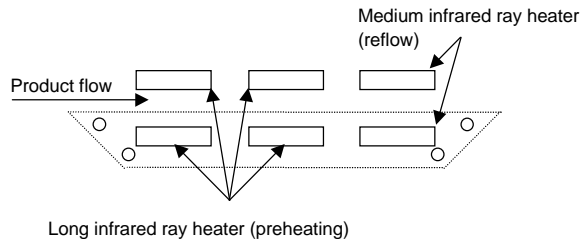


Figure 3 Heating top and bottom with long or medium infrared rays

- Complete the infrared ray reflow process within 30 seconds at a package surface temperature of between 210°C and 240°C.
- Refer to Figure 4 for an example of a good temperature profile for infrared or hot air reflow.

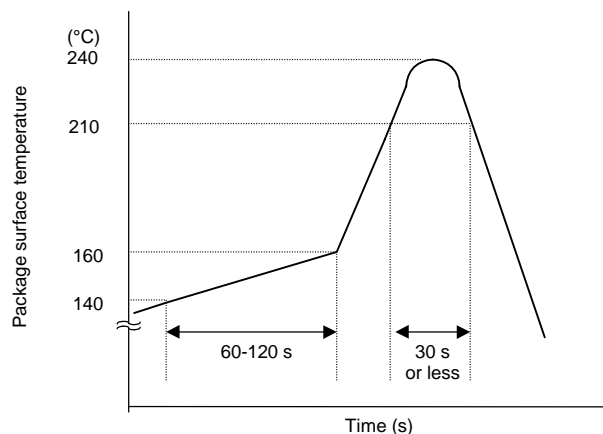


Figure 4 Sample temperature profile for infrared or hot air reflow

(3) Using hot air reflow

- Complete hot air reflow within 30 seconds at a package surface temperature of between 210°C and 240°C.
- For an example of a recommended temperature profile, refer to Figure 4 above.

(4) Using solder flow

- Apply preheating for 60 to 120 seconds at a temperature of 150°C.
- For lead insertion-type packages, complete solder flow within 10 seconds with the temperature at the stopper (or, if there is no stopper, at a location more than 1.5 mm from the body) which does not exceed 260°C.

- For surface-mount packages, complete soldering within 5 seconds at a temperature of 250°C or less in order to prevent thermal stress in the device.
- Figure 5 shows an example of a recommended temperature profile for surface-mount packages using solder flow.

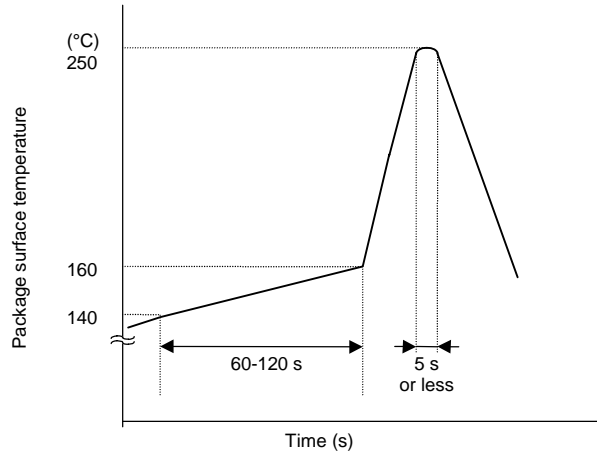


Figure 5 Sample temperature profile for solder flow

3.5.4 Flux cleaning and ultrasonic cleaning

- (1) When cleaning circuit boards to remove flux, make sure that no residual reactive ions such as Na or Cl remain. Note that organic solvents react with water to generate hydrogen chloride and other corrosive gases which can degrade device performance.
- (2) Washing devices with water will not cause any problems. However, make sure that no reactive ions such as sodium and chlorine are left as a residue. Also, be sure to dry devices sufficiently after washing.
- (3) Do not rub device markings with a brush or with your hand during cleaning or while the devices are still wet from the cleaning agent. Doing so can rub off the markings.
- (4) The dip cleaning, shower cleaning and steam cleaning processes all involve the chemical action of a solvent. Use only recommended solvents for these cleaning methods. When immersing devices in a solvent or steam bath, make sure that the temperature of the liquid is 50°C or below, and that the circuit board is removed from the bath within one minute.
- (5) Ultrasonic cleaning should not be used with hermetically-sealed ceramic packages such as a leadless chip carrier (LCC), pin grid array (PGA) or charge-coupled device (CCD), because the bonding wires can become disconnected due to resonance during the cleaning process. Even if a device package allows ultrasonic cleaning, limit the duration of ultrasonic cleaning to as short a time as possible, since long hours of ultrasonic cleaning degrade the adhesion between the mold resin and the frame material. The following ultrasonic cleaning conditions are recommended:

Frequency: 27 kHz ~ 29 kHz

Ultrasonic output power: 300 W or less (0.25 W/cm² or less)

Cleaning time: 30 seconds or less

Suspend the circuit board in the solvent bath during ultrasonic cleaning in such a way that the ultrasonic vibrator does not come into direct contact with the circuit board or the device.

3.5.5 No cleaning

If analog devices or high-speed devices are used without being cleaned, flux residues may cause minute amounts of leakage between pins. Similarly, dew condensation, which occurs in environments containing residual chlorine when power to the device is on, may cause between-lead leakage or migration. Therefore, Toshiba recommends that these devices be cleaned. However, if the flux used contains only a small amount of halogen (0.05W% or less), the devices may be used without cleaning without any problems.

3.5.6 Mounting tape carrier packages (TCPs)

- (1) When tape carrier packages (TCPs) are mounted, measures must be taken to prevent electrostatic breakdown of the devices.
- (2) If devices are being picked up from tape, or outer lead bonding (OLB) mounting is being carried out, consult the manufacturer of the insertion machine which is being used, in order to establish the optimum mounting conditions in advance and to avoid any possible hazards.
- (3) The base film, which is made of polyimide, is hard and thin. Be careful not to cut or scratch your hands or any objects while handling the tape.
- (4) When punching tape, try not to scatter broken pieces of tape too much.
- (5) Treat the extra film, reels and spacers left after punching as industrial waste, taking care not to destroy or pollute the environment.
- (6) Chips housed in tape carrier packages (TCPs) are bare chips and therefore have their reverse side exposed. To ensure that the chip will not be cracked during mounting, ensure that no mechanical shock is applied to the reverse side of the chip. Electrical contact may also cause a chip to fail. Therefore, when mounting devices, make sure that nothing comes into electrical contact with the reverse side of the chip.
If your design requires connecting the reverse side of the chip to the circuit board, please consult Toshiba or a Toshiba distributor beforehand.

3.5.7 Mounting chips

Devices delivered in chip form tend to degrade or break under external forces much more easily than plastic-packaged devices. Therefore, caution is required when handling this type of device.

- (1) Mount devices in a properly prepared environment so that chip surfaces will not be exposed to polluted ambient air or other polluted substances.
- (2) When handling chips, be careful not to expose them to static electricity.
In particular, measures must be taken to prevent static damage during the mounting of chips. With this in mind, Toshiba recommend mounting all peripheral parts first and then mounting chips last (after all other components have been mounted).
- (3) Make sure that PCBs (or any other kind of circuit board) on which chips are being mounted do not have any chemical residues on them (such as the chemicals which were used for etching the PCBs).
- (4) When mounting chips on a board, use the method of assembly that is most suitable for maintaining the appropriate electrical, thermal and mechanical properties of the semiconductor devices used.

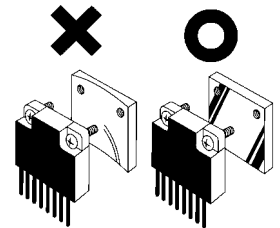
* For details of devices in chip form, refer to the relevant device's individual datasheets.

3.5.8 Circuit board coating

When devices are to be used in equipment requiring a high degree of reliability or in extreme environments (where moisture, corrosive gas or dust is present), circuit boards may be coated for protection. However, before doing so, you must carefully consider the possible stress and contamination effects that may result and then choose the coating resin which results in the minimum level of stress to the device.

3.5.9 Heat sinks

- (1) When attaching a heat sink to a device, be careful not to apply excessive force to the device in the process.
- (2) When attaching a device to a heat sink by fixing it at two or more locations, evenly tighten all the screws in stages (i.e. do not fully tighten one screw while the rest are still only loosely tightened). Finally, fully tighten all the screws up to the specified torque.
- (3) Drill holes for screws in the heat sink exactly as specified. Smooth the surface by removing burrs and protrusions or indentations which might interfere with the installation of any part of the device.
- (4) A coating of silicone compound can be applied between the heat sink and the device to improve heat conductivity. Be sure to apply the coating thinly and evenly; do not use too much. Also, be sure to use a non-volatile compound, as volatile compounds can crack after a time, causing the heat radiation properties of the heat sink to deteriorate.
- (5) If the device is housed in a plastic package, use caution when selecting the type of silicone compound to be applied between the heat sink and the device. With some types, the base oil separates and penetrates the plastic package, significantly reducing the useful life of the device.
Two recommended silicone compounds in which base oil separation is not a problem are YG6260 from Toshiba Silicone.
- (6) Heat-sink-equipped devices can become very hot during operation. Do not touch them, or you may sustain a burn.



3.5.10 Tightening torque

- (1) Make sure the screws are tightened with fastening torques not exceeding the torque values stipulated in individual datasheets and databooks for the devices used.
- (2) Do not allow a power screwdriver (electrical or air-driven) to touch devices.

3.5.11 Repeated device mounting and usage

Do not remount or re-use devices which fall into the categories listed below; these devices may cause significant problems relating to performance and reliability.

- (1) Devices which have been removed from the board after soldering
- (2) Devices which have been inserted in the wrong orientation or which have had reverse current applied
- (3) Devices which have undergone lead forming more than once

3.6 Protecting Devices in the Field

3.6.1 Temperature

Semiconductor devices are generally more sensitive to temperature than are other electronic components. The various electrical characteristics of a semiconductor device are dependent on the ambient temperature at which the device is used. It is therefore necessary to understand the temperature characteristics of a device and to incorporate device derating into circuit design. Note also that if a device is used above its maximum temperature rating, device deterioration is more rapid and it will reach the end of its usable life sooner than expected.

3.6.2 Humidity

Resin-molded devices are sometimes improperly sealed. When these devices are used for an extended period of time in a high-humidity environment, moisture can penetrate into the device and cause chip degradation or malfunction. Furthermore, when devices are mounted on a regular printed circuit board, the impedance between wiring components can decrease under high-humidity conditions. In systems which require a high signal-source impedance, circuit board leakage or leakage between device lead pins can cause malfunctions. The application of a moisture-proof treatment to the device surface should be considered in this case. On the other hand, operation under low-humidity conditions can damage a device due to the occurrence of electrostatic discharge. Unless damp-proofing measures have been specifically taken, use devices only in environments with appropriate ambient moisture levels (i.e. within a relative humidity range of 40% to 60%).

3.6.3 Corrosive gases

Corrosive gases can cause chemical reactions in devices, degrading device characteristics. For example, sulphur-bearing corrosive gases emanating from rubber placed near a device (accompanied by condensation under high-humidity conditions) can corrode a device's leads. The resulting chemical reaction between leads forms foreign particles which can cause electrical leakage.

3.6.4 Radioactive and cosmic rays

Most industrial and consumer semiconductor devices are not designed with protection against radioactive and cosmic rays. Devices used in aerospace equipment or in radioactive environments must therefore be shielded.

3.6.5 Strong electrical and magnetic fields

Devices exposed to strong magnetic fields can undergo a polarization phenomenon in their plastic material, or within the chip, which gives rise to abnormal symptoms such as impedance changes or increased leakage current. Failures have been reported in LSIs mounted near malfunctioning deflection yokes in TV sets. In such cases the device's installation location must be changed or the device must be shielded against the electrical or magnetic field. Shielding against magnetism is especially necessary for devices used in an alternating magnetic field because of the electromotive forces generated in this type of environment.

3.6.6 Interference from light (ultraviolet rays, sunlight, fluorescent lamps and incandescent lamps)

Light striking a semiconductor device generates electromotive force due to photoelectric effects. In some cases the device can malfunction. This is especially true for devices in which the internal chip is exposed. When designing circuits, make sure that devices are protected against incident light from external sources. This problem is not limited to optical semiconductors and EPROMs. All types of device can be affected by light.

3.6.7 Dust and oil

Just like corrosive gases, dust and oil can cause chemical reactions in devices, which will adversely affect a device's electrical characteristics. To avoid this problem, do not use devices in dusty or oily environments. This is especially important for optical devices because dust and oil can affect a device's optical characteristics as well as its physical integrity and the electrical performance factors mentioned above.

3.6.8 Fire

Semiconductor devices are combustible; they can emit smoke and catch fire if heated sufficiently. When this happens, some devices may generate poisonous gases. Devices should therefore never be used in close proximity to an open flame or a heat-generating body, or near flammable or combustible materials.

3.7 Disposal of Devices and Packing Materials

When discarding unused devices and packing materials, follow all procedures specified by local regulations in order to protect the environment against contamination.

4. Precautions and Usage Considerations

This section describes matters specific to each product group which need to be taken into consideration when using devices. If the same item is described in Sections 3 and 4, the description in Section 4 takes precedence.

4.1 Microcontrollers

4.1.1 Design

- (1) Using resonators which are not specifically recommended for use

Resonators recommended for use with Toshiba products in microcontroller oscillator applications are listed in Toshiba databooks along with information about oscillation conditions. If you use a resonator not included in this list, please consult Toshiba or the resonator manufacturer concerning the suitability of the device for your application.

- (2) Undefined functions

In some microcontrollers certain instruction code values do not constitute valid processor instructions. Also, it is possible that the values of bits in registers will become undefined. Take care in your applications not to use invalid instructions or to let register bit values become undefined.

TMPR4927A

Conventions in this Manual

Value Conventions

- Hexadecimal values are expressed as in the following example. (This value is expressed as 42 in the decimal system.)
- KB (kilobyte) = 1,024 Bytes,
MB (megabyte) = $1,024 \times 1,024 = 1,048,576$ Bytes,
GB (gigabyte) = $1,024 \times 1,024 \times 1,024 = 1,073,741,824$ Bytes

Data Conventions

- Byte: 8 bits
- Half-word: 2 consecutive Bytes (16 bits)
- Word: 4 consecutive Bytes (32 bits)
- Double-word: 8 consecutive Bytes (64 bits)

Signal Conventions

- An asterisk (“*”) is added to the end of signal names to indicate Low Active signals. (Example: RESET*)
- “Assert” means to move a signal to its Active level. “Deassert” means to move a signal to its Inactive level.

Register Conventions

- Bit operation is expressed as follows.
Set: Put a bit in the “1” position.
Clear: Put a bit in the “0” position.
- Properties of each bit in a register are expressed as follows.
R: Read only. The software cannot change the bit value.
W: Write only. The value that is read is undefined.
R/W: Read/Write is possible.
R/W1C: Read/Write 1 Clear. These bits can be read from and written to. The corresponding bit is cleared when “1” is written to this bit. “0” is invalid if written.
R/W0C: Read/Write 0 Clear. These bits can be read from and written to. The corresponding bit is cleared when “0” is written to this bit. “1” is invalid if written.
R/L: Property unique to the PCI Controller. This bit can be read. The value of this bit can only be changed by the method described in “10.3.14: Set Configuration Space”.
- Registers and the register bit/field name are expressed as “<register name>.<bit/field name>”.
Example: CCFG.TOE
The above example indicates Time Out Bus Error Enable (TOE), a bit field of bit 14 in the Chip Configuration Register (CCFG).

Handling reserved regions

Operation is undefined when a register defined in this document as a reserved region (Reserved) is accessed. If there is a bit or field that was defined as Reserved in a register, write “0” when writing to that bit/field. Also, do not use any value read from this bit/field.

Diagnostic function

Any function described as a “diagnostic function” is used to facilitate operation evaluations. The operation of such functions is not guaranteed.

References

64-bit TX System RISC TX49/H2 Core Architecture User's Manual

(<http://doc.semicon.toshiba.co.jp/>)

MIPS RISC Architecture, Gerry Kane and Joe Heinrich (ISBN 0-13-590472-2)

See MIPS Run, Dominic Sweetman (ISBN 1-55860-410-3)

MIPS Publications (<http://www.mips.com/publications/>)

PCI Local Bus Specification Revision 2.2 (<http://www.pcisig.com/>)

PCI Bus Power Management Interface Specification Revision 1.1

Audio CODEC '97 (AC '97) Revision 2.1 (<http://developer.intel.com/ial/scalableplatforms/audio/>)

1. Outline and Features

1.1 Outline

The TMPR4927 (hereinafter called "TX4927") is a standard microcontroller of the TX49 64-bit TX System RISC family.

The TX4927 uses the TX49/H2 core as the CPU. The TX49/H2 core is a 64-bit RISC core Toshiba developed based on the MIPS III architecture of MIPS Technologies, Inc. ("MIPS"). For information on the architecture of the TX49/H2 core, including the instruction set, refer to the manual *64-bit TX System RISC, TX49/H2 Core Architecture*.

The TX4927 is designed for embedded applications. In addition to its TX49/H2 core, the TX4927 also incorporates peripheral circuits such as an external bus controller, DMA controller, SDRAM controller, PCI controller, serial I/O ports, timers/counters, parallel I/O ports, AC-link controller, and interrupt controller. In particular, the built-in SDRAM controller featuring a maximum data bus width of 64 bits and memory clock frequency of 100 MHz achieves low memory access latency and high memory bandwidth, making the best of the capabilities of the high-performance CPU core.

1.2 Features

- TX49/H2 core
 - Maximum operating frequency: 200 MHz
 - Contains single- and double-precision floating-point operation units (FPU) that comply with IEEE754
- External bus controller (8 channels)
- Direct memory access (DMA) controller (4 channels)
- SDRAM controller (4 channels)
 - 64-bit data bus
 - Memory clock frequency: 100 MHz
 - ECC/parity support
- PCI controller
 - Complies with PCI Local Bus Specification Revision 2.2
 - PCI bus clock frequency: 66 MHz/33 MHz
- Serial I/O ports (2 channels)
- Timers/counters (3 channels)
- Parallel I/O ports (up to 16 channels)
- AC-link controller
- Interrupt controller
- Supports selection between little endian and big endian modes
- Low power consumption (1.5 W typ.)
 - Internal logic operates at 1.5 V and I/O operates at 3.3 V. Supports low power (Halt) mode.
- Supports IEEE1149.1 (JTAG): Debug support unit (Extended EJTAG)
- Package: 420-pin TBGA

1.2.1 Features of the TX49/H2 Core

The TX49/H2 is a high-performance, low-power 64-bit RISC CPU core developed by Toshiba.

- 64-bit operation
- 32 64-bit integer general-purpose registers
- 64G bytes of physical address space
- Optimized 5-stage pipeline
- Instruction set
 - Upwardly compatible with MIPS III ISA
 - Additional instructions: 3-operand multiply, MAC (sum of products), and PREF (prefetch)
- 32K bytes of instruction cache and 32K bytes of data cache
 - 4-way set associative, locking functions supported
- Memory management unit (MMU)
 - 48 double entry (odd/even) joint TLBs
- Contains single- and double-precision FPU that comply with IEEE754
- 4-stage write buffers
- Debug support unit: Extended EJTAG

1.2.2 Features of TX4927 Peripherals

(1) External bus controller (EBUSC)

The external bus controller generates necessary signals to control external memory and I/O devices.

- 8 channels of chip select signals, enabling control of up to eight external devices
- Supports access to ROM (including mask ROM, page mode ROM, EPROM, and EEPROM), SRAM, flash ROM, and I/O devices
- Supports 32-bit, 16-bit, and 8-bit data bus sizing on a per channel basis
- Supports selection among full speed (up to 100 MHz), 1/2 speed (up to 50 MHz), 1/3 speed (up to 33 MHz), and 1/4 speed (up to 25 MHz) on a per channel basis
- Supports specification of timing on a per channel basis
 - The user can specify setup and hold times for address, chip enable, write enable, and output enable signals.
- Supports memory sizes of 1M byte to 1G byte for devices with 32-bit data bus, 1M byte to 512M bytes for devices with 16-bit data bus, and 1M byte to 256M bytes for devices with 8-bit data bus

(2) Direct memory access controller (DMAC)

The TX4927 contains a 4-channel DMA controller that executes DMA transfer to memory and I/O devices.

- 4 channels independently handling internal/external DMA requests
- Supports DMA transfer with built-in serial I/O controller and AC-link controller based on internal DMA requests
- Supports single address (fly-by DMA) and dual address transfers in external I/O DMA transfer mode using external DMA requests
- Supports transfer between memory and external I/O devices having 32/16/8-bit data bus
- Supports memory-to-memory copy mode, with no address boundary restrictions
Supports burst transfer of up to 8 double words for a single read/write
- Supports memory fill mode, writing double-word data to specified memory area
- Supports chained DMA transfer

(3) SDRAM controller (SDRAMC)

The SDRAM controller generates necessary control signals for the SDRAM interface. It has four channels and can handle up to 2G bytes (512 MB/channel) of memory by supporting a variety of memory configurations.

- Memory clock frequency: 50 to 100 MHz
- 4 sets of independent memory channels
- Supports 16 M/64 M/128 M/256 M-bit SDRAM with 2/4 bank size availability
- Supports use of Registered DIMM
- Supports ECC or parity generation/check functions
- Supports 64/32-bit data bus sizing on a per channel basis
- Supports specification of SDRAM timing on a per channel basis
- Supports critical word first access of TX49/H2 core
- Low power mode: selectable between self-refreshing and precharge power-down

(4) PCI controller (PCIC)

The TX4927 contains a PCI controller that complies with PCI Local Bus Specification Revision 2.2.

- Compliance with PCI Local Bus Specification Revision 2.2
- 32-bit PCI interface featuring maximum PCI bus clock frequency of 66 MHz
- Supports both target and initiator functions
- Supports change of address mapping between internal bus and PCI bus
- PCI bus arbiter enables connection of up to 4 external bus masters
- Supports booting of TX4927 from memory on PCI bus
- 1 channel of DMA controller dedicated to PCI controller (PDMAC)

(5) Serial I/O ports (SIO)

The TX4927 contains a 2-channel asynchronous serial I/O interface (full duplex UART).

- 2-channel full duplex UART
- Built-in baud rate generator
- FIFOs
 - 8-bit x 8 transmitter FIFO
 - 13-bit (8 data bits and 5 status bits) x 16 receiver FIFO
- Supports DMA transfer

(6) Timer/counter control (TMR)

The TX4927 contains 3-channel timers/counters.

- 3-channel 32-bit up-counter
- Supports three modes: interval timer mode, pulse generator mode, and watchdog timer mode
- 2 timer output pins
- 1 count clock input pin
- 1 external watchdog reset signal

(7) Parallel I/O ports (PIO)

The TX4927 contains 16-bit parallel I/O ports (including 8 bits shared with CB[7:0]).

- Independent selection of direction of pins and output port type (totem-pole or open-drain output) on a per bit basis

(8) AC-link controller (ACLC)

The TX4927 contains an AC-link controller, which can be operated using any audio and/or modem CODECs described in Audio CODEC '97 Revision 2.1 (AC'97).

- Supports up to two CODECs
- Supports recording and playback for right and left 16-bit PCM channels
- Supports playback for 16-bit surround, center, and LFE channels
- Supports audio recording and playback at variable rate
- Supports Line1 and GPIO slots for modem CODEC
- Supports AC-link low power mode, wakeup, and warm reset
- Supports input/output of sample data by DMA transfer

(9) Interrupt controller (IRC)

The TX4927 contains an interrupt controller, which receives interrupt requests sent by both the TX4927's built-in peripherals and external devices and issues interrupt requests to the TX49/H2 core. It has a 16-bit flag register to generate interrupt requests to external devices or the TX49/H2 core.

- Supports 18 internal interrupt sources from built-in peripherals and 6 external interrupt signal inputs
- 8 interrupt priority levels for each interrupt source
- Supports selection between edge- and level-triggered interrupt detection for each external interrupt
- 16-bit read/write flag register for interrupt requests, making it possible to issue interrupt requests to external devices and to the TX49/H2 core (IRC interrupts)

(10) Extended EJTAG interface

The TX4927 contains an Extended Enhanced Joint Test Action Group (Extended EJTAG) interface, which provides two functions: JTAG boundary scan test that complies with IEEE1149.1 and real-time debugging using a debug support unit (DSU) built into the TX49/H2 core.

- IEEE 1149.1 JTAG Boundary Scan
- Real-time debugging functions using special emulation probe: execution control (execution, break, step, and register/memory access) and PC trace

2. Structure

2.1 TX4927 Block Diagram

Figure 2.1.1 shows the internal block diagram of the TX4927.

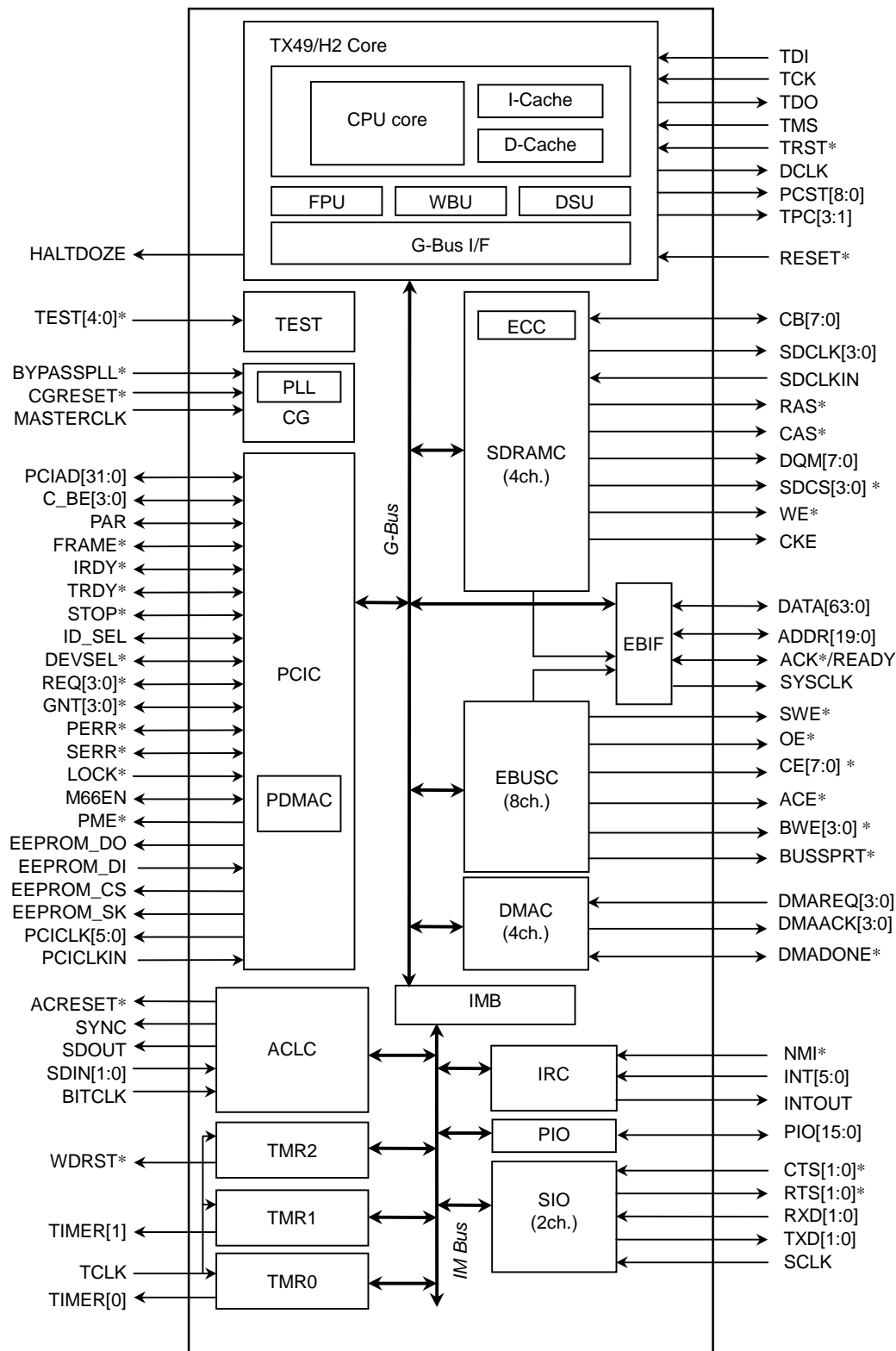


Figure 2.1.1 TX4927 Block Diagram

The TX4927 has the following blocks:

- (1) TX49/H2 core: Consists of the CPU, system control coprocessor (CP0), instruction cache, data cache, floating-point operation unit (FPU), write buffer unit (WBU), debug support unit (DSU), and G-Bus interface.
 - FPU: Single- and double-precision floating-point operation unit that complies with IEEE754. Assigned as one of the coprocessor units (CP1).
 - I-Cache: Instruction cache memory of 32K bytes (4-way set associative).
 - D-Cache: Data cache memory of 32K bytes (4-way set associative). One of three write policies can be selected: write back, write through without write allocate, and write through with write allocate.
 - DSU: Debug support unit, which is an on-chip debugging module.
- (2) EBUSC: External bus controller. Controls eight channels of ROM, SRAM, and I/O devices.
- (3) DMAC: Direct memory access controller. Enables data transfer between internal and external I/O devices and memory.
- (4) SDRAMC: SDRAM controller. Controls four channels of SDRAM and supports 64-bit data buses, 100 MHz operation, and ECC/parity generation.
- (5) PCIC: PCI bus controller that complies with PCI Local Bus Specification Revision 2.2. Supports 66 MHz operation and contains a dedicated DMA controller (PDMAC).
- (6) SIO: Serial I/O. Asynchronous serial interface having two channels.
- (7) TMR: Timers/counters having three channels.
- (8) PIO: Parallel I/O. Includes 8-bit dedicated ports and 8-bit shared ports.
- (9) ACLC: AC-link controller that complies with Audio CODEC '97 Revision 2.1 (AC '97).
- (10) IRC: Interrupt controller.
- (11) EBIG: External bus interface. Connects the SDRAMC and EBUSC with the 20-bit external address bus and 64-bit external data bus.
- (12) CG: Clock generator. Contains a PLL for supplying clock pulses to sections of the TX4927.
- (13) G-Bus: One of the internal buses of the TX4927. G-Bus is a high-speed 64-bit internal bus directly connected to the TX49/H2 core.
- (14) IM-Bus: One of the internal buses of the TX4927. IM-Bus is a low-speed 32-bit internal bus connected to the G-Bus via the IMB.
- (15) IMB: G-Bus to IM-Bus bridge.
- (16) TEST: Internal diagnostic module.

3. Signals

3.1 Pin Signal Description

In the following tables, asterisks at the end of signal names indicate active-low signals.

In the Type column, PU indicates that the pin is equipped with an internal pull-up resistor and PD indicates that the pin is equipped with an internal pull-down resistor. OD indicates an open-drain pin.

The Initial State column shows the state of the signal when the RESET* signal is asserted and immediately after it is deasserted. Those signals which are selected by a configuration signal upon a reset have the state selected by the configuration signal even when the reset signal is asserted.

3.1.1 Signals Common to SDRAM and External Bus Interfaces

Table 3.1.1 Signals Common to SDRAM and External Bus Interfaces

Signal Name	Type	Description	Initial State
ADDR[19:0]	Input/output PU	<p>Address</p> <p>Address signals.</p> <p>For SDRAM, ADDR[19:5] are used (refer to Sections “9.3.2.2” and “9.3.2.3 Address Signal Mapping”).</p> <p>When the external bus controller uses these pins, the meaning of each bit varies with the data bus width (refer to Section “7.3.5 Data Bus Size”).</p> <p>The ADDR signals are also used as boot configuration signals (input) during a reset. For details of configuration signals, refer to Section “3.2 Boot Configuration”.</p> <p>The ADDR signals are input signals only when the RESET* signal is asserted and become output signals after the RESET* signal is deasserted.</p>	Input
DATA[63:0]	Input/output PU	<p>Data</p> <p>64-bit data bus.</p> <p>The DATA[15:0] signals are also used as boot configuration signals (input) during a reset. For details of configuration signals, refer to Section “3.2 Boot Configuration”.</p>	Input
BUSSPRT*	Output	<p>Bus Separate</p> <p>Controls the connection and separation of devices controlled by the external bus controller to or from a high-speed device, such as SDRAM (refer to Section “7.6 Flash ROM, SRAM Usage Example”).</p> <p>H: Separate devices other than SDRAM from the data bus.</p> <p>L: Connect devices other than SDRAM to the data bus.</p> <p>Separation and connection are performed using external bidirectional bus buffers (such as the 74xx245).</p>	High

3.1.2 SDRAM Interface Signals

Table 3.1.2 SDRAM Interface Signals

Signal Name	Type	Description	Initial State
SDCLK[3:0]	Output	SDRAM Controller Clock Clock signals used by SDRAM. The clock frequency is the same as the G-Bus clock (GBUSCLK) frequency. When these clock signals are not used, the pins can be set to H using the SDCLK Enable field of the configuration register (CCFG.SDCLKEN[3:0]).	All High
SDCLKIN	Input/output	SDRAM Feedback Clock input Feedback clock signal for SDRAM controller input signals. Setting the SDCLKINEN bit of the pin configuration register causes the TX4927 to feed back signals internally, making SDCLKIN an output signal.	Input
CKE	Output	Clock Enable CKE signal for SDRAM.	High
SDCS[3:0]*	Output	Synchronous Memory Device Chip Select Chip select signals for SDRAM.	All High
RAS*	Output	Row Address Strobe RAS signal for SDRAM.	High
CAS*	Output	Column Address Strobe CAS signal for SDRAM.	High
WE*	Output	Write Enable WR signal for SDRAM.	High
DQM[7:0]	Output	Data Mask During a write cycle, the DQM signals function as a data mask. During a read cycle, they control the SDRAM output buffers. The bits correspond to the following data bus signals: DQM[7]:DATA[63:54], DQM[6]:DATA[53:48] DQM[5]:DATA[47:40], DQM[4]:DATA[39:32] DQM[3]:DATA[31:24], DQM[2]:DATA[23:16] DQM[1]:DATA[15:8], DQM[0]:DATA[7:0] Connect any one of the DQM[3:0] to SDRAM which connects CB.	All High
CB[7:0]	Input/output PU	ECC/Parity Check Bit ECC/parity check bit signals. The bits correspond to the following data bus signals: CB[7]:DATA[63:54], CB[6]:DATA[53:48] CB[5]:DATA[47:40], CB[4]:DATA[39:32] CB[3]:DATA[31:24], CB[2]:DATA[23:16] CB[1]:DATA[15:8], CB[0]:DATA[7:0] CB[7:0] share pins with the PIO[15:8] signals for parallel I/O. The boot configuration signal on the ADDR[18] pin selects between PIO[15:8] and CB[7:0].	Input

3.1.3 External Interface Signals

Table 3.1.3 External Interface Signals

Signal Name	Type	Description	Initial State
SYSCLK	Output	System Clock Clock for external I/O devices. Outputs a clock in full speed mode (at the same frequency as the G-Bus clock (GBUSCLK) frequency), half speed mode (at one half the GBUSCLK frequency), third speed mode (at one third the GBUSCLK frequency), or quarter speed mode (at one quarter the GBUSCLK frequency). The boot configuration signals on the ADDR[14:13] pins select which speed mode will be used. When this clock signal is not used, the pin can be set to H using the SYSCLK Enable bit of the configuration register (CCFG.SYSCLKEN).	High
ACE*	Output	Address Clock Enable Latch enable signal for the high-order address bits of ADDR.	High
CE[7:0]*	Output	Chip Enable Chip select signals for ROM, SRAM, and I/O devices.	All High
OE*	Output	Output Enable Output enable signal for ROM, SRAM, and I/O devices.	High
SWE*	Output	Write Enable Write enable signal for SRAM and I/O devices.	High
BWE[3:0]* /BE[3:0]*	Output	Byte Enable/Byte Write Enable Byte Enable/Byte Write Enable BE[3:0]* indicate a valid data position on the data bus DATA[31:0] during read and write bus operation. In 16-bit bus mode, only BE[1:0]* are used. In 8-bit bus mode, only BE[0]* is used. BWE[3:0]* indicate a valid data position on the data bus DATA[31:0] during write bus operation. In 16-bit bus mode, only BWE[1:0]* are used. In 8-bit bus mode, only BWE[0]* is used. The following shows the correspondence between BE[3:0]*/BWE[3:0]* and the data bus signals. BE[3]*/BWE[3]*: DATA[31:24] BE[2]*/BWE[2]*: DATA[23:16] BE[1]*/BWE[1]*: DATA[15:8] BE[0]*/BWE[0]*: DATA[7:0] The boot configuration signal on the DATA[5] pin and the EBCCRn.BC bit of the external bus controller determine whether the signals are used as BE[3:0]* or BWE[3:0]*.	All High
ACK*/ READY	Input/output PU	Data Acknowledge/Ready Flow control signal (refer to Section "7.3.6 Access Modes").	High

3.1.4 DMA Interface Signals

Table 3.1.4 DMA Interface Signals

Signal Name	Type	Description	Initial State
DMAREQ[3:0]	Input PU	DMA Request DMA transfer request signals from an external I/O device. The DMAREQ[2] signal shares the pin with the ACRESET* signal. The boot configuration signal on the ADDR[9] pin selects between DMAREQ[2] and ACRESET*.	Input (other than DMAREQ[2]) Selected by ADDR[9] (DMAREQ[2] only) L: Input H: Low
DMAACK[3:0]	Output	DMA Acknowledge DMA transfer acknowledge signals to an external I/O device. The DMAACK[2] signal shares the pin with the SYNC signal. The boot configuration signal on the ADDR[9] pin selects between DMAACK[2] and SYNC.	All High (other than DMAACK[2]) Selected by ADDR[9] (DMAACK[2] only) L: High H: Low
DMADONE*	Input/output PU	DMA Done DMADONE* is either used as an output signal that reports the termination of DMA transfer or as an input signal that causes DMA transfer to terminate.	Input

3.1.5 PCI Interface Signals

Table 3.1.5 PCI Interface Signals

Signal Name	Type	Description	Initial State
PCICLK[5:0]	Output	PCI Clock PCI bus clock signals. When these clock signals are not used, the pins can be set to H using the PCICLK Enable field of the pin configuration register (PCFG.PCICKEN[5:0]).	All High
PCICLKIN	Input	PCI Feedback Clock PCI feedback clock input.	Input
PCIAD[31:0]	Input/output	PCI Address and Data Multiplexed address and data bus.	Input
C_BE[3:0]	Input/output	Command and Byte Enable Command and byte enable signals.	Input
PAR	Input/output	Parity Even parity signal for PCIAD[31:0] and C_BE[3:0]*.	Input
FRAME*	Input/output	Cycle Frame Indicates that bus operation is in progress.	Input
IRDY*	Input/output	Initiator Ready Indicates that the initiator is ready to complete data transfer.	Input
TRDY*	Input/output	Target Ready Indicates that the target is ready to complete data transfer.	Input
STOP*	Input/output	Stop The target sends this signal to the initiator to request termination of data transfer.	Input
LOCK*	Input	Lock Indicates that the PCI bus master is locking (exclusively accessing) a specified memory target on the PCI bus.	Input
ID_SEL	Input	Initialization Device Select Chip select signal used for configuration access. This pin is not used in host mode. When the PCI Controller is configured in host mode, this pin must be pulled down.	Input
DEVSEL*	Input/output	Device Select The target asserts this signal in response to access from the initiator.	Input

Signal Name	Type	Description	Initial State
REQ[3:2]*	Input	Request Signals used by the master to request bus mastership. The boot configuration signal on the DATA[2] pin determines whether the built-in PCI bus arbiter is used. In internal arbiter mode, REQ[3:2]* are PCI bus request input signals. In external arbiter mode, REQ[3:2]* are not used. Because the pins are still placed in the input state, they must be pulled up externally.	Input
REQ[1]* /INTOUT	Input/output/ OD	Request Signal used by the master to request bus mastership. The boot configuration signal on the DATA[2] pin determines whether the built-in PCI bus arbiter is used. In internal arbiter mode, this signal is a PCI bus request input signal. In external arbiter mode, this signal is an external interrupt output signal (INTOUT). Refer to Section "15.3.7 Interrupt Requests".	Selected by DATA[2] H: Input L: Hi-Z
REQ[0]*	Input/output	Request Signal used by the master to request bus mastership. The boot configuration signal on the DATA[2] pin determines whether the built-in PCI bus arbiter is used. In internal arbiter mode, this signal is a PCI bus request input signal. In external arbiter mode, this signal is a PCI bus request output signal.	Selected by DATA[2] H: Input L: High
GNT[3:0]*	Input/output	Grant Indicates that bus mastership has been granted to the PCI bus master. The boot configuration signal on the DATA[2] pin determines whether the built-in PCI bus arbiter is used. In internal arbiter mode, all of GNT[3:0]* are PCI bus grant output signals. In external arbiter mode, GNT[0]* is a PCI bus grant input signal. Because GNT[3:1]* also become input signals, they must be pulled up externally.	Selected by DATA[2] H: All High L: Input
PERR*	Input/output	Data Parity Error Indicates a data parity error in a bus cycle other than special cycles.	Input
SERR*	Input/OD	System Error Indicates an address parity error, a data parity error in a special cycle, or a fatal error. In host mode, SERR* is an input signal. In satellite mode, SERR* is an open-drain output signal. The mode is determined by the boot configuration signal on the ADDR[19] pin.	Input
M66EN	Input/output	PCI Bus 66 MHz Clock Enable 1: Enable 66 MHz operating mode. 0: Disable 66 MHz operating mode. This pin is configured as input in satellite mode and as output in host mode. The mode is selected through the logic level of the ADDR[19] pin at boot time. This pin must be pulled down when the PCI Controller is configured in satellite mode and when the 66-MHz operating mode is disabled.	Selected by ADDR[19] H: Low L: Input
PME*	Input/OD	Power Management Event PME* indicates the power management mode. In host mode, PME* is an input signal. In satellite mode, PME* is an open-drain output signal. The mode is determined by the boot configuration signal on the ADDR[19] pin.	Selected by ADDR[19] H: Input L: Hi-Z
EEPROM_DI	Input PU	EEPROM Data In Data input from serial EEPROM for initially setting the PCI configuration.	Input
EEPROM_DO	Output	EEPROM Data Out Data output to serial EEPROM for initially setting the PCI configuration.	Low
EEPROM_CS	Output	EEPROM Chip Select Chip select for serial EEPROM for initially setting the PCI configuration.	Low
EEPROM_SK	Output	EEPROM Serial Clock Clock for serial EEPROM for initially setting the PCI configuration.	Low

Note : The PCI bus specification specifies that the following pins require pullups: FRAME*, IRDY*, TRDY*, STOP*, LOCK*, DEVSEL*, PERR*, SERR* and PME*. If these pins are unused, pullups must be provided externally to the TX4927.

3.1.6 Serial I/O Interface Signals

Table 3.1.6 Serial I/O Interface Signals

Signal Name	Type	Description	Initial State
CTS [1:0]*	Input PU	SIO Clear to Send CTS* signals.	Input
RTS [1:0]*	Output	SIO Request to Send RTS* signals.	All Low
RXD[1:0]	Input PU	SIO Receive Data Serial data input signals.	Input
TXD[1:0]	3-state Output	SIO Transmit Data Serial data output signals.	All High
SCLK	Input PU	External Serial Clock SIO clock input signal. SIO0 and SIO1 share this signal.	Input

3.1.7 Timer Interface Signals

Table 3.1.7 Timer Interface Signals

Signal Name	Type	Description	Initial State
TIMER[1:0]	Output	Timer Output Timer output signals.	All High
TCLK	Input PU	External Timer Clock Timer input clock signal. TMR0, TMR1, and TMR2 share this signal.	Input
WDRST*	OD output	Watchdog Reset Watchdog reset output signal.	Hi-Z

3.1.8 Parallel I/O Interface Signals

Table 3.1.8 Parallel I/O Interface Signals

Signal Name	Type	Description	Initial State
PIO[15:8]	Input/output PU	PIO Ports[15:8] Parallel I/O signals. PIO[15:8] share pins with the SDRAM ECC/parity signals (CB[7:0]). The boot configuration signal on the ADDR[18] pin selects between PIO[15:8] and CB[7:0].	Input
PIO[7:0]	Input/output	PIO Ports[7:0] Parallel I/O signals. PIO[4:2] share pins with the AC-link interface signals (SDOUT, SDIN[0], and BITCLK). The boot configuration signal on the ADDR[9] pin selects between PIO[4:2] and AC-link interface signals.	Input (other than PIO[4]) Selected by ADDR[9] (PIO[4] only) L: Input H: All Low

3.1.9 AC-link Interface Signals

Table 3.1.9 AC-link Interface Signals

Signal Name	Type	Description	Initial State
ACRESET*	Output	AC '97 Master H/W Reset ACRESET* shares the pin with the DMAREQ[2] signal. The boot configuration signal on the ADDR[9] pin selects between ACRESET* and DMAREQ[2].	Selected by ADDR[9] L: Low H: Input
SYNC	Output	48 kHz Fixed Rate Sample Sync SYNC shares the pin with the DMAACK[2] signal. The boot configuration signal on the ADDR[9] pin selects between SYNC and DMAACK[2].	Selected by ADDR[9] L: Low H: High
SDOUT	Output	Serial, Time Division Multiplexed, AC '97 Output Stream SDOUT shares the pin with the PIO[4] signal. The boot configuration signal on the ADDR[9] pin selects between SDOUT and PIO[4].	Selected by ADDR[9] L: Low H: Input
SDIN[1]	Input	Serial, Time Division Multiplexed, AC '97 Input Stream	Input
SDIN[0]	Input	Serial, Time Division Multiplexed, AC '97 Input Stream SDIN[0] shares the pin with the PIO[3] signal. The boot configuration signal on the ADDR[9] pin selects between SDIN[0] and PIO[3].	Input
BITCLK	Input	12.288 MHz Serial Data Clock BITCLK shares the pin with the PIO[2] signal. The boot configuration signal on the ADDR[9] pin selects between BITCLK and PIO[2].	Input

3.1.10 Interrupt Signals

Table 3.1.10 Interrupt Signals

Signal Name	Type	Description	Initial State
NMI*	Input PU	Non-Maskable Interrupt Non-maskable interrupt signal.	Input
INT[5:0]	Input PU	External Interrupt Requests External interrupt request signals.	Input

3.1.11 Extended EJTAG Interface Signals

Table 3.1.11 Extended EJTAG Interface Signals

Signal Name	Type	Description	Initial State
TCK	Input PU	JTAG Test Clock Input Clock input signal for JTAG. TCK is used to execute JTAG instructions and input/output data.	Input
TDI/DINT*	Input PU	JTAG Test Data Input/Debug Interrupt When PC trace mode is not selected, this signal is a JTAG data input signal. It is used to input serial data to JTAG data/instruction registers. When PC trace mode is selected, this signal is an interrupt input signal used to cancel PC trace mode for the debug unit.	Input
TDO/TPC[0]	Output	JTAG Test Data Output/PC Trace Output When PC trace mode is not selected, this signal is a JTAG data output signal. Data is output by means of serial scan. When PC trace mode is selected, this signal outputs the value of the noncontinuous program counter in sync with the debug clock (DCLK).	High
TPC[3:1]	Output	PC Trace Output TPC[3:1] output the value of the noncontiguous program counter in sync with DCLK.	All High
TMS	Input PU	JTAG Test Mode Select Input TMS mainly controls state transition in the TAP controller state machine.	Input

Signal Name	Type	Description	Initial State
TRST*	Input	Test Reset Input Asynchronous reset input for the TAP controller and debug support unit (DSU). When an EJTAG probe is not connected, this pin must be fixed to low. When connecting an EJTAG probe, prevent floating, for example, by connecting a pull-up resistor. When this signal is deasserted, G-Bus timeout detection is disabled (refer to Section "5.1.1 Detecting G-Bus Timeout").	Input
DCLK	Output	Debug Clock Clock output signal for the real-time debugging system. When PC trace mode is selected, the TPC[3:1] and PCST signals are output synchronously. This clock is the TX49/H2 core operating clock (CPUCLK) divided by 3.	Low
PCST[8:0]	Output	PC Trace Status Information Outputs PC trace status and other information.	All Low

3.1.12 Clock Signals

Table 3.1.12 Clock Signals

Signal Name	Type	Description	Initial State
MASTERCLK	Input	Master Clock Input pin for the TX4927 operating clock. A crystal resonator cannot be connected to this pin because the pin does not contain an oscillator.	Input
HALTDOZE	Output	Halt/Doze State Output This signal is asserted (High output) when the TX4927 enters Halt or Doze mode.	Low
BYPASSPLL*	Input	Bypass PLL This pin must be fixed to High.	Input
CGRESET*	Input	CG Reset CGRESET* initializes the CG.	Input

3.1.13 Initialization Signal

Table 3.1.13 Initialization Signal

Signal Name	Type	Description	Initial State
RESET*	Input	Reset Reset signal.	Input

3.1.14 Test Signals

Table 3.1.14 Test Signals

Signal Name	Type	Description	Initial State
TEST[4:0]*	Input PU	Test Mode Setting Test pins. These pins must be left open or fixed to High. TEST[1]* may be used when debugging the system. Toshiba recommends that your board design enable the pin to be driven low after the TX4927 is mounted on the PC board. Contact Toshiba technical staff for more information on the TEST[1]* functions.	Input

3.1.15 Power Supply Pins

Table 3.1.15 Power Supply Pins

Signal Name	Type	Description	Initial State
PLL1VDD_A, PLL2VDD_A	—	PLL Power Pins PLL analog power supply pins. PLL1VDD_A = 1.5 V. PLL2VDD_A = 1.5 V.	—
PLL1VSS_A, PLL2VSS_A	—	PLL Ground Pins PLL analog ground pins. PLL1VSS_A = 0 V. PLL2VSS_A = 0 V.	—
VccInt	—	Internal Power Pins Digital power supply pins for internal logic. VccInt = 1.5 V.	—
VccIO	—	I/O Power Pins Digital power supply pins for input/output pins. VccIO = 3.3 V.	—
Vss	—	Ground Pins Digital ground pins. Vss = 0 V.	—

3.2 Boot Configuration

The ADDR[19:0] and DATA[15:0] signals can also function as configuration signals for initially setting various functions upon booting the system. The states of the configuration signals immediately after the RESET* or CGRESET* signal is deasserted are read as initial values for the TX4927 internal registers. A High signal level sets a value of 1 and a Low signal level sets a value of 0.

All configuration signals are provided with internal pull-up resistors. To drive a signal Low, pull down the corresponding pin on the board using an approx. 4.7 kΩ resistor. Driving a signal High does not require a pull-down resistor. Any signals defined as Reserved should not be pulled down.

Table 3.2.1 lists the functions that can be set using configuration signals. Table 3.2.2 and 3.2.3 describe each configuration signal.

Table 3.2.1 Functions that Can be Set Using Configuration Signals

Peripheral Function	Functions that Can be Set	Configuration Signal
PCI controller	PCI controller operating mode (satellite or host)	ADDR[19]
	Division ratio of PCICLK[5:0] to CPUCLK	ADDR[11:10]
	PCI bus arbiter selection (internal or external)	DATA[2]
External bus controller	Division ratio of SYSCLK to GBUSCLK	ADDR[14:13]
	Boot device selection	ADDR[8]
	Division ratio of the external bus controller clock upon booting	ADDR[7:6]
	BE[3:0]*/BWE[3:0]* function selection upon booting	DATA[5]
	Handling of the ACK signal upon booting (internal or external)	DATA[4]
	Data bus width for the boot device	DATA[1:0]
Clock	Division ratio of CPUCLK to MASTERCLK	ADDR[2:0]
Others	Shared pin function setting	ADDR[18], ADDR[9]
	Endian setting	ADDR[12]
	Board information setting	DATA[15:8]
	Controlling built-in timer interrupts of the TX49/H2 core	DATA[7]

Table 3.2.2 Boot Configuration Specified with the ADDR[19:0] Signals

Signal	Description	Corresponding Register Bit	Configuration Determined at
ADDR[19]	PCI Controller Mode Select Specifies the operating mode of the TX4927 PCI controller. L = Satellite H = Host	CCFG. PCIMODE	RESET* deassert edge
ADDR[18]	Select Shared I/O Pins Specifies the function of the PIO[15:8]/CB[7:0] shared pins. L = PIO[15:8] H = CB[7:0]	PCFG. SEL1	RESET* deassert edge
ADDR[17:15]	Reserved	—	—
ADDR[14:13]	Select SYSCLK Frequency Specifies the division ratio of the SYSCLK frequency to the G-Bus clock (GBUSCLK) frequency. LL = 4 (SYSCLK frequency = GBUSCLK frequency/4) LH = 3 (SYSCLK frequency = GBUSCLK frequency/3) HL = 2 (SYSCLK frequency = GBUSCLK frequency/2) HH = 1 (SYSCLK frequency = GBUSCLK frequency)	CCFG. SYSSP	CGRESET* deassert edge
ADDR[12]	TX4927 Endian Mode Specifies the TX4927 endian mode. L = Little endian H = Big endian	CCFG. ENDIAN	RESET* deassert edge
ADDR[11:10]	Select PCI Clock Frequency Specifies the division ratio of the PCI bus clock (PCICLK[5:0]) to the TX49/H2 core clock (CPUCLK). LL = 2.5 (PCICLK frequency = CPUCLK frequency/2.5) LH = 3 (PCICLK frequency = CPUCLK frequency/3) HL = 5 (PCICLK frequency = CPUCLK frequency/5) HH = 6 (PCICLK frequency = CPUCLK frequency/6)	CCFG. PCIDIVMODE	CGRESET* deassert edge
ADDR[9]	PIO/ALCL Select Specifies whether PIO[7:2] signals are used as PIO or AC-link interface signals. H = AC-link interface L = PIO	PCFG.SEL2	RESET* deassert edge
ADDR[8]	Select Boot Memory Selects boot memory. H = Device connected to channel 0 of the external bus controller L = PCI boot (Set ADDR[7:6] as HH.)	EBCCR0.ME	RESET* deassert edge
ADDR[7:6]	Select Boot Device Clock Frequency Specifies the clock division ratio for external bus controller channel 0 upon booting (refer to Section "7.3.8 Clock Options"). HH = 1/1 HL = 1/2 LH = 1/3 LL = 1/4	EBCCR0.SP	RESET* deassert edge
ADDR[5:3]	Reserved	—	—
ADDR[2:0]	CPUCLK Clock Speed Setting Specifies the value by which MASTERCLK input signal is multiplied to produce the TX49/H2 core clock (CPUCLK). The values of ADDR[1:0] are also reflected in the EC field of the TX49/H2 core Config register. HHH: MASTERCLK frequency : CPUCLK frequency = 1:2 HHL: MASTERCLK frequency : CPUCLK frequency = 1:2.5 HLH: MASTERCLK frequency : CPUCLK frequency = 1:3 HLL: MASTERCLK frequency : CPUCLK frequency = 1:4 LHH: MASTERCLK frequency : CPUCLK frequency = 1:8 LHL: MASTERCLK frequency : CPUCLK frequency = 1:10 LLH: MASTERCLK frequency : CPUCLK frequency = 1:12 LLL: MASTERCLK frequency : CPUCLK frequency = 1:16	CCFG.DIVMODE	CGRESET* deassert edge

Table 3.2.3 Boot Configuration Specified with the DATA[15:0] Signals

Signal	Description	Corresponding Register Bit	Configuration Determined at
DATA[15:8]	Boot Configuration Reads the DA board information and accordingly sets the boot configuration field (BCFG) of the chip configuration register (CCFG).	CCFG.BCFG	RESET* deassert edge
DATA[7]	TX49/H2 Internal Timer Interrupt Disable Specifies whether timer interrupts within the TX49/H2 core are enabled. H = Enable timer interrupts within the TX49/H2 core. L = Disable timer interrupts within the TX49/H2 core.	CCFG.TINTDIS	RESET* deassert edge
DATA[6]	Reserved	—	—
DATA[5]	Specifies the function of the BE[3:0]*/BWE[3:0]* pins upon booting. L = BE[3:0]* (Byte Enable) H = BWE[3:0]* (Byte Write Enable)	EBCCR0.BC	RESET* deassert edge
DATA[4]	Boot ACK* Input Specifies the access mode for external bus controller channel 0. L = External ACK mode H = Normal mode	EBCCR0.WT[0]	RESET* deassert edge
DATA[3]	Reserved	—	—
DATA[2]	PCI Arbiter Select Selects a PCI bus arbiter. L = External PCI bus arbiter. H = Built-in PCI bus arbiter.	CCFG.PCIARB	RESET* deassert edge
DATA[1:0]	Boot ROM Bus Width Specifies the data bus width when booting from a memory device connected to the external memory controller. LL = Reserved LH = 32 bits HL = 16 bits HH = 8 bits	EBCCR0.BSZ	RESET* deassert edge

4. Address Mapping

This chapter explains the physical address map of TX4927.

Please refer to "64 bit TX System RISC TX49/H2 Core Architecture" about the details of mapping to a physical address from the virtual address of TX49/H2 core.

4.1 TX4927 Physical Address Map

TX4927 supports up to 64G (2^{36}) bytes of physical address.

Following resources are to be allocated in the physical address of the TX4927.

- TX4927 Internal registers (refer to §4.2 Register Map)
- SDRAM (refer to §9.3.2 Address Mapping)
- External Devices such as ROM, I/O Devices (refer to §7.3.3 Address Mapping)
- PCI Bus (refer to §10.3.4 Initiator Access)

Each resource is to be allocated in any physical addresses by the register setup. Refer to the explanation of each controller for the details of the mapping.

At initialization, only the internal registers and the memory space which stores the TX49/H2 core reset vectors are allocated shown as Figure 4.1.1. Usually ROM connected to the external bus controller channel 0 is used for the memory device that stores the reset vectors. TX4927 also supports using the memories on PCI bus as the memory device stores the reset vectors. Refer to §10.3.12 PCI Boot Configuration for detail about this.

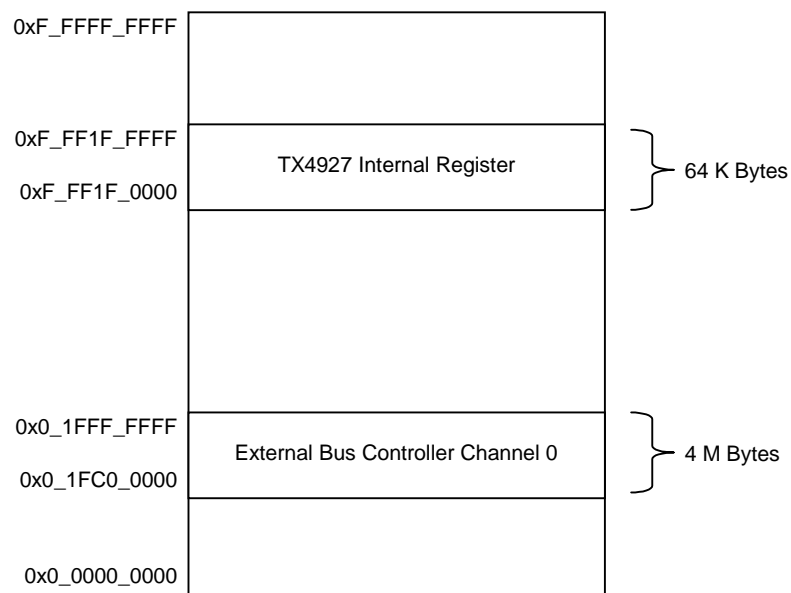


Figure 4.1.1 Physical Address Map at Initializing System

It is possible to access a resource of TX4927 as a PCI target device through PCI bus. About how to allocate resources of TX4927 to the PCI bus address space, refer to §10.3.5 Target Access.

4.2 Register Map

4.2.1 Addressing

TX4927 internal registers are to be accessed through 64 K bytes address space that is based on physical address 0xF_FF1F_0000 or pointed address by RAMP register (refer to §5.2.7). Figure 4.2.1 shows how to generate internal register address. Physical address 1 and physical address 2 shown Figure 4.2.1 access the same register.

In TX49/H2 Core, the physical address form 0xF_FF00_0000 to 0xF_FF3F_FFFF are uncached mapped to the virtual address form 0xFF00_0000 to 0xFF3F_FFFF (32 bit mode) /form 0xFFFF_FFFF_FF00_0000 to 0xFFFF_FFFF_FF3F_FFFF (64 bit mode).

This space includes the region form 0xF_FF1F_0000 allocated TX4927 internal registers at initialization.

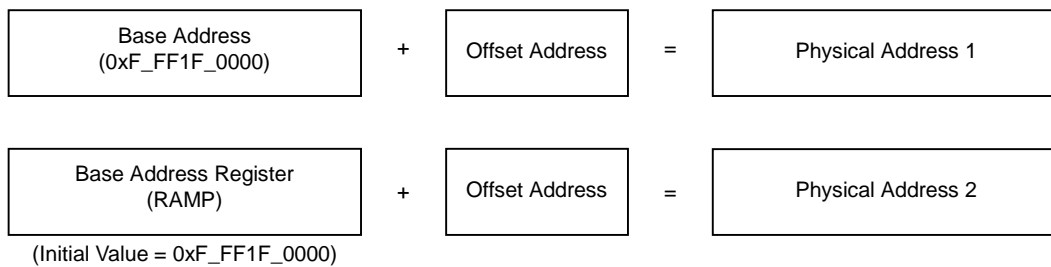


Figure 4.2.1 Generating Physical Address for a Internal Register

4.2.2 Ways to Access to Internal Registers

3 ways to access to the internal registers of TX4927 are supported. First is 32-bit register access. Second is 64-bit register access. Last is PCI configuration register access in PCI satellite mode.

32-bit register supports 32-bit size access only. Another size access without 32-bit size is undefined.

64-bit register supports both 64-bit size access and two times 32-bit size access. In each Endian mode, 32-bit size access is performed shown as Table 4.2.1.

When the build-in PCI controller works in the satellite mode (refer to §10.3.1 Terminology Explanation), PCI configuration registers are to be accessed through PCI bus in configuration cycles. It is possible to access to the arbitrary size of PCI configuration register as always Little Endian space regardless the system setup.

Table 4.2.1 32-bit Size Access to 64-bit Register

Address	Big Endian (Bit which are accessed)	Little Endian (Bit which are accessed)
0x*_****_***0	[63.....32] [31.....0]	[63.....32] [31.....0]
0x*_****_***8	#####	#####
0x*_****_***4	[63.....32] [31.....0]	[63.....32] [31.....0]
0x*_****_***C	#####	#####

(##### means 32 bits data (upper 32 bits or lower 32 bits) which are accessed.)

4.2.3 Register Map

The outline of the register map allocated built-in controllers is shown in Table 4.2.2, and the table of the internal registers is shown in Table 4.2.3, respectively.

Please refer to "§10.5 PCI Configuration Space Register" about PCI configuration register.

Table 4.2.2 Register Map

Offset Address	Peripheral Controller	Detail
0x0000 to 0x7FFF	Reserved	—
0x8000 to 0x8FFF	SDRAMC	Refer to §9.4
0x9000 to 0x9FFF	EBUSC	Refer to §7.4
0xA000 to 0xAFFF	ECC	Refer to §9.4
0xB000 to 0xBFFF	DMAC	Refer to §8.4
0xD000 to 0xDFFF	PCIC	Refer to §10.4
0xE000 to 0xEFFF	CONFIG	Refer to §5.2
0xF000 to 0xF0FF	TMR0	Refer to §12.4
0xF100 to 0xF1FF	TMR1	Refer to §12.4
0xF200 to 0xF2FF	TMR2	Refer to §12.4
0xF300 to 0xF3FF	SIO0	Refer to §11.4
0xF400 to 0xF4FF	SIO1	Refer to §11.4
0xF500 to 0xF50F	PIO	Refer to §13.4
0xF510 to 0xF6FF	IRC	Refer to §15.4
0xF700 to 0xF7FF	ACLC	Refer to §14.4
0xF700 to 0xFFFF	Reserved	

Table 4.2.3 Internal Registers (1/5)

Offset Address	Register Size (bit)	Register Symbol	Register Name
SDRAM Controller (SDRAMC)			
0x8000	64	SDCCR0	SDRAM Channel Control Register 0
0x8008	64	SDCCR1	SDRAM Channel Control Register 1
0x8010	64	SDCCR2	SDRAM Channel Control Register 2
0x8018	64	SDCCR3	SDRAM Channel Control Register 3
0x8040	64	SDCTR	SDRAM Timing Register
0x8058	64	SDCCMD	SDRAM Command Register
External Bus Controller (EBUSC)			
0x9000	64	EBCCR0	EBUS Channel Control Register 0
0x9008	64	EBCCR1	EBUS Channel Control Register 1
0x9010	64	EBCCR2	EBUS Channel Control Register 2
0x9018	64	EBCCR3	EBUS Channel Control Register 3
0x9020	64	EBCCR4	EBUS Channel Control Register 4
0x9028	64	EBCCR5	EBUS Channel Control Register 5
0x9030	64	EBCCR6	EBUS Channel Control Register 6
0x9038	64	EBCCR7	EBUS Channel Control Register 7
SDRAM Error Check Correction (ECC)			
0xA000	64	ECCCR	ECC Control Register
0xA008	64	ECCSR	ECC Status Register
DMA Controller (DMAC)			
0xB000	64	DMCHAR0	DMA Chain Address Register 0
0xB008	64	DMSAR0	DMA Source Address Register 0
0xB010	64	DMDAR0	DMA Destination Address Register 0
0xB018	64	DMCNTR0	DMA Count Register 0
0xB020	64	DMSAIR0	DMA Source Address Increment Register 0
0xB028	64	DMDAIR0	DMA Destination Address Increment Register 0
0xB030	64	DMCCR0	DMA Channel Control Register 0
0xB038	64	DMCSR0	DMA Channel Status Register 0
0xB040	64	DMCHAR1	DMA Chain Address Register 1
0xB048	64	DMSAR1	DMA Source Address Register 1
0xB050	64	DMDAR1	DMA Destination Address Register 1
0xB058	64	DMCNTR1	DMA Count Register 1
0xB060	64	DMSAIR1	DMA Source Address Increment Register 1
0xB068	64	DMDAIR1	DMA Destination Address Increment Register 1
0xB070	64	DMCCR1	DMA Channel Control Register 1
0xB078	64	DMCSR1	DMA Channel Status Register 1
0xB080	64	DMCHAR2	DMA Chain Address Register 2
0xB088	64	DMSAR2	DMA Source Address Register 2
0xB090	64	DMDAR2	DMA Destination Address Register 2
0xB098	64	DMCNTR2	DMA Count Register 2
0xB0A0	64	DMSAIR2	DMA Source Address Increment Register 2
0xB0A8	64	DMDAIR2	DMA Destination Address Increment Register 2
0xB0B0	64	DMCCR2	DMA Channel Control Register 2
0xB0B8	64	DMCSR2	DMA Channel Status Register 2
0xB0C0	64	DMCHAR3	DMA Chain Address Register 3
0xB0C8	64	DMSAR3	DMA Source Address Register 3
0xB0D0	64	DMDAR3	DMA Destination Address Register 3
0xB0D8	64	DMCNTR3	DMA Count Register 3
0xB0E0	64	DMSAIR3	DMA Source Address Increment Register 3
0xB0E8	64	DMDAIR3	DMA Destination Address Increment Register 3
0xB0F0	64	DMCCR3	DMA Channel Control Register 3
0xB0F8	64	DMCSR3	DMA Channel Status Register 3
0xB148	64	DMMFDR	DMA Memory Fill Data Register
0xB150	64	DMMCR	DMA Master Control Register

Table 4.2.3 Internal Registers (2/5)

Offset Address	Register Size (bit)	Register Symbol	Register Name
PCI Controller (PCIC)			
0xD000	32	PCIID	ID Register (Device ID, Vendor ID)
0xD004	32	PCISTATUS	PCI Status, Command Register (Status, Command)
0xD008	32	PCICCREV	Class Code, Revision ID Register (Class Code, Revision ID)
0xD00C	32	PCICFG1	PCI Configuration 1 Register (BIST, Header Type, Latency Timer, Cache Line Size)
0xD010	32	P2GM0PLBASE	P2G Memory Space 0 PCI Lower Base Address Register (Base Address 0 Lower)
0xD014	32	P2GM0PUBASE	P2G Memory Space 0 PCI Upper Base Address Register (Base Address 0 Upper)
0xD018	32	P2GM1PLBASE	P2G Memory Space 1 PCI Lower Base Address Register (Base Address 1 Lower)
0xD01C	32	P2GM1PUBASE	P2G Memory Space 1 PCI Upper Base Address Register (Base Address 1 Upper)
0xD020	32	P2GM2PBASE	P2G Memory Space 2 PCI Base Address Register (Base Address 2)
0xD024	32	P2GIOPBASE	P2G I/O Space PCI Base Address Register (Base Address 3)
0xD02C	32	PCISID	Subsystem ID Register (Subsystem ID, Subsystem Vendor ID)
0xD034	32	PCICAPPTR	Capabilities Pointer Register (Capabilities Pointer)
0xD03C	32	PCICFG2	PCI Configuration 2 Register (Max_Lat, Min_Gnt, Interrupt Pin, Interrupt Line)
0xD040	32	G2PTOCNT	G2P Timeout Count register (Retry Timeout Value, TRDY Timeout Value)
0xD080	32	G2PSTATUS	G2P Status Register
0xD084	32	G2PMASK	G2P Interrupt Mask Register
0xD088	32	PCISSTATUS	Satellite Mode PCI Status Register (Status, PMCSR)
0xD08c	32	PCIMASK	PCI Status Interrupt Mask Register
0xD090	32	P2GCFG	P2G Configuration Register
0xD094	32	P2GSTATUS	P2G Status Register
0xD098	32	P2GMASK	P2G Interrupt Mask Register
0xD09C	32	P2GCCMD	P2G Current Command Register
0xD100	32	PBAREQPORT	PCI Bus Arbiter Request Port Register
0xD104	32	PBACFG	PCI Bus Arbiter Configuration Register
0xD108	32	PBASTATUS	PCI Bus Arbiter Status Register
0xD10C	32	PBAMASK	PCI Bus Arbiter Interrupt Mask Register
0xD110	32	PBABM	PCI Bus Arbiter Broken Master Register
0xD114	32	PBACREQ	PCI Bus Arbiter Current Request Register (for a diagnosis)
0xD118	32	PBACGNT	PCI Bus Arbiter Current Grant Register (for a diagnosis)
0xD11C	32	PBACSTATE	PCI Bus Arbiter Current Status Register (for a diagnosis)
0xD120	64	G2PM0GBASE	G2P Memory Space 0 G-Bus Base Address Register
0xD128	64	G2PM1GBASE	G2P Memory Space 1 G-Bus Base Address Register
0xD130	64	G2PM2GBASE	G2P Memory Space 2 G-Bus Base Address Register
0xD138	64	G2PIOGBASE	G2P I/O Space G-Bus Base Address Register
0xD140	32	G2PM0MASK	G2P Memory Space 0 Address Mask Register
0xD144	32	G2PM1MASK	G2P Memory Space 1 Address Mask Register
0xD148	32	G2PM2MASK	G2P Memory Space 2 Address Mask Register
0xD14C	32	G2PIOMASK	G2P I/O Space Address Mask Register
0xD150	64	G2PM0PBASE	G2P Memory Space 0 PCI Base Address Register
0xD158	64	G2PM1PBASE	G2P Memory Space 1 PCI Base Address Register
0xD160	64	G2PM2PBASE	G2P Memory Space 2 PCI Base Address Register
0xD168	64	G2PIOPBASE	G2P I/O Space PCI Base Address Register
0xD170	32	PCICCFG	PCI Controller Configuration Register
0xD174	32	PCICSTATUS	PCI Controller Status Register
0xD178	32	PCICMASK	PCI Controller Interrupt Mask register

Table 4.2.3 Internal Registers (3/5)

Offset Address	Register Size (bit)	Register Symbol	Register Name
PCI Controller (PCIC)			
0xD180	64	P2GM0GBASE	P2G Memory Space 0 G-Bus Base Address Register
0xD188	64	P2GM1GBASE	P2G Memory Space 1 G-Bus Base Address Register
0xD190	64	P2GM2GBASE	P2G Memory Space 2 G-Bus Base Address Register
0xD198	64	P2GIOGBASE	P2G I/O Space 0 G-Bus Base Address Register
0xD1A0	32	G2PCFGADRS	G2P Configuration Address Register
0xD1A4	32	G2PCFGDATA	G2P Configuration Data Register
0xD1C8	32	G2PINTACK	G2P Interrupt Acknowledge Register
0xD1CC	32	G2PSPC	G2P Special Cycle Data Register
0xD1D0	32	PCICDATA0	PCI Configuration Data 0 Register
0xD1D4	32	PCICDATA1	PCI Configuration Data 1 Register
0xD1D8	32	PCICDATA2	PCI Configuration Data 2 Register
0xD1DC	32	PCICDATA3	PCI Configuration Data 3 Register
0xD200	64	PDMCA	PDMAC Chain Address Register
0xD208	64	PDMGA	PDMAC G-Bus Address Register
0xD210	64	PDMPA	PDMAC PCI Bus Address Register
0xD218	64	PDMCTR	PDMAC Count Register
0xD220	64	PDMCFG	PDMAC Configuration Register
0xD228	64	PDMSTATUS	PDMAC Status Register
Configuration			
0xE000	64	CCFG	Chip Configuration Register
0xE008	64	REVID	Chip Revision ID Register
0xE010	64	PCFG	Pin Configuration Register
0xE018	64	TOEA	Timeout Error Access Address Register
0xE020	64	CLKCTR	Clock Control Register
0xE030	64	GARBC	G-Bus Arbiter Control Register
0xE048	64	RAMP	Register Address Mapping Register
Timer (Channel 0)			
0xF000	32	TMTCR0	Timer Control Register 0
0xF004	32	TMTISR0	Timer Interrupt Status Register 0
0xF008	32	TMCPR0A0	Compare Address Register A 0
0xF00C	32	TMCPR0B0	Compare Address Register B 0
0xF010	32	TMITMR0	Interval Timer Mode Register 0
0xF020	32	TMCCDR0	Divider Register 0
0xF030	32	TMPGMR0	Plus Generator Mode Register 0
0xF0F0	32	TMTRR0	Timer Read Register 0
Timer (Channel 1)			
0xF100	32	TMTCR1	Timer Control Register 1
0xF104	32	TMTISR1	Timer Interrupt Status Register 1
0xF108	32	TMCPR1A1	Compare Address Register A 1
0xF10C	32	TMCPR1B1	Compare Address Register B 1
0xF110	32	TMITMR1	Interval Timer Mode Register 1
0xF120	32	TMCCDR1	Divider Register 1
0xF130	32	TMPGMR1	Plus Generator Mode Register 1
0xF1F0	32	TMTRR1	Timer Read Register 1
Timer (Channel 2)			
0xF200	32	TMTCR2	Timer Control Register 2
0xF204	32	TMTISR2	Timer Interrupt Status Register 2
0xF208	32	TMCPR2A2	Compare Register A 2
0xF210	32	TMITMR2	Interval Timer Mode Register 2
0xF220	32	TMCCDR2	Divider Register 2
0xF240	32	TMWTMR2	Watch Dog Timer Register 2
0xF2F0	32	TMTRR2	Timer Read Register 2

Table 4.2.3 Internal Registers (4/5)

Offset Address	Register Size (bit)	Register Symbol	Register Name
Serial I/O (Channel 0)			
0xF300	32	SILCR0	Line Control Register 0
0xF304	32	SIDICR0	DMA/Interrupt Control Register 0
0xF308	32	SIDISR0	DMA/ Interrupt Status Register 0
0xF30C	32	SISCISR0	Status Change Interrupt Status Register 0
0xF310	32	SIFCR0	FIFO Control Register 0
0xF314	32	SIFLCR0	Flow Control Register 0
0xF318	32	SIBGR0	Baud Rate Control Register 0
0xF31C	32	SITFIFO0	Transmitter FIFO Register 0
0xF320	32	SIRFIFO0	Receiver FIFO Register 0
Serial I/O (Channel 1)			
0xF400	32	SILCR1	Line Control Register 1
0xF404	32	SIDICR1	DMA/Interrupt Control Register 1
0xF408	32	SIDISR1	DMA/ Interrupt Status Register 1
0xF40C	32	SISCISR1	Status Change Interrupt Status Register 1
0xF410	32	SIFCR1	FIFO Control Register 1
0xF414	32	SIFLCR1	Flow Control Register 1
0xF418	32	SIBGR1	Baud Rate Control Register 1
0xF41C	32	SITFIFO1	Transmitter FIFO Register 1
0xF420	32	SIRFIFO1	Receiver FIFO Register 1
Parallel I/O (PIO)			
0xF500	32	PIODO	Output Data Register
0xF504	32	PIODI	Input Data Register
0xF508	32	PIODIR	Direction Control Register
0xF50C	32	PIOOD	Open Drain Control Register
Interrupt Controller (IRC)			
0xF510	32	IRFLAG0	Interrupt Request Flag 0 Register
0xF514	32	IRFLAG1	Interrupt Request Flag 1 Register
0xF518	32	IRPOL	Interrupt Request Polarity Control Register
0xF51C	32	IRRCNT	Interrupt Request Control Register
0xF520	32	IRMASKINT	Internal Interrupt Mask Register
0xF524	32	IRMASKEXT	External Interrupt Mask Register
0xF600	32	IRDEN	Interrupt Detection Enable Register
0xF604	32	IRDM0	Interrupt Detection Mode Register 0
0xF608	32	IRDM1	Interrupt Detection Mode Register 1
0xF610	32	IRLVL0	Interrupt Level Register 0
0xF614	32	IRLVL1	Interrupt Level Register 1
0xF618	32	IRLVL2	Interrupt Level Register 2
0xF61C	32	IRLVL3	Interrupt Level Register 3
0xF620	32	IRLVL4	Interrupt Level Register 4
0xF624	32	IRLVL5	Interrupt Level Register 5
0xF628	32	IRLVL6	Interrupt Level Register 6
0xF62C	32	IRLVL7	Interrupt Level Register 7
0xF640	32	IRMSK	Interrupt Mask Level Register
0xF660	32	IREDC	Interrupt Edge Detection Clear Register
0xF680	32	IRPND	Interrupt Pending Register
0xF6A0	32	IRCS	Interrupt Current Status Register

Table 4.2.3 Internal Registers (5/5)

Offset Address	Register Size (bit)	Register Symbol	Register Name
AC-link Controller (ACLC)			
0xF700	32	ACCTLEN	ACLC Control Enable Register
0xF704	32	ACCTLDIS	ACLC Control Disable Register
0xF708	32	ACREGACC	ACLC CODEC Register Access Register
0xF710	32	ACINTSTS	ACLC Interrupt Status Register
0xF714	32	ACINTMSTS	ACLC Interrupt Masked Status Register
0xF718	32	ACINTEN	ACLC Interrupt Enable Register
0xF71C	32	ACINTDIS	ACLC Interrupt Disable Register
0xF720	32	ACSEMAPH	ACLC Semaphore Register
0xF740	32	ACGPIDAT	ACLC GPI Data Register
0xF744	32	ACGPODAT	ACLC GPO Data Register
0xF748	32	ACSLTEN	ACLC Slot Enable Register
0xF74C	32	ACSLTDIS	ACLC Slot Disable Register
0xF750	32	ACFIFOSTS	ACLC FIFO Status Register
0xF780	32	ACDMASTS	ACLC DMA Request Status Register
0xF784	32	ACDMASEL	ACLC DMA Channel Selection Register
0xF7A0	32	ACAUDODAT	ACLC Audio PCM Output Data Register
0xF7A4	32	ACSURRDAT	ACLC Surround Data Register
0xF7A8	32	ACCENTDAT	ACLC Center Data register
0xF7AC	32	ACLFEDAT	ACLC LFE Data Register
0xF7B0	32	ACAUDIDAT	ACLC Audio PCM Input Data Register
0xF7B8	32	ACMODODAT	ACLC Modem Output Data Register
0xF7BC	32	ACMODIDAT	ACLC Modem Input Data Register
0xF7FC	32	ACREVID	ACLC Revision ID Register

5. Configuration Registers

5.1 Detailed Description

The configuration registers set up and control the basic functionality of the entire TX4927. Refer to Section 5.2 for details of each configuration register. Also refer to sections mentioned in the description about each bit field.

5.1.1 Detecting G-Bus Timeout

The G-bus is an internal bus of the TX4927. Access to each address on the G-Bus is completed upon a bus response from the accessed address. If an attempt is made to access an undefined physical address or if a hardware failure occurs, no bus response is made. If a bus response does not occur, the bus access will not be completed, leading to a system halt. To solve this problem, the TX4927 is provided with a G-Bus timeout detection function. This function forcibly stops bus access if no bus response occurs within the specified time.

Setting the G-Bus Timeout Error Detection bit (CCFG.TOE) of the chip configuration register enables the G-Bus timeout detection function. If a bus response does not occur within the G-Bus clock (GBUSCLK) cycle specified in the G-Bus Timeout Time field (CCFG.GTOT), the G-Bus timeout detection function makes an error response to force the bus access to end. The accessed address is stored to the timeout error access address register (TOEA).

If a timeout error is detected while the TX49/H2 core, as the bus master, is gaining write access to the G-Bus, the Write-Access Bus Error bit (CCFG.BEOW) is set. Enabling interrupt No. 1 in the interrupt controller makes it possible to post an interrupt to the TX49/H2 core. If a timeout error is detected while the TX49/H2 core is gaining read access to the bus, a bus error exception occurs in the TX49/H2 core.

If a timeout error is detected while another G-Bus master (the PCI controller or DMA controller) is accessing the G-Bus, an error bit in that controller is set, which can be used to post an interrupt. Refer to the descriptions of each controller for details.

If the TRST* signal is deasserted, it is assumed that an EJTAG probe is connected, so the G-Bus timeout detection feature is disabled.

5.2 Registers

Table 5.2.1 lists the configuration registers.

Table 5.2.1 Configuration Register Mapping

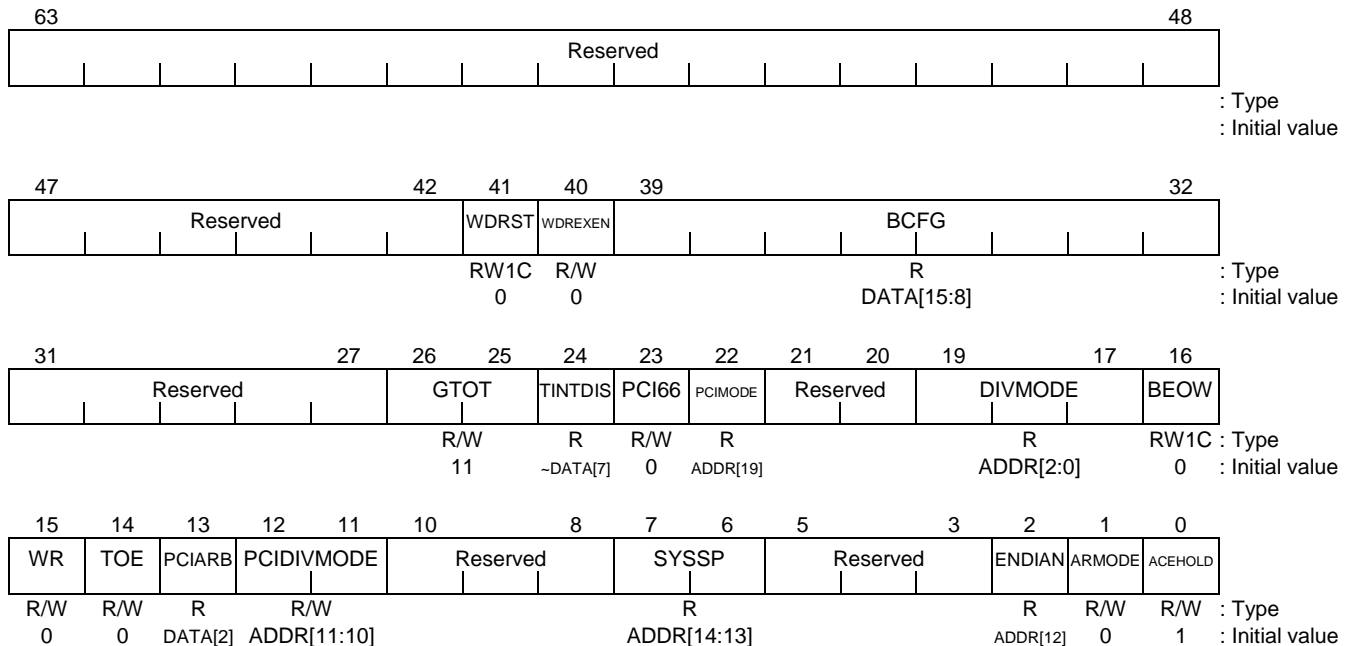
Offset Address	Size in Bits	Register Symbol	Register Name
0xE000	64	CCFG	Chip Configuration Register
0xE008	64	REVID	Chip Revision ID Register
0xE010	64	PCFG	Pin Configuration Register
0xE018	64	TOEA	Timeout Error Access Address Register
0xE020	64	CLKCTR	Clock Control Register
0xE030	64	GARBC	G-Bus Arbiter Control Register
0xE048	64	RAMP	Register Address Mapping Register

Any address not defined in this table is reserved for future use.

5.2.1 Chip Configuration Register (CCFG)

0xE000

For the bit fields whose initial values are set by boot configuration (refer to Section 3.2), the initial input signal level and the corresponding register value are indicated.



Bit	Mnemonic	Field Name	Description	Initial Value	Read/Write
63:42	—	Reserved	—	—	—
41	WDRST	Watchdog Reset Status	Watch Dog Reset Status (Initial Value 0, RW1C) Indicates that a watchdog reset has occurred (refer to Section 12.3.6). Initialized when CGRESET* is asserted. 0 = No watchdog reset has occurred. 1 = A watchdog reset has occurred	0	RW1C
40	WDRSTEN	Watchdog Reset External Output	Watch Dog Reset External Enable (Initial Value 0, R/W) Specifies whether to assert the WDRST* signal at a watchdog reset (refer to Section 12.3.6). Initialized when CGRESET* is asserted. 0 = Do not assert the WDRST* signal. 1 = Assert the WDRST* signal.	0	R/W
39:32	BCFG	Boot Configuration	Set to 1 at a reset if the corresponding DATA[15:8] signal is high. Set to 0 at a reset if the corresponding DATA[15:8] signal is low.	DATA[15:8]	R
31:27	—	Reserved	—	—	—
26:25	GTOT	G-Bus Timeout Time	Specifies the number of G-Bus clock (GBUSCLK) cycles after which a bus timeout error will occur on the internal bus (G-Bus) of the TX4927. 11 = 4096 GBUSCLK 10 = 2048 GBUSCLK 01 = 1024 GBUSCLK 00 = 512 GBUSCLK	11	R/W
24	TINTDIS	Disable TX49/H2 Core Timer Interrupt	Indicates a value for indicating whether to enable the TX49/H2 internal timer interrupt (refer to Section 15.3.5). H: 0: The TX49/H2 internal timer interrupt is enabled. L: 1: The TX49/H2 internal timer interrupt is disabled.	~DATA[7]	R

Figure 5.2.1 Chip Configuration Register (1/3)

Bit	Mnemonic	Field Name	Description	Initial Value	Read/Write
23	PCI66	PCI 66MHz Mode	Used to inform the device connected to the PCI bus that a 66 MHz operation is to be performed. This bit is valid only when the PCI controller of the TX4927 is in host mode. (Refer to Section 10.3.8.) 0 = Do not perform a 66 MHz operation. 1 = Perform a 66 MHz operation.	0	R/W
22	PCIMODE	PCI Operation Mode	Indicates information about the operation mode of the TX4927 PCI controller. (Refer to Section 10.3.1.) L: 0: Satellite mode H: 1: Host mode	ADDR[19]	R
21:20	—	Reserved	—	—	—
19:17	DIVMODE	CPUCLK Frequency Multiplication Factor	Indicates information about the frequency multiplication factor of the TX49/H2 core clock (CPUCLK) to the MASTERCLK. This field is set with a result of encoding an initial input value at ADDR[2:0]. The PLL incorporated in the TX4927 multiplies the MASTERCLK and supplies the resulting frequency to the TX49/H2 core. DIVMODE[1:0] The value set in DIVMODE[1:0] is reflected in the EC field of the TX49/H2 core Config register. HHH: 100: CPUCLK frequency = 2 × MASTERCLK frequency HLH: 101: CPUCLK frequency = 3 × MASTERCLK frequency HLL: 110: CPUCLK frequency = 4 × MASTERCLK frequency HHL: 111: CPUCLK frequency = 2.5 × MASTERCLK frequency LHH: 000: CPUCLK frequency = 8 × MASTERCLK frequency LLH: 001: CPUCLK frequency = 12 × MASTERCLK frequency LLL: 010: CPUCLK frequency = 16 × MASTERCLK frequency LHL: 011: CPUCLK frequency = 10 × MASTERCLK frequency	ADDR[2:0]	R
16	BEOW	Write-Access Bus Error	Indicates that a timeout error has occurred in the internal bus (G-Bus) during a write bus transaction of the TX49/H2 core. This bit corresponds to interrupt No. 1 in the interrupt controller. 0 = No error has occurred. 1 = An error has occurred.	0	RW1C
15	WR	Watchdog Timer Mode	Specifies how information will be reported in watchdog timer mode (refer to Section 12.3.6). 0 = Generate an NMI exception. 1 = Generate a watchdog reset.	0	R/W
14	TOE	G-Bus Timeout Error Detection	Specifies whether to detect and report a bus timeout error in the internal bus (G-Bus) of the TX4927. 0 = Do not detect or report a bus timeout error. 1 = Detect and report a bus timeout error.	0	R/W
13	PCIARB	PCI Arbiter Selection	Indicates the PCI bus arbiter selection setting (refer to Section 10.3.12). L: 0 = External PCI bus arbiter H: 1 = Built-in PCI bus arbiter	DATA[2]	R
12:11	PCIDIVMODE	PCICLK Frequency Division Ratio	Specifies the frequency division ratio of the PCI bus clock output (PCICLK[5:0]) frequency to the clock frequency (CPUCLK) of the TX49/H2 core. LL: 00: PCICLK frequency = CPUCLK frequency ÷ 2.5 LH: 01: PCICLK frequency = CPUCLK frequency ÷ 3 HL: 10: PCICLK frequency = CPUCLK frequency ÷ 5 HH: 11: PCICLK frequency = CPUCLK frequency ÷ 6	ADDR[11:10]	R/W
10:8	—	Reserved	—	—	—
7:6	SYSSP	SYSClk frequency division ratio	Indicates the frequency division ratio of the SYSClk frequency to the G-Bus clock frequency (GBUSCLK). LL: 00: SYSClk frequency = GBUSCLK frequency ÷ 4 LH: 01: SYSClk frequency = GBUSCLK frequency ÷ 3 HL: 10: SYSClk frequency = GBUSCLK frequency ÷ 2 HH: 11: SYSClk frequency = GBUSCLK frequency	ADDR[14:13]	R
5:3	—	Reserved	—	—	—

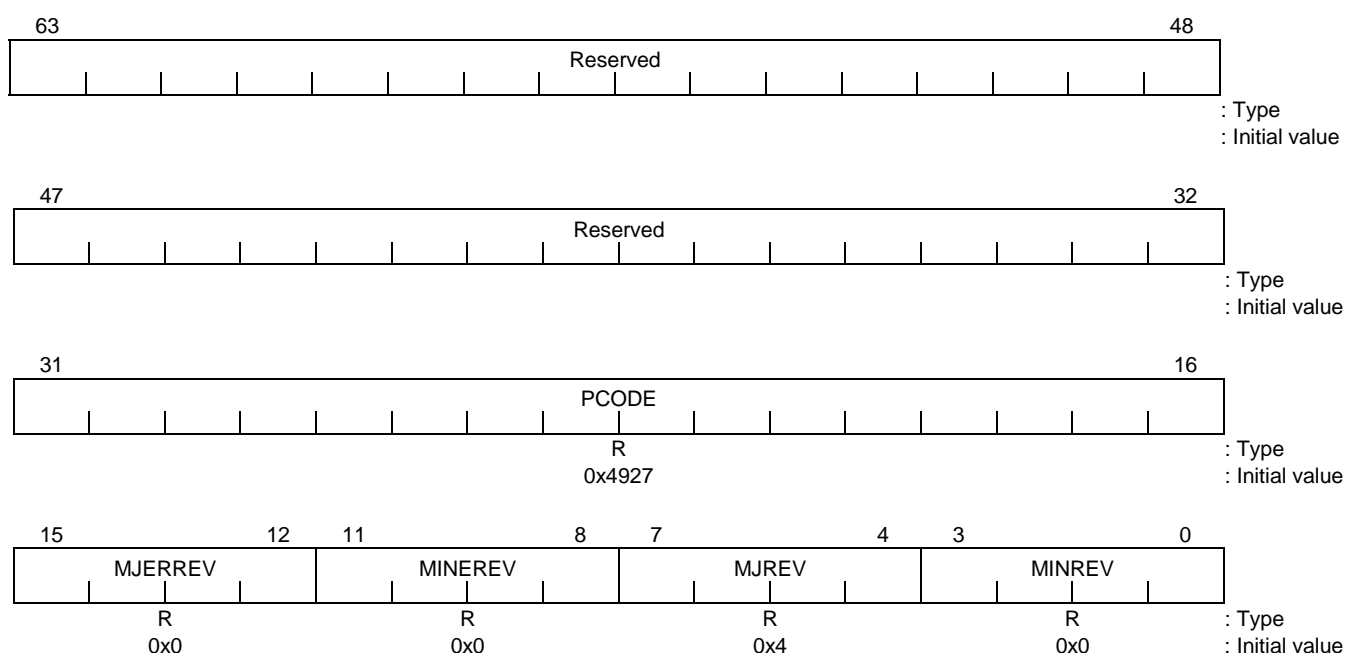
Figure 5.2.1 Chip Configuration Register (2/3)

Bit	Mnemonic	Field Name	Description	Initial Value	Read/Write
2	ENDIAN	Endian	Indicates the TX4927 endian mode setting. L: 0 = Little endian mode H: 1 = Big endian mode	ADDR[12]	R
1	ARMODE	ACK*/READY Mode	Selects an ACK*/READY signal operation mode for the external bus controller (refer to Section 7.3.6). 0 = ACK*/READY dynamic mode 1 = ACK*/READY static mode	0	R/W
0	ACEHOLD	ACE Hold	Specifies the hold time of an address relative to the external bus controller ACE* signal (refer to Section 7.3.4). 0 = Switch the address at the same time when the ACE* signal is deasserted. 1 = Switch the address one clock cycle after the ACE* signal is deasserted.	1	R/W

Figure 5.2.1 Chip Configuration Register (3/3)

5.2.2 Chip Revision ID Register (REVID)

0xE008

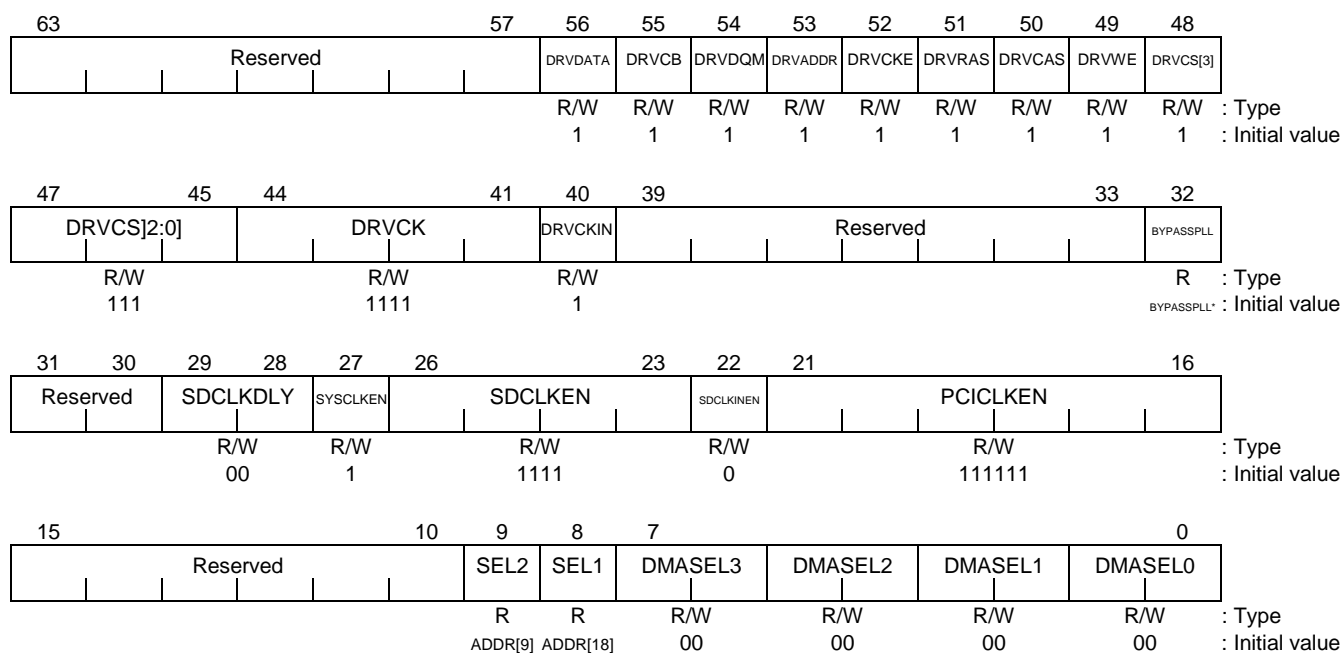


Bit	Mnemonic	Field Name	Description	Initial Value	Read/Write
63:32	—	Reserved	—	—	—
31:16	PCODE	Product Code	Indicates the product number. It is a fixed value.	0x4927	R
15:12	MJERREV	Major Extra Code	Indicates the major extra code.	0x0	R
11:8	MINEREV	Major Extra Code	Indicates the minor extra code.	0x0	R
7:4	MJREV	Major Revision Code	Indicates the major revision of the product. Contact Toshiba technical staff for the latest information.	0x4	R
3:0	MINREV	Minor Revision Code	Indicates the minor revision of the product. Contact Toshiba technical staff for the latest information.	0x0	R

Figure 5.2.2 Chip Revision ID Register

0xE010

For the bit fields whose initial values are set by boot configuration (refer to Section 3.2), the initial input signal level and the corresponding register value are indicated.



Bit	Mnemonic	Field Name	Description	Initial Value	Read/Write
63:57	—	Reserved	—	—	—
56	DRVDATA	DATA Signal Control	Specifies the driving capability of the DATA[63:0] signals. 0 = 8 mA 1 = 16 mA	1	R/W
55	DRVCB	CB Signal Control	Specifies the driving capability of the CB[7:0]* signals. 0 = 8 mA 1 = 16 mA	1	R/W
54	DRVDQM	DQM Signal Control	Specifies the driving capability of the DQM[7:0]* signals. 0 = 8 mA 1 = 16 mA	1	R/W
53	DRVADDR	ADDR Signal Control	Specifies the driving capability of the ADDR[19:0] signals. 0 = 8 mA 1 = 16 mA	1	R/W
52	DRVCKE	CKE Signal Control	Specifies the driving capability of the CKE signal. 0 = 8 mA 1 = 16 mA	1	R/W
51	DRVRAS	RAS Signal Control	Specifies the driving capability of the RAS* signal. 0 = 8 mA 1 = 16 mA	1	R/W
50	DRVCAS	CAS Signal Control	Specifies the driving capability of the CAS* signal. 0 = 8 mA 1 = 16 mA	1	R/W
49	DRVWE	WE Signal Control	Specifies the driving capability of the WE* signal. 0 = 8 mA 1 = 16 mA	1	R/W

Figure 5.2.3 Pin Configuration Register (1/3)

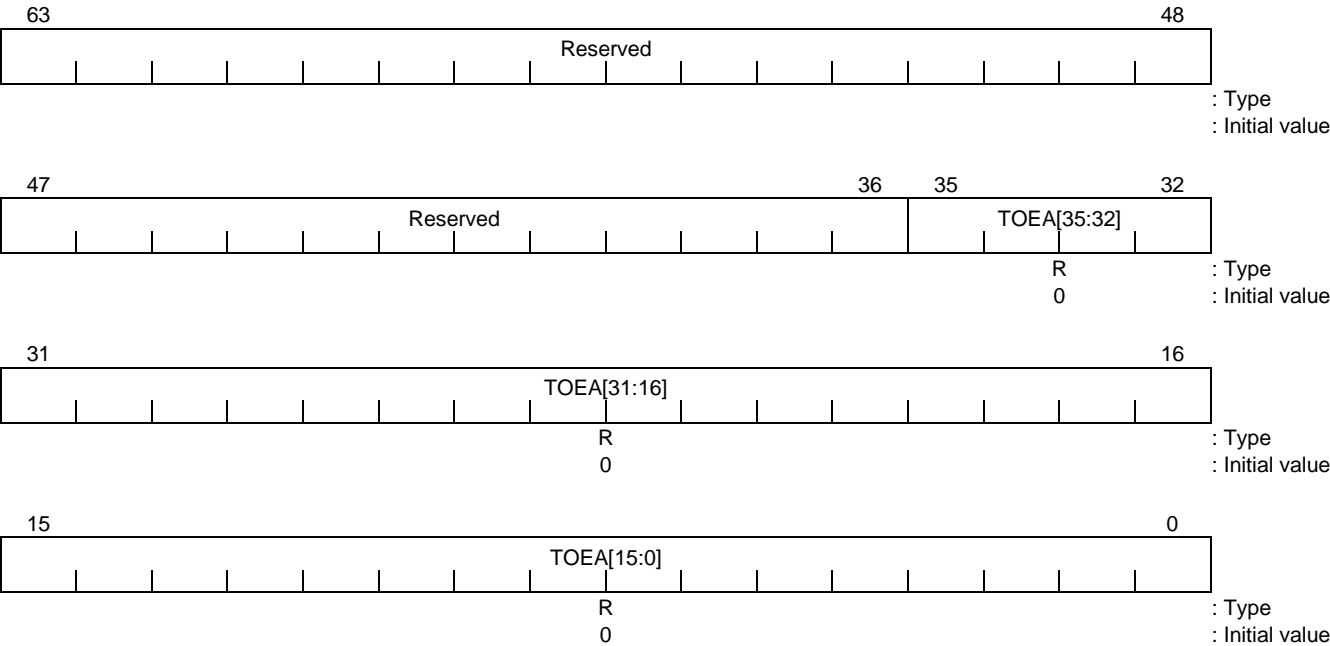
Bit	Mnemonic	Field Name	Description	Initial Value	Read/Write
48:45	DRVCS[3:0]	SDRAM CS Signal Control	Specifies the driving capability of the SDSC[3:0]* signals. 0 = 8 mA 1 = 16 mA	1111	R/W
44:41	DRVCK[3:0]	SDRAM SDCLK Signal Control	Specifies the driving capability of the SDCLK[3:0] signals. 0 = 8 mA 1 = 16 mA	1111	R/W
40	DRVCKIN	SDRAM SDCLKIN Signal Control	Specifies the driving capability of the SDCLKIN signal. 0 = 8 mA 1 = 16 mA	1	R/W
39:33	—	Reserved	—	—	—
32	BYPASS PLL	Bypass PLL	Indicates information about whether a PLL for a circuit other than the PCI controller is on or off. L: 0 = The PLL is off. H: 1 = The PLL is on.	BYPASSPLL*	R
31:30	—	Reserved	—	—	—
29:28	SDCLKDLY	SDCLK Feedback Delay	Specifies the feedback delay for the SDCLK. This function is for diagnosis purposes. Usually, set the bits to 00. 00 = Delay 1 (minimum delay) 10 = Delay 2 01 = Delay 3 11 = Delay 4 (maximum delay)	00	R/W
27	SYSCLKEN	SYSCLK Enable	Specifies whether to output the SYSCLK. 1 = Clock output 0 = H	1	R/W
26:23	SDCLKEN [3:0]	SDCLK Enable	Individually specifies whether to output each of SDCLK[3:0]. 1 = Clock output 0 = H Bit 26 = SDCLK[3] Bit 25 = SDCLK[2] Bit 24 = SDCLK[1] Bit 23 = SDCLK[0]	1111	R/W
22	SDCLKINEN	SDCLKIN Enable	Specifies how SDCLK[3:0] should be fed back. This function is for diagnosis purposes. Usually, set this bit to 0. 0 = Use the SDCLKIN signal as a feedback clock. 1 = Perform feedback within the TX4927 (the SDCLKIN becomes an output signal).	0	R/W
21:16	PCICLKEN [5:0]	PCICLK Enable	Individually specifies whether to output each of PCICLK[5:0]. 1 = Clock output 0 = H Bit 21 = PCICLK[5] Bit 20 = PCICLK[4] Bit 19 = PCICLK[3] Bit 18 = PCICLK[2] Bit 17 = PCICLK[1] Bit 16 = PCICLK[0]	111111	R/W
15:10	—	Reserved	—	—	—
9	SEL2	Shared-Pin Status 2	DMAREQ[2], DMAACK[2], and PIO[4:2] share pins with the AC-link interface signals. Indicates which function the shared pins are set to. L: 0 = The shared pins are set to DMAREQ[2], DMAACK[2], and PIO[4:2]. H: 1 = The shared pins are set to the AC-link interface signals.	ADDR[9]	R
8	SEL1	Shared-Pin Status 1	Indicates which function, PIO[15:8] or CB[7:0], the shared pins are set to. L: 0 = The shared pins are set to PIO[15:8]. H: 1 = The shared pins are set to CB[7:0].	ADDR[18]	R

Figure 5.2.3 Pin Configuration Register (2/3)

Bit	Mnemonic	Field Name	Description	Initial Value	Read/Write
7:6	DMASEL3	DMA Request Select 3	Selects a DMA request used by DMA controller channel 3. 00: DMAREQ[3] (external) 01: SIO channel 0 transmission (internal) 10: ACLC channel 3 (internal) 11: ACLC channel 1 (internal)	00	R/W
5:4	DMASEL2	DMA Request Select 2	Selects a DMA request used by DMA controller channel 2. If PCFG.SEL2 = 0 00: DMAREQ[2] (external) 01: SIO channel 0 reception (internal) 10: Reserved 11: Reserved If PCFG.SEL2 = 1 00: ACLC channel 1 (internal) 01: SIO channel 0 reception (internal) 10: ACLC channel 2 (internal) 11: ACLC channel 0 (internal)	00	R/W
3:2	DMASEL1	DMA Request Select 1	Selects a DMA request used by DMA controller channel 1. 00: DMAREQ[1] (external) 01: SIO channel 1 transmission (internal) 10: ACLC channel 1 (internal) 11: ACLC channel 3 (internal)	00	R/W
1:0	DMASEL0	DMA Request Select 0	Selects a DMA request used by DMA controller channel 0. 00: DMAREQ[0] (external) 01: SIO channel 1 reception (internal) 10: ACLC channel 0 (internal) 11: ACLC channel 2 (internal)	00	R/W

Figure 5.2.3 Pin Configuration Register (3/3)

5.2.4 Timeout Error Access Address Register (TOEA) 0xE018



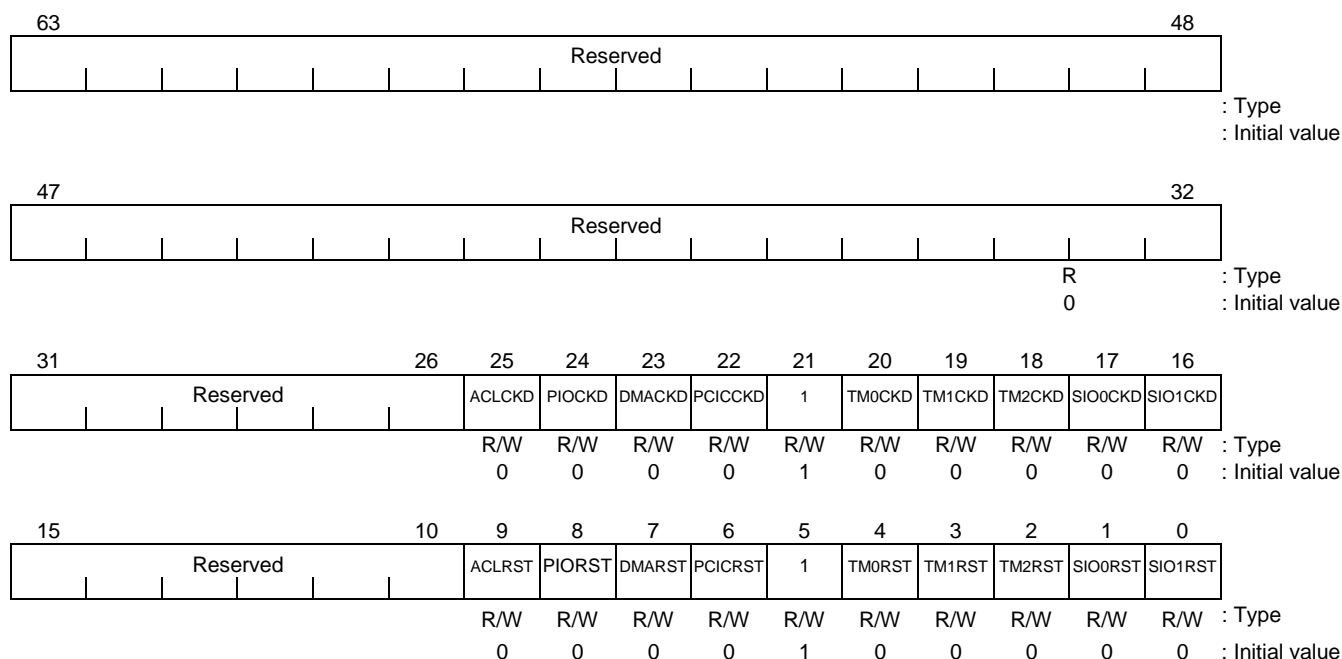
Bit	Mnemonic	Field Name	Description	Initial Value	Read/Write
63:36	—	Reserved	—	—	—
35:0	TOEA	Timeout Error Access Address	Holds the G-Bus address for the G-Bus cycle in which the latest G-Bus timeout error was detected.	0x0_0000_0000	R

Figure 5.2.4 Timeout Error Access Address Register

5.2.5 Clock Control Register (CLKCTR)

0xE020

For the low-order 16 bits of the clock control register, canceling a reset requires that the corresponding reset bit be cleared by software. Before clearing them, wait at least 128 CPU clock cycles after they are set.



Bit	Mnemonic	Field Name	Description	Initial Value	Read/Write
63:26	—	Reserved	—	—	—
25	ACLCKD	ACLK Clock Disable	Controls clock pulses for the AC-link controller. 0 = Supply clock pulses. 1 = Do not supply clock pulses.	0	R/W
24	PIOCKD	PIO Clock Disable	Controls clock pulses for the parallel IO controller. 0 = Supply clock pulses. 1 = Do not supply clock pulses.	0	R/W
23	DMACKD	DMAC Clock Disable	Controls clock pulses for the DMA controller. 0 = Supply clock pulses. 1 = Do not supply clock pulses.	0	R/W
22	PCICKD	PCIC Clock Disable	Controls clock pulses for the PCI controller. 0 = Supply clock pulses. 1 = Do not supply clock pulses.	0	R/W
21	—	—	Always set this bit to 1.	1	R/W
20	TM0CKD	Timer 0 Clock Disable	Controls clock pulses for the TMR0 controller. 0 = Supply clock pulses. 1 = Do not supply clock pulses.	0	R/W
19	TM1CKD	Timer 1 Clock Disable	Controls clock pulses for the TMR1 controller. 0 = Supply clock pulses. 1 = Do not supply clock pulses.	0	R/W
18	TM2CKD	Timer 2 Clock Disable	Controls clock pulses for the TMR2 controller. 0 = Supply clock pulses. 1 = Do not supply clock pulses.	0	R/W
17	SIO0CKD	SIO0 Clock Disable	Controls clock pulses for the SIO0 controller. 0 = Supply clock pulses. 1 = Do not supply clock pulses.	0	R/W

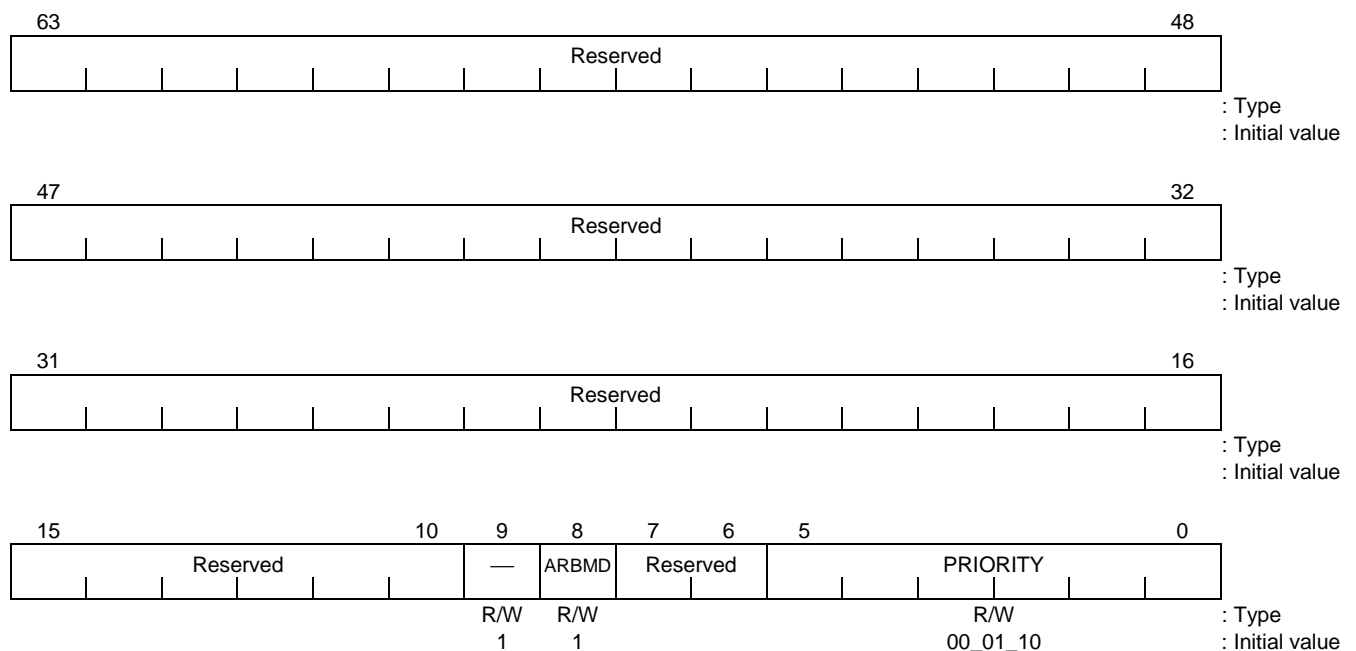
Figure 5.2.5 Clock Control Register (1/2)

Bit	Mnemonic	Field Name	Description	Initial Value	Read/Write
16	SIO1CKD	SIO1 Clock Disable	Controls clock pulses for the SIO1 controller. 0 = Supply clock pulses. 1 = Do not supply clock pulses.	0	R/W
15:10	—	Reserved	—	—	—
9	ACLRST	ACLC Reset	Resets the AC-link controller. 0 = Normal state 1 = Reset	0	R/W
8	PIORST	PIO Reset	Resets the parallel IO controller. 0 = Normal state 1 = Reset	0	R/W
7	DMARST	DMAC Reset	Resets the DMA controller. 0 = Normal state 1 = Reset	0	R/W
6	PCICRST	PCIC Reset	Resets the PCI controller. 0 = Normal state 1 = Reset	0	R/W
5	—	—	Always set this bit to 1.	1	R/W
4	TMR0RST	TMR0 Reset	Resets the TMR0 controller. 0 = Normal state 1 = Reset	0	R/W
3	TMR1RST	TMR1 Reset	Resets the TMR1 controller. 0 = Normal state 1 = Reset	0	R/W
2	TMR2RST	TMR2 Reset	Resets the TMR2 controller. 0 = Normal state 1 = Reset	0	R/W
1	SIO0RST	SIO0 Reset	Resets the SIO0 controller. 0 = Normal state 1 = Reset	0	R/W
0	SIO1RST	SIO1 Reset	Resets the SIO1 controller. 0 = Normal state 1 = Reset	0	R/W

Figure 5.2.5 Clock Control Register (2/2)

5.2.6 G-Bus Arbiter Control Register (GARBC)

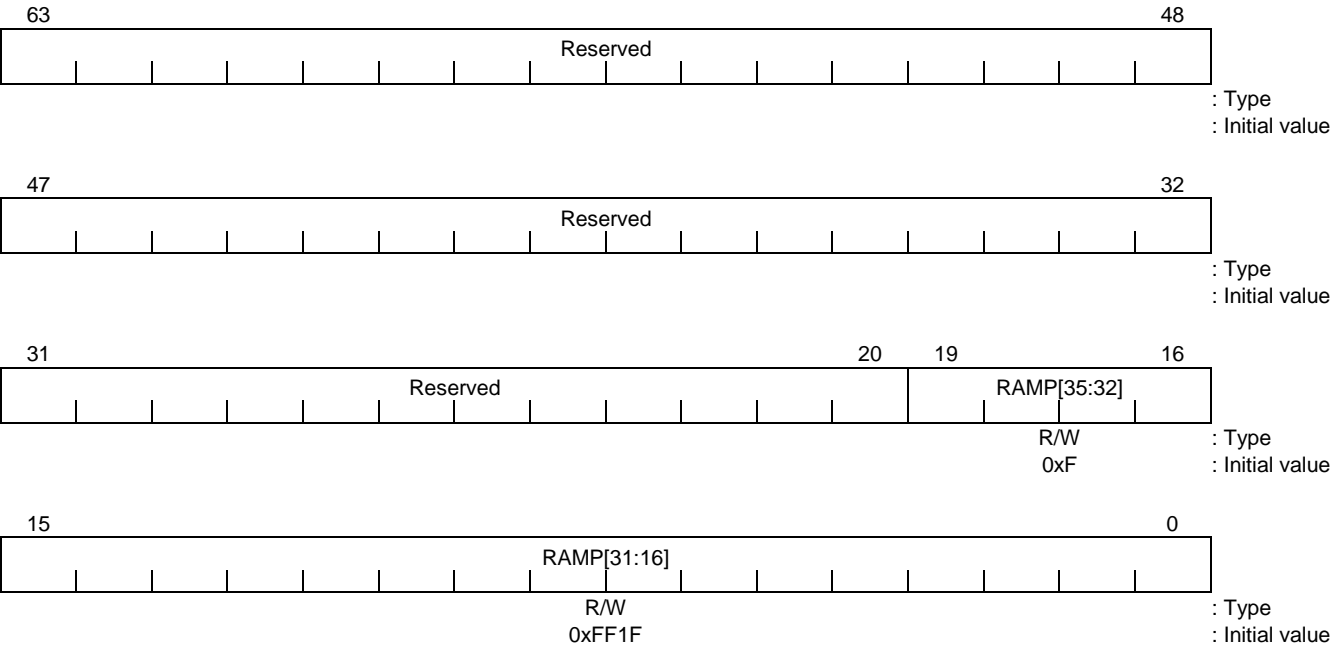
0xE030



Bit	Mnemonic	Field Name	Description	Initial Value	Read/Write
63:10	—	Reserved	—	—	—
9	—	—	Always set this bit to 1. When 0 is set, there is the possibility of a deadlock.	1	R/W
8	ARBMD	Arbitration Mode	Specifies how to prioritize G-Bus arbitration. 0 = Fixed priority. The G-Bus arbitration priority conforms to the content of the PRIORITY field (bits [5:0]). 1 = Round-robin (in a round-robin fashion, PCI controller > PDMAC > DMAC) Note: Before accessing the PCI by DMAC, specify round-robin as the priority mode. If fixed-priority mode is selected, a dead lock is likely to occur in PCI bus access.	1	R/W
7:6	—	Reserved	—	—	—
5:0	PRIORITY	Arbitration Priority	Specifies the priority when ARBMD (bit [8]) specifies fixed-priority mode. [5:4] = Bus master with the highest priority [3:2] = Bus master with the second highest priority [1:0] = Bus master with the third highest priority 00 = PCI controller 01 = PDMAC 10 = DMAC A priority of PCI controller > PDMAC > DMAC is initially set up.	00_01_10	R/W

Figure 5.2.6 G-Bus Arbiter Control Register

5.2.7 Register Address Mapping Register (RAMP) 0xE048



Bit	Mnemonic	Field Name	Description	Initial Value	Read/Write
63:20	—	Reserved	—	—	—
19:0	RAMP[35:16]	Register Address Mapping	This is a base address register for the TX4927 built-in registers. It holds the high-order 20 bits of a register address. The default built-in register base address is 0xF_FF1F_0000. Even after the content of the base address register is changed, the default value can be used to reference the built-in registers. (Refer to "4.2 Register Mapping".)	0xF_FF1F	R/W

Figure 5.2.7 Register Address Mapping Register

6. Clocks

6.1 TX4927 Clock Signals

Figure 6.1.1 shows the configuration of TX4927 blocks and clock signals. Table 6.1.1 describes each clock signal. Table 6.1.2 shows the relationship among different clock signals when the CPU clock frequency is 200 MHz or 166.7 MHz.

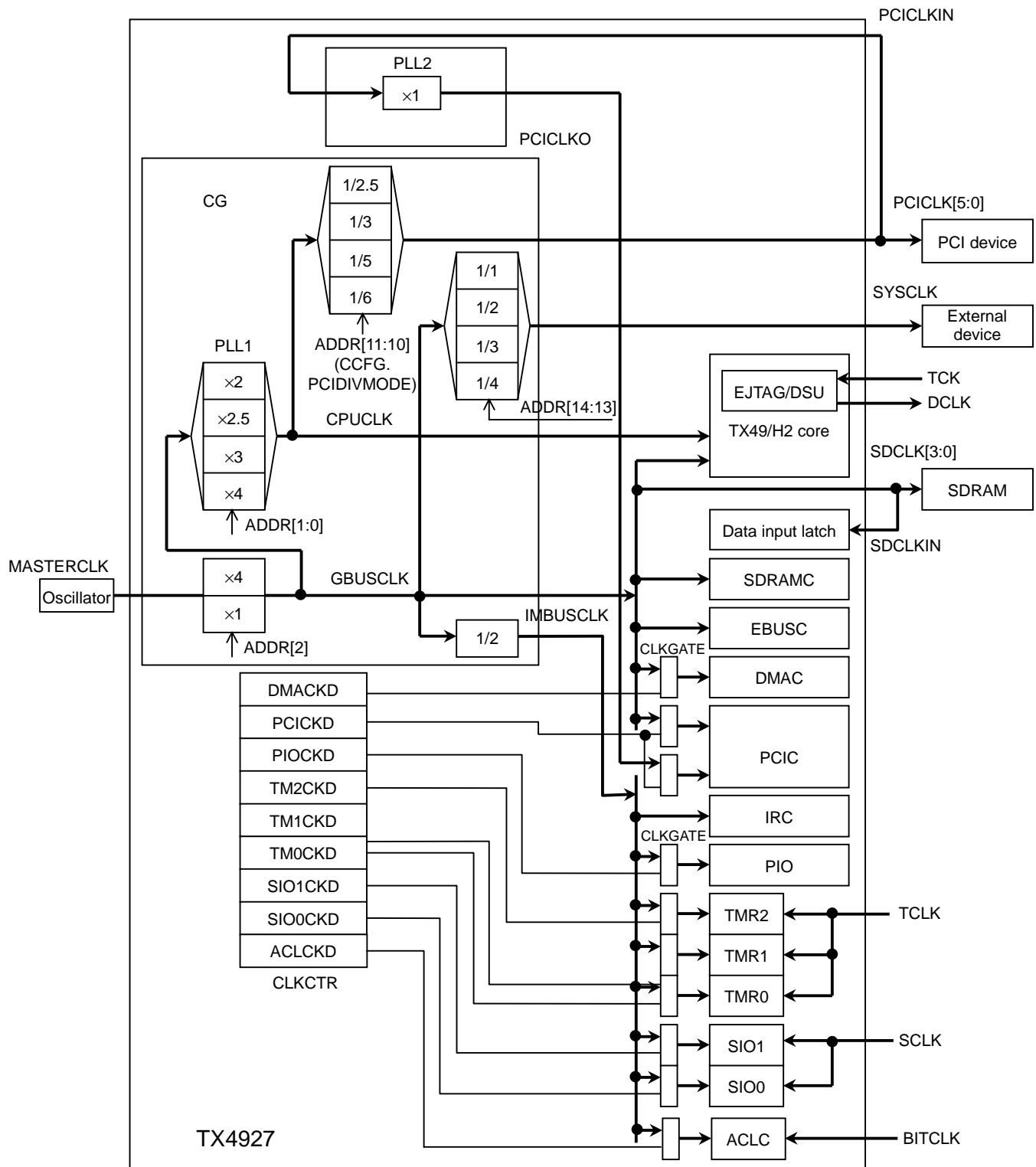


Figure 6.1.1 TX4927 Block and Clock Configuration

Table 6.1.1 TX4927 Clock Signals (1/2)

Clock	Input/Output	Description	Related Configuration Signals (Refer to Section 3.2.)	Related Registers (Refer to Chapters 5 and 10.)
MASTERCLK	Input	Master input clock for the TX4927. The TX4927 internal clock generator multiplies or divides MASTERCLK to generate internal clock pulses.	—	—
CPUCLK	Internal signal	Clock supplied to the TX49/H2 core. PLL1 in the TX4927 generates CPUCLK by multiplying MASTERCLK. Boot configuration signals ADDR[2:0] can set the frequency ratio of CPUCLK to MASTERCLK. ADDR[2:0] HHH = 2 times MASTERCLK HHL = 2.5 times MASTERCLK HLH = 3 times MASTERCLK HLL = 4 times MASTERCLK LHH = 8 times MASTERCLK LHL = 10 times MASTERCLK LLH = 12 times MASTERCLK LLL = 16 times MASTERCLK	ADDR[2:0]	CCFG.DIVMODE[2:0]
GBUSCLK	Internal signal	Clock supplied to peripheral blocks on the G-Bus. PLL1 in the TX4927 generates GBUSCLK by multiplying MASTERCLK. Boot configuration signal ADDR[2] can set the multiplier value. ADDR[2] L = 4 times MASTERCLK H = 1 times MASTERCLK	ADDR[2]	CCFG.DIVMODE[2]
IMBUSCLK	Internal signal	Clock supplied to peripheral modules on the IM-Bus. The frequency of IMBUSCLK is half that of GBUSCLK.	—	—
SYSCLK	Output	System clock output from the TX4927. Used by the devices connected to the external bus controller (EBUSC). Boot configuration signals ADDR[14:13] can set the frequency ratio of SYSCLK to GBUSCLK. ADDR[14:13] LL: GBUSCLK divided by 4 LH: GBUSCLK divided by 3 HL: GBUSCLK divided by 2 HH: GBUSCLK divided by 1 The SYSCLKEN bit of the PCFG register can disable the output of SYSCLK. Note: To use SYSCLK to access external devices, the SYSCLK rate must match the EBUSC channel operating rate. For details, refer to Section 7.3.8.	ADDR[14:13]	CCFG.SYSSP PCFG.SYSCLKEN
SDCLK[3:0]	Output	Clock supplied to SDRAM. The frequency of SDCLK[3:0] is the same as that of GBUSCLK. The SDCLKEN[3:0] field of the PCFG register can disable the output of SDCLK[3:0] on a per bit basis.	—	PCFG.DRVCK[3:0] PCFG.SDCLKEN[3:0]
SDCLKIN	Input/output	Reference clock used to latch input data signals from SDRAM. The clock output from SDCLK should be connected to SDCLKIN via a feedback line outside the TX4927.	—	PCFG.DRVCKIN (PCFG.SDCLKDLY) (PCFG.SDCLKINEN)

Table 6.1.1 TX4927 Clock Signals (2/2)

Clock	Input/Output	Description	Related Configuration Signals (Refer to Section 3.2.)	Related Registers (Refer to Chapters 5 and 10.)
PCICLK[5:0]	Output	<p>Clock supplied to devices on the PCI bus.</p> <p>The PCICLKEN bit of the PCFG register can disable the output of PCICLK.</p> <p>The frequency depends on boot configuration signals ADDR[11:10] or the PCIDIVMODE field of the CCFG register.</p> <p>ADDR[11:10] (CCFG_PCIDIVMODE)</p> <p>00: CPUCLK divided by 2.5</p> <p>01: CPUCLK divided by 3</p> <p>10: CPUCLK divided by 5</p> <p>11: CPUCLK divided by 6</p> <p>Note: PCICLK[5:0] can supply clock pulses at 66 or 33 MHz when the CPUCLK frequency is set to 200 or 166.7 MHz.</p>	ADDR[11:10]	CCFG.PCIDIVMODE PCFG.PCICLKEN[5:0]
PCICLKIN	Input	<p>PCI bus clock. The built-in PCI controller of the TX4927 operates with this clock.</p> <p>Note: To achieve an accurate phase match with the external clock, PCICLK[5:0] or the PCI clock output from another PCI device must be supplied to PCICLKIN.</p>	—	—
PCICLK0	Internal signal	<p>Clock supplied to the PCI controller. PCICLK0 is generated by PLL2 based on PCICLKIN.</p> <p>PCICLK0 has the same frequency and phase as those of PCICLKIN (input pin).</p>	—	—
EEPROM_SK	Output	Clock for serial EEPROM used to initially set the PIC configuration.	—	—
SCLK	Input	Input clock for SIO. SCLK is shared by SIO0 and SIO1.	—	—
TCLK	Input	Input clock for timers. TCLK is shared by TMR0, TMR1, and TMR2.	—	—
BITCLK	Input	<p>Input clock for the AC-link controller.</p> <p>The pin is shared with the PIO[2] signal.</p>	ADDR[9]	—
TCK	Input	Input clock for JTAG.	—	—
DCLK	Output	Clock output for the real-time debugging system.	—	—

Table 6.1.2 Relationship Among Different Clock Frequencies

Master Clock (Input) and Boot Configured Settings		Internal Clock			External Clock (Output)								
MASTERCLK (MHz)	Boot Configured Settings ADDR[2:0]	CPUCLK (MHz)	GBUSCLK (MHz)	IMBUSCLK (MHz)	SDCLK [3:0] (MHz)	SYSCLK (MHz)				PCICLK[5:0] (MHz) †			
						Boot Configured Settings ADDR[14:13]				Boot Configured Settings ADDR[11:10]			
						HH (1/1)	HL (1/2)	LH (1/3)	LL (1/4)	HH (1/6)	HL (1/5)	LH (1/3)	LL (1/2.5)
100	HHH (×2.0)	200	100	50	100	100	50	33	25	33	40	66	—
25	LHH (×8.0)												
80	HHL (×2.5)		80	40	80	80	40	26.6	50				
20	LHL (×10.0)												
66	HLH (×3.0)		66	33	66	66	33	22	16.5				
16.7	LLH (×12.0)												
50	HLL (×4.0)		50	25	50	50	25	16.6	12.5				
12.5	LLL (×16.0)												
83	HHH (×2.0)	166.7	83	41.5	83	83	41.5	27.7	20.8	27.8	33	55.5	66
20.8	LHH (×8.0)												
66	HHL (×2.5)		66	33	66	66	33	22	16.5				
16.7	LHL (×10.0)												
55.5	HLH (×3.0)		55.5	27.8	55.5	55.5	27.8	18.5	13.9				
13.9	LLH (×12.0)												
41.6	HLL (×4.0)		41.6	20.8	41.6	41.6	20.8	13.9	10.4				
10.4	LLL (×16.0)												

† The frequency division ratio for PCICLK[5:0] can also be modified by setting the CCFG.PCIDIVMODE field.

6.2 Power-Down Mode

6.2.1 Halt Mode and Doze Mode

The WAIT instruction causes the TX49/H2 core to enter either of the two low-power modes: Halt and Doze. The TX49/H2 can exit from Halt or Doze mode upon an interrupt exception. Ensure, therefore, that the TX49/H2 does not enter Halt or Doze mode when all interrupts are masked in the interrupt controller.

The HALT bit of the TX49/H2 core Config register is used to select Halt or Doze mode. As the TX4927 does not use the snoop function of the TX49/H2 core, the bit should be set to select Halt mode, which achieves greater power reduction than Doze mode.

6.2.2 Power Reduction for Peripheral Modules

When the system does not use the DMA controller, PCI controller, serial I/O controller, timers/counters, parallel I/O controller, or AC-link controller, it can stop the input clock for that module to reduce power dissipation.

The clock control register (CLKCTR) is used to control whether to turn each clock on or off. The module should be reset before its clock can be turned on or off. This reset is performed using the reset bit for the specific module, provided in the clock control register. The reset also initializes the registers of the module, thus requiring subsequent setup of necessary register values and other configurations. Refer to Section 5.2.5, "Clock Control Register" for detail of the clock control register (CLKCTR).

6.3 Power-On Sequence

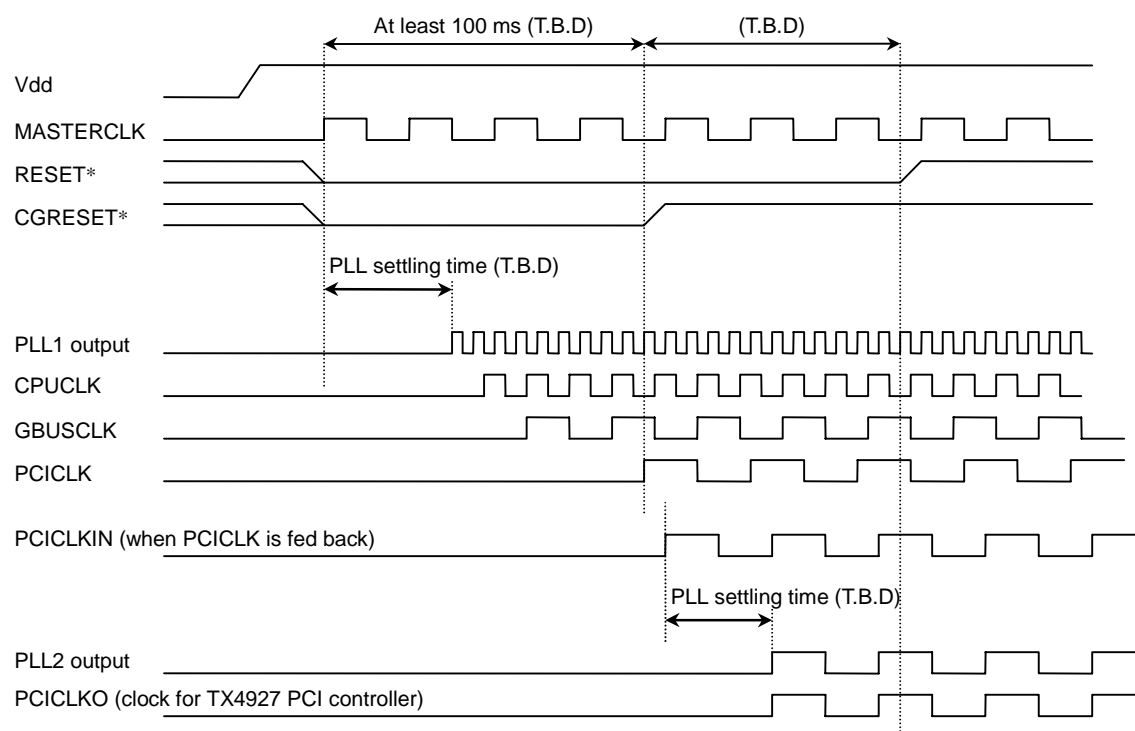


Figure 6.3.1 Power-On Sequence

7. External Bus Controller

7.1 Features

The External Bus Controller is used for accessing ROM, SRAM memory, and I/O peripherals. The features of this bus are described below.

- (1) 8 independent channels
- (2) Supports access to ROM (mask ROM, page mode ROM, EPROM, EEPROM), SRAM, flash memory, and I/O peripherals.
- (3) Selectable data bus width of 8-bit, 16-bit, 32-bit for each channel
- (4) Selectable full-speed, 1/2 speed, 1/3 speed, 1/4 speed for each channel
- (5) Programmable timing for each channel. Programmable setup and hold time of address, chip enable, write enable, and output enable signals.
- (6) Supports memory sizes from 1 MB to 1 GB for devices with a 32-bit data bus. Supports memory sizes from 1 MB to 512 MB for devices with a 16-bit data bus. Supports memory sizes from 1 MB to 256 MB for devices with an 8-bit data bus.
- (7) Supports special DMAC Burst access (address decrement/fixed).
- (8) Supports critical word first access of the TX49/H2 core.
- (9) Supports page mode memory. Supports 4-, 8-, and 16-page size.
- (10) Supports the External Acknowledge Signal (ACK*) and External Ready Signal modes.
- (11) Channel 0 can be used as Boot memory. Boot settings can be made from the following selections:
 - Data bus width: 8-bit, 16-bit, 32-bit
 - ACK* output or ACK* input
 - BWE pin (byte enable or byte Write enable)
 - Boot channel clock frequency

7.2 Block Diagram

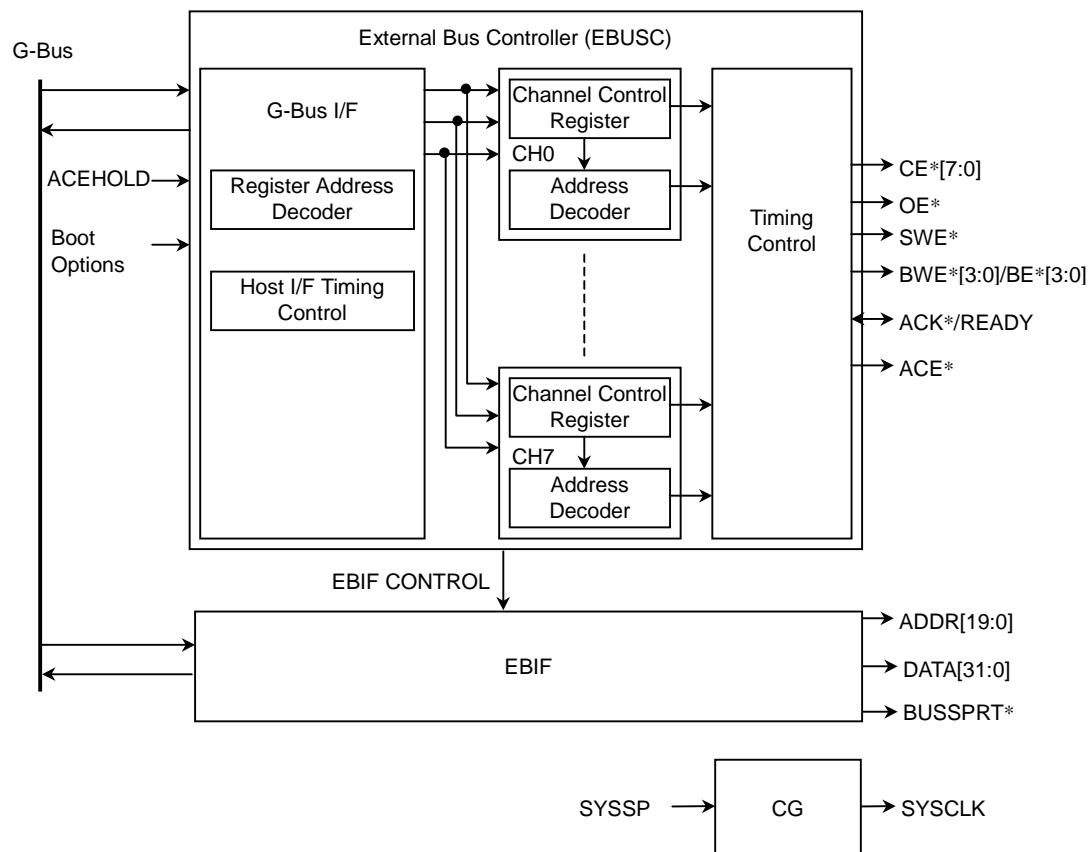


Figure 7.2.1 Block Diagram of External Bus Controller

7.3 Detailed Explanation

7.3.1 External Bus Control Register

The External Bus Controller (EBUSC) has eight channels. This register contains one Channel Control Register (EBCCRn) for each channel, and all settings can be made independently for each channel.

Either Word or Double-word access is possible for a Control Register. However, be sure to make any Enable settings to EBCCRn.ME last when using Word access and dividing register settings into two accesses. If EBCCRn.ME is enabled before setting the base address, then unintended memory access may result.

7.3.2 Global/Boot-up Options

In addition to the settings made separately for each channel, the Channel Control Registers can also use global options that make settings common to all channels.

External Bus Controller Channel 0 can be used as a Boot memory channel. Channel 0 is set by the external pins (Boot pins) during reset.

These settings are summarized below in Table 7.3.1. (Please refer to "3.3: Configuration signals" and "5.1.1: Chip Configuration Register" for more information.)

Table 7.3.1 Global/Boot-up Options

Pin Name	Set Register	Explanation
—	CCFG.ARMODE	Selects the operation mode of the ACK*/READY signal. 0 = ACK*/READY Dynamic mode (Default) 1 = ACK*/READY Static mode
—	CCFG.ACEHOLD	Sets the address hold time relative to the ACE* signal. 0: Address changes simultaneous to deassertion of the ACE* signal. 1: Address changes 1 clock cycle after deassertion of the ACE* signal. (Default)
ADDR[14:13]	CCFG.SYSSP	Specifies the division ratio of the SYSCLK output relative to the internal bus clock (GBUSCLK). 00: 1/4 speed (1/4 the GBUSCLK frequency) 01: 1/3 speed (1/3 the GBUSCLK frequency) 10: 1/2 speed (1/2 the GBUSCLK frequency) 11: Full speed (same frequency as the GBUSCLK frequency)
ADDR[8]	EBCCR0.ME	Specifies whether to enable or disable Channel 0. 0: Disable this channel as a Boot channel. 1: Enable this channel as a Boot channel.
ADDR[7:6]	EBCCR0.SP	Specifies the operation speed of Channel 0. 00: 1/4 Speed mode 01: 1/3 Speed mode 10: 1/2 Speed mode 11: Full Speed mode
DATA[5]	EBCCR0.BC	When accessing Channel 0, specifies whether to use the BWE[3:0] signal as a Byte Enable signal (BE[3:0]) or to use it as a Byte Write Enable signal (BWE[3:0]). 0: Byte Enable mode 1: Byte Write Enable mode
DATA[4]	EBCCR0.WT[0]	Specifies the Channel 0 access mode. 0: Normal mode (DATA[4] = H) 1: External ACK mode (DATA[4] = L)
DATA[1:0]	EBCCR0.BSZ	Specifies the memory bus width of Channel 0. 00: Reserved 01: 32-bit width 10: 16-bit width 11: 8-bit width

7.3.3 Address Mapping

Each of the eight channels can use the Base Address field (EBCCRn.BA[35:20]) and the Channel Size field (EBCCRn.CS[3:0]) of the External Bus Channel Control Register to map to any physical address.

A channel is selected when the following equation becomes True.

$$\text{paddr}[35:20] \& \text{!Mask}[35:20] == \text{BA}[35:20] \& \text{!Mask}[35:20]$$

In the above equation, paddr represents the accessed physical address, Mask[35:20] represents the address mask value selected from Table 7.3.2 from the Channel Size field value, the ampersand (&) represents the AND operation, and the exclamation mark (!) represents the Logical NOT for each bit.

Operation is indeterminate when either multiple channels are selected simultaneously, or a channel is selected simultaneously with the SDRAM Controller or PCI Controller.

Table 7.3.2 Address Mask

CS[3:0]	Channel Size	Address Mask[35:20]
0000	1 MB	0000_0000_0000_0000
0001	2 MB	0000_0000_0000_0001
0010	4 MB	0000_0000_0000_0011
0011	8 MB	0000_0000_0000_0111
0100	16 MB	0000_0000_0000_1111
0101	32 MB	0000_0000_0001_1111
0110	64 MB	0000_0000_0011_1111
0111	128 MB	0000_0000_0111_1111
1000	256 MB	0000_0000_1111_1111
1001	512 MB	0000_0001_1111_1111
1010	1 GB	0000_0011_1111_1111
1011	Reserved	Reserved
1100	Reserved	Reserved
1101	Reserved	Reserved
1110	Reserved	Reserved
1111	Reserved	Reserved

7.3.4 External Address Output

The maximum memory space size for each channel is 1 GB (230B). Addresses are output by dividing the 20-bit ADDR[19:0] signal into two parts: the upper address and the lower address. The address bit output to each bit of the ADDR[19:0] signal changes according to the setting of the channel data bus width. (See 7.3.5: "Data Bus Size" for more information.)

It is possible for an external device to latch the upper eight address bits using the ACE* signal. Either the ACE* signal itself can be used as a Latch Enable signal or the upper address can be latched at the rise of SYSCLK when the ACE* signal is being asserted.

The ADDR signal output is held for one clock cycle after the ACE* signal rise when the CCFG.ACEHOLD bit is set (default). (See Figure 7.5.1.) The ADDR signal output is not held when the CCFG.ACEHOLD bit is cleared. This hold time setting is applied globally to all channels.

The ACE* signal of the upper address is always asserted at the first external bus access cycle after Reset. In all subsequent external bus access cycles, the bit mapping of the upper address output to ADDR[19:12] is compared to the bit mapping of the upper address output to ADDR[19:12] previously. The upper address is output and the ACE* signal is asserted only if the compared results do not match.

As indicated below in Table 7.3.3, in the case of channel sizes that do not use the upper address latched by the ACE* signal, with the exception of the first cycle after reset, the upper address is not output and the ACE* signal is not asserted.

Table 7.3.3 Relationship Between the Upper Address Output and the Channel Size (CS)

CS Bus Width	1 MB	2 MB	4 MB	8 MB or more
32 bits	—	—	—	√
16 bits	—	—	√	√
8 bits	—	√	√	√

√: The upper address output changes when the upper address changes.

—: The upper address output does not change (with the exception of the first cycle after reset.)

7.3.5 Data Bus Size

The External Bus Controller supports devices with a data bus width of 8 bits, 16 bits, and 32 bits. The data bus width is selected using the BSZ field of the Channel Control Register (EBCCRn). The address bits output to each bit of the ADDR[19:0] signal change according to the mode. When access of a size larger than the data bus width is performed, the dynamic bus sizing function is used to execute multiple bus access cycles in order from the lower address.

7.3.5.1 32-bit Bus Width Mode

DATA[31:0] becomes valid.

Bits [21:2] of the physical address are output to ADDR[19:0]. The internal address bits [29:22], which are the upper address, are multiplexed to external ADDR[19:12]. The maximum memory size is 1 GB.

Table 7.3.4 Address Output Bit Correspondence in the 32-bit Mode

ADDR Bit	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Upper Address	29	28	27	26	25	24	23	22												
Lower Address	21	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2

When a Single cycle that accesses 1-Byte/1 half-word/1-word data is executed, 32-bit access is executed only once on the external bus. 32-bit access is executed twice when performing 1-double-word access. When a Burst cycle is executed, two 32-bit cycles are executed for each Burst access when the Bus cycle tries to request a byte combination other than double-word data.

7.3.5.2 16-bit Bus Width Mode

DATA[15:0] becomes valid.

Bits [20:1] of the physical address are output to ADDR[19:0]. The internal address bits [28:21], which are the upper address, are multiplexed to external ADDR[19:12]. In other words, the address is shifted up one bit relative to the 32-bit bus mode when output. As a result, the maximum memory size of the 16-bit bus mode is 512 MB.

Table 7.3.5 Address Output Bit Correspondence in the 16-bit Mode

ADDR Bit	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Upper Address	28	27	26	25	24	23	22	21												
Lower Address	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1

When a Single cycle that accesses 1-Byte or 1 half-word data is executed, 16-bit access is executed only once on the external bus. 16-bit access is executed twice when performing 1-word access. 16-bit access is executed four times when performing 1-double-word access. When a Burst cycle is executed, four 16-bit cycles are executed for each Burst access when the Bus cycle tries to request a byte combination other than double-word data.

7.3.5.3 8-bit Bus Width Mode

DATA[7:0] becomes valid.

Bits [19:0] of the physical address are output to ADDR[19:0]. The internal address bits [27:20], which are the upper address, are multiplexed to external ADDR[19:12]. In other words, the address is shifted up two bits or more relative to the 32-bit bus mode when output. As a result, the maximum memory size of the 8-bit bus mode is 256 MB.

Table 7.3.6 Address Output Bit Correspondence in the 8-bit Mode

ADDR Bit	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
Upper Address	27	26	25	24	23	22	21	20												
Lower Address	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0

When a Single cycle that accesses 1-Byte data is executed, 8-bit access is executed only once on the external bus. 8-bit access is executed twice when performing 1-half-word access. 8-bit access is executed four times when performing 1-word access. 8-bit access is executed eight times when performing 1-double-word access. When a Burst cycle is executed, eight 8-bit cycles are executed for each Burst access when the Bus cycle tries to request a byte combination other than double-word data.

7.3.6 Access Mode

The following four modes are available as controller access modes. These modes can be set separately for each channel.

- Normal mode
- Page mode
- External ACK mode
- Ready mode

Depending on the combination of modes in each channel, either of two modes in which the ACK*/Ready signal operates differently (ACK*/Ready Dynamic mode, ACK*/Ready Static mode) is selected by the ACK*/Ready Mode bit (CCFG.ARMODE) of the Chip Configuration Register. The mode selected is applied globally to all channels.

(1) ACK*/READY Dynamic mode (CCFG.ARMODE = 0)

This mode is selected in the initial state.

The ACK*/Ready signal automatically switches to either input or output according to the setting of each channel. When in the Normal mode or the Page mode, the ACK*/Ready signal is an output signal, and the internally generated ACK* signal is output. When in the External ACK* or Ready mode, the ACK*/Ready signal becomes an input signal. The ACK*/Ready signal outputs High if there is no access to the External Bus Controller. However, this signal may output Low during access to SDRAM.

Please refer to the timing diagrams (Figure 7.5.23 and Figure 7.5.24) and be careful to avoid conflicts when switching from output to input.

(2) ACK*/Ready Static mode (CCFG.ARMODE = 1)

The internally generated ACK* signal is not output when in either the Normal mode or Page mode. Therefore, the ACK*/Ready signal will not become an output in any channel.

Access using Burst transfer by the internal bus (G-Bus) is supported when in a mode other than the Ready mode. However, the Ready mode is not supported.

Table 7.3.7 Operation Mode

	PM	RDY	PWT:WT	Mode	ACK*/READY Pin State	Access End Timing State	G-Bus Burst Access
ACK*/Ready Dynamic Mode	0	0	!3f	Normal	Output	Internally Generated ACK*	√
			3f	External ACK*	Input	ACK* Input	√
		1	—	READY	Input	Ready Input	—
	!0	0	—	Page	Output	Internally Generated ACK*	√
		1	—	Reserved	—	—	—
ACK*/Ready Static Mode	0	0	!3f	Normal	Hi-Z	Internally Generated ACK*	√
			3f	External ACK*	Input	ACK* Input	√
		1	—	READY	Input	Ready Input	—
	!0	0	—	Page	Hi-Z	Internally Generated ACK*	√
		1	—	Reserved	—	—	—

7.3.6.1 Normal Mode

When in this mode, the ACK*/Ready signal becomes an ACK* output when it is in the ACK*/Ready Dynamic mode. The ACK*/Ready signal becomes High-Z when it is in the ACK*/Ready Static mode.

Wait cycles are inserted according to the EBCCRn.PWT and EBCCRn.WT value at the access cycle. The Wait cycle count is 0 – 0x3e (becomes the external ACK mode when set to EBCCRn.PWT: WT = 0x3f).

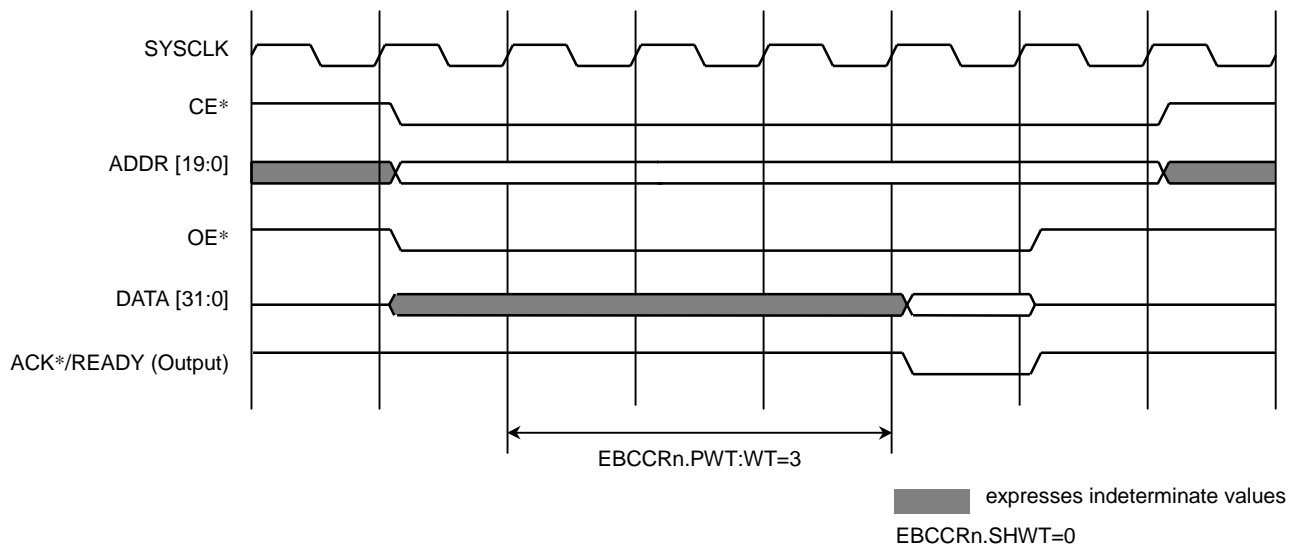


Figure 7.3.1 Normal Mode

7.3.6.2 External ACK Mode

When in this mode, the ACK*/READY pin becomes ACK* input, and the cycle is ended by the ACK* signal from an external device. ACK* input is internally synchronized. Refer to Section "7.3.7.4 ACK* Input Timing" for more information regarding timing.

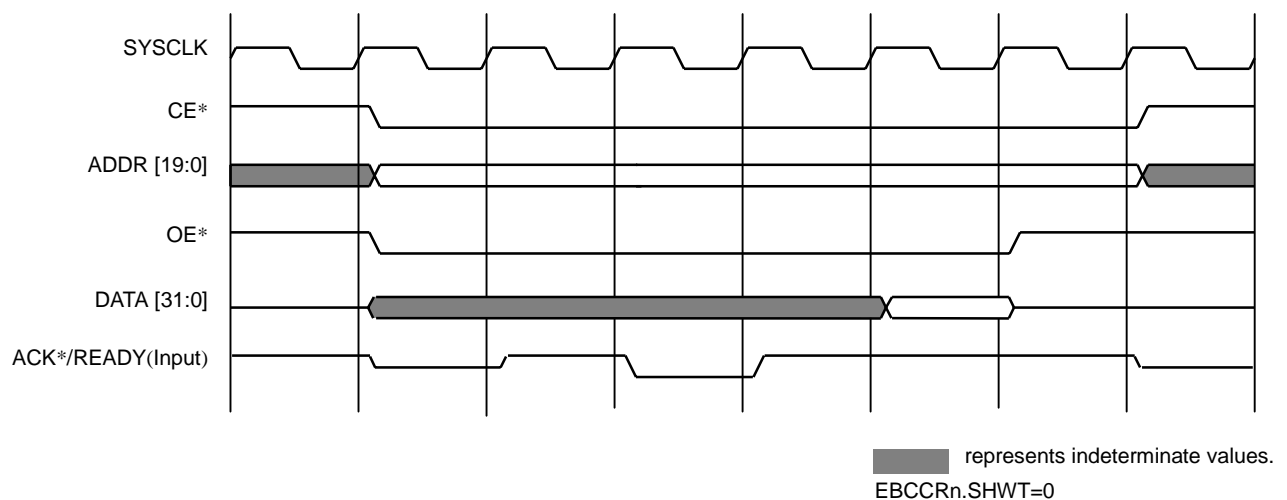


Figure 7.3.2 External ACK Mode

7.3.6.3 Ready Mode

When in this mode, the ACK*/Ready pin becomes Ready input, and the cycle is ended by Ready input from an external device. Ready input is internally synchronized. See Section "7.3.7.5 Ready Input Timing" for more information regarding the operation timing.

When the Wait cycle count specified by EBCCRn.PWT:WT elapses, a check is performed to see whether the Ready signal was asserted. Since EBCCRn.WT[0] is used to indicate the ACK*/Ready Static/Dynamic mode, it is not used for setting the Wait cycle count. Therefore, the Wait cycle count that can be set by the Ready mode is 0, 2, 4, 6, ..., 62.

The Ready mode does not support Burst access by the internal bus.

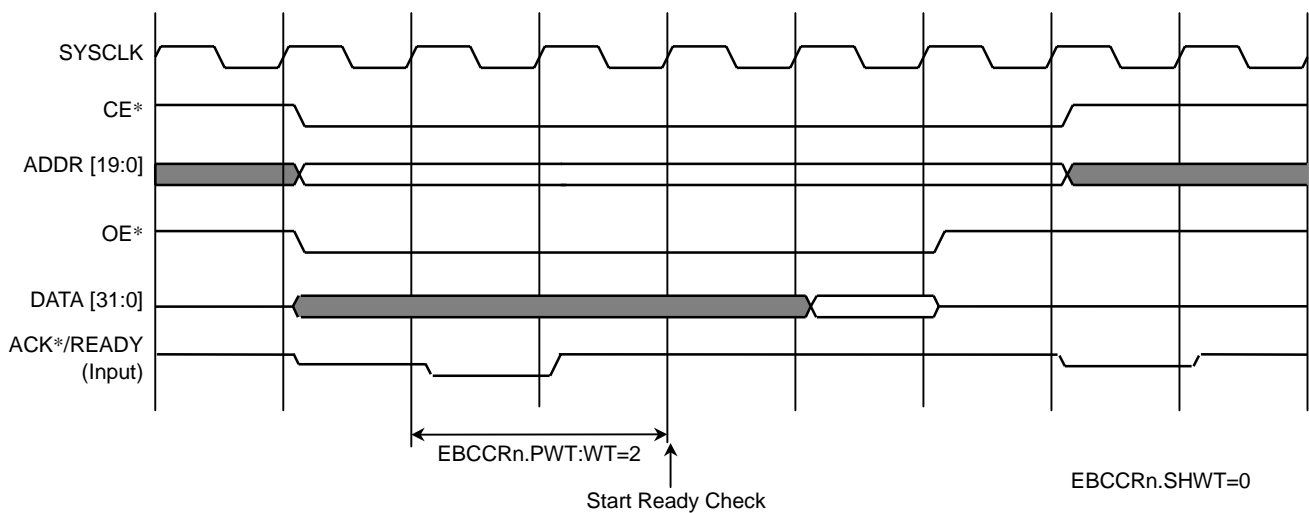


Figure 7.3.3 Ready Mode

7.3.6.4 Page Mode

When in this mode, the ACK*/Ready pin becomes ACK* output when it is in the Dynamic mode. When it is in the ACK*/Ready Static mode, the ACK*/Ready signal becomes HiZ.

Wait cycles are inserted into the access cycle according to the values of EBCCRn.PWT and EBCCRn.WT. The Wait cycle count in the first access cycle of Single access or Burst access is determined by the EBCCRn.WT value. The Wait cycle count can be set from 0 to 15. The Wait cycle count of subsequent Burst cycles is determined by the EBCCRn.PWT value. The Wait cycle count can be set from 0 to 3.

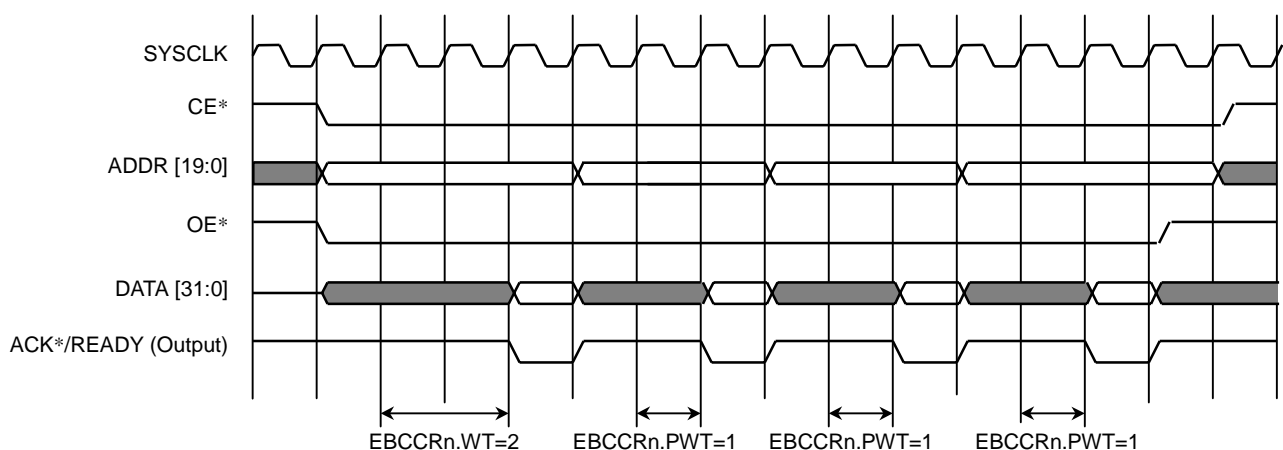


Figure 7.3.4 Page Mode

7.3.7 Access Timing

7.3.7.1 SHWT Option

The SHWT option is selected when the SHWT (Setup/Hold Wait Time) field of the Channel Control Register is a value other than “0.” This option inserts a Setup cycle and a Hold cycle between the current signal and the next signal.

Setup cycle: CE* from ADDR, OE* from CE*, BWE* from CE*, SWE* from CE*.

Hold cycle: ADDR from CE*, CE* from OE*, CE* from BWE*, CE* from SWE*

This option is used for I/O devices that are generally slow. All Setup cycles and Hold cycles will be identical, so each cycle cannot be set individually.

The SHWT mode cannot be used by the Page mode. The SHWT mode can be used by all other modes, but there is one restriction: the internal bus cannot use Burst access.

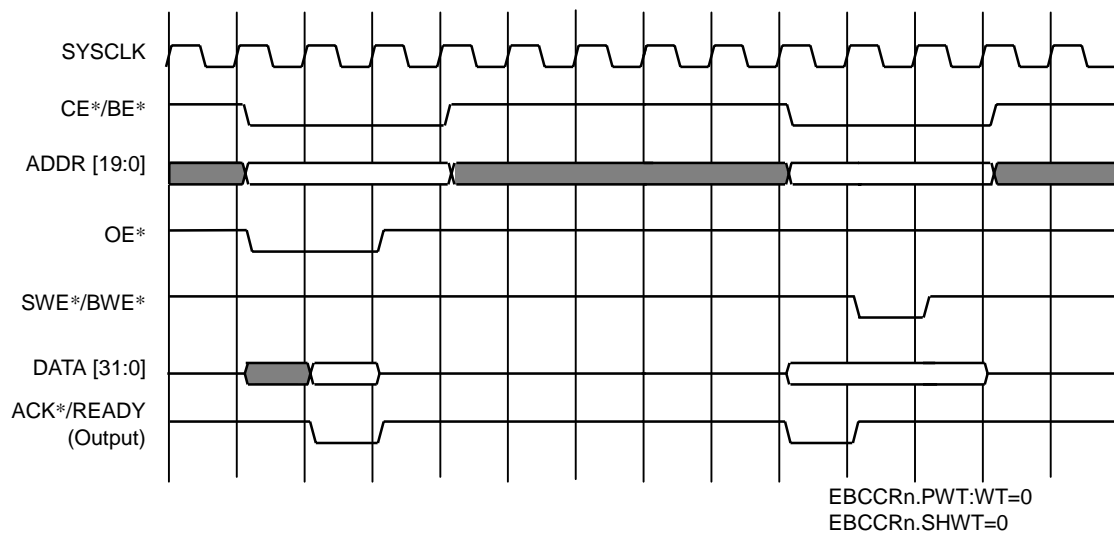


Figure 7.3.5 SHWT Disable (Normal Mode, Single Read/Write Cycle)

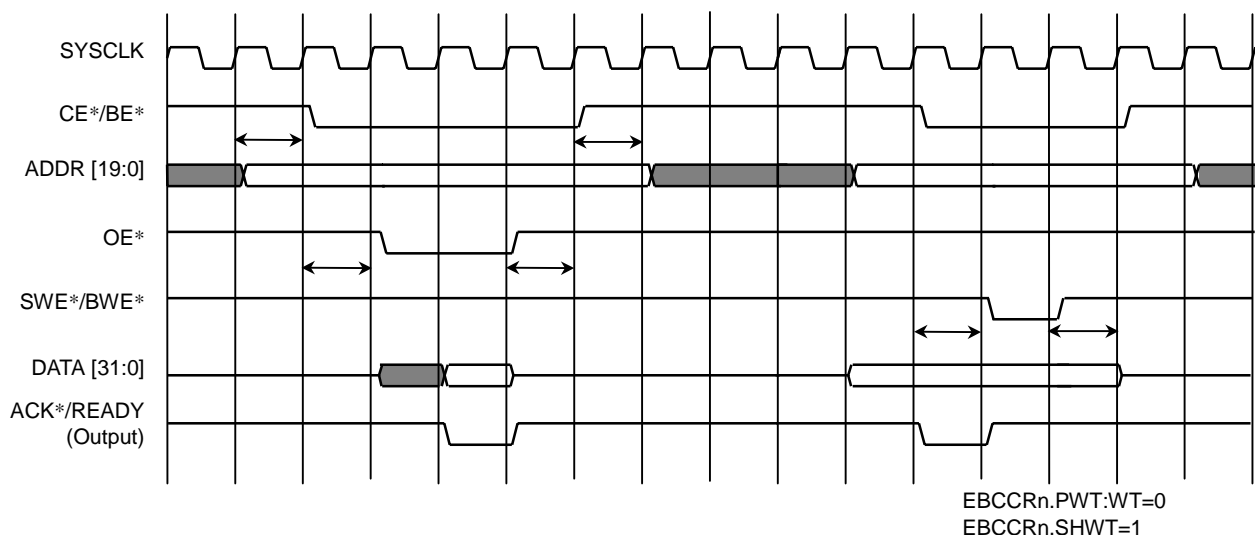


Figure 7.3.6 SHWT 1 Wait (Normal Mode, Single Read/Write Cycle)

7.3.7.2 ACK*/READY Input/Output Switching Timing

When in the ACK*/Ready Static mode, the ACK*/Ready signal is always an input signal. When in the ACK*/Ready Dynamic mode, the ACK*/Ready signal is an input signal when in the External ACK mode or the Ready mode, but is an output signal in all other modes.

During External ACK mode or Ready mode access, the ACK* signal becomes High-Z at the cycle where the CE* signal is asserted. At the end of the access cycle, the ACK* signal is output (driven) again one clock cycle after the CE* signal is deasserted (see Figure 7.3.3).

7.3.7.3 ACK* Output Timing (Normal Mode, Page Mode)

When in the Normal mode and Page mode of the ACK*/Ready Dynamic mode, the ACK* signal becomes an output signal and is asserted for one clock cycle to send notification to the external device of the data Read and data Write timing.

During the Read cycle, the data is latched at the rise of the next clock cycle after when the ACK* signal is asserted. (See Figure 7.3.7 ACK* Output Timing (Single Read Cycle)).

During the Write cycle, SWE*/BWE* is deasserted at the next clock cycle after when the ACK* signal is deasserted, and the data is held for one more clock cycle after that. (See Figure 7.3.8 ACK* Output Timing (Single Write Cycle)).

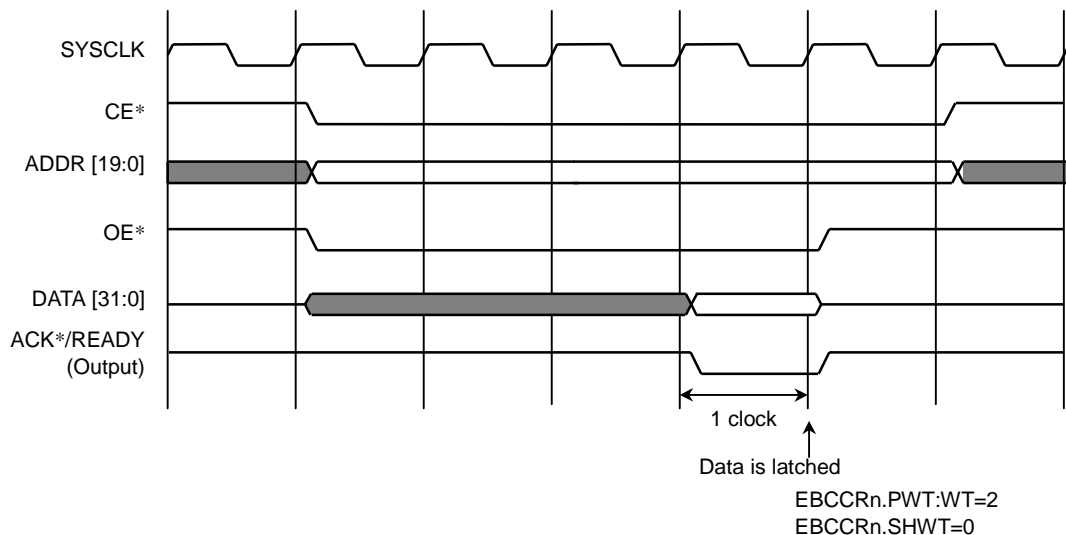


Figure 7.3.7 ACK* Output Timing (Single Read Cycle)

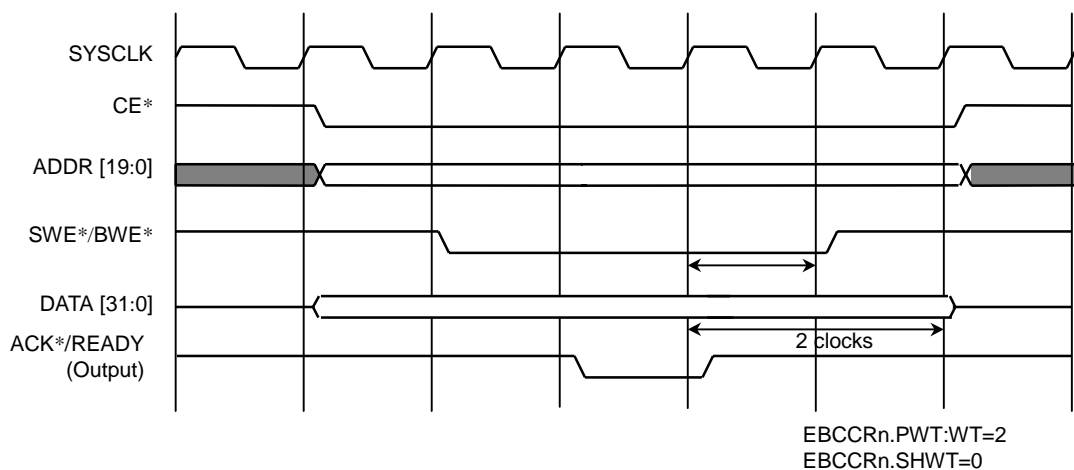


Figure 7.3.8 ACK* Output Timing (Single Write Cycle)

7.3.7.4 ACK* Input Timing (External ACK Mode)

The ACK* signal becomes an input signal when in the external ACK mode.

During a Read cycle, data is latched two clock cycles after assertion of the ACK* signal is acknowledged (Figure 7.3.9 ACK* Input Timing (Single Read Cycle)). During a Write cycle, assertion of the ACK* signal is acknowledged, SWE*/BWE* is deasserted three clock cycles later, then data is held for one clock cycle after that (Figure 7.3.10 ACK* Input Timing (Single Write Cycle)).

The ACK* input signal is internally synchronized. Due to internal State Machine restrictions, ACK* cannot be acknowledged consecutively on consecutive clock cycles. External devices can assert ACK* across multiple clock cycles under the following conditions.

- During Single access, the ACK* signal can be asserted before the end of the cycle during which CE* is asserted.
- During Burst access, it is possible to assert the ACK* signal for up to three clock cycles during Reads and for up to five clock cycles during Writes. If the ACK* signal is asserted for a period longer than this, it will be acknowledged as the next valid ACK* signal.

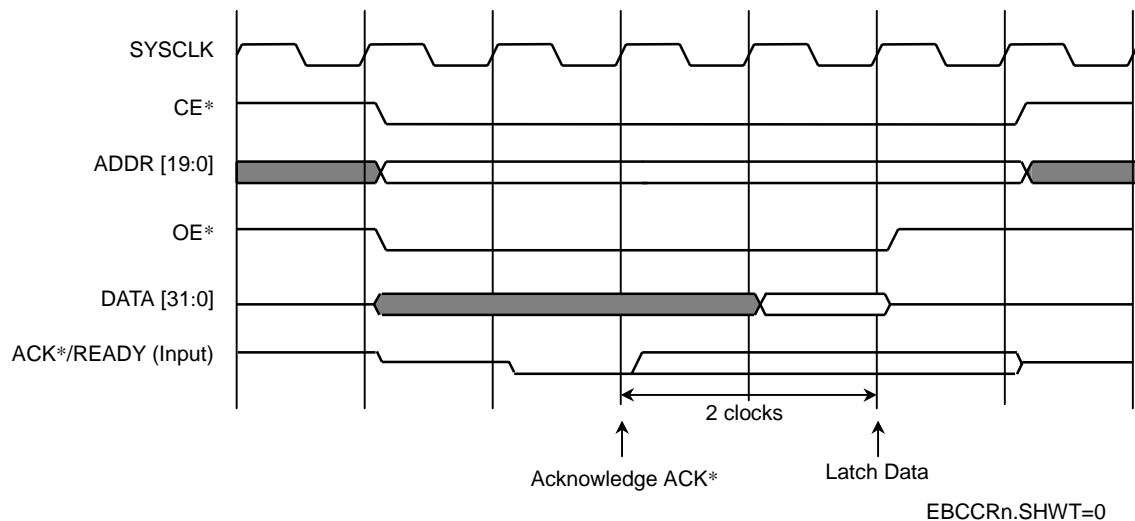


Figure 7.3.9 ACK* Input Timing (Single Read Cycle)

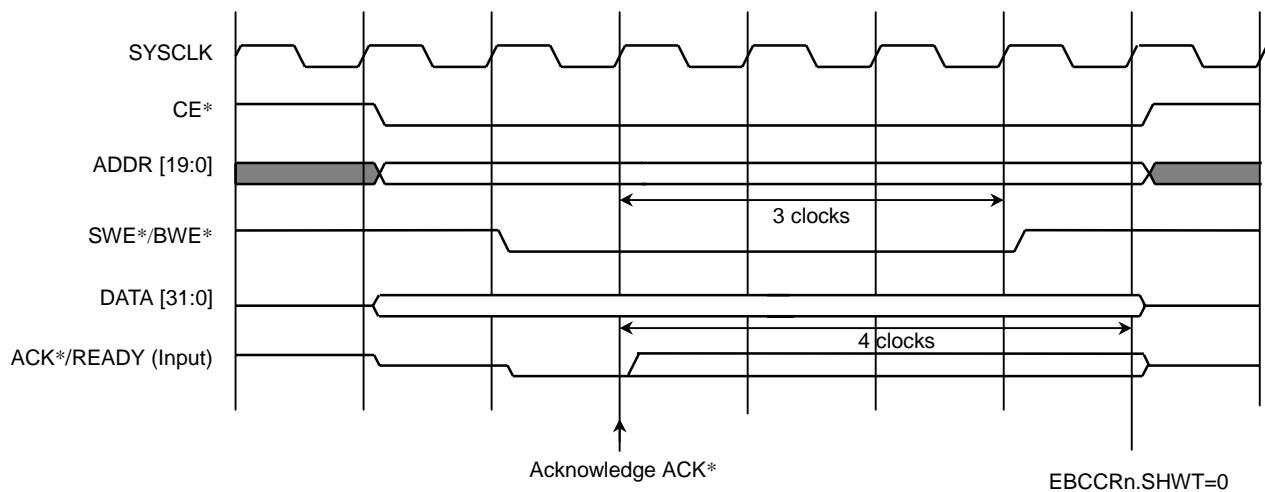


Figure 7.3.10 ACK* Input Timing (Single Write Cycle)

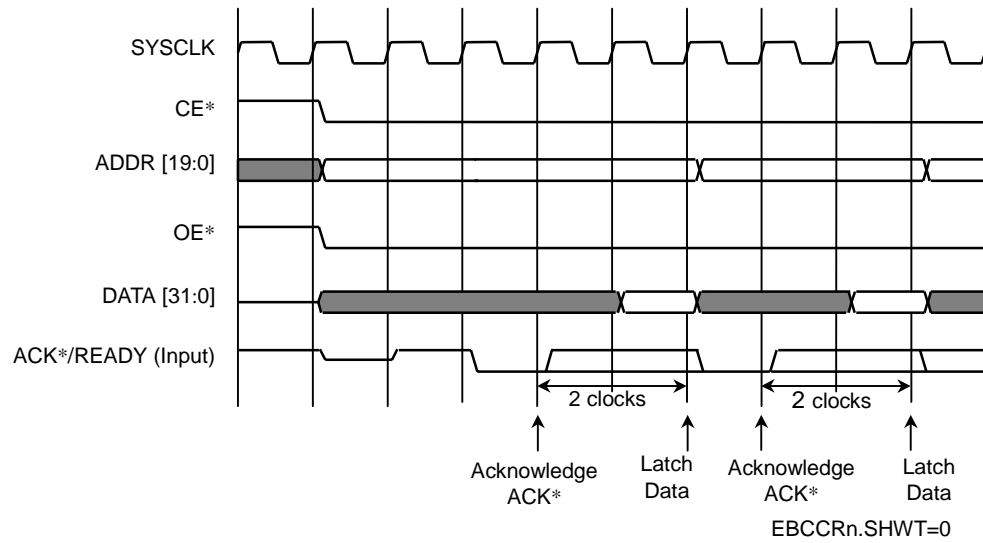


Figure 7.3.11 ACK* Input Timing (Burst Read Cycle)

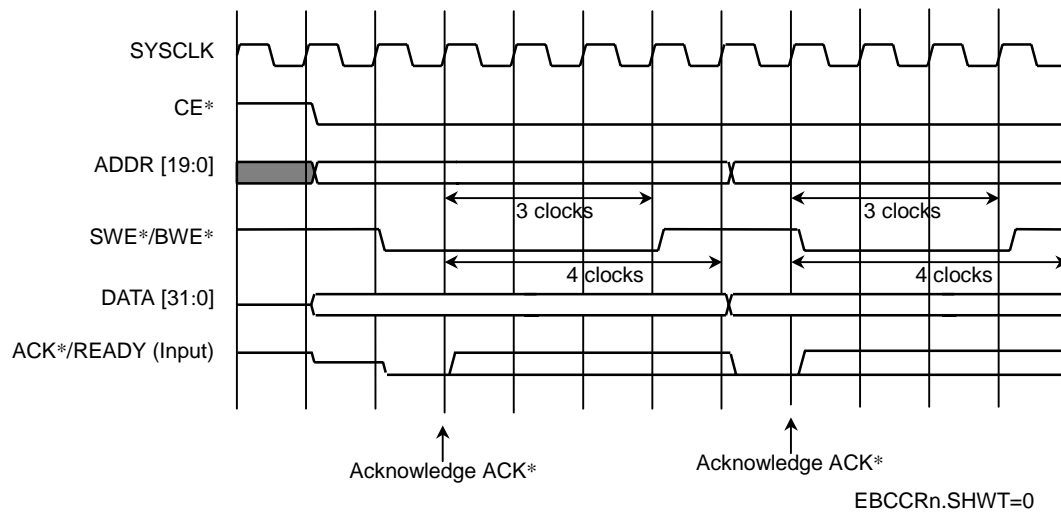


Figure 7.3.12 ACK* Input Timing (Burst Write Cycle)

7.3.7.5 Ready Input Timing

The ACK*/Ready pin is used as a Ready input when in the Ready mode. The Ready input timing is the same as the ACK* input timing explained in 7.3.7.4 ACK* Input Timing (External ACK Mode) with the two following exceptions.

- Ready must be a High Active signal.
- When in the Ready mode, the Wait cycle count specified by EBCCRn.PWT:WT must be inserted in order to delay the Ready signal check (see 7.3.6.3 Ready Mode).

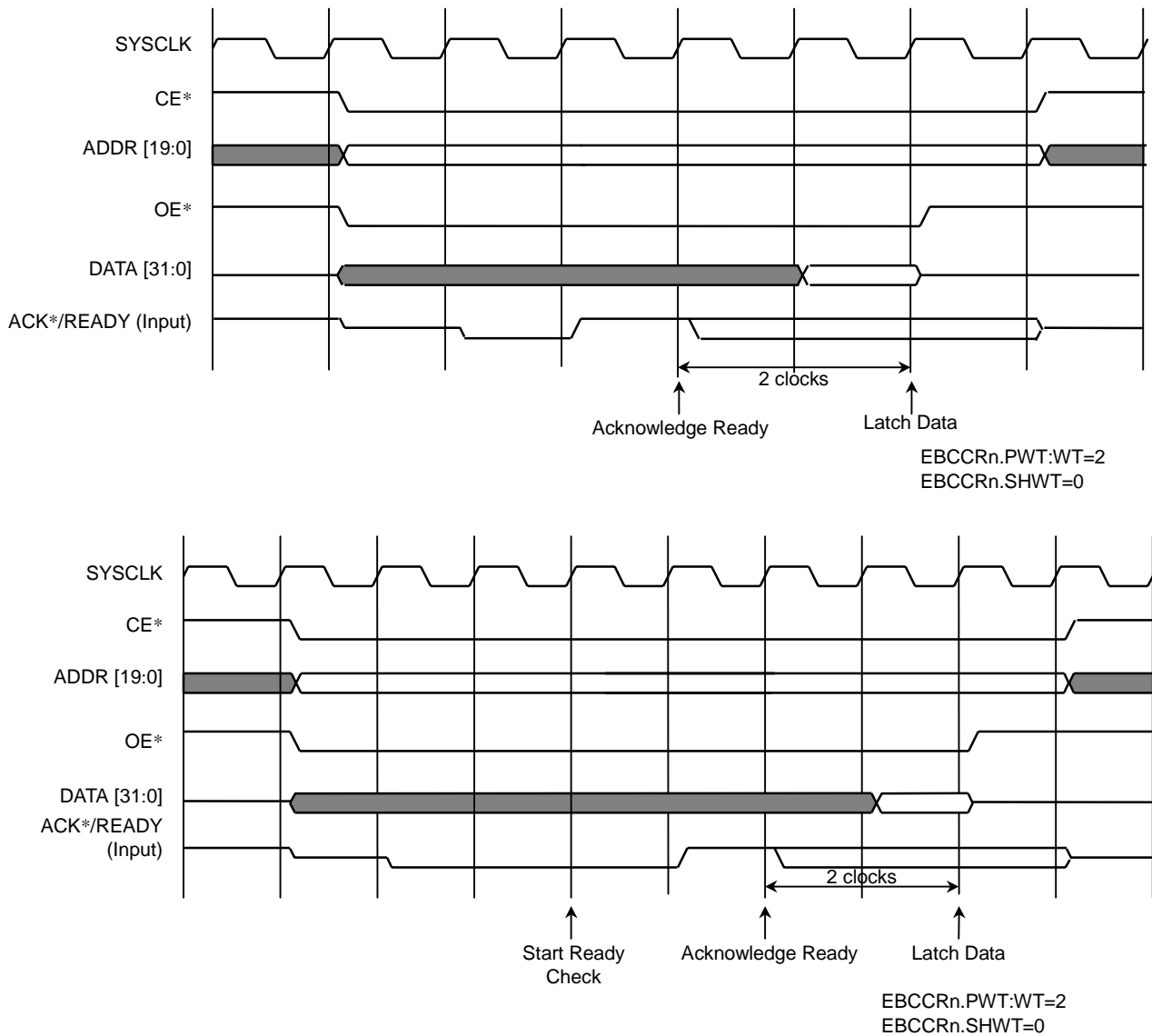


Figure 7.3.13 Ready Input Timing (Read Cycle)

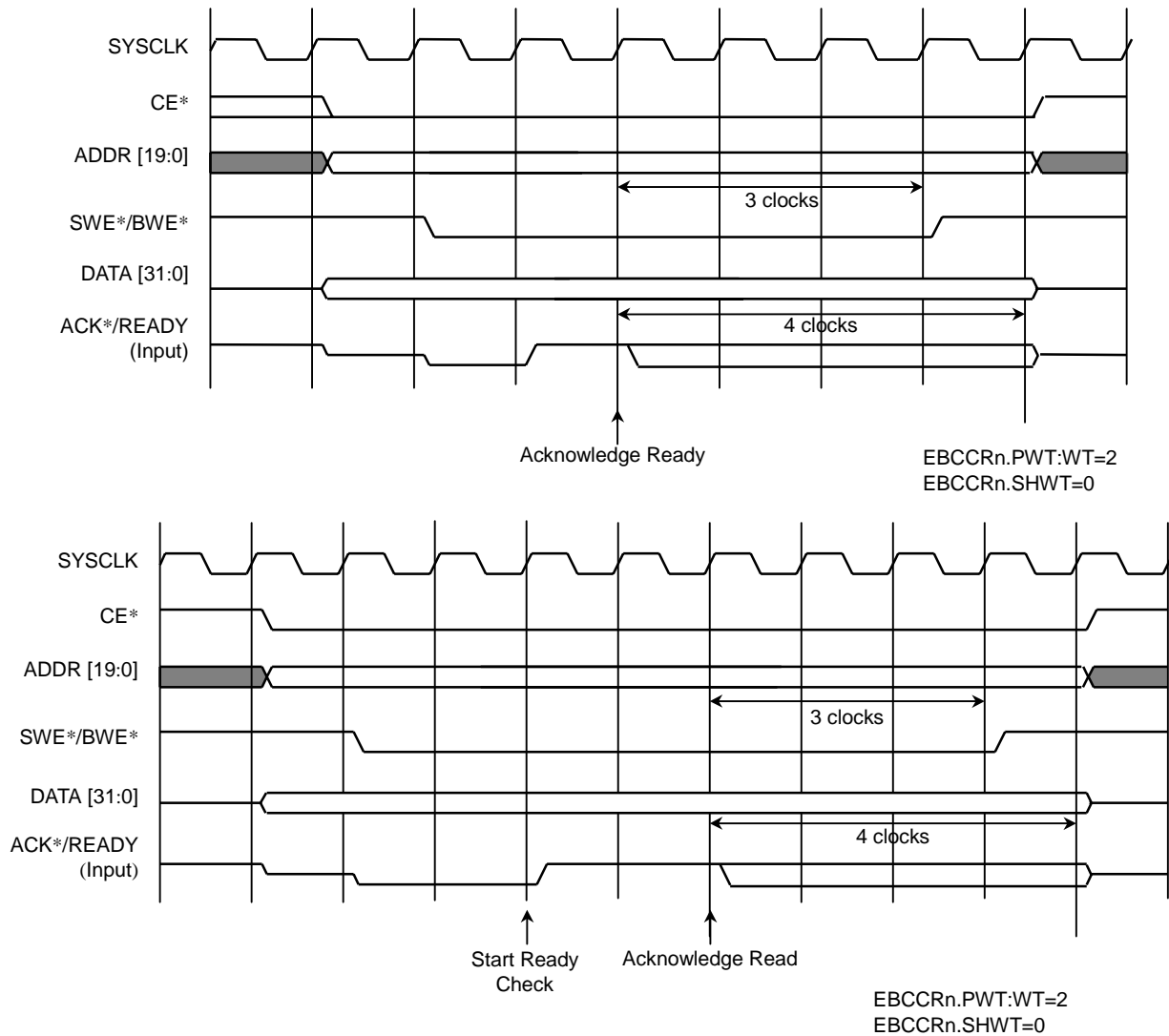


Figure 7.3.14 Ready Input Timing (Write Cycle)

7.3.8 Clock Options

External devices connected to the external bus can use the SYSCLK signal as the clock. The SYSCLK signal clock frequency can be set to one of the following divisions of the internal bus clock (GBUSCLK): 1/1, 1/2, 1/3, 1/4. The ADDR[14:13] signal is used to set this frequency during reset, and the setting is reflected in the SYSCLK Division Ratio field (CCFG.SYSSP) of the Chip Configuration Register.

The operation reference clock frequency can be set to one of the following divisions of the internal bus clock (GBUSCLK) for each channel independent of the SYSCLK signal clock frequency: 1/1, 1/2, 1/3, 1/4. The external signal of the External Bus Controller operates synchronous to this operation clock. The Bus Speed field (EBCCRn.SP) of the External Bus Channel Control Register sets this frequency.

Please set the same value as CCFG.SYSSP to EBCCRn.SP when the external device uses the SYSCLK signal. If these two values do not match, then the channel, the operation reference clock, and the SYSCLK signal will no longer be synchronous and will not operate properly.

7.4 Register

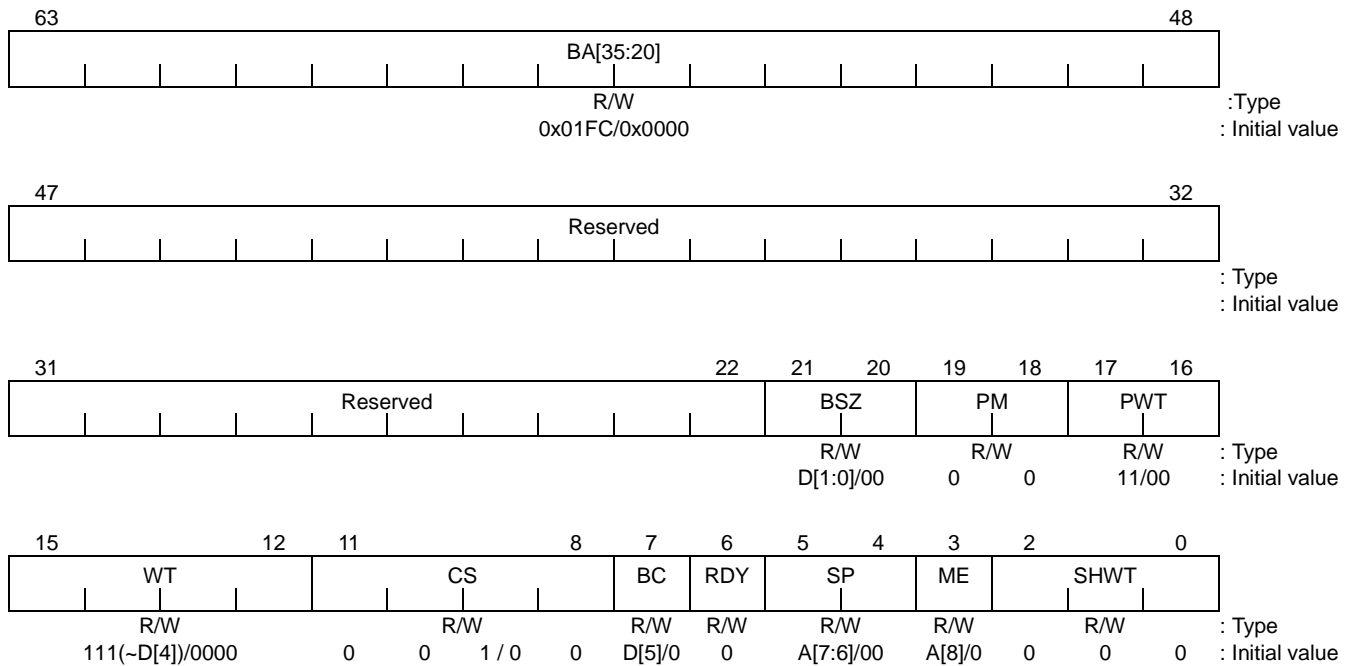
Table 7.4.1 External Bus Controller (EBUSC) Registers

Offset Address		Bit Width	Register Symbol	Register Name
Big Endian	Little Endian			
0x9000		64	EBCCR0	E-Bus Channel Control Register 0
0x9008		64	EBCCR1	E-Bus Channel Control Register 1
0x9010		64	EBCCR2	E-Bus Channel Control Register 2
0x9018		64	EBCCR3	E-Bus Channel Control Register 3
0x9020		64	EBCCR4	E-Bus Channel Control Register 4
0x9028		64	EBCCR5	E-Bus Channel Control Register 5
0x9030		64	EBCCR6	E-Bus Channel Control Register 6
0x9038		64	EBCCR7	E-Bus Channel Control Register 7

7.4.1 External Bus Channel Control Register (EBCCRn) 0x9000 (ch. 0), 0x9008 (ch. 1)
 0x9010 (ch. 2), 0x9018 (ch. 3)
 0x9020 (ch. 4), 0x9028 (ch. 5)
 0x9030 (ch. 6), 0x9038 (ch. 7)

Channel 0 can be used as Boot memory. Therefore, the default is set by the Boot signal (see 7.3.2 Global/Boot-up Options). Channels 1 - 7 have the same register configuration as Channel 0, but they have different defaults than Channel 0.

When the EBCCRn is programmed using a sequence of 32-bit store instructions, the base address in the high-order 32-bit portion of the register must be written first, followed by the Master Enable bit in the low-order 32-bit portion.



Only in the case of Channel 0 are fields with different defaults in the “Channel 0/Other channel” state.

D[] represents the corresponding Data[] signal value when the RESET* signal is deasserted. A[] represents the corresponding ADDR[] signal value when the RESET* signal is deasserted.

Bit	Mnemonic	Field Name	Description	Read/Write
63:48	BA[35:20]	Base Address	External Bus Control Base Address (Default: 0x01FC/0x0000) A physical address is used to specify the base address. The upper 16 bits [35:20] of the physical address are compared to the value of this field.	R/W
47:22		Reserved		—
21:20	BSZ	Bus Width	External Bus Control Bus Size (Default: DATA[1:0]/00) Specifies the memory bus width. 00: Reserved 10: 16-bit width 01: 32-bit width 11: 8-bit width Note: DATA[1:0] is set to Channel 0 as the default.	R/W
19:18	PM	Page Mode Page Size	External Bus Control Page Mode Page Size (Default: 00) Specifies the Page mode (Page mode memory support) use and page size. 00: Normal mode 01: 4-page mode 10: 8-page mode 11: 16-page mode	R/W

Figure 7.4.1 External Bus Channel Control Register (1/3)

Bit	Mnemonic	Field Name	Description	Read/Write
17:16	PWT	Page Mode Wait time	External Bus Control Page Mode Wait Time (Default: 11 / 00) Specifies the wait cycle count during Burst access when in the Page mode. 00: 0 wait cycles 10: 2 wait cycles 01: 1 wait cycle 11: 3 wait cycles Specifies a wait cycle count from 0 to 62 that matches WT when in the Normal mode or Ready mode. (See the WT item.)	R/W
15:12	WT	Normal Mode Wait Time	External Bus Control Normal Mode Wait Time (Default: 111 (~DATA[4])/0000) Specifies the wait cycle count in the first cycle of a Single Cycle or Burst access. Specifies the following wait cycle count when in the Page mode. 0000: 0 wait cycles 0100: 4 wait cycles 1000: 8 wait cycles 1100: 12 wait cycles 0001: 1 wait cycle 0101: 5 wait cycles 1001: 9 wait cycles 1101: 13 wait cycles 0010: 2 wait cycles 0110: 6 wait cycles 1010: 10 wait cycles 1110: 14 wait cycles 0011: 3 wait cycles 0111: 7 wait cycles 1011: 11 wait cycles 1111: 15 wait cycles Specifies a wait cycle count from 0 to 62 that matches PWT when in a mode other than the Page mode. PWT[1:0]: WT[3:0] 000000: 0 wait cycles 010000: 16 wait cycles 110000: 48 wait cycles 000001: 1 wait cycle 010001: 17 wait cycles 110001: 49 wait cycles : : : 001110: 14 wait cycles 011110: 30 wait cycles 111110: 62 wait cycles 001111: 15 wait cycles 011111: 31 wait cycles 111111: External ACK mode Note 1: Value that is the reverse of DATA[4] is set to the LSB of Channel 0 as the default. Note 2: If PWT:WT is set to 0x3f when PM = 00 and RDY = 0, the external bus enters the ACK* Input mode (External ACK mode) without the wait cycle count for the ACK* output being the maximum value. Note 3: WT[0] is used to select Dynamic/Static ACK*/Ready mode when in the Ready mode. Therefore, the Wait cycle count is an even number. Note 4: Set the WT wait cycle count to a value greater than the PWT Wait cycle count when in the Page mode.	R/W
11:8	CS	Channel Size	External Bus Control Channel Size (Default: 0010/0000) Specifies the channel memory size. 0000: 1 MB 0101: 32 MB *1010: 1 GB 0001: 2 MB 0110: 64 MB 1011-1111: Reserved 0010: 4 MB 0111: 128 MB 0011: 8 MB 1000: 256 MB 0100: 16 MB 1001: 512 MB * The channel memory size can be set up to 512 MB when the memory bus width is 16 bits, or up to 256 MB when the memory bus width is 8 bits. No size larger than this can be set.	R/W
7	BC	Byte Control	External Bus Byte Control (Default: DATA[5]/0) Specifies whether to use the BWE*[3:0] signal as an asserted Byte Write Enable signal (BWE*[3:0]) only during a Write cycle, or to use it as an asserted Byte Enable signal (BE*[3:0]) that is asserted during both Read and Write cycles. 0: Byte Enable (BE *[3:0]) 1: Byte Write Enable (BWE*[3:0]) Note: DATA[5] is set to Channel 0 as the default.	R/W
6	RDY	Ready Input Mode	External Bus Control Ready Input Mode (Default: 0) Specifies whether to use the Ready mode. 0: Disable the Ready mode. 1: Enable the Ready mode. Note: The Ready mode cannot be used when the Page mode is selected.	R/W

Figure 7.4.1 External Bus Channel Control Register (2/3)

Bit	Mnemonic	Field Name	Description	Read/Write
5:4	SP	Bus Speed	<p>External Bus Control Bus Speed (Default: ADDR[7:6] / 00)</p> <p>Specifies the External Bus speed.</p> <p>00: 1/4 speed (1/4 of the GBUSCLK frequency)</p> <p>01: 1/3 speed (1/3 of the GBUSCLK frequency)</p> <p>10: 1/2 speed (1/2 of the GBUSCLK frequency)</p> <p>11: Full speed (same frequency as GBUSCLK)</p> <p>Note: ADDR[7:6] is set to Channel 0 as the default.</p>	R/W
3	ME	Master Enable	<p>External Bus Control Master Enable (Default: ADDR[8] / 0)</p> <p>Enables a channel.</p> <p>0: Disable channel</p> <p>1: Enable channel</p> <p>Note: ADDR[8] is set to Channel 0 as the default.</p>	R/W
2:0	SHWT	Set Up/Hold Wait Time	<p>External Bus Control Setup/Hold Wait Time (Default: 000)</p> <p>Specifies the wait count when switching between the Address and Chip Enable signal, or the Chip Enable Signal and Write Enable/Output Enable signal.</p> <p>* 000: Disable 100: 4 wait cycles</p> <p>001: 1 wait cycle 101: 5 wait cycles</p> <p>010: 2 wait cycles 110: 6 wait cycles</p> <p>011: 3 wait cycles 111: 7 wait cycles</p> <p>* Set this bit field to "0" when using it in the Page mode or when performing Burst access.</p>	R/W


Figure 7.4.1 External Bus Channel Control Register (3/3)

7.5 Timing Diagrams

Please take the following points into account when referring to the timing diagrams.

1. The clock frequency of the SYSCLK signal can be set to one of the following divisions of the internal bus clock (GBUSCLK): 1/1, 1/2, 1/3, or 1/4. Also, the operating reference clock frequency can be set to one of the following divisions of the internal bus clock (GBUSCLK) for each channel: 1/1, 1/2, 1/3, or 1/4. (See 7.3.8.) The timing diagrams indicate the SYSCLK signal clock frequency and channel operating reference clock frequency as being equivalent.
2. Both the BWE* signal and BE* signal are indicated in all timing diagrams. The setting of the Channel Control Register (EBCCRn) determines whether the BWE* pin will function as BWE* or BE*.
3. All Burst cycles in the timing diagrams illustrate examples in which the address increases by increments of 1 starting from 0. However, cases where the CWF (Critical Word First) function of the TX49 core was used or the decrement burst function performed by the DMA Controller was used are exceptions.
4. The timing diagrams display each clock cycle currently being accessed using the symbols described in the following table.

SWn	Normal Wait Cycles
PWn	Page Wait Cycles
ASn	Set-up Time from SHWT Address Validation to CE Fall
CSn	Set-up Time from SHWT CE Fall to OE/SWE Fall
AHn	Hold Time from SHWT CE Rise to Address Change
CHn	Hold Time from SHWT OE/SWE Rise to CE Rise
ESn	Synch Cycles of the External Input Signal
ACEn	Address Clock Enable Cycles
Sn	Other Cycles

5. Shaded areas () in the diagrams are undefined values.

7.5.1 ACE* Signal

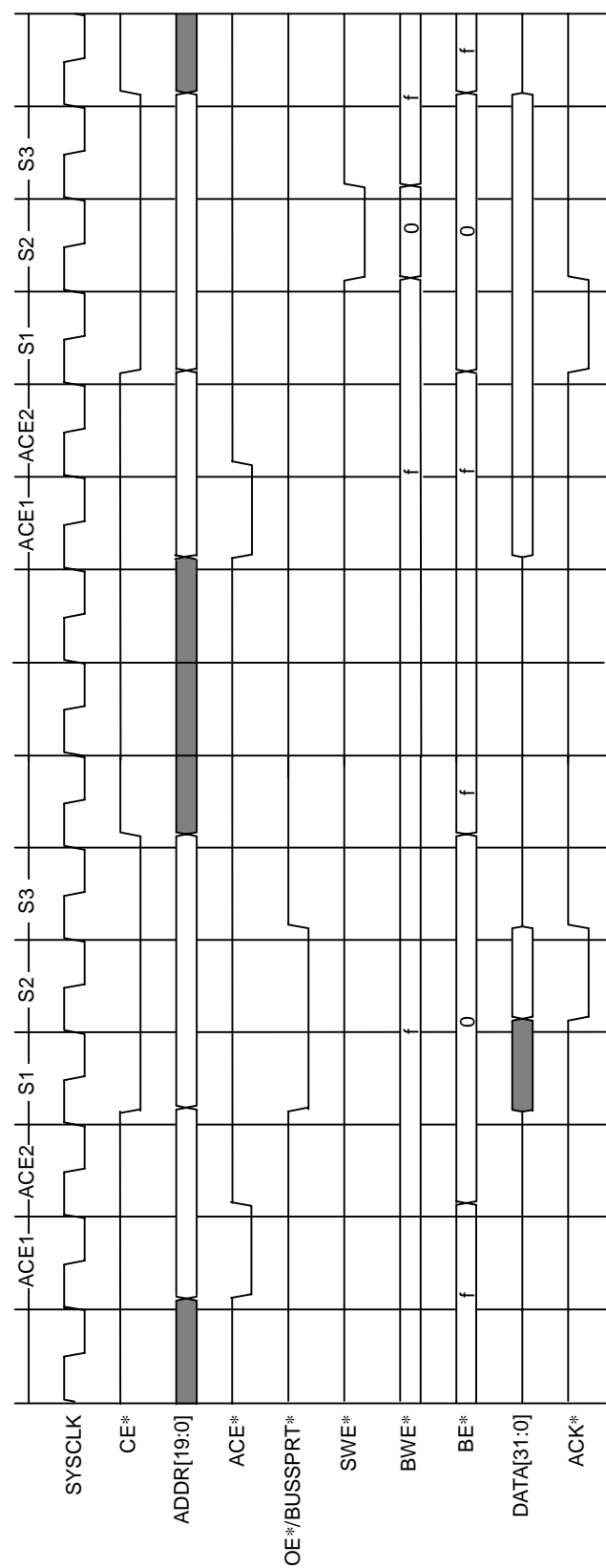


Figure 7.5.1 ACE* Signal (CCFG.ACEHOLD=1, PWT: WT=0, SHWT=0, Normal)

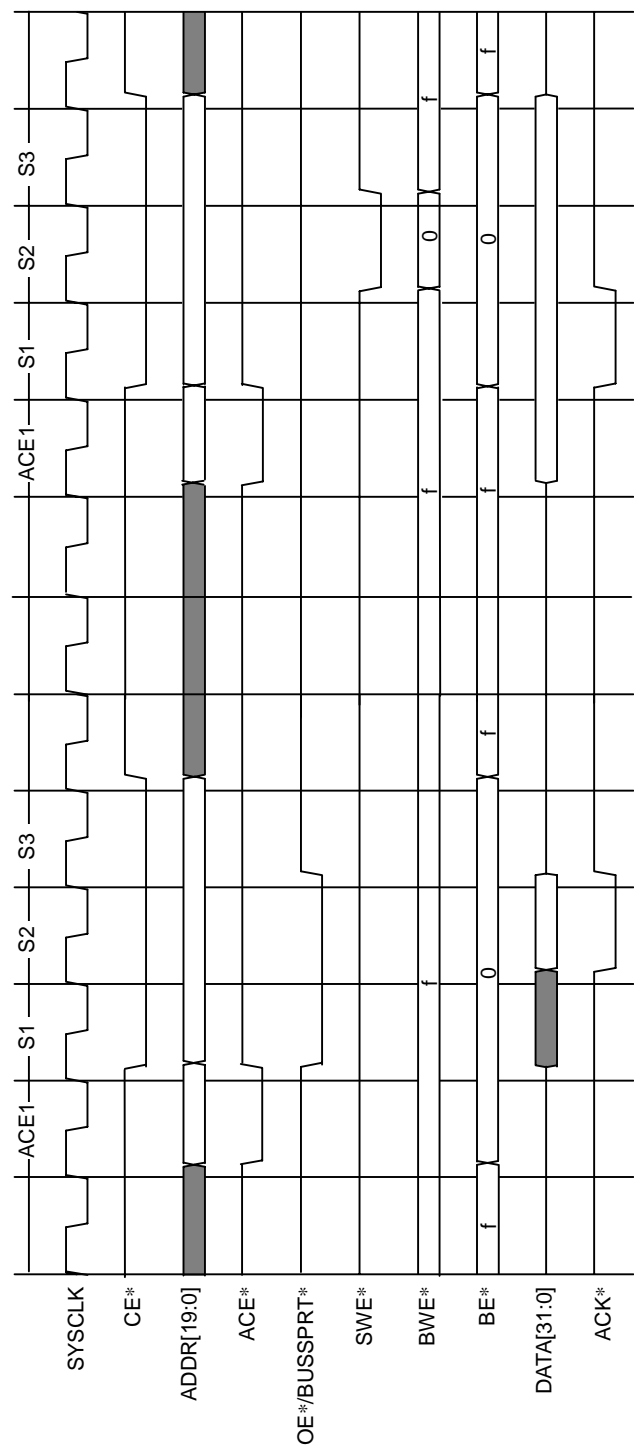


Figure 7.5.2 ACE* Signal (CCFG.ACEHOLD=0, PWT: WT=0, SHWT=0, Normal)

7.5.2 Normal mode access (Single, 32-bit Bus)

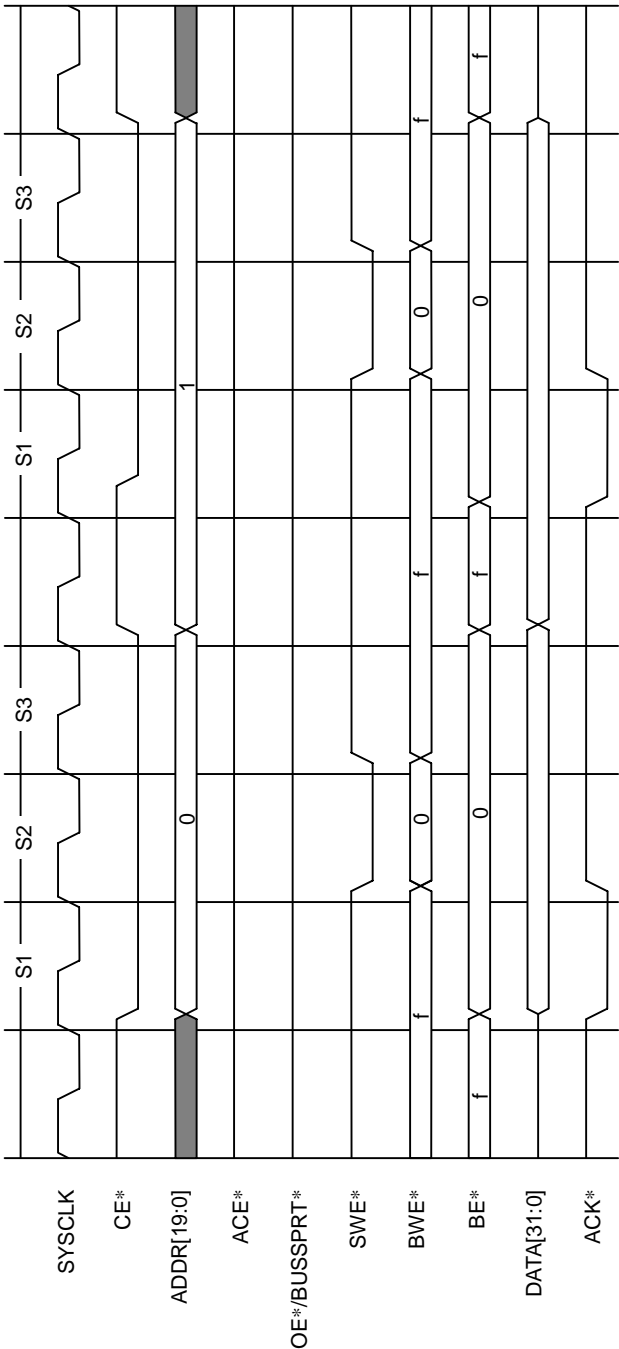


Figure 7.5.3 Double-word Single Write (PWT: WT=1, SHWT=0, Normal, 32-bit Bus)

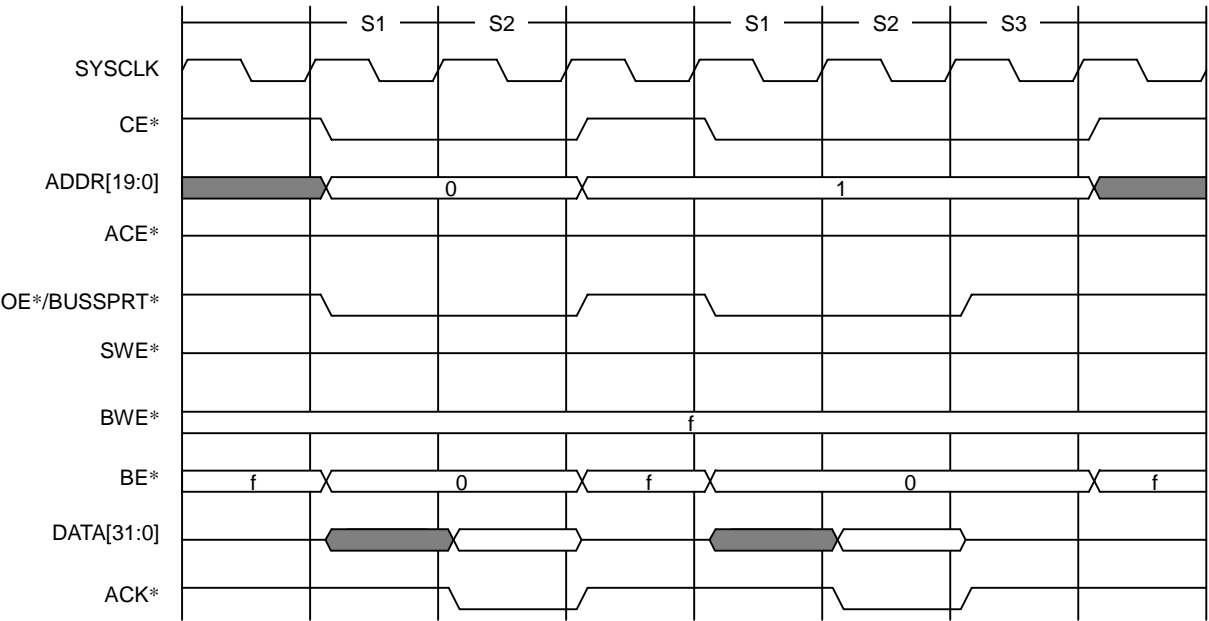


Figure 7.5.4 Double-word Single Read (PWT: WT=0, SHWT=0, Normal, 32-bit Bus)

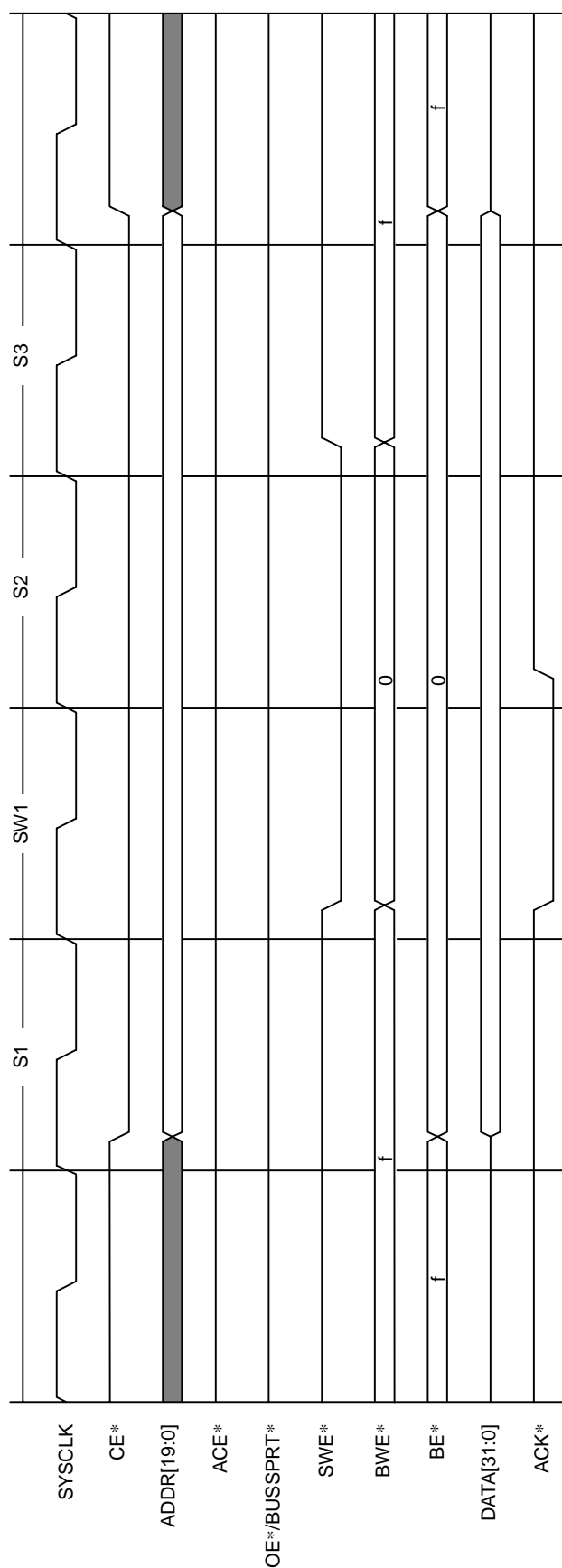


Figure 7.5.5 1-word Single Write (PWT: WT=0, SHWT=0, Normal, 32-bit Bus)

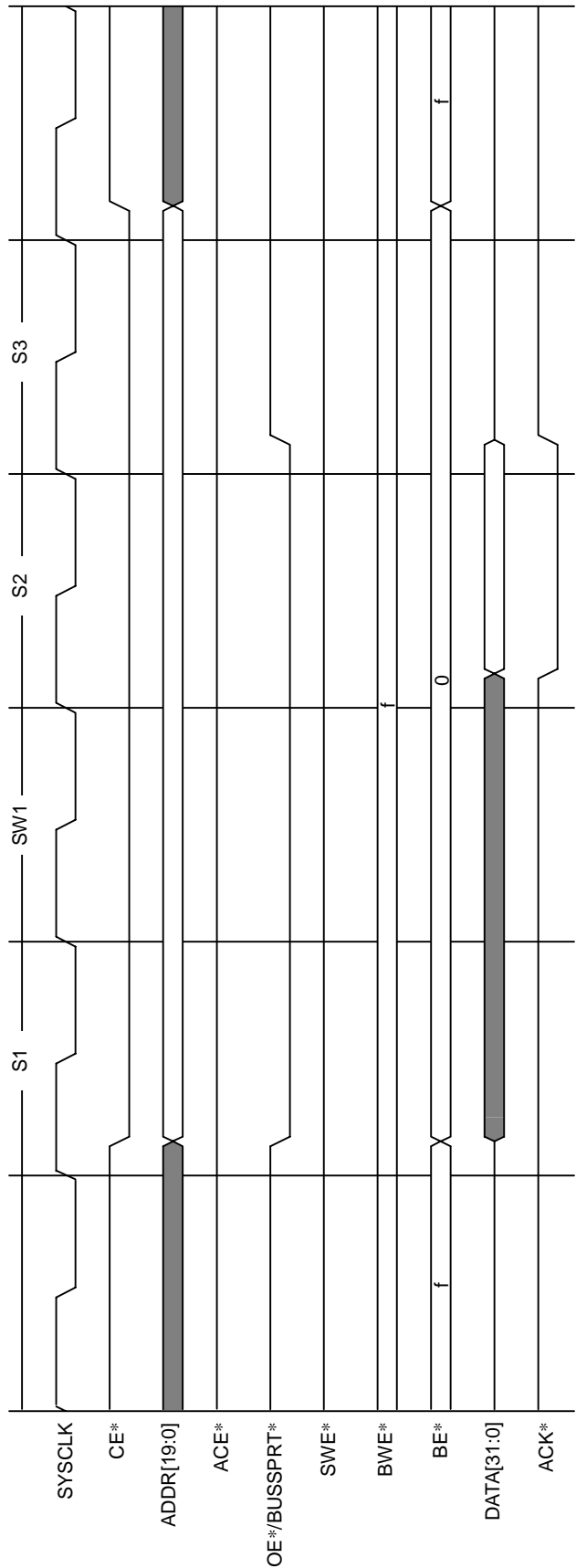


Figure 7.5.6 1-word Single Read (PWT: WT=0, SHWT=0, Normal, 32-bit Bus)

7.5.3 Normal mode access (Burst, 32-bit Bus)

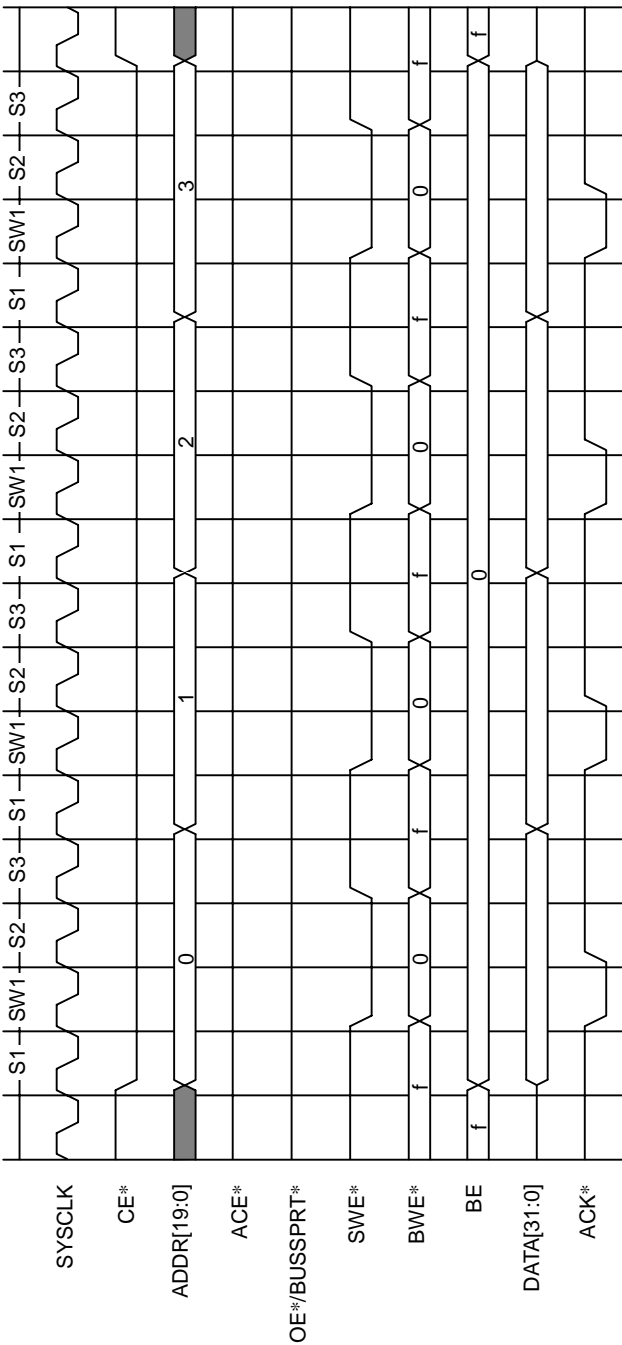


Figure 7.5.7 4-word Burst Write (PWT: WT=1, SHWT=0, Normal, 32-bit Bus)

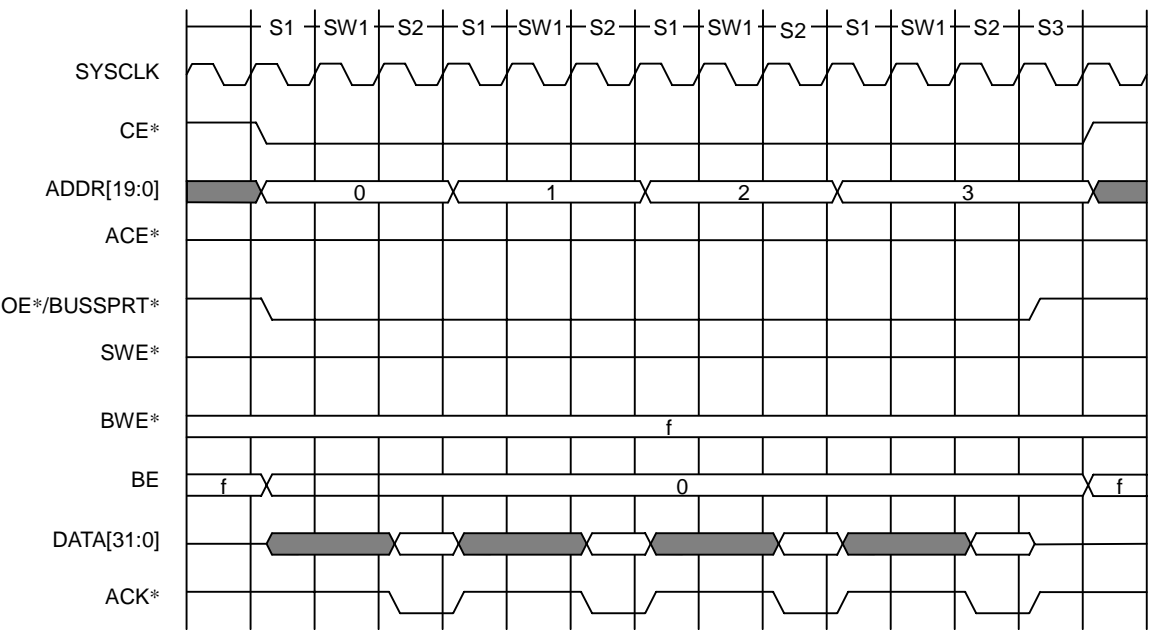


Figure 7.5.8 4-word Burst Write (PWT: WT=1, SHWT=0, Normal, 32-bit Bus)

7.5.4 Normal Mode Access (Single, 16-bit bus)

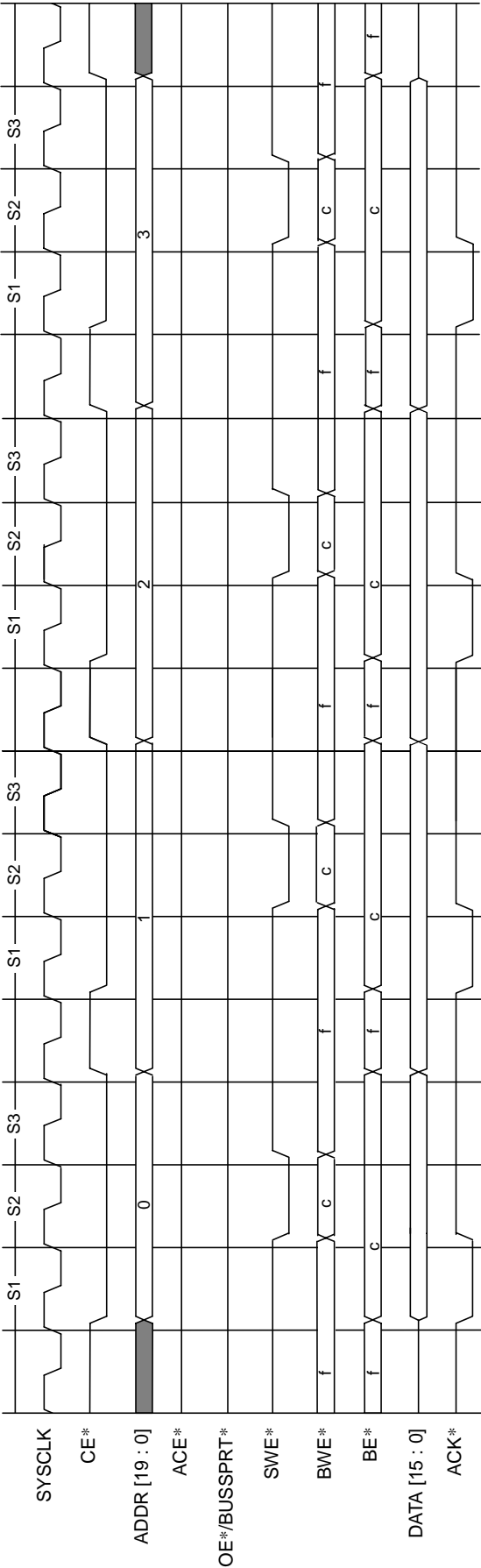


Figure 7.5.9 Double-word Single Write (PWT: WT=0, SHWT=0, Normal, 16-bit Bus)

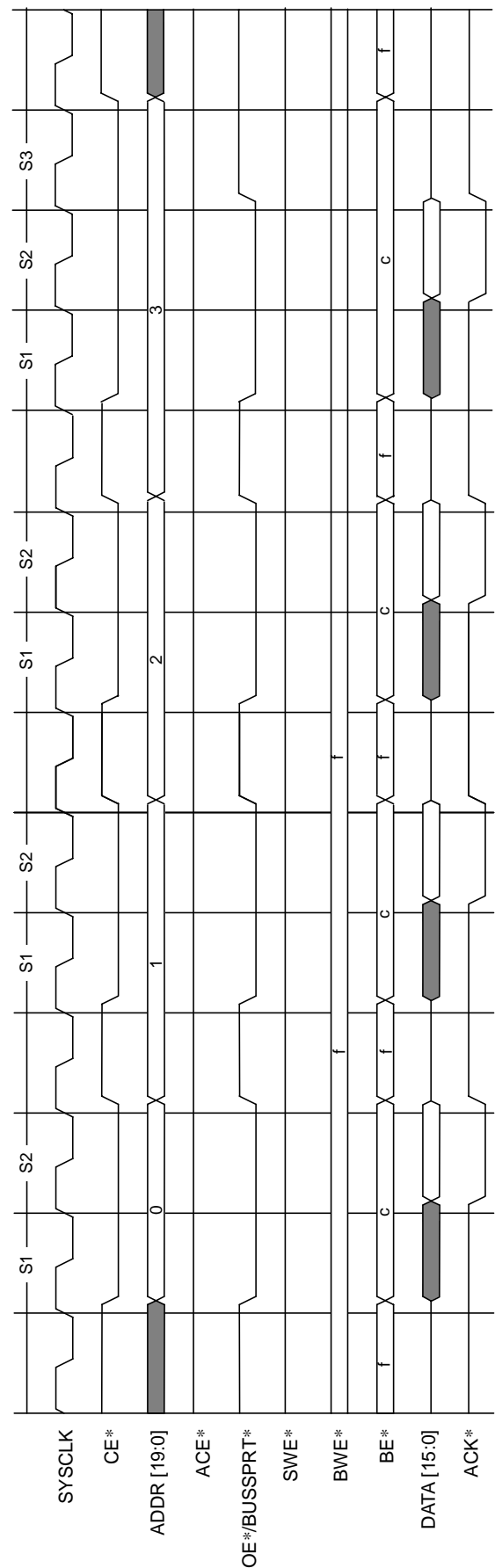


Figure 7.5.10 Double-word Single Read (PWT: WT=0, SHWT=0, Normal, 16-bit Bus)

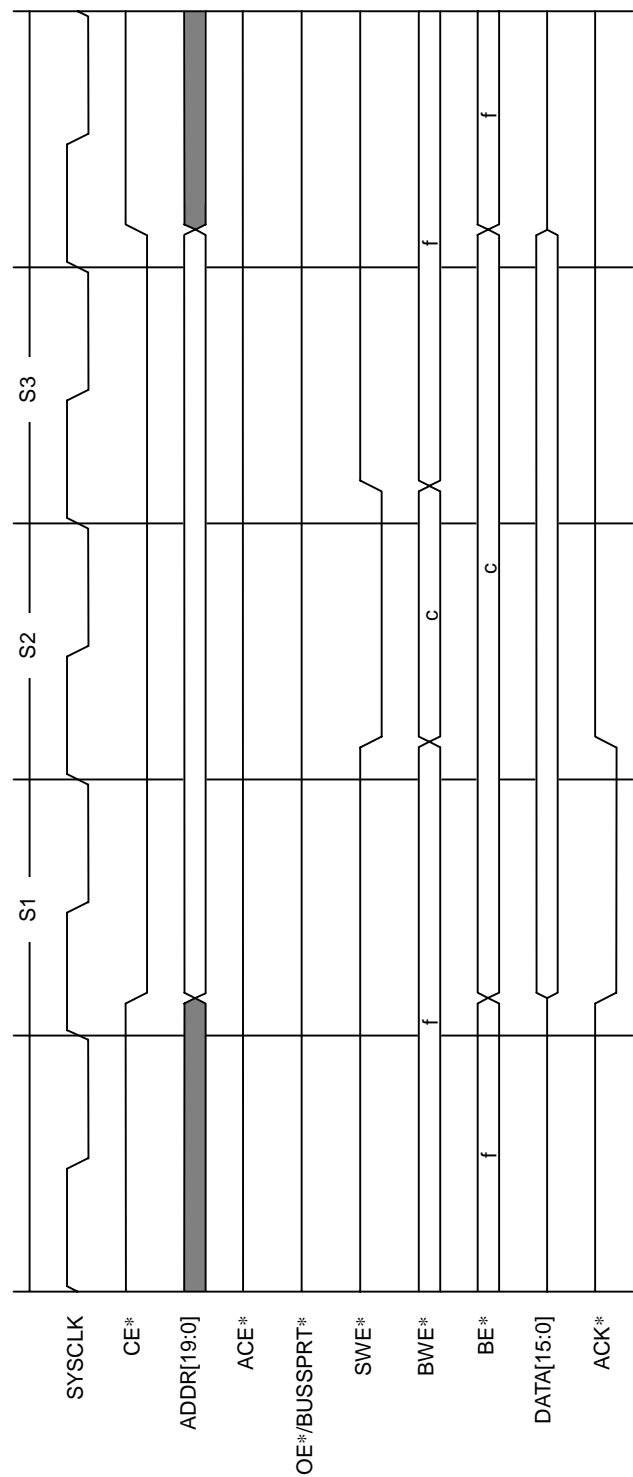


Figure 7.5.11 Half-word Single Write (PWT: WT=0, SHWT=0, Normal, 16-bit Bus)

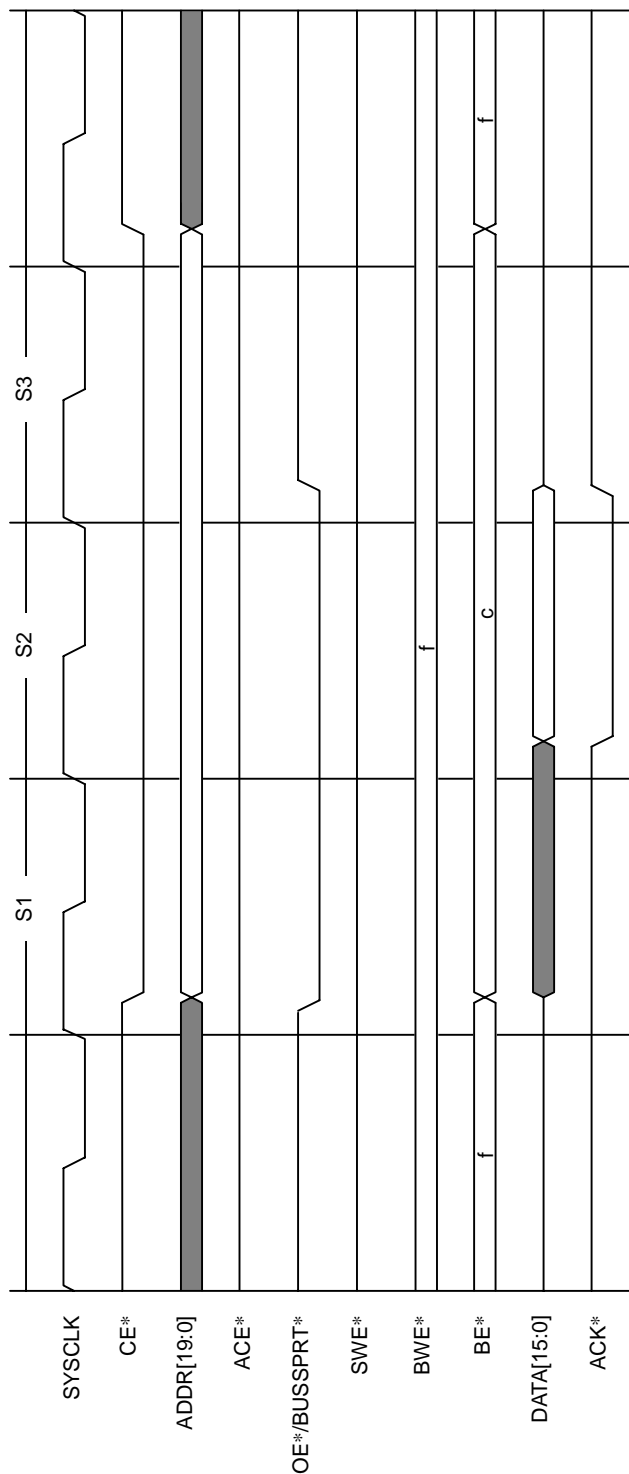


Figure 7.5.12 Half-word Single Read (PWT: WT=0, SHWT=0, Normal, 16-bit Bus)

7.5.5 Normal Mode Access (Burst, 16-bit Bus)

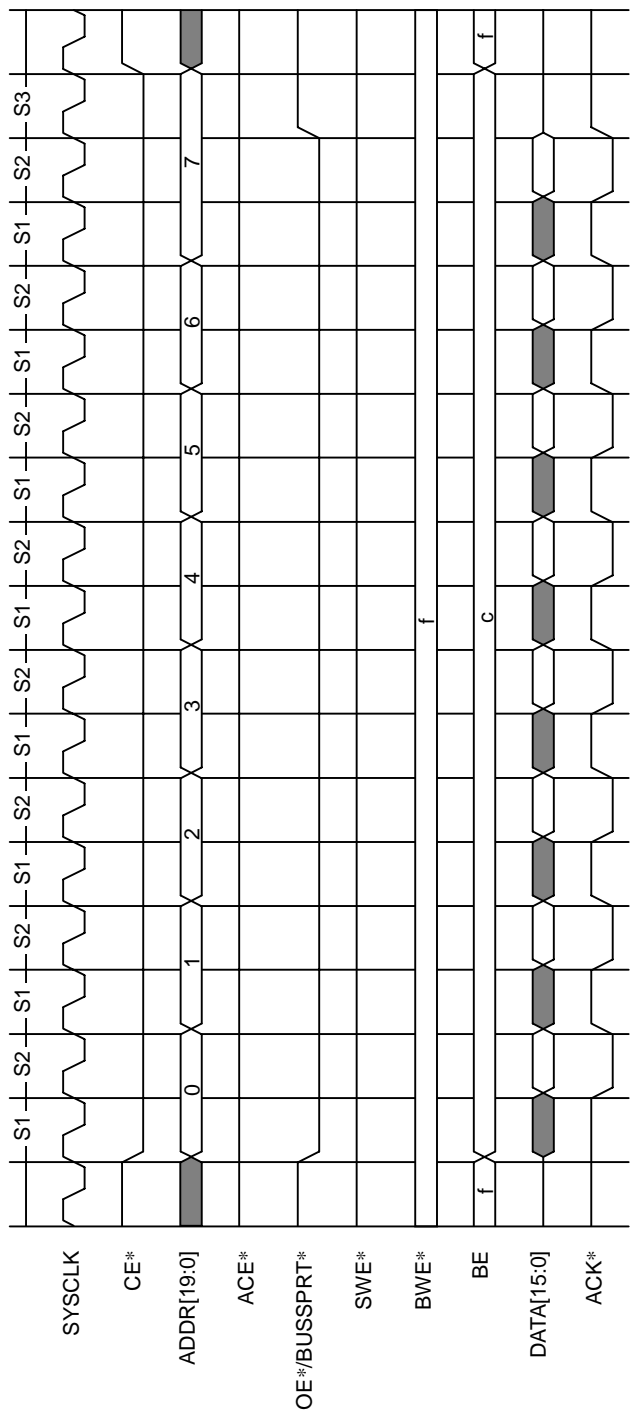


Figure 7.5.13 4-word Burst Read (PWT: WT=0, SHWT=0, Normal, 16-bit Bus)

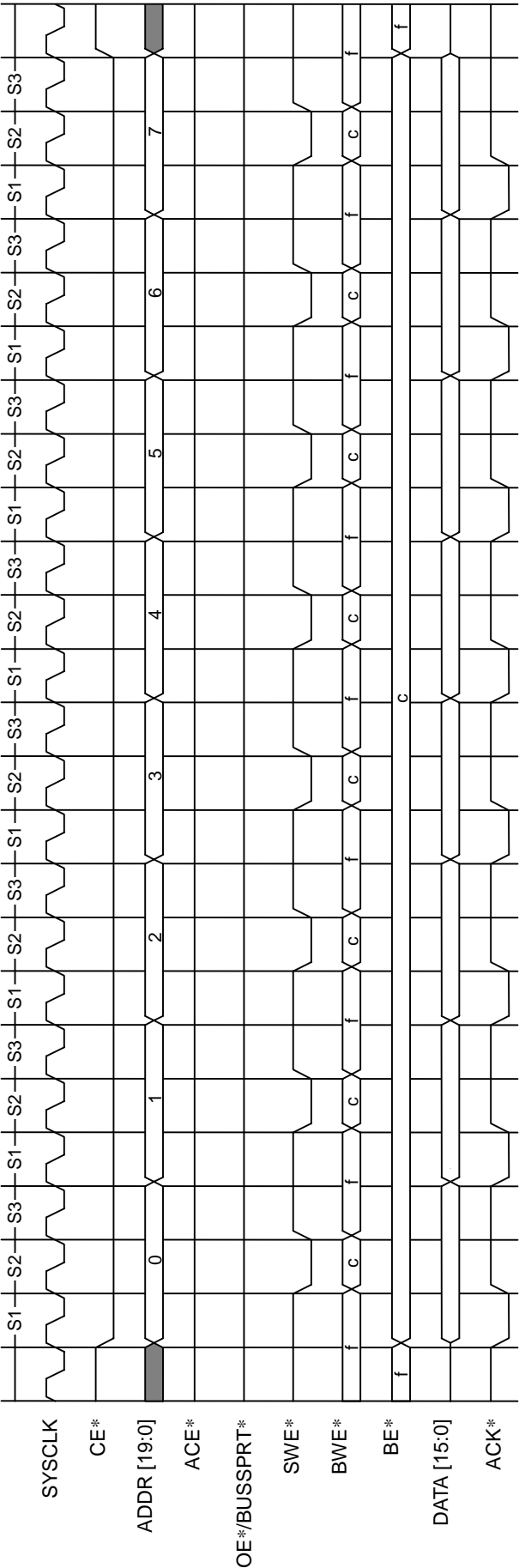


Figure 7.5.14 4-word Burst Write (PWT: WT=0, SHWT=0, Normal, 16-bit Bus)

7.5.6 Normal Mode Access (Single, 8-bit Bus)

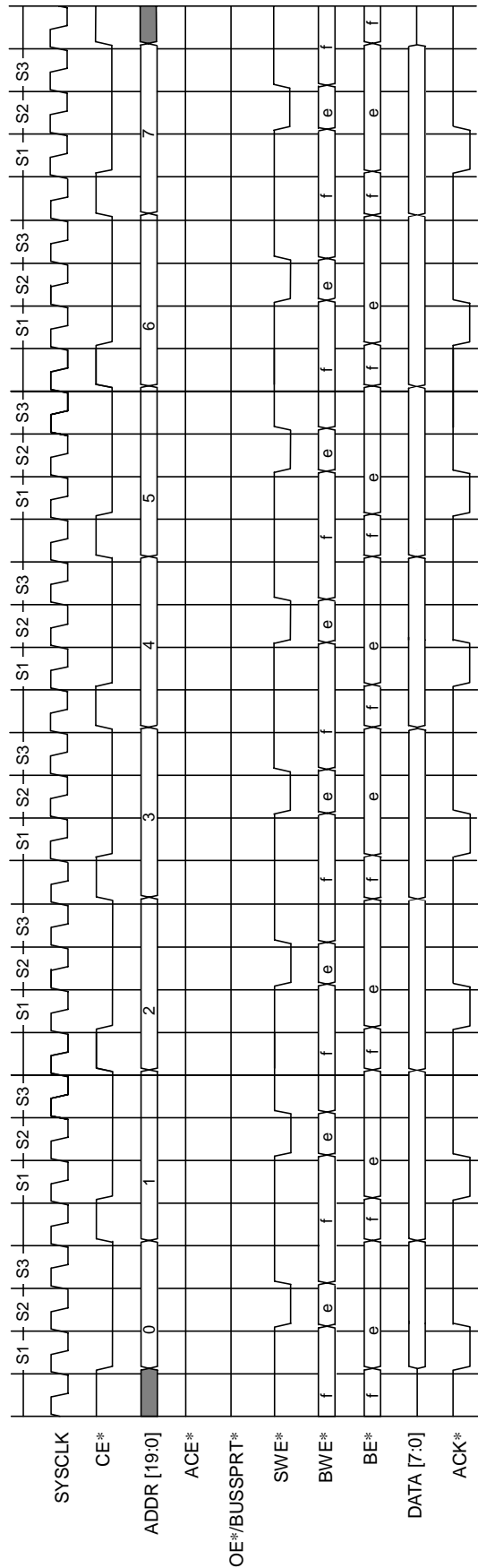


Figure 7.5.15 Double-word Single Write (PWT: WT=0, SHWT=0, Normal, 8-bit Bus)

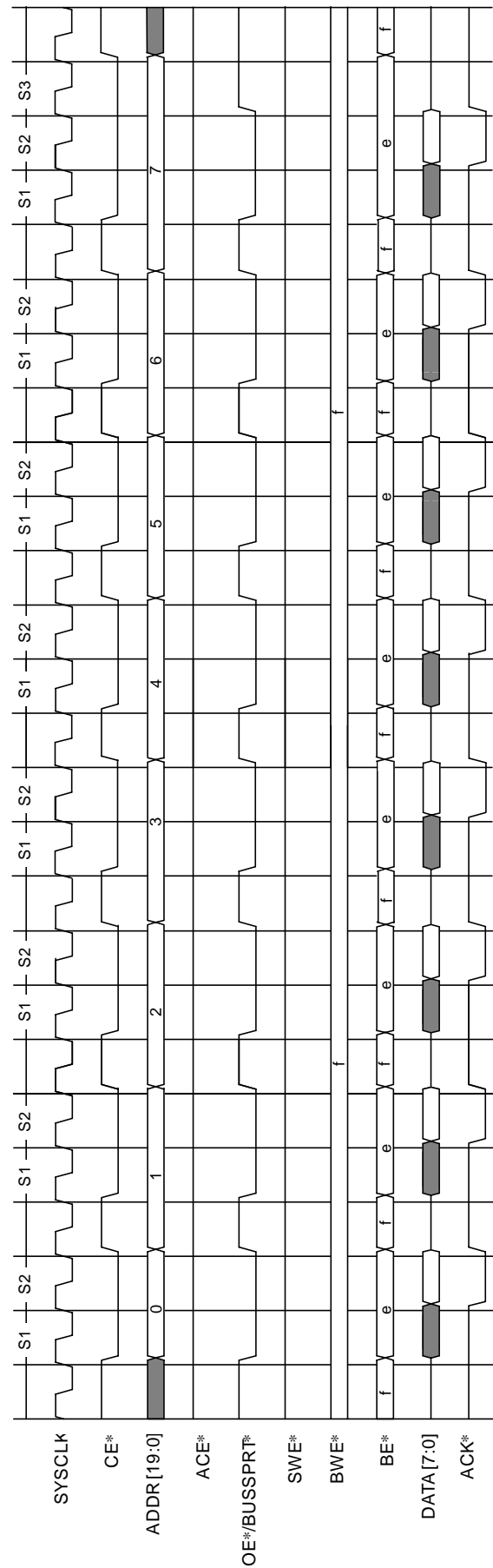


Figure 7.5.16 Double-word Single Read (PWT: WT=0, SHWT=0, Normal, 8-bit Bus)

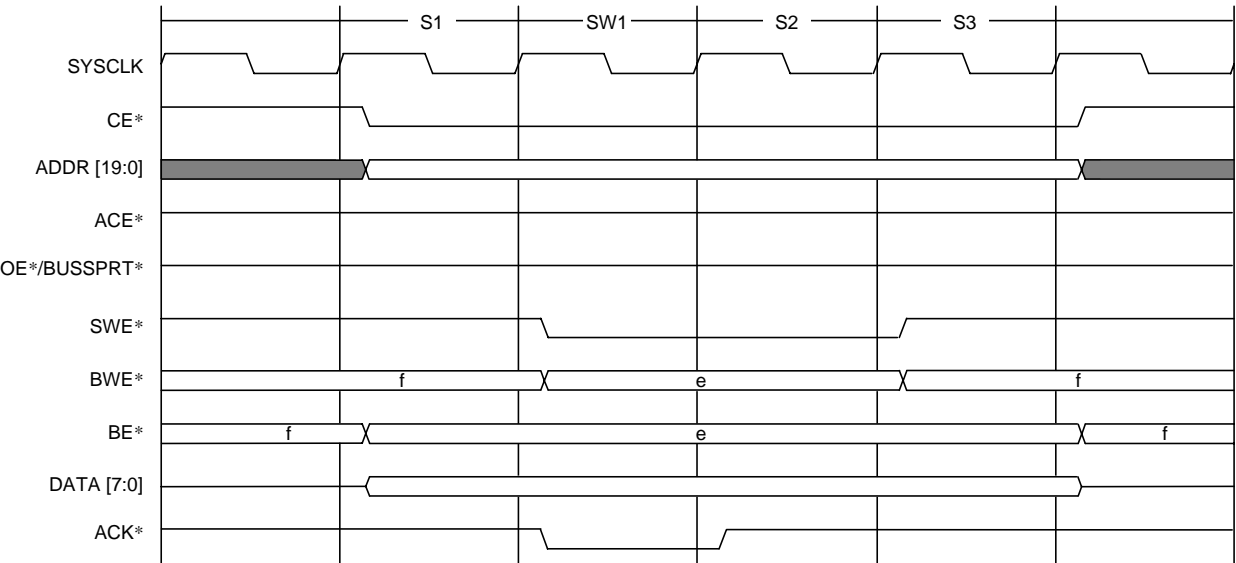


Figure 7.5.17 1-byte Single Write (PWT: WT=1, SHWT=0, Normal, 8-bit Bus)

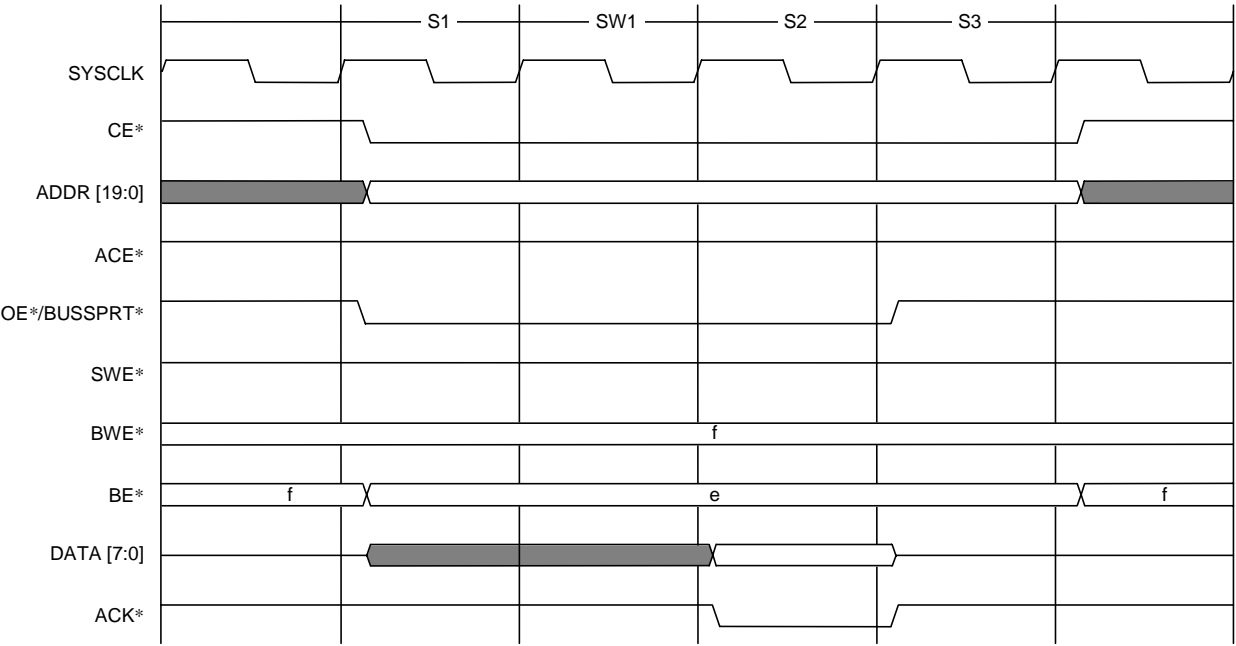


Figure 7.5.18 1-byte Single Read (PWT: WT=1, SHWT=0, Normal, 8-bit Bus)

7.5.7 Normal Mode Access (Burst, 8-bit Bus)

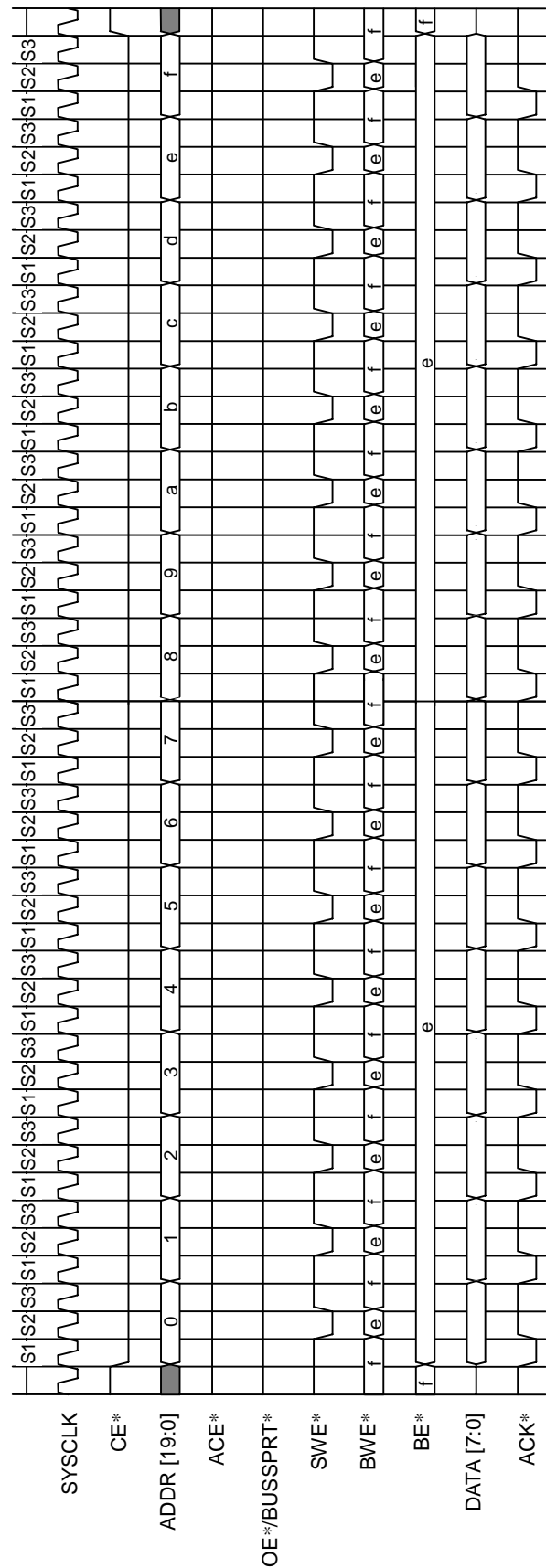


Figure 7.5.19 4-word Burst Write (PWT: WT=0, SHWT=0, Normal, 8-bit Bus)

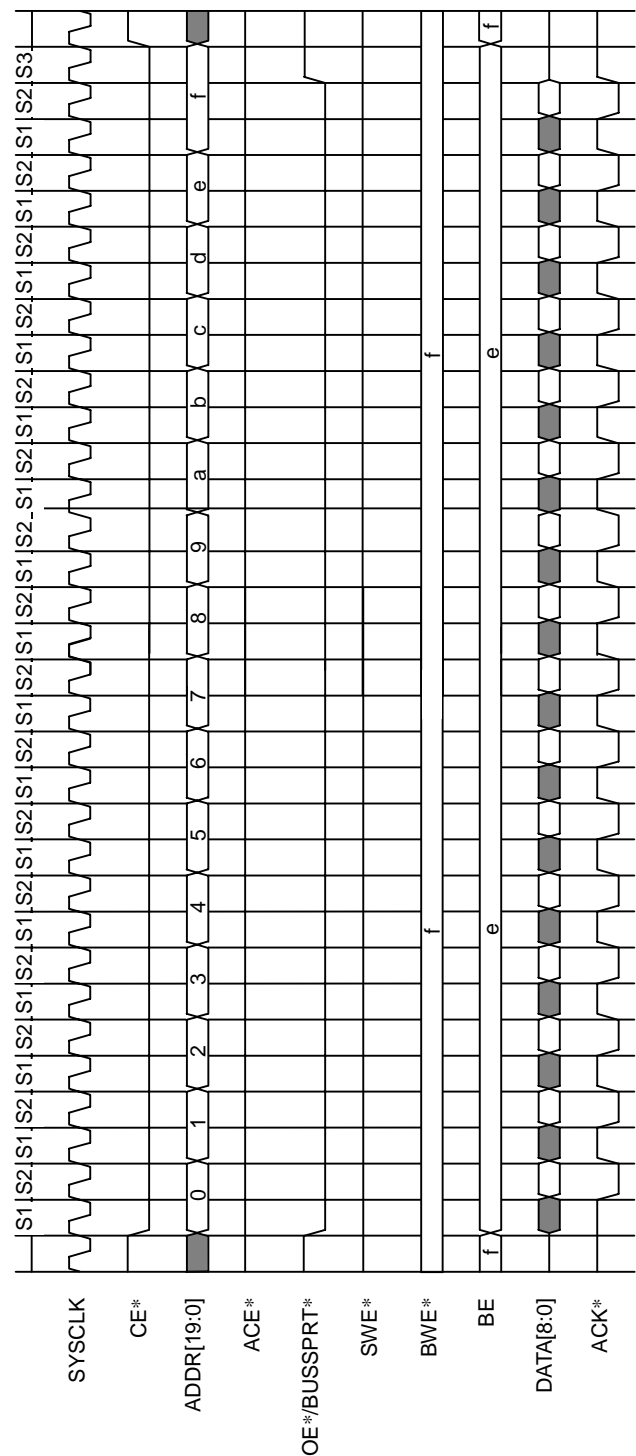


Figure 7.5.20 4-word Burst Read (PWT: WT=0, SHWT=0, Normal, 8-bit Bus)

7.5.8 Page Mode Access (Burst, 32-bit Bus)

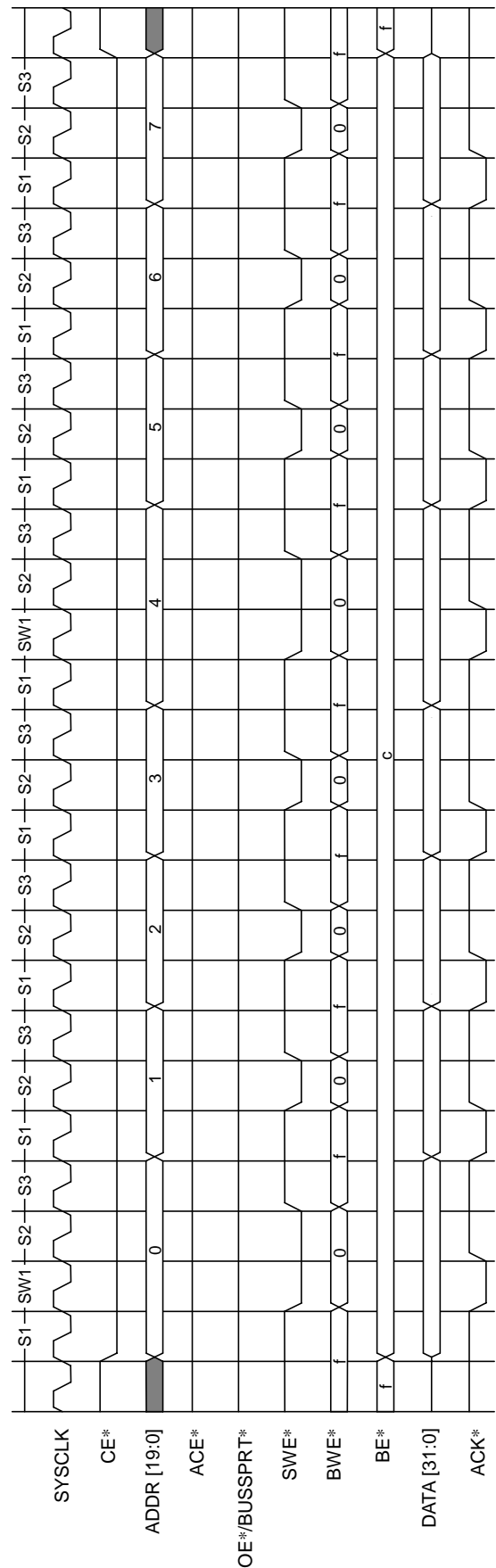


Figure 7.5.21 8-word Burst Write (WT=1, PWT=0, SHWT=0, 4-page, 32-bit Bus)

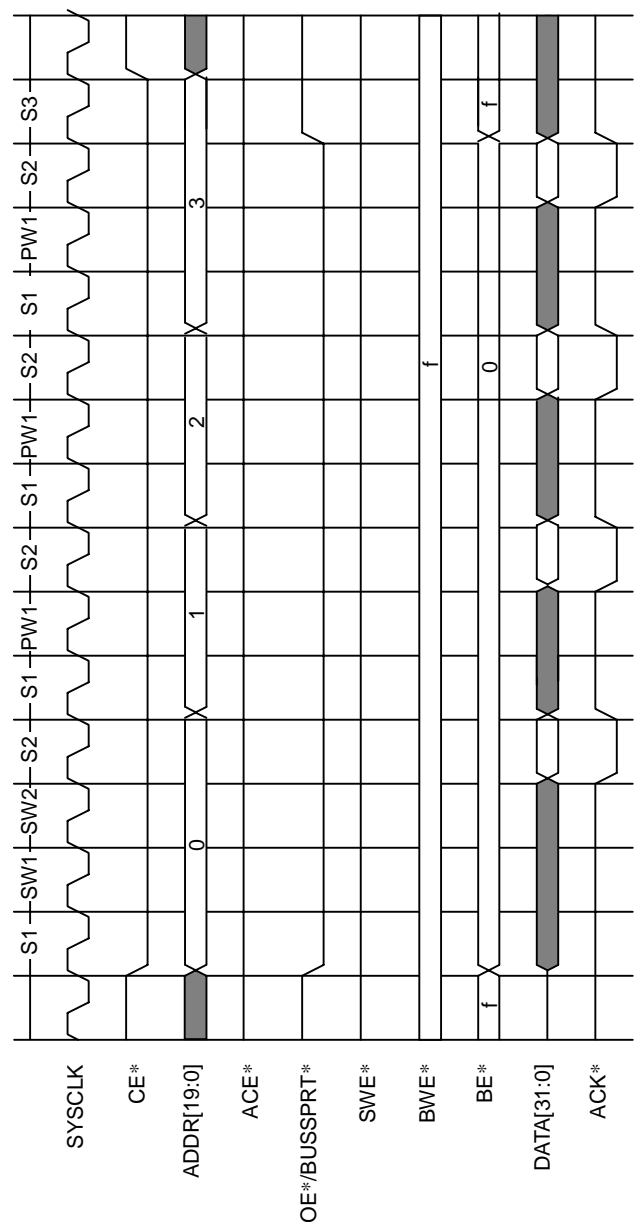
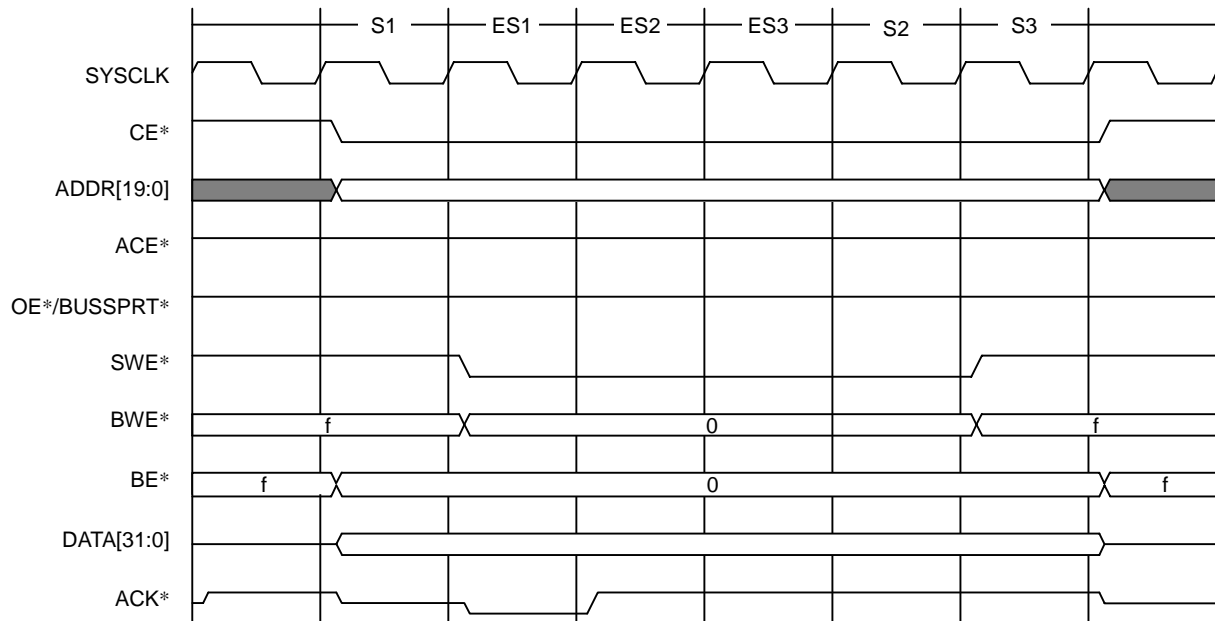


Figure 7.5.22 4-word Burst Read (WT=2, PWT=1, SHWT=0, 4-page, 32-bit Bus)

7.5.9 External ACK Mode Access (32-bit Bus)



Note 1: The TX4927 sets the ACK* signal to High Impedance in the S1 State.

Note 2: External devices drive the ACK* signal to Low (assert the signal) until the ES1 State.

Note 3: External devices drive the ACK* signal to High (deassert the signal) in the ES2 State. If an external device is late in asserting ACK*, then the Wait State is inserted for the amount of time the external device is late. If a certain condition is met, it is okay for the ACK* signal to be driven to Low for 1 clock cycle or more. See 7.3.7.4 ACK* Input Timing (External ACK Mode) for more information.

Figure 7.5.23 1-word Single Write (0 Wait, SHWT=0, External ACK*, 32-bit Bus)

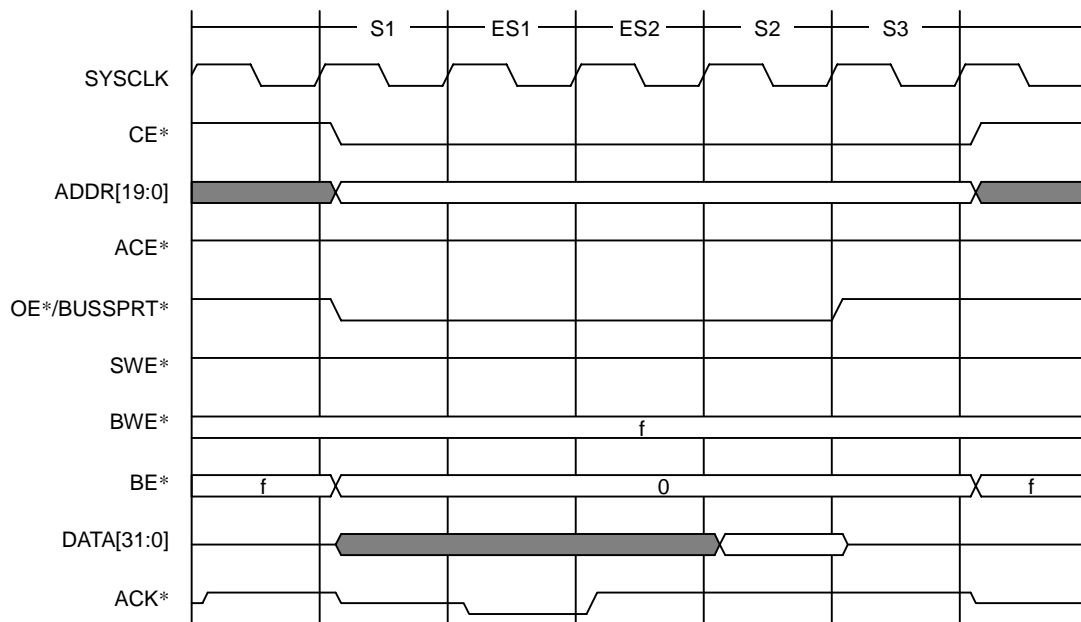


Figure 7.5.24 1-word Single Read (0 Wait, SHWT=0, External ACK*, 32-bit Bus)

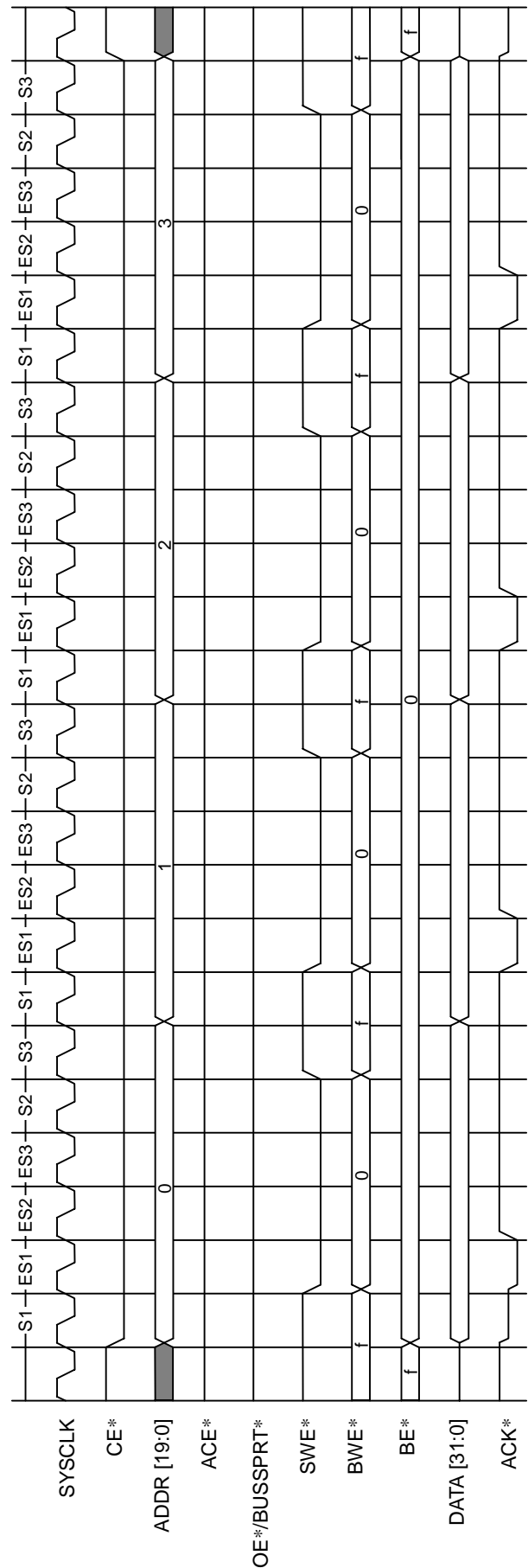


Figure 7.5.25 4-word Burst Write (0 Wait, SHWT=0, External ACK*, 32-bit Bus)

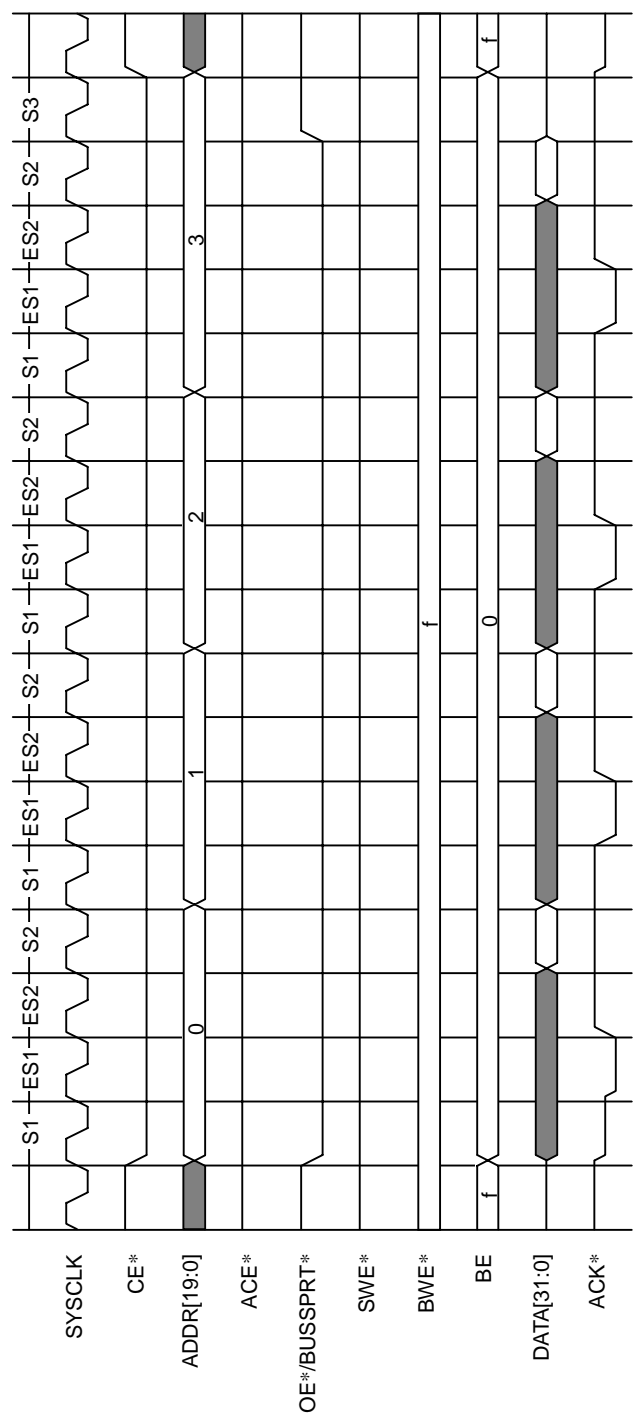
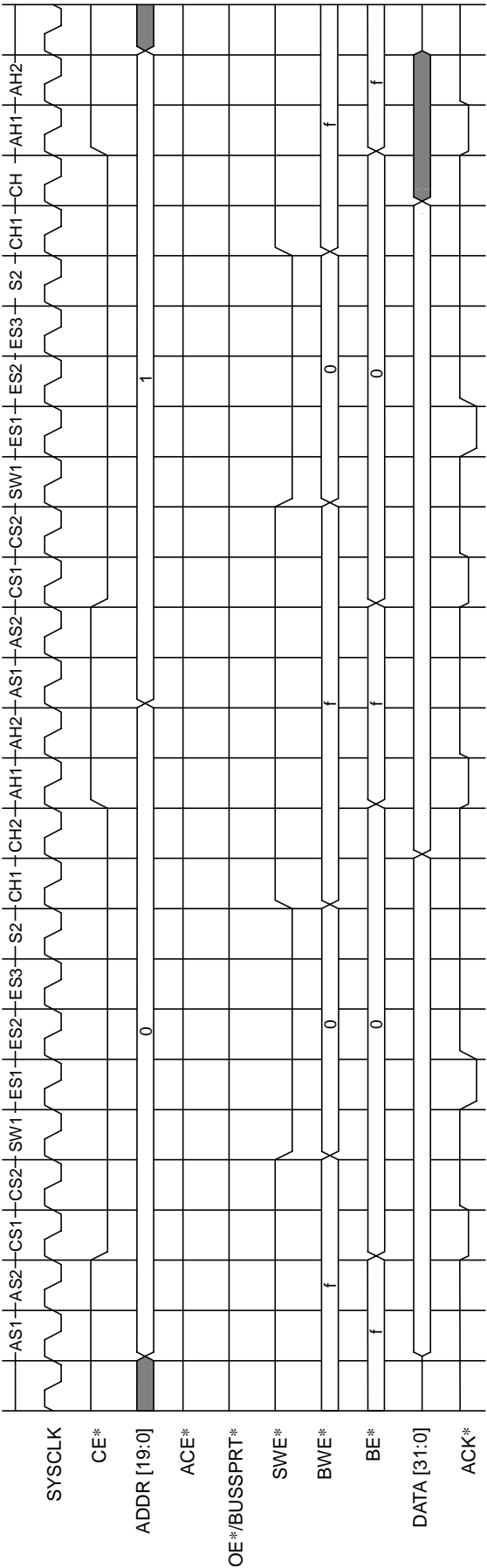
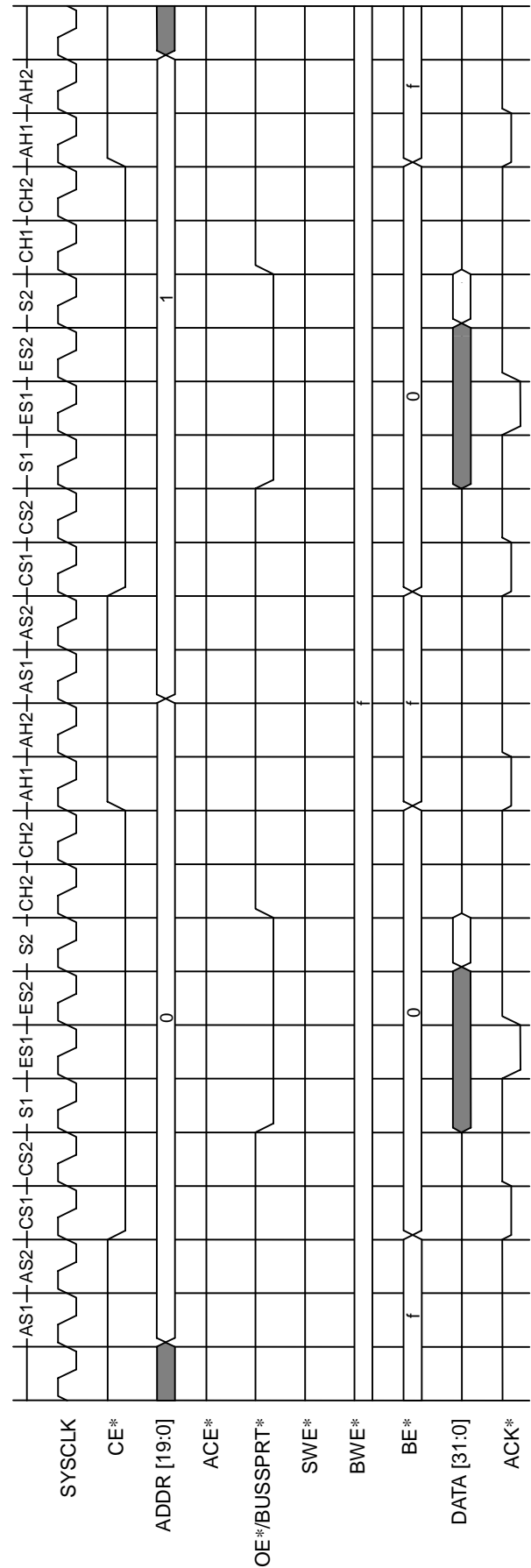


Figure 7.5.26 4-word Burst Read (0 Wait, SHWT=0, External ACK*, 32-bit Bus)



Note: The TX4927 drives the ACK* signal when in the AH2, AS1, or AS2 State.

Figure 7.5.27 Double-word Single Write (1 Wait, SHWT=2, External ACK*, 32-bit Bus)



Note: The TX4927 drives the ACK* signal when in the AH2, AS1, or AS2 State.

Figure 7.5.28 Double-word Single Read (0 Wait, SHWT=2, External ACK*, 32-bit Bus)

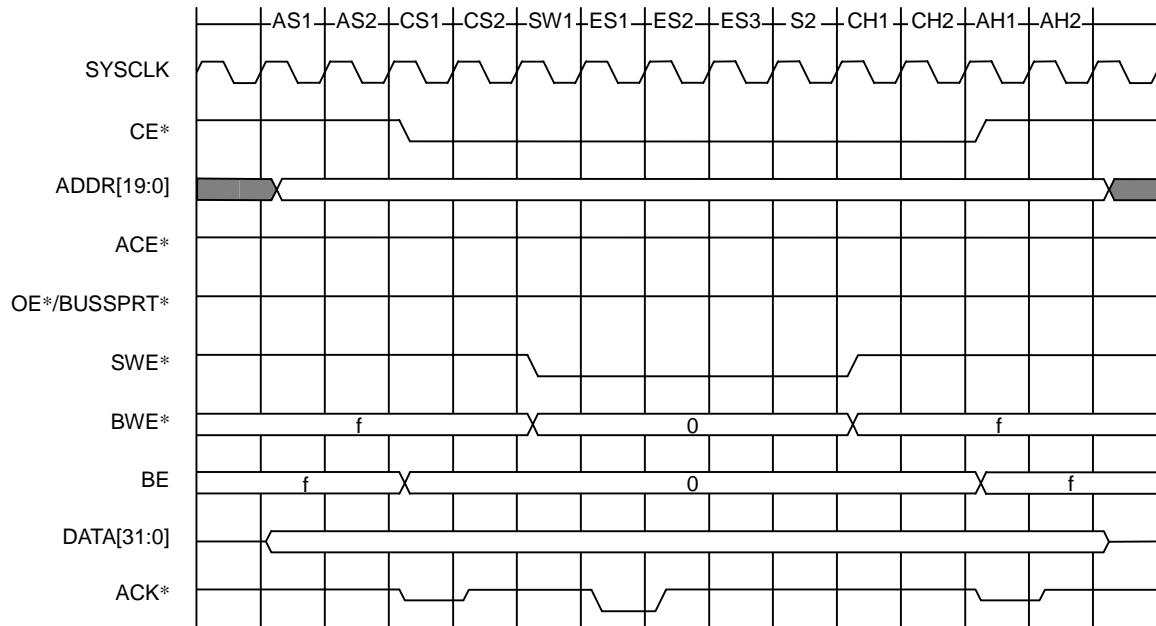


Figure 7.5.29 1-word Single Write (1 Wait, SHWT=2, External ACK*, 32-bit Bus)

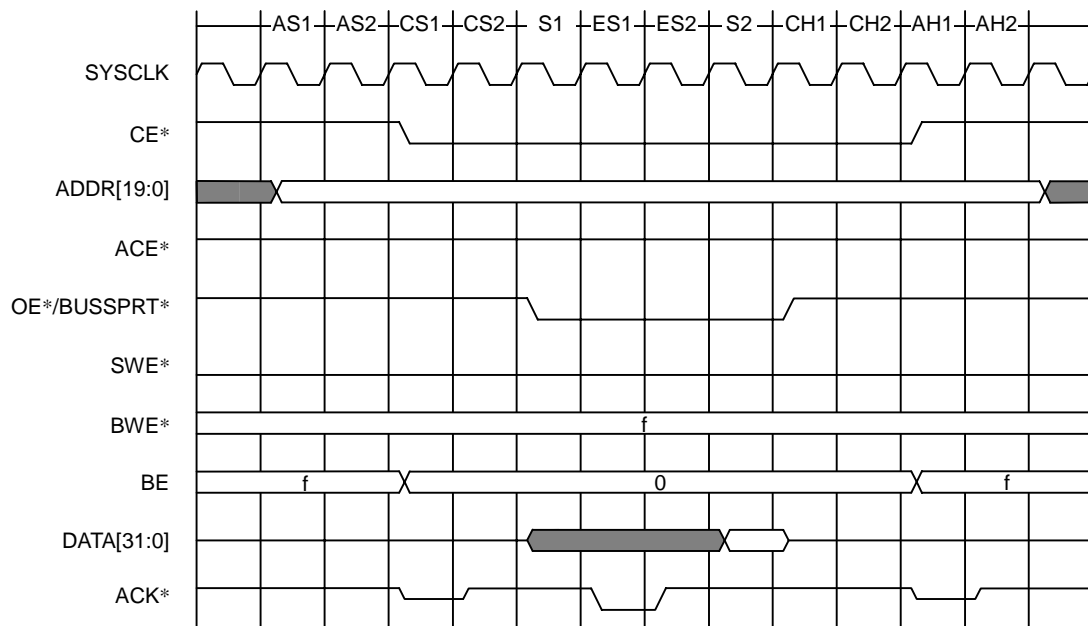


Figure 7.5.30 1-word Single Read (0 Wait, SHWT=2, External ACK*, 32-bit Bus)

7.5.10 READY Mode Access (32-bit Bus)

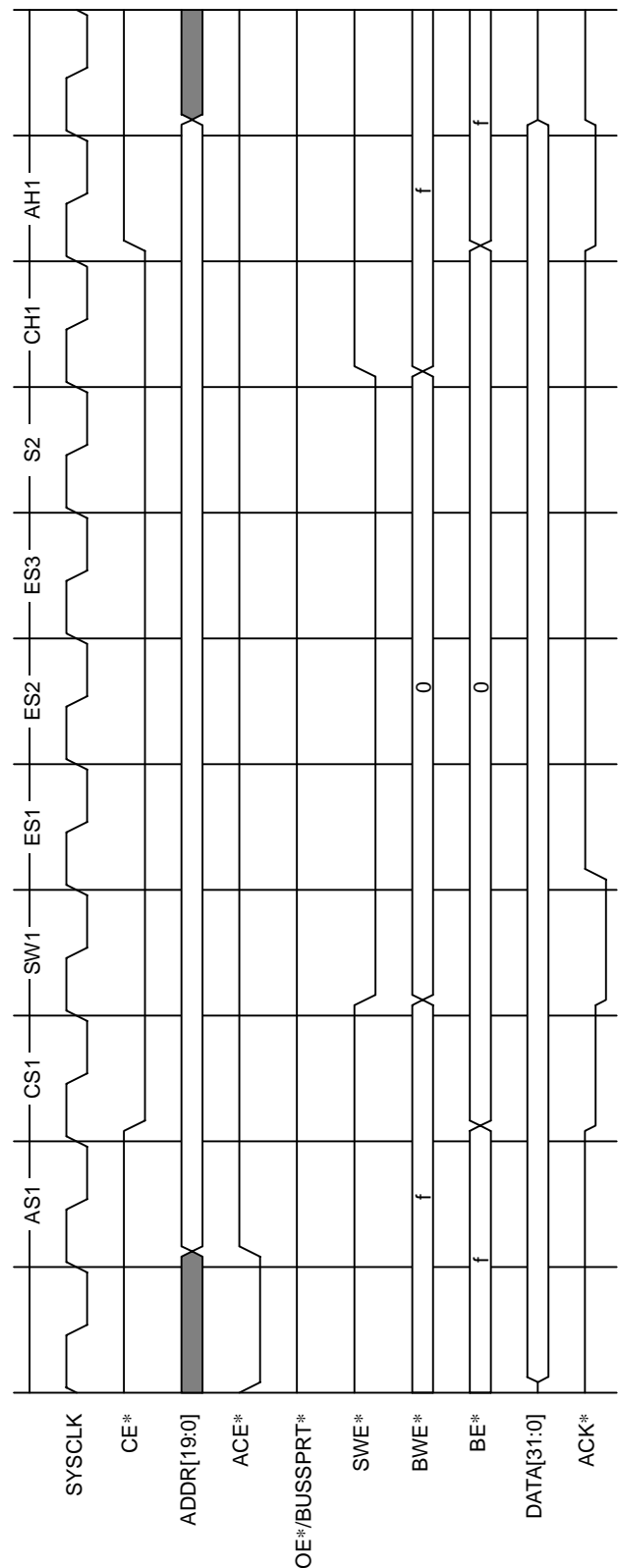


Figure 7.5.31 1-word Single Write (PWT: WT=2, SHWT=1, READY, 32-bit Bus)

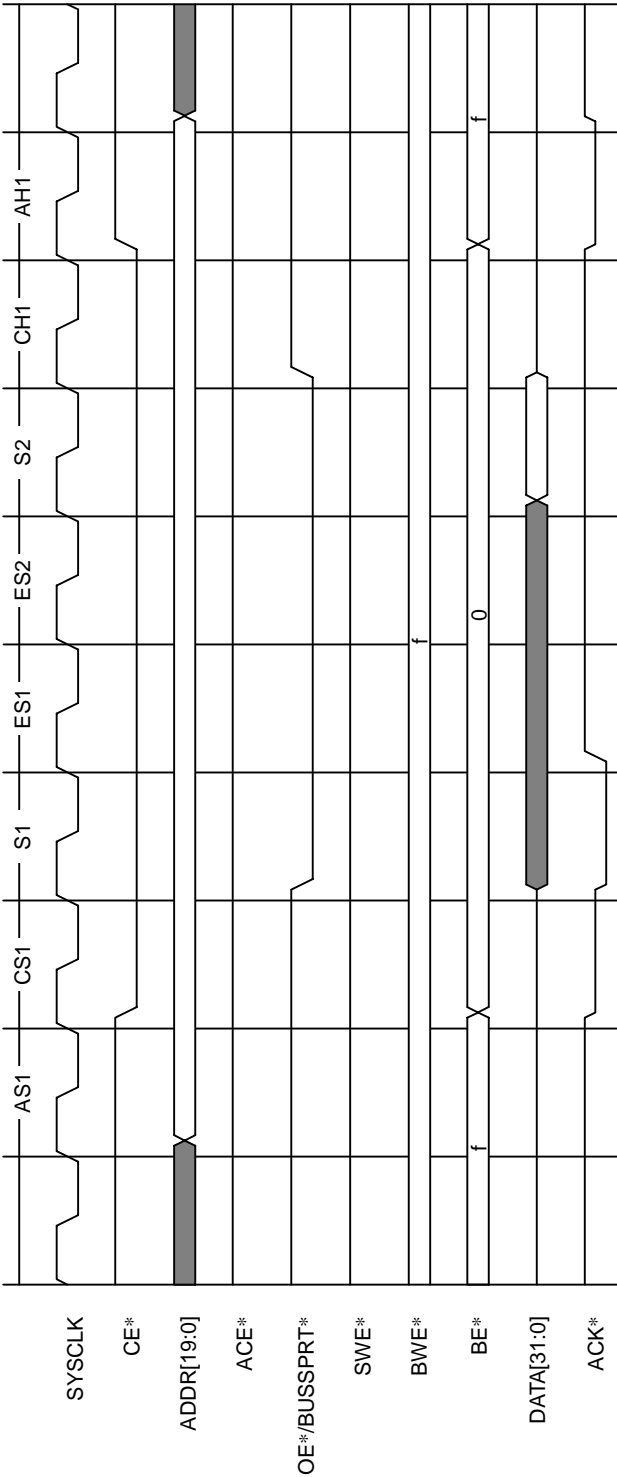


Figure 7.5.32 1-word Single Read (PWT: WT=2, SHWT=1, READY, 32-bit Bus)

7.6 Flash ROM, SRAM Usage Example

Figure 7.6.1 illustrates example Flash ROM connections, and Figure 7.6.2 illustrates example SRAM connections. Also, Figure 7.6.3 illustrates example connections with the SDRAM and the bus separated.

Since connecting multiple memory devices such as SDRAM and ROM onto a single bus increases the load, 100 MHz class high-speed SDRAM access may not be performed normally. As a corrective measure, there is a way of reducing the bus load by connecting a device other than SDRAM via a buffer. If such a method is employed, directional control becomes necessary since the data becomes bidirectional.

The TX4927 prepares the BUSSPRT* signal for performing data directional control (see Figure 7.6.3). BUSSPRT* is asserted when the External Bus Controller channel is active and a Read operation is being performed.

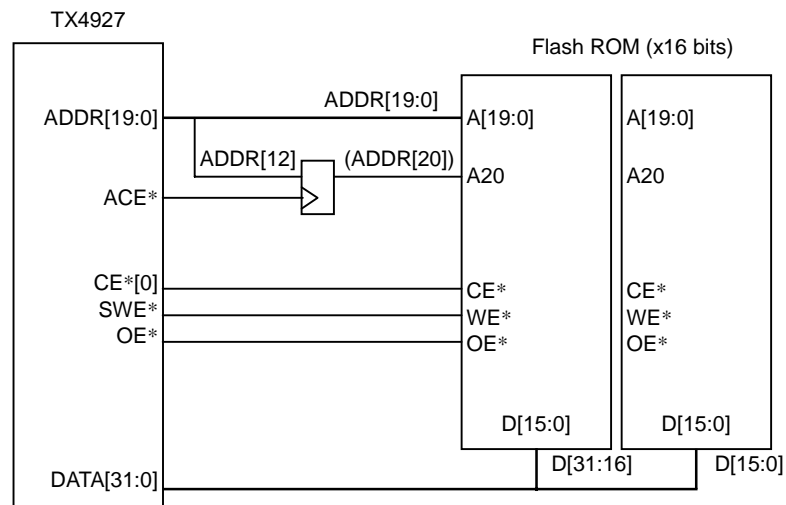


Figure 7.6.1 Flash ROM (x16 Bits) Connection Example (32-bit Data Bus)

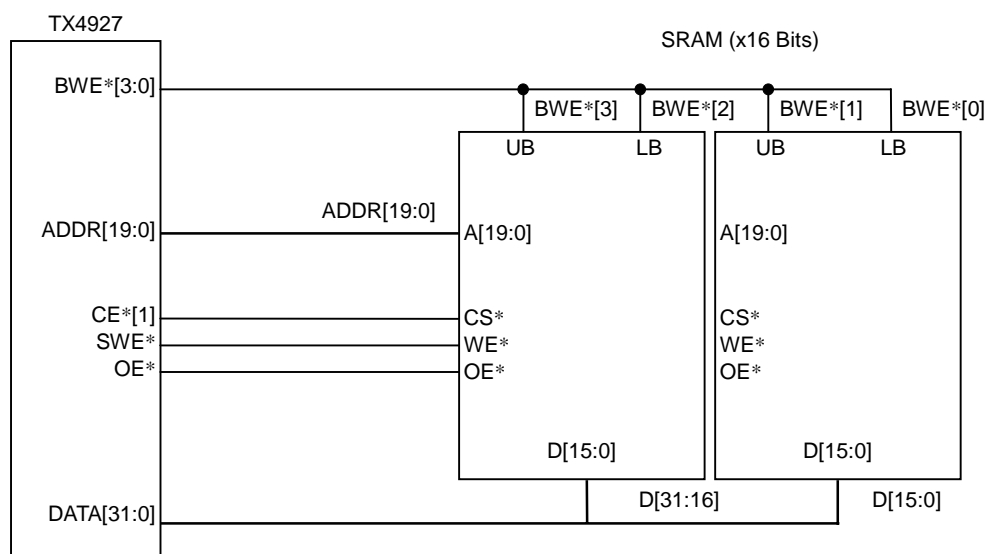


Figure 7.6.2 SRAM (x16 Bits) Connection Example (32-bit Data Bus)

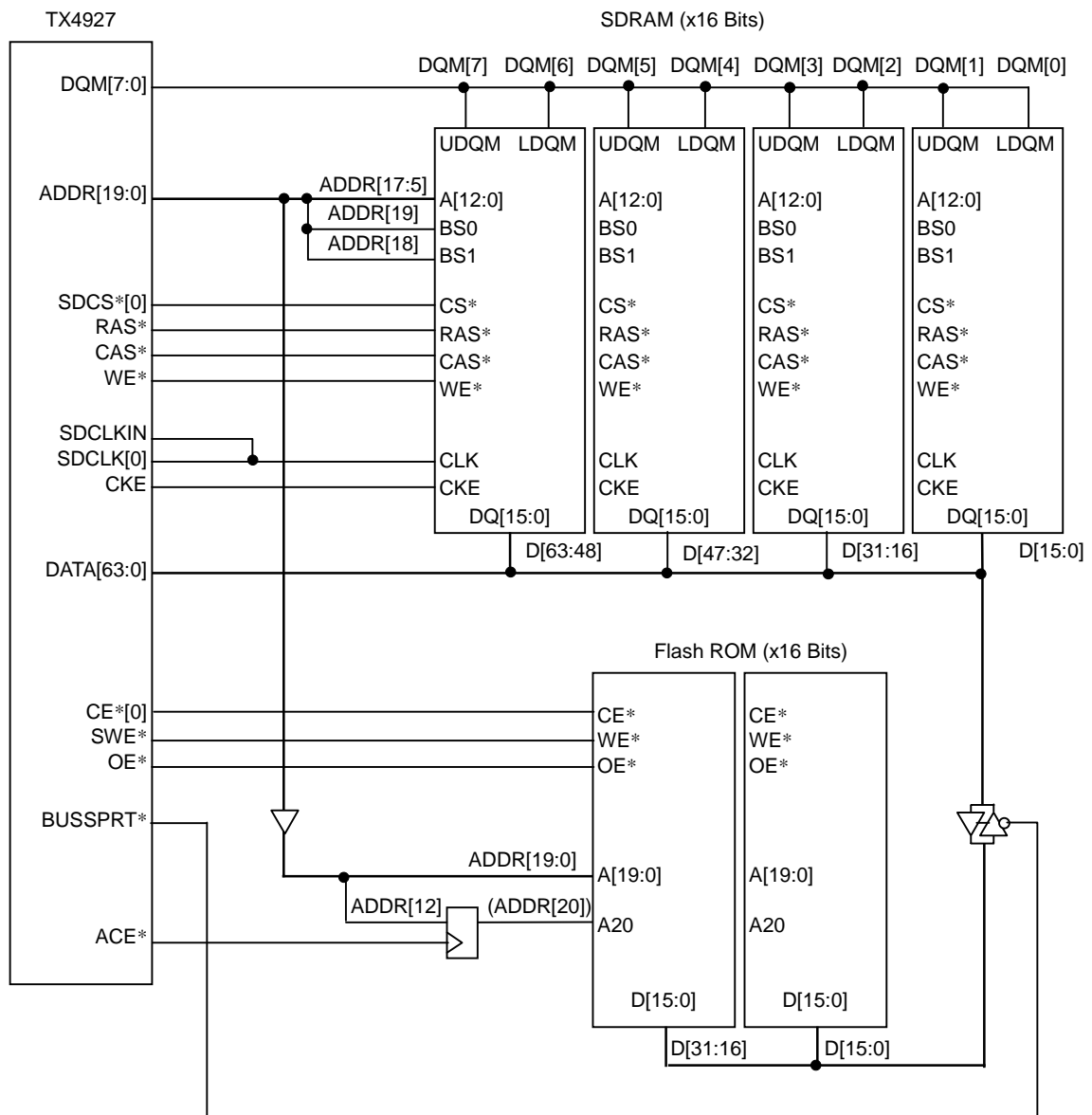


Figure 7.6.3 Connection Example with SDRAM and the Bus Separated

8. DMA Controller

8.1 Features

The TX4927 contains a four-channel DMA Controller (DMAC) that executes DMA (Direct Memory Access) with memory and I/O devices.

The DMA Controller has the following characteristics.

- Has four on-chip DMA channels
- Supports external I/O devices with 8-, 16-, and 32-bit Data Bus widths and transfer between memory devices.
- Supports single address transfer (Fly-by DMA) and dual address transfer when in the external I/O DMA Transfer Mode that is operated by external request signals
- Supports on-chip Serial I/O Controllers and AC-Link Controllers
- Supports Memory-Memory Copy modes that do not have address boundary limitations. Burst transfer of up to eight double words is possible for each Read or Write operation.
- Supports Memory Fill mode that writes double-word data to the specified memory region
- Supports Chained DMA Transfer
- On-chip signed 24-bit address count up registers for both the source address and destination address
- On-chip 26-bit Byte Count Register for each channel
- One of two methods can be selected for determining access priority among multiple channels: Round Robin or Fixed Priority
- Big Endian or Little Endian mode can be set separately for each channel

8.2 Block Diagram

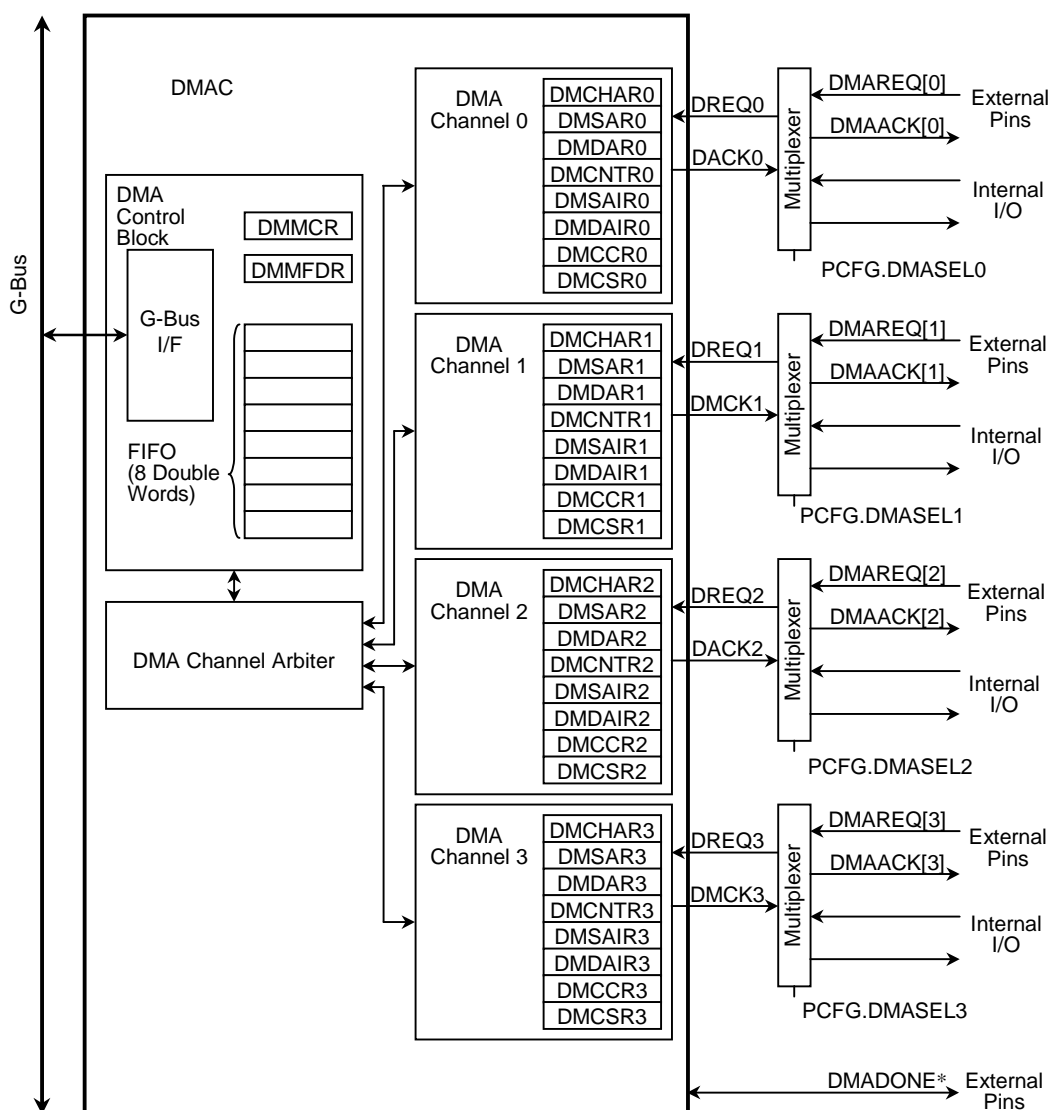


Figure 8.2.1 DMA Controller Block Diagram

8.3 Detailed Explanation

8.3.1 Transfer Mode

The DMA Controller supports five transfer mode types (refer to Table 8.3.1 below). The setting of the External Request bit (DMCCRN.EXTRQ) of the DMA Channel Control Register selects whether transfer with an I/O device is a DMA transfer.

- I/O DMA Transfer Mode (DMCCRN.EXTRQ = “1”)

Perform DMA transfer with either an external device connected to the External Bus Controller or an on-chip I/O device (ACLC or SIO).
- Memory Transfer Mode (DMCCRN.EXTRQ = “0”)

Either copies data between memory devices or fills data in memory.

Table 8.3.1 DMA Controller Transfer Modes

Transfer Mode	DMCCRN EXTREQ	PCFG DMASEL	DMCCRN SNGAD	DMSAR	DMDAR	Ref.
External I/O (Single Address)	1	00	1	√	—	8.3.3 8.3.7
External I/O (Dual Address)	1	00	0	√	√	8.3.3 8.3.8
Internal I/O	1	01 (SIO) 10, 11 (ACLC)	0	√	√	8.3.4 8.3.8
Memory-Memory Copy	0	—	0	√	√	8.3.4 8.3.8
Fill Memory	0	—	1	√	—	8.3.6 8.3.7

8.3.2 On-chip Registers

The DMA Controller has two shared registers that are shared by four channels. Section 8.4 explains each register in detail.

- Shared Registers
 - DMMCR: DMA Master Control Register
 - DMMFDR: DMA Memory Fill Data Register
- DMA Channel Register
 - DMCHARn: DMA Chained Address Register
 - DMSARn: DMA Source Address Register
 - DMDARn: DMA Destination Address Register
 - DMCNTRn: DMA Count Register
 - DMSAIRn: DMA Source Address Increment Register
 - DMDAIRn: DMA Destination Address Increment Register
 - DMCCRN: DMA Channel Control Register
 - DMCSRn: DMA Channel Status Register

8.3.3 External I/O DMA Transfer Mode

The External I/O DMA Transfer Mode performs DMA transfer with external I/O devices that are connected to the External Bus Controller.

8.3.3.1 External Interface

External I/O devices signal DMA requests to the DMA Controller by asserting the DMA Transfer Request Signal (DMAREQ[n]). On the other hand, the DMA Controller accesses external I/O devices by asserting the DMA Transfer Acknowledge Signal (DMAACK[n]).

The DMA Transfer Request signal (DMAREQ[n]) can use the Request Polarity bit (REQPOL) of the DMA Channel Control Register (DMCCRn) to select the signal polarity for each channel, and can use the Edge Request bit (EGREQ) to select either edge detection or level detection for each channel. The DMA Transfer Acknowledge signal (DMAACK[n]) can also use the Acknowledge Polarity bit (ACKPOL) to select the polarity.

Please assert/deassert the DMAREQ[n] signal as follows below.

- When level detection is set (DMCCRn.EGREQ = 0)

The DMAREQ[n] signal must be continuously asserted until one SYSCLK cycle after the DMAACK[n] signal is asserted. Also, the DMAREQ[n] signal must be deasserted before the CE*/CS* signal is deasserted. If this signal is asserted too soon, DMA transfer will not be performed. If this signal is asserted or deasserted too late, unexpected DMA transfer may result.

During Dual Address transfer, we recommend detecting assertion of the CE* signal for the external I/O device that is currently asserting DMAACK[n], then deasserting DMAREQ[n].

- When edge detection is set (DMCCRn.EGREQ = 1)

Please set up assertion of the DMAREQ[n] signal so the DMAREQ[n] signal is asserted after the DMAACK[n] signal corresponding to a previously asserted DMAREQ[n] signal is deasserted. The DMAREQ[n] signal will not be detected even if it is asserted before DMAACK[n] is deasserted.

Figure 8.3.1 is a timing diagram that shows the timing of external DMA access. In this timing diagram, both the DMAREQ[n] signal and the DMAACK[n] signal are set to Low active (DMCCRn.REQPL = 0, DMCCRn.ACKPOL = 0).

The DMAACK[n] and DMADONE[n] signals, which are DMA control signals, are synchronized to SDCLK. When these signals are used by an external I/O device that is synchronous to SYSCLK, it is necessary to take clock skew into account.

The DMAACK[n] signal is asserted either at the SYSCLK cycle, the same as with assertion of the CE*/CS* signal, or before that. In addition, it is deasserted after the last ACK*/READY signal is deasserted.

When the DMADONE* signal (refer to 8.3.3.4) is used as an output signal, it is asserted for at least one SYSCLK cycle while the DMAACK[n] signal is asserted either during the same SYSCLK cycle that the CE*/CS* signal is deasserted or during a subsequent SYSCLK cycle. When the DMADONE* signal is used as an input signal, it must be asserted for one SYSCLK cycle while the DMAACK[n] signal is being asserted.

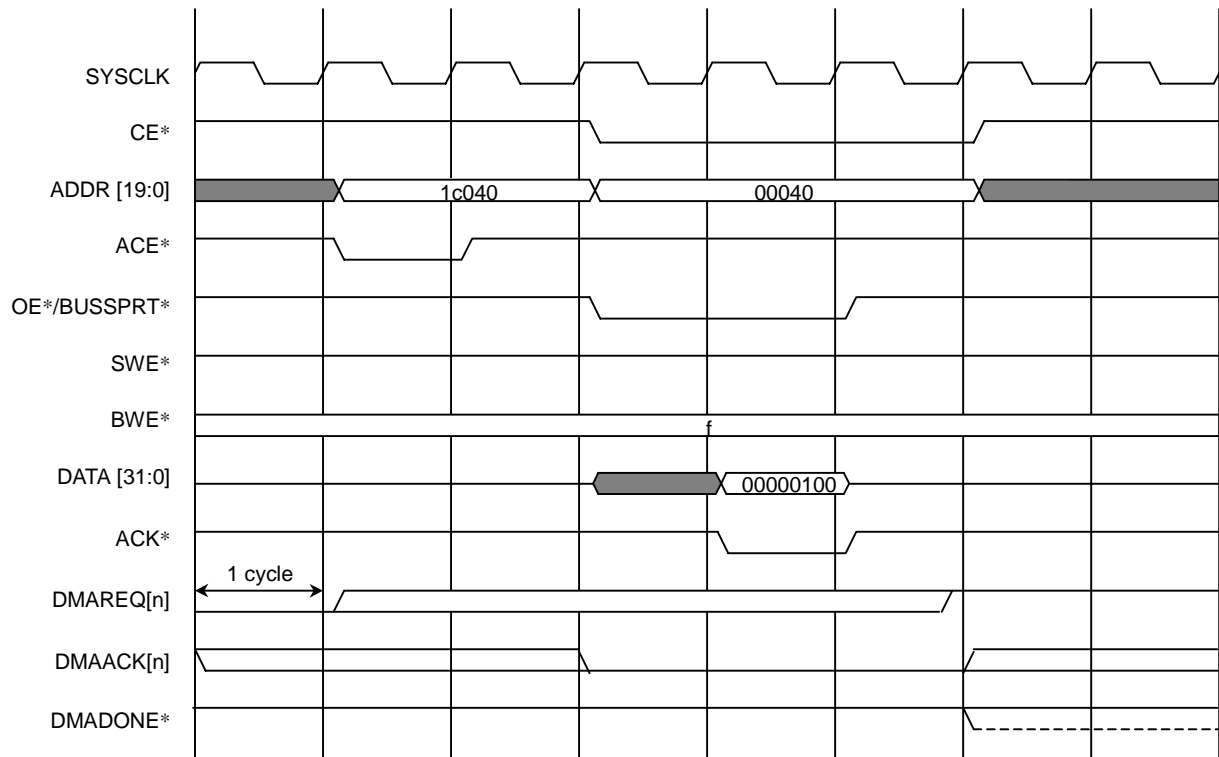


Figure 8.3.1 External I/O DMA Transfer (Single Address, Level Request)

8.3.3.2 Dual Address Transfer

If the Single Address bit (DMCCRn.SNGAD) has been cleared, access to external I/O devices and to external memory is each performed continuously. Each access is the same as normal access except when the DMAACK[n] signal is asserted.

Please refer to “8.3.8 Dual Address Transfer” for information regarding setting the register.

8.3.3.3 Single Address Transfer (Fly-by DMA)

If the Single Address bit (DMCCRn.SNGAD) is set, either data reading from an external I/O device and data writing to external memory or data reading from external memory and data writing to an external I/O device is performed simultaneously. The following conditions must be met in order to perform Single Address transfer.

- The data bus widths of the external I/O device and external memory match
- Data can be input/output to/from the external I/O device and external memory during the same clock cycle

The Transfer Direction bit (MEMIO) of the DMA Channel Control Register (DMCCRn) specifies the transfer direction.

- From memory to an external I/O device (DMCCRn.MEMIO = “1”)

External memory Read operation to an address specified by the DMA Source Address Register (DMSARn) is performed simultaneously to assertion of the DMAACK[n] signal.

- Single Address transfer from memory to an external I/O device (DMCCRn.MEMIO = "0")
External memory Write operation to an address specified by the DMA Source Address Register (DMSARn) is performed simultaneously to assertion of the DMAACK[n] signal. At this time, the external I/O device drives the DATA signal instead of the TX4927.

Special attention must be paid to the timing design when the bus clock frequency is high or when performing Burst transfer. Single Address transfer using Burst transfer with SDRAM is not recommended.

8.3.3.4 DMADONE* Signal

The DMADONE* signal operates as either the DMA stop request input signal or the DMA done signalling output signal, or may operate as both of these signals depending on the setting of the DONE Control Field (DNCTRL) of the DMA Channel Control Register (DMCCRn).

The DMADONE* signal is shared by four channels. The DMADONE* channel is valid for a channel when the DMAACK[n] signal for that channel is asserted.

If the DMADONE* channel is set to be used as an output signal (DMCCRn.DNCTRL = 10/11), it will operate as follows depending on the setting of the Chain End bit (CHDN) of the DMA Channel Control Register (DMCCRn).

When the Chain End bit (CHDN) is set, the DMADONE* signal is only asserted when the DMAACK[n] signal for the last DMA transfer in the Link List Command Chain is asserted.

When the Chain End bit (CHDN) is cleared, the DMADONE* signal is asserted when the DMAACK[n] signal for the last data transfer in a DMA transfer specified by the current DMA Channel Register is asserted. Namely, if the Link List Command chain is used, there is one assertion at the end of each data transfer specified by each Descriptor.

If the DMADONE* signal is set to be used as an input signal (DMCCRn.DNCTRL = 01/11), DMA transfer can be set to end normally when the external device asserts the DMADONE* signal when the DMAACK[n] signal of channel *n* is asserted. DMADONE* is asserted during DMAACK[n] is not asserted, then unexpected operation occurs. When DMA transfer is terminated by the DMADONE* assertion of the external device, the External DONE Assert bit (DMCSRn.EXTDN) of the DMA Channel Status Register is set regardless of the setting of the Chain End bit (CHDN) of the DMA Channel Control Register (DMCCRn). Operation is as follows depending on the setting of the Chain End bit (CHDN).

When the Chain End bit (CHDN) is set, all DMA transfer for that chain is terminated. At this time, the Normal Chain End bit (NCHNC) and the Normal Transfer End bit (NTRNFC) of the DMA Channel Status Register are both set and the Transfer Active bit (DMCCRn.XFACT) of the DMA Channel Control Register is cleared.

When the Chain End bit (CHDN) is cleared, only DMA transfer specified by the current DMA Channel Register ends normally, and only the Normal Transfer End bit (NTRNFC) is set. When the Chain Enable bit (CHNEN) of the DMA Channel Control Register (DMCCRn) is set, chain transfer is executed and DMA transfer continues. When the Chain Enable bit (CHNEN) is cleared, the Transfer Active bit (DMCCRn.XFACT) is cleared and the Normal Chain End bit (NCHNC) is set.

Three clock cycles are required from external assertion of the DMADONE* signal to disabling of new DMA access. Operation will not stop even if the bus operation in progress is a Single transfer or a Burst transfer. For example, if the DMADONE* signal is asserted during Read operation of Dual Address transfer, the corresponding Write bus operation will also be executed.

If the DMADONE* pin is set to become both input and output for channel *n* (DMCCRn.DNCTRL = “11”), the DMADONE* signal becomes an open drain signal when the channel becomes active. When used by this mode, the DMADONE* signal must be pulled up by an external source. When in this mode, the External DONE Assert bit (DMCSRn.EXTDN) is not only set when asserted by an external device, but is also set when asserted by the TX4927.

8.3.4 Internal I/O DMA Transfer Mode

Performs DMA with the on-chip Serial I/O Controller and the AC-link Controller. Set the DMA Channel Control Register (DMCCRn) as follows.

- DMCCRn.EXTRQ = 1: I/O DMA Transfer mode
- DMCCRn.SNGAD = 0: Dual Address Transfer

Refer to “8.3.8 Dual Address Transfer” and “11.3.6 DMA transfer (Serial I/O Controller)” or “14.3.6.4 DMA operation (AC-link Controller) for more information.

8.3.5 Memory-Memory Copy Mode

It is possible to copy memory from any particular address to any other particular address when in the Memory-Memory Copy mode.

Set the DMA Channel Control Register (DMCCRn) as follows.

- DMCCRn.EXTRQ = 0: Memory Transfer mode
- DMCCRn.SNGAD = 0: Dual Address mode

Furthermore, when in the Memory-Memory Copy mode it is possible to set the interval for requesting ownership of each bus using the Internal Request Delay field (INTRQD) of the DMA Channel Control Register (DMCCRn).

Refer to “8.3.8 Dual Address Transfer” for information regarding the setting of other registers.

8.3.6 Memory Fill Transfer Mode

When in the Memory Fill Transfer mode, double word data set in the DMA Memory Fill Data Register (DMMFDR) is written to the data region specified by the DMA Source Address Register (DMSARn). This data can be used for initializing the memory, etc.

Set the DMA Channel Control Register (DMCCRn) as follows.

- DMCCRn.EXTRQ = 0: Memory transfer mode
- DMCCRn.SNGAD = 1: Single Address Transfer
- DMCCRn.MEMIO = 0: Transfer from I/O to memory

In addition, when in the Memory Fill Transfer mode, it is possible to set the interval for requesting ownership of each bus using the Internal Request Delay field (INTRQD) of the DMA Channel Control Register (DMCCRn).

Refer to “8.3.7 Single Address Transfer” for information regarding the setting of other registers.

By using this function together with the memory Write function that writes to multiple SDRAM Controller memory channels simultaneously (refer to Section 9.3.4), it is possible to initialize memory even more efficiently.

8.3.7 Single Address Transfer

This section explains register settings during Single Address transfer (DMCCRn.SNGAD = 1). This applies to the following DMA Transfer modes.

- External I/O (Single Address) Transfer
- Memory Fill Transfer

8.3.7.1 Channel Register Settings During Single Address Transfer

Table 8.3.2 shows restrictions of the Channel Register settings during Single Address transfer. If these restrictions are not met, then a Configuration Error is detected, the Configuration Error bit (CFERR) of the DMA Channel Status Register (DMCSRn) is set and DMA transfer is not performed.

For Burst transfer, +8, 0, or -8 can be set to the DMA Source Address Increment Register (DMSAIRn). Setting 0 is only possible during transfer from memory to external I/O. A Configuration Error will result if the value “0” is set during transfer from external I/O to memory or during Memory Fill transfer.

If the setting of the DMA Source Address Increment Register (DMSAIRn) is negative and the transfer setting size is 2 bytes or larger, then set the DMA Source Address Register (DMSARn) with 1 to 3 low-order bits complemented.

- If the transfer size is 2 bytes, set the DMSARn with the low-order 1 bit complemented.
- If the transfer size is 4 bytes, set the DMSARn with the low-order 2 bits complemented.
- If the transfer size is 8 bytes or larger, set the DMSARn with the low-order 3 bits complemented.

Example: When the transfer address is 0x0_0001_0000, the DMA Source Address Register (DMSARn) is as follows below.

- DMSAIRn setting is “0” or greater: 0x0_0001_0000
- DMSAIRn setting is a negative value: 0x0_0001_0007

During Single Address transfer, the DMA Destination Address Register (DMDARn) and DMA Destination Address Increment Register (DMDAIRn) settings are ignored.

Table 8.3.2 Channel Register Setting Restrictions During Single Address Transfer

Transfer Setting Size (DMCCRn.XFSZ)	DMSARn[2:0]		DMSAIRn[2:0]	DMCNTRn[2:0]
	DMSAIRn is “0” or greater	DMSAIRn setting is a negative value		
1 Byte	***	***	***	***
2 Bytes	**0	**0	**0	**0
4 Bytes	*00	*00	*00	*00
8 Bytes	000	111	000	000
4 Double Words	000	111	8/0/-8	000
8 Double Words				
16 Double Words				
32 Double Words				

8.3.7.2 Burst Transfer During Single Address Transfer

According to the SDRAM Controller and External Bus Controller specifications, the DMA Controller cannot perform Burst transfer that spans across 32-double word boundaries. Consequently, if the address that starts DMA transfer is not a multiple of the transfer setting size (DMCCRn.XFSZ) (is not aligned), transfer cannot be performed by any of the transfer sizes that were specified by a Burst transfer. Therefore, the DMA Controller executes multiple Burst transactions of a transfer size smaller than the specified transfer size. This division method changes according to the setting of the Transfer Size Mode bit (DMCCRn.USEXFSZ) of the DMA Channel Control Register.

Figure 8.3.2 shows the Single Address Burst transfer status when the lower 8 bits of the Transfer Start address are 0xA8 and the transfer setting size (DMCCRn.XFSZ) is set to 4 double words.

Panel (a) of this figure shows the situation when the Transfer Size Mode bit (DMCCRn.USEXFSZ) is “0”. In this case, first a three-double word transfer is performed up to the address aligned to the transfer setting size. Then, four-double word transfer specified by the transfer setting size is repeated. This setting is normally used.

On the other hand, panel (b) shows when the Transfer Size Mode bit (DMCCRn.USEXFSWZ) is “1”. In this case, transfer is repeated according to the transfer setting size. Three-double word transfer and one-double word transfer is only performed consecutively without releasing bus ownership when transfer spans across a 32-double word boundary.

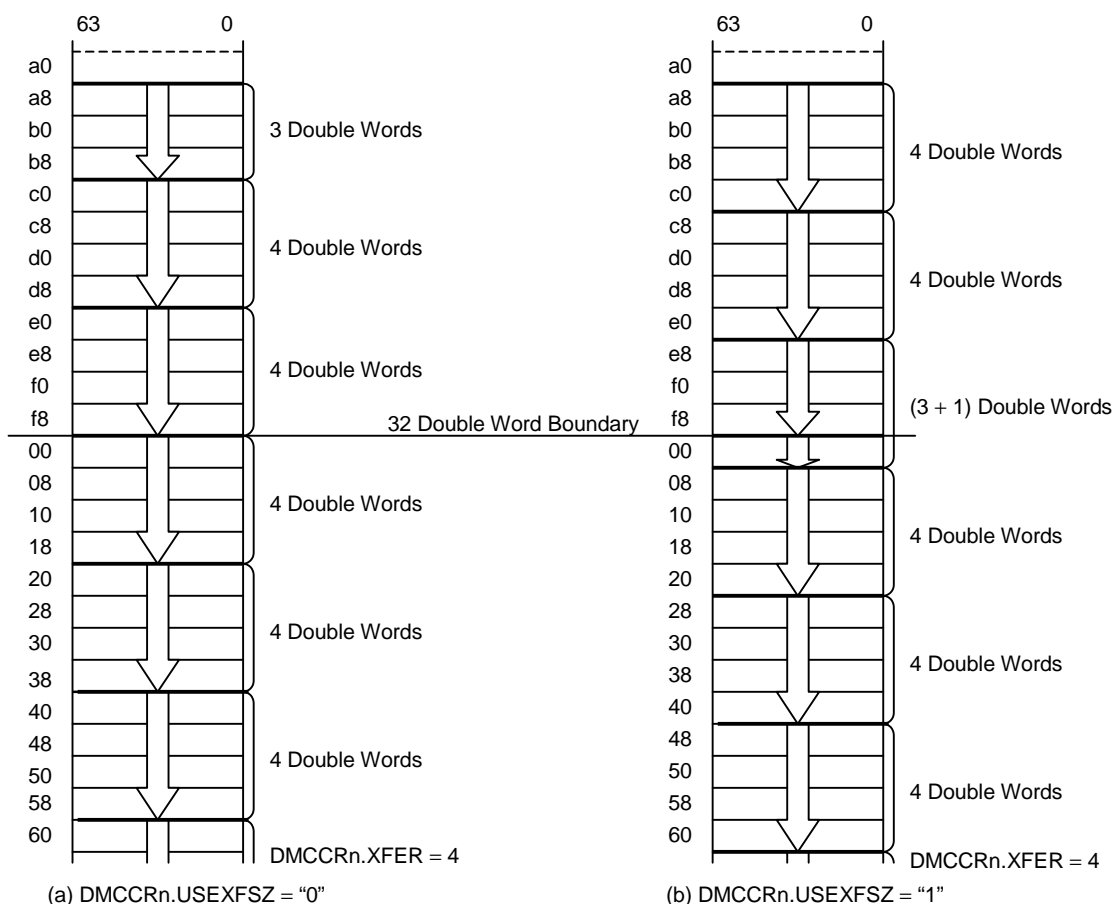


Figure 8.3.2 Non-aligned Single Address Burst Transfer

8.3.8 Dual Address Transfer

This section explains the register settings for Dual Address transfer (DMCCRn.SNGAD = 0). This applies to the following DMA transfer modes.

- External I/O (Dual Address) transfer
- Internal I/O DMA transfer
- Memory-Memory Copy transfer

8.3.8.1 Channel Register Settings During Dual Address Transfer

Table 8.3.3 shows restrictions of the Channel Register settings during Dual Address transfer. If these restrictions are not met, then a Configuration Error is detected, the Configuration Error bit (CFERR) of the DMA Channel Status Register (DMCSRn) is set, and DMA transfer is not performed.

If the setting of the DMA Source Address Increment Register (DMSAIRn) is negative and the transfer setting size is 8 bytes or larger, then a value will be set in the DMA Source Address Register (DMSARn) that reflects as follows.

If the setting of the DMA Source Address Increment Register (DMSAIRn) is negative and the transfer size is 2 bytes or larger, set the DMA Source Address Register (DMSARn) as follows:

- If the transfer size is 2 bytes, set the DMSAR_n with the low-order 1 bit complemented.
- If the transfer size is 4 bytes, set the DMSAR_n with the low-order 2 bits complemented.
- If the transfer size is 8 bytes or larger, set the DMSAR_n with the low-order 3 bits complemented.

Likewise, if the setting of the DMA Destination Address Increment Register (DMDAIR_n) is negative and the transfer size is 2 bytes or larger, set the DMA Destination Address Register (DMDAR_n) as follows:

- If the transfer size is 2 bytes, set the DMDAR_n with the low-order 1 bit complemented.
- If the transfer size is 4 bytes, set the DMDAR_n with the low-order 2 bits complemented.
- If the transfer size is 8 bytes or larger, set the DMDAR_n with the low-order 3 bits complemented.

Example: When the transfer address is 0x0_0001_0000, the DMA Source Address Register (DMSAR_n) is as follows below.

- DMSAIR_n setting is “0” or greater: 0x0_0001_0000
- DMSAIR_n setting is a negative value: 0x0_0001_0007

Table 8.3.3 Channel Register Setting Restrictions During Dual Address Transfer

Transfer Setting Size (DMCCRn.XFSZ)	DMSARn[2:0]		DMDARn[2:0]		DMSAIRn	DMDAIRn	DMCNTRn	DMCCRn REVBYTE
	DMSAIRn setting is 0 or greater	DMSAIRn setting is a negative value	DMDAIRn setting is 0 or greater	DMDAIRn setting is a negative value				
1 Byte	***	***	***	***	***	***	***	0
2 Bytes	**0	**0	**0	**1	**0	**0	**0	0
4 Bytes	*00	*00	*00	*11	*00	*00	*00	0
8 Bytes, 4 / 8 Double Wods (DMMCR.FIFUM[n]=0)	000	111	000	111	000	000	000	0/1
4 / 8 Double Words (DMMCR.FIFUM[n]=1)	000	111	000	111	8/0/-8	8/-8 ‡	000	0/1
	***	—	***	—	8	8	***	0
	—	***	—	***	-8	-8		0
16 Double Words	Cannot be set (Configuration Error)							
32 Double Words	Cannot be set (Configuration Error)							

‡: 8, 0, or -8 can be specified when the Destination Burst Inhibit bit (DMCCR_n.DBINH) is set.

8.3.8.2 Burst Transfer During Dual Address Transfer

The DMA Controller has a 64-bit 8-stage FIFO on-chip that is connected to the internal bus (G-Bus) for Burst transfer during Dual Address transfer. Since this FIFO employs a shifter, it is possible to perform transfer of any address or data size. Burst transfer is only performed when 4 Double Words or 8 Double Words is set by the Transfer Setting Size field (DMCCR_n.XFSZ) and the FIFO Use Enable bit (DMMCR_n.FIFUM[n]) of the DMA Master Control Register is set.

According to the SDRAM Controller and External Bus Controller specifications, the DMA Controller cannot perform Burst transfer that spans across 32-double word boundaries. Consequently, if the address that starts DMA transfer is not a multiple of the transfer setting size (DMCCR_n.XFSZ) (is not aligned), transfer cannot be performed by any of the transfer sizes that

were specified by a Burst transfer. Therefore, it is necessary to divide the transfer into multiple Burst transactions of a transfer size smaller than the specified transfer size. This division method changes according to the setting of the Transfer Size Mode bit (DMCCRN.USEXFSZ) of the DMA Channel Control Register and whether or not the address offset relative to the Transfer Setting size (DMCCRN.XFSZ) is equivalent to the source address and destination address combined.

Figure 8.3.3 shows Dual Address Burst transfer when the Transfer Size Mode bit (DMCCRN.USEXFSZ) is set to “1”, the lower 8 bits of the Transfer Start address for the transfer source are set to 0xA8, the lower 8 bits of the Transfer Start address for the transfer destination are set to 0x38, and the Transfer Setting Size (DMCCRN.XFSZ) is set to 8 Double Words.

Transfer repeats according to the transfer setting size, regardless of the different address offsets. However, transfers that span across 32-double word boundaries are divided. Since data remains in the on-chip FIFO when in this mode, it becomes possible to share the on-chip FIFO among multiple DMA channels.

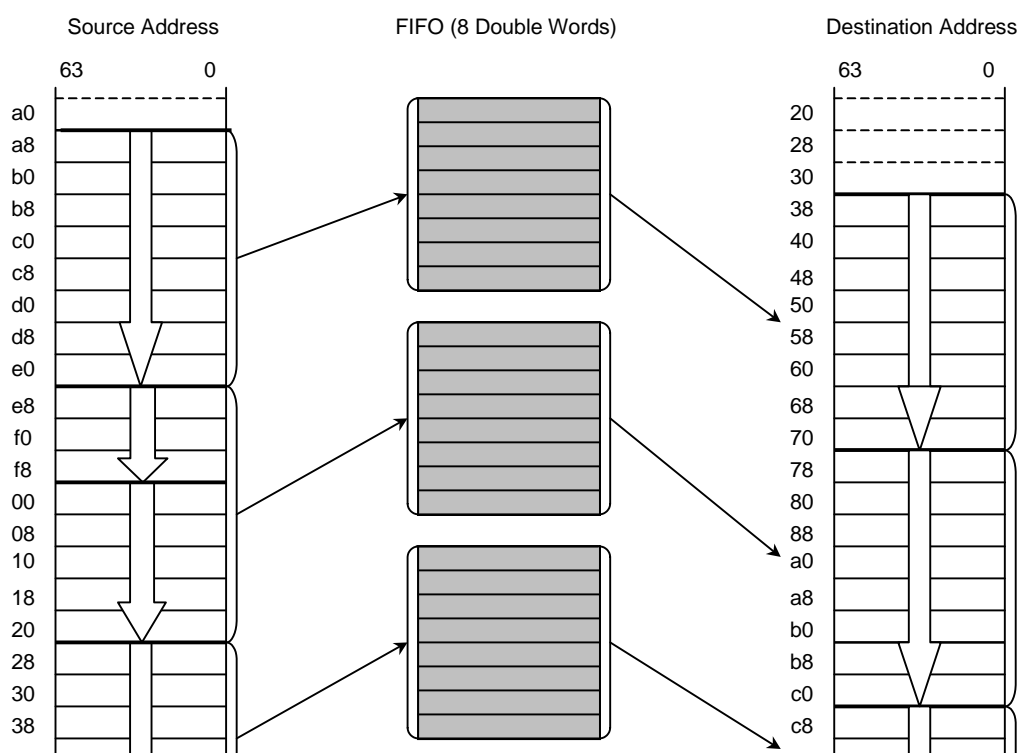


Figure 8.3.3 Dual Address Burst Transfer (DMCCRN.USEXFSZ = 1)

Figure 8.3.4 shows Dual Address Burst transfer when the Transfer Size Mode bit (DMCCRN.USEXFSZ) is set to “0”, the lower 8 bits of the Transfer Start address for the transfer source are set to 0xA8, the lower 8 bits of the Transfer Start address for the transfer destination are set to (a) 0x28/(b) 0x30, and the Transfer Setting Size (DMCCRN.XFSZ) is set to 8 double words.

Panel (a) of this figure shows when the address offset is equivalent. In this case, first transfer of three double words is performed up to the address that is aligned with the transfer setting size. Then, transfer of eight double words that is specified by the transfer setting size is repeated.

On the other hand, panel (b) show when the address offset is not equivalent. In this case, first only data up to the address that is aligned with the transfer setting size is read to the on-chip FIFO. Then, data is written up to the address that is aligned with the transfer setting size as long as data remains in the on-chip FIFO. Efficiency decreases since the transfer size is divided. Also, since

data may remain in the on-chip FIFO, Burst transfer of a Dual Address that uses the on-chip FIFO simultaneously with another channel cannot be performed.

Using the Burst Inhibit bit makes it possible to mix Burst transfer with 8-Double-Word Single transfer. This in turn makes it possible to perform Burst access only for memory access during DMA transfer with external I/O devices that cannot perform Burst transfer.

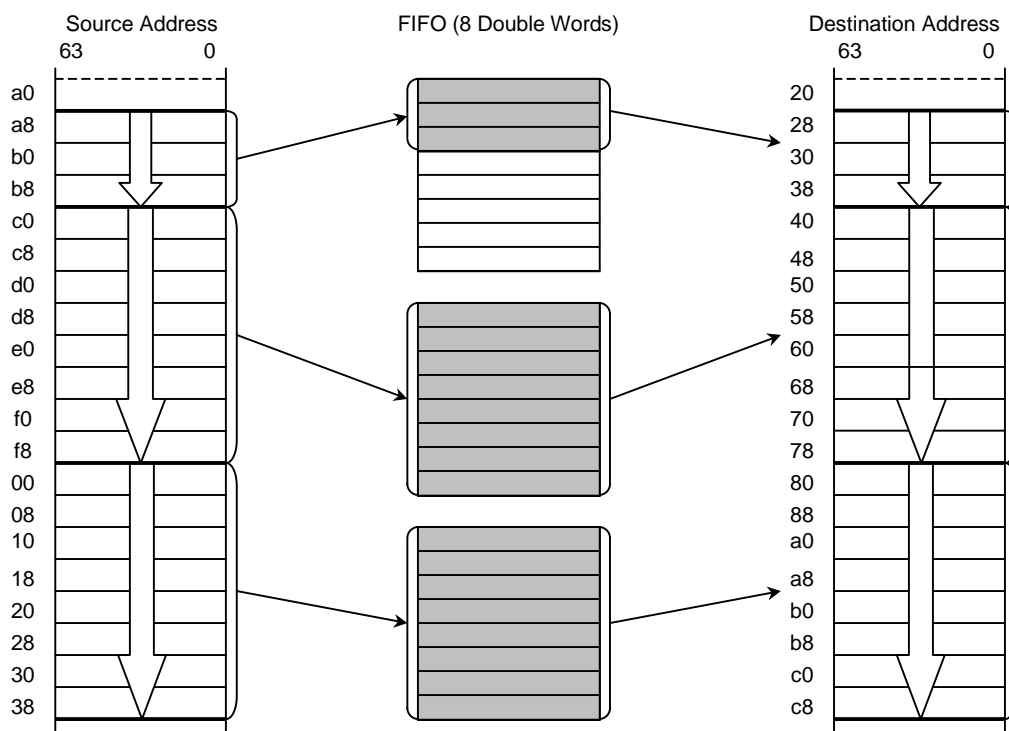
When the Source Burst Inhibit bit (DMCCRn.SBINH) is set, data read from the Source Address to the on-chip FIFO is divided into multiple 8-byte Single Read transfers, then transfer is executed.

When the Destination Burst Inhibit bit (DMCCRn.DBINH) is set, data written from the FIFO to the Destination Address is divided into multiple 8-byte Single Write transfers, then transfer is executed.

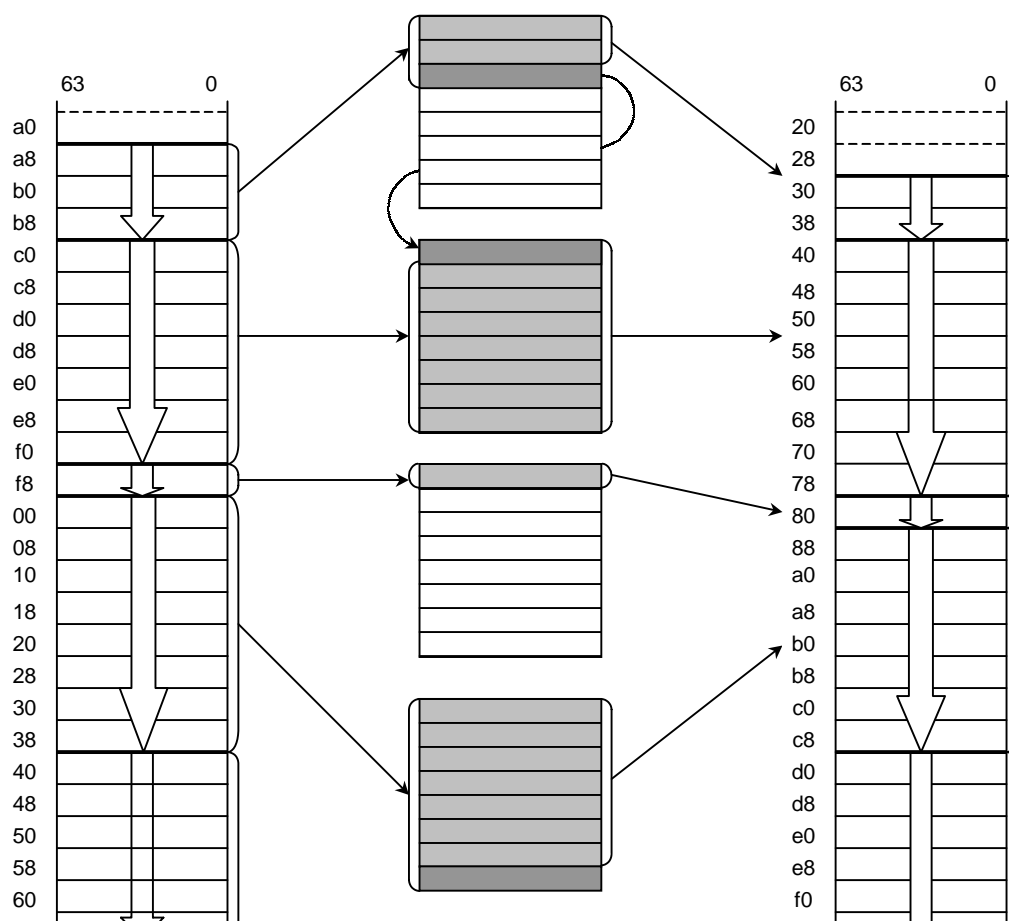
8.3.8.3 Double Word Byte Swapping

When the Reverse Byte bit (REVBYTE) of the DMA Channel Configuration Register (DMCCRn) is set, read double word data is written after byte swapping is performed. For example, if the read data is "0x01234567_90ABCDEF", then the data "0xEFCDAB89_67452301" is written.

The Reverse Byte bit can only be set when the REVBYTE column of Table 8.3.3 is set so "0/1" is indicated.



(a) Address offset is equivalent



(b) Address offset differs

Figure 8.3.4 Dual Address Burst Transfer (DMCCRn.USEFSZ = 0)

8.3.9 DMA Transfer

The sequence of DMA transfer that uses only the DMA Channel Register is as follows below.

1. Select DMA request signal
When performing external I/O or internal I/O DMA, set the DMA Request Select field (PCFG.DMASEL) of the Pin Configuration Register.
2. Set the Master Enable bit
Set the Master Enable bit (DMMCR.MSTEN) of the DMA Master Control Register.
3. Set the Address Register and Count Register
Set the five following register values.
 - DMA Source Address Register (DMSARn)
 - DMA Destination Address Register (DMDARn)
 - DMA Count Register (DMCNTRn)
 - DMA Source Address Increment Register (DMSAIRn)
 - DMA Destination Address Increment Register (DMDAIRn)
4. Set Chain Address Register
Set “0” to the DMA Chain Address Register (DMCHARn).
5. Clear the DMA Channel Status Register (DMCSRn)
Clear when status from the previous DMA transfer remains.
6. Set the DMA Channel Control Register (DMCCRn)
7. Initiate DMA transfer
DMA transfer is started by setting the Transfer Active bit (XFACT) of the DMA Channel Control Register.
8. Signal completion
When DMA data transfer ends normally, set the Normal Transfer Complete bit (NTRNFC) of the DMA Channel Status Register (DMCSRn). An interrupt is signalled if the Transfer Complete Interrupt Enable bit (INTENT) of the DMA Channel Control Register (DMCCRn) is set.

If an error is detected during DMA transfer, the error cause is recorded in the lower four bits of the DMA Channel Status Register and the transfer is interrupted. If the Error Interrupt Enable bit (INTENE) of the DMA Channel Control Register is set, then the interrupt is signaled.

8.3.10 Chain DMA Transfer

Table 8.3.4 shows the data structure in memory that the DMA Command Descriptor has. When the Simple Chain bit (SMPCHN) of the DMA Channel Control Register (DMCCRN) is set, only the initial four double words are used. DMSAIRn, DMDAIR, DMCCRN, and DMCSRn use the settings from when DMA started. In addition, all eight double words are used when the Simple Chain bit (SMPCHN) is cleared.

Saving the start memory address of another DMA Command Descriptor in the Offset 0 Chain Address field makes it possible to construct a chain list of DMA Command Descriptors (Figure 8.3.5). Set “0” in the Chain Address field of the DMA Command Descriptor at the end of the chain list.

When DMA transfer that is specified by one DMA Command Descriptor ends, the DMA Controller automatically reads the next DMA Command Descriptor indicated by the Chain Address Register (Chain transfer), then continues DMA transfer. Continuous DMA transfer that uses multiple Descriptors connected into such a chain-like structure is called Chain DMA transfer.

Since the DMA Channel Status Register is also overwritten during Chain transfer when the DMA Simple Chain bit (SMPCHN) is cleared, be sure not to unnecessarily clear necessary bits.

Placing DMA Command Descriptors at addresses that do not span across 32-double-word boundaries in memory is efficient since they are read by one G-Bus Burst Read operation.

Table 8.3.4 DMA Command Descriptors

Offset Address	Field Name	Transfer Destination Register
0x00	Chain Address	DMA Chain Address Register (DMCHARn)
0x08	Source Address	DMA Source Address Register (DMSARN)
0x10	Destination Address	DMA Destination Address Register (DMDARN)
0x18	Count	DMA Count Register (DMCNTRn)
0x20	Source Address Increment	DMA Source Address Increment Register (DMSAIRn)
0x28	Destination Address Increment	DMA Destination Address Increment Register (DMDAIRn)
0x30	Channel Control	DMA Channel Control Register (DMCCRN)
0x38	Channel Status	DMA Channel Status Register (DMCSRn)

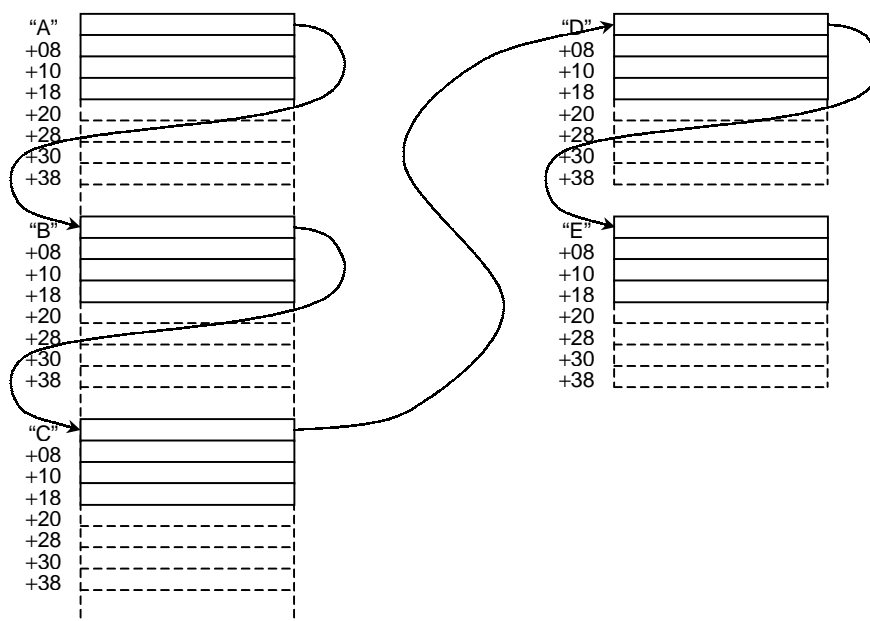


Figure 8.3.5 DMA Command Descriptor Chain

The sequence of Chain DMA transfer is as follows below.

1. Select DMA request signal
When performing external I/O or internal I/O DMA, set the DMA Request Select field (PCFG.DMASEL) of the Pin Configuration Register.
2. Set the Master Enable bit
Set the Master Enable bit (DMMCR.MSTEN) of the DMA Master Control Register.
3. Structure of the DMA command Descriptor chain
Construct the DMA Command Descriptor Chain in memory.
4. Set the Count Register
Set "0" to the DMA Count Register (DMCNTRn) .
Sets the DMA Source Address Increment Register (DMSAIRn) and DMA destination Address Increment Register (MMDAIRn).
5. Clear the DMA Channel Status Register (DMCSRn)
Clear the status of the previous DMA transfer.
6. Set the DMA Channel Control Register (DMCCRn).
7. Initiate DMA transfer
Setting the address of the DMA Command Descriptor at the beginning of the chain list in the DMA Chain Address Register (DMCHARn) automatically initiates DMA transfer. First, the value stored in each field of the DMA Command descriptor at the beginning of the Chain List is read to each corresponding DMA Channel register (Chain transfer), then DMA transfer is performed according to the read value.

When a value other than "0" is stored in the DMA Chain Address Register (DMCHARn), data of the size stored in the DMA Count Register (DMCNTRn) is completely transferred, then the DMA Command Descriptor value of the memory address specified by the DMA Chain Address Register is read.

In addition, if the Chain Address field value read the Descriptor 0, the DMA Chain Address Register value is not updated. All previous values (Data Command Descriptor Addresses with the value "0" in the Chain Address field when the values were read) are held.

0 Value judgement is performed when the lower 32 bits of the DMA Chain Address Register are rewritten. If the value is not "0" at this time, DMA transfer is automatically initiated. Therefore, please write to the upper 32 bits first when writing to the DMA Chain Address Register using 32-bit Store instructions.

8. Signal completion
Set the Normal Chain End bit (NCHNC) of the DMA Channel Status Register (DMCSRn) when DMA data transfer of all Descriptor Chains is complete. An interrupt is signalled if the Chain End Interrupt Enable bit (INTENC) of the DMA Channel Control Register (DMCCRn) is set at this time.

In addition, the Normal Transfer End bit (NTRNFC) of the DMA Channel Status Register (DMCSRn) is set each time DMA data transfer specified by each DMA Command Descriptor ends normally. An interrupt is signalled if the Transfer End Interrupt Enable bit (INTENT) of the DMA Channel Control Register (DMCCRn) is set at this time.

If an error is detected during DMA transfer, the error cause is recorded in the lower four bits of the DMA Channel Status register and transfer is interrupted. An interrupt is signalled if the Error Interrupt Enable bit (INTENE) of the DMA Channel Control Register is set.

8.3.11 Dynamic Chain Operation

It is possible to add DMA Command Descriptor chains to the DMA Command Descriptor chain while Chain DMA transfer is in progress. This is performed according to the following procedure.

1. Construct the DMA Command Descriptor chain
Construct the DMA Command Descriptor chain to be added to memory.
2. Add a DMA Command Descriptor chain
Substitute the address of the Command Descriptor at the beginning of the Descriptor Chain to be added into the Chain Address field of the Descriptor at the end of the DMA Command Descriptor chain that is currently performing DMA transfer.
3. Check the Chain Enable bit
Read the value of the Chain Enable bit (CHNEN) of the DMA Channel Control Register (DMCCRn). If that value is "0", then write the Chain Address field value of the DMA Command Descriptor that is indicated by the address stored in the DMA Chain Address Register (DMCHARn).

8.3.12 Interrupts

An interrupt number (10 – 13) of the Interrupt Controller is mapped to each channel. In addition, there are completion interrupts for when transfer ends normally and error interrupts for when transfer ends abnormally for each channel. When an interrupt occurs, then the bit that corresponds to either the Normal Interrupt Status field (DIS[3:0]) or the Error Interrupt Status field (EIS[3:0]) of the DMA Master Control Register (DMMCR) is set.

Figure 8.3.6 shows the relationship between the Status bit and Interrupt Enable bit for each interrupt cause. Refer to the explanation for each Status bit for more information regarding each information cause.

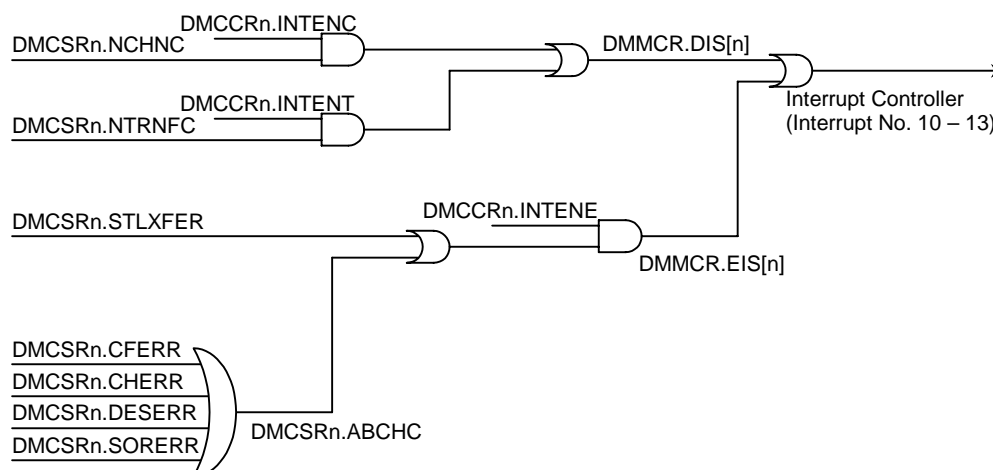


Figure 8.3.6 DMA Controller Interrupt Signal

8.3.13 Transfer Stall Detection Function

If the period from when a certain channel last performs internal bus access to when the next internal bus access is performed exceeds the Transfer Stall Detection Interval field (STLTIME) of the DMA Channel Control Register (DMCCRn), the Transfer Stall Detection bit (STLXFER) of the DMA Channel Status Register (DMCSRn) is set. An error interrupt is signalled if the Error Interrupt Enable bit (DMCCRn.INTENE) is set.

In contrast to other error interrupts, DMA transfer is not stopped. Normal DMA transfer is executed if bus ownership can be obtained. Furthermore, clearing the Transfer Stall Detection field (STLXFER) resumes transfer stall detection as well.

Setting the Transfer Stall Detection Interval field (STLTIME) to “000” disables the Transfer Stall Detection function.

8.3.14 Arbitration Among DMA Channels

The DMA Controller has an on-chip DMA Channel Arbiter that arbitrates bus ownership among four DMA channels that use the internal bus (G-Bus). There are two methods for determining priority: the round robin method and the fixed priority method. (See Figure 8.3.7.) The Round Robin Priority bit (RRPT) of the DMA Master Control Register (DMMCR) selects the priority method.

- Fixed priority (DMMCR.RRPT = 0)
As shown below, Channel 0 has the highest priority and Channel 3 has the lowest priority.
 $CH0 > CH1 > CH2 > CH3$
- Round Robin method (DMMCR.RRPT = 1)
The last channel to perform DMA transfer has the lowest priority.
 - After CH0 DMA transfer execution: $CH1 > CH2 > CH3 > CH0$
 - After CH1 DMA transfer execution: $CH2 > CH3 > CH0 > CH1$
 - After CH2 DMA transfer execution: $CH3 > CH0 > CH1 > CH2$
 - After CH3 DMA transfer execution: $CH0 > CH1 > CH2 > CH3$

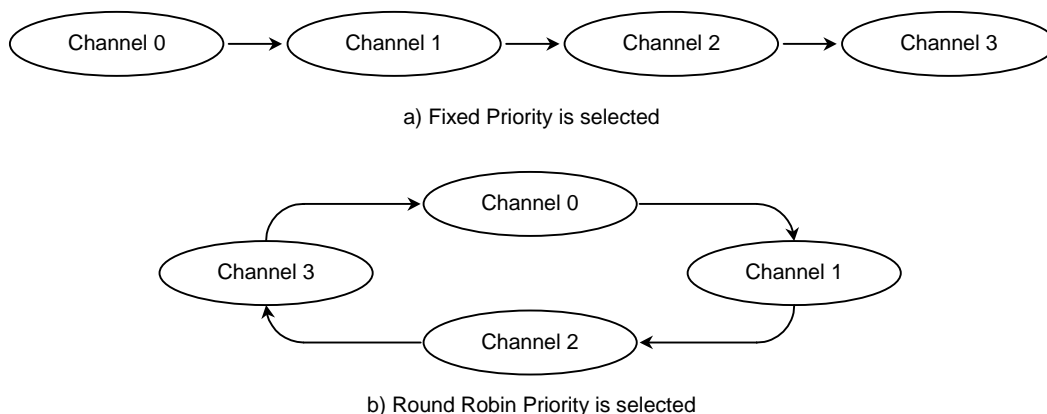


Figure 8.3.7 DMA Channel Arbitration

8.3.15 Restrictions in Access to PCI Bus

The PCI Controller detects a bus error if the DMA Controller performs one of the following accesses to the PCI Bus.

- Burst transfer exceeding 8 double words (PCICSTATUS.TLB)
- Address Increment value –8 Burst transfer (PCICSTATUS.NIB)
- Address Increment Value 0 Burst transfer (PCICSTATUS.ZIB)
- Dual Address Burst transfer when the setting for DMSARn, DMDARn, or DMCNTRn is not a double word boundary (PCICSTATUS.IAA)

In addition, Single Address transfers between an external I/O device and the PCI Bus are not supported. Data transfer is not performed, but no error is detected.

8.4 DMA Controller Registers

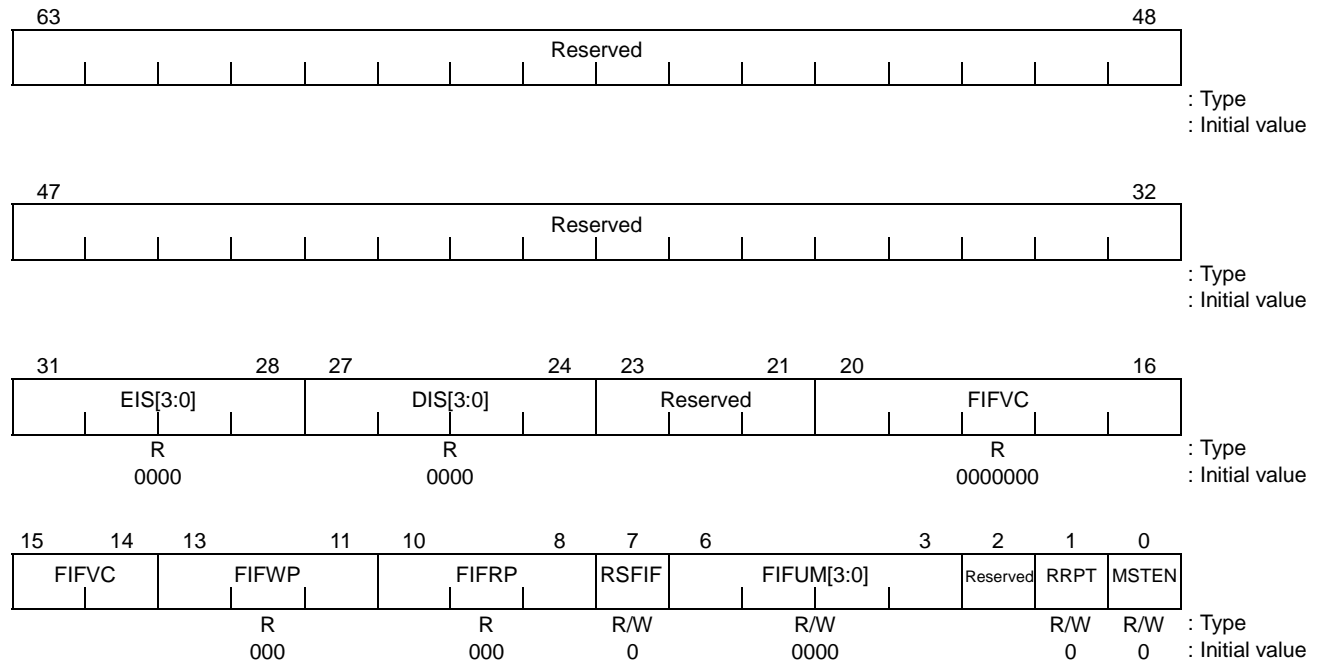
Table 8.4.1 DMA Controller Registers

Offset Address	Bit Width	Mnemonic	Register Name
0xB000	64	DMCHAR0	DMA Chain Address Register 0
0xB008	64	DMSAR0	DMA Source Address Register 0
0xB010	64	DMDAR0	DMA Destination Address Register 0
0xB018	64	DMCNR0	DMA Count Register 0
0xB020	64	DMSAIR0	DMA Source Address Increment Register 0
0xB028	64	DMDAIR0	DMA Destination Address Increment Register 0
0xB030	64	DMCCR0	DMA Channel Control Register 0
0xB038	64	DMCSR0	DMA Channel Status Register 0
0xB040	64	DMCHAR1	DMA Chain Address Register 1
0xB048	64	DMSAR1	DMA Source Address Register 1
0xB050	64	DMDAR1	DMA Destination Address Register 1
0xB058	64	DMCNR1	DMA Count Register 1
0xB060	64	DMSAIR1	DMA Source Address Increment Register 1
0xB068	64	DMDAIR1	DMA Destination Address Increment Register 1
0xB070	64	DMCCR1	DMA Channel Control Register 1
0xB078	64	DMCSR1	DMA Channel Status Register 1
0xB080	64	DMCHAR2	DMA Chain Address Register 2
0xB088	64	DMSAR2	DMA Source Address Register 2
0xB090	64	DMDAR2	DMA Destination Address Register 2
0xB098	64	DMCNR2	DMA Count Register 2
0xB0A0	64	DMSAIR2	DMA Source Address Increment Register 2
0xB0A8	64	DMDAIR2	DMA Destination Address Increment Register 2
0xB0B0	64	DMCCR2	DMA Channel Control Register 2
0xB0B8	64	DMCSR2	DMA Channel Status Register 2
0xB0C0	64	DMCHAR3	DMA Chain Address Register 3
0xB0C8	64	DMSAR3	DMA Source Address Register 3
0xB0D0	64	DMDAR3	DMA Destination Address Register 3
0xB0D8	64	DMCNR3	DMA Count Register 3
0xB0E0	64	DMSAIR3	DMA Source Address Increment Register 3
0xB0E8	64	DMDAIR3	DMA Destination Address Increment Register 3
0xB0F0	64	DMCCR3	DMA Channel Control Register 3
0xB0F8	64	DMCSR3	DMA Channel Status Register 3
0xB148	64	DMMFDR	DMA Memory Fill Data Register
0xB150	64	DMMCR	DMA Master Control Register

8.4.1 DMA Master Control Register (DMMCR)

Offset address: 0xB150

This register controls the entire DMA Controller.



Bit	Mnemonic	Field Name	Description	Read/Write
63:32		Reserved		—
31:28	EIS[3:0]	Error Interrupt Status	Error Interrupt Status [3:0] (Default: 0x0) These four bits indicate the error interrupt status of each channel. EIS[n] corresponds to channel <i>n</i> . 1: There is an error interrupt in the corresponding channel. 0: There is no error interrupt in the corresponding channel.	R
27:24	DIS[3:0]	Normal Completion Interrupt Status	Done Interrupt Status [3:0] (Default: 0x0) These four bits indicate the transfer completion (transfer complete or chain ended) interrupt status of each channel. DIS[n] corresponds to channel <i>n</i> . 1: There is a transfer completion interrupt in the corresponding channel. 0: There is no transfer completion interrupt in the corresponding channel.	R
23:21		Reserved		—
20:14	FIFVC	FIFO Valid Entry Count	FIFO Valid Entry Count (Default: 0000000) These read only bits indicate the byte count of data that were written to FIFO but not read out from the FIFO.	R
13:11	FIFWP	FIFO Write Pointer	FIFO Write Pointer (Default: 000) These read only bits indicate the next write position in FIFO. This is a diagnostic function.	R
10:8	FIFRP	FIFO Read Pointer	FIFO Read Pointer (Default: 000) These read only bits indicate the next read position in FIFO. This is a diagnostic function.	R
7	RSFIF	Reset FIFO	Reset FIFO (Default: 0) This bit is used for resetting FIFO. When this bit is set to “1”, the FIFO read pointer, FIFO write pointer and FIFO valid entry count are initialized to “0”. If an error occurs during DMA transfer, use this bit when data remains in the FIFO (when the FIFO Valid entry Count Field is not “0”) to initialize the FIFO.	R/W

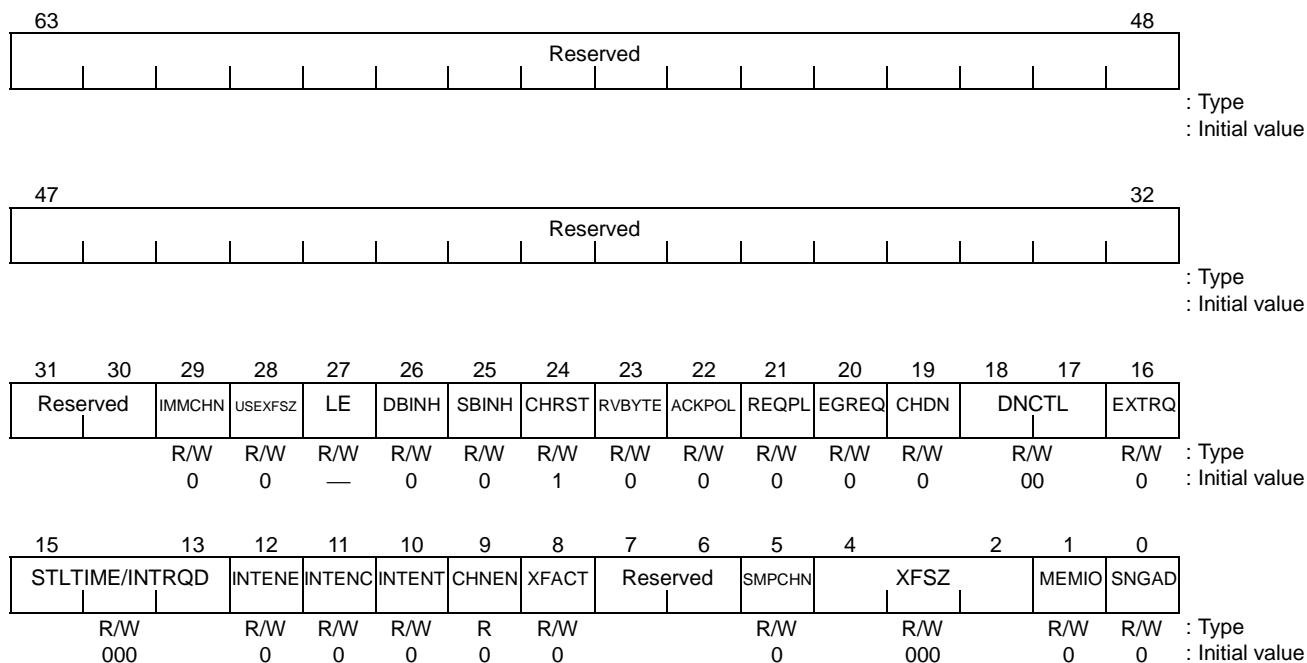
Figure 8.4.1 DMA Master Control Register (1/2)

Bit	Mnemonic	Field Name	Description	Read/Write
6:3	FIFUM[3:0]	FIFO Use Enable [3:0]	FIFO Use Enable [3:0] (Default: 0x0) Each channel specifies whether to use 8-double word FIFO in Dual Address transfer. FIFUM[n] corresponds to channel <i>n</i> . Refer to “8.3.8.2 Burst Transfer During Dual Address Transfer” for more information.	R/W
2		Reserved		—
1	RRPT	Round Robin Priority	Round Robin Priority (Default: 0) Specifies the method for determining priority among channels. 1: Round Robin method. Priority of the last channel used is the lowest, and the next previous channel has the next lowest priority. Round robin is in the order Channel 0 > Channel 1 > Channel 2 > Channel 3. 0: Fixed Priority. Priority is fixed in the order Channel 0 > Channel 1 > Channel 2 > Channel 3.	R/W
0	MSTEN	Master Enable	Master Enable (Default: 0) This bit enables the DMA Controller. 1: Enable 0: Disable Note: If the entire DMA Controller is disabled, then all internal logic including the Bus Interface Logic and State Machine are reset.	R/W

Figure 8.4.1 DMA Master Control Register (2/2)

8.4.2 DMA Channel Control Register (DMCCRN)

Offset address: 0xB030 (ch. 0) / 0xB070 (ch. 1) / 0xB0B0 (ch. 2) / 0xB0F0 (ch. 3)



Bit	Mnemonic	Field Name	Description	Read/Write
63:32		Reserved		—
29	IMMCHN	Immediate Chain	Immediate Chain (Default: 0) Always set this bit to "1".	R/W
28	USEXFSZ	Transfer Set Size Mode	Use Transfer Set Size (Default: 0) Selects the DMA channel operation mode during Burst DMA transfer. Refer to "8.3.7.2 Burst Transfer During Single Address Transfer" and "8.3.8.2 Burst Transfer During Dual Address Transfer" for more information. 1: The DMA Controller always transfers the amount of data set in DMCCRN.XFSZ for each bus operation. Since alignment to the boundary of the DMCCRN.XFSZ in the address is not forced when in this mode, transfers that exceed 32-double-word boundaries are divided into two operations. 0: The DMA Controller calculates the transfer size so the address set in DMSARn and DMDARn (only during Dual Address transfer) can be aligned to the boundary of the size set in DMCCRN.XFSZ, then transfers data according to that size. Note: In Dual Address Transfer mode, programming this bit to 0 is valid only when both the contents of the DMSARn and the DMDARn are on doubleword boundaries and the contents of the DMCNTRn is a multiple of eight bytes.	R/W
27	LE	Little Endian	Little Endian (Default: value that is the opposite of the G-Bus Endian (CCFG.ENDIAN)) This bit sets the Endian of the channel. Please use the default value as is. 1: Channel operates in the Little Endian mode 0: Channel operates in the Big Endian mode	R/W

Figure 8.4.2 DMA Channel Control Register (1/4)

Bit	Mnemonic	Field Name	Description	Read/Write
26	DBINH	Destination Burst Inhibit	<p>Destination Burst Inhibit (Default: 0)</p> <p>During Dual Address transfer, this bit sets whether to perform Burst transfer or Single transfer on a Write cycle to the address set from FIFO to DMDARn when Burst transfer is set by DMCCRn.XFSZ. Refer to “8.3.8.2 Burst Transfer During Dual Address Transfer” for more information.</p> <p>The settings of this bit have no effect during Single Address transfers.</p> <p>1: Multiple Single transfers are executed. 0: Burst transfer is executed.</p>	R/W
25	SBINH	Source Burst Inhibit	<p>Source Burst Inhibit (Default: 0)</p> <p>During Dual Address transfer, this bit sets whether to perform Burst transfer or Single transfer on a Read cycle to the FIFO from the address set to DMSARn when Burst transfer is set by DMCCRn.XFSZ. Refer to “8.3.8.2 Burst Transfer During Dual Address Transfer” for more information.</p> <p>The settings of this bit have no effect during Single Address transfers.</p> <p>1: Multiple Single transfers are executed. 0: Burst transfer is executed.</p>	R/W
24	CHRST	Channel Reset	<p>Channel Reset (Default: 1)</p> <p>This bit is used for initializing channels. The DMCCRn.XFACT, DMCCRn.CHNEN, and DMCSRn bits are all cleared. In addition, all channel logic and interrupts from channels are cleared and bus ownership requests to the DMA Channel Arbiter are also reset. The software must clear this bit before operating a channel.</p> <p>1: Reset channel 0: Enable channel</p>	R/W
23	REVBYTE	Reverse Byte	<p>Reverse Bytes (Default: 0)</p> <p>This bit specifies whether to reverse the byte order during a Dual Address transfer when the Transfer Setting Size field (DMCCRn.XFSZ) setting is 8 bytes or more. Refer to “8.3.8.3 Double Word Byte Swapping” for more information.</p> <p>1: Reverses the byte order. 0: Does not reverse the byte order.</p>	R/W
22	ACKPOL	Acknowledge Polarity	<p>Acknowledge Polarity (Default: 0)</p> <p>Specifies the polarity of the DMAACK[n] signal.</p> <p>1: Asserts when the DMAACK[n] signal is High 0: Asserts when the DMAACK[n] signal is Low</p>	R/W
21	REQPL	Request Polarity	<p>Request Polarity (Default: 0)</p> <p>Specifies the polarity of the DMAREQ[n] signal.</p> <p>1: Asserts when the DMAREQ[n] signal is High. 0: Asserts when the DMAREQ[n] signal is Low.</p>	R/W
20	EGREQ	Edge Request	<p>Edge Request (Default: 0)</p> <p>Specifies the method for detecting DMA requests by the DMAREQ[n] signal.</p> <p>1: DMAREQ[n] signal is Edge Detect. 0: DMAREQ[n] signal is Level Detect.</p>	R/W
19	CHDN	Chain Complete	<p>Chain Done (Default: 0)</p> <p>Selects control by the DMADONE* signal. See “8.3.3.4 DMA Controller” for more information.</p> <p>1: Assertion of the DMADONE* signal controls the overall Chain DMA transfer. 0: Assertion of the DMADONE* signal controls DMA transfer according to the DMA Channel Register setting at that time.</p>	R/W
18:17	DNCTL	DONE Control	<p>Done Control (Default: 00)</p> <p>Specifies the input/output mode of the DMADONE* signal. Refer to “8.3.3.4 DMADONE* Signal” for more information.</p> <p>00: DMADONE* signal becomes the input signal, but input is ignored. 01: DMADONE* signal becomes the input signal. 10: DMADONE* signal becomes the output signal. 11: DMADONE* signal becomes the open drain input/output signal.</p>	R/W

Figure 8.4.2 DMA Channel Control Register (2/4)

Bit	Mnemonic	Field Name	Description	Read/Write
16	EXTRQ	External Request	<p>External Request (Default: 0) Sets the Request Transfer mode.</p> <p>1: I/O DMA transfer mode This bit is used by the External I/O DMA Transfer mode and the Internal I/O DMA Transfer mode. A channel requests internal bus ownership when the I/O device asserts the DMA request signal.</p> <p>0: Memory Transfer mode This bit is used by the Memory-Memory Copy Transfer mode and the Memory Fill Transfer mode. A channel requests internal bus ownership when the value of DMCSRn.WAITC becomes "0".</p>	R/W
15:13	STLTIME / INTRQD	Transfer Stall Detection Interval/Internal Request Delay	<ul style="list-style-type: none"> When in the I/O DMA Transfer mode (DMCCRn.EXTRQ is "1") Stalled Transfer Detect Time (Default: 000) Sets the detection interval for a lack of bus ownership. If this channel <i>n</i> releases bus ownership then the interval it does not have ownership exceeds the clock count set by this field, then DMCSRn.STLXFER is set to "1". Refer to "8.3.13 Transfer Stall Detection Function" for more information. 000: Does not detect stalled transfers. 001: Sets 960 (15×64) clocks as the detection interval 010: Sets 4032 (63×64) clocks as the detection interval 011: Sets 16320 (255×64) clocks as the detection interval 100: Sets 65472 (1023×64) clocks as the detection interval 101: Sets 262080 (4095×64) clocks as the detection interval 110: Sets 1048512 (16383×64) clocks as the detection interval 111: Sets 4194240 (65535×64) clocks as the detection interval When in the Memory Transfer mode (DMCCRn.EXTRQ is "0") Internal Request Delay (Default: 000) Sets the delay time from when bus ownership is released to the next bus ownership request. Bus ownership is released, the set delay time elapses, then a bus ownership request is generated from the channel. 000: Always requests bus ownership when this channel is active. (Bus ownership is released after bus operation ends) 001: Set 16 clocks as the delay time 010: Set 32 clocks as the delay time 011: Set 64 clocks as the delay time 100: Set 128 clocks as the delay time 101: Set 256 clocks as the delay time 110: Set 512 clocks as the delay time 111: Set 1024 clocks as the delay time 	R/W
12	INTENE	Error Interrupt Enable	<p>Interrupt Enable on Error (Default: 0) Enables interrupts when the Error End bit (DMCSRn.ABCHC) or the Transfer Stall Detection bit (DMCSRn.STLXFER) is set. 1: Generates interrupts. 0: Does not generate interrupts.</p>	R/W
11	INTENC	Chain End Interrupt Enable	<p>Interrupt Enable on Chain Done (Default: 0) This bit enables interrupts when the Chain End bit (DMCSRn.NCHNC) is set. 1: Generate interrupts. 0: Do not generate interrupts.</p>	R/W
10	INTENT	Transfer End Interrupt Enable	<p>Interrupt Enable on Transfer Done (Default: 0) This bit enables interrupts when the Transfer End bit (DMCSRn.NTRNFC) is set. 1: Generate interrupts. 0: Do not generate interrupts.</p>	R/W

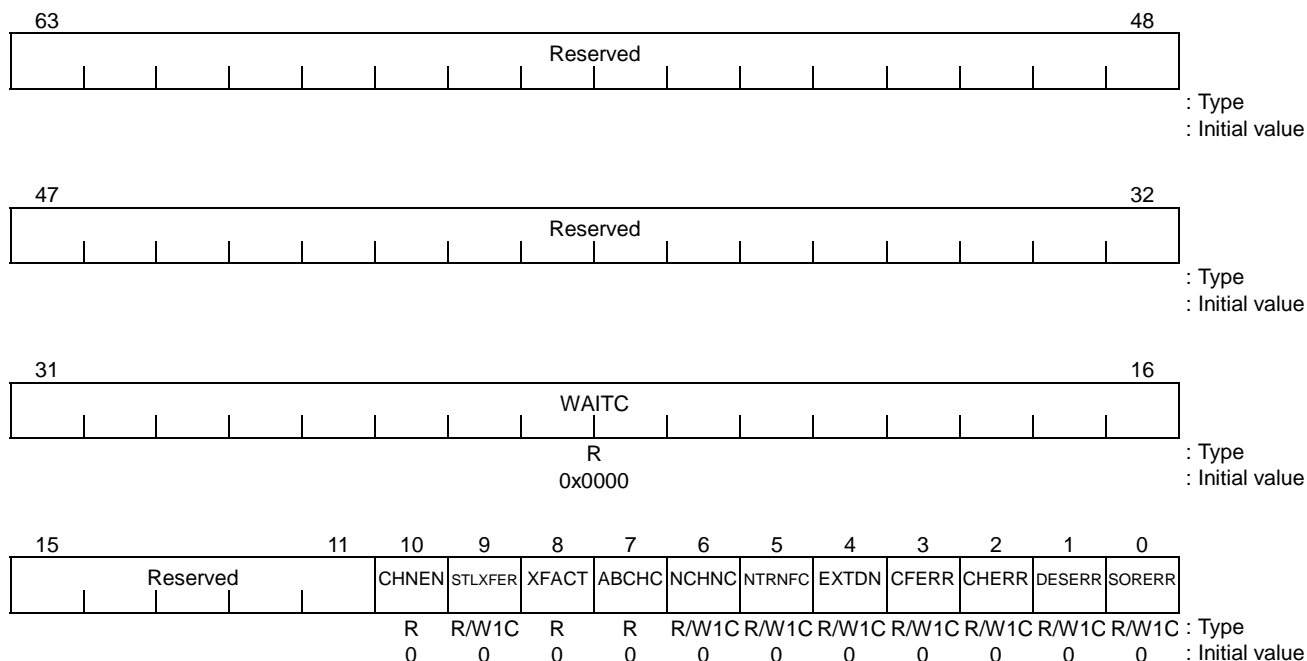
Figure 8.4.2 DMA Channel Control Register (3/4)

Bit	Mnemonic	Field Name		Read/Write
9	CHNEN	Chain Enable	<p>Chain Enable (Default: 0)</p> <p>This bit indicates whether Chain operation is being performed. Read Only.</p> <p>This bit is cleared when either the Master Enable bit (DMCCR.MSTEN) is cleared or the Channel Reset bit (DMCCRn.CHRST) is set. This bit is set if a value other than "0" is set when the CPU writes to the DMA Chain Address Register (DMCHARn) or when a Chain transfer writes DMA Command Descriptor. This bit is then cleared when "0" is set to the DMA Chain Address Register (DMCHARn).</p> <p>1: If transfer completes due to the current DMA Channel Register setting, a DMA Command Descriptor is loaded in the DMA Channel Register from the specified DMA Chain Address Register (DMCHARn) address, then DMA transfer continues.</p> <p>0: Further transfer does not start even if transfer completes due to the current DMA Channel Register setting.</p>	R
8	XFACT	Transfer Active	<p>Transfer Active (Default: 0)</p> <p>DMA transfer is performed according to the DMA Channel Register setting when this bit is set. This bit is automatically set when a value other than "0" is set in the DMA Chain Address Register (DMCHARn). DMA transfer is then initiated. This bit is automatically cleared either when DMA transfer ends normally it is stopped due to an error.</p> <p>1: Perform DMA transfer.</p> <p>0: Do not perform DMA transfer.</p>	R/W
7:6		Reserved		—
5	SMPCHN	Simple Chain	<p>Simple Chain (Default: 0)</p> <p>This bit selects the DMA Channel Register that loads data from DMA Command Descriptors during Chain DMA transfer.</p> <p>1: Data is only loaded to the four following DMA Channel Registers: the Chain Address Register (DMCHARn), the Source Address Register (DMSARn), the Destination Address Register (DMDARn), and the Count Register (DMCNRn).</p> <p>0: Data is loaded to all eight DMA Channel Registers.</p>	R/W
4:2	XFSZ	Transfer Set Size	<p>Transfer Set Size (Default: 000)</p> <p>These bits set the transfer data size of each bus operation in the internal bus.</p> <p>When the transfer set size is set to four double words or greater, the data size actually transferred during a single bus operation does not always match the transfer set size. Refer to "8.3.7.2 Burst Transfer During Single Address Transfer" and "8.3.8.2 Burst Transfer During Dual Address Transfer" for more information.</p> <p>000: 1 byte 001: 2 byte 010: 4 byte 011: 8 bytes (1 double word) 100: 4 double words 101: 8 double words 110: 16 double words (Single Address transfer only) 111: 32 double words (Single Address transfer only)</p>	R/W
1	MEMIO	Memory to I/O	<p>Memory to I/O (Default: 0)</p> <p>This bit specifies the transfer direction during Single Address transfer (DMCCRn.SNGAD = 1). Clear this bit when in the Memory Fill Transfer mode.</p> <p>The setting of this bit is ignored when Dual Address transfer is set (DMCCRn.SNGAD = 0).</p> <p>1: From memory to I/O 0: From I/O to memory</p>	R/W
0	SNGAD	Single Address	<p>Single Address (Default: 0)</p> <p>This bit specifies whether the transfer method is Single Address transfer or Dual Address transfer.</p> <p>1: Single Address transfer 0: Dual Address transfer</p>	R/W

Figure 8.4.2 DMA Channel Control Register (4/4)

8.4.3 DMA Channel Status Register (DMCSRn)

Offset Address: 0xB038 (ch. 0) / 0xB078 (ch. 1) / 0xB0B8 (ch. 2) / 0xB0F8 (ch. 3)



Bit	Mnemonic	Field Name	Description	Read/Write
63:32		Reserved		—
31:16	WAITC	Wait Counter	Wait Counter (Default: 0x0000) This is a diagnostic function. • I/O DMA transfer mode (DMCCRn.EXTRQ = "1") This counter is decremented by 1 at each 64 G-Bus cycles. After channel <i>n</i> releases bus ownership, this counter sets the default (the value that is the detection interval clock cycle count set by the Transfer Stall Detection Interval field (DMCCRn.STLTIME) divided by 64). The Transfer Stall Detect bit (DMCSRn.STLXFER) is set when the interval during which bus ownership is not held reaches the set clock cycle. The counter is reset to the default and stops counting. Clearing the Transfer Stall Detect bit (DMCSRn.STLXFER) resumes the count and starts stall detection. • Memory transfer mode (DMCCRn.EXTRQ = "0") This counter is decremented by 1 at each G-Bus cycle. After bus ownership is released, the counter is set to the delay clock cycle count set by the Internal Request Delay field (DMCCRn.INTRQD). When the counter reaches "0" the count stops and channel <i>n</i> requests bus ownership.	R
15:11		Reserved		—
10	CHNEN	Chain Enable	Chain Enable (Default: 0) This value is a copy of the Chain Enable bit (CHNEN) of the DMA Channel Control Register (DMCCRn).	R
9	STLXFER	Transfer Stall Detect	Stalled Transfer Detect (Default: 0) This bit indicates whether the interval during which bus ownership is not held exceeds the value set by the Transfer Stall Detect Interval field (DMCCRn.STLTIME) after bus ownership is released when in the I/O DMA transfer mode. 1: Indicates that the interval during which bus ownership was not held exceeds the DMCCRn.STLTIME setting. 0: The interval during which bus ownership was not held did not exceed the setting since this bit was last cleared.	R/W1C

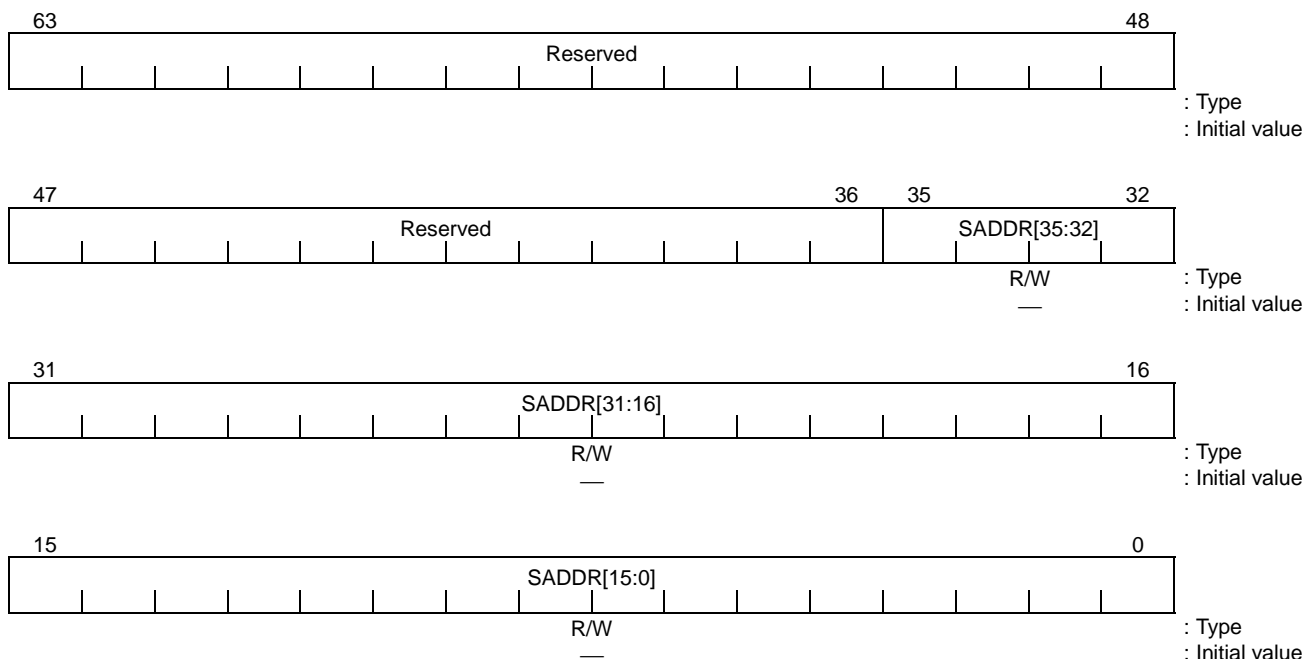
Figure 8.4.3 DMA Channel Status Register (1/2)

Bit	Mnemonic	Field Name	Description	Read/Write
8	XFACT	Transfer Active	Transfer Active (Default: 0) This value is a copy of the Transfer Active bit (XFACT) of the DMA Channel Control Register (DMCCRn).	R
7	ABCHC	Error Complete	Error Completion (Default: 0) This bit indicates whether an error occurred during DMA transfer. This bit indicates the logical sum of the four error bits (CFERR, CHERR, DESERR, SORERR) in DMCSRn[3:0]. 1: DMA transfer ends due to an error. 0: No error occurred since this bit was last cleared.	R
6	NCHNC	Chain Complete	Normal Chain Completion (Default: 0) When performing chain DMA transfer, This bit indicates whether all DMA data transfers in the DMA Descriptor chain are complete. 1: All DMA data transfers in the DMA Descriptor chain ended normally. Or, DMA transfer that did not use a DMA Descriptor chain ended normally. 0: DMA transfer has not ended normally since this bit was last cleared.	R/W1C
5	NTRNFC	Transfer Complete	Normal Transfer Completion (Default: 0) This bit indicates whether DMA transfer ended according to the current DMA Channel Register setting. 1: DMA transfer ended normally. 0: DMA transfer has not ended since this bit was last cleared.	R/W1C
4	EXTDN	External DONE Asserted	External Done Asserted (Default: 0) This bit indicates whether an external I/O device asserted the DMADONE* signal. When the DMADONE* signal is set to bidirectional, this bit is also set when the TX4927 asserts the DMADONE* signal. 1: DMADONE* signal was asserted. 0: DMADONE* signal was not asserted.	R/W1C
3	CFERR	Configuration Error	Configuration Error (Default: 0) Indicates whether an illegal register setting was made. 1: There was a configuration error. 0: There was no configuration error.	R/W1C
2	CHERR	Chain Bus Error	Chain Bus Error (Default: 0) This bit indicates whether a bus error occurred while reading a DMA Command Descriptor. 1: Bus error occurred. 0: No bus error occurred.	R/W1C
1	DESERR	Destination Error	Destination Bus Error (Default: 0) This bit indicates whether a bus error occurred during a destination bus Write operation (a Write to a set DMDARn address). 1: Bus error occurred. 0: No bus error occurred.	R/W1C
0	SORERR	Source Bus Error	Source Bus Error (Default: 0) This bit indicates whether a bus error occurred during either a source bus Read or Write operation (A Read or Write to a set DMSARn address). 1: Bus error occurred. 0: No bus error occurred.	R/W1C

Figure 8.4.3 DMA Channel Status Register (2/2)

8.4.4 DMA Source Address Register (DMSARn)

Offset Address: 0xB008 (ch. 0) / 0xB048 (ch. 1) / 0xB088 (ch. 2) / 0xB0C8 (ch. 3)

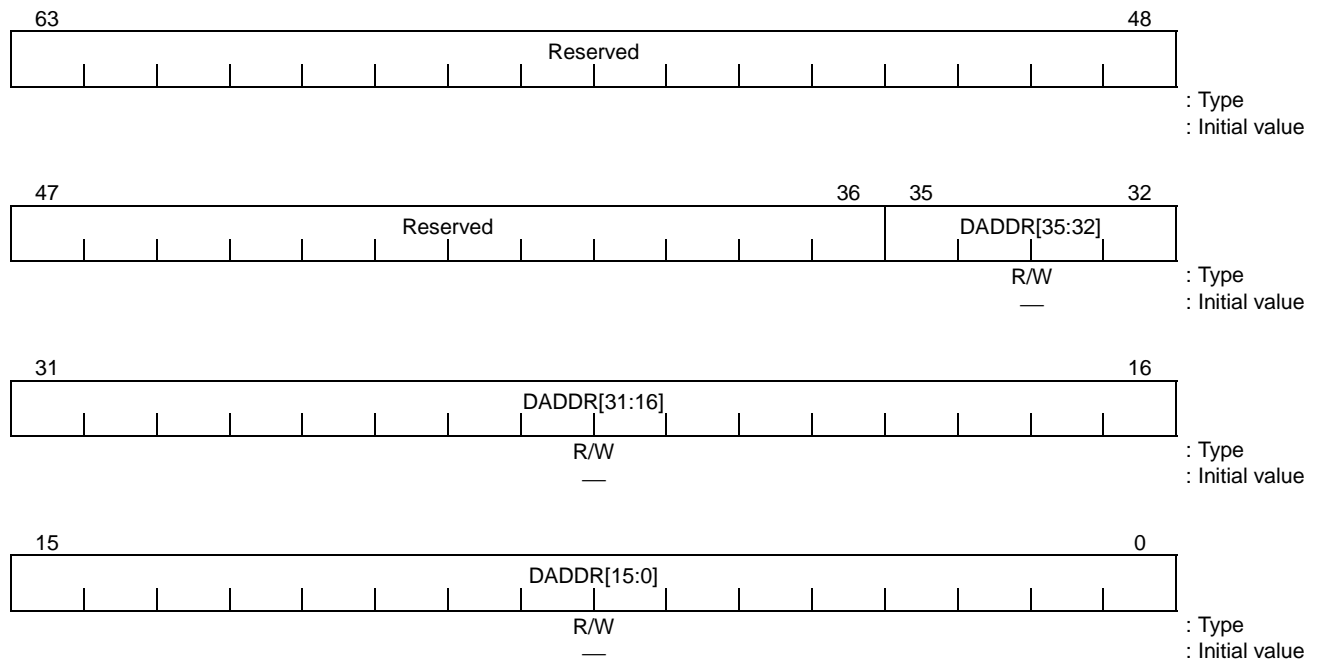


Bits	Mnemonic	Field Name	Description	Read/Write
63:36	—	Reserved		—
35:0	SADDR	Source Address	<p>Source Address (Default: Undefined)</p> <p>This field sets the physical address of the transfer source during Dual Address transfer. This field sets the physical address of memory access during Single Address transfer. This field is used for either Memory-to-I/O or I/O-to-Memory transfers.</p> <p>Refer to “8.3.7.1 Channel Register Settings During Single Address Transfer” and “8.3.8.1 Channel Register Settings During Dual Address Transfer” for more information.</p> <p>During Burst transfer, the value changes once for each bus operation only by the size that was transferred. During Single transfer, the value only changes by the value specified by the DMA Source Address Increment Register (DMSAIRn).</p>	R/W

Figure 8.4.4 DMA Source Address Register

8.4.5 DMA Destination Address Register (DMDARn)

Offset Address: 0xB010 (ch. 0) / 0xB050 (ch. 1) / 0xB090 (ch. 2) / 0xB0D0 (ch. 3)

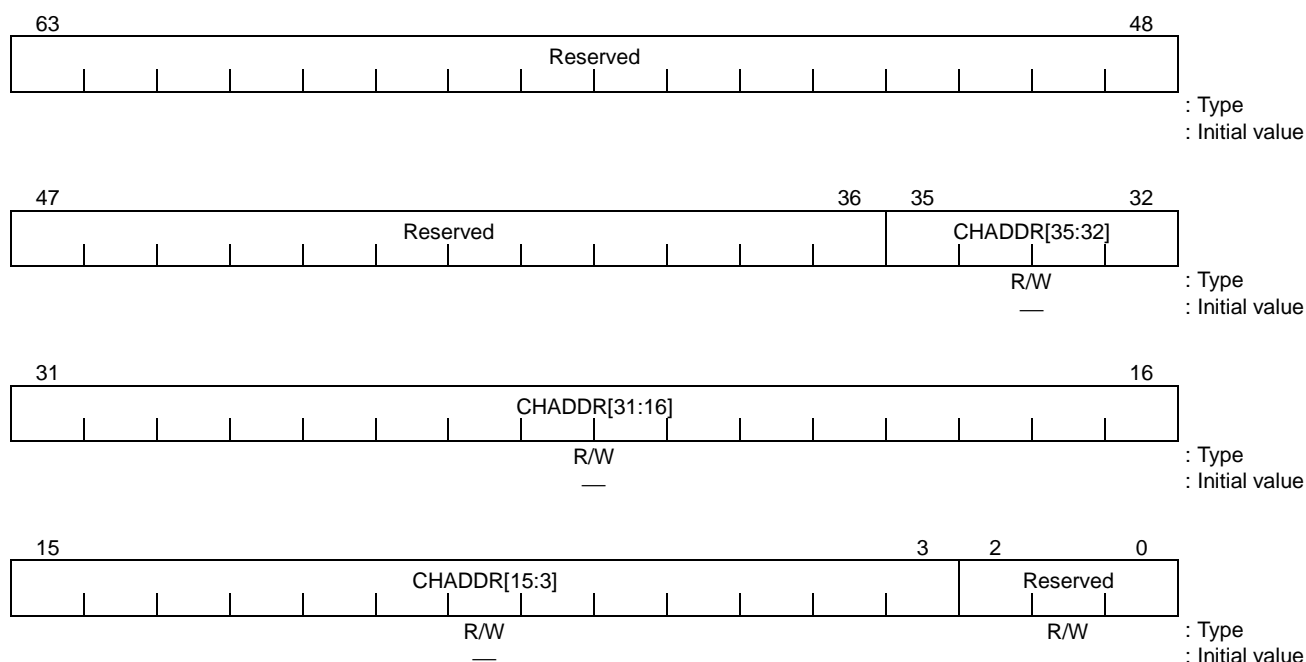


Bit	Mnemonic	Field Name	Description	Read/Write
63:36		Reserved		—
35:0	DADDR	Destination Address	Destination Address (Default: undefined) This register sets the physical address of the transfer destination during Dual Address transfer. This register is ignored during Single Address transfer. Refer to “8.3.8.1 Channel Register Settings During Dual Address Transfer” for more information. During Burst transfer, the value changes only by the size of data transferred during each single bus operation. During Single transfer, the value only changes by the value specified by the DMA Destination Address Increment Register (DMDAIRn).	R/W

Figure 8.4.5 DMA Destination Address Register

8.4.6 DMA Chain Address Register (DMCHARn)

Offset Address: 0xB000 (ch. 0) / 0xB040 (ch. 1) / 0xB080 (ch. 2) / 0xB0C0 (ch. 3)

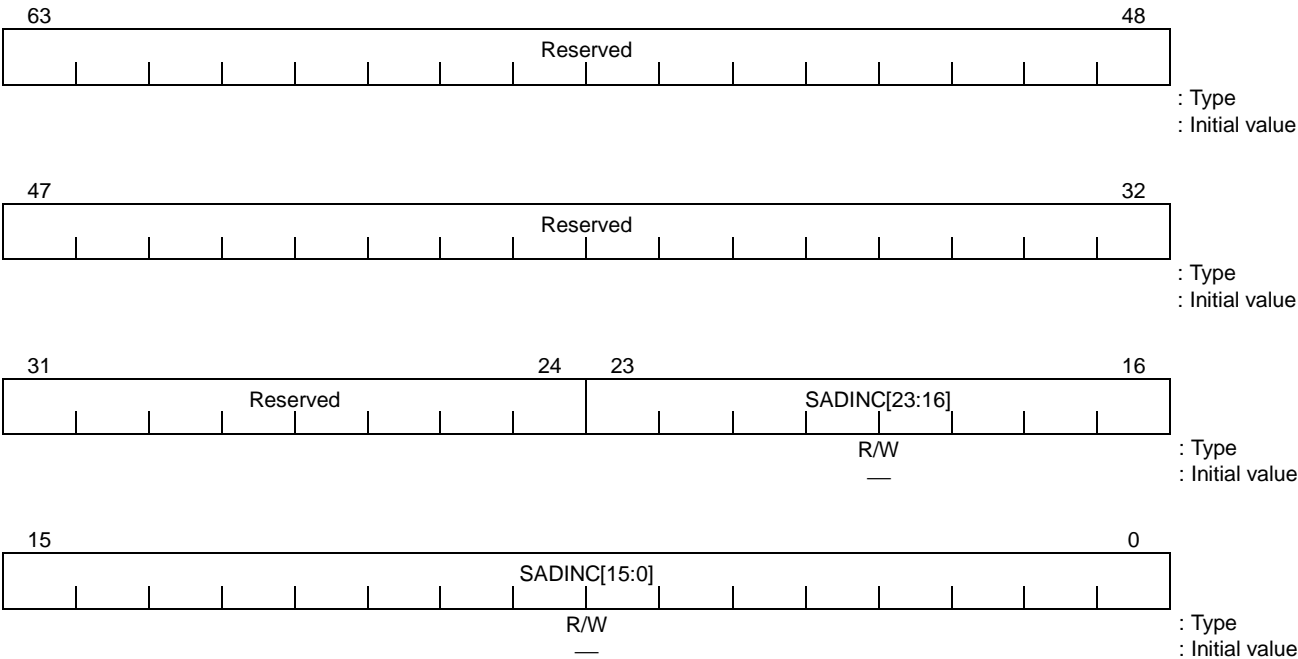


Bit	Mnemonic	Field Name	Description	Read/Write
63:36		Reserved		—
35:3	CHADDR	Chain Address	Chain Address (Default: undefined) When Chain DMA transfer is executed, this register sets the physical address of the next DMA Command Descriptor to be read. If DMA transfer according to the current Channel Register setting ends and the Chain Enable bit (DMCCRn.CHNEN) is set, then the DMA Command Descriptor is loaded in the Channel Register starting from the address indicated by this register. When a value other than "0" is set in this register, the Chain Enable bit (DMCCRn.CHNEN) and the Transfer Active bit (DMCCRn.XFACT) are set. When "0" is set in this register, only the Chain Enable bit (DMCCRn.CHNEN) is cleared. When the Chain Address field value reads a DMA Command Descriptor of 0, the value of this register is not updated and the value before that one (address of the Data Command Descriptor when the value of the Chain Address field being read was "0") is held.	R/W
2:0		Reserved		R/W

Figure 8.4.6 DMA Chain Address Register

8.4.7 DMA Source Address Increment Register (DMSAIRn)

Offset Address: 0xB020 (ch. 0) / 0xB060 (ch. 1) / 0xB0A0 (ch. 2) / 0xB0E0 (ch. 3)

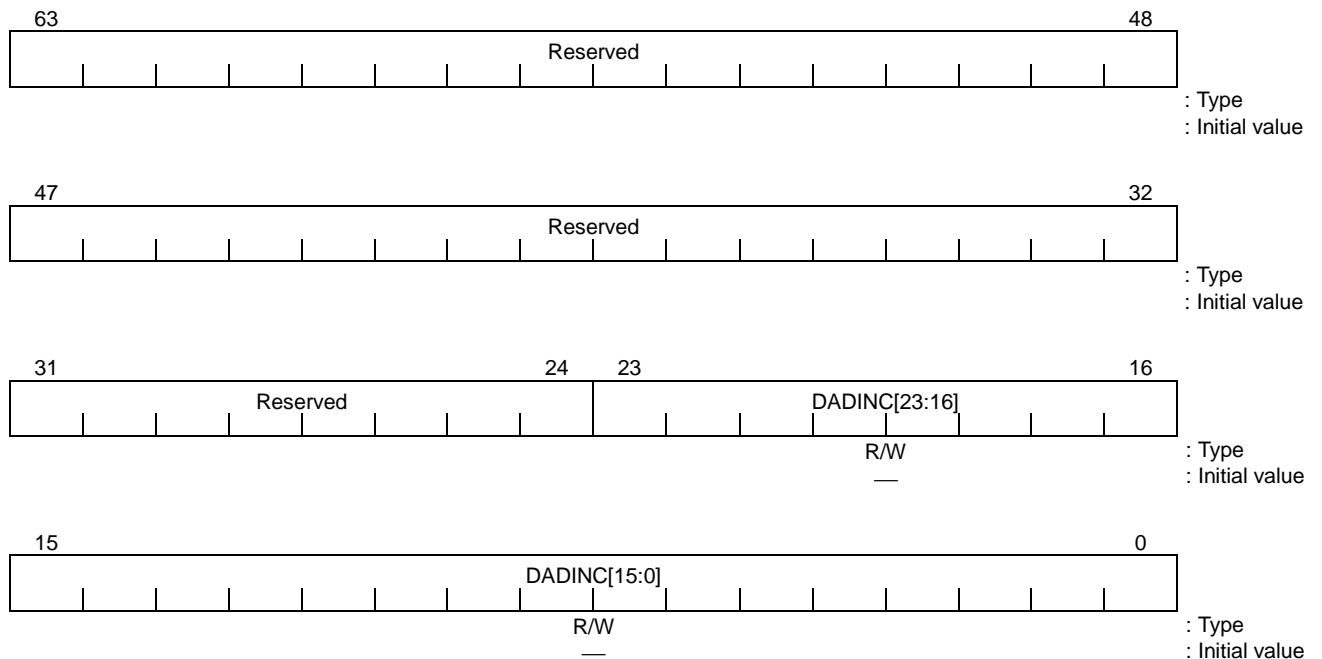


Bit	Mnemonic	Field Name	Description	Read/Write
63:24		Reserved		—
23:0	SADINC	Source Address Increment	Source Address Increment (Default: undefined) This field sets the increase/decrease value of the DMA Source Address Register (DMSARn). This value is a 24-bit two's complement and indicates a byte count. Refer to "8.3.7.1 Channel Register Settings During Single Address Transfer" and "8.3.8.1 Channel Register Settings During Dual Address Transfer" for more information.	R/W

Figure 8.4.7 DMA Source Address Increment Register

8.4.8 DMA Destination Address Increment Register (DMDAIRn)

Offset Address: 0xB028 (ch. 0) / 0xB068 (ch. 1) / 0xB0A8 (ch. 2) / 0xB0E8 (ch. 3)

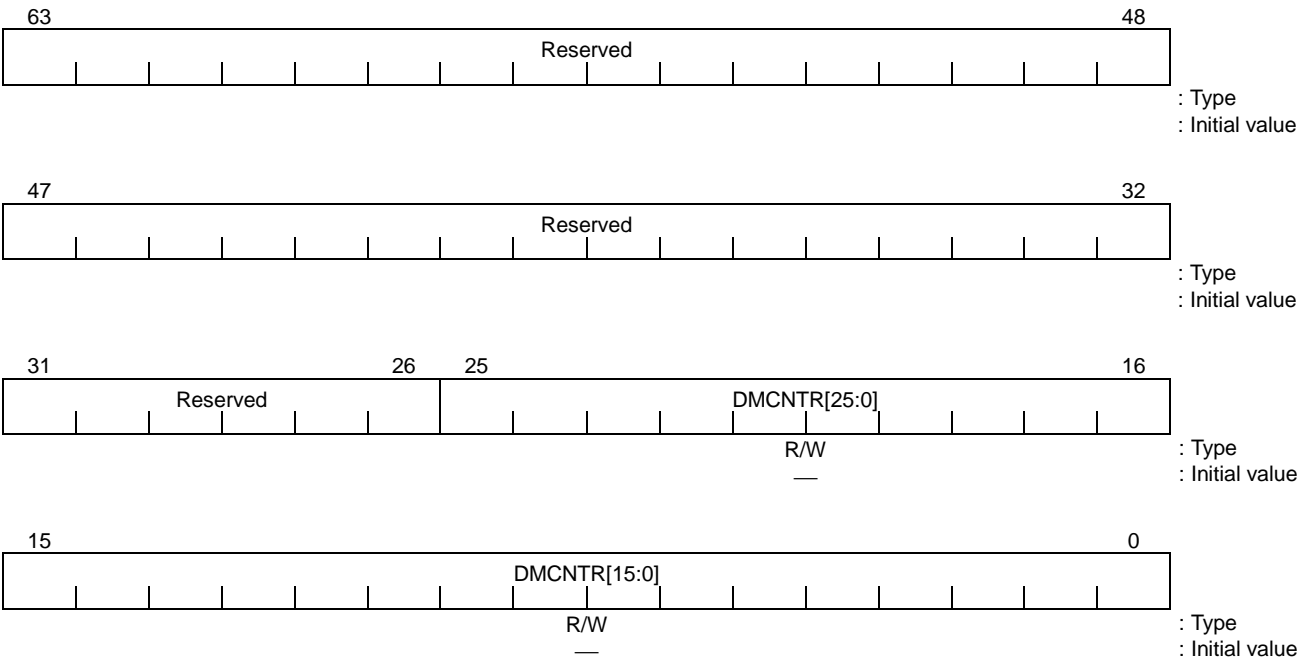


Bit	Mnemonic	Field Name	Description	Read/Write
63:24		Reserved		—
23:0	DADINC	Destination Address Increment	Destination Address Increment (Default: undefined) This field sets the increase/decrease value of the DMA Destination Address Register (DMDARn). This value is a 24-bit two's complement and indicates a byte count. Refer to "8.3.8.1 Channel Register Settings During Dual Address Transfer" for more information.	R/W

Figure 8.4.8 DMA Destination Address Increment Register

8.4.9 DMA Count Register (DMCNTRn)

Offset Address: 0xB018 (ch. 0) / 0xB058 (ch. 1) / 0xB098 (ch. 2) / 0xB0D8 (ch. 3)

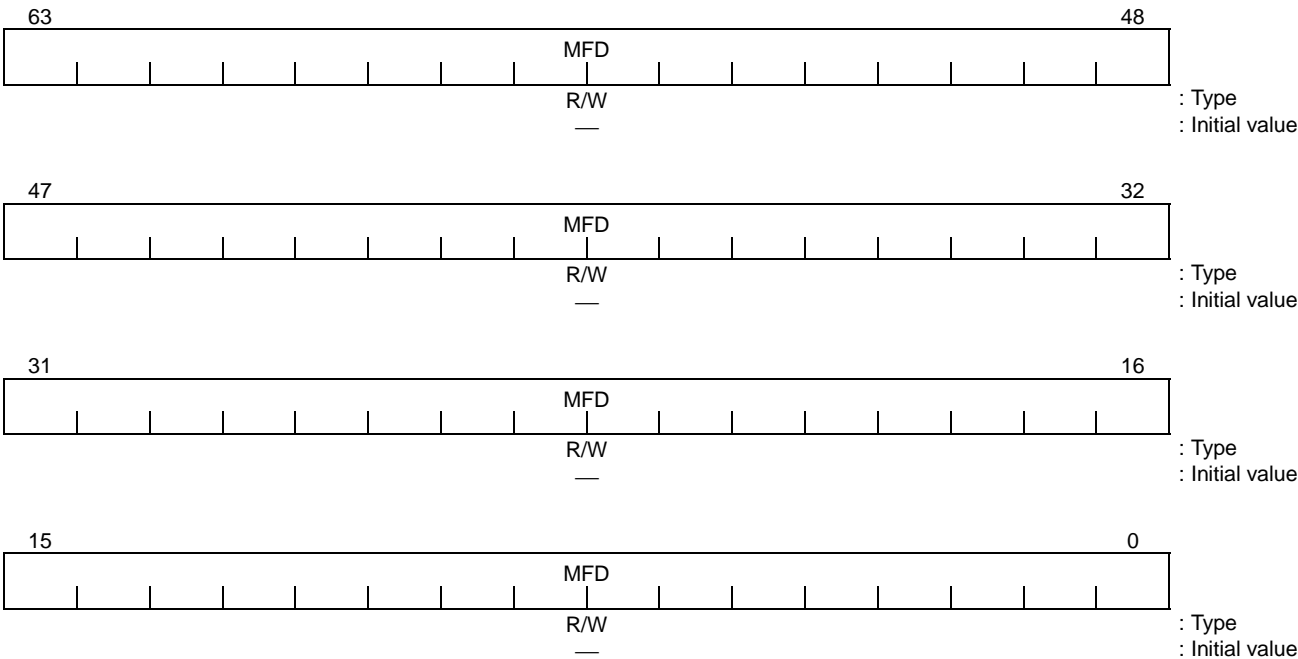


Bit	Mnemonic	Field Name	Description	Read/Write
63:26		Reserved		—
25:0	DMCNTR	Count	Count Register (Default: undefined) This register sets the byte count that is transferred by the DMA Channel Register setting. The value is a 26-bit unsigned data that is decremented only by the size of the data transferred during a single bus operation. Refer to “8.3.7.1 Channel Register Settings During Single Address Transfer” and “8.3.8.1 Channel Register Settings During Dual Address Transfer” for more information.	R/W

Figure 8.4.9 DMA Count Register

8.4.10 DMA Memory Fiill Data Register (DMMFDR)

Offset Address: 0xB148



Bit	Mnemonic	Field Name	Description	Read/Write
63:0	MFD	Memory Fill Data	Memory Fill Data (Default: undefined) This register, which stores double-word data written to memory when in the Memory Fill Transfer mode, is shared between all channels.	R/W

Figure 8.4.10 DMA Memory Fill Data Register

8.5 Timing Diagrams

This section contains timing diagrams for the external I/O DMA transfer mode. The DMAREQ[n] signals and DMAACK[n] signals in the timing diagrams are set to Low Active.

8.5.1 Single Address Single Transfer from Memory to I/O (32-bit ROM)

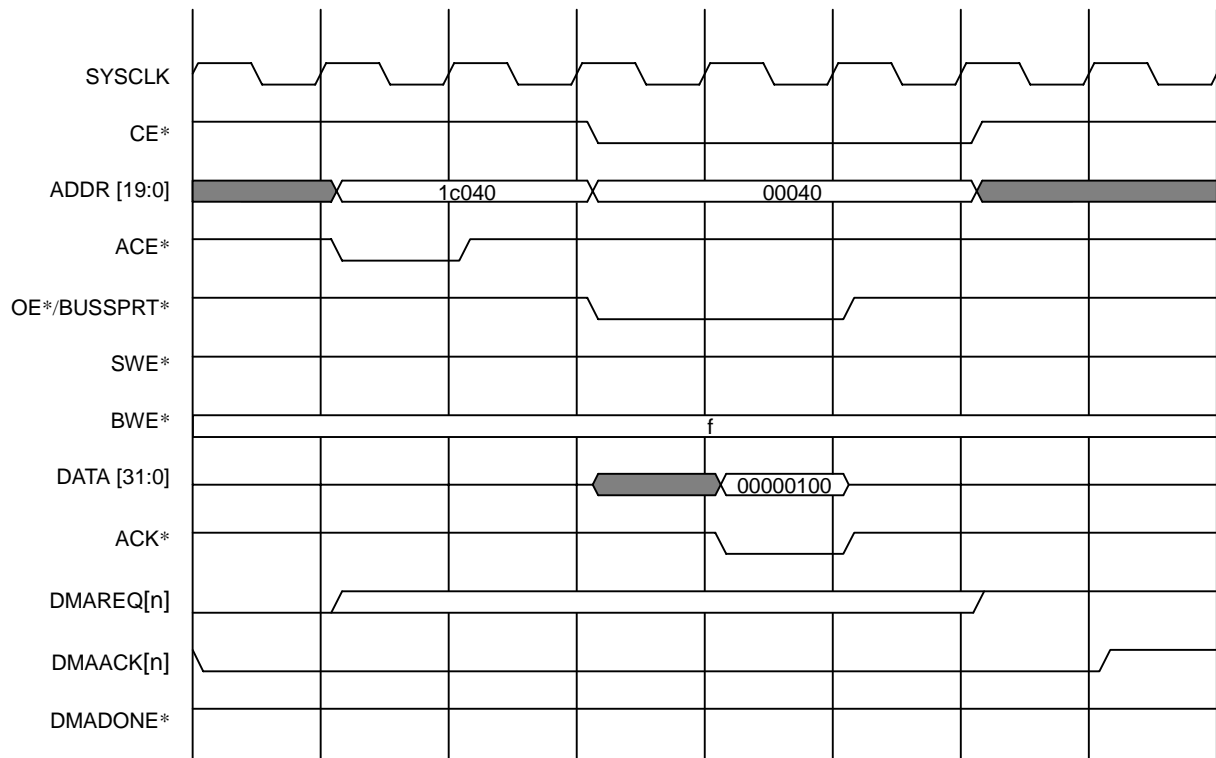


Figure 8.5.1 Single Address Single Transfer from Memory to I/O
(Single Read of 32-bit Data from 32-bit ROM)

8.5.2 Single Address Single Transfer from Memory to I/O (16-bit ROM)

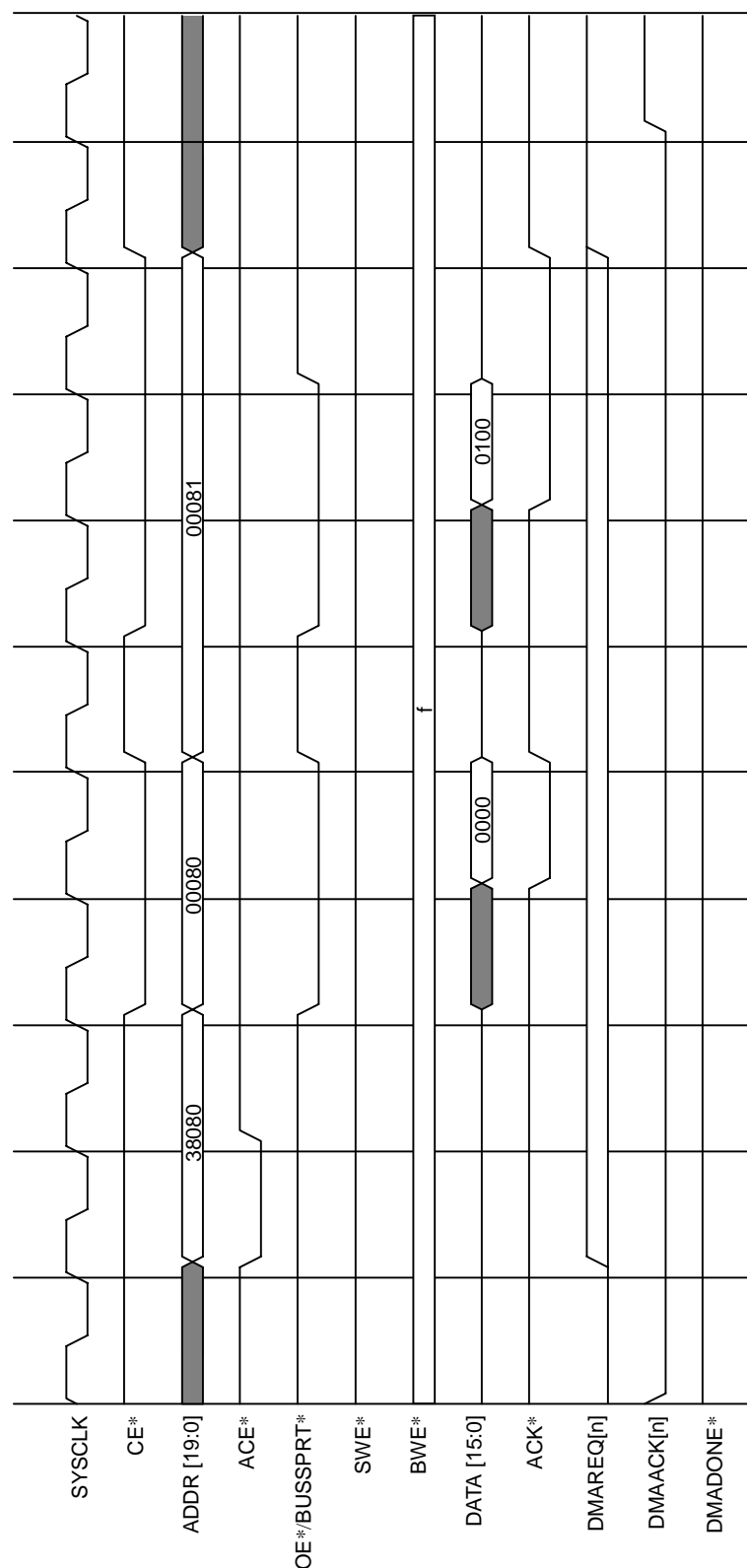


Figure 8.5.2 Single Address Single Transfer from Memory to I/O
(Single Read of 32-bit Data from 16-bit ROM)

8.5.3 Single Address Single Transfer from I/O to Memory (32-bit SRAM)

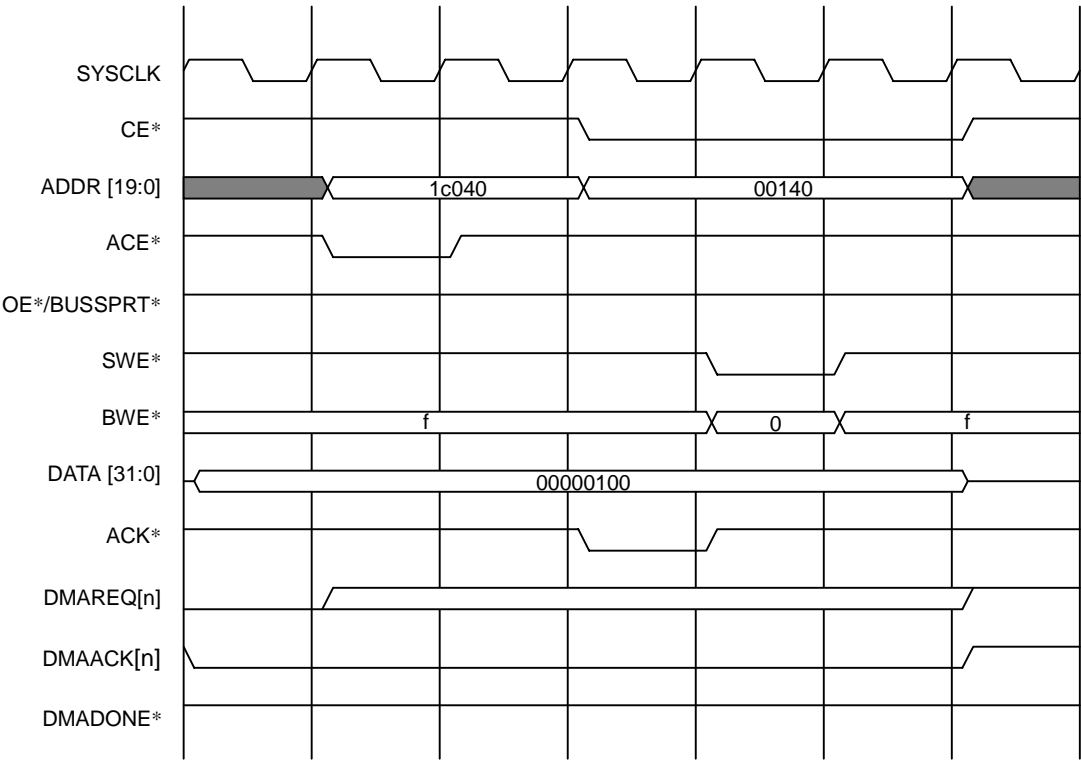


Figure 8.5.3 Single Address Single Transfer from I/O to Memory
(Single Write of 32-bit Data to 32-bit SRAM)

8.5.4 Single Address Burst Transfer from Memory to I/O (32-bit ROM)

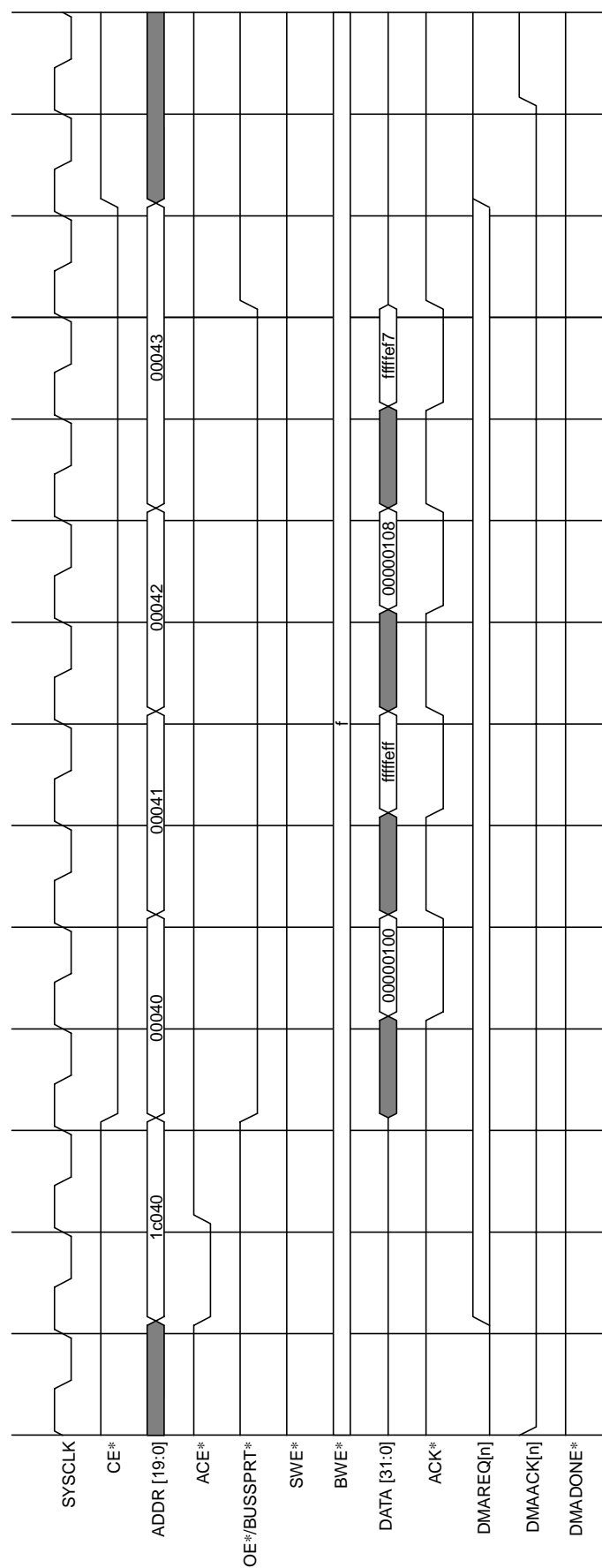


Figure 8.5.4 Single Address Burst Transfer from Memory to I/O
(Burst Read of 4-word Data from 32-bit ROM)

8.5.5 Single Address Burst Transfer from I/O to Memory (32-bit SRAM)

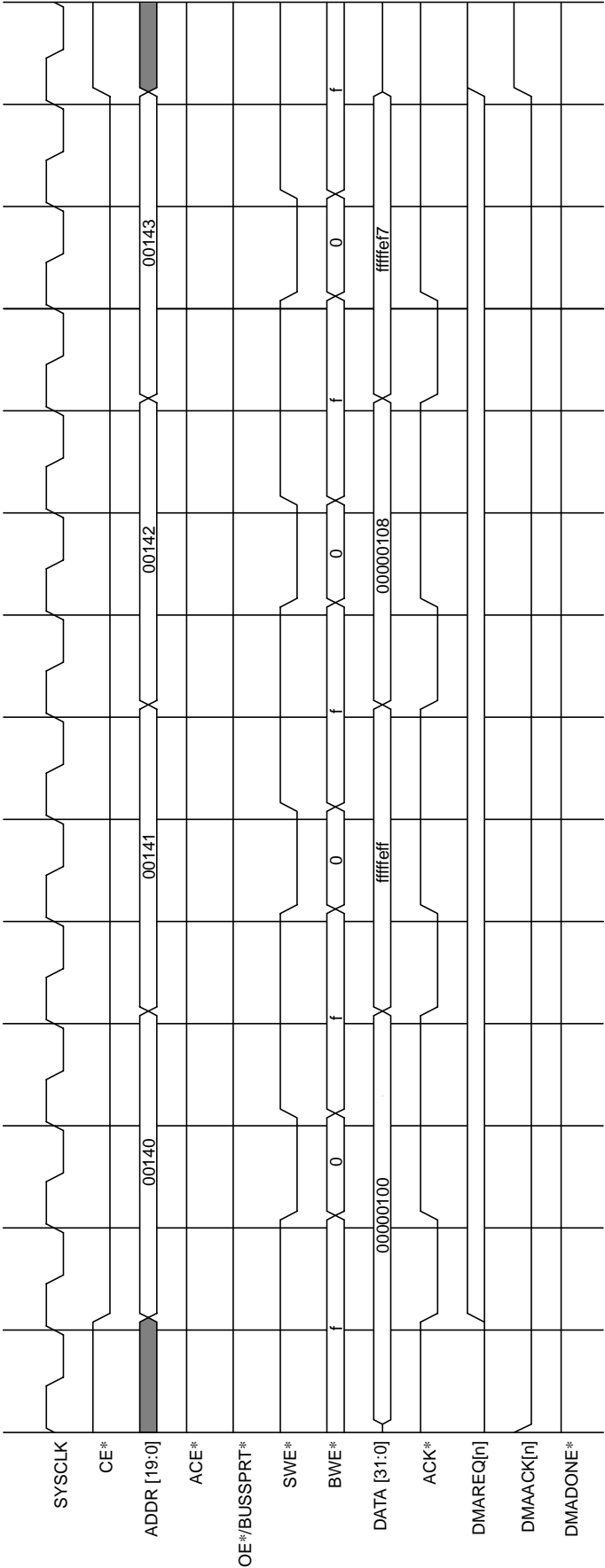


Figure 8.5.5 Single Address Burst Transfer from I/O to Memory
(Burst Write of 4-word Data from 32-bit SRAM)

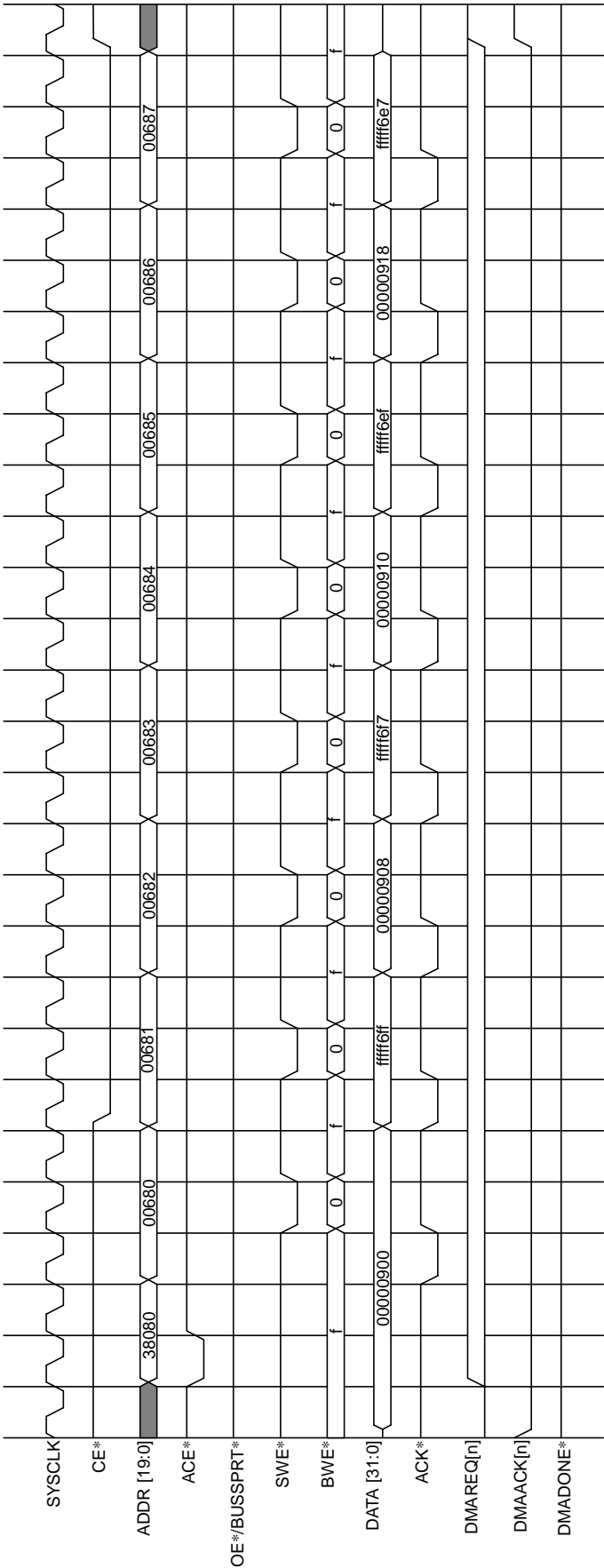


Figure 8.5.6 Single Address Burst Transfer from I/O to Memory
(Burst Write of 8-word Data to 32-bit SRAM)

8.5.6 Single Address Single Transfer from Memory to I/O (16-bit ROM)

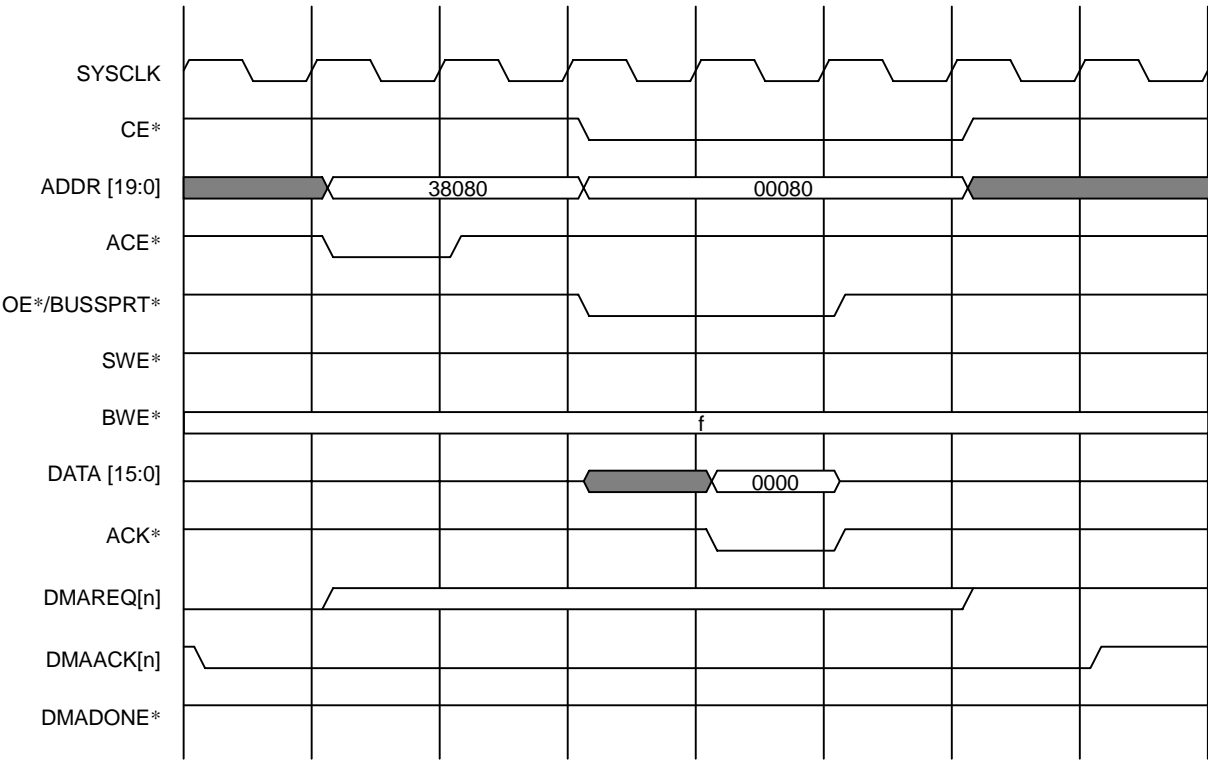


Figure 8.5.7 Single Address Single Transfer from Memory to I/O
(Single Read from 16-bit ROM to 16-bit Data)

8.5.7 Single Address Single Transfer from I/O to Memory (16-bit SRAM)

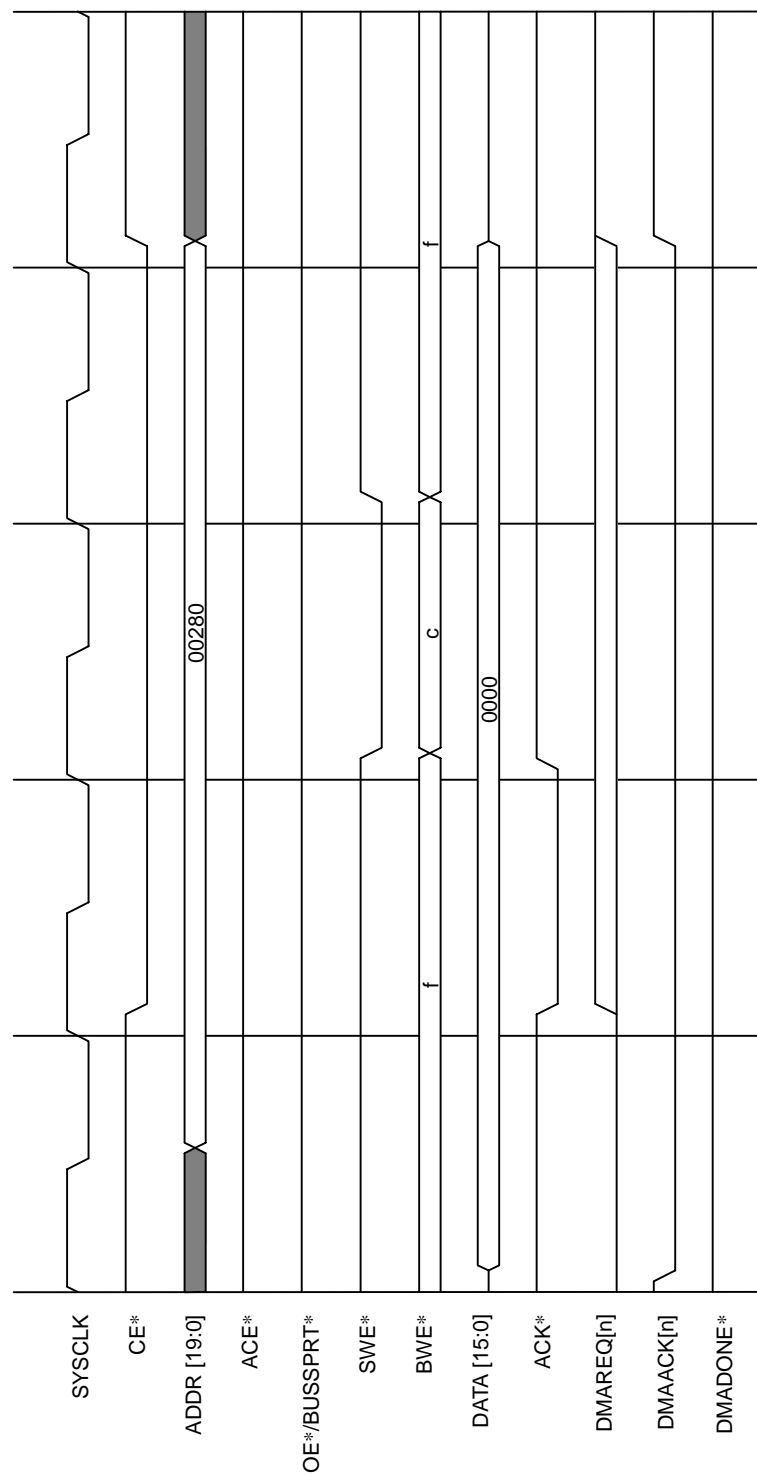


Figure 8.5.8 Single Address Single Transfer from I/O to Memory
(Single Write of 16-bit Data to 16-bit SRAM)

8.5.8 Single Address Single Transfer from Memory to I/O (32-bit Half Speed ROM)

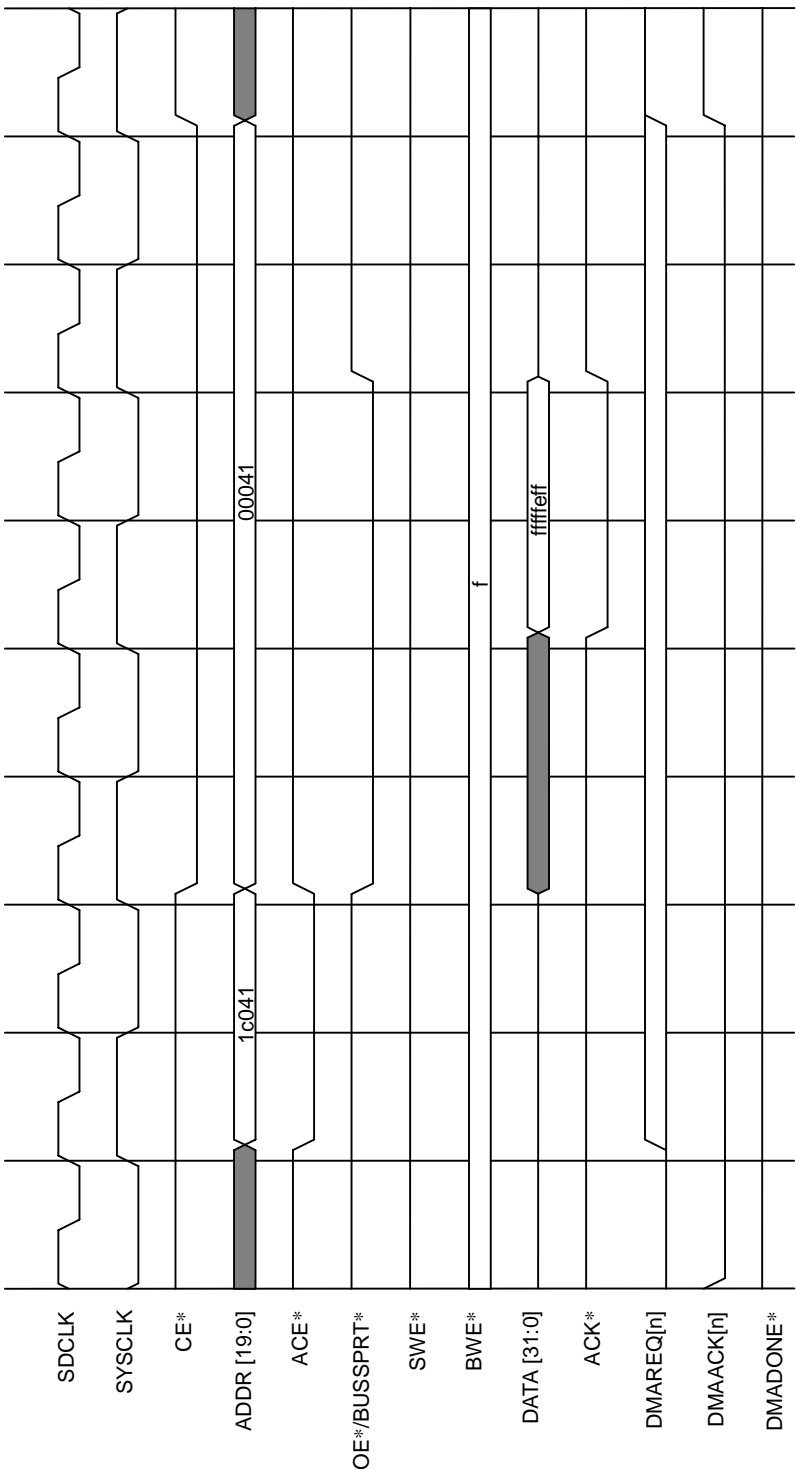


Figure 8.5.9 Single Address Single Transfer from Memory to I/O
(Single Read of 32-bit Data from 32-bit Half Speed ROM)

8.5.9 Single Address Single Transfer from I/O to Memory (32-bit Half Speed SRAM)

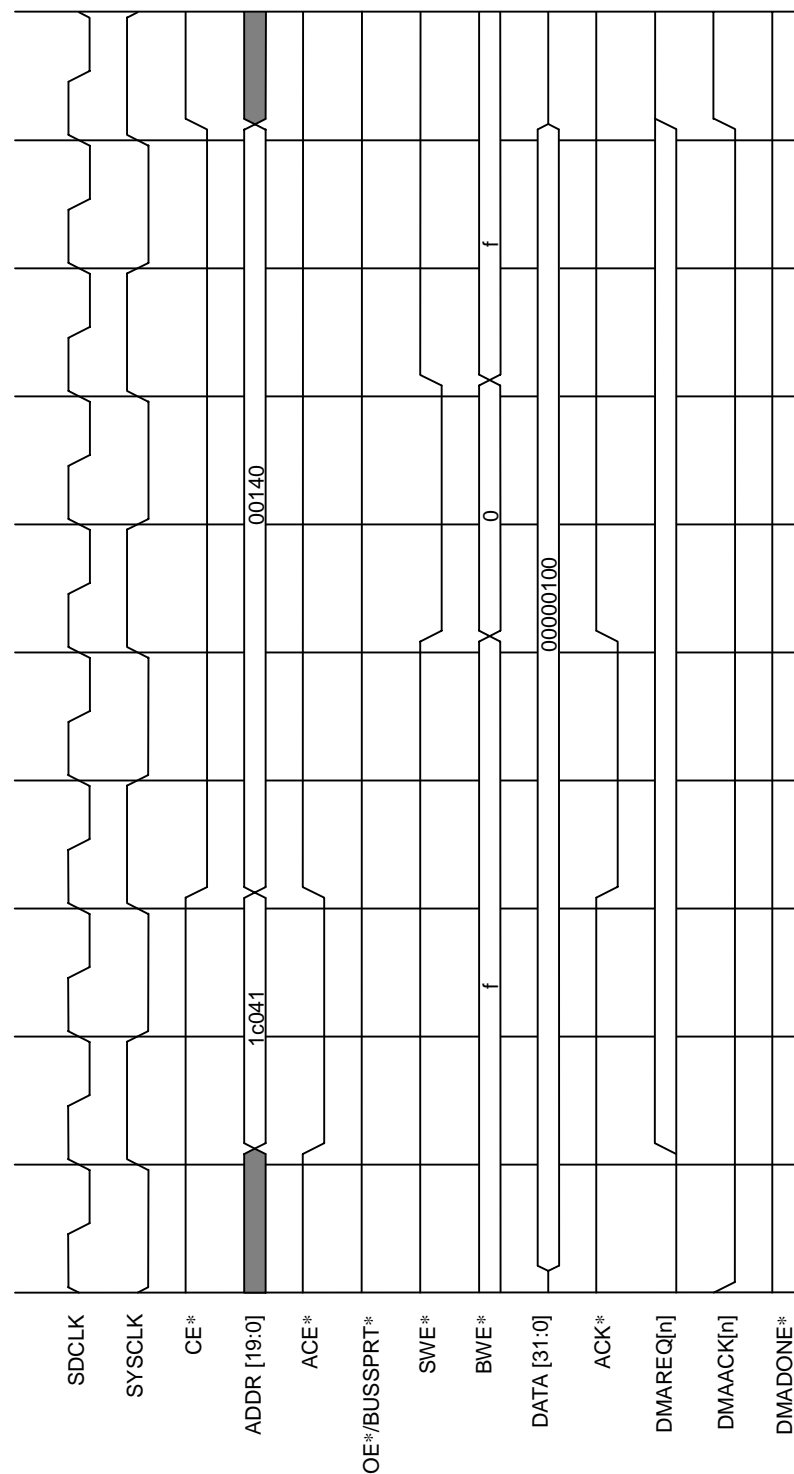


Figure 8.5.10 Single Address Single Transfer from I/O to Memory
(Single Write of 32-bit Data to 32-bit Half Speed SRAM)

8.5.10 Single Address Single Transfer from Memory to I/O (64-bit SRAM)

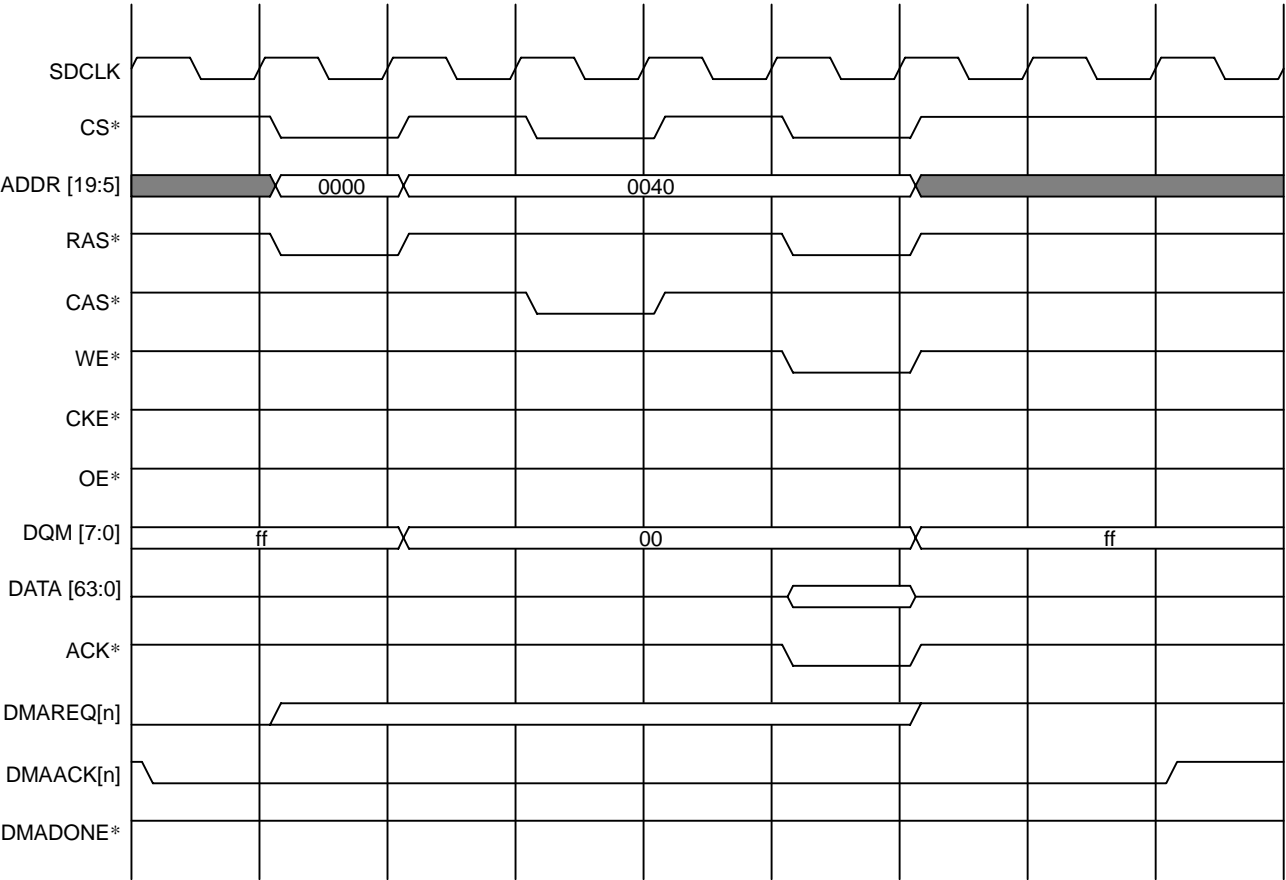


Figure 8.5.11 Single Address Single Transfer from Memory to I/O
(Single Read of 64-bit Data from 64-bit SDRAM)

8.5.11 Single Address Single Transfer from I/O to Memory (64-bit SDRAM)

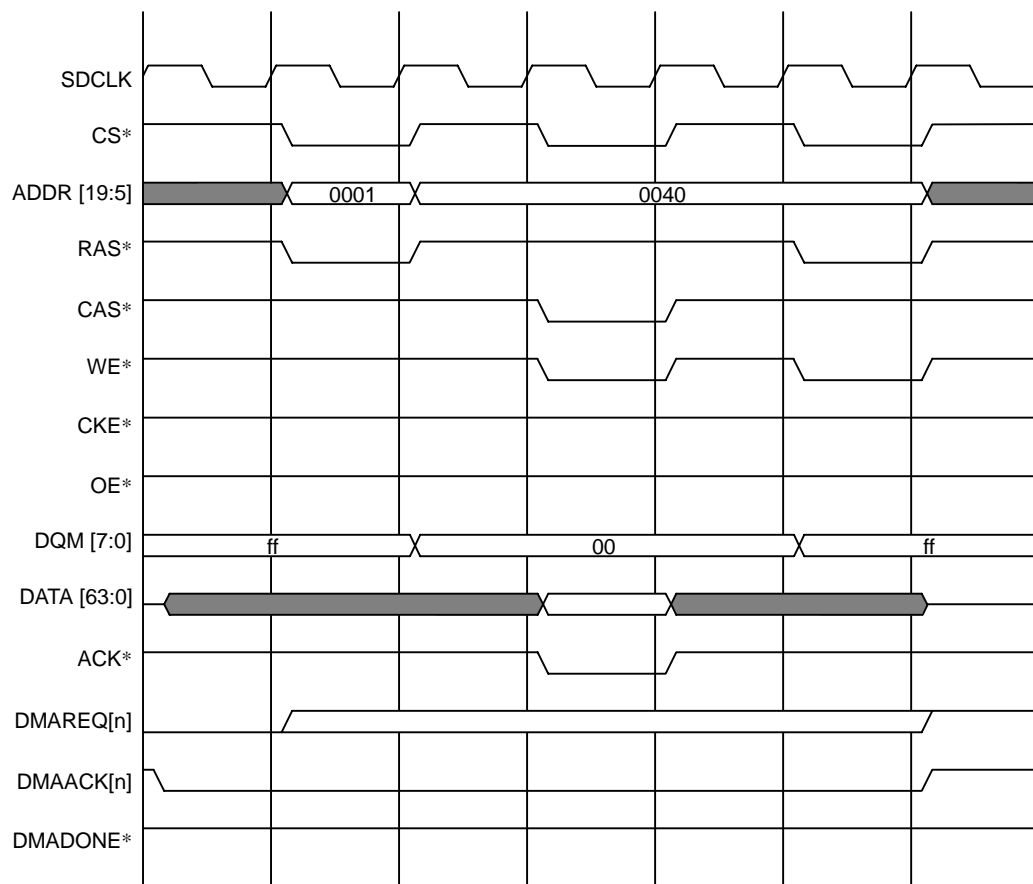


Figure 8.5.12 Single Address Single Transfer from I/O to Memory
(Single Write of 64-bit Data to 64-bit SDRAM)

8.5.12 Single Address Single Transfer from Memory to I/O of Last Cycle when DMADONE* Signal is Set to Output

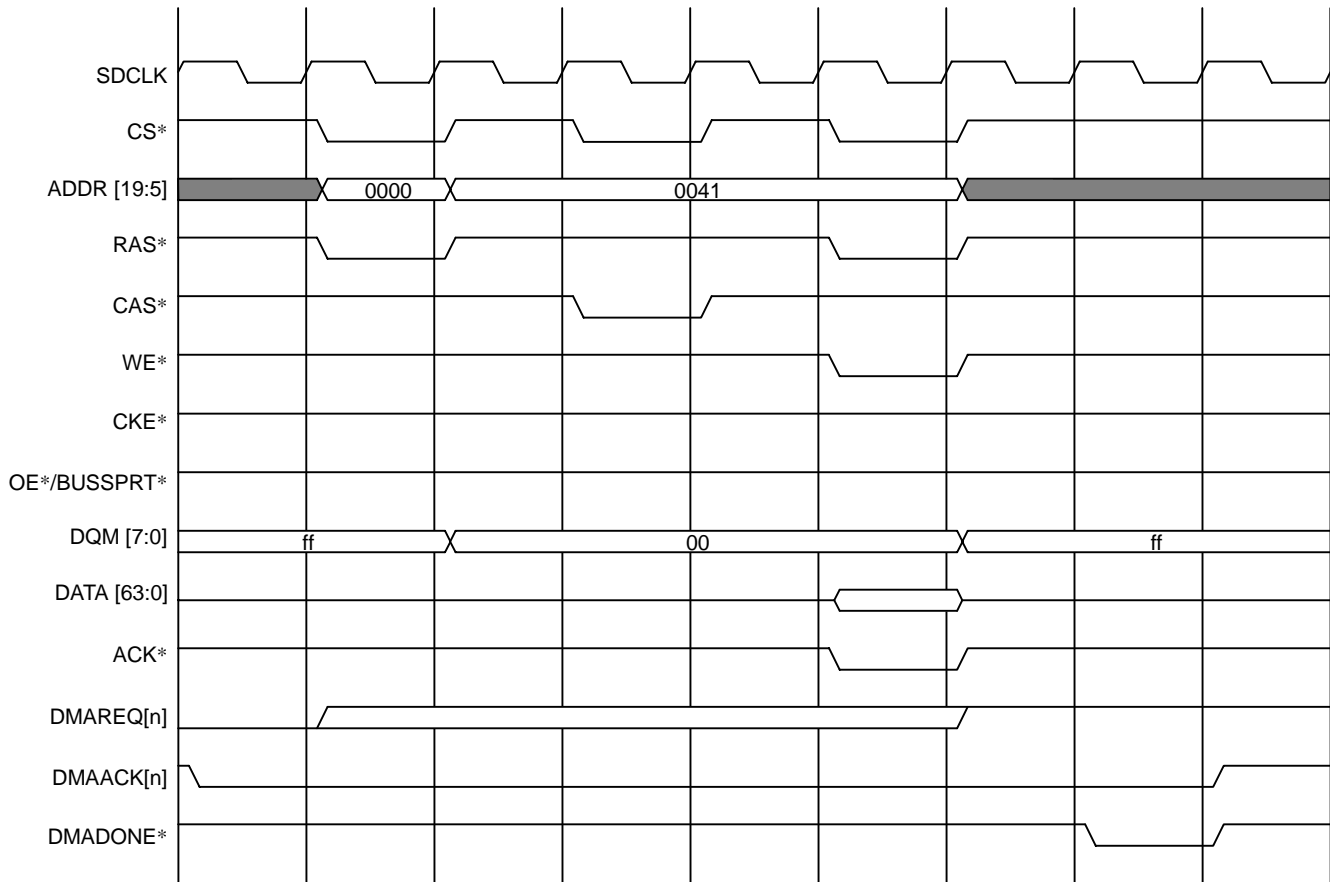


Figure 8.5.13 Single Address Single Transfer from Memory to I/O
(Single Read of 64-bit Data from 64-bit SDRAM)

8.5.13 Single Address Single Transfer from Memory to I/O (32-bit SDRAM)

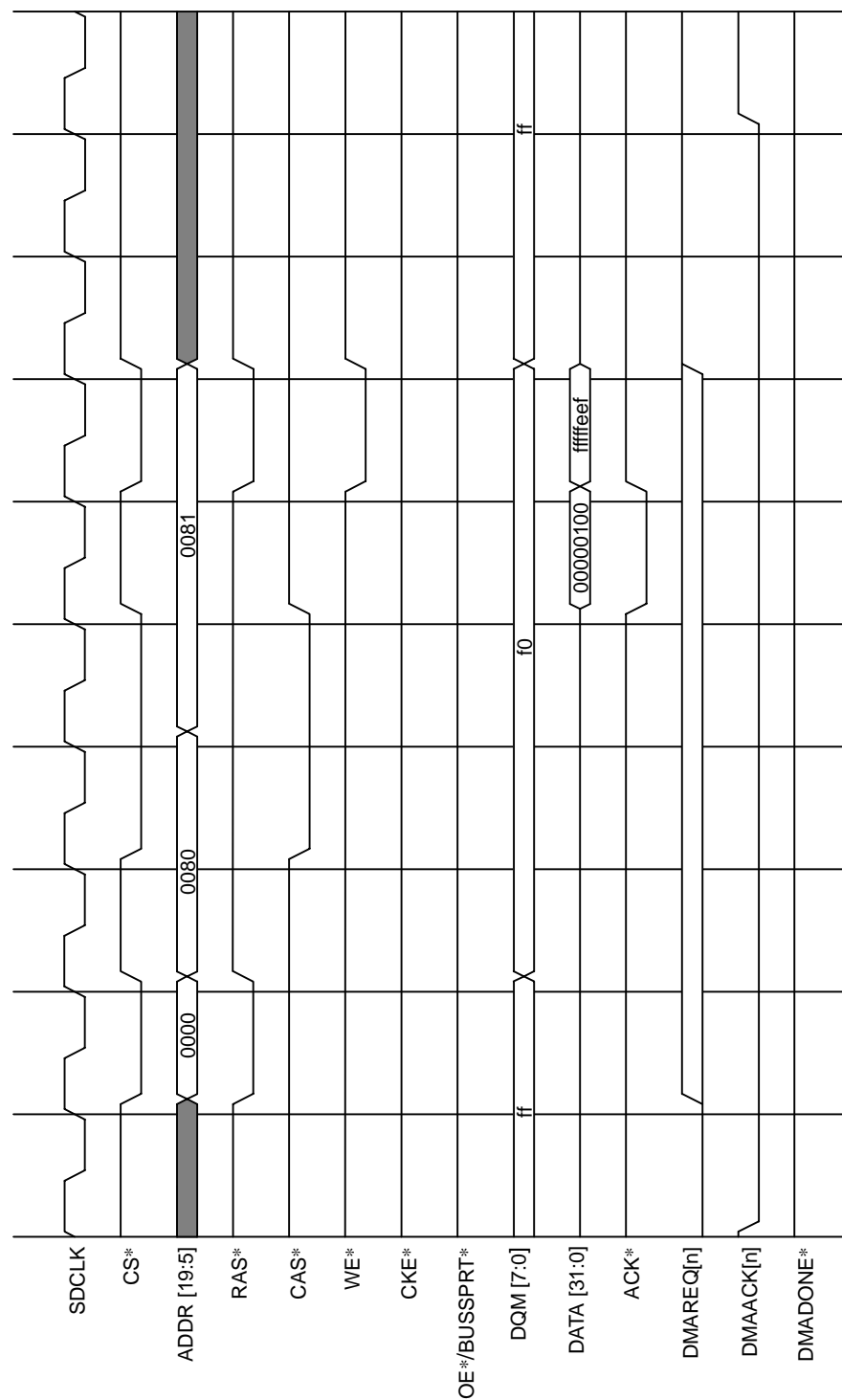


Figure 8.5.14 Single Address Single Transfer from Memory to I/O
(Single Read of 32-bit Data from 32-bit SDRAM)

8.5.14 Single Address Single Transfer from I/O to Memory (32-bit SDRAM)

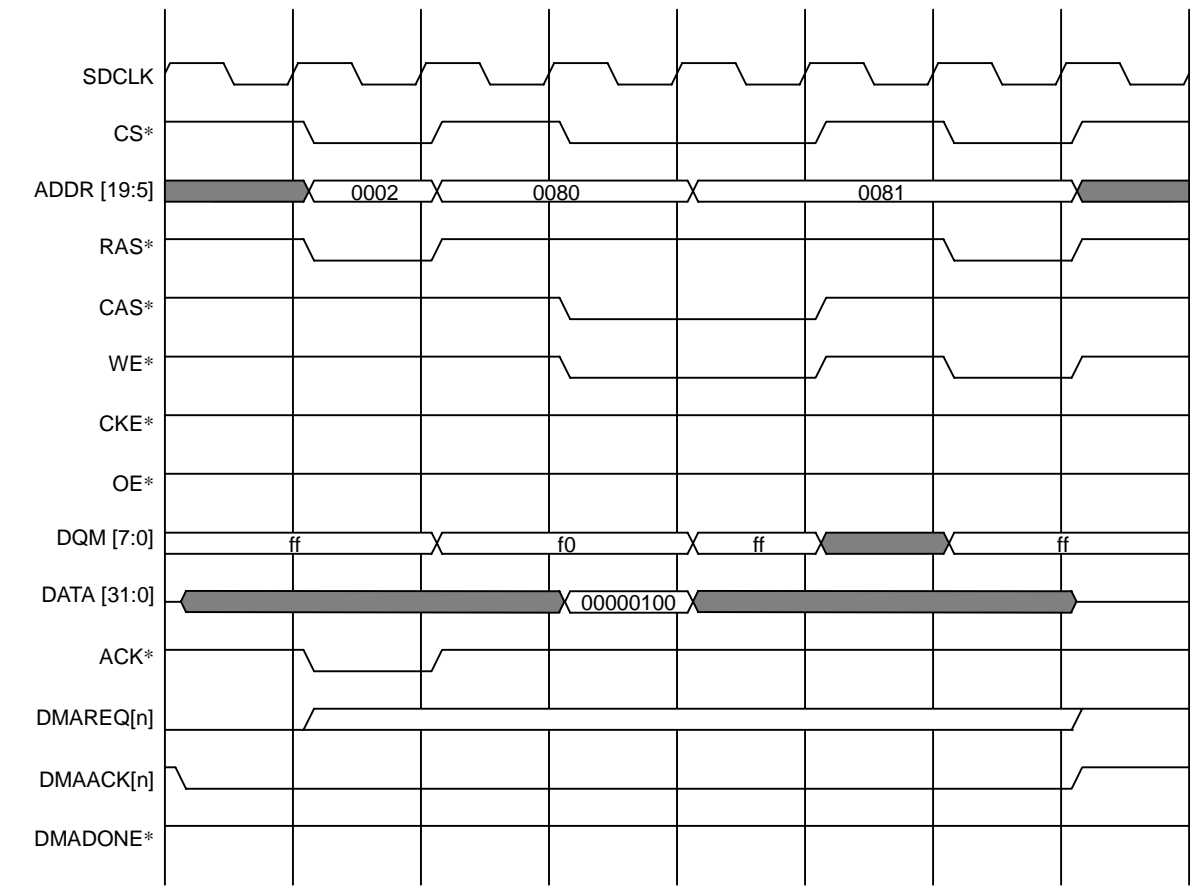


Figure 8.5.15 Single Address Single Transfer from I/O to Memory
(Single Write of 32-bit Data to 32-bit SDRAM)

8.5.15 External I/O Device – SRAM Dual Address Transfer

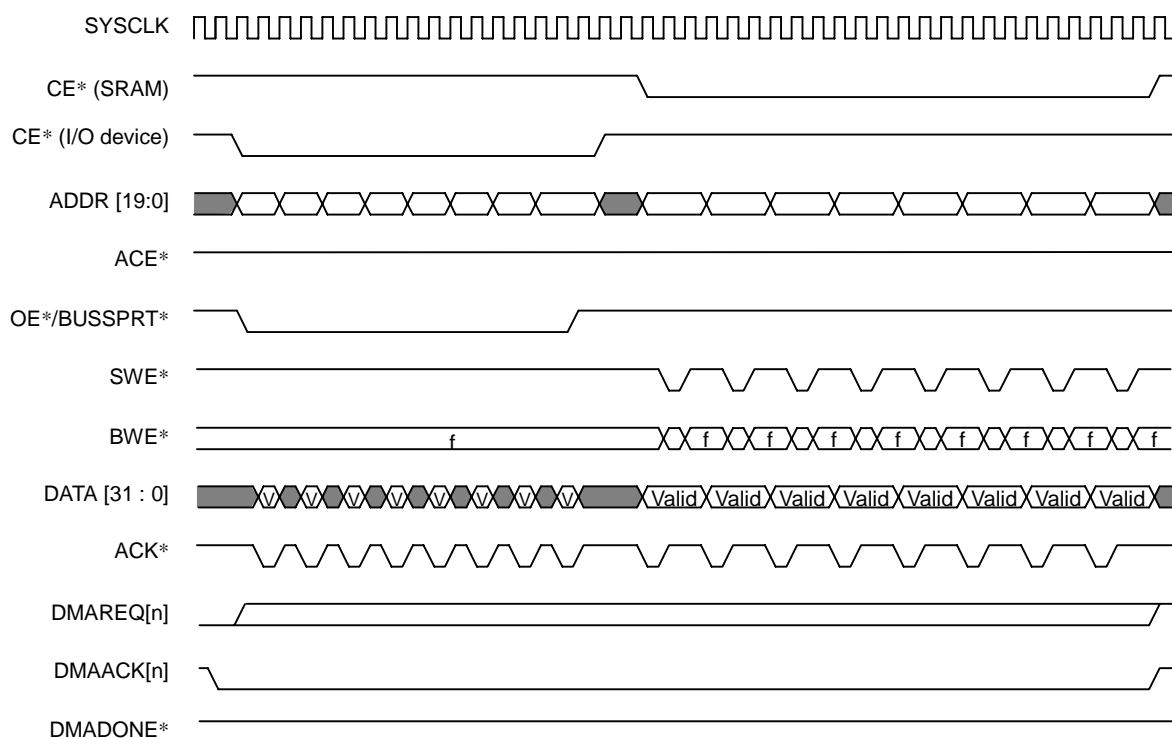


Figure 8.5.16 Dual Address Transfer from External I/O Device to SRAM
(8-word Burst Transfer to 32-bit Bus SRAM)

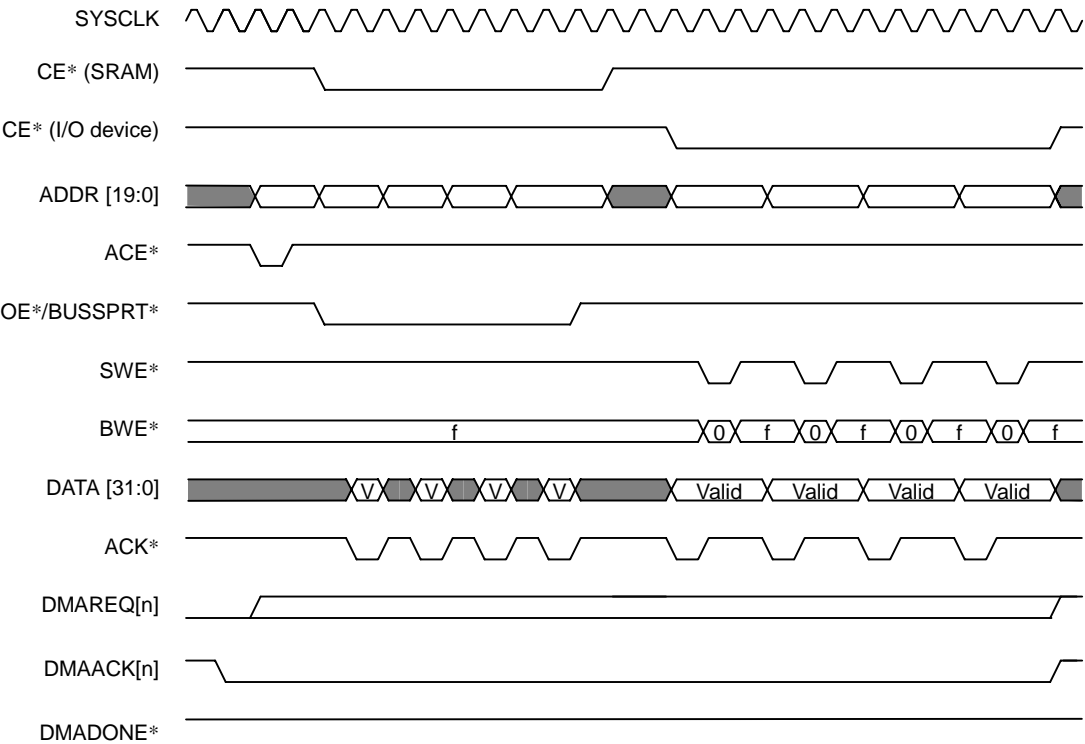


Figure 8.5.17 Dual Address Transfer from SRAM to External I/O Device
(4-word Burst Transfer from 32-bit Bus SRAM)

8.5.16 External I/O Device – SDRAM Dual Address Transfer

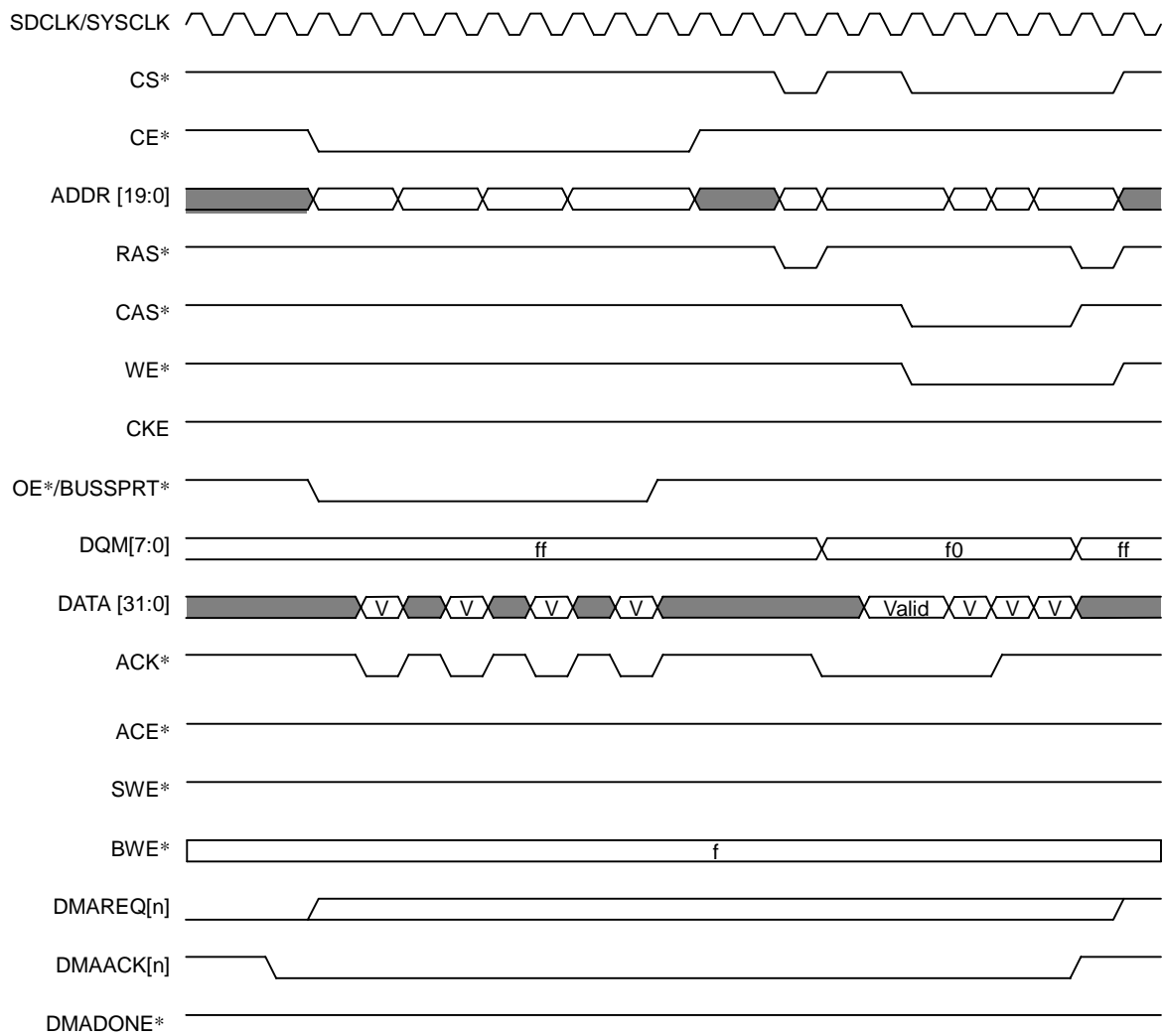


Figure 8.5.18 Dual Address Transfer from External I/O Device to SDRAM
(4-word Burst Transfer to 32-bit SDRAM)

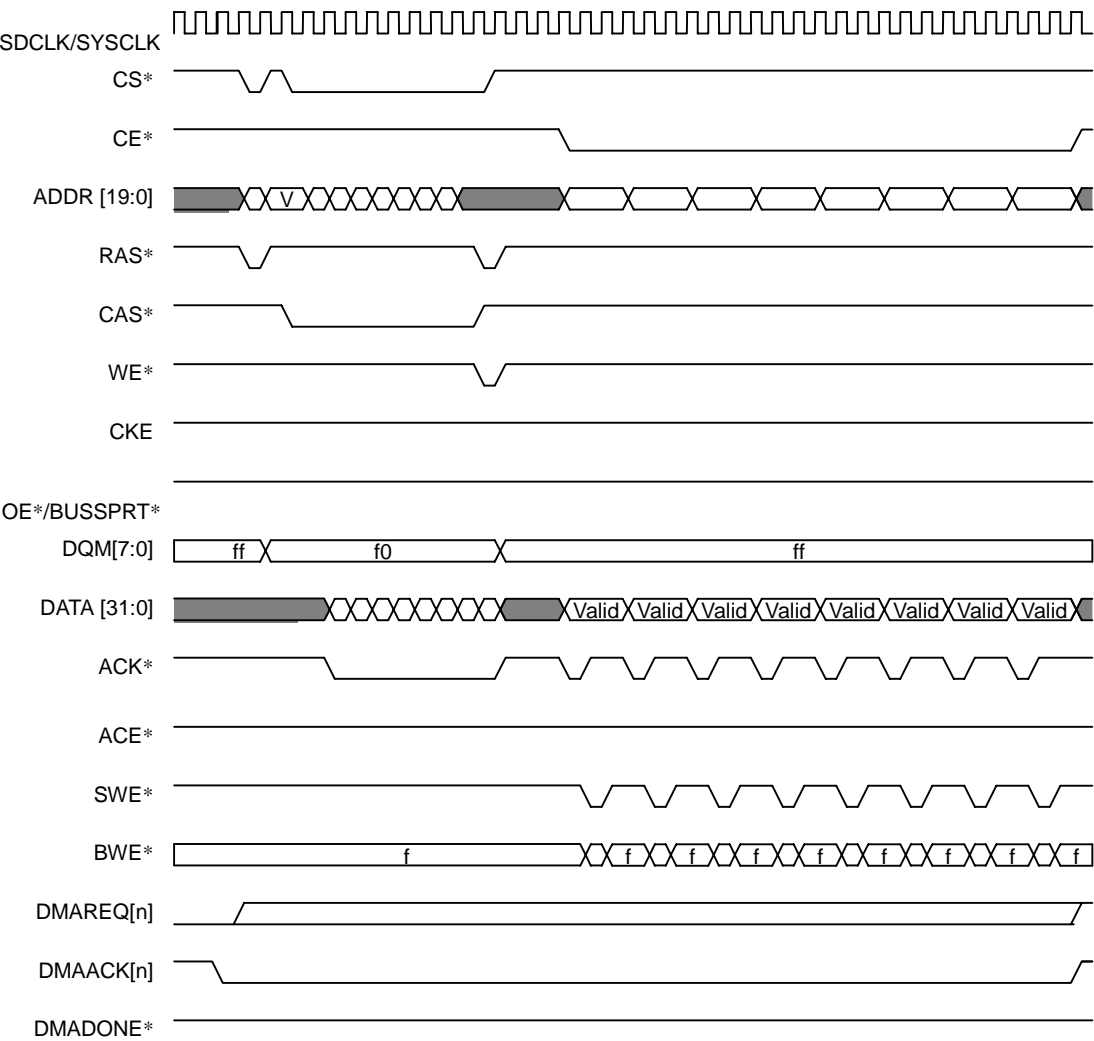


Figure 8.5.19 Dual Address Transfer from SDRAM to External I/O Device
(8-word Burst Transfer from 32-bit SDRAM)

8.5.17 External I/O Device (Non-burst) – SDRAM Dual Address Transfer

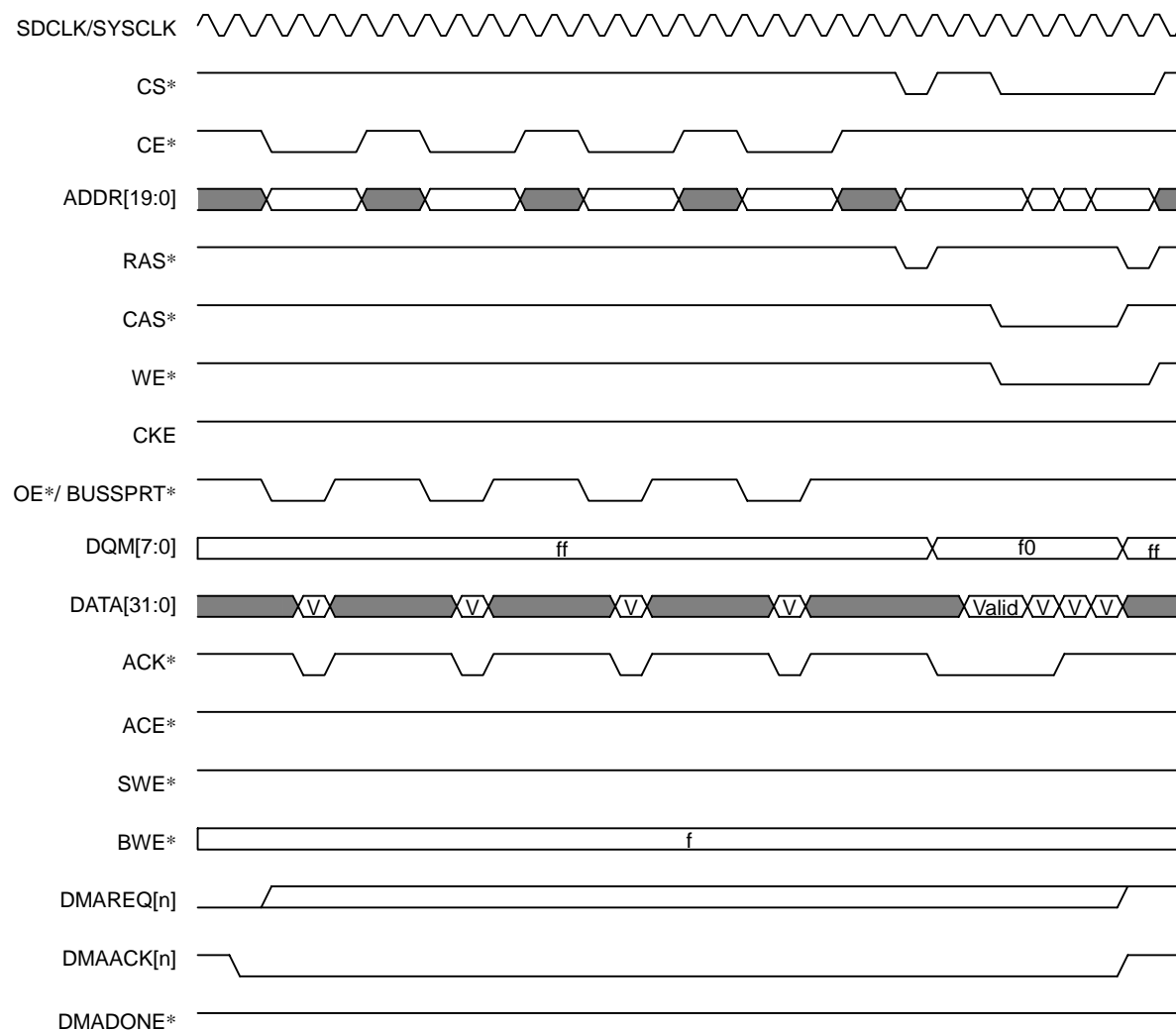


Figure 8.5.20 Dual Address Transfer from External I/O Device (Non-Burst) to SDRAM
(4-word Burst Transfer to 32-bit SDRAM: Set DMCCRn.SBINH to "1")

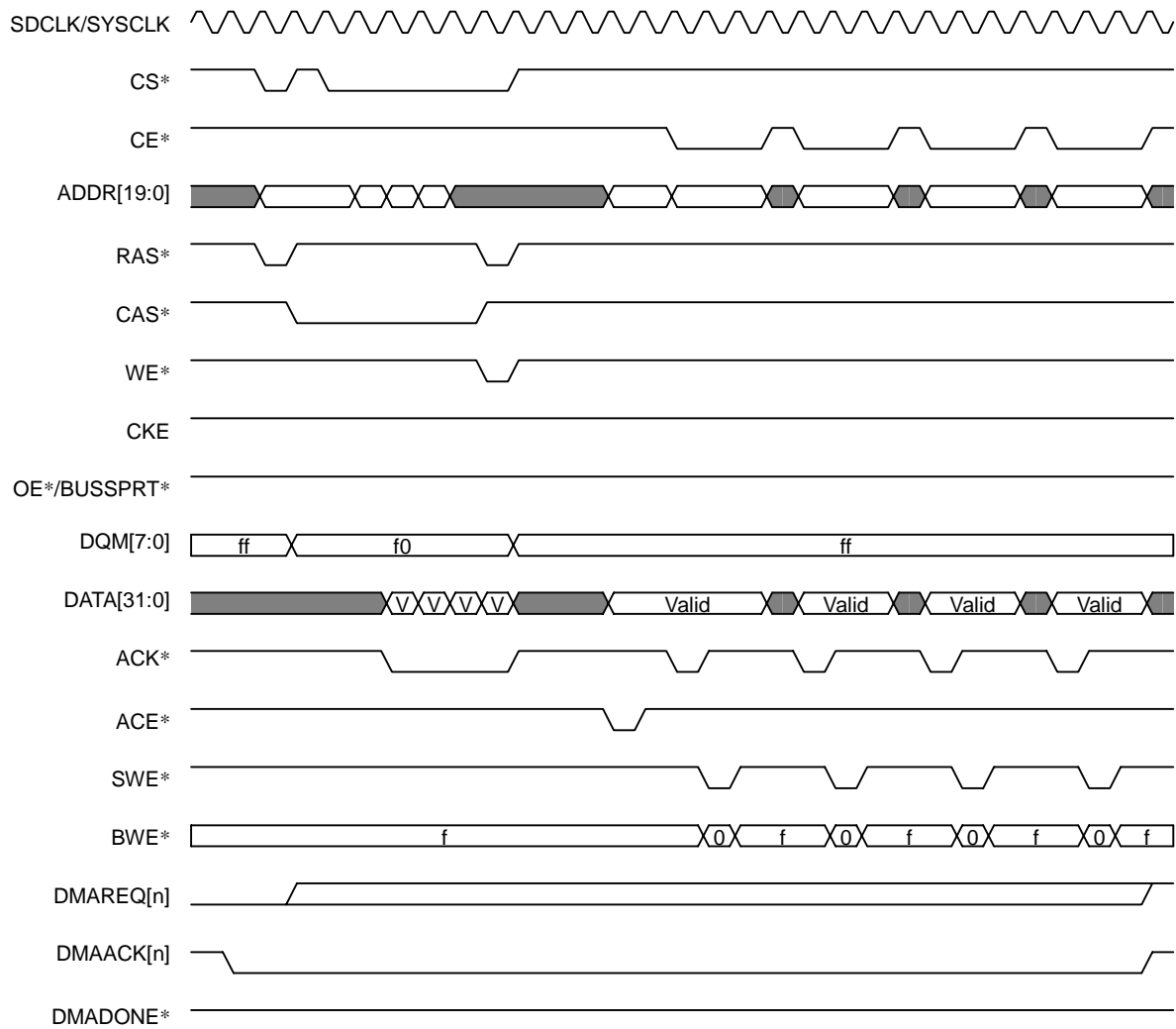


Figure 8.5.21 Dual Address Transfer from SDRAM to External I/O Device
(4-word Burst Transfer from 32-bit SDRAM: Set DMCCRn.DBINH to "1")

9. SDRAM Controller

9.1 Characteristics

The SDRAM Controller (SDRAMC) generates the control signals required to interface with the SDRAM. There are a total of four channels, which can each be operated independently. The SDRAM Controller supports various bus configurations and a memory size of up to 2 GB.

The SDRAM has the following characteristics.

- Clock frequency: 50 – 100 MHz
- Four independent memory channels
- Can use registered DIMM
- Selectable data bus width for each channel: 64-bit/32-bit
- Supports critical word first access of the TX49/H2 core
- Supports DMAC special Burst access (address decrement/fix)
- Programmable SDRAM timing latency
Can set timing to match the clock frequency used and the memory speed. Can realize a system with optimized memory performance.
- Can write to any byte during Single or Burst Write operation. This feature is controlled by the DQM signal.
- Can set the refresh cycle to be programmable.
- SDRAM refresh mode: both auto refresh and self refresh are possible.
- Low power consumption mode: can select between self refresh or pre-charge power down
- SDRAM Burst length: fixed to "2"
- SDRAM addressing mode: Fixed to the Sequential mode
- Supports systems with high fan-out
Supports two selectable data read-back buses and supports the Slow Write Burst Mode in order to handle data buses with large load. In order to maintain timing consistency during Read operation, it is possible to select whether to use the feedback clock to latch data or to by-pass this latch path. Two clock cycles are used for each Write operation when in the Slow Write Burst Mode.
- Can use the ECC or parity generation/check functions.
- Can select EC (Error Check only), ECC (Error Check and Correct), or ECC + Scrub (write correction data back to memory) when using the ECC function.
- Can select Odd parity/Even parity when using the Parity function.

9.2 Block Diagram

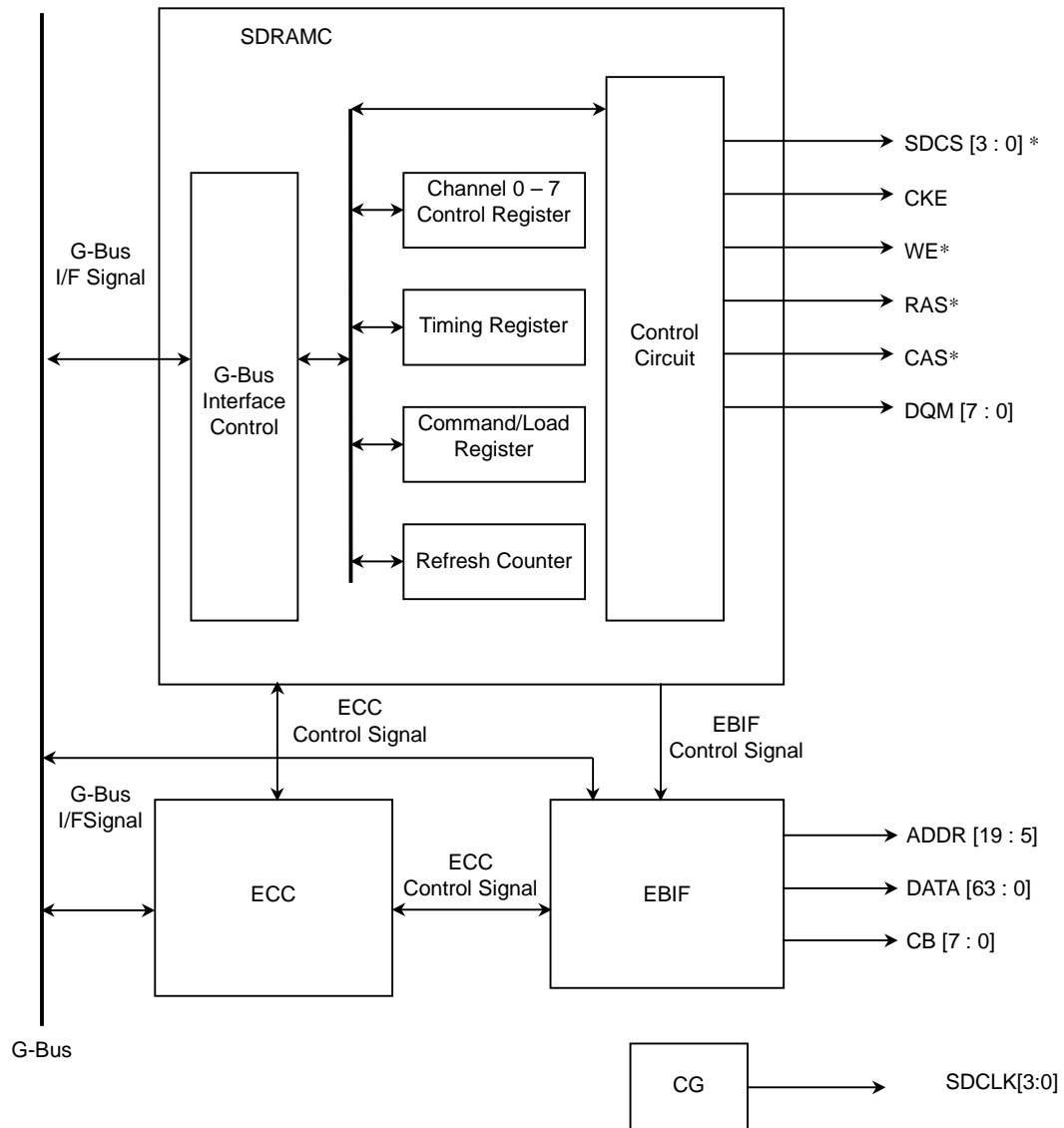


Figure 9.2.1 Block Diagram of SDRAMC

9.3 Detailed Explanation

9.3.1 Supported SDRAM configurations

This controller supports the SDRAM configurations listed below in Table 9.3.1.

The MW field of the SDRAM Channel Control Register (SDCCRN) can be used to separately set the data bus width for each channel to either 64 bits or 32 bits.

DATA[31:0] and DQM[3:0] are used when using a 32-bit data bus. DQM[7:4] output High. DATA[63:32] output an undefined value when DATA[31:0] become the output, but enter the High-Z state when DATA[31:0] are the input. When in the Big Endian Mode, first external access of the upper word (bits 63:32) of the internal data bus is performed, then external access of the lower word (bits 31:0) is performed. When in the Little Endian Mode, first external access of the lower word (bits 31:0) is performed, then external access of the upper word (bits 63:32) is performed. When using a 32-bit data bus, two external access will always be performed even when accessing less than 32 bits of data.

The maximum memory capacity per channel when a 64-bit data bus is configured is 512 MBytes when using 16 256-Mbit SDRAMs with a 4-bit data bus. The total maximum memory capacity is 2 GBytes when totaling up the four channels.

Table 9.3.1 Supported SDRAM Configurations

SDRAM Configuration			Row Address (bit)	Column Address (bit)	Remarks
16 Mbit	2-bank	1 M × 16	11	8	
		2 M × 8	11	9	
		4 M × 4	11	10	See Note
64 Mbit	2-bank	2 M × 32	11	9	
		2 M × 32	12	8	
		4 M × 16	11	10	
		4 M × 16	13	8	
		8 M × 8	13	9	
		16 M × 4	13	10	See Note
	4-bank	2 M × 32	11	8	
		4 M × 16	12	8	
		8 M × 8	12	9	
		16 M × 4	12	10	See Note
128 Mbit	4-bank	4 M × 32	12	8	
		8 M × 16	12	9	
		16 M × 8	12	10	
		32 M × 4	12	11	See Note
256 Mbit	4-bank	16 M × 16	13	9	
		32 M × 8	13	10	
		64 M × 4	13	11	See Note

Note1: The SDRAM Controller logic-wise does support these configurations, but please design carefully since the memory bus load will be large.

Note2: This SDRAM configuration has 512 Mbytes of memory on a channel. If it is mapped to physical address space beginning with address 0, it overlaps the address space for the ROM wherein the bootstrap vectors reside.

9.3.2 Address Mapping

9.3.2.1 Physical Address Mapping

It is possible to map each of the four channels to an arbitrary physical address using the Base Address field (SDCCRn.BA[35:21]) of the SDRAM Channel Control Register and the Address Mask Field (SDCCRn.AM[35:21]).

The channel that becomes True in the following equation is selected.

$$\text{paddr}[35:21] \& \text{!AM}[35:21] = \text{BA}[35:21] \& \text{!AM}[35:21]$$

In the above equation, "paddr" represents the accessed physical address, "&" represents the AND of each bit, and "!" represents the logical NOT of each bit.

Operation is undefined when multiple channels are simultaneously selected, or when external bus controllers or PCI controllers are simultaneously selected.

9.3.2.2 Address Signal Mapping (64-bit Data Bus)

Table 9.3.2 shows the address signal mapping when using a 64-bit data bus. B0 is used in the bank selection in memory with a two-bank configuration. [B1:B0] are used in the bank selection in memory with a four-bank configuration. Bits with the description "L/H" output High when performing auto-precharging, or output Low when not performing auto-precharging.

Table 9.3.2 Address Signal Mapping (64-bit Data Bus) (1/2)

Row address width = 11 Column address width = 8															
Address bit ADDR [19:5]	19 (B0)	18 (B1)	17	16	15 (AP)	14	13	12	11	10	9	8	7	6	5
Column Address	22	23	21	20	L/H	L/H	L/H	10	9	8	7	6	5	4	3
Row Address	22	23	21	20	21	20	19	18	17	16	15	14	13	12	11

Row Address Width = 11 Column Address Width = 9															
Address Bit ADDR [19:5]	19 (B0)	18 (B1)	17	16	15 (AP)	14	13	12	11	10	9	8	7	6	5
Column Address	23	23	23	23	L/H	23	22	10	9	8	7	6	5	4	3
Row Address	23	23	23	23	21	20	19	18	17	16	15	14	13	12	11

Row Address Width = 11 Column Address Width = 10															
Address Bit ADDR [19:5]	19 (B0)	18 (B1)	17	16	15 (AP)	14	13	12	11	10	9	8	7	6	5
Column Address	24	23	23	24	L/H	23	22	10	9	8	7	6	5	4	3
Row Address	24	23	23	24	21	20	19	18	17	16	15	14	13	12	11

Row Address Width = 12 Column Address Width = 8															
Address Bit ADDR [19:5]	19 (B0)	18 (B1)	17	16	15 (AP)	14	13	12	11	10	9	8	7	6	5
Column Address	23	24	23	22	L/H	24	23	10	9	8	7	6	5	4	3
Row Address	23	24	23	22	21	20	19	18	17	16	15	14	13	12	11

Row Address Width = 12 Column Address Width = 9															
Address Bit ADDR [19:5]	19 (B0)	18 (B1)	17	16	15 (AP)	14	13	12	11	10	9	8	7	6	5
Column Address	24	25	24	22	L/H	24	23	10	9	8	7	6	5	4	3
Row Address	24	25	24	22	21	20	19	18	17	16	15	14	13	12	11

Table 9.3.2 Address Signal Mapping (64-bit Data Bus) (2/2)

Row Address Width = 12 Column Address Width = 10															
Address Bit ADDR [19:5]	19 (B0)	18 (B1)	17	16	15 (AP)	14	13	12	11	10	9	8	7	6	5
Column Address	25	26	25	22	L/H	24	23	10	9	8	7	6	5	4	3
Row Address	25	26	25	22	21	20	19	18	17	16	15	14	13	12	11

Row Address Width = 12 Column Address Width = 11															
Address Bit ADDR [19:5]	19 (B0)	18 (B1)	17	16	15 (AP)	14	13	12	11	10	9	8	7	6	5
Column Address	26	27	26	25	L/H	24	23	10	9	8	7	6	5	4	3
Row Address	26	27	26	22	21	20	19	18	17	16	15	14	13	12	11

Row Address Width = 13 Column Address Width = 8															
Address Bit ADDR [19:5]	19 (B0)	18 (B1)	17	16	15 (AP)	14	13	12	11	10	9	8	7	6	5
Column Address	24	25	23	22	L/H	25	24	10	9	8	7	6	5	4	3
Row Address	24	25	23	22	21	20	19	18	17	16	15	14	13	12	11

Row Address = 13 Column Address Width = 9															
Address Bit ADDR [19:5]	19 (B0)	18 (B1)	17	16	15 (AP)	14	13	12	11	10	9	8	7	6	5
Column Address	25	26	23	22	L/H	25	24	10	9	8	7	6	5	4	3
Row Address	25	26	23	22	21	20	19	18	17	16	15	14	13	12	11

Row Address Width = 13 Column Address Width = 10															
Address Bit ADDR [19:5]	19 (B0)	18 (B1)	17	16	15 (AP)	14	13	12	11	10	9	8	7	6	5
Column Address	26	27	23	22	L/H	25	24	10	9	8	7	6	5	4	3
Row Address	26	27	23	22	21	20	19	18	17	16	15	14	13	12	11

Row Address Width = 13 Column Address Width = 11															
Address Bit ADDR [19:5]	19 (B0)	18 (B1)	17	16	15 (AP)	14	13	12	11	10	9	8	7	6	5
Column Address	27	28	23	26	L/H	25	24	10	9	8	7	6	5	4	3
Row Address	27	28	23	22	21	20	19	18	17	16	15	14	13	12	11

9.3.2.3 Address Signal Mapping (32-bit Data Bus)

Table 9.3.3 shows the address signal mapping when using a 32-bit data bus. B0 is used in the bank selection in memory with a two-bank configuration. [B1:B0] are used in the bank selection in memory with a four-bank configuration. Bits with the description "L/H" output High when performing auto-precharging, or output Low when not performing auto-precharging.

Table 9.3.3 Address Signal Mapping (32-bit Data Bus) (1/2)

Row Address Width = 11 Column Address Width = 8															
Address Bit ADDR [19:5]	19 (B0)	18 (B1)	17	16	15 (AP)	14	13	12	11	10	9	8	7	6	5
Column Address	21	22	20	19	L/H	L/H	L/H	9	8	7	6	5	4	3	2
Row Address	21	22	20	19	20	19	18	17	16	15	14	13	12	11	10

Row Address Width = 11 Column Address Width = 9															
Address Bit ADDR [19:5]	19 (B0)	18 (B1)	17	16	15 (AP)	14	13	12	11	10	9	8	7	6	5
Column Address	22	22	22	22	L/H	22	21	9	8	7	6	5	4	3	2
Row Address	22	22	22	22	20	19	18	17	16	15	14	13	12	11	10

Row Address Width = 11 Column Address Width = 10															
Address Bit ADDR [19:5]	19 (B0)	18 (B1)	17	16	15 (AP)	14	13	12	11	10	9	8	7	6	5
Column Address	23	22	22	23	L/H	22	21	9	8	7	6	5	4	3	2
Row Address	23	22	22	23	20	19	18	17	16	15	14	13	12	11	10

Row Address Width = 12 Column Address Width = 8															
Address Bit ADDR [19:5]	19 (B0)	18 (B1)	17	16	15 (AP)	14	13	12	11	10	9	8	7	6	5
Column Address	22	23	22	21	L/H	23	22	9	8	7	6	5	4	3	2
Row Address	22	23	22	21	20	19	18	17	16	15	14	13	12	11	10

Row Address Width = 12 Column Address Width = 9															
Address Bit ADDR [19:5]	19 (B0)	18 (B1)	17	16	15 (AP)	14	13	12	11	10	9	8	7	6	5
Column Address	23	24	23	21	L/H	23	22	9	8	7	6	5	4	3	2
Row Address	23	24	23	21	20	19	18	17	16	15	14	13	12	11	10

Table 9.3.3 Address Signal Mapping (32-bit Data Bus) (2/2)

Row Address Width = 12 Column Address Width = 10															
Address Bit ADDR [19:5]	19 (B0)	18 (B1)	17	16	15 (AP)	14	13	12	11	10	9	8	7	6	5
Column Address	24	25	24	21	L/H	23	22	9	8	7	6	5	4	3	2
Row Address	24	25	24	21	20	19	18	17	16	15	14	13	12	11	10

Row Address Width = 12 Column Address Width = 11															
Address Bit ADDR [19:5]	19 (B0)	18 (B1)	17	16	15 (AP)	14	13	12	11	10	9	8	7	6	5
Column Address	25	26	25	24	L/H	23	22	9	8	7	6	5	4	3	2
Row Address	25	26	25	21	20	19	18	17	16	15	14	13	12	11	10

Row Address Width = 13 Column Address Width = 8															
Address Bit ADDR [19:5]	19 (B0)	18 (B1)	17	16	15 (AP)	14	13	12	11	10	9	8	7	6	5
Column Address	23	24	22	21	L/H	24	23	9	8	7	6	5	4	3	2
Row Address	23	24	22	21	20	19	18	17	16	15	14	13	12	11	10

Row Address Width = 13 Column Address Width = 9															
Address Bit ADDR [19:5]	19 (B0)	18 (B1)	17	16	15 (AP)	14	13	12	11	10	9	8	7	6	5
Column Address	24	25	22	21	L/H	24	23	9	8	7	6	5	4	3	2
Row Address	24	25	22	21	20	19	18	17	16	15	14	13	12	11	10

Row Address Width = 13 Column Address Width = 10															
Address Bit ADDR [19:5]	19 (B0)	18 (B1)	17	16	15 (AP)	14	13	12	11	10	9	8	7	6	5
Column Address	25	26	22	21	L/H	24	23	9	8	7	6	5	4	3	2
Row Address	25	26	22	21	20	19	18	17	16	15	14	13	12	11	10

Row Address Width = 13 Column Address Width = 11															
Address Bit ADDR [19:5]	19 (B0)	18 (B1)	17	16	15 (AP)	14	13	12	11	10	9	8	7	6	5
Column Address	26	27	22	25	L/H	24	23	9	8	7	6	5	4	3	2
Row Address	26	27	22	21	20	19	18	17	16	15	14	13	12	11	10

9.3.3 Initialization of SDRAM

The TX4927 Command Register has functions for generating the cycles required for initializing SDRAM. Using software to set each register makes it possible to execute initial settings at a particular timing.

- 1 Set the SDRAM Channel Control Register (SDCCRN).
- 2 Set the SDRAM Timing Register (SDCTR). This timing setting is applied to all channels, so please set it to the slowest memory device.
- 3 Use the SDRAM Command Register (SDCCMD) to issue the Pre-charge All command.
- 4 Issue the Set Mode Register command in the same manner.
- 5 Set the refresh count required to initialize SDRAM to the refresh counter (SDCTR.RC)¹ and set the refresh cycle (SDCTR.RP).^{2 3}
- 6 Wait until the refresh counter returns to “0.”
- 7 Set the refresh cycle (SDCTR.RP) to the proper value.

¹ The number of refresh operations can be counted using the refresh counter. With this function, it is no longer necessary to assemble special timing groups in the software when counting refresh operations.

² Setting the refresh cycle to a small value makes it possible to expedite completion of the refresh cycle required for SDRAM initialization. As described above, please set normal values after the required number of refresh cycles have been generated.

³ Refresh requests have priority over all other SDRAM Controller access requests. Please do not set the memory refresh cycle to an unnecessarily short value.

9.3.4 Initialization of Memory Data, ECC/Parity

The SDRAMC has functions for simultaneously performing Memory Writes to multiple memory channels. These functions are effective when quickly initializing data memory or ECC/parity memory.

Channels for which both the Channel Enable bit (SDCCRN.CE) and the Master Enable bit (SDCCRN.ME) of the SDRAM Channel Control Register are set become the Master channel. Also, channels for which both the Channel Enable bit (SDCCRN.CE) and the Slave Enable bit (SDCCRN.SE) are set become the Slave channel. See Table 9.3.4 Master/Slave Channel Settings for information regarding the Master/Slave channel settings.

The slave channel is simultaneously written to when the Master channel is written to. Settings of the Master channel are used when in the ECC/Parity mode. Please set to the same value the SDRAM settings of all channels that are simultaneously written to.

Using the DMA Controller and performing 32 double word Burst access is the most efficient way to access the Master channel. The DMAC has registers for setting memory initialization data. When the DMAC is launched by an internal request when in the Single address IO→Memory Transfer mode, the data set in this register are written to memory. See Chapter 8 "DMA Controller" for more information.

Table 9.3.4 Master/Slave Channel Settings

SDCCRN.CE (Channel Enable)	SDCCRN.ME (Master Enable)	SDCCRN.SE (Slave Enable)	Description
0	X	X	Channel is disabled.
1	0	0	Normal operation is performed.
1	0	1	When a Write operation is executed by a channel where SDCCRN.ME=1, the Write operation is also executed by this channel. Normal operation is performed when this channel is Active.
1	1	0	When a Write operation is executed by this channel, the Write operation is simultaneously executed by all channels where SDCCRN.SE=1.
1	1	1	When a Write operation is executed by this channel, the Write operation is simultaneously executed by all channels where SDCCRN.SE=1. A Write operation is also simultaneously executed by this channel when the Write operation is executed by another channel where SDCCRN.ME=1.

9.3.5 Low Power Consumption Function

9.3.5.1 Power Down Mode, Self-Refresh Mode

SDRAM has two low power consumption modes called the Power Down mode and the Self-Refresh mode. Memory data is lost in the case of the Power Down mode since Memory Refresh is not performed, but the amount of power consumed is reduced the most. Memory data is not lost in the case of the Self-Refresh mode.

SDRAM is set to the Power Down mode by using the SDRAM Command Register (SDCCMD) to issue the Power Down Mode command. Similarly, SDRAM is set to the Self-Refresh mode by issuing the Self-Refresh Mode command. The SDRAMC terminates internal refresh circuit operation after one of these commands has been issued. Issuing the Normal Mode command returns operation to normal.

When the Power Down Auto Entry bit (SDCTR.PDAE) of the SDRAM Timing Register is set, SDRAM is automatically set to the Power Down mode when memory access is not being performed. The SDRAMC internal refresh circuit will continue operating, so there will be no loss of memory data.

If either the Memory Access, Memory Refresh, or Memory command is executed while SDRAM is set to the Power Down mode or the Self-Refresh mode, then the Power Down mode and Self-Refresh mode will automatically terminate, and memory access will be performed.

After returning from a low power consumption mode that was set by either the Power Down Mode command or the Self-Refresh Mode command, the next memory access starts after 10 SDCLK cycles pass. This latency sufficiently follows the stipulated time from Power Down to first access of the SDRAM.

If setting the Power Down Auto Entry bit automatically causes memory access to be requested when set in the Power Down mode, then add 1 SDCLK cycle more of access latency than when not in the Power Down mode.

9.3.5.2 Advanced CKE

Advanced CKE is a function that speeds up the CKE assertion and deassertion timing by 1 clock cycle. This function is set using the Address CKE bit (SDCTR.ACE) of the SDRAM Timing Register.

Advanced CKE assumes that it will be used in a system where SDRAM data is saved even when the power to the TX4927 itself is cut. Since CKE On/Off becomes 1 cycle faster, it is possible to delay CKE by 1 clock cycle using external power consumption control logic. Please set the SDRAM to the Self-Refresh mode before using this function.

When combining advanced CKE functionality with Power Down Auto Entry functionality and memory access is requested while in the Power Down mode, two more SDCLK cycles of latency are added than would be the case when not in the Power Down mode.

9.3.6 Bus Errors

The SDRAMC detects bus errors in the following situations:

- Bus time-out occurs during Read or Write operation to the SDRAMC
- ECC 2-bit fault error or Parity error occurs during SDRAM Read operation

If a bus error occurs when accessing the SDRAMC, then the SDRAMC will immediately assert the current operation. Then, the current SDRAM cycle will end, remaining SDRAMC operations will be aborted, a Pre-charge All command will be issued to SDRAM, then the SDRAMC will return to the Idle state.

9.3.7 Memory Read and Memory Write

The RAS* signal, CAS* signal, WE*, signal, and ADDR[19:5] signal are set up 1 cycle before the SDCS* signal is asserted in the case of the Read command, Write command, Pre-charge command, or Mode Register Set command. The same set up time is observed even for active commands if the Active Command Ready bit (SDCTR.DA) of the SDRAM Timing Register is set. Figure 9.5.1 is a timing diagram of Single Read operation when the SDCTR.DA bit is cleared. Figure 9.5.2 is a timing diagram of Single Read operation when the SDCTR.DA bit is set.

Burst or Single Read operation is terminated by the Pre-charge Active Bank command. Burst or Single Write operation is terminated by the Auto Pre-charge Command.

9.3.8 Slow Write Burst

When the Slow Write Burst bit (SDCTR.SWB) of the SDRAM Timing Register is cleared, the data changes at each cycle during Burst Write operation (Figure 9.5.6). When the Slow Write Burst bit is set, the data will change every other cycle (Figure 9.5.7).

When the Slow Write Burst bit is set, all Write accesses will operate as $t_{\text{RCD}} = 3t_{\text{CK}}$ regardless of the setting of the RAS-CAS Delay bit (SDCTR.RCD) of the SDRAM Timing Register. The RAS-CAS Delay bit setting becomes valid when Slow Write Burst access is invalid. The setting of the Slow Burst bit does not have any effect on Read access.

9.3.9 Clock Feedback

When performing Read access at fast rates like 100 MHz, there may be insufficient set up time if an attempt to directly latch Read data with the internal clock is made. With the TX4927, it is possible to latch data using SDRAM clock SDCLKIN that is input from outside the chip. Please connect SDCLKIN to one of the SDCLK[3:0] pins and the external source.

9.3.10 ECC

9.3.10.1 ECC/Parity Mode

Table 9.3.5 shows the supported ECC/Parity functions. The ECC/Parity mode can be set separately for each channel using the ECC/Parity Mode field (SDCCRN.ECC) of the SDRAM Channel Control Register. The ECC enable bit (ECCCR.ECCE) of the ECC Control Register must be set in order to use the ECC function. No error detection, logging, or notification will be performed if this bit is not set.

Table 9.3.5 ECC/Parity Mode

ECC Field	Mode Name	Description
0x0	NOP Mode	Disables the ECC/Parity function.
0x1	EC Mode	EC (Error Check) enable Read: Performs only error checking. Correction is not performed. Write: Generates check code.
0x2	ECC Mode	ECC (Error Check and Correct) enable Read: Performs error checking and correction. Write: Generates check code.
0x3	ECC + Scrub Mode	ECC + scrub enable Read: Performs error checking and correction. Corrected data is written back to memory if an error occurs. Write: Generates check code.
0x4	Even Parity Mode	Even parity enable Read: Performs error checking. Write: Generates even parity.
0x5	Odd Parity Mode	Odd parity enable Read: Performs error checking. Write: Generates odd parity.
0x6	—	Reserved
0x7	—	Reserved

- The ECC/Parity Mode changes dynamically according to each channel setting.
- Error checking is performed when writing data smaller than 64 bits when Memory Read access is being performed while in the EC Mode, ECC Mode, or ECC + scrub mode.
- Data correction is performed if the read data cause a single-bit error when in the ECC Mode or the ECC + scrub mode. Data is read unchanged when in any other mode regardless of whether or not an error occurs.

9.3.10.2 ECC Error Notification

When either an ECC error or a parity error occurs, error data is written into one of the following fields, then error notification is performed as described below:

- Error Address Field (ERRAD) in the ECC Status Register (ECCSR)
- Error ECC/Parity Mode Field (ERRMODE)
- Error Memory Width Field (ERRMW)
- Error Syndrome Field (ERRS)

The Multi-bit Error bit (ECCSR.MBERR) of the ECC Status Register is set and an interrupt is generated if either an ECC multi-bit error or parity error is detected during any Read/Write access while the Multi-bit Error Interrupt Enable bit (ECCCR.MEI) is set.

The Single-bit Error bit (ECCSR.SBERR) of the ECC Status Register is set and an interrupt is generated if an ECC single-bit error is detected during any Read/Write access while the Single-bit Error Interrupt Enable bit (ECCCR.SEI) is set.

Multi-bit errors are assigned a higher priority than single-bit errors. If a multi-bit error is detected while the Single-bit Error bit (ECCSR.SBERR) is set, then the Single-bit Error bit (ECCSR.SBERR) is cleared, error data is written for the multi-bit error, then error notification is performed. If a single-bit error is detected while the Multi-bit Error bit (ECCSR.MBERR) is set, the Single-bit Error bit (ECCSR.SBERR) is not set and not error data is written. However, the single-bit error is corrected according to the usual procedure.

The following error notification will also be performed if either an ECC multi-bit error or parity error is detected while the Multi-bit Error Bus Error Enable Bit (ECCCR.MEB) of the ECC Control Register is set.

During read access by the TX49 core, bus error notification is sent to the TX49 core and an exception is generated. A nonmaskable interrupt is generated during Read-Modify-Write memory Read access that is performed when writing from the TX49 core data that is smaller than 64 bits. Bus error notification is sent to the appropriate bus master during Read/Write access from another bus master.

9.3.10.3 Adding Read Latency for Each ECC/Parity Mode

When using the ECC/parity function, memory access latency is added according to which ECC/parity mode is selected, whether errors will be generated or not, the error type to be generated, and whether or not to generate bus errors. Table 9.3.6 shows in cycles the memory Read access latency that will be added based on NOP mode operation under each condition.

Table 9.3.6 Read Latency Added for Each ECC/Parity Mode

ECC/Parity Mode	Bus Error Notification (ECCCR.MEB)	Error Type/Operation	Added Read Latency (in cycles)
NOP Mode	—	—	0
EC Mode	Disable	No error	0
		SBErr: Do not correct MBErr: Correct	0
		No error	1
	Enable	SBErr: Do not correct MBErr: Do not correct	2
		No error	1
		SBErr: Correct MBErr: Do not correct	2
ECC Mode	Disable	No error	1
		SBErr: Correct MBErr: Do not correct	2
		No error	1
	Enable	SBErr: Correct MBErr: Do not correct	2
		No error	1
		SBErr: Correct & scrub MBErr: Do not correct	3
ECC + scrub Mode	Disable	No error	1
		SBErr: Correct & scrub MBErr: Do not correct	Max. 22
		No error	1
	Enable	SBErr: Correct & scrub MBErr: Do not correct	Max. 22
		No error	1
		SBErr: Correct & scrub MBErr: Do not correct	2
Even Parity Mode Odd Parity Mode	Disable	No error	0
		MBErr: Do not correct	0
		No error	1
	Enable	MBErr: Do not correct	1
		No error	1
		MBErr: Do not correct	1

SBErr = Single-bit error

MBErr = Multi-bit error

9.3.10.4 ECC Memory Access

8-bit check code is used whether the data bus width is 64 bits or 32 bits. For 32-bit data bus width, check code is generated for and the error check is performed on 64-bit data that consists of two 32-bit data at the double word boundary.

CB[7:0] are used for check code reading and writing when in the 64-bit mode. CB[3:0] are used for check code reading and writing when in the 32-bit mode. An 8-bit check code is used for 64-bit data. Similar to the data however, accesses to the memory are divided into half with 4 bits being accessed at a time. The upper 4 bits of the check code are accessed simultaneous to when the upper 32 bits of the data are written or read. Similarly, the lower 4 bits of the check code are accessed simultaneous to when the lower 32 bits of the data are written or read.

All 64-bit data are always read and checked when set in the EC mode, ECC mode, or ECC + Scrub mode. Consequently, data at the double word boundary, including this data, is read and checked even when accessing data smaller than a double word (word access, byte access, etc.).

Read-Modify-Write (RMW) is performed during a Write operation of less than a double word. First, 64 bits of data that include the address where the writing is performed is read. Then, check code is generated for new 64-bit data that has replaced the written data.

Single-bit errors are corrected, but multi-bit errors are not. Therefore, if multi-bit errors are detected, no data are written back to memory.

If data is being transferred between external I/O and memory during a DMAC single address transfer, check code will not be generated even if the ECC function has been enabled.

9.3.10.5 Diagnostic Mode

Setting the Diagnostic Mode bit (ECCCR.DM) of the ECC Control Register makes it possible to use the Diagnostic Mode. When in this mode and writing to a channel for which the ECC function is enabled, the code that is set in the Diagnostic ECC field (ECCCR.DECC) is written in place of the code that was calculated from the Write data.

9.4 Registers

Table 9.4.1 SDRAM Control Register

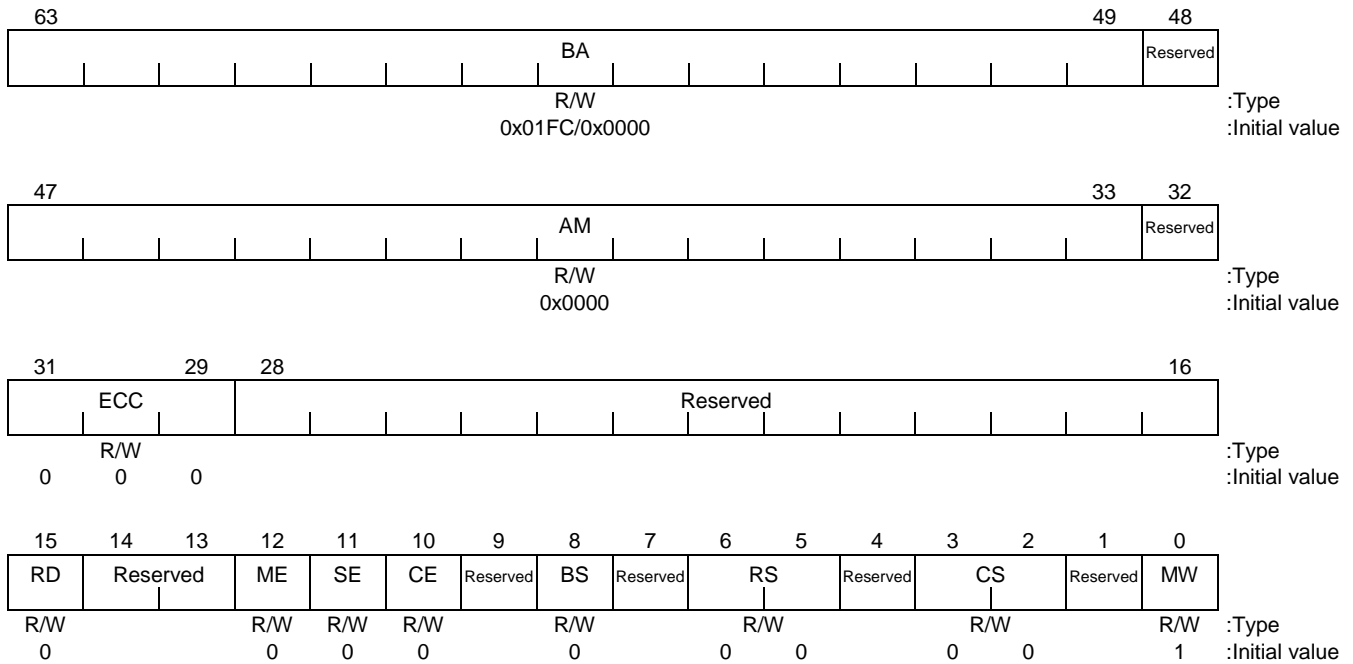
Offset Address		Bit Width	Register Symbol	Register Name
Big Endian	Little Endian			
0x8000		64	SDCCR0	SDRAM Channel Control Register 0
0x8008		64	SDCCR1	SDRAM Channel Control Register 1
0x8010		64	SDCCR2	SDRAM Channel Control Register 2
0x8018		64	SDCCR3	SDRAM Channel Control Register 3
0x8040		64	SDCTR	SDRAM Timing Register
0x8058		64	SDCCMD	SDRAM Command Register

Table 9.4.2 ECC Control Register

Offset Address		Bit Width	Register Symbol	Register Name
Big Endian	Little Endian			
0xA000		64	ECCCR	ECC Control Register
0xA008		64	ECCSR	ECC Status Register

9.4.1 SDRAM Channel Control Register (SDCCRN) 0x8000 (ch. 0) 0x8008 (ch. 1) 0x8010 (ch. 2) 0x8018 (ch. 3)

When the SDCCRN is programmed using a sequence of 32-bit store instructions, the base address and the address mask in the high-order 32-bit portion of the register must be written first, followed by the Channel Enable bit in the low-order 32-bit portion.



Bit	Mnemonic	Field Name	Description	Read/Write
63:49	BA[35:21]	Base Address	Base Address (Default: 0x01FC/0x0000) Specifies the base address. The upper 15 bits [35:21] of the physical address are compared to the value of this field. (Note) Only the default for Channel 0 differs. Channel 0: 0x01FC, Others: 0x0000	R/W
48	—	—	Reserved	—
47:33	AM[35:21]	Address Mask	Address Mask (Default: 0x0000) Sets the valid bits for address comparison according to the base address. 0: Bits of the corresponding BA field are compared. 1: Bits of the corresponding BA field are not compared.	R/W
32	—	—	Reserved	—
31:29	ECC	ECC/Parity Mode	ECC/Parity mode (Default: 000) Specifies the channel ECC/Parity type (refer to 9.3.10.1). 000: NOP Mode 001: EC Mode 010: ECC Mode 011: ECC + scrub Mode 100: Even Parity Mode 101: Odd Parity Mode 110: Reserved 111: Reserved	R/W
28:16	—	—	Reserved	—

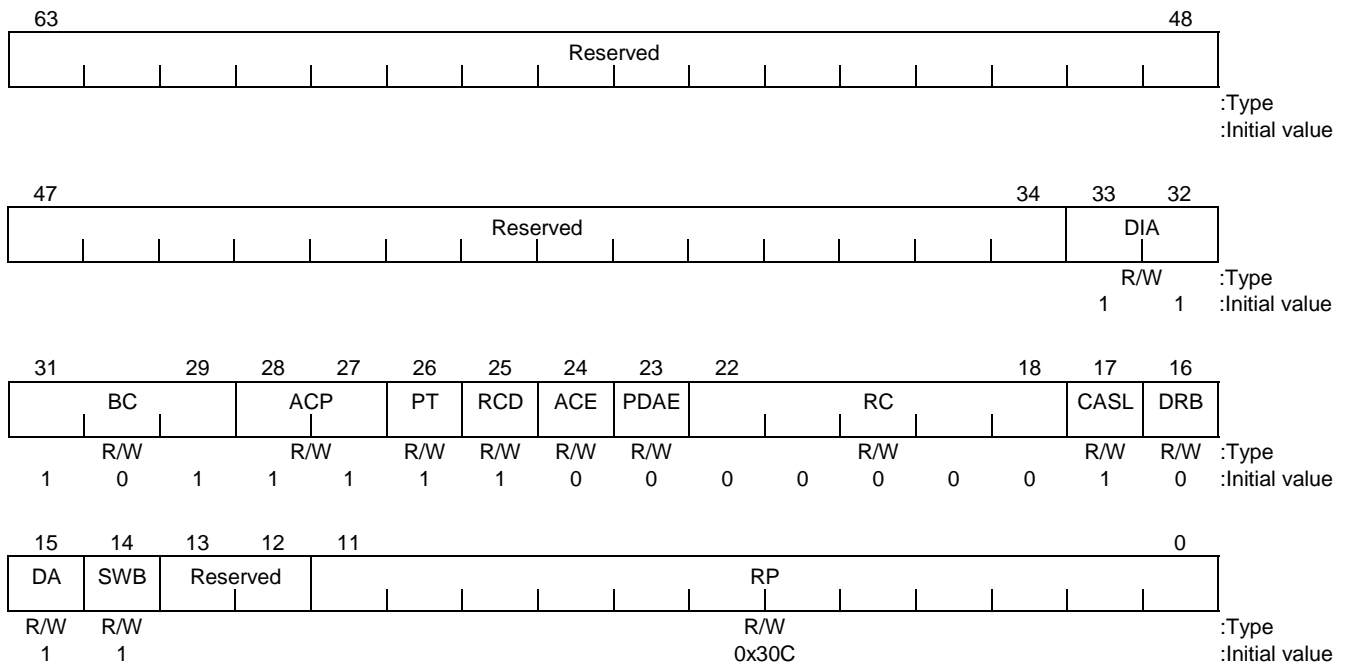
Figure 9.4.1 SDRAM Channel Control Register (1/2)

Bit	Mnemonic	Field Name	Description	Read/Write
15	RD	Registered DIMM	Registered DIMM (Default: 0) Specifies whether the SDRAM connected to the channel is Registered memory. 0: Disable Registered memory 1: Enable Registered memory	R/W
14:13	—	—	Reserved	—
12	ME	Master Enable	Master Enable (Default: 0) Specifies during ECC initialization whether a channel will be made the Master channel. 0: Disable 1: Enable	R/W
11	SE	Slave Enable	Slave Enable (Default: 0) Specifies during ECC initialization whether a channel will be made the Slave channel. 0: Disable 1: Enable	R/W
10	CE	Channel Enable	Enable (Default: 0) Specifies whether to enable a channel. 0: Disable 1: Enable	R/W
9	—	—	Reserved	—
8	BS	Bank Count	Number of Banks (Default: 0) Specifies the bank count. 0: 2 banks 1: 4 banks	R/W
7	—	—	Reserved	—
6:5	RS	Row Size	Row Size (Default: 00) Specifies the row size. 00: 2048 Rows (11 bits) 01: 4096 Rows (12 bits) 0: 8192 Rows (13 bits) 11: Reserved	R/W
4	—	—	Reserved	—
3:2	CS	Column Size	Column Size (Default: 00) Specifies the column size. 00: 256 words (8 bits) 01: 512 words (9 bits) 10: 1024 words (10 bits) 11: 2048 words (11 bits)	R/W
1	—	—	Reserved	—
0	MW	Memory Width	Memory Width (Default: 0) Specifies the bus width. 0: 64 bits 1: 32 bits	R/W

Figure 9.4.1 SDRAM Channel Control Register (2/2)

9.4.2 SDRAM Timing Register (SDCTR)

0x8040



Bit	Mnemonic	Field Name	Description	Read/Write
63:34	—	—	Reserved	—
33:32	DIA	Write Active Period	Data In to Active (t_{DAL}) (Default: 11) Specifies the period from the last Write data to the Active command. 00: Reserved 01: 4 t_{CK} 10: 5 t_{CK} 11: 6 t_{CK}	R/W
31:29	BC	Bank Cycle Time	Bank Cycle Time (t_{RC}) (Default: 101) Specifies the bank cycle time. ² 000: 5 t_{CK} 100: 9 t_{CK} 001: 6 t_{CK} 101: 10 t_{CK} 010: 7 t_{CK} 110: Reserved 011: 8 t_{CK} 111: Reserved	R/W
28:27	ACP	Active Command Time	Active Command Period (t_{RAS}) (Default: 11) Specifies the active command time. 00: 3 t_{CK} 01: 4 t_{CK} 10: 5 t_{CK} 11: 6 t_{CK}	R/W
26	PT	Precharge Time	Precharge Time (t_{RP}) (Default: 1) Specifies the precharge time. 0: 2 t_{CK} 1: 3 t_{CK}	R/W
25	RCD	RAS-CAS Delay	RAS to CAS Delay (t_{RCD}) (Default: 1) Specifies the RAS - CAS delay. 0: 2 t_{CK} 1: 3 t_{CK}	R/W

Figure 9.4.2 SDRAM Timing Register (1/2)

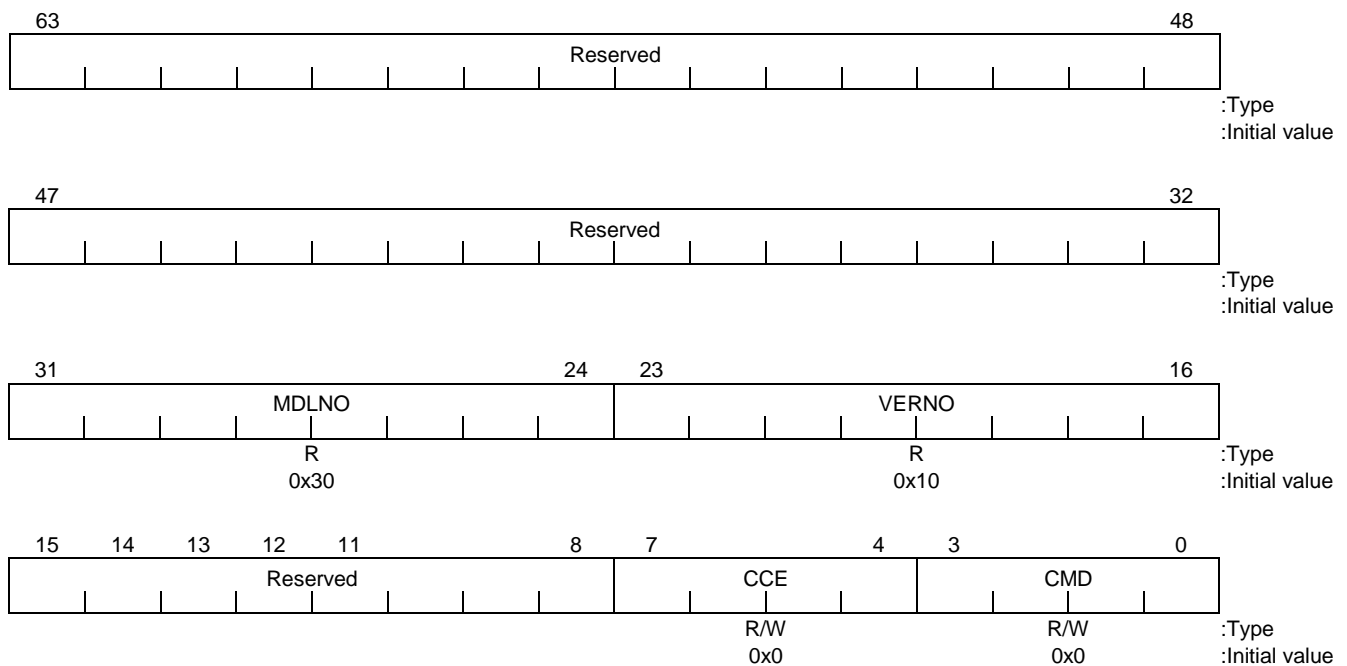
¹ t_{CK} = Clock cycle² t_{RC} is used during (i) refresh cycle time, (ii) single Read, (iii) two transfer burst Reads. The bank cycle time is $t_{RAS} + t_{RP} + 1t_{CK}$ if $t_{RAS} + t_{RP} < t_{RC}$ in the case of (ii) (iii).

Bit	Mnemonic	Field Name	Description	Read/Write
24	ACE	Advanced CKE	Advanced CKE enable (Default: 0) Enabling this function makes the timing at which CKE changes one cycle earlier. 0: Disable 1: Enable	R/W
23	PDAE	Power Down Auto Entry	Power Down Auto Entry Enable (Default: 0) Enabling this function makes CKE become "L" while the SDRAMC is in the Idle state. When refresh, memory access, or command execution is performed, CKE automatically becomes "H", the requested operation is performed, then CKE returns to "L" when the operation is complete. 0: Disable 1: Enable	R/W
22:18	RC	Refresh Counter	Refresh Counter (Default: 000000) This counter is decremented at each refresh. If the refresh circuit is activated and a value other than "0" is loaded, this field becomes a down counter that stops at "0". A value other than "0" must be reloaded to start the countdown again. This is used during memory initialization.	R/W
17	CASL	CAS Latency	CAS Latency (t_{CASL}) (Default: 1) Specifies the CAS latency. 0: 2 t_{CK} 1: 3 t_{CK}	R/W
16	DRB	Data Read Bypass	Data Read Bypass (Default: 0) Selects the Data Read path used. 0: Data Read latches to the register using the feedback clock. 1: Data Read bypasses the feedback clock latch.	R/W
15	DA	Active Command Delay	Delay Activate (t_{DA}) (Default: 1) Specifies the delay from the row address to the bank active command. Setting this bit to "1" sets up the row address two cycles before the active command is executed. 0: 0 t_{CK} 1: 1 t_{CK}	R/W
14	SWB	Slow Write Burst	Slow Write Burst (t_{SWB}) (Default: 0) Specifies whether to perform Slow Write Burst. 0: Burst Write occurs at each 1 t_{CK} 1: Burst Write occurs at each 2 t_{CK}	R/W
13:12	—	—	Reserved	—
11:0	RP	Refresh Period	Refresh Period (Default: 0x30c) Specifies the clock cycle count that generates the refresh cycle. Refresh is only enabled when at least one SDRAM channel is enabled. Please program the Timing Register before an arbitrary channel is enabled. Default is 0x30C. A refresh cycle occurs for each 7.8 μs @100 MHz in this situation.	R/W

Figure 9.4.2 SDRAM Timing Register (2/2)

9.4.3 SDRAM Command Register (SDCCMD)

0x8058

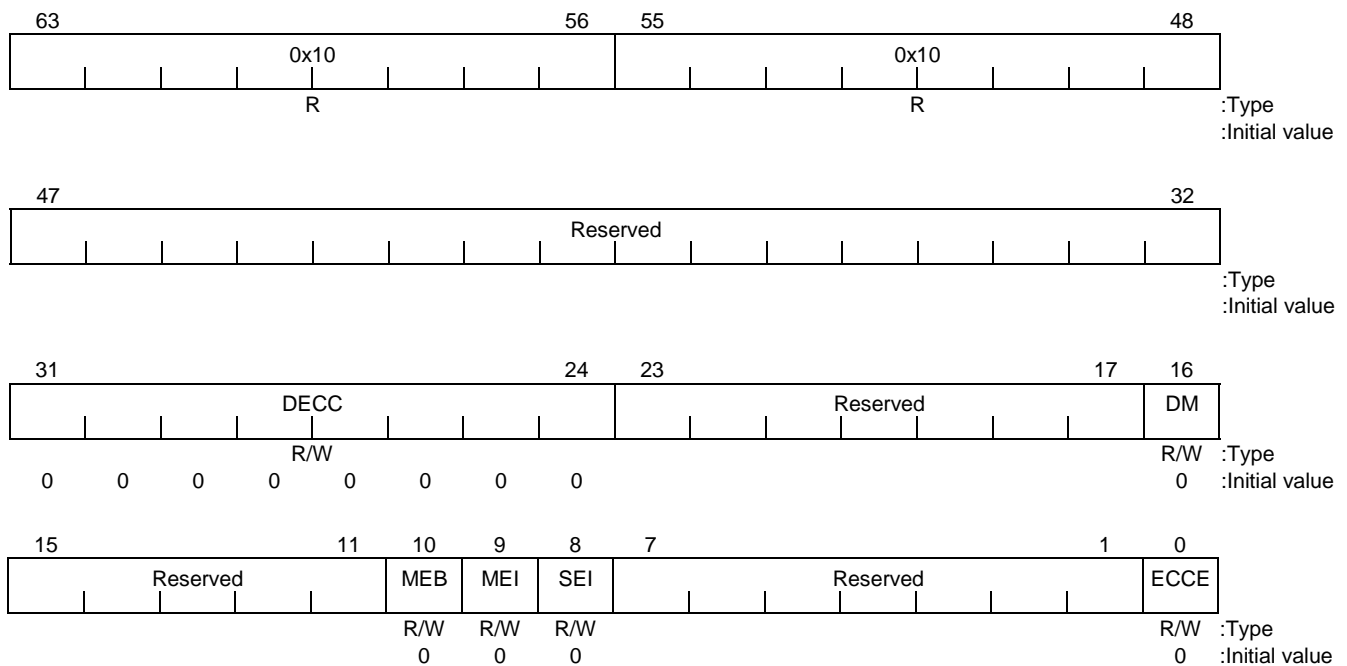


Bit	Mnemonic	Field Name	Description	Read/Write
63:32	—	—	Reserved	—
31:24	MDLNO	Model Number	Model Number (Default: 0x30) Indicates the model number. The default value is 0x30 for the TX4927. This field is Read Only.	R
23:16	VERNO	Version Number	Version Number (Default: 0x10) Indicates the version number. The default value is 0x10 for the TX4927. This field is Read Only.	R
15:8	—	—	Reserved	—
7:4	CCE	Command Channel Enable	Command Channel Enable Setting one of these bits to “1” enables the command of the corresponding channel. This command is simultaneously executed on all channels that are enabled. bit 7: Channel 3 bit 6: Channel 2 bit 5: Channel 1 bit 4: Channel 0	R/W
3:0	CMD	Command	Command Specifies a command that is performed on memory. 0x0: NOP command 0x1: Set Mode Register command Set SDRAM Mode Register from SDCTR value 0x2: Reserved 0x3: Precharge All command Precharge All SDRAM Banks 0x4: Self-Refresh Mode command Sets SDRAM to the Self-Refresh Mode 0x5: Power Down Mode Command Set SDRAM to the Power Down Mode 0x6: Normal Mode Command Cancel Self-Refresh/Power Down Mode 0x7-0xf: Reserved	R/W

Figure 9.4.3 SDRAM Command Register

9.4.4 ECC Control Register (ECCCR)

0xA000



Bit	Mnemonic	Field Name	Description	Read/Write
63:56	MDLNO	Model Number	Model Number (Default: 0x10) Indicates the model number. The default value for the TX4927 is 0x10. This field is Read Only.	R
55:48	VERNO	Version Number	Address Mask (Default: 0x10) Indicates the version number. The default value for the TX4927 is 0x10. This field is Read Only.	R
47:32	—	—	Reserved	—
31:24	DECC	Diagnostic ECC	Diagnostic ECC (Default: 0x00) The value set by this field is output from CB[7:0] as the check code when the ECCDM bit is set to "Enable."	R/W
23:17	—	—	Reserved	—
16	DM	Diagnostic Mode	ECC Diagnostic Mode (Default: 0) Specifies whether to use the Diagnostic Mode. 0: Disable 1: Enable	R/W
15:11	—	—	Reserved	—
10	MEB	Multi-Bit Error Bus Error Enable	Multi-Bit Error Bus Error Enable (Default: 0) Specifies whether to generate a bus error when a multi-bit error occurs. When this function is enabled, an NMI is generated for RMW* errors occurring during a Write operation to the TX49/H2 core. Bus errors are generated for all other operations. 0: Disable 1: Enable	R/W
9	MEI	Multi-Bit Error Interrupt Enable	Multi-Bit Error Interrupt Enable (Default: 0) Specifies whether to generate an interrupt during a multi-bit error. 0: Disable 1: Enable	R/W

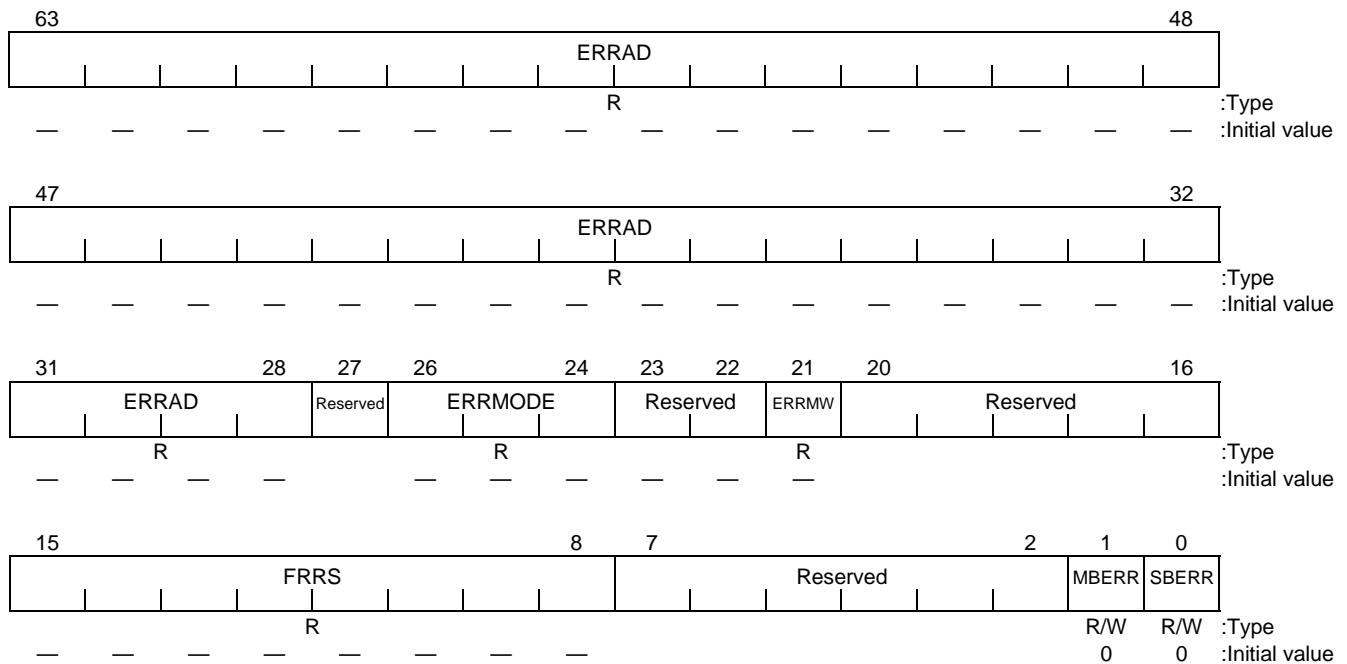
Figure 9.4.4 ECC Control Register (1/2)

Bit	Mnemonic	Field Name	Description	Read/Write
8	SEI	Single-Bit Error Interrupt Enable	Single-Bit Error Interrupt Enable (Default: 0) Specifies whether to generate an interrupt during a single-bit error. 0: Disable 1: Enable	R/W
7:1	—	—	Reserved	—
0	ECCE	ECC Enable	ECC Enable (Default: 0) Specifies whether to enable the ECC/Parity function. When disabled, the ECC function will not operate even if the ECC Parity Mode field (SDCCRN.ECC) selects the ECC/Parity Mode. 0: Disable 1: Enable	R/W

Figure 9.4.4 ECC Control Register (2/2)

9.4.5 ECC Status Register (ECCSR)


0xA008



Bit	Mnemonic	Field Name	Description	Read/Write
63:28	ERRAD	Error Address	Error Address (Default: Unknown) A 36-bit physical address is set when an error occurs. This address is retained until either SBERR or MBERR is cleared. This field is Read Only.	R
27	—	—	Reserved	—
26:24	ERRMODE	Error ECC/Parity Mode	Error ECC Mode (Default: Unknown) The ECC/Parity Mode is set when an error occurs. This address is retained until either SBERR or MBERR is cleared. This field is Read Only.	R
23:22	—	—	Reserved	—
21	ERRMW	Error Memory Width	Error Memory Width (Default: Unknown) The memory data width is set when an error occurs. This address is retained until either SBERR or MBERR is cleared. This field is Read Only. 0: 64 bits 1: 32 bits	R
20:16	—	—	Reserved	—
15:8	ERRS	Error Syndrome	Error Syndrome (Default: Unknown) The error syndrome for when errors occur is set. The syndrome is retained until either SBERR or MBERR is cleared. This field is Read Only.	R
7:2	—	—	Reserved	—
1	MBERR	Multi-Bit Error	Multi-Bit Error (Default: 0) This bit is set to “1” when a multi-bit error occurs, or when a parity error occurs while in the Parity Mode. Once a multi-bit error occurs, until this bit is cleared, no status in the Status Register is updated even if new multi-/single-bit errors occur. 0: No error 1: Generate error	R/W
0	SBERR	Single-Bit Error	Single-Bit Error (Default: 0) This bit is set to “1” when a single-bit error occurs. Once a single-bit error occurs, until this bit is cleared, no status in the Status Register is updated even if new single-bit error occurs. If a multi-bit error occurs, status is updated regardless of whether a single-bit error has occurred or not. 0: No error 1: Generate error	R/W

Figure 9.4.5 ECC Status Register

9.5 Timing Diagrams

Please note the following when referring to the timing diagrams in this section: the shaded area  in each diagram expresses values that have yet to be determined.

9.5.1 Single Read (64-bit Bus)

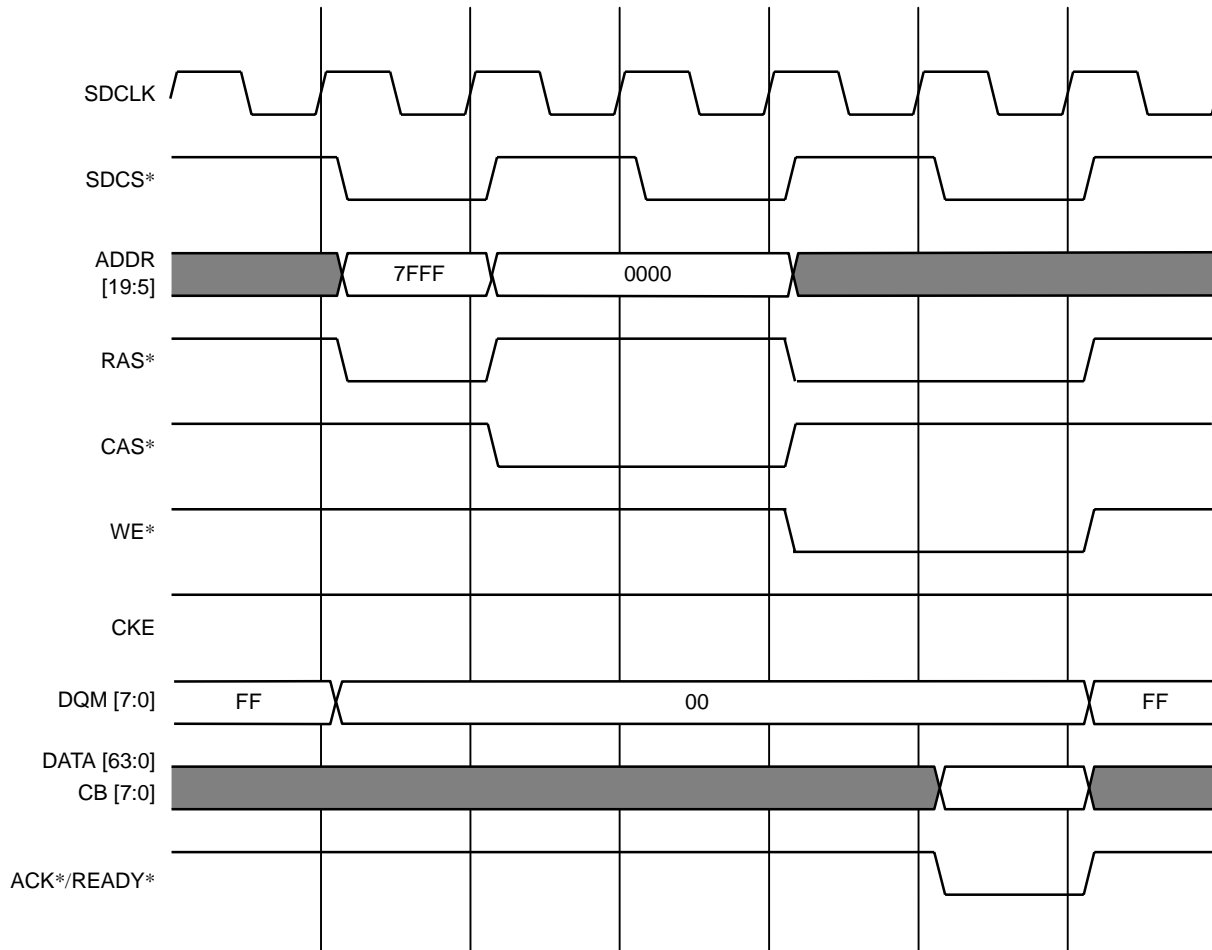


Figure 9.5.1 Single Read ($t_{RCD} = 2$, $t_{CASL} = 2$, $t_{DA} = 0$, 64-bit Bus)

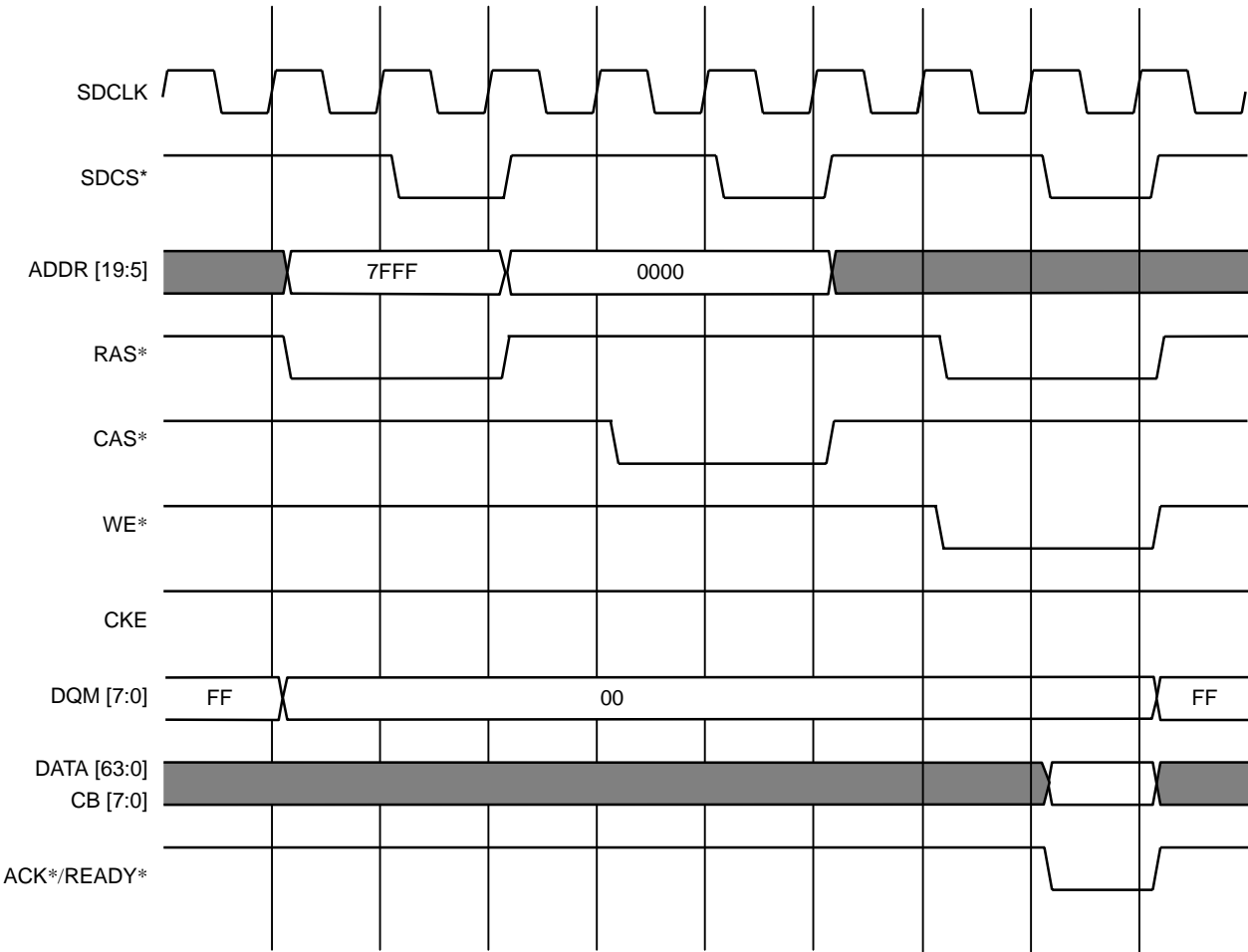


Figure 9.5.2 Single Read ($t_{RCD} = 3$, $t_{CASL} = 3$, $t_{DA} = 1$, 64-bit Bus)

9.5.2 Single Write (64-bit Bus)

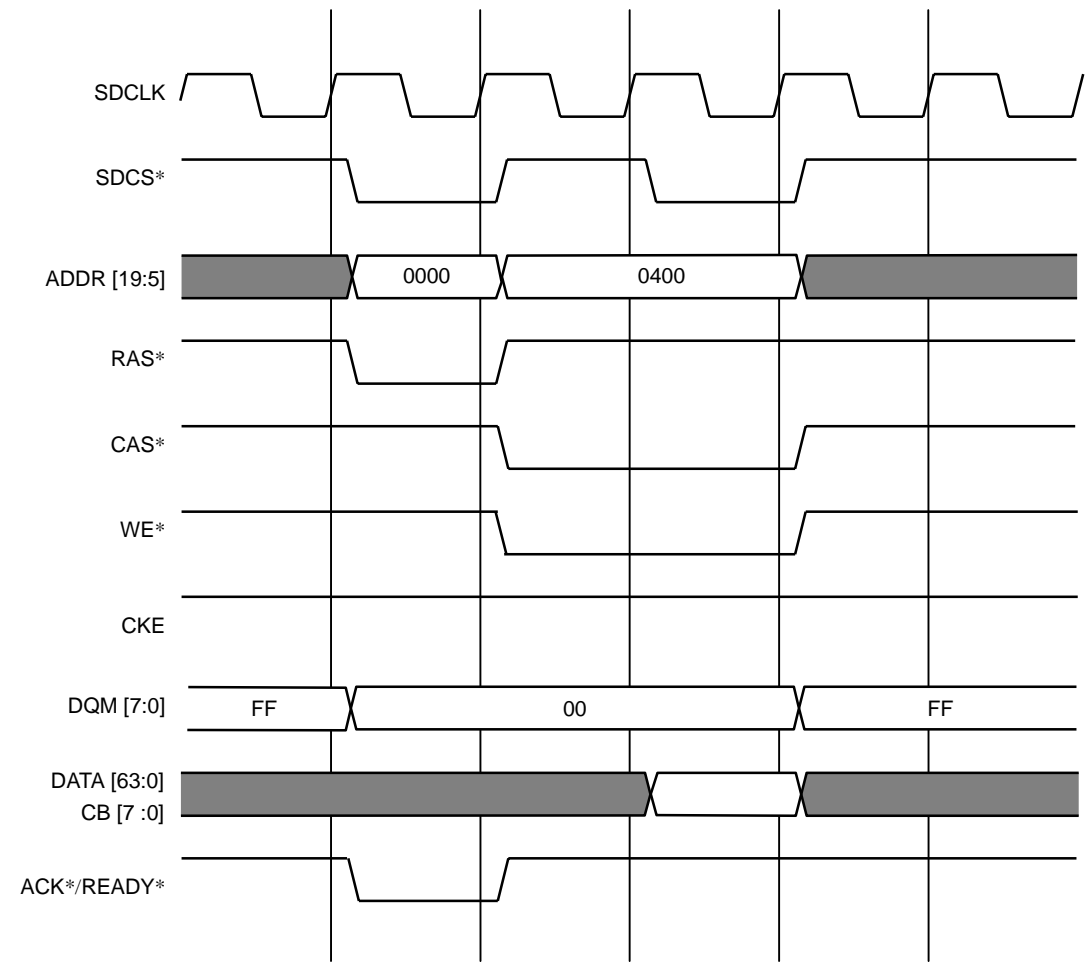


Figure 9.5.3 Double-Word Single Write ($t_{RCD} = 2$, $t_{DA} = 0$, 64-bit Bus)

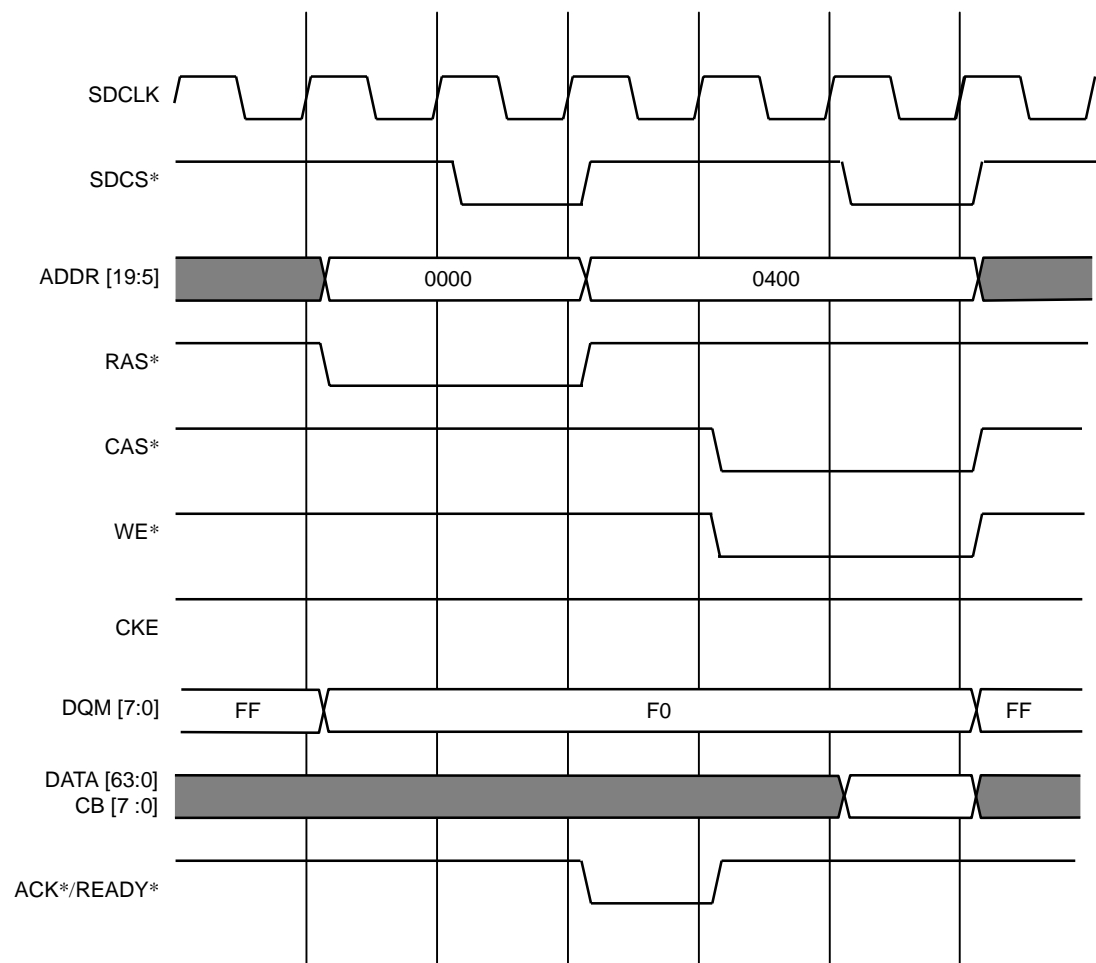


Figure 9.5.4 One-Word Single Write ($t_{RCD} = 3$, $t_{DA} = 1$, 64-bit Bus)

9.5.3 Burst Read (64-bit Bus)

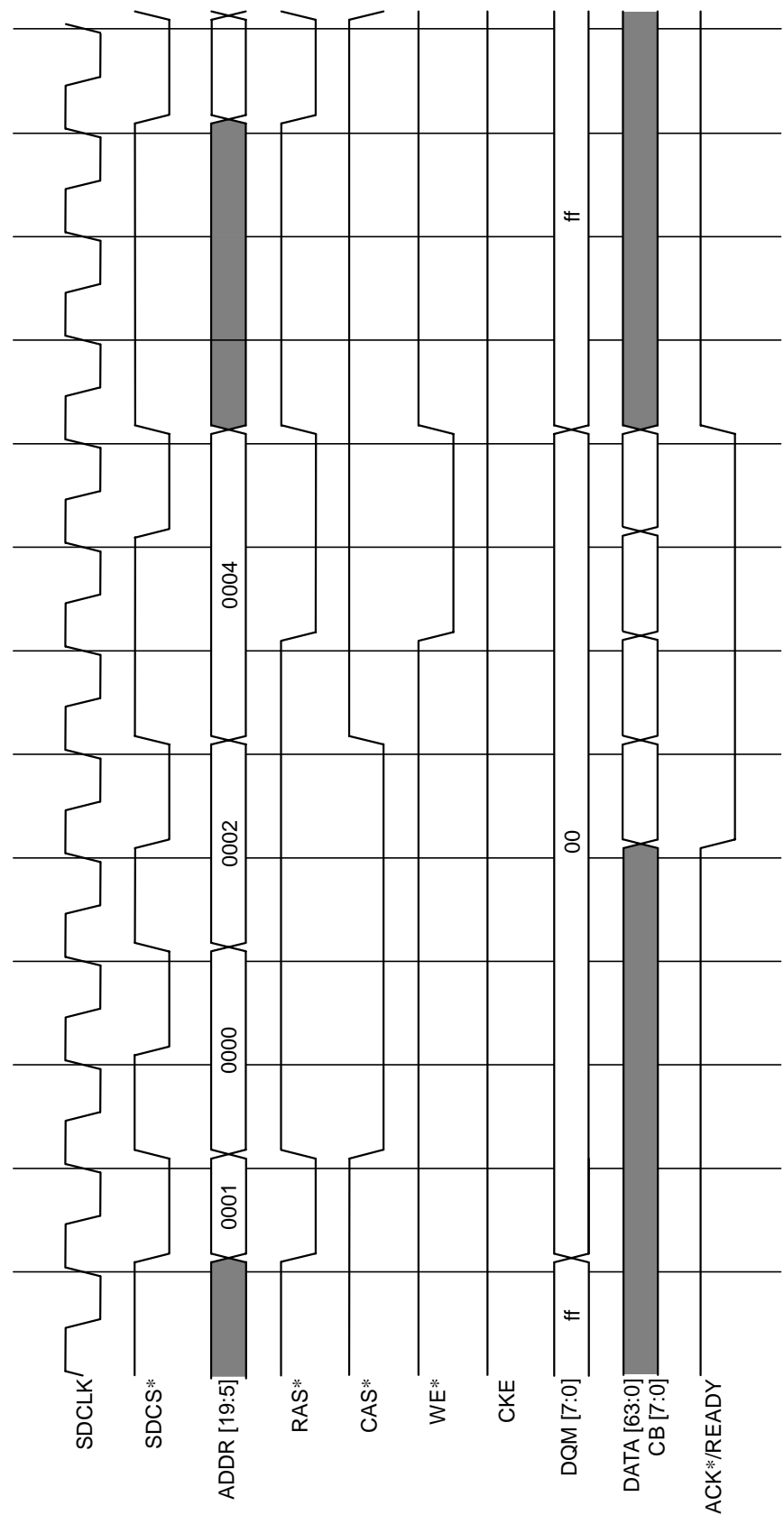


Figure 9.5.5 Eight-Word Burst Read ($t_{RCD} = 2$, $t_{CASL} = 2$, $t_{DA} = 0$, 64-bit Bus)

9.5.4 Burst Write (64-bit Bus)

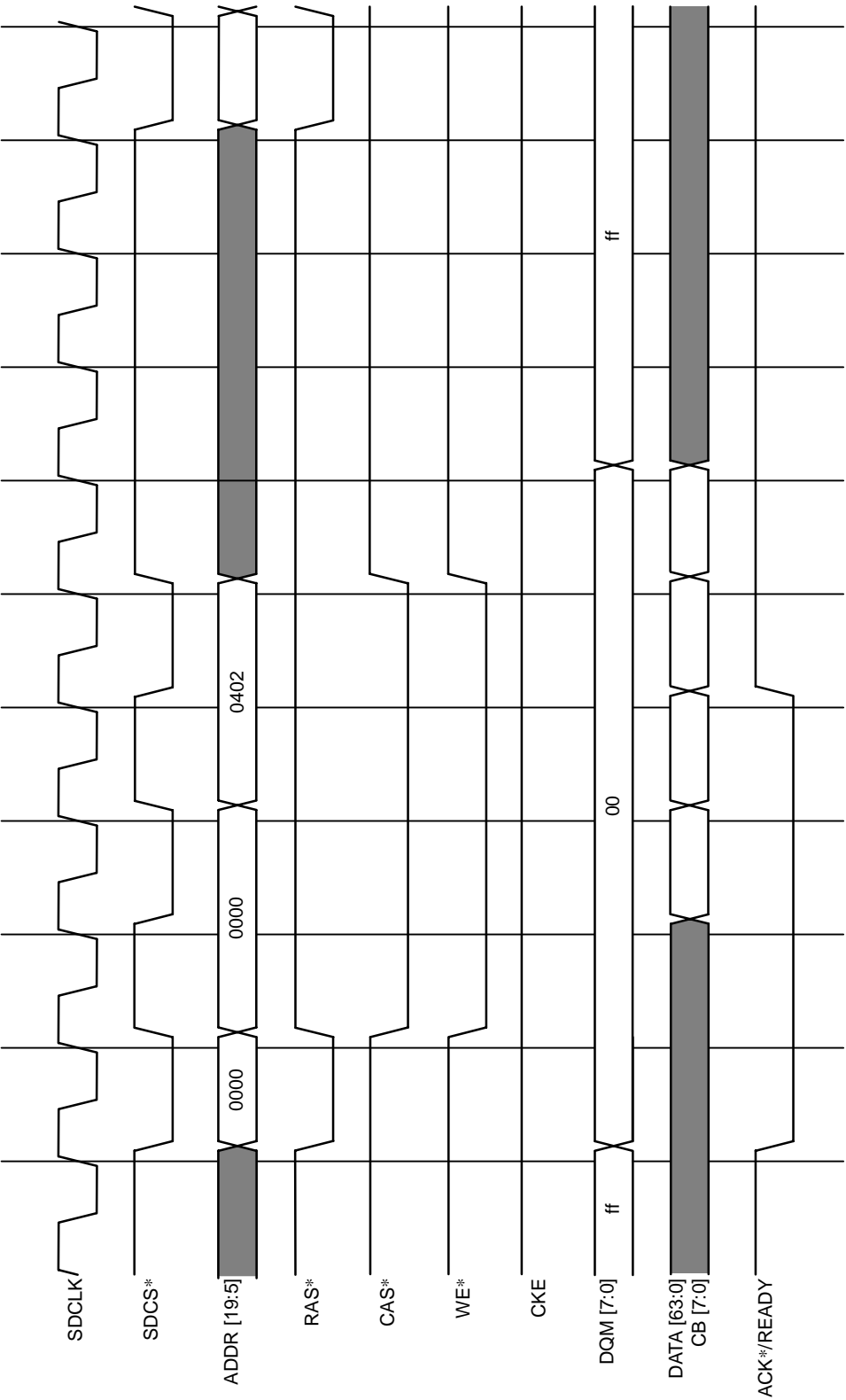


Figure 9.5.6 Eight-Word Burst Write ($t_{RCD} = 2$, $t_{DA} = 0$, 64-bit Bus)

9.5.5 Burst Write (64-bit Bus, Slow Write Burst)

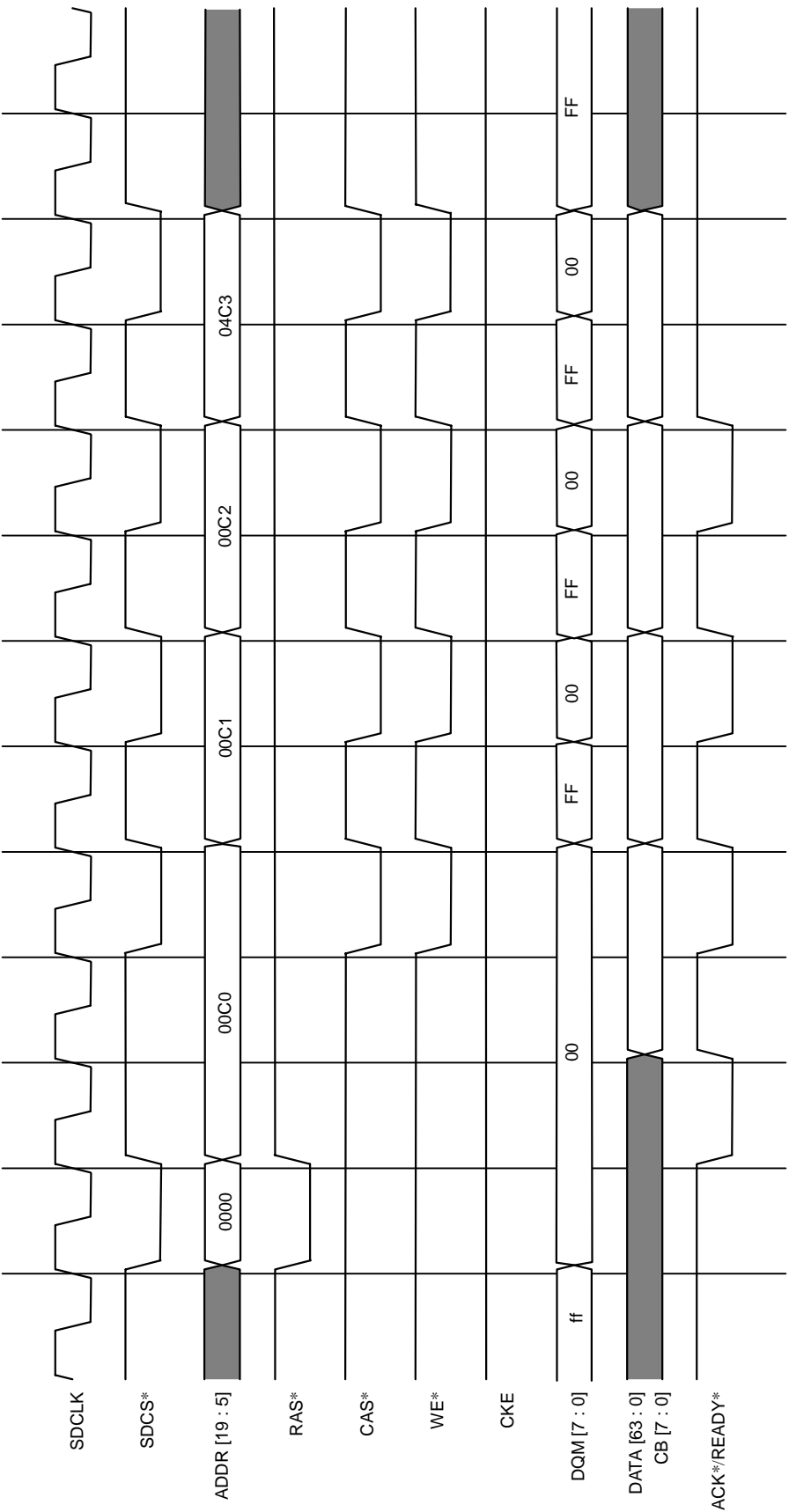


Figure 9.5.7 Eight-Word Burst Write ($t_{RCD} = 2$, $t_{DA} = 0$, 64-bit Bus, Slow Write Burst)

9.5.6 Single Read (32-bit Bus)

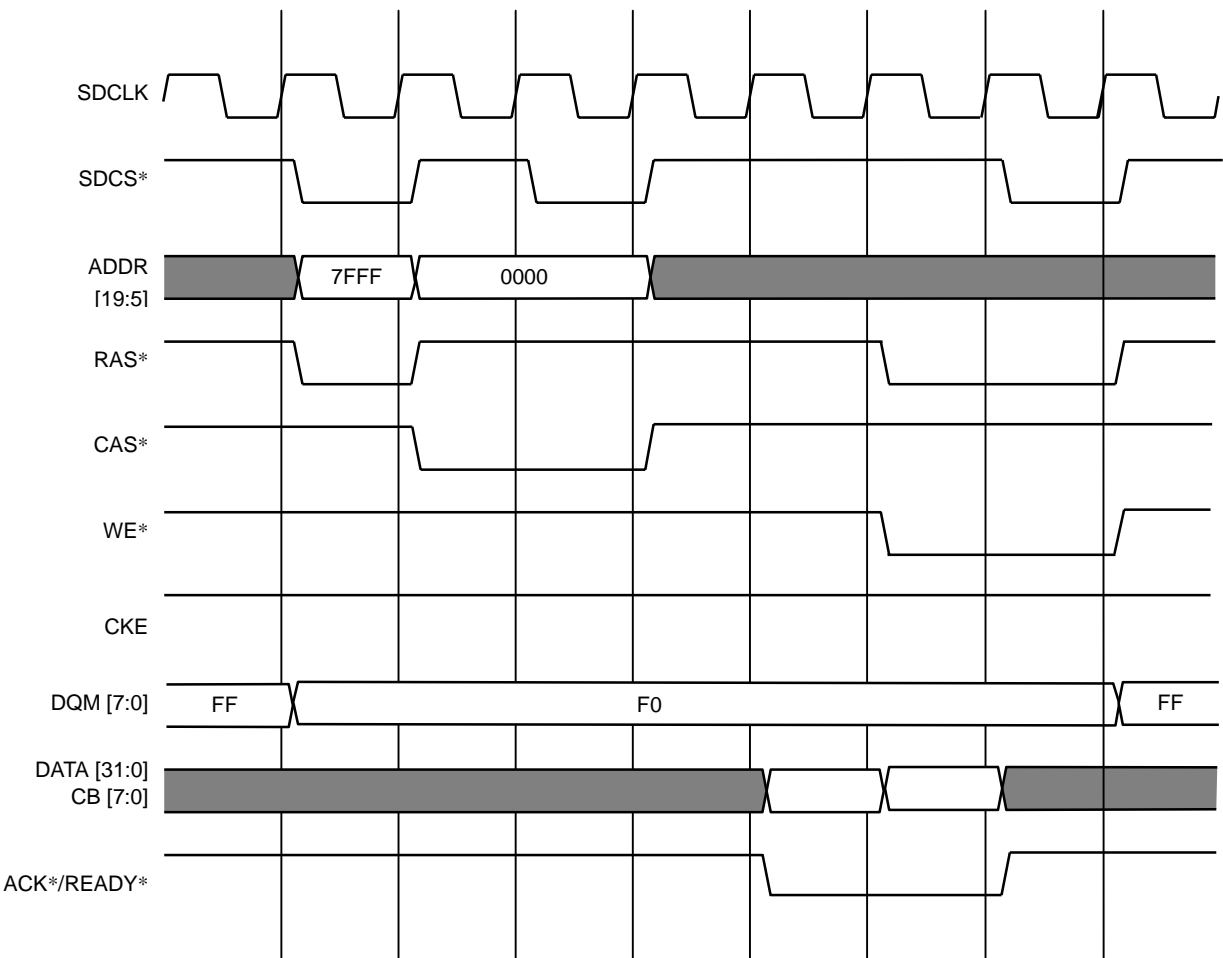


Figure 9.5.8 Double-Word Single Read ($t_{RCD} = 2$, $t_{CASL} = 2$, $t_{DA} = 0$, 32-bit Bus)

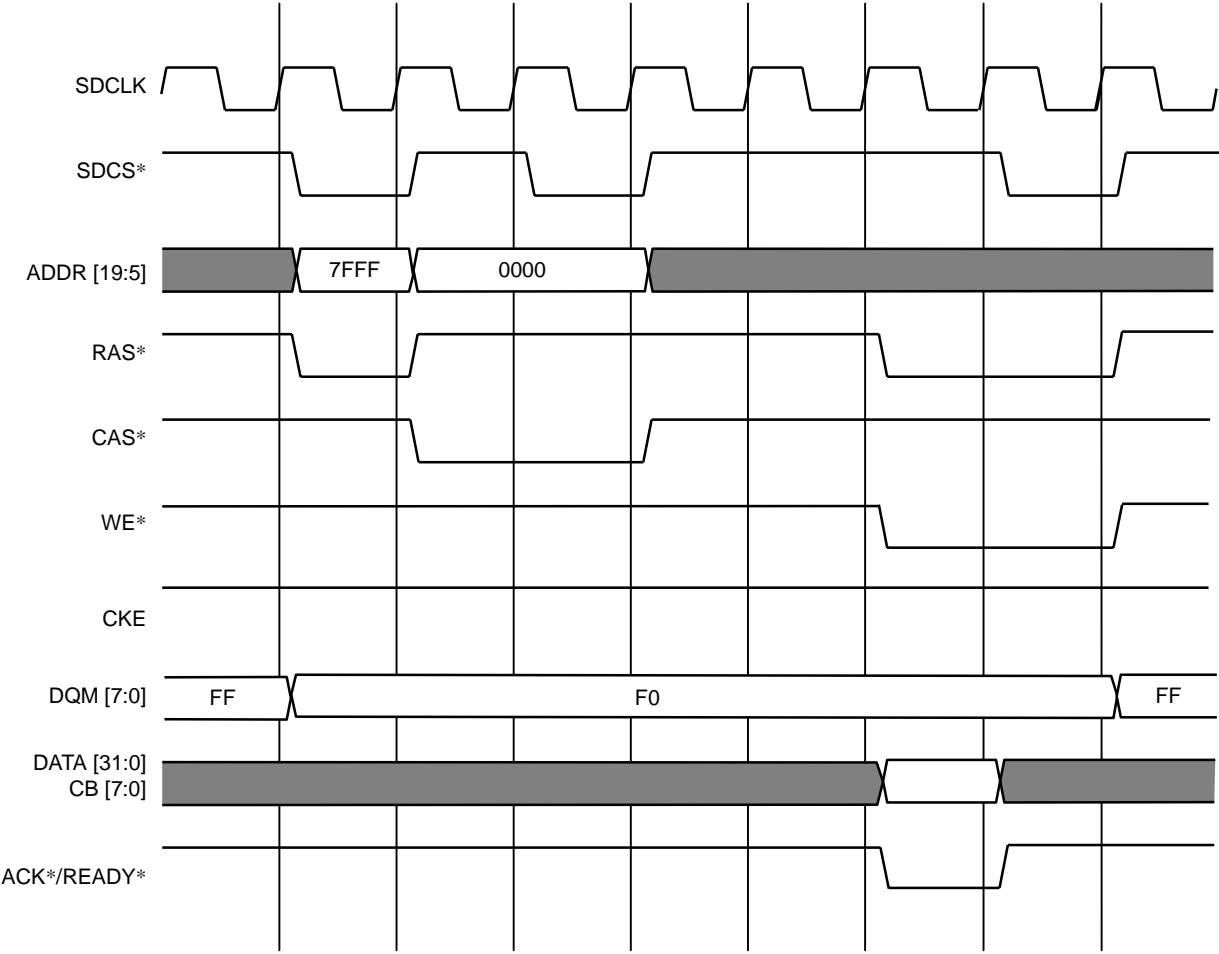


Figure 9.5.9 One-Word Single Read ($t_{RCD} = 2$, $t_{CASL} = 3$, $t_{DA} = 0$, 32-bit Bus)

9.5.7 Single Write (32-bit Bus)

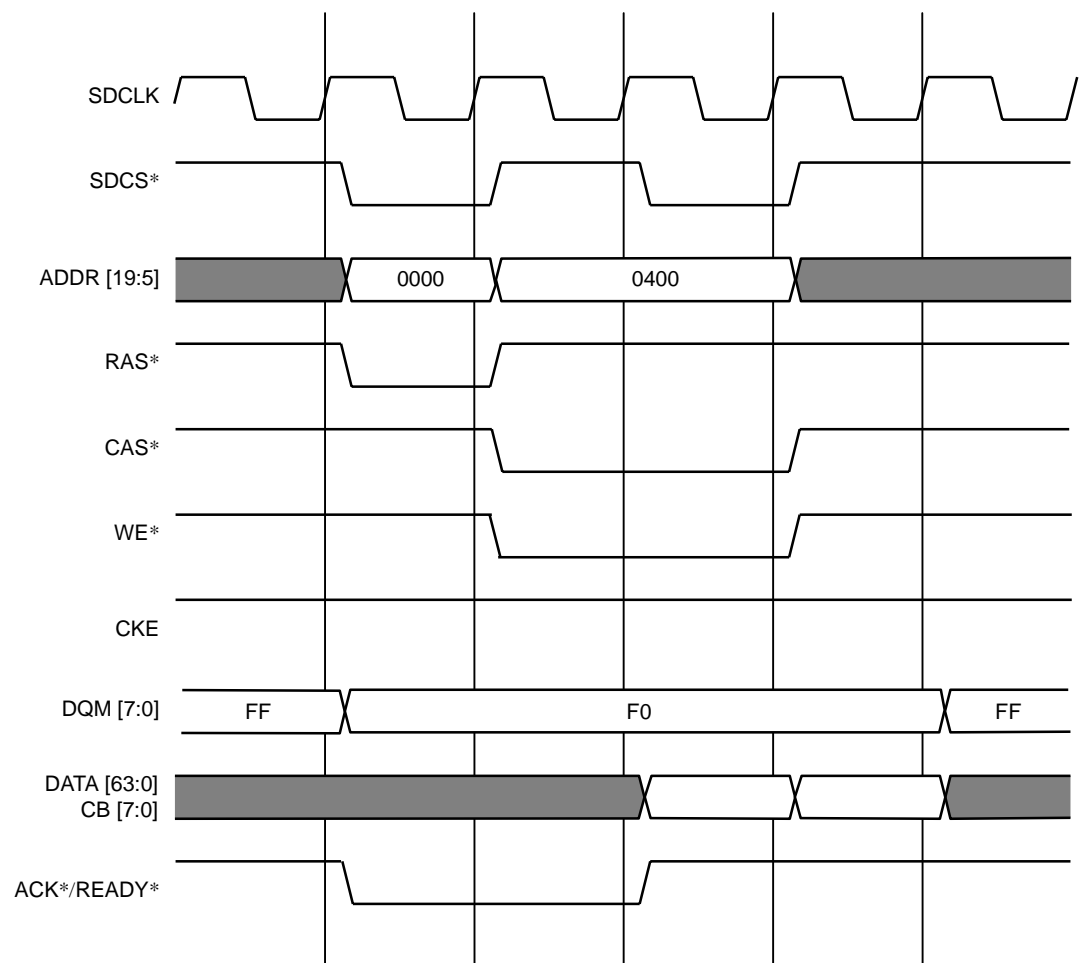


Figure 9.5.10 Double-Word Single Write ($t_{RCD} = 2$, $t_{DA} = 0$, 32-bit Bus)

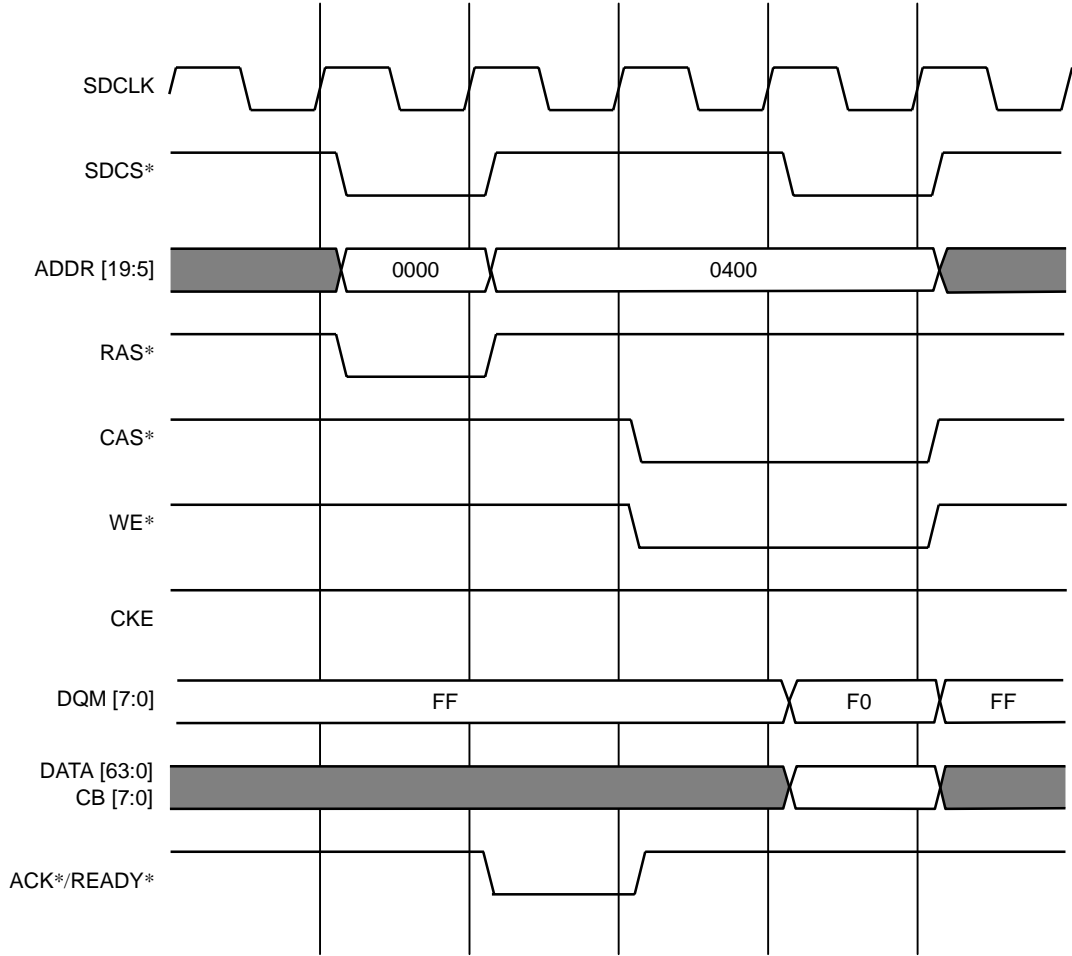


Figure 9.5.11 One-Word Single Write ($t_{RCD} = 3$, $t_{DA} = 0$, 32-bit Bus)

9.5.8 Low Power Consumption and Power Down Mode

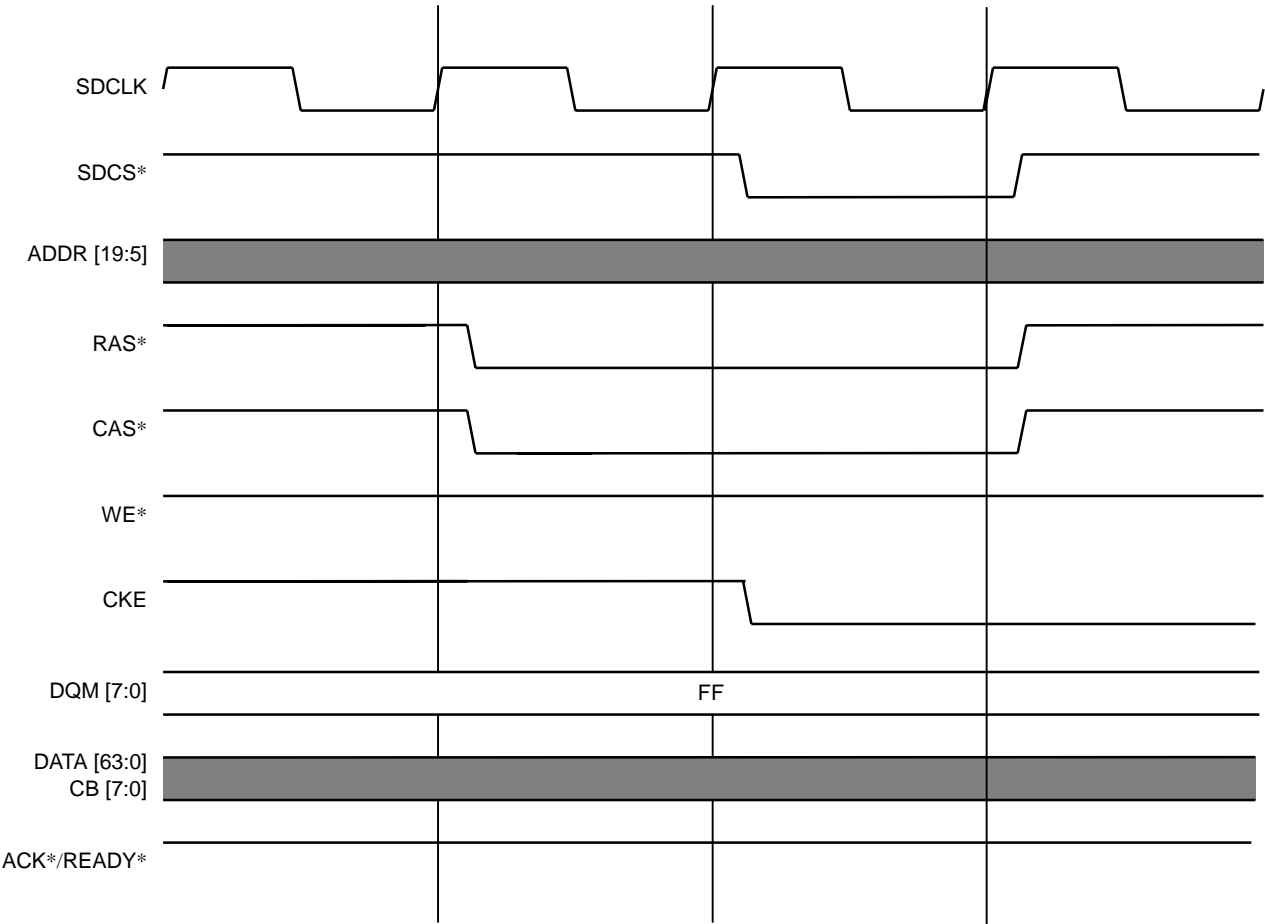


Figure 9.5.12 Transition to Low Power Consumption Mode (SDCTR.ACE = 0)

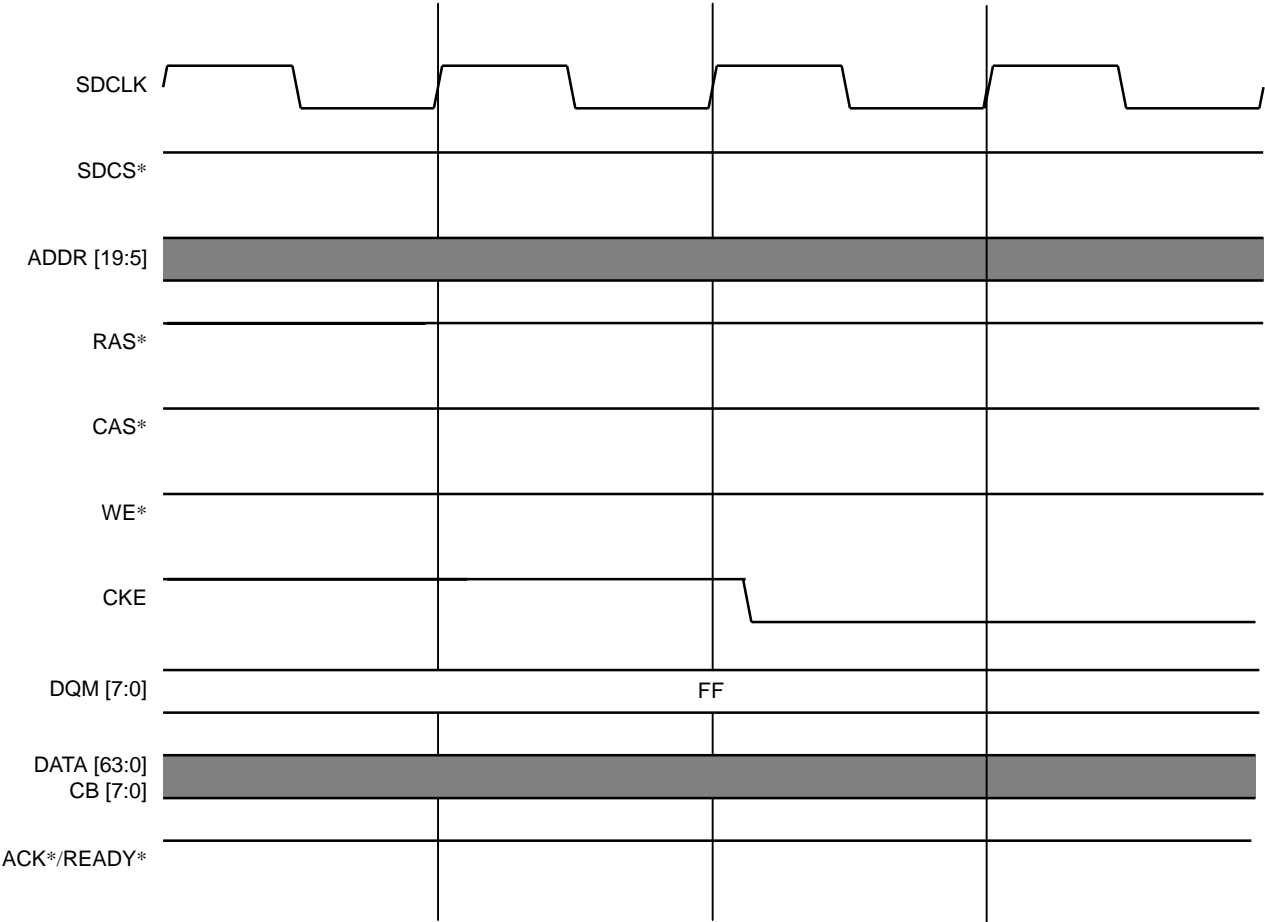


Figure 9.5.13 Transition to Power Down Mode

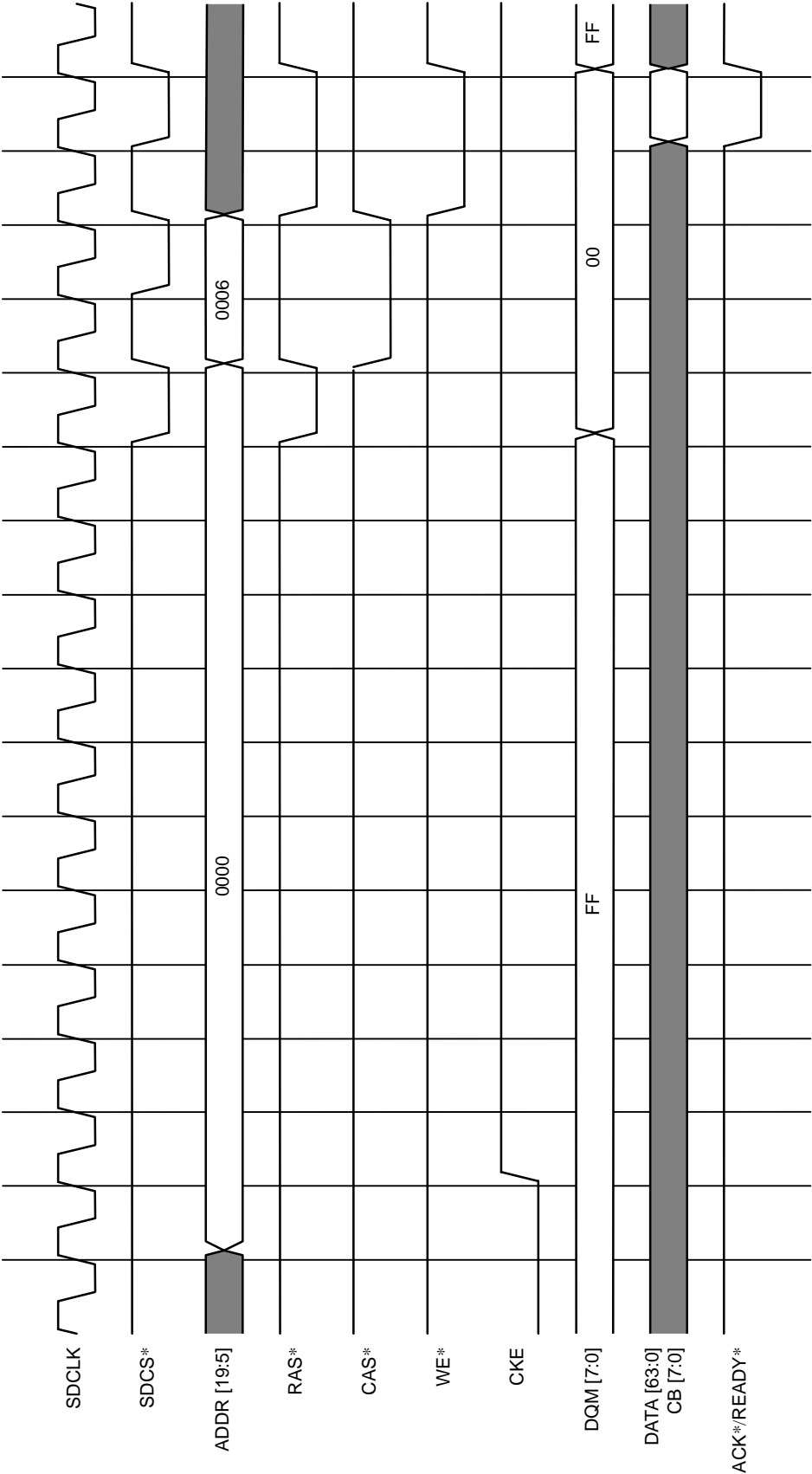


Figure 9.5.14 Return From Low Power Consumption/Power Down Mode
(SDCTR.PDAE = 0, SDCTR.ACE = 0)

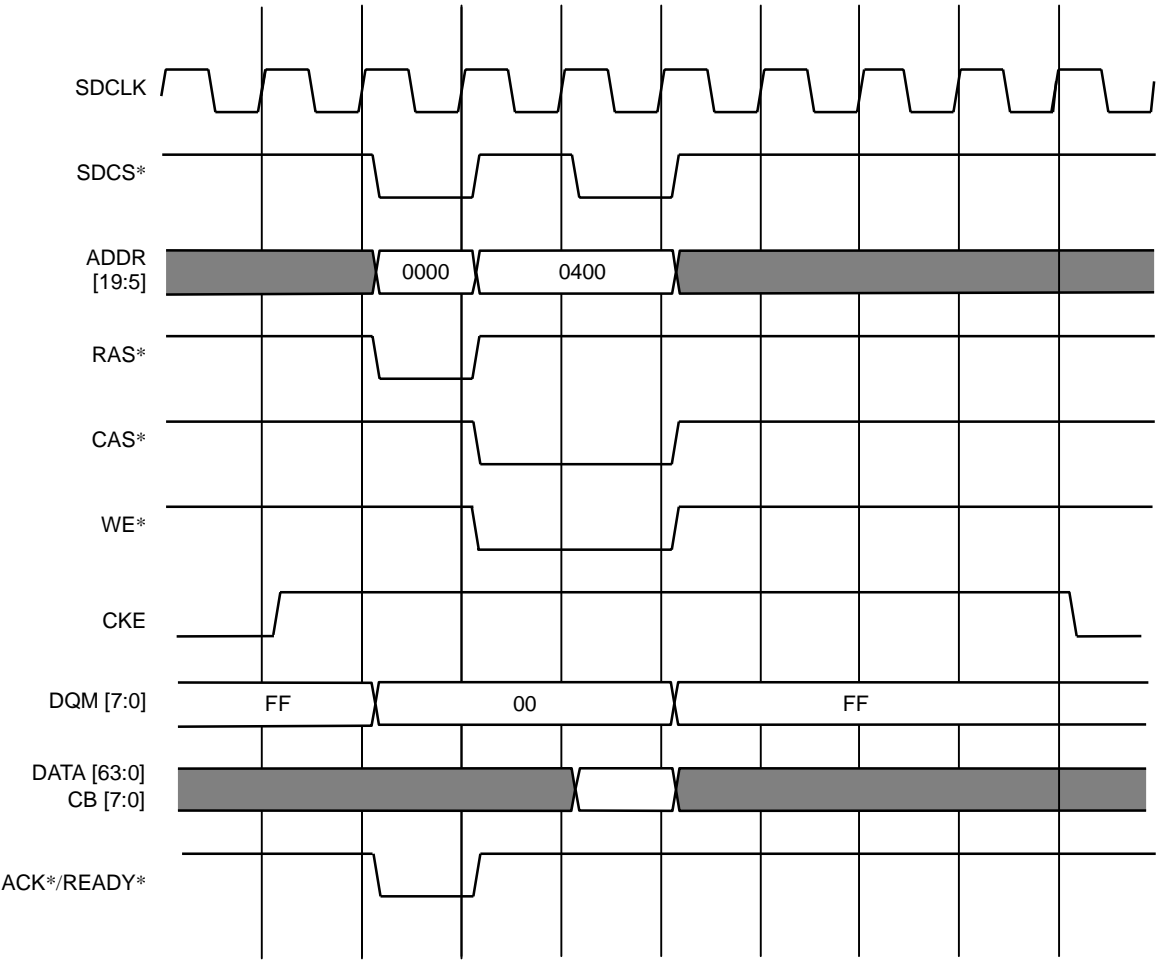


Figure 9.5.15 Power Down Auto Entry (SDCTR.PDAE = 1, SDCTR.ACE = 0)

9.6 SDRAM Usage Example

Figure 9.6.1 illustrates an example SDRAM connection. Figure 9.6.2 illustrates an example SDRAM DIMM (168-pin) connection.

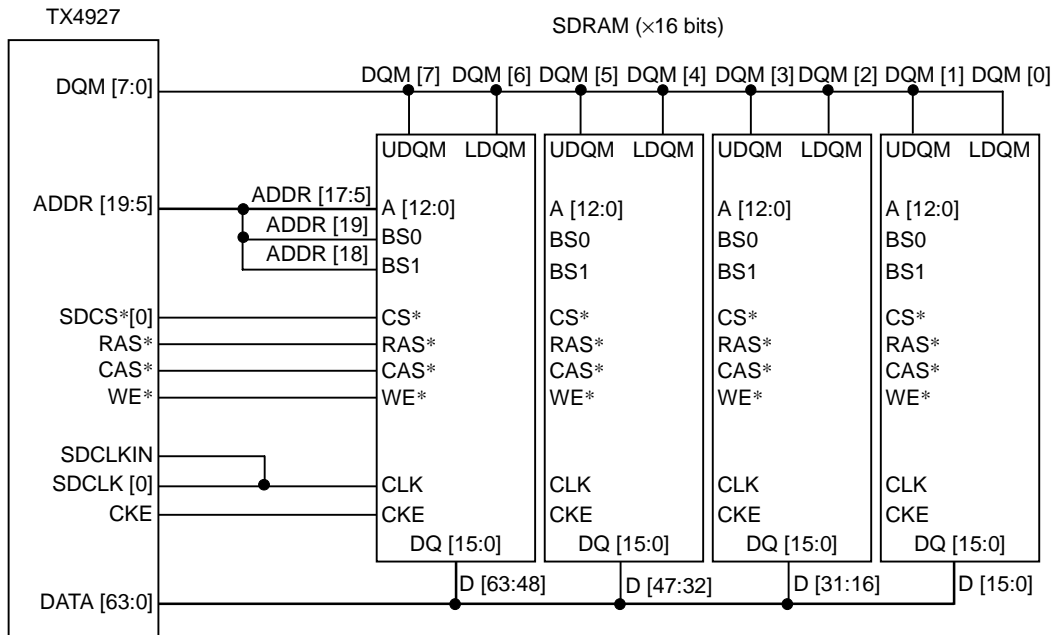


Figure 9.6.1 SDRAM (x16 bits) Connection Example

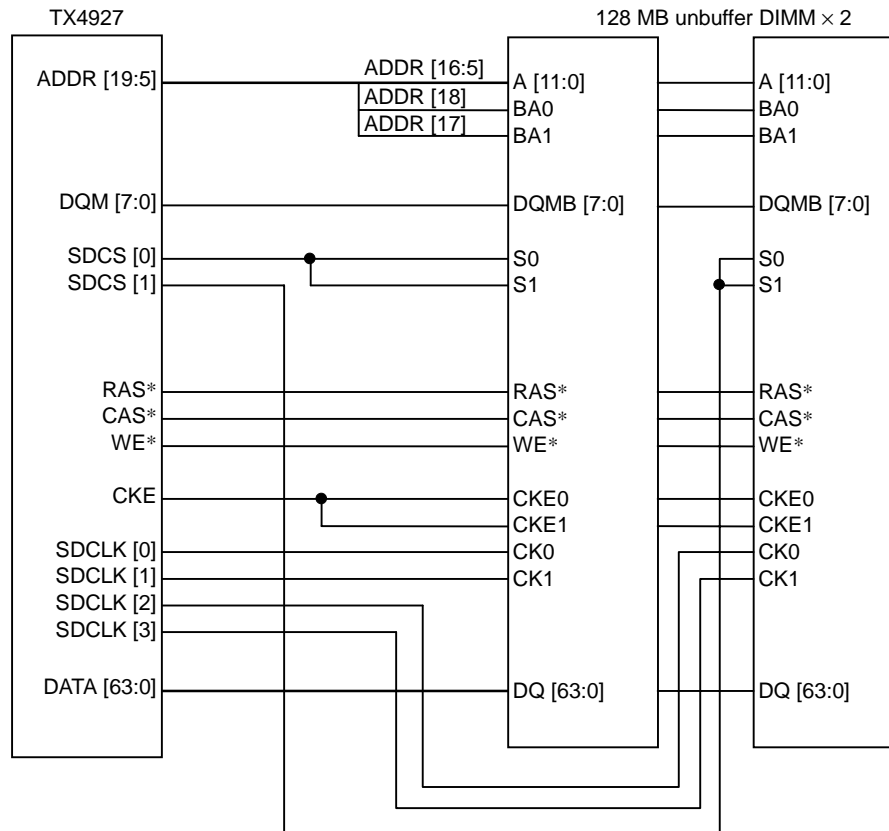


Figure 9.6.2 168-pin DIMM Connection Example

10. PCI Controller

10.1 Features

The TX4927 PCI Controller functions as a bus bridge between the TX4927 External PCI and the internal bus (G-Bus).

10.1.1 Overall

- Compliant to “PCI Local Bus Specification Revision 2.2”
- PCI Bus: 32-bit data bus; Internal Bus: 64-bit data bus
- Maximum PCI bus clock operating frequency: 66 MHz
- Dual address cycle support (40-bit PCI address space)
- Supports both the Initiator and Target functions
- Supports power management functions that are compliant to PCI Bus Power Management Interface Specifications Version 1.1.
- On-chip PCI Bus Arbiter, can connect to a maximum of four external bus masters
- 1-channel on-chip DMA Controller (PDMAC) dedicated to the PCI Controller
- Supports PC clock input mode/output mode
- The Internal Bus clock and PCI Bus clock are asynchronous and can be set independently
- Includes function for booting the TX4927 from memory on the PCI Bus
- Can set configuration data from serial ROM
- Mounted a retry function on the Internal Bus side also in order to avoid deadlock on the PCI Bus.

10.1.2 Initiator Function

- Single and Burst transfer from the Internal Bus to the PCI Bus
- Supports memory, I/O, configuration, special cycle, and interrupt acknowledge transactions.
- Address mapping between the Internal Bus and the PCI Bus can be modified
- Mounted 8-stage 64-bit data one FIFO each for Read and Write
- Post Write function enables quick termination of a maximum of four Write transactions by the G-Bus without waiting for completion on the PCI Bus.
- Endian switching function

10.1.3 Target Function

- Single and Burst transfer from the PCI Bus to the Internal Bus
- Supports memory, I/O, and configuration cycles
- Supports high-speed back-to-back transactions on the PCI Bus
- Address mapping between the PCI Bus and the Internal bus can be modified
- Mounted 8-stage 64-bit data FIFO for Read
- Mounted 12-stage 64-bit data FIFO for Write
- Post Write function enables quick termination of a maximum of nine Write transactions by the PCI Bus without waiting for completion on the G-Bus.
- Read Burst length (pre-fetch data size) on the Internal Bus when reading a pre-fetchable space can be made programmable
- Endian switching function

10.1.4 PCI Arbiter

- Supports four external PCI bus masters
- Uses the Programmable Fairness algorithm (two levels with different priorities for four round-robin request/grant pairs)
- Supports bus parking
- Bus master uses the Most Recently Used algorithm
- Unused slots and broken masters can be automatically disabled after Power On reset
- On-chip arbitration function can be disabled and external arbiter can be used

10.1.5 PDMAC (PCI DMA Controller)

- Direct Memory Access (DMA) Controller dedicated to 1-channel PCI
- Is possible to transfer data using minimal G-Bus bandwidth
- Data can be transferred bidirectionally between the G-Bus and the PCI Bus
- Specifying a physical address on the PCI Bus and an address on the G-Bus makes it possible to automatically transfer data between the PCI Bus and the G-Bus
- Supports the Chain DMA mode, in which a Descriptor containing chain-shaped addresses and a transfer size is automatically read from memory while DMA transfer continuous
- On-chip 4-stage 64-bit data buffer

10.2 Block Diagram

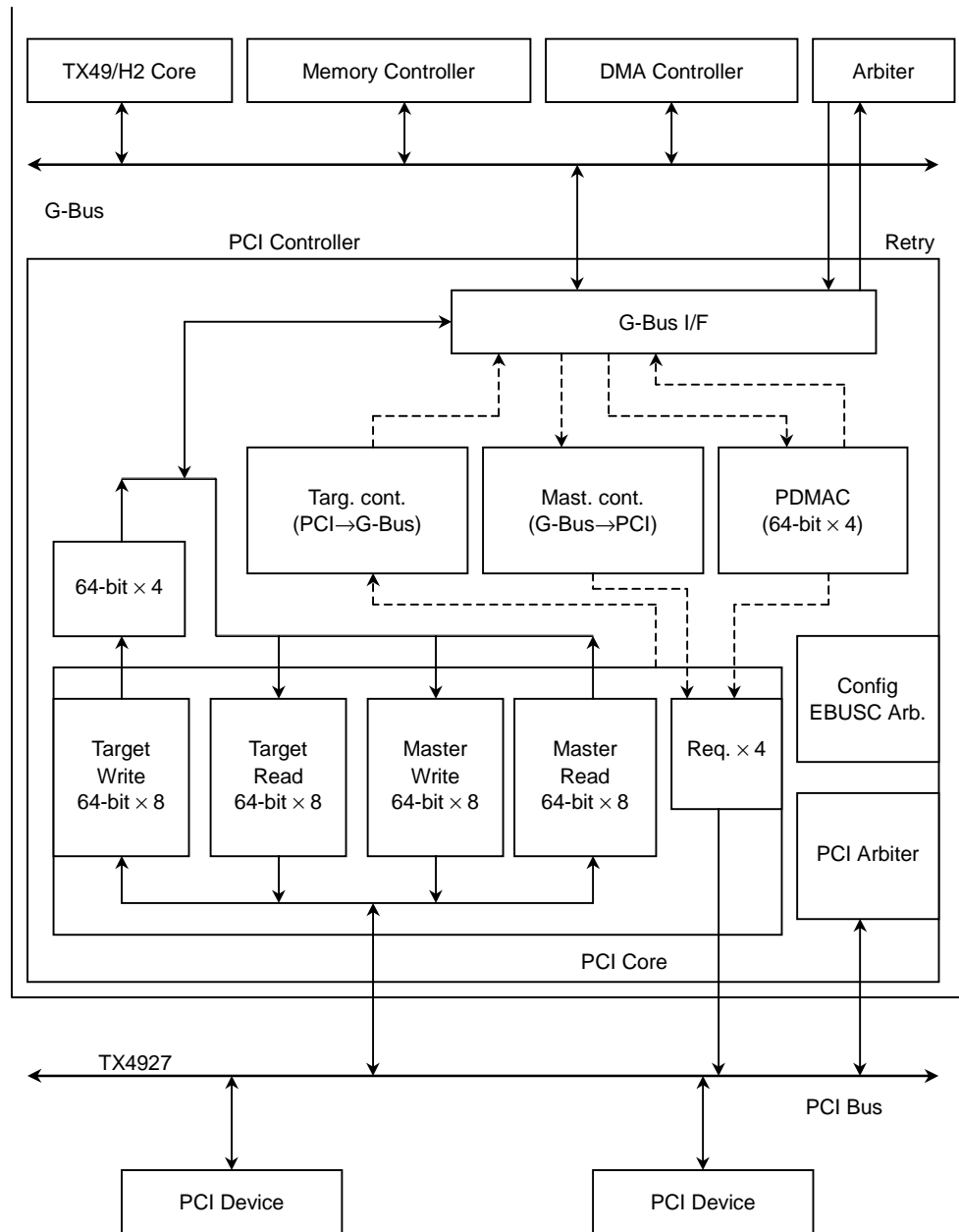


Figure 10.2.1 PCI Controller Block Diagram

10.3 Detailed Explanation

10.3.1 Terminology Explanation

The following terms are used in this chapter.

- **Initiator**
Means the bus Master of the PCI Bus. The TX4927 operates as the initiator when it obtains the PCI Bus and issues PCI access.
- **Target**
Means the bus Slave of the PCI Bus. The TX4927 operates as the target when an external PCI device on the PCI Bus executes PCI access to the TX4927.
- **Host mode**
One PCI Host device exists for one PCI Bus. The PCI Host device uses a PCI configuration space to perform PCI configuration on other PCI devices on the PCI Bus.

The TX4927 is set to the Host mode if the ADDR[19] signal is High when the RESET* signal is being deasserted.

- **Satellite mode**
A PCI device other than the PCI Host device accepts configuration from the PCI Host device. This state is referred to as the Satellite mode.

The TX4927 is set to the Satellite mode if the ADDR[19] signal is Low when the RESET signal is being deasserted.

- **DWORD, QWORD**
DWORD expresses 32-bit words, and QWORD expresses 64-bit words. According to conventions observed regarding MIPS architecture, this manual uses the following expressions:
 - Byte: 8-bit
 - Half-word: 16-bit
 - Word: 32-bit
 - Double-word: 64-bit

10.3.2 On-chip Register

The PCI Controller on-chip register contains the PCI Configuration Space Register and the PCI Controller Control Register. The registers that can be accessed vary according to whether the current mode is the Host mode or the Satellite mode.

An external PCI Host device only accesses the PCI Configuration Space Register when in the Satellite mode. This register is defined in the PCI Bus Specifications. A PCI configuration cycle is used to access this register. This register cannot be accessed when in the Host mode. Section 10.5 “PCI Configuration Space Register” explains each register in detail.

The PCI Controller Control Register is only accessed by the TX49 core and cannot be accessed from the PCI Bus.

Registers in the PCI Controller Control Register that include an offset address in the range from 0xD000 to 0xD07F can only be accessed when in the Host mode and cannot be accessed when in the

Satellite mode. These registers correspond to PCI Configuration Space Registers that an external PCI Host device accesses when in the Satellite mode. Section 10.4 “PCI Controller Control Register” explains each register in detail.

Figure 10.3.1 illustrates the register map when in the Host mode. Figure 10.3.2 illustrates the register map when in the Satellite mode.

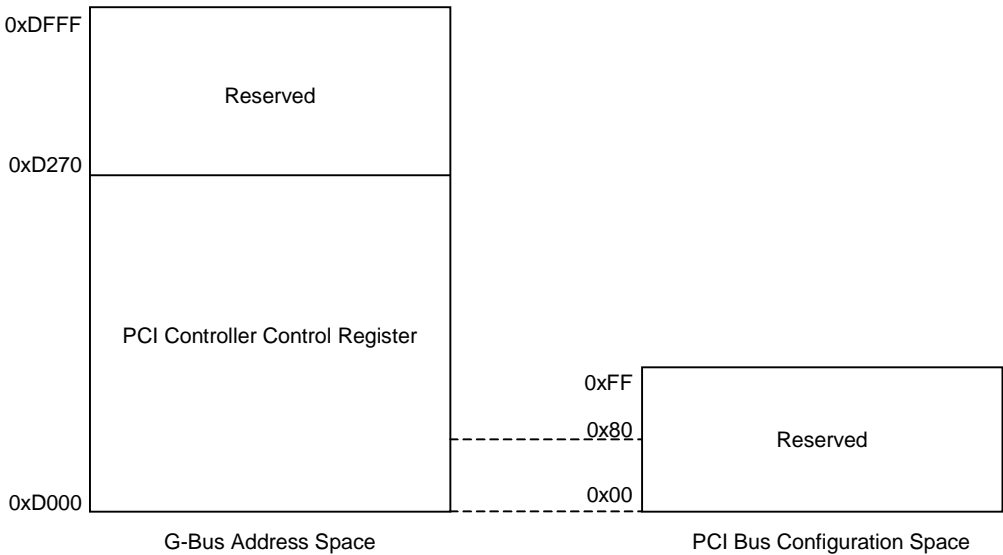


Figure 10.3.1 Register Map in the Host Mode

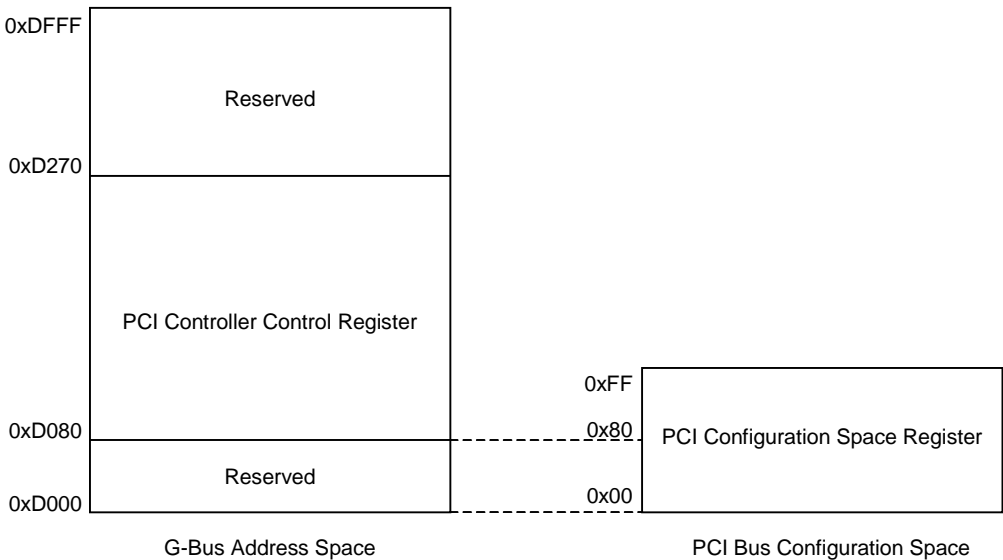


Figure 10.3.2 Register Map in the Satellite Mode

10.3.3 Supported PCI Bus Commands

Table 10.3.1 shows the PCI Bus commands that the PCI Controller supports.

Table 10.3.1 Supported PCI Bus Commands

C/BE Value	PCI Command	As Initiator	As Target
0000	Interrupt Acknowledge	†	—
0001	Special Cycle	†	—
0010	I/O Read	√	√
0011	I/O Write	√	√
0100	(Reserved)	—	—
0101	(Reserved)	—	—
0110	Memory Read	√	√
0111	Memory Write	√	√
1000	(Reserved)	—	—
1001	(Reserved)	—	—
1010	Configuration Read	†	‡
1011	Configuration Write	†	‡
1100	Memory Read Multiple	√	√
1101	Dual Address Cycle	√	√
1110	Memory Read Line	√	√
1111	Memory Write and Invalidate	√	√

Key: √ : Supported when in both the Host mode and the Satellite mode
 † : Supported only when in the Host mode
 ‡ : Supported only when in the Satellite mode
 — : Not supported

- I/O Read, I/O Write, Memory Read, Memory Write

This command executes Read/Write access to the address mapped on the G-Bus and PCI Bus.

- Memory Read Multiple, Memory Read Line

The Memory Read Multiple command is issued if all of the following conditions are met when the Initiator function is operating and Burst Read access is issued from the G-Bus to the PCI Bus.

- (1) A value other than “0” is set to the Cache Line Size Field (PCICFG1.CLS) of the PCI Configuration 1 Register.
- (2) The Read data word count is larger than the value set in the Cache Line Size Field.

Also, the Read Memory Line command is issued when all of the following conditions are met.

- (1) A value other than “0” is set to the Cache Line Size Field (PCICFG1.CLS) of the PCI Configuration 1 Register.
- (2) The Read data word count is larger than the value set in the Cache Line Size Field.

The Memory Read command is issued if these conditions are not met, namely, if “0” is set to the Cache Line Size field (PCICFG1.CLS) of the PCI Configuration 1 Register. In the case of the target, a normal G-Bus cycle is issued to the address mapped from the PCI Bus to the G-Bus.

- Memory Write and Invalidate

When the TX4927 operates as the initiator, the PCI Controller issues the Memory Write and Invalidate command if all of the following conditions are met when write access from the G-Bus to the PCI Bus occurs.

- (1) The Memory Write and Invalidate Enable bit (PCISTATUS.MWIEN) of the PCI Status Command Register is set.
- (2) A value other than “0” was set to the Cache Line Size field (PCICFG1.CLS) of the PCI Configuration 1 Register.
- (3) The word count of the Write data is larger than the value set in the Cache Line Size field.

The Memory Write command is issued in these conditions are not met.

When the TX4927 operates as the target, the Memory Write and Invalidate command is converted into G-Bus Write access. Note that the TX4927 does not support the cache memory Snoop function.

- Dual address cycle

When the TX4927 operates as the initiator, the PCI Controller executes dual access cycles if the PCI Bus address exceeds 0x00_FFFF_FFFF.

When the TX4927 operates as the target, normal G-Bus cycles are executed to the address mapped from the PCI Bus to the G-Bus.

- Configuration Read, Configuration Write

These commands only issue configuration cycles as the when in the Host mode.

The corresponding configuration cycles are issued on the PCI Bus. This is done by either reading or writing from/to the G2P Configuration Data Register (G2PCFGDATA) after writing the configuration space address to the G2P Configuration Address Register. The TX4927 supports both “Type 0” and “Type 1” configuration transactions.

On systems that have PCI card slots, the PCI Host device checks each PCI card slot during system initialization to see if PCI device exist, then set the Configuration Space Register of the devices that do exist. If a PCI Configuration Read operation is performed for devices that do not exist, then by default a Bus Error exception will be generated since there is no PCI Bus response. Clearing the Bus Error Response During Initiator Read bit (PCICFG.IRBER) of the PCI Controller Configuration Register makes it possible to execute a Read transaction without causing a Bus Error. All bits of the data read at this time will be set to “1”.

Configuration cycles will be accepted as the target only when in the Satellite mode. After reset, Retry response to PCI Configuration access will continue until the software sets the Target Configuration Access Ready Bit (PCICFG.TCAR) of the PCI Controller Configuration Register. Please use the software to set this bit after the software initialization process ends and the software is ready to accept PCI configuration.

- Interrupt Acknowledge

This command issues interrupt acknowledge cycles as an initiator only when in the Host mode. Interrupt acknowledge cycles are executed on the PCI Bus when the G2P Interrupt Acknowledge Data Register (G2PINTACK) is read. The value returned by this Read becomes the interrupt acknowledge cycle data.

The TX4927 does not support interrupt acknowledge cycles as the target.

- Special Cycle

This command issues special cycles as the initiator only when in the Host mode. This command issues special cycles on the PCI Bus when writing to the G2P Special Cycle Data Register (G2PSPC). The written value is output as the special cycle data.

The TX4927 does not support special cycles as the target.

10.3.4 Initiator Access (G-Bus → PCI Bus Address Conversion)

During PCI initiator access, the G-Bus address of the Burst transaction issued by the G-Bus that was converted into the PCI Bus address is used to issue a Burst transaction on the PCI Bus. 36-bit physical address (G-Bus addresses) are used on the G-Bus. Also, 40-bit PCI Bus addresses are used on the PCI Bus.

Three memory access windows and one I/O access window can be set in the G-Bus space (Figure 10.3.3). The size of each window is variable. When Burst transactions are issued to these access windows on the G-Bus, then that G-Bus address is converted into a PCI Bus address that is used to issue a Burst transaction to the PCI Bus as the initiator. PCI memory access is issued when the access window is the memory access window. PCI I/O access is issued when the access window is the I/O access window. Dual access cycles are also issued to the PCI Bus when the PCI Bus address exceeds 0x00_FFFF_FFFF.

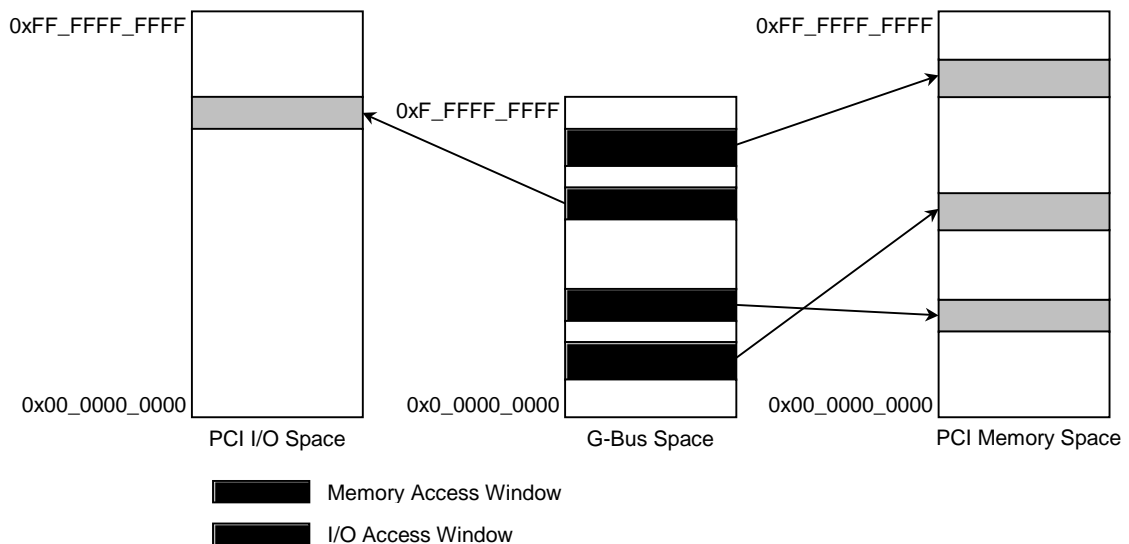


Figure 10.3.3 Initiator Access Memory Window

When expressed as a formula, conversion of a G-Bus address (GBusAddr[35:0]) into a PCI Bus Address (PCIAddr[39:0]) is as follows below. GBASE[35:8], PBASE[39:8], and AM[35:8] each represent the setting register of the corresponding access window indicated below in Table 10.3.2. The “&” symbol indicates a logical AND for each bit, “||” indicates a logical OR for each bit, “!” indicates logical NOT, and “|” indicates bit linking.

If (GBusAddr[35:8] & ! AM[35:8] == GBASE[35:8] & ! AM[35:8]) then
 PCIAddr[39:0] = PBASE[39:36]
 | ((PBASE[35:8] & ! AM[35:8]) || (GBusAddr[35:8] & AM[35:8]))
 | GBusAddr[7:0];

Table 10.3.2 Initiator Access Space Address Mapping Register

	G-Bus Base Address GBASE[35:8]	PCI Bus Base Address PBASE[39:8]	Address Mask AM[35:8]
Memory Space 0	G2PM0GBASE.BA[35:8]	G2PM0PBASE.BA[39:8]	G2PM0MASK.AM[35:8]
Memory Space 1	G2PM1GBASE.BA[35:8]	G2PM1PBASE.BA[39:8]	G2PM1MASK.AM[35:8]
Memory Space 2	G2PM2GBASE.BA[35:8]	G2PM2PBASE.BA[39:8]	G2PM2MASK.AM[35:8]
I/O Space	G2PIOGBASE.BA[35:8]	G2PIOPBASE.BA[39:8]	G2PIOMASK.AM[35:8]

Figure 10.3.4 illustrates this address conversion.

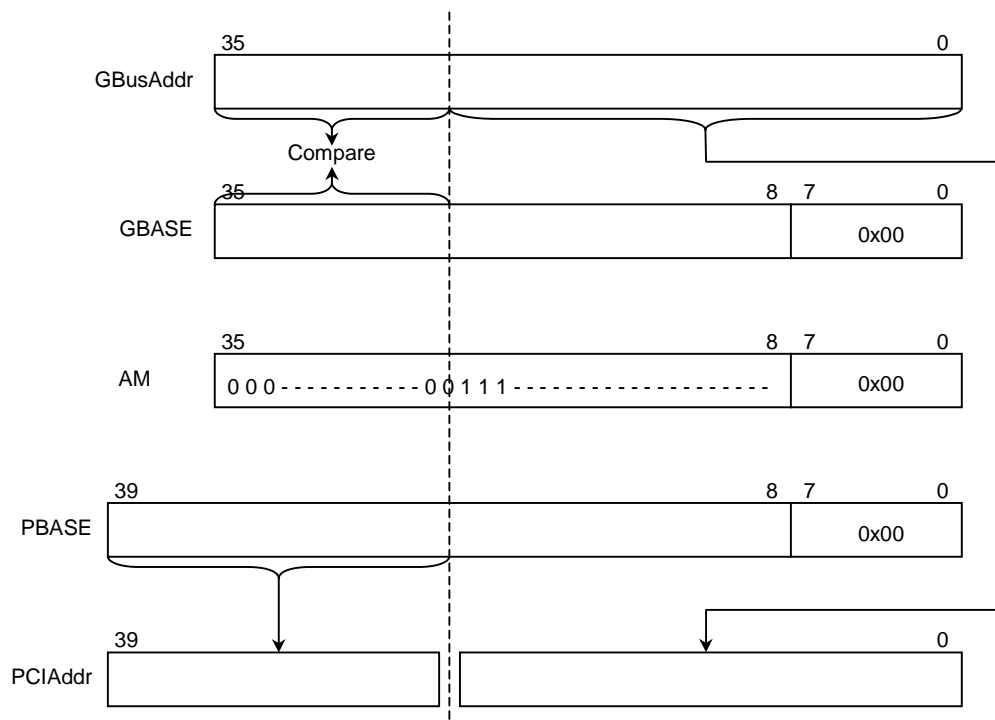


Figure 10.3.4 Address Conversion For Initiator (G-Bus → PCI Bus Address Conversion)

It is possible to set each space to valid/invalid or to perform Word Swap (see 10.3.7 “Endian Switching Function”). Table 10.3.3 shows the settings registers for these properties.

When 64-bit access is made to the initiator memory space, two 32-bit Burst accesses are issued on the PCI Bus. 64-bit access to the I/O space is not supported.

Also, operation is not guaranteed if resources in the PCI space were made cacheable and were then accessed when the Critical Word First function of the TX49/H2 core was enabled.

Table 10.3.3 Initiator Access Space Properties Register

	Enable	Word Swap
Memory Space 0	<i>BusMasterEnable</i> & PCICCFG.G2PM0EN	G2PM0GBASE.BSWAP
Memory Space 1	<i>BusMasterEnable</i> & PCICCFG.G2PM1EN	G2PM1GBASE.BSWAP
Memory Space 2	<i>BusMasterEnable</i> & PCICCFG.G2PM2EN	G2PM2GBASE.BSWAP
I/O Space	<i>BusMasterEnable</i> & PCICCFG.G2PIOEN	G2PIOGBASE.BSWAP

BusMasterEnable:

Host mode: PCI State Command Register Bus Master Bit (PCISTATUS.BM)

Satellite mode: Command Register Bus Master bit

10.3.5 Target Access (PCI Bus → G-Bus Address Conversion)

During PCI target access, the PCI Bus address of the Bus transaction issued by the PCI Bus is converted into a G-Bus address and is used to issue a Bus transaction on the G-Bus. 40-bit PCI Bus addresses are used on the PCI Bus. Also, 36-bit physical addresses are used on the G-Bus.

Three memory access windows and one I/O access window can be set in the PCI bus space (Figure 10.3.5). The size of each window is fixed. When Bus transactions to these access windows is issued on the PCI Bus, these Bus transactions are accepted as PCI target devices. The PCI Bus Address is converted into G-Bus addresses, then Bus transactions are issued to the G-Bus.

The memory space window responds to the PCI memory space access command. The I/O space window responds to the PCI I/O space access command.

Note: Byte swapping is always disabled when prefetch mode is disabled. When the G-Bus is configured for big-endian mode, the order of bits in a 32-bit word does not change during a PCI transfer. (The byte ordering changes.)

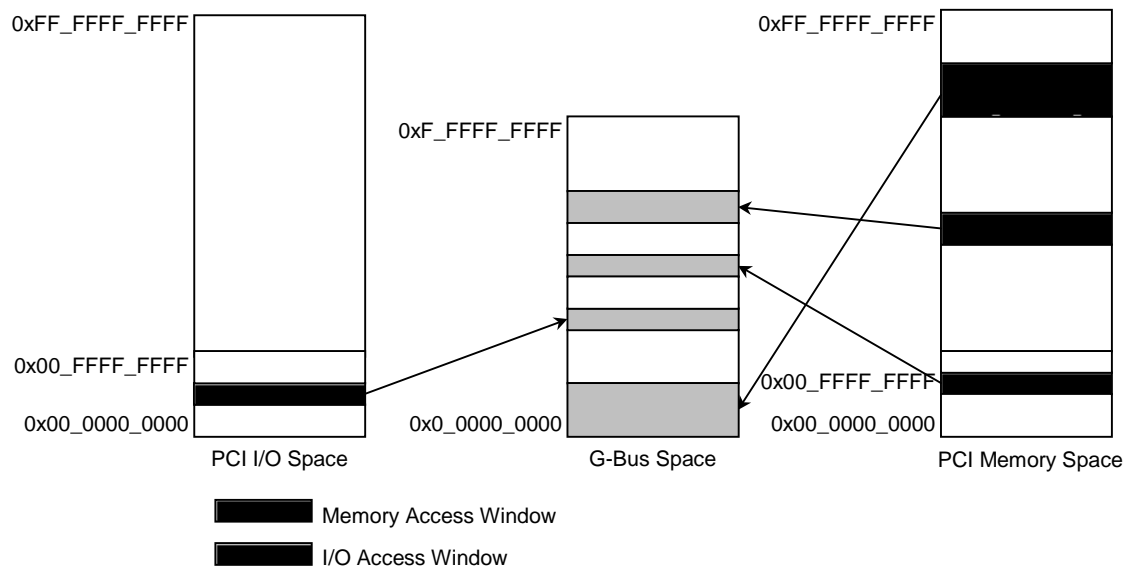


Figure 10.3.5 Target Access Memory Window

When expressed as a formula, conversion of a PCI Bus Address (PCIAddr[39:0]) into a G-Bus address (GBusAddr[35:0]) is as follows below. GBASE[35:8], and PBASE[39:8] each represent the setting register of the corresponding access window indicated below in Table 10.3.4. The “&” symbol indicates a logical AND for each bit, and “|” indicates bit linking.

Memory space 0

If (PCIAddr[39:29] == P2GM0PUBASE.BA[39:32] | P2GM0PLBASE.BA[31:29]) then
GBusAddr[35:0] = P2GM0GBASE[35:29] | PCIAddr[28:0];

Memory space 1

If (PCIAddr[39:24] == P2GM1PUBASE.BA[39:32] | P2GM1PLBASE.BA[31:24]) then
GBusAddr[35:0] = P2GM1GBASE[35:24] | PCIAddr[23:0];

Memory space 2

If (PCIAddr[31:20] == P2GM2PBASE.BA[31:20]) then
GBusAddr[35:0] = P2GM2GBASE[35:20] | PCIAddr[19:0];

I/O space

If (PCIAddr[31:8] == P2GIOBASE.BA[31:8]) then
GBusAddr[35:0] = P2GIOGBASE[35:8] | PCIAddr[7:0];

Table 10.3.4 Target Access Space Address Mapping Register

	Space Size	PCI Address	PCI Bus Base Address PBASE	G-Bus Base Address GBASE
Memory Space 0	512 MB	40-bit	P2GM0PUBASE.BA[39:32] P2GM0PLBASE.BA[31:29]	P2GM0GBASE.BA[35:29]
Memory Space 1	16 MB	40-bit	P2GM1PUBASE.BA[39:32] P2GM1PLBASE.BA[31:24]	P2GM1GBASE.BA[35:24]
Memory Space 2	1 MB	32-bit	P2GM2PBASE.BA[31:20]	P2GM2GBASE.BA[35:20]
I/O Space	256 B	32-bit	P2GIOBASE.BA[31:8]	P2GIOGBASE.BA[35:8]

Figure 10.3.6 illustrates this address conversion.

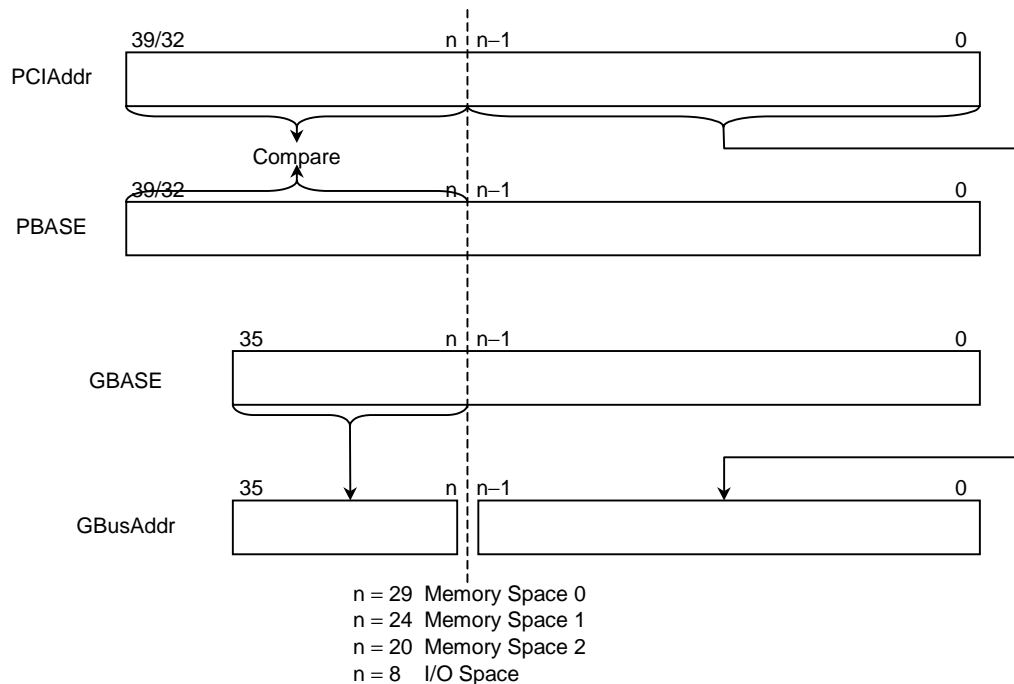


Figure 10.3.6 Address Conversion for Target (PCI Bus → G-Bus Address Conversion)

It is possible to set each space to valid/invalid, pre-fetch Read to valid/invalid, or to perform Word Swap (see 10.3.7). Table 10.3.5 shows the settings registers for these properties.

When pre-fetch Reads are set to valid, data transfer is performed on the G-Bus according to the size set by the Target Pre-fetch Read Burst Length Field (P2GCFG.TPRBL) of the P2G Configuration Register during a PCI target Read transaction. This is performed using accesses to resources that will not be affected even if a pre-read such as memory is performed. Also, PCI Burst Reads to memory spaces that were set to I/O space and pre-fetch disable are not supported.

Note: Always use PCI single reads. Don't use burst reads.

Table 10.3.5 Target Access Space Properties Register

	Enable	Pre-fetch (Initial State)	Word Swap
Memory Space 0	PCICCFG.TCAR & <i>MemEnable</i> & P2GM0GBASE.P2GM0EN	P2GCFG.MEM0PD (valid)	P2GM0GBASE.BSWAP
Memory Space 1	PCICCFG.TCAR & <i>MemEnable</i> & P2GM1GBASE.P2GM1EN	P2GCFG.MEM1PD (valid)	P2GM1GBASE.BSWAP
Memory Space 2	PCICCFG.TCAR & <i>MemEnable</i> & P2GM2GBASE.P2GM2EN	P2GCFG.MEM2PD (invalid)	P2GM2GBASE.BSWAP
I/O Space	PCICCFG.TCAR & <i>IOEnable</i> & P2GIOGBASE.P2GIOEN	Always invalid	P2GIOGBASE.BSWAP

MemEnable:

Host mode: PCI State Command Register Memory Space bit (PCISTATUS.MEMSP)

Satellite mode: Command Register Memory Space bit

IOEnable:

Host mode: PCI State Command Register I/O Space bit (PCISTATUS.IOSP)

Satellite mode: Command Register I/O Space bit

10.3.6 Post Write Function

The Post Write function improves system performance by completing the original bus Write transaction without waiting for the other bus to complete its transaction when the first bus issues a Write transaction. Initiator Write can Post Write a maximum of four Write transactions, and Target Write can Post Write a maximum of nine Write transactions.

Due to compatibility issues with old PC software in the PCI specifications, performing Post Writes with Initiator Configuration Write and Target I/O Write is not recognized. However, the TX4927 PCI Controller can even perform Post Writes to these functions. In order to guarantee that these Writes are completed by the target device, please execute Reads to the device that performed the Write, then either refer to the read value (so the TX49/H2 core can support non-blocking load) or execute the SYNC instruction.

10.3.7 Endian Switching Function

The TX4927 supports both the Little Endian mode and the Bit Endian mode. On the other hand, the PCI Bus is only defined in Little Endian logic. Therefore, when the TX4927 is in the Big Endian mode, either the software or the hardware must perform some kind of conversion when exchanging data larger than 2 B in size with the PCI Bus.

The PCI Controller can specify the endian switching function that reverses the byte arrangement of the DWORD (32-bit) data for each access window.

Initial state operation matches the correspondence between the address and byte data regardless of the endian mode (operation is address consistent). For example, if WORD (16-bit) data is written to address 0 of the PCI Bus when the TX4927 is in the Big Endian mode, the upper byte (address 0 in Big Endian) is written to PCI Bus address 0 and the lower byte (address 1 in Big Endian) is written to address 1 of the PCI Bus. For Little Endian PCI devices, this means that the byte order is reversed.

When in the Big Endian mode and a particular access window Endian switching mechanism is validated, data is transferred so the byte order does not change in DWORD (32-bit) access to that access window.

Endian switching during initiator access is specified by the Byte Swap bit (BSWAP) of the G-Bus Base Address Register (G2PMnGBASE, G2PIOGBASE) of the access window for each initiator access (see Table 10.3.3).

Ending switching during target access is specified by the Byte Swap bit (BSWAP) of the G-Bus Base Address Register (P2GMnGBASE, P2GIOGBASE) of the access window for each target access (see Table 10.3.5).

10.3.8 66 MHz Operation Mode

The TX4927 PCI Controller supports 66 MHz PCI. When in the Host mode, the procedure for setting the PCI Bus to the 66 MHz mode is as follows below.

- (1) Start the system with a PCI Bus Clock frequency of 33 MHz or less.
- (2) The TX4927 system initialization program checks the 66 MHz Capable bit (bit 5) of the configuration Space Register Status Register in all PCI devices. If the 66 MHz Capable bit of all devices is set, then change the PCI Bus Clock frequency according to the following procedure.
- (3) Assert the PCI Bus Reset signal. (The TX4927 does not have PCI Reset output, so it is necessary to use an external circuit to control the PCI Bus Reset signal.)
- (4) Set the Software Reset bit (PCICFG.SRST) of the PCI Controller Configuration Register.
- (5) Setting the PCI66 MHz Mode bit (CCFG.PCI66) of the Chip Configuration Register asserts the M66EN signal.
- (6) Modifying the setting of the PCICLK Division Ratio field (CCFG.PCIDIVMODE) of the Chip Configuration Register changes the PCI Clock frequency from 33 MHz to 66 MHz.
- (7) The software reset bit (PCICCFG.SRST) is cleared after the PLL stabilizes (about 10 ms).
- (8) Deassert the PCI Bus Reset signal. Each PCI device detects assertion of the M66EN signal if necessary and performs the process.

When the TX4927 is in the Satellite mode, the M66EN signal becomes the input signal. It is possible to read this state from the 66 MHz Drive Status bit (P2GSTATUS.M66EN) of the P2G Status Register.

PCI Reset is detected by either using the PCI Bus Reset Signal as the TX4927 overall reset signal or using the PCI Bus Reset Signal assertion detection device that the system provides. Then, the software reset the PCI Controller. The software uses a hardware reset (PCICCFG.HRST) of the PCI Controller Configuration Register to reset the PCI Controller.

10.3.9 Power Management

The TX4927 PCI Controller supports power management functions that are compliant to PCI Bus Power Management Interface Specifications Version 1.1.

The PCI Host device controls the system status by reporting the power management state to the PCI Satellite device. Also, the PCI Satellite device uses the PME* signal to report requests for changing the power management state or to report to the PCI Host device that a power management event has occurred.

10.3.9.1 Power Management State

In the case of the PCI Bus Power Management Interface Specifications, four power management states are defined from State D0 to State D3. The TX4927 supports states D0 through D3. Figure 10.3.7 illustrates the power management state transition.

After Power On Reset, or when transitioning from the D3_{HOT} state to the D0 state, the power management state becomes uninitialized D0. If initialized by the system software at this point, the state transitions to D0 Active.

If an external PCI Host device writes 11b (D3_{HOT}) to the PowerState field of the Power Management Control Status Register (PMCSR) of the Configuration space when in the Satellite mode, then the Power Management State Change bit (P2GSTATUS.PMSC) of the P2G Status Register is set and transitions to the D3_{HOT} state. It then becomes possible to report Power State Change interrupts. The PowerState field value can be read from the PowerState field (PCISSTATUS.PS) of the Satellite Mode PCI Status Register.

The TX4927 uses the software to change the system status after a status change is detected.

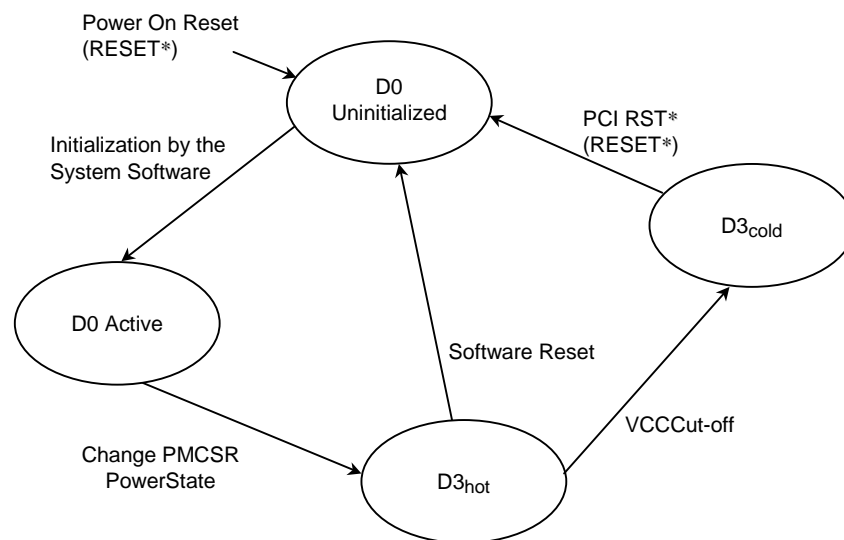


Figure 10.3.7 Transition of the Power Management States

10.3.9.2 PME* Signal (Satellite Mode)

The following PMEs (Power Management Events) are reported when in the Satellite mode.

- The PCI Host device sets the PME_En bit of the PMCSR Register in the TX4927 Configuration space. This makes it possible for the TX4927 to assert the PME* signal.

Then, the PME_En Set bit (P2GSTATUS.PMEES) of the P2G Status Register is set. Furthermore, it also becomes possible to generate PME_En Set interrupts. The PME_En bit value can be read from the PME_En bit (PCISSTATUS.PMEEN) of the Satellite Mode PCI Status Register.

- Writing “1” to the PME bit (P2GCFG.PME) of the P2G Configuration Register sets the PME_Status bit of the PMCSR Register, then asserts the PME* signal, which is the open drain signal. PME is then reported to the PCI Host device.
- The PCI Host device checks the PMCSR PME_Status bit of each PCI device, then specifies the PCI device that asserted the PME* signal.
- After the process corresponding to PME ends, the PCI Host device writes “1” to the TX4927 PME_Status bit that reported PME, thereby reporting the end of the process. As a result, the PME_Status bit of the PMCSR Register is cleared and the PME* signal is deasserted.

Then, the PME Status Clear bit (P2GSTATUS.PMECLR) of the P2G Status Register is set. It is also possible to generate PME Status Clear interrupts.

10.3.9.3 PME* Signal* (Host Mode)

The PME Detection bit (PCICSTATUS.PMED) of the PCI Controller Status Register is set when an external satellite device asserts the PME* signal while the TX4927 is in the Host mode. It is also possible to generate PME Detection interrupts at this time.

10.3.10 PDMAC (PCI DMA Controller)

The PCI DMA Controller (PDMAC) is a one-channel PCI Director Memory Access (DMA) controller. Data can be transferred bidirectionally between the G-Bus and the PCI Bus.

Note: The PDMAC can only access the SDRAMC on the G-Bus. It does not provide support for access to other controllers on the G-Bus.

10.3.10.1 DMA Transfer

The following DMA transfer procedure does not use the Chain DMA mode.

1. Address Register and Count Register Setting
Sets values for the three following registers.
 - PDMAC G-Bus Address Register (PDMGA)
 - PDMAC PCI Bus Address Register (PDMPA)
 - PDMAC Count Register (PDMCTR)
2. Chain Address Register Setting
Sets “0” to the PDMAC Chain Address Register (PDMCA).
3. PDMAC Status Register (PDMSTATUS) Clearing
Clears any remaining status from a previous DMA transfer.

4. PDMAC Control register (PDMCFG) Setting
Clears the Channel Reset bit (CHRST), and makes settings such as the data transfer direction (XFRDIRC), and the data transfer unit size (XFRSIZE).
5. DMA Transfer Initiation
Setting the Transfer Active bit (XFRACT) of the PDMAC Control Register initiates DMA transfer.
6. Termination Report
When the DMA data transfer terminates normally, the Normal Data Transfer Complete bit (NTCMP) of the PDMAC Status Register (PDMSTATUS) is set. An interrupt is then reported if the Normal Data Transfer Complete Interrupt Enable bit (NTCMPIE) of the PDMAC Control Register is set.

If an error is detected during DMA transfer, the error cause is recorded in the lower 5 bits of the PDMAC Status Register and the transfer is aborted. An interrupt is then reported if the Error Detection Interrupt Enable bit (ERRIE) of the PDMAC Control register is set.

10.3.10.2 Chain DMA

DMA Command Descriptors are 4 QWORD (32-Byte) data structures indicated in Table 10.3.6 that are placed in memory.

Storing the starting memory address of another DMA Command Descriptor in the Offset 0 Chain Address Field makes it possible to configure a chain list for the DMA command Descriptor. Set "0" in the Chain Address field of the DMA Command Descriptor at the end of the chain list.

When the DMA transfer specified by one DMA Command Descriptor ends, the PDMAC reads the next DMA Command Descriptor that the Chain Address field automatically points to, then continues the DMA transfer. Such continuous DMA transfer that uses multiple descriptors in a chain format is referred to as the Chain DMA mode.

When a DMA Command Descriptor is placed to an address that does not extend across a 32 QWORD boundary in memory, this transfer method is more efficient since data can be read by a single G-Bus Burst Read transaction.

Table 10.3.6 DMA Command Descriptors

Offset Address	Field Name	Transfer Destination Register
0x00	Chain Address	PDMAC Chain Address Register (PDMCA)
0x08	G-Bus Address	PDMAC G-Bus Address Register (PDMGA)
0x10	PCI Bus Address	PDMAC PCI Bus Address Register (PDMPA)
0x18	Count	PDMAC Count Register (PDMCTR)

The DMA transfer procedure is as follows when in the Chain DMA mode.

1. Count Register Setting
Sets "0" to the PDMAC Count Register (PMDCTR).
2. DMA Command Descriptor Chain Construction
Constructs the DMA Command Descriptor Chain in memory.
3. PDMAC Status Register (PDMSTATUS) Clearing
Clears any remaining status from a previous DMA transfer.

4. PDMAC Control Register (PDMCFG) Setting
Clears the Channel Register bit (CHRST) and makes settings such as the data transfer direction (XFRDIRC) and the data transfer unit size (XFRSIZE).
5. DMA Transfer Initiation
Setting the address of the DMA Command descriptor that is at the beginning of the Chain List in the PDMAC Chain Address Register (PDMCA) automatically initiates DMA transfer.

First, the values stored in each field of the DMA Command Descriptor that is at the beginning of the Chain List are read to each corresponding PDMAC Register, then DMA transfer is performed according to the read values.

If a value other than “0” is stored in the PDMAC Chain Address Register (PDMCA), data transfer of the size stored in the PDMAC Count Register is complete, then the DMA Command Descriptor value for the memory address specified by the PDMAC Chain Address Register is read.

When the Chain Address field value reads a descriptor of “0”, the PDMAC Chain Address Register value is not updated and the previous value (address of the Data Command Descriptor at which the Chain Address field value is “0” when read) is held.

0 value judgement is performed when the lower 32 bits of the PDMAC Chain Address Register are rewritten. DMA transfer is automatically initiated if the value was not “0”. Therefore, please write to the upper 32 bits first when writing to the PDMAC Chain Address Register using a 32-bit Store instruction.

6. Termination Report
When DMA data transfer of all descriptor chains terminates normally, the Normal Chain Complete bit (NCCMP) of the PDMAC Status Register is set. An interrupt is reported if the Chain Termination Interrupt Enable bit (MCCMPIE) of the PDMAC Control register (PDMCFG) is set.

Also, the Normal Data Transfer Complete bit (NTCMP) of the DPMAC Status Register is set each time the DMA data transfer specified by a DMA Command Descriptor terminates normally. An interrupt is reported if the Normal Data Transfer Complete Interrupt Enable bit (NTCMPPIE) of the PDMAC Control Register (PDMCFG) is set.

If an error is detected during DMA transfer, the error cause is recorded in the lower 5 bits of the PDMAC Status Register and the transfer is aborted. An interrupt is then reported if the Error Detection Interrupt Enable bit (ERRIE) of the PDMAC Control register is set.

10.3.10.3 Dynamic Chain Operation

It is possible to dynamically add other DMA Command Descriptor Chains to a DMA Command Descriptor Chain that is currently being processed when executing DMA data transfer. This is done according to the following procedure.

1. DMA Command Descriptor Chain Construction
Constructs a DMA Command Descriptor Chain in memory.
2. Addition of DMA Command Descriptor Chains
Substitutes the address of the command descriptor that is at the beginning of the descriptor chain to be added into the Descriptor Chain Address field at the end of the DMA Command Descriptor Chain that is currently performing DMA transfer.

3. Chain Enable bit checking

Reads the value of the Chain Enable bit (CHNEN) in the PDMAC Control Register (PDMCFG). If the read value is “0”, then the Chain Address field value of the DMA Command Descriptor indicated by the address stored in the PDMAC Chain Address Register (PDMCA) is written to the PDMAC Chain Address Register (PDMCA).

10.3.10.4 Data Transfer Size

The Transfer Size field (PDMCFG.XFERSIZE) of the PDMAC Control Register specifies the transfer size of each G-Bus transaction in a DMA transfer. The transfer size can be selected from one of the following: 1 DWORD, 1 QWORD, or 4 QWORD (Burst transfer).

1 QWORD or 4 QWORD can only be selected as the transfer size when the setting of the PDMAC G-Bus Address Register (PDMGA) and the PDMAC PCI Bus Address Register (PDMPA) is a 64-bit address boundary and the PDMAC Count Register (PDMCTR) setting is an 8-byte multiple. 1 DWORD must be selected as the transfer size in all other cases.

10.3.11 Error Detection, Interrupt Reporting

The PCI Controller reports the four following types of interrupts to the Interrupt Controller (IRC).

- Normal Operation Interrupt (Interrupt Number: 16, PCIC)
- PDMAC Interrupt (Interrupt Number: 15, PDMAC)
- Power Management Interrupt (Interrupt Number: 23, PCIPME)
- Error Detection Interrupt (Interrupt Number: 22, PCIERR)

When each cause is detected, an interrupt is reported if the corresponding Status bit is set, and the corresponding Interrupt Enable Bit is set. The following tables list the name of each interrupt cause, the Status bit, and the Interrupt Enable bit. Please refer to the explanation of each Status bit for more information regarding each interrupt cause.

10.3.11.1 Normal Operation Interrupt

Name	Status Bit		Interrupt Enable Bit	
M66EN Signal Assert Detect	P2GSTATUS	M66EN	P2GMASK	M66ENIE

10.3.11.2 PDMAC Interrupts

Name	Status Bit		Interrupt Enable Bit	
Normal Chain Termination	PDMSTATUS	NCCMP	PDMCFG	NCCMPIE
Normal Data Transfer Termination		NTCMP		NTCMPIE
Inter-Transfer Stall Time Reached		STLTRF		ERRIE
Configuration Error		CFGERR		
PCI Fatal Error		PCIERR		
G-Bus Chain Error		CHNERR		
G-Bus Data Error		DATAERR		

10.3.11.3 Power Management Interrupts

Name	Status Bit		Interrupt Enable Bit	
PM Status Change Detect	P2GSTATUS	PMSC	P2GMASK	PMSCIE
PME_En Set Detect		PMEES		PMEESIE
PME Status Clear Detect		PMECLR		PMECLRIE
PME Detect	PCICSTATUS	PME	PCICMASK	PMEIE

10.3.11.4 Error Detection Interrupts

Name	Status Bit		Interrupt Enable Bit	
Parity Error Detect	PCISTATUS / PCISSTATUS	DPE	PCIMASK	DPEIE
System Error Report		SSE		SSEIE
Master Abort Receive		RMA		RMAIE
Target Abort Receive		RTA		RTAIE
Target Abort Report		STA		STAIE
Master Data Parity Error		MDPE		MDPEIE
TRDY Timeout Error	G2PSTATUS	IDTTOE	G2PMASK	IDTTOEIE
Retry Timeout Error		IDRTOE		IDRTOEIE
Broken Master Detect	PBASTATUS	BMD	PBAMASK	BMDIE
Long Burst Transfer Detect	PCICSTATUS	TLB	PCICMASK	TLBIE
Negative Increase Burst Transfer Detect		NIB		NIBIE
Zero Increase Burst Transfer Detect		ZIB		ZIBIE
PERR* Detect		PERR		PERRIE
SERR* Detect		SERR		SERRIE
G-Bus Bus Error Detect		GBE		GBEIE

10.3.12 PCI Bus Arbiter

Configuration settings (DATA[2] signal) during boot up select whether to use the on-chip PCI Bus arbiter (Internal PCI Bus Arbiter mode) or to use the External PCI Bus arbiter (External PCI Bus Arbiter mode).

When in the Internal PCI Bus Arbiter mode, setting the PCI Bus Arbiter Enable bit (PBACFG.PBAEN) of the PCI Bus Arbiter Configuration Register starts operation.

The on-chip PCI Bus arbiter can arbitrate eight sets of PCI Bus usage requests from the Bus Master. Five ports are used: one for the PCI Controller bus master and four for External Bus masters. The three remaining ports are reserved for future expanded features.

10.3.12.1 Request Signal, Grant Signal

The four external Bus Masters are connected to the REQ[3:0] signal and the GNT[3:0]* signal.

Also, when in the External PCI Bus Master mode, the REQ[0]* signal becomes the PCI Bus Request Output signal and the GNT[0]* signal becomes the Bus Usage Permission Input Signal. Furthermore, the REQ[1]* signal can be used as an interrupt output signal to the external devices (see 14.3.7 for more information).

10.3.12.2 Priority Control

As illustrated below in Figure 10.3.8, a combination of two round-robin sequences is used as the arbitration algorithm that determines the priority of Internal PCI Bus arbiter bus requests. The round-robin with the lower priority (Level 2) consists of Masters W - Z, and the round-robin with the high priority (Level 1), consists of Master A - D and Level 2 Masters. The PCI Bus Arbiter Request Port Register (PBAREQPORT) specifies whether to allocate the PCI Controller and the four External Bus Masters to Masters A-D or W - Z.

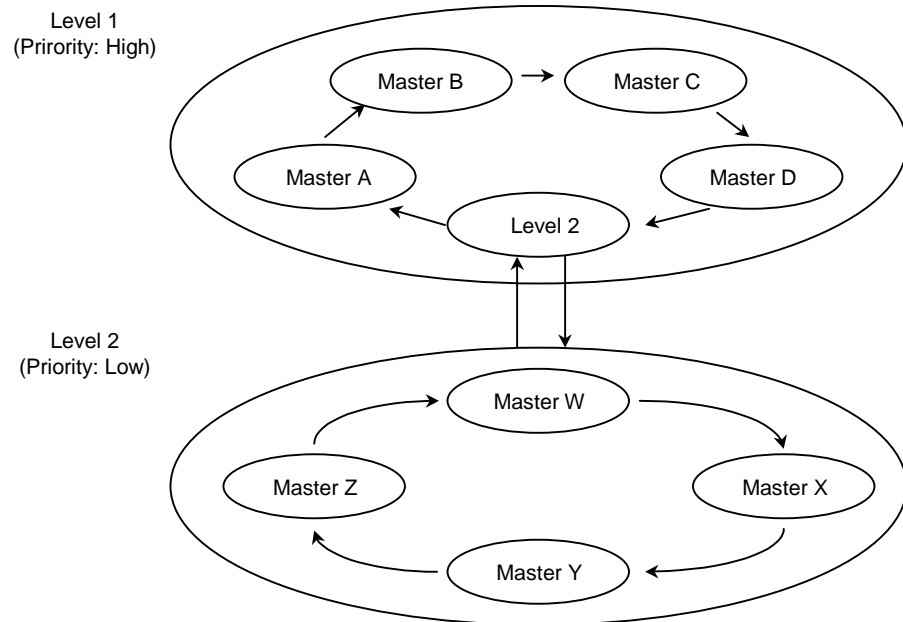


Figure 10.3.8 PCI Bus Arbitration Priority

The Bus Master priority is determined based on the Level 1 round-robin sequence. However, when Level 2 is used inside Level 1, the Level 2 Bus Master priority is determined based on the Level 2 round-robin sequence.

All 8 Bus Masters cannot be used on the TX4927. However, the Bus Master priority would be as follows if we assume there is a hypothetical device that can use all 8 Bus Masters and all 8 Bus Masters (Masters A - D, W - Z) simultaneously requested the bus.

```

A → B → C → D → W
→ A → B → C → D → X
→ A → B → C → D → Y
→ A → B → C → D → Z
→ A (returns to the beginning)

```

Since the priority can only transition in the order indicated by the above arrows (or the arrows in Figure 10.3.8, if we assume that the three Bus Masters A, B, and W exist, then Master B will obtain the bus first. If A and W then simultaneously request the bus, then PCI Bus ownership will transition in the order B → W → A.

10.3.12.3 Bus Parking

The On-chip PCI Bus Arbiter supports bus parking.

The last PCI Bus Master is made the Park Master when the Fix Park Master bit (FIXPM) of the PCI Bus Arbiter Configuration Register (PBACFG) is cleared (in the default state). When this bit is set, the Internal PCI Bus Arbiter Request A Port (Master A) becomes the Park Master.

10.3.12.4 Broken Master Detect

The TX4927 On-chip PCI Bus Arbiter has a function for automatically detecting broken masters.

If the PCI Bus Master requests and is granted the bus when the PCI Bus is in the Idle state, this master must assert the FRAME* signal within 16 PCI block cycles and start a transaction. The PCI Bus Arbiter recognizes any device that breaks this rule as a broken bus master and removes that device from the bus arbitration sequence.

This detection function is enabled when the Broken Master Check Enable bit (BMCEN) of the PCI Bus Arbiter Configuration Register (PBACFG) is set. When a broken master is detected, the Broken Master Detection bit (PBSTATUS.BMD) of the PCI Bus Arbiter Status Register is set and the bit in the PCI Bus Arbiter Broken Master Register (PBABM) that corresponds to that master is set. Then it also becomes possible to report an interrupt.

10.3.12.5 Special Programming

There may be some devices among PCI bus masters that operate differently from typical PCI devices. PCI devices with the following characteristics can be made usable by changing the programming of the PCI bus arbiter.

1. Bus masters that can not re-assert REQ unless GNT is once deasserted after deasserting REQ
 - Assign the bus master to a request port other than Port A through the PBAREQPORT register (at 0xD100). (Assign the TX4927 to Port A.)
 - Enable the Fixed Parked Master (FIXPA) bit in the PBACFG register (at 0xD104).
2. Bus masters that initiate a PCI transaction even when the deassertion of GNT has taken away their bus mastership before the start of the transaction
 - Assign the bus master to request port A, B, C or D through the PBAREQPORT register (at 0xD100).

For example, a bus master with both of the above characteristics can be used by configuring the PCI bus arbiter as follows:

Set the internal PCI bus arbiter to the fixed parked master.

Assign the TX4927 to request port A.

Assign the bus master to request port B.

If this bus master is connected to REQ[3] and broken master checking is to be enabled, values to be written to the PBACFG and PBAREQPORT registers are as follows:

PBACFG (at 0xD104): 0x0000000B

PBAREQPORT (at 0xD100): 0x73546210

10.3.13 PCI Boot

Setting the configuration during boot up (ADDR[8:6]) makes it possible to set the reset exception vector address of the TX49/H2 core to PCI Bus address 0x00_BFC0_0000.

Two windows of the memory space from the G-Bus to the PCI Bus space are used when in the PCI

Boot mode. The defaults of several registers are changed as indicated below.

- G-Bus base address (G2GBASE): 0x0_1FC0_0000
- Space size (G2PM2MASK): 4 MB
- PCI Bus base address (G2PM2PBASE): 0x00_BFC0_0000
- Initiator Memory Space 2 Enable (PCICCFG.G2PM2EN): 1
- Bus Master bit (PCISTATUS.BM) [Only when in the Host mode] 1
- Target Configuration Access Ready (PCICSTAUTS.TCAR) [Only when in the Satellite mode] 1

Also, the on-chip PCI Bus Arbiter cannot be used when the PCI Boot mode is being used while in the Satellite mode.

10.3.14 Set Configuration Space

In Table 10.5.1, the values for the registers inside the PCI Configuration Space Register that have a gray background can be rewritten using one of the two following methods.

10.3.14.1 Set the Configuration Space Using EEPROM

Load values during Reset by connecting standard 93C46/93C48 EEPROM to a dedicated port.

The PCI Controller reads 16-bit half-word data for address $2n$ ($n: 0, 1, 2, \dots, 31$) of the PCI Configuration Space from EEPROM address $(2n + 2 - 4(n \bmod 2))$. Also, 16-bit data is read in order from the upper bits to the lower bits. The EEPROM values that correspond to the registers in Table 10.5.1 that have a white background are “don’t care”.

10.3.14.2 Set the Configuration Space Using Software Reset

By using the following procedure, it is possible to use the software to set the configuration space without using EEPROM.

- (1) Set the value to be loaded in the Configuration Data 0 Register (PCICDATA0), the Configuration Data 1 Register (PCICDATA1), the Configuration Data 2 Register (PCICDATA2), and the Configuration Data 3 Register (PCICDATA3).
- (2) Set the Load Configuration Data Register bit (LCFG) of the PCI Controller Configuration Register (PCICCFG) and the Software Reset bit (SRST).
- (3) Clear the Software Reset bit (PCICCFG.SRST) at least four PCI Bus clock cycles later. This starts loading the data.

After these processes are complete, please set the Target Configuration Access Ready bit (PCICCFG.TCAR) of the PCI Controller Configuration Register to be able to accept access to the PCI Configuration space.

10.3.15 PCI Clock

The PCI bus signals are synchronized by the PCI clock applied to the PCICLKIN pin. Therefore, in PCI clock output mode, the PCI output clock must be connected to the PCICLKIN pin.

10.4 PCI Controller Control Register

Table 10.4.1 lists the registers contained in the PCI Controller Control Register. Parentheses in the register names indicate the corresponding PCI Configuration Space Register.

Table 10.4.1 PCI Controller Control Register (1/2)

Section	Address	Size	Mnemonic	Register Name
10.4.1	0xD000	32	PCIID	ID Register (Device ID, Vendor ID)
10.4.2	0xD004	32	PCISTATUS	PCI Status, Command Register (Status, Command)
10.4.3	0xD008	32	PCICCREV	Class Code, Revision ID Register (Class Code, Revision ID)
10.4.4	0xD00C	32	PCICFG1	PCI Configuration 1 Register (BIST, Header Type, Latency Timer, Cache Line Size)
10.4.5	0xD010	32	P2GM0PLBASE	P2G Memory Space 0 PCI Lower Base Address Register (Base Address 0 Lower)
10.4.6	0xD014	32	P2GM0PUBASE	P2G Memory Space 0 PCI Upper Base Address Register (Base Address 0 Upper)
10.4.7	0xD018	32	P2GM1PLBASE	P2G Memory Space 1 PCI Lower Base Address Register (Base Address 1 Lower)
10.4.8	0xD01C	32	P2GM1PUBASE	P2G Memory Space 1 PCI Upper Base Address Register (Base Address 1 Upper)
10.4.9	0xD020	32	P2GM2PBASE	P2G Memory Space 2 PCI Base Address Register (Base Address 2)
10.4.10	0xD024	32	P2GIOPBASE	P2G I/O Space PCI Base Address Register (Base Address 3)
10.4.11	0xD02C	32	PCISID	Subsystem ID Register (Subsystem ID, Subsystem Vendor ID)
10.4.12	0xD034	32	PCICAPPTR	Capabilities Pointer Register (Capabilities Pointer)
10.4.13	0xD03C	32	PCICFG2	PCI Configuration 2 Register (Max_Lat, Min_Gnt, Interrupt Pin, Interrupt Line)
10.4.14	0xD040	32	G2PTCNT	G2P Timeout Count Register (Retry Timeout Value, TRDY Timeout Value)
10.4.15	0xD080	32	G2PSTATUS	G2P Status Register
10.4.16	0xD084	32	G2PMASK	G2P Interrupt Mask Register
10.4.17	0xD088	32	PCISSTATUS	Satellite Mode PCI Status Register (Status, PMCSR)
10.4.18	0xD08C	32	PCIMASK	PCI Status Interrupt Mask Register
10.4.19	0xD090	32	P2GCFG	P2G Configuration Register
10.4.20	0xD094	32	P2GSTATUS	P2G Status Register
10.4.21	0xD098	32	P2GMASK	P2G Interrupt Mask Register
10.4.22	0xD09C	32	P2GCCMD	P2G Current Command Register
10.4.23	0xD100	32	PBAREQPORT	PCI Bus Arbiter Request Port Register
10.4.24	0xD104	32	PBACFG	PCI Bus Arbiter Configuration Register
10.4.25	0xD108	32	PBASTATUS	PCI Bus Arbiter Status Register
10.4.26	0xD10C	32	PBAMASK	PCI Bus Arbiter Interrupt Mask Register
10.4.27	0xD110	32	PBABM	PCI Bus Arbiter Broken Master Register
10.4.28	0xD114	32	PBACREQ	PCI Bus Arbiter Current Request Register (for diagnostics)
10.4.29	0xD118	32	PBACGNT	PCI Bus Arbiter Current Grant Register (for diagnostics)
10.4.30	0xD11C	32	PBACSTATE	PCI Bus Arbiter Current State Register (for diagnostics)
10.4.31	0xD120	64	G2PM0GBASE	G2P Memory Space 0 G-Bus Base Address Register
10.4.32	0xD128	64	G2PM1GBASE	G2P Memory Space 1 G-Bus Base Address Register
10.4.33	0xD130	64	G2PM2GBASE	G2P Memory Space 2 G-Bus Base Address Register
10.4.34	0xD138	64	G2PIOGBASE	G2P I/O Space G-Bus Base Address Register
10.4.35	0xD140	32	G2PM0MASK	G2P Memory Space 0 Address Mask Register
10.4.36	0xD144	32	G2PM1MASK	G2P Memory Space 1 Address Mask Register
10.4.37	0xD148	32	G2PM2MASK	G2P Memory Space 2 Address Mask Register
10.4.38	0xD14C	32	G2PIOMASK	G2P I/O Space Address Mask Register
10.4.39	0xD150	64	G2PM0PBASE	G2P Memory Space 0 PCI Base Address Register
10.4.40	0xD158	64	G2PM1PBASE	G2P Memory Space 1 PCI Base Address Register

Table 10.4.1 PCI Controller Control Register (2/2)

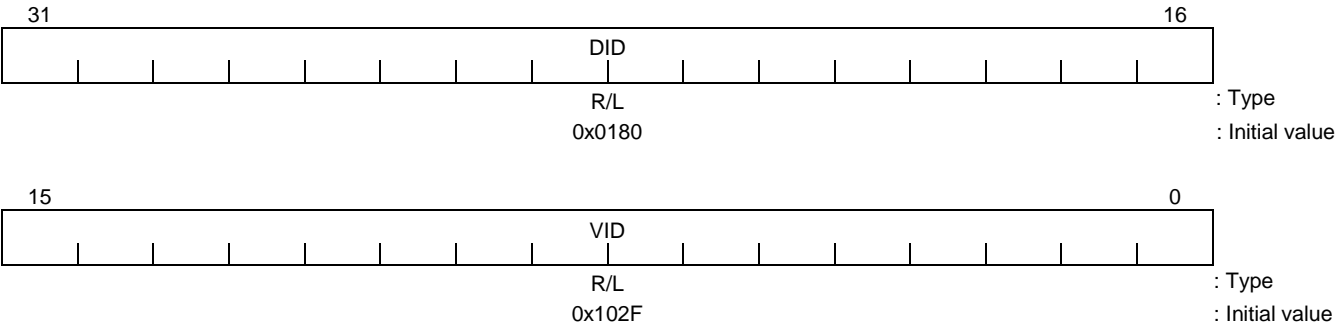
Section	Address	Size	Mnemonic	Register Name
10.4.41	0xD160	64	G2PM2PBASE	G2P Memory Space 2 PCI Base Address Register
10.4.42	0xD168	64	G2PIOPBASE	G2P I/O Space PCI Base Address Register
10.4.43	0xD170	32	PCICCFG	PCI Controller Configuration Register
10.4.44	0xD174	32	PCICSTATUS	PCI Controller Status Register
10.4.45	0xD178	32	PCICMASK	PCI Controller Interrupt Mask Register
10.4.46	0xD180	64	P2GM0GBASE	P2G Memory Space 0 G-Bus Base Address Register
10.4.47	0xD188	64	P2GM1GBASE	P2G Memory Space 1 G-Bus Base Address Register
10.4.48	0xD190	64	P2GM2GBASE	P2G Memory Space 2 G-Bus Base Address Register
10.4.49	0xD198	64	P2GIOGBASE	P2G I/O Space G-Bus Base Address Register
10.4.50	0xD1A0	32	G2PCFGADRS	G2P Configuration Address Register
10.4.51	0xD1A4	32	G2PCFGDATA	G2P Configuration Data Register
10.4.52	0xD1C8	32	G2PINTACK	G2P Interrupt Acknowledge Data Register
10.4.53	0xD1CC	32	G2PSPC	G2P Special Cycle Data Register
10.4.54	0xD1D0	32	PCICDATA0	Configuration Data 0 Register
10.4.55	0xD1D4	32	PCICDATA1	Configuration Data 1 Register
10.4.56	0xD1D8	32	PCICDATA2	Configuration Data 2 Register
10.4.57	0xD1DC	32	PCICDATA3	Configuration Data 3 Register
10.4.58	0xD200	64	PDMCA	PDMAC Chain Address Register
10.4.59	0xD208	64	PDMGA	PDMAC G-Bus Address Register
10.4.60	0xD210	64	PDMPA	PDMAC PCI Bus Address Register
10.4.61	0xD218	64	PDMCTR	PDMAC Count Register
10.4.62	0xD220	64	PDMCFG	PDMAC Configuration Register
10.4.63	0xD228	64	PDMSTATUS	PDMAC Status Register

10.4.1 ID Register (PCIID)

0xD000[HH5]

The Device ID field corresponds to the Device ID Register in the PCI Configuration Space, and the Vendor ID field corresponds to the Vendor ID register of the PCI Configuration Space.

This register cannot be access when in the Satellite mode.



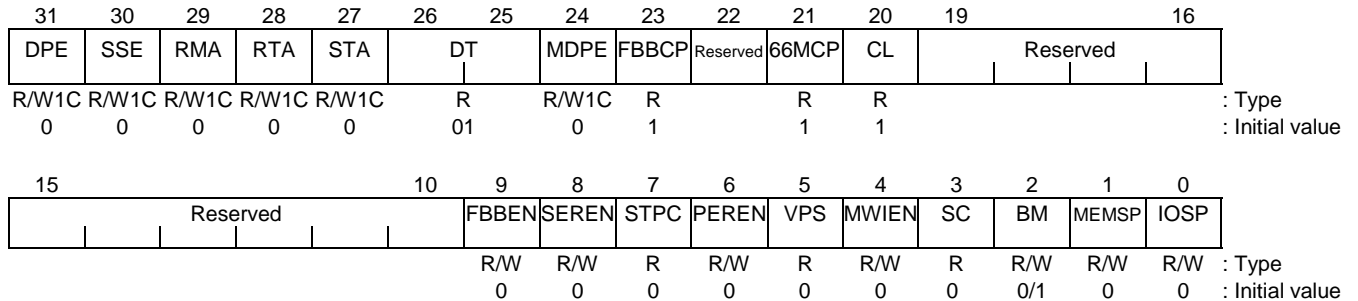
Bits	Mnemonic	Field Name	Description	Read/Write
31:16	DID	Device ID	Device ID (Default: 0x0180) This register indicates the ID that is allocated to a device. The ID can be changed by loading data from a configuration EEPROM during initialization.	R/L
15:0	VID	Vendor ID	Vendor ID (Default: 0x102F) This register indicates the device product that is allocated by PCI SIG. The product allocation can be changed by loading data from a configuration EEPROM during initialization.	R/L

Figure 10.4.1 ID Registers

10.4.2 PCI Status, Command Register (PCISTATUS) 0xD004

The upper 16 bits correspond to the Status Register in the PCI Configuration Space, and the lower 16 bits correspond to the Command Register in the PCI Configuration Space.

This register cannot be accessed when in the Satellite mode. However, it is possible to read some values of the upper 16 bits from the Satellite Mode PCI Status Register (PCISSTATUS).



Bit	Mnemonic	Field Name	Description	Read/Write
31	DPE	Detected Parity Error	Detected Parity Error (Default: 0) Indicates that a parity error was detected. A parity error is detected in the three following situations: <ul style="list-style-type: none"> Detected a data parity error as the Read command PCI initiator. Detected a data parity error as the Write command PCI target. Detected an address parity error. This bit is set regardless of the setting of the Parity Error Response bit (PCISTATUS.PEREN) of the PCI Status, Command Register. 1: Detected a parity error. 0: Did not detect a parity error.	R/W1C
30	SSE	Signaled System Error	Signaled System Error (Default: 0) Detects either an address parity error or a special cycle data parity error. This bit is set when the SERR* signal is asserted. 1: Asserted the SERR* signal 0: Did not assert the SERR* signal.	R/W1C
29	RMA	Received Master Abort	Received Master Abort (Default: 0) This bit is set when a Master Abort aborts a PCI Bus Transaction when the PCI Controller operates as the PCI initiator (except for special cycles). 1: Transaction was aborted by a Master Abort. 0: Transaction was not aborted by a Master Abort.	R/W1C
28	RTA	Received Target Abort	Received Target Abort (Default: 0) This bit is set when a Target Abort aborts a PCI Bus Transaction when the PCI Controller operates as the PCI initiator. 1: Transaction was aborted by a Target Abort. 0: Transaction was not aborted by a Target Abort.	R/W1C
27	STA	Signaled Target Abort	Signaled Target Abort (Default: 0) This bit is set when a Target Abort aborts a PCI Bus Transaction when the PCI Controller operates as the PCI target. 1: Bus transaction was aborted by a Target Abort. 0: Bus transaction was not aborted by a Target Abort.	R/W1C
26:25	DT	DEVSEL Timing	DEVSEL Timing (Fixed Value: 01) Three DEVSEL assert timings are defined in the PCI 2.2 Specifications: 00b = Fast; 01b = Medium; 10b = Slow; 11b = Reserved). With the exception of Read Configuration and Write Configuration, when the PCI Controller is the PCI target, the DEVSEL signal is asserted to a certain bus command and indicates the slowest speed for responding to the PCI Bus Master.	R

Figure 10.4.2 PCI Status, Command Register (1/2)

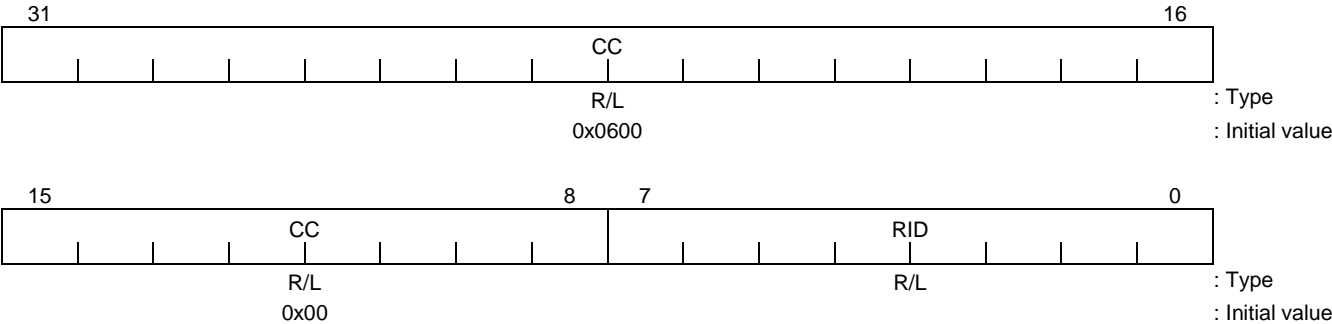
Bit	Mnemonic	Field Name	Description	Read/Write
24	MDPE	Master Data Parity Error	Master Data Parity Error (Default: 0) Indicates the a parity error occurred when the PCI Controller is the PCI initiator. This bit is not set when the PCI Controller is the target. This bit is set when all of the three following conditions are met. <ul style="list-style-type: none"> It has been detected that the PERR* signal was set either directly or indirectly. The PCI Controller is the Bus Master for a PCI Bus transaction during which an error occurred. The Parity Error Response bit of the PCI Status Command Register (PCISTATUS.PEREN) has been set. 	R/W1C
23	FBBCP	Fast Back-to-Back Capable	Fast Back-to-Back Capable (Fixed Value: 1) Indicates whether target access of a fast back-to-back transaction can be accepted. Is fixed to "1".	R
22		Reserved		—
21	66MCP	66 MHz Capable	66 MHz Capable (Fixed Value: 1) Indicates the 66 MHz operation is possible. Is fixed to "1".	R
20	CL	Capabilities List	Capabilities List (Fixed Value: 1) Indicates that the capabilities list is being implemented. Is fixed to "1".	R
19:10		Reserved		—
9	FB BEN	Fast Back-to-Back Enable	Fast Back-to-Back Enable (Default: 0) Indicates that issuing of fast back-to-back transactions has been enabled. 1: Enable 0: Disable	R/W
8	SEREN	SERR* Enable	SERR* Enable (Default: 0) Enables/Disables the SERR* signal. The SERR* signal reports that either a PCI Bus address parity error or a special cycle data parity error was detected. The SERR* signal is only asserted when the Parity Error Response bit is set and this bit is set. 1: Enable 0: Disable	R/W
7	STPC	Stepping Control	Stepping Control (Fixed Value: 0) Indicates that stepping control is not being supported.	R
6	PEREN	Parity Error Response	Parity Error Response (Default 0) Sets operation when a PCI address/data parity error is detected. A parity error response (either when the Parity Error Response bit (PCISTATUS.PEREN) of the PERR* Signal Assert or PCI Status, Command Register is set, or the SERR* signal is asserted) is performed only when this bit is set. When this bit is cleared, the PCI Controller ignores all parity errors and continues the transaction process as if the parity of that transaction was correct. 1: Parity error response is performed. 0: Parity error response is not performed.	R/W
5	VPS	VGA Palette Snoop	VGA Palette Snoop (Fixed Value: 0) Indicates that the VGA palette snoop function is not supported.	R
4	MWIEN	Memory Write and Invalidate Enable	Memory Write and Invalidate Enable (Default: 0) Controls whether to use the Memory Write and Invalidate command instead of the Memory Write command when the PCI Controller is the initiator.	R/W
3	SC	Special Cycles	Special Cycles (Fixed Value: 0) Indicates that special cycles will not be accepted as PCI targets.	R
2	BM	Bus Master	Bus Master (Default: 0/1) The default is only "1" when in the PCI Boot mode and in the Host mode. 1: Operates as the Bus Master. 0: Does not operate as the Bus Master.	R/W
1	MEMSP	Memory Space	Memory Space (Default: 0) 1: Respond to PCI memory access. 0: Do not respond to PCI memory access.	R/W
0	IOSP	I/O Space	I/O Space (Default: 0) 1: Respond to PCI I/O access. 0: Do not respond to PCI I/O access.	R/W

Figure 10.4.2 PCI Status, Command Register (2/2)

10.4.3 Class Code, Revision ID Register (PCICCREV) 0xD008

The Class Code field corresponds to the Class Code Register of the PCI Configuration Space, and the Revision ID field corresponds to the Revision ID Register of the PCI Configuration Space.

This register cannot be accessed when in the Satellite mode.



Bits	Mnemonic	Field Name	Description	Read/Write
31:8	CC	Class Code	Class Code (Default: 0x060000) Classifies the device types. The default is 060000h, which defines the PCI Controller as a Host bridge device. It is possible to change the device type by loading data from Configuration EEPROM during initialization.	R/L
7:0	RID	Revision ID	Revision ID Indicates the device revision ID. Please contact our Engineering Department for the exact value. It is possible to change the revision ID by loading data from Configuration EEPROM during initialization.	R/L

Figure 10.4.3 Class Code, Revision ID Register

10.4.4 PCI Configuration 1 Register (PCICFG1) 0xD00C

The following fields correspond to the following registers.

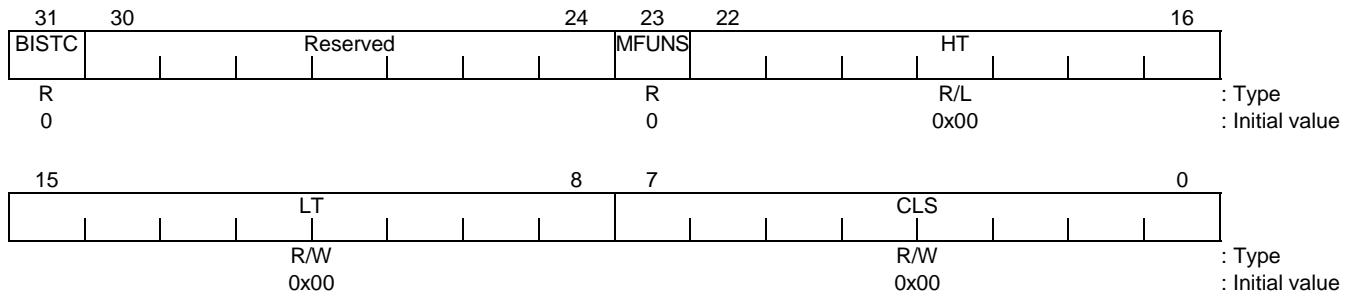
BIST field → BIST Register of the PCI Configuration Space

Header Type field → Header Type Register in the PCI Configuration Space

Latency Timer field → Latency Timer Register of the PCI Configuration Space

Cache Line Size field → Cache Line Size Register of the PCI Configuration Space.

This register cannot be accessed when the PCI Controller is in the Satellite mode.



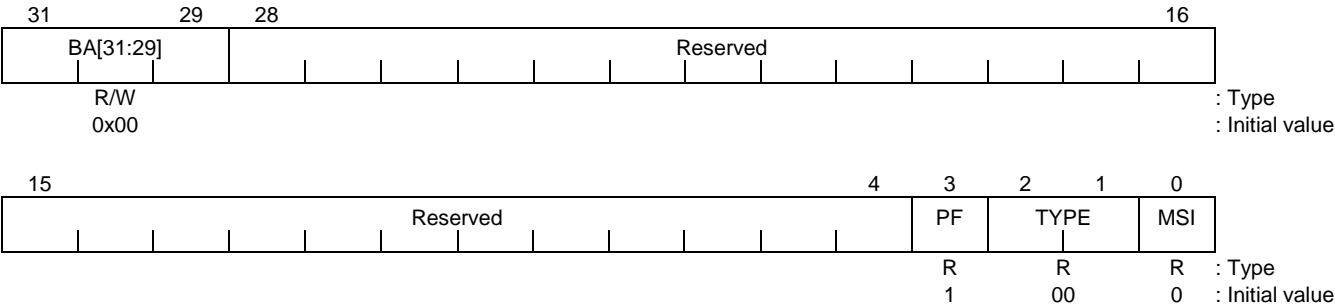
Bit	Mnemonic	Field Name	Description	Read/Write
31	BISTC	BIST Capable	BIST Capable (Fixed Value: 0) Indicates that the BIST function is not being supported.	R
30:24		Reserved		—
23	MFUNS	Multi-Function	Multi-Function (Fixed Value: 0) 0: Indicates that the device is a single-function device.	R
22:16	HT	Header Type	Header Type (Default: 0x00) Indicates the Header type. 0000000: Header Type 0 It is possible to change the header type by loading data from Configuration EEPROM during initialization.	R/L
15:8	LT	Latency Timer	Latency Timer (Default: 0x00) Sets the latency timer value. Specifies the PCI Bus clock count during which to abort access when the GNT* signal is deasserted during PCI access. Since the lower two bits are fixed to "0", cycle counts can only be specified in multiples of 4.	R/W
7:0	CLS	Cache Line Size	Cache Line Size (Default: 0x00) Is used to select the PCI Bus command during a Burst Read transaction. See "10.3.3 Supported PCI Bus Commands)" for more information.	R/W

Figure 10.4.4 PCI Configuration 1 Register

10.4.5 P2G Memory Space 0 PCI Lower Base Address Register (P2GM0PLBASE) 0xD010

This register corresponds to the Memory Space 0 Lower Base Address Register at offset address 0x10 of the PCI Configuration Space.

This register cannot be accessed when the PCI Controller is in the Satellite mode.



Bit	Mnemonic	Field Name	Description	Read/Write
31:29	BA[31:29]	Base Address	Base Address (Default: 0x00) Sets the lower address of the PCI base address in Target Access Memory Space 0. The size of Memory Space 0 is fixed at 512 MB.	R/W
28:4		Reserved		—
3	PF	Prefetchable	Prefetchable (Fixed Value: 1) 1: Indicates that memory is prefetchable.	R
2:1	TYPE	Type	Type (Default: 00) 00: Indicates that an address is within a 32-bit address region.	R
0	MSI	Memory Space	Memory Space Indicator (Fixed Value: 0) 0: Indicates that this Base Address Register is for use by the PCI Memory Space.	R

Figure 10.4.5 P2G Memory Space 0 PCI Lower Base Address Register

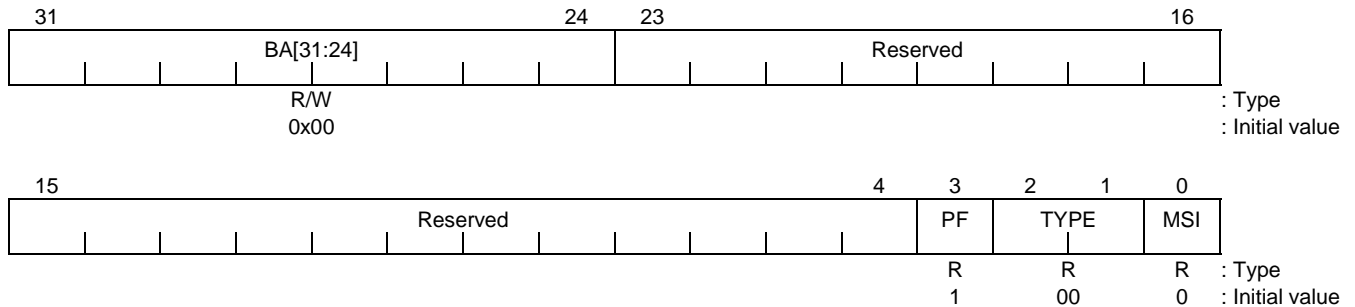
10.4.6 P2G Memory Space 0 PCI Upper Base Address Register (P2GM0PUBASE) 0xD014

This register is unused since the PCI Controller does not support the target dual-address cycle. It is forbidden to write to this register.

10.4.7 P2G Memory Space 1 PCI Lower Base Address Register (P2GM1PLBASE) 0xD018

This register corresponds to the Memory Space 1 Lower Base Address Register at offset address 0x18 of the PCI Configuration Space.

This register cannot be accessed when the PCI Controller is in the Satellite mode.



Bit	Mnemonic	Field Name	Description	Read/Write
31:24	BA[31:24]	Base Address	Base Address (Default: 0x00) Sets the lower address of the PCI base address in Target Access Memory Space 1. The size of Memory Space 1 is fixed at 16 MB.	R/W
23:4		Reserved		—
3	PF	Prefetchable	Prefetchable (Fixed Value: 1) 1: Indicates that memory is prefetchable.	R
2:1	TYPE	Type	Memory Type (Default: 00) 00: Indicates that memory is placed in the 32-bit address space.	R
0	MSI	Memory Space	Memory Space Indicator (Fixed Value: 0) 0: Indicates that this Base Address Register is for use by the PCI Memory Space.	R

Figure 10.4.6 P2G Memory Space 1 PCI Lower Base Address Register

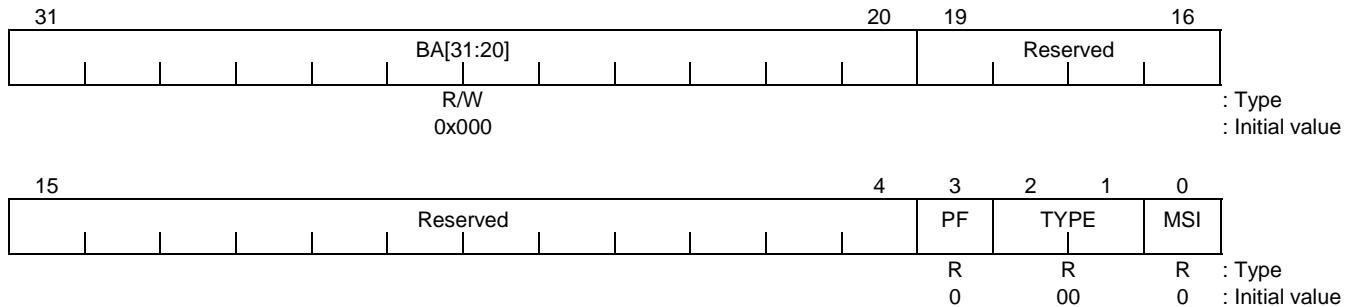
10.4.8 P2G Memory Space 1 PCI Upper Base Address Register (P2GM1PUBASE) 0xD01C

This register is unused since the PCI Controller does not support the target dual-address cycle. It is forbidden to write to this register.

10.4.9 P2G Memory Space 2 PCI Base Address Register (P2GM2PBASE) 0xD020

This register corresponds to the Memory Space 2 Base Address Register at offset address 0x20 of the PCI Configuration Space.

This register cannot be accessed when the PCI Controller is in the Satellite mode.



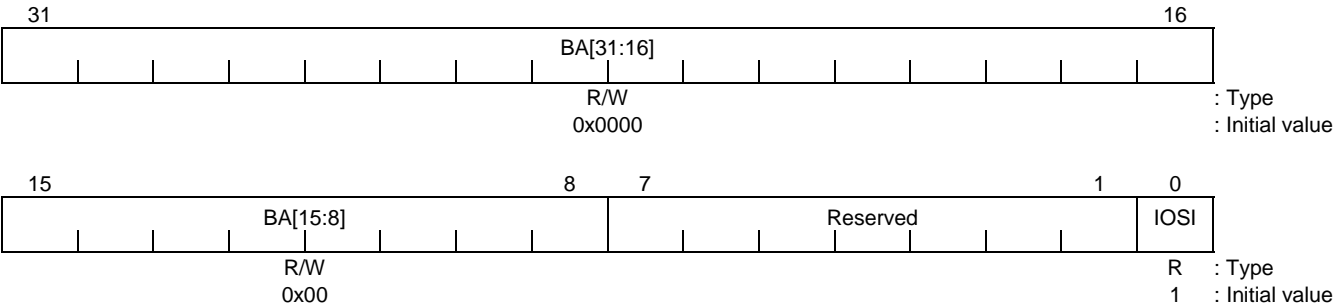
Bit	Mnemonic	Field Name	Description	Read/Write
31:20	BA[31:20]	Base Address	Base Address (Default: 0x00) Sets the PCI base address in Target Access Memory Space 2. The size of Memory Space 12 is fixed at 1 MB.	R/W
19:4		Reserved		—
3	PF	Prefetchable	Prefetchable (Fixed Value: 0) 0: Indicates that memory is not prefetchable.	R
2:1	TYPE	Type	Memory Type (Default: 00) 00: Indicates that an address is within a 32-bit address region.	R
0	MSI	Memory Space	Memory Space Indicator (Fixed Value: 0) 0: Indicates that this Base Address Register is for use by the PCI Memory Space.	R

Figure 10.4.7 P2G Memory Space 2 PCI Base Address Register

10.4.10 P2G I/O Space PCI Base Address Register (P2GIOPBASE) 0xD024

This register corresponds to the I/O Space Base Address at offset address 0x24 of the PCI Configuration Space.

This register cannot be accessed when the PCI Controller is in the Satellite mode.



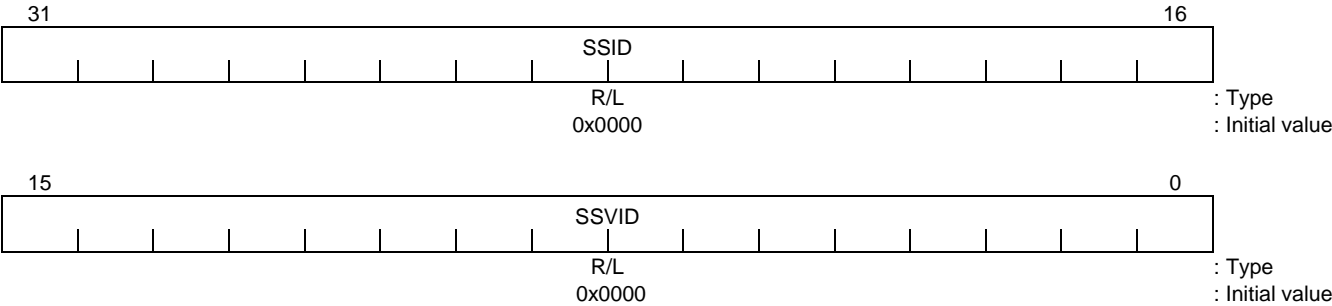
Bit	Mnemonic	Field Name	Description	Read/Write
31:8	BA[31:8]	Base Address	Base Address (Default: 0x00) Sets the PCI base address of the Target Access I/O Space. The size of this I/O space is fixed at 256 Bytes.	R/W
7:1		Reserved		—
0	IOSI	I/O Space	I/O Space Indicator (Fixed Value: 1) 1: Indicates that this Base Address Register is for use by the PCI I/O Space.	R

Figure 10.4.8 P2G I/O Space PCI Base Address Register

10.4.11 Subsystem ID Register (PCISID) 0xD02C

The Subsystem ID field corresponds to the Subsystem ID Register of the PCI Configuration Space, and the Subsystem Vendor ID field corresponds to the Subsystem Vendor ID Register of the PCI Configuration Space.

This register cannot be accessed when the PCI Controller is in the Satellite mode.



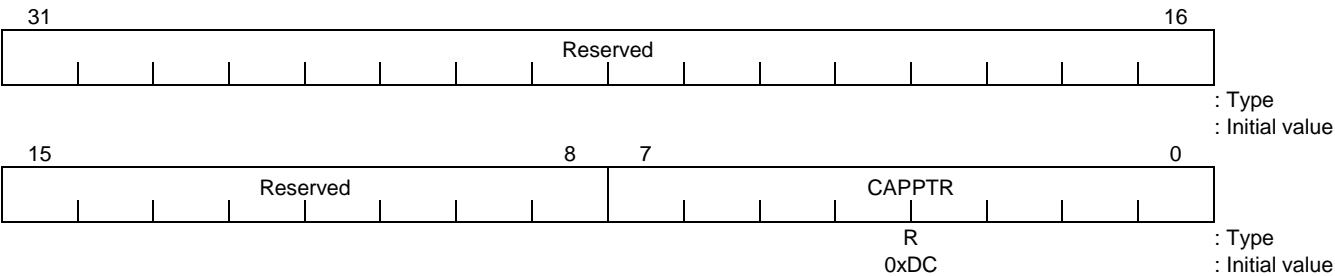
Bits	Mnemonic	Field Name	Description	Read/Write
31:16	SSID	Subsystem ID	Subsystem ID (Default: 0x0000) This register is used to acknowledge either a subsystem that has a PCI device or an add-in board. It is possible to change the Subsystem ID by loading data from Configuration EEPROM during initialization.	R/L
15:0	SSVID	Subsystem Vendor ID	Subsystem Vendor ID (Default: 0x0000) This register is used to acknowledge either a subsystem that has a PCI device or an add-in board. It is possible to change the Subsystem ID by loading data from Configuration EEPROM during initialization.	R/L

Figure 10.4.9 Subsystem ID Register

10.4.12 Capabilities Pointer Register (PCICAPPTR) 0xD034

The Capabilities Pointer field corresponds to the Capabilities Pointer Register of the PCI Configuration Space.

This register cannot be accessed when the PCI Controller is in the Satellite mode.



Bits	Mnemonic	Field Name	Description	Read/Write
31:8		Reserved		—
7:0	CAPPTR	Capabilities Pointer	Capabilities Pointer (Fixed Value: 0xDC) Indicates as an offset value the starting address of the capabilities list that indicates extended functions.	R

Figure 10.4.10 Capabilities Pointer Register

10.4.13 PCI Configuration 2 Register (PCICFG2) 0xD03C

The following fields correspond to the following registers:

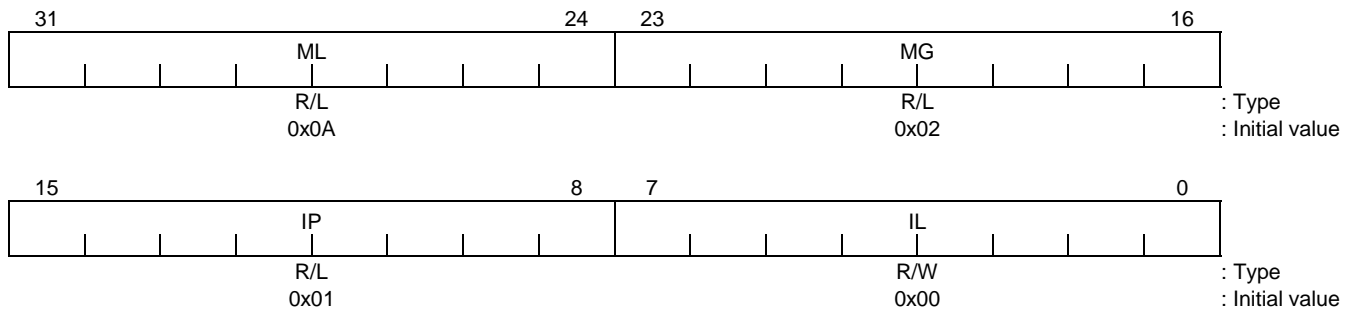
Max. Latency field → Max_Lat Register of the PCI Configuration Space

Min. Grant field → Min_Gnt Register of the PCI Configuration Space

Interrupt Pin field → Interrupt Pin Register of the PCI Configuration Space

Interrupt Line field → Interrupt Line Register of the PCI Configuration Space

This register cannot be accessed when the PCI Controller is in the Satellite mode.



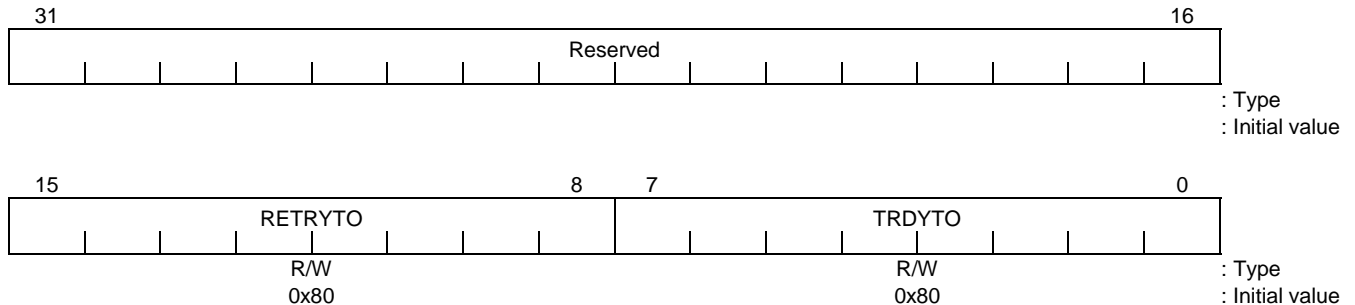
Bits	Mnemonic	Field Name	Description	Read/Write
31:24	ML	Maximum Latency	Max_Lat (Maximum Latency) (Default: 0x0A) 00h: Does not use this register to determine PCI Bus priority. 01h-FFh: Specifies the time interval for requesting bus ownership. In units of 250 ns, assuming the PCICLK is 33 MHz. It is possible to change the maximum latency by loading data from Configuration EEPROM during initialization.	R/L
23:16	MG	Minimum Grant	Min_Gnt (Minimum Grant) (Default: 0x02) 00h: Is not used to calculate the latency timer value. 01h-FFh: Sets the time required for Burst transfer. In units of 250 ns, assuming the PCICLK is 33 MHz. It is possible to change this value by loading data from Configuration EEPROM during initialization.	R/L
15:8	IP	Interrupt Pin	Interrupt Pin (Default: 0x01) Valid values: 00 - 04h 00h: Do not use interrupt signals. 01h: Use Interrupt signal INTA* 02h: Use Interrupt signal INTB* 03h: Use Interrupt signal INTC* 04h: Use Interrupt signal INTD* 05h - FFh: Reserved It is possible to change this value by loading data from Configuration EEPROM during initialization. When using either the REQ[2]* signal or the PIO signal to report an interrupt to an external device as the PCI device, please use EEPROM to set the connection with that device.	R/L
7:0	IL	Interrupt Line	Interrupt Line (Default: 0x00) This is a readable/writable 8-bit register. The software uses this register to indicate information such as the interrupt signal connection information. Operation of the TX4927 is not affected.	R/W

Figure 10.4.11 PCI Configuration 2 Register

10.4.14 G2P Timeout Count Register (G2PTOCNT) 0xD040

The Retry Timeout field corresponds to the Retry Timeout Value Register of the PCI Configuration Space, and the TRDY Timeout field corresponds to the TRDY Timeout Value Register of the PCI Configuration Space.

This register cannot be accessed when the PCI Controller is in the Satellite mode.

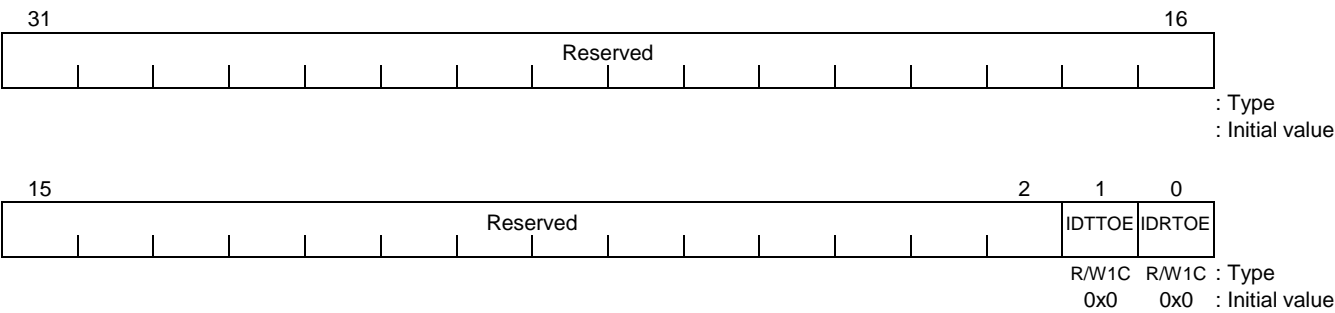


Bits	Mnemonic	Field Name	Description	Read/Write
31:16		Reserved		—
15:8	RETRYTO	Retry Timeout	Retry Time Out (Default: 0x80) Sets the maximum number of retries to accept when operating as the initiator on the PCI Bus. Ends with an error when receiving more retry terminations than the set maximum number. Setting a "0" disables this timeout function. Note: Generally, disable retry time-out detection by setting this field to zero. Some PCI devices invoke more than 128 retries at normal times.	R/W
7:0	TRDYTO	TRDY Timeout	TRDY Time Out (Default: 0x80) Sets the maximum value of the time to wait for assertion of the TRDY* signal when operating as the initiator on the PCI Bus. Setting a "0" disables this timeout function. Note: Generally, disable TRDY time-out detection by setting this field to zero. Some PCI devices exhibit a TRDY delay longer than 128 PCI clocks at normal times.	R/W

Figure 10.4.12 G2P Timeout Count Register

10.4.15 G2P Status Register (G2PSTATUS)

0xD080



Bit	Mnemonic	Field Name	Description	Read/Write
31:2		Reserved		—
1	IDTTOE	TRDY Timeout Error	Initiator Detected TRDY Time Out Error (Default: 0x0) This bit is set when the initiator detects a TRDY timeout.	R/W1C
0	IDRTOE	Retry Timeout Error	Initiator Detected Retry Time Out Error (Default: 0x0) This bit is set when the initiator detects a Retry timeout.	R/W1C

Figure 10.4.13 G2P Status Register

10.4.16 G2P Interrupt Mask Register (G2PMASK) 0xD084

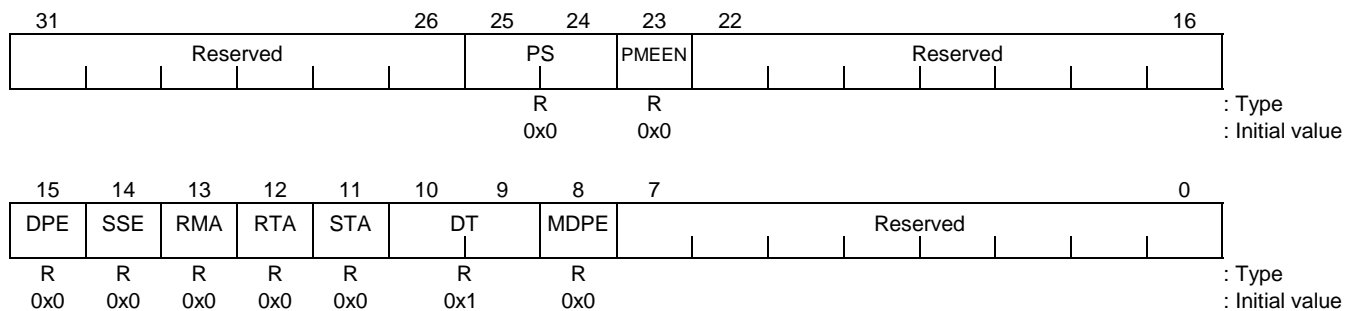


Bit	Mnemonic	Field Name	Description	Read/Write
31:2		Reserved		—
1	IDTTOEIE	TRDY Timeout Error Interrupt Enable	Initiator Detected TRDY Time Out Interrupt Enable (Default: 0x0) The initiator generates an interrupt when it detects a TRDY timeout. 1: Generates an interrupt. 0: Does not generate an interrupt.	R/W
0	IDRTOEIE	Retry Timeout Error Interrupt Enable	Initiator Detected Retry Time Out Interrupt Enable (Default: 0x0) The initiator generates an interrupt when it detects a Retry timeout. 1: Generates an interrupt. 0: Does not generate an interrupt.	R/W

Figure 10.4.14 G2P Interrupt Mask Register

10.4.17 Satellite Mode PCI Status Register (PCISSTATUS) 0xD088

The PCI Status, Command Register (PCISTATUS) or the PMCSR Register of the Configuration Space cannot be accessed when the PCI Controller is in the Satellite mode. It is possible however to read values from either of these registers.



Bit	Mnemonic	Field Name	Description	Read/Write
31:24		Reserved		—
25:24	PS	Power State	PowerState (Default: 0x0) This is a shadow register of the PowerState field in the PMCSR Register.	R
23	PMEEN	PME Enable	PME_En (Default: 0x0) This is a shadow register of the PME_En bit of the PMCSR Register.	R
22:16		Reserved		—
15	DPE	Detected Parity Error	Detected Parity Error (Default: 0x0) This is a shadow register of the PCISTATUS.DPE bit.	R
14	SSE	Signaled System Error	Signaled System Error (Default: 0x0) This is a shadow register of the PCISTATUS.SSE bit.	R
13	RMA	Received Master Abort	Received Master Abort (Default: 0x0) This is a shadow register of the PCISTATUS.RMA bit.	R
12	RTA	Received Target Abort	Received Target Abort (Default: 0x0) This is a shadow register of the PCISTATUS.RTA bit.	R
11	STA	Signaled Target Abort	Signaled Target Abort (Default: 0x0) This is a shadow register of the PCISTATUS.STA bit.	R
10:9	DT	Set DEVSEL Timing	DEVSEL Timing (Fixed Value: 0x1) This is a shadow register of the PCISTATUS.DT field.	R
8	MDPE	Data Parity Detected	Master Data Parity Error Detected (Default: 0x0) This is a shadow register of the PCISTATUS.MDPE bit.	R
7:0		Reserved		—

Figure 10.4.15 Satellite Mode PCI Status Register

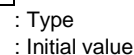
10.4.18 PCI Status Interrupt Mask Register (PCIMASK) 0xD08C



Bit	Mnemonic	Field Name	Description	Read/Write
31:16		Reserved		—
15	DPEIE	Detected Parity Error Interrupt Enable	Detected Parity Error Interrupt Enable (Default: 0x0) Generates an interrupt when a parity error is detected. Usually, this interrupt is masked and a Master Data Parity error signals the error to the system. 1: Generates an interrupt. 0: Does not generate an interrupt.	R/W
14	SSEIE	Signaled System Error Interrupt Enable	Signaled System Error Interrupt Enable (Default: 0x0) Generates an interrupt when a system error is signaled. 1: Generates an interrupt. 0: Does not generate an interrupt.	R/W
13	RMAIE	Received Master Abort Interrupt Enable	Received Master Abort Interrupt Enable (Default: 0x0) Generates an interrupt when a Master Abort is received. 1: Generates an interrupt. 0: Does not generate an interrupt.	R/W
12	RTAIE	Received Target Abort Interrupt Enable	Received Target Abort Interrupt Enable (Default: 0x0) Generates an interrupt when a Target Abort is received. 1: Generates an interrupt. 0: Does not generate an interrupt.	R/W
11	STAIE	Signaled Target Abort Interrupt Enable	Signaled Target Abort Interrupt Enable (Default: 0x0) Generates an interrupt when a Target Abort is signaled. 1: Generates an interrupt. 0: Does not generate an interrupt.	R/W
13	RMA	Received Master Abort	Received Master Abort (Default: 0x0) This is a shadow register of the PCISTATUS.RMA bit.	R/W
12	RTA	Received Target Abort	Received Target Abort (Default: 0x0) This is a shadow register of the PCISTATUS.RTA bit.	R/W
11	STA	Signaled Target Abort	Signaled Target Abort (Default: 0x0) This is a shadow register of the PCISTATUS.STA bit.	R/W
10:9		Reserved		—
8	MDPEIE	Master Data Parity Detected Interrupt Enable	Master Data Parity Detected Interrupt Enable (Default: 0x0) Generates an interrupt when data parity is detected. 1: Generates an interrupt. 0: Does not generate an interrupt.	R/W
7:0		Reserved		—

Figure 10.4.16 PCI Status Interrupt Mask Register

0xD090



- : Type
- : Initial value

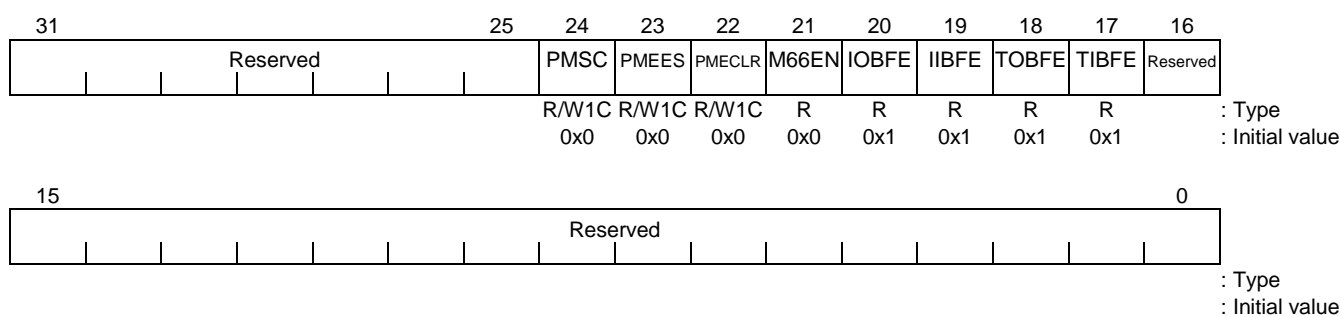
Figure 10.4.17 P2G Configuration Register (1/2)

Bit	Mnemonic	Field Name	Description	Read/Write
11	MEM1PD	Memory 1 Window Prefetch Disable	Memory 1 Window Prefetch Disable (Default: 0x0) Prefetching during a G-Bus Burst Read transfer cycle to the Memory 1 Space is disabled when this bit is set to "1". PCI Burst Read transactions are not supported when prefetching is disabled. Even if the setting of this bit is changed, prefetchable bits in the Base Address Register of the PCI Configuration Space will not reflect this change. We recommend using the default setting when the PCI Controller is in the Satellite mode.	R/W
10	MEM2PD	Memory 2 Window Space Prefetch Disable	Memory 2 Window Prefetch Disable (Default: 0x1) Prefetching during a G-Bus Burst Read transfer cycle to the Memory 2 Space is disabled when this bit is set to "1". PCI Burst Read transactions are not supported when prefetching is disabled. Even if the setting of this bit is changed, prefetchable bits in the Base Address Register of the PCI Configuration Space will not reflect this change. We recommend using the default setting when the PCI Controller is in the Satellite mode.	R/W
9	TOBFR	Target Out-Bound FIFO Reset	Target Out-Bound FIFO Reset (Default: 0x0) The PCI Controller flushes the CORE internal Target Out-Bound FIFO when "1" is written to this bit. This bit always reads out "0" when it is read. This is a diagnostic function.	R/W
8	TIBFR	Target In-Bound FIFO Reset	Target In-Bound FIFO Reset (Default: 0x0) The PCI Controller flushes the CORE internal Target In-Bound FIFO when "1" is written to this bit. This bit always read out "0" when it is read. This is a diagnostic function.	R/W
7:0		Reserved		—

Figure 10.4.17 P2G Configuration Register (2/2)

10.4.20 P2G Status Register (P2GSTATUS)

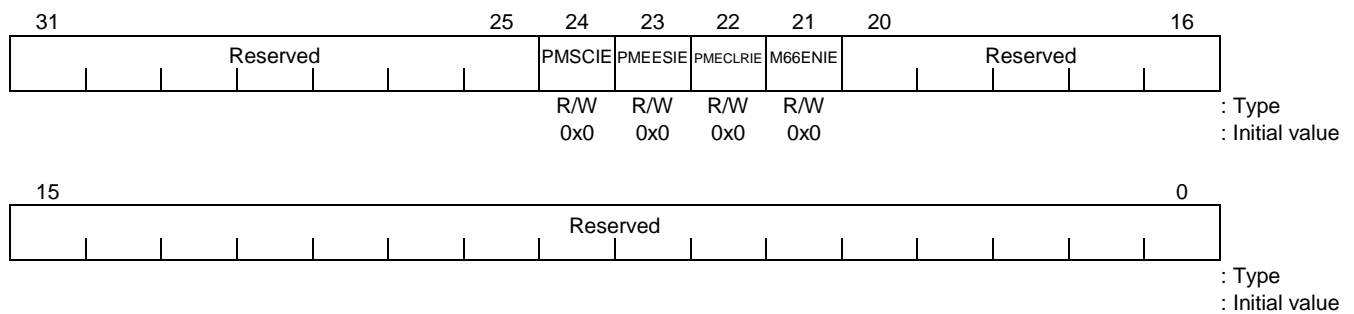
0xD094



Bit	Mnemonic	Field Name	Description	Read/Write
31:25		Reserved		—
24	PMSC	PM State Change Detected	Power Management State Change (Default: 0x0) “1” is set to this bit when the PowerState field of the Power Management Register (PMCSR) is rewritten. This bit is cleared to “0” when a “1” is written to it. This bit is only valid when the PCI Controller is in the Satellite mode.	R/W1C
23	PMEES	PME_En Set Detected	PME_En Set (Default: 0x0) This bit is set to “1” when the PME_En bit of the PMCSR Register is set to “1”. When this bit is set, it indicates that the PCI Master (Host) device enabled PME* signal output. 1: Indicates that the PME_En bit is set. 0: Indicates that the PME_En bit is not set. This bit is cleared to “0” when a “1” is written to it. This bit is only valid when the PCI Controller is in the Satellite mode.	R/W1C
22	PMECLR	PME Status Clear Detected	PME_Status Clear (Default: 0x0) This bit indicates that the PME_Status bit of the PMCSR Register was cleared. 1: Indicates that the PME_Status bit was cleared. 0: Indicates that the PME_Status bit was not cleared. This bit is cleared to “0” when a “1” is written to it. This bit is only valid when the PCI Controller is in the Satellite mode.	R/W1C
21	M66EN	66 MHz Drive Status	M66EN Status (Default: 0x0) This bit indicates the current status of the M66EN signal. This bit can only be read. Writes to this bit are invalid. 1: The M66EN signal is asserted. 0: The M66EN signal is deasserted.	R
20	IOBFE	Initiator Out-Bound FIFO Empty	Initiator Out-Bound FIFO Empty (Default: 0x1) 1: Indicates that the Initiator Out-Bound FIFO is empty. 0: Indicates that the Initiator Out-Bound FIFO is not empty. This is a diagnostic function.	R
19	IIBFE	Initiator In-Bound FIFO Empty	Initiator In-Bound FIFO Empty (Default: 0x1) 1: Indicates that the Initiator In-Bound FIFO is empty. 0: Indicates that the Initiator In-Bound FIFO is not empty. This is a diagnostic function.	R
18	TOBFE	Target Out-Bound FIFO Empty	Target Out-Bound FIFO Empty (Default: 0x1) 1: Indicates that the Target Out-Bound FIFO is empty. 0: Indicates that the Target Out-Bound FIFO is not empty. This is a diagnostic function.	R
17	TIBFE	Target In-Bound FIFO Empty	Target In-Bound FIFO Empty (Default: 0x1) 1: Indicates that the Target In-Bound FIFO is empty. 0: Indicates that the Target In-Bound FIFO is not empty. This is a diagnostic function.	R
16:0		Reserved		—

Figure 10.4.18 P2G Status Register

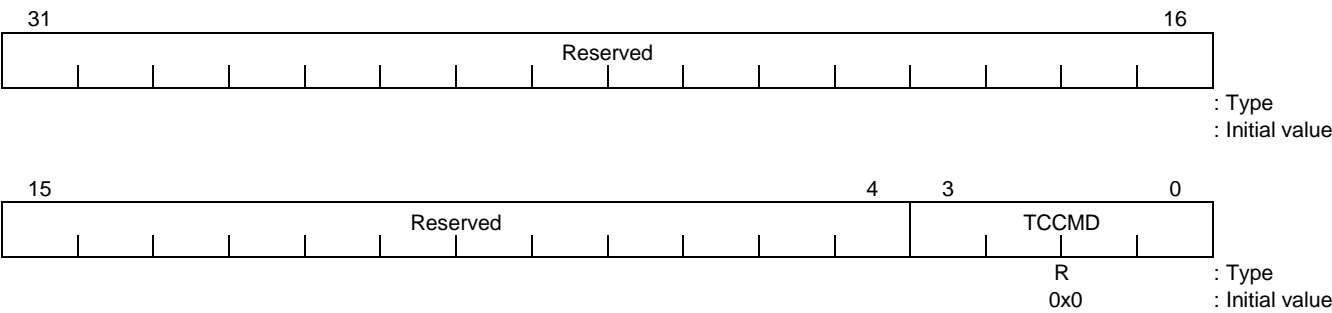
10.4.21 P2G Interrupt Mask Register (P2GMASK) 0xD098



Bit	Mnemonic	Field Name	Description	Read/Write
31:25		Reserved		—
24	PMSCIE	Power Management State Change Interrupt Enable	Power Management State Change Interrupt Enable (Default: 0x0) Generates an interrupt when the PowerState field of the Power Management Register (PMCSR) is rewritten. 1: Generates an interrupt. 0: Does not generate an interrupt.	R/W
23	PMEESIE	PME_En Set Interrupt Enable	PME_En Set Interrupt Enable (Default: 0x0) Generates an interrupt when the PME_En bit of the PMCSR Register is set. 1: Generates an interrupt. 0: Does not generate an interrupt.	R/W
22	PMECLRIE	PME Status Clear Interrupt Enable	PME_Status Clear Interrupt Enable (Default: 0x0) Generates an interrupt when the PME_Status bit of the PMCSR Register is cleared. 1: Generates an interrupt. 0: Does not generate an interrupt.	R/W
21	M66ENIE	66 MHz Drive Interrupt Enable	M66EN Detected Interrupt Enable (Default: 0x0) Generates an M66EN interrupt when the PCI Controller is in the Satellite mode. Note: This bit must be masked in order to clear an M66EN interrupt since the M66EN bit of the P2GSTATUS Register itself cannot be cleared. When the PCI Controller is in the Host mode, M66EN interrupts are invalid and will not be signaled even if this bit is set to "1". 1: Generates an interrupt. 0: Does not generate an interrupt.	R/W
20:0		Reserved		—

Figure 10.4.19 P2G Interrupt Mask Register

10.4.22 P2G Current Command Register (P2GCCMD) 0xD09C



Bits	Mnemonic	Field Name	Description	Read/Write
31:4		Reserved		—
3:0	TCCMD	Target Current Command Register	Target Current Command (Default: 0x0) Indicates the PCI command within the target access process that is currently in progress. This is a diagnostic function.	R

Figure 10.4.20 P2G Current Command Register

Diagram illustrating the Register File (RF) structure, showing 32 registers (0-31) organized into two 16-bit halves. Each register is 32 bits wide and is divided into four 8-bit fields: ReqAP, ReqBP, ReqCP, and ReqDP for the top half, and ReqWP, ReqXP, ReqYP, and ReqZP for the bottom half. The Req fields are labeled with their respective register numbers (e.g., ReqAP, ReqBP, ReqCP, ReqDP, ReqWP, ReqXP, ReqYP, ReqZP). The Req fields are labeled with their respective register numbers (e.g., ReqAP, ReqBP, ReqCP, ReqDP, ReqWP, ReqXP, ReqYP, ReqZP). The Req fields are labeled with their respective register numbers (e.g., ReqAP, ReqBP, ReqCP, ReqDP, ReqWP, ReqXP, ReqYP, ReqZP).

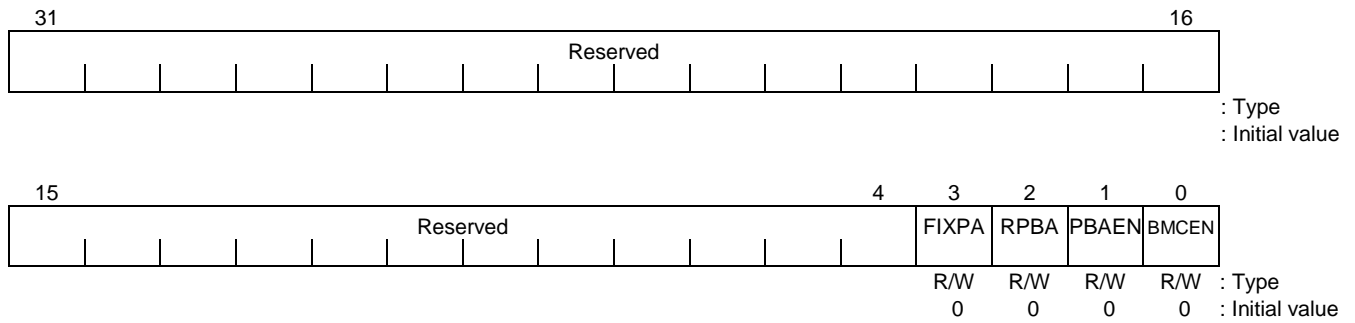
Figure 10.4.21 PCI Bus Arbiter Request Port Register (1/2)

Bit	Mnemonic	Field Name	Description	Read/Write
19		Reserved		—
18:16	ReqDP	Request D Port	Request D Port (Default: 100) Sets the PCI Bus Master that connects to the Internal PCI Bus Arbiter Request D Port (Master D). 111: Makes the PCI Controller Master D. 110: Reserved 101: Reserved 100: Reserved 011: Makes REQ*[3] Master D. 010: Makes REQ*[2] Master D. 001: Makes REQ*[1] Master D. 000: Makes REQ*[0] Master D.	R/W
15		Reserved		—
14:12	ReqWP	Request W Port	Request W Port (Default: 011) Sets the PCI Bus Master that connects to the Internal PCI Bus Arbiter Request W Port (Master W). 111: Makes the PCI Controller Master W. 110: Reserved 101: Reserved 100: Reserved 011: Makes REQ*[3] Master W. 010: Makes REQ*[2] Master W. 001: Makes REQ*[1] Master W. 000: Makes REQ*[0] Master W.	R/W
11		Reserved		—
10:8	ReqXP	Request X Port	Request X Port (Default: 010) Sets the PCI Bus Master that connects to the Internal PCI Bus Arbiter Request X Port (Port X). 111: Makes the PCI Controller Master X. 110: Reserved 101: Reserved 100: Reserved 011: Makes REQ*[3] Master X. 010: Makes REQ*[2] Master X. 001: Makes REQ*[1] Master X. 000: Makes REQ*[0] Master X.	R/W
7		Reserved		—
6:4	ReqYP	Request Y Port	Request Y Port (Default: 001) Sets the PCI Bus Master that connects to the Internal PCI Bus Arbiter Request Y Port (Port Y). 111: Makes the PCI Controller Master Y. 110: Reserved 101: Reserved 100: Reserved 011: Makes REQ*[3] Master Y. 010: Makes REQ*[2] Master Y. 001: Makes REQ*[1] Master Y. 000: Makes REQ*[0] Master Y.	R/W
3		Reserved		—
2:0	ReqZP	Request Z Port	Request Z Port (Default: 000) Sets the PCI Bus Master that connects to the Internal PCI Bus Arbiter Request Z Port (Port Z). 111: Makes the PCI Controller Master Z. 110: Reserved 101: Reserved 100: Reserved 011: Makes REQ*[3] Master Z. 010: Makes REQ*[2] Master Z. 001: Makes REQ*[1] Master Z. 000: Makes REQ*[0] Master Z.	R/W

Figure 10.4.21 PCI Bus Arbiter Request Port Register (2/2)

10.4.24 PCI Bus Arbiter Configuration Register (PBACFG) 0xD104

This register is only valid when using the on-chip PCI Bus Arbiter.

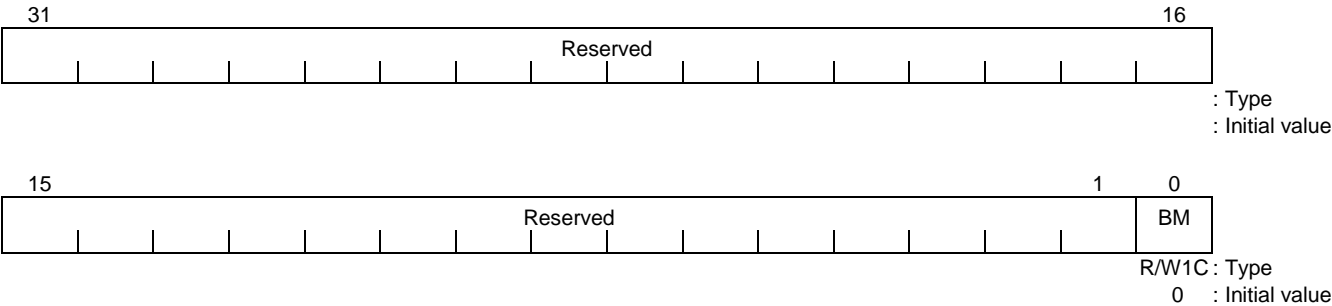


Bit	Mnemonic	Field Name	Description	Read/Write
31:4		Reserved		—
3	FIXPA	Fixed Park Master	Fixed Park Master (Default: 0) Selects the method for determining the Park Master. 0: The last Bus Master becomes the Park Master. 1: Internal PCI Bus Arbiter Request Port A is the Park Master.	R/W
2	RPBA	Reset PCI Bus Arbiter	Reset PCI Bus Arbiter (Default: 0) Resets the PCI Bus Arbiter. However, the PCI Bus Arbiter Register settings are saved. Please use the software to clear this bit. 1: The PCI Bus Arbiter is currently being reset. 0: The PCI Bus Arbiter is not currently being reset.	R/W
1	PBAEN	PCI Bus Arbiter Enable	PCI Bus Arbiter Enable (Default: 0) This is the Bus Arbiter Enable bit. After Reset, External PCI Bus requests to the PCI Arbiter cannot be accepted until this bit is set to "1". The PCI Controller is the default Parking Master after Reset. 1: Enables the PCI Bus Arbiter. 0: Disables the PCI Bus Arbiter.	R/W
0	BMCEN	Broken Master Check Enable	Broken Master Check Enable (Default: 0) Controls Broken Master detection. 1: Enables the Broken PCI Bus Master check. 0: Disables the Broken PCI Bus Master check.	R/W

Figure 10.4.22 PCI Bus Arbiter Configuration Register

10.4.25 PCI Bus Arbiter Status Register (PBASTATUS) 0xD108

This register is only valid when using the on-chip PCI Bus Arbiter.

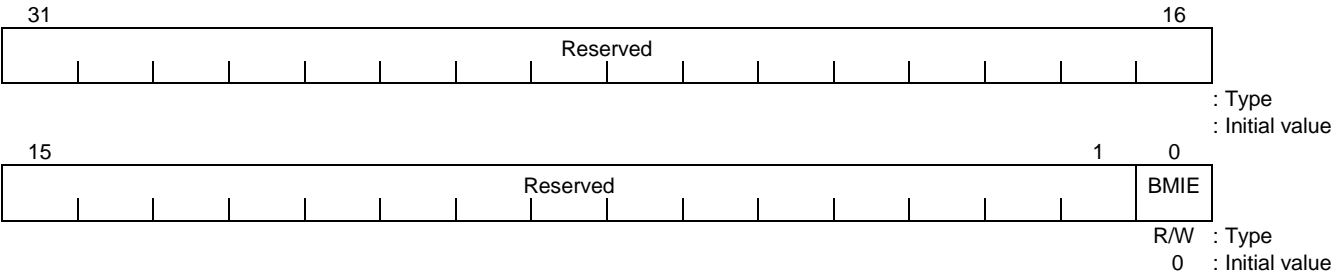


Bit	Mnemonic	Field Name	Description	Read/Write
31:1		Reserved		—
0	BM	Broken Master Detected	Broken Master Detected (Default: 0) This bit indicates that a Broken Master was detected. This bit is set to “1” if even one of the bits in the PCI Bus Arbiter Broken Master Register (PBABM) is “1”. 1: Indicates that a Broken Master was detected. 0: Indicates that no Broken Master has been detected.	R/W1C

Figure 10.4.23 PCI Bus Arbiter Status Register

10.4.26 PCI Bus Arbiter Interrupt Mask Register (PBAMASK) 0xD10C

This register is only valid when using the on-chip PCI Bus Arbiter.



Bit	Mnemonic	Field Name	Description	Read/Write
31:1		Reserved		—
0	BMIE	Broken Master Detected Interrupt Enable	Broken Master Detected Interrupt Enable (Default: 0) Generates an interrupt when a Broken Master is detected. 1: Generates an interrupt. 0: Does not generate an interrupt.	R/W

Figure 10.4.24 PCI Bus Arbiter Interrupt Mask Register

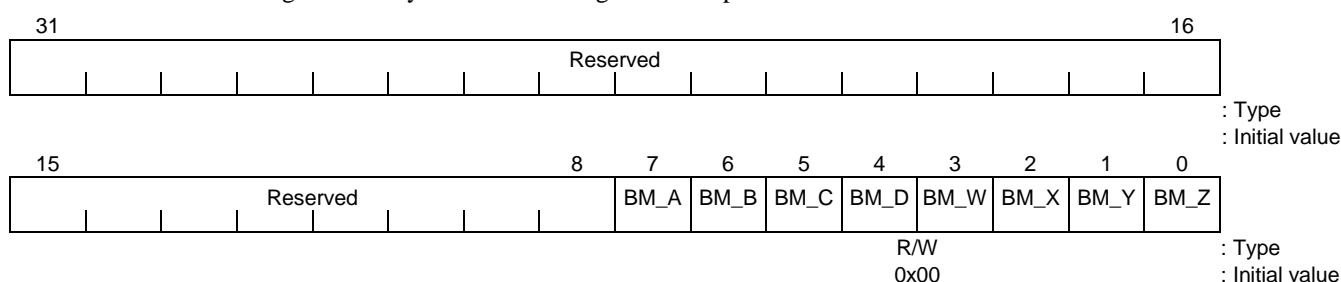
10.4.27 PCI Bus Arbiter Broken Master Register (PBABM) 0xD110

This register indicates the acknowledged Broken Master. This register sets the bit that corresponds to the PCI Master device that was acknowledged as the Broken Master when the Broken Master Check Enable bit (BMCEN) in the PCI Bus Arbiter Configuration Register (PBACFG) is set.

Regardless of the value of the Broken Master Check Enable bit, a PCI Master device is removed from the arbitration scheme when “1” is written to the corresponding BM bit.

This register must be cleared to “0” since bit mapping changes, making this register value invalid when the PCI Bus Arbiter Request Port Register (PBAREQPORT) is changed.

This register is only valid when using the on-chip PCI Bus Arbiter.

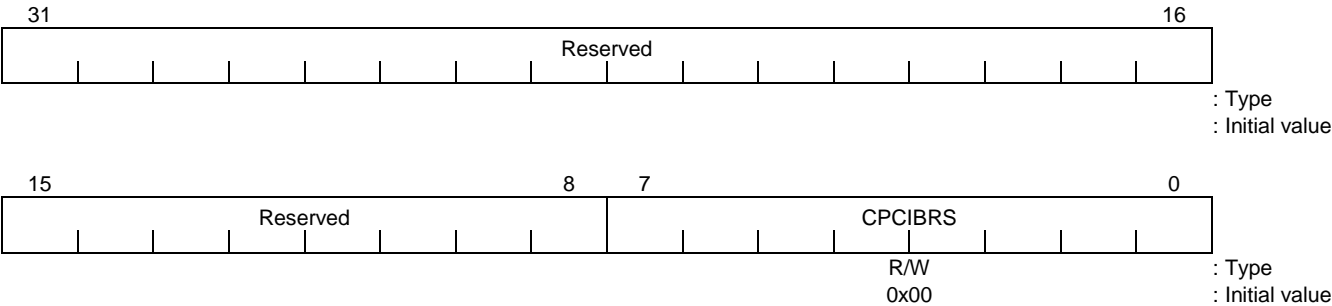


Bit	Mnemonic	Field Name	Description	Read/Write
31:8		Reserved		—
7	BM_A	Broken Master	Broken Master A (Default: 0) Indicates whether PCI Bus Master A is a Broken Master. 1: PCI Bus Master A was acknowledged as a Broken Master. 0: PCI Bus Master A was not acknowledged as a Broken Master.	R/W
6	BM_B	Broken Master	Broken Master B (Default: 0) Indicates whether PCI Bus Master B is a Broken Master. 1: PCI Bus Master B was acknowledged as a Broken Master. 0: PCI Bus Master B was not acknowledged as a Broken Master.	R/W
5	BM_C	Broken Master	Broken Master C (Default: 0) Indicates whether PCI Bus Master C is a Broken Master. 1: PCI Bus Master C was acknowledged as a Broken Master. 0: PCI Bus Master C was not acknowledged as a Broken Master.	R/W
4	BM_D	Broken Master	Broken Master D (Default: 0) Indicates whether PCI Bus Master D is a Broken Master. 1: PCI Bus Master D was acknowledged as a Broken Master. 0: PCI Bus Master D was not acknowledged as a Broken Master.	R/W
3	BM_W	Broken Master	Broken Master W (Default: 0) Indicates whether PCI Bus Master W is a Broken Master. 1: PCI Bus Master W was acknowledged as a Broken Master. 0: PCI Bus Master W was not acknowledged as a Broken Master.	R/W
2	BM_X	Broken Master	Broken Master X (Default: 0) Indicates whether PCI Bus Master X is a Broken Master. 1: PCI Bus Master X was acknowledged as a Broken Master. 0: PCI Bus Master X was not acknowledged as a Broken Master.	R/W
1	BM_Y	Broken Master	Broken Master Y (Default: 0) Indicates whether PCI Bus Master Y is a Broken Master. 1: PCI Bus Master Y was acknowledged as a Broken Master. 0: PCI Bus Master Y was not acknowledged as a Broken Master.	R/W
0	BM_Z	Broken Master	Broken Master Z (Default: 0) Indicates whether PCI Bus Master Z is a Broken Master. 1: PCI Bus Master Z was acknowledged as a Broken Master. 0: PCI Bus Master Z was not acknowledged as a Broken Master.	R/W

Figure 10.4.25 PCI Bus Arbiter Broken Master Register

10.4.28 PCI Bus Arbiter Current Request Register (PBACREQ) 0xD114

This register is a diagnostic register that is only valid when using the on-chip PCI Bus Arbiter.

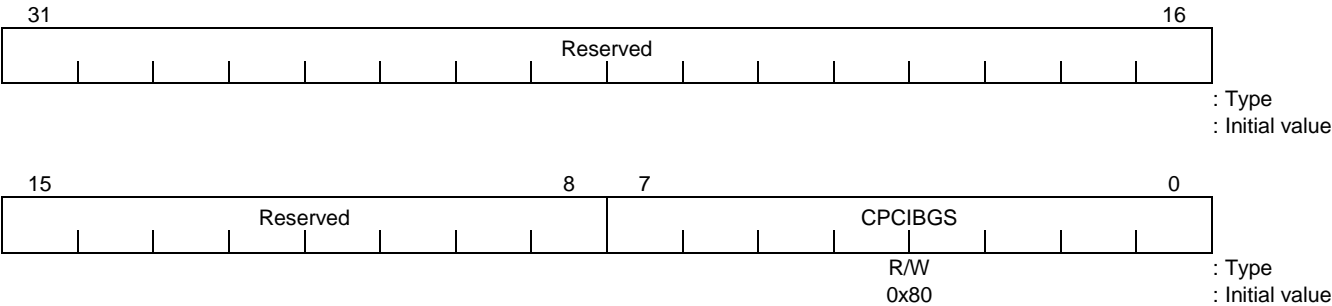


Bits	Mnemonic	Field Name	Description	Read/Write
31:8		Reserved		—
7:0	CPCIBRS	Current PCI Bus Request Status	Current PCI Bus Request Status (Default: 0x00) This register indicates the status of the current PCI Bus Request Input Signal (PCI Controller and REQ*[3:0]). CPCIBRS[7] corresponds to the PCI Controller and REQ*[3:0]. CPCIBRS[3:0] correspond to REQ*[3:0].	R/W

Figure 10.4.26 PCI Bus Arbiter Current Request Register

10.4.29 PCI Bus Arbiter Current Grant Register (PBACGNT) 0xD118

This is a diagnostic register that is only valid when using the on-chip PCI Bus Arbiter.

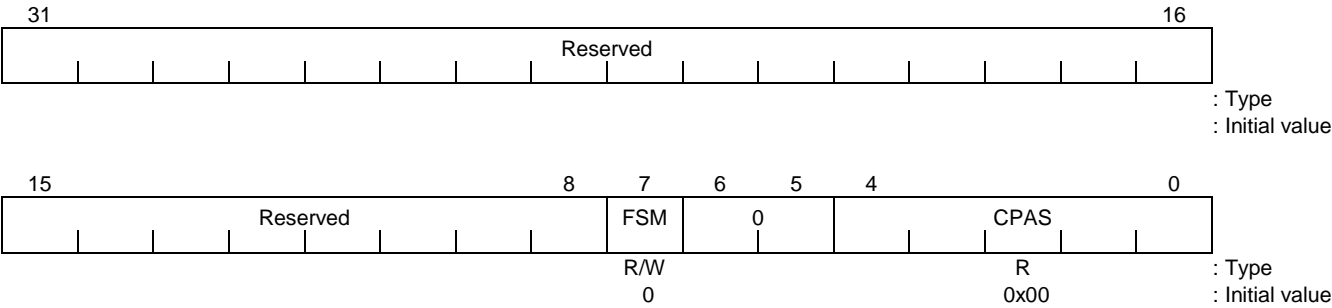


Bits	Mnemonic	Field Name	Description	Read/Write
31:8		Reserved		—
7:0	CPCIBGS	Current PCI Grant Status	Current PCI Bus Grant Status (Default: 0x80) This register indicates the current PCI Bus Grant output signal (PCI Controller and GNT*[3:0]). CPCIBGS[7] corresponds to the PCI Controller, and CPCIBGS[3:0] correspond to GNT*[3:0].	R/W

Figure 10.4.27 PCI Bus Arbiter Current Grant Register

10.4.30 PCI Bus Arbiter Current State Register (PBACSTATE) 0xD11C

This is a diagnostic register that is only valid when using the on-chip PCI Bus Arbiter.



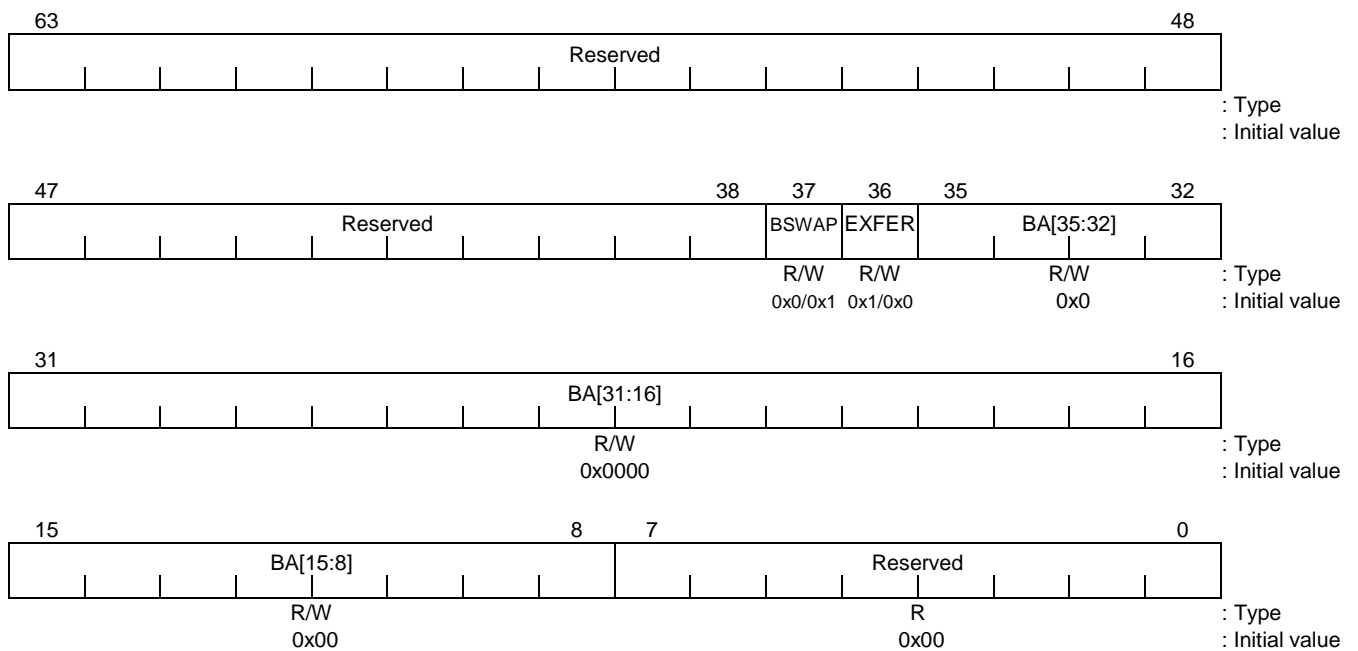
Bit	Mnemonic	Field Name	Description	Read/Write
31:8		Reserved		—
7	FSM	Observe PCI Arbiter State Machine	Observe PCI Arbiter Finite State Machine (Default: 0) Specifies which State Machine to observe. 1: Observe the Level 1 State Machine. 0: Observe the Level 2 State Machine.	R/W
6:5		Reserved		—

Figure 10.4.28 PCI Bus Arbiter Current State Register (1/2)

Bit	Mnemonic	Field Name	Description	Read/Write
4:0	CPAS	Current PCI Bus Arbiter State	<p>Current PCI Bus Arbiter State (Default: 0x00)</p> <p>Displays the State Machine that was selected by the FSM bit.</p> <p>Please refer to Figures 12.5.3 and 12.11.1 for an explanation of Agent/Grant A - W and Level 2.</p> <p>When FSM =1:</p> <p>0x00: Preparation state for transferring bus ownership to PCI Agent A.</p> <p>0x01: State in which Grant A is provided to PCI Agent A when PCI Bus ownership is being held elsewhere.</p> <p>0x02: State in which Grant A is provided to PCI Agent A when PCI Bus ownership is not being held elsewhere.</p> <p>0x03: The agent that was provided Grant A exists in this state. If there is bus ownership, the PCI Bus Arbiter transfers bus ownership to another agent.</p> <p>0x04: Preparation state for transferring bus ownership to PCI Agent B.</p> <p>0x05: State in which Grant B is provided to PCI Agent B when PCI Bus ownership is being held elsewhere.</p> <p>0x06: State in which Grant B is provided to PCI Agent B when PCI Bus ownership is not being held elsewhere.</p> <p>0x07: The agent that was provided Grant B exists in this state. If there is bus ownership, the PCI Bus Arbiter transfers bus ownership to another agent.</p> <p>0x08: Preparation state for transferring bus ownership to PCI Agent C.</p> <p>0x09: State in which Grant C is provided to PCI Agent C when PCI Bus ownership is being held elsewhere.</p> <p>0x0A: State in which Grant C is provided to PCI Agent C when PCI Bus ownership is not being held elsewhere.</p> <p>0x0B: The agent that was provided Grant C exists in this state. If there is bus ownership, the PCI Bus Arbiter transfers bus ownership to another agent.</p> <p>0x0C: Preparation state for transferring bus ownership to PCI Agent D.</p> <p>0x0D: State in which Grant D is provided to PCI Agent D when PCI Bus ownership is being held elsewhere.</p> <p>0x0E: State in which Grant D is provided to PCI Agent D when PCI Bus ownership is not being held elsewhere.</p> <p>0x0F: The agent that was provided Grant D exists in this state. If there is bus ownership, the PCI Bus Arbiter transfers bus ownership to another agent.</p> <p>0x10: Preparation state for transferring bus ownership to PCI Agent Level 2.</p> <p>0x11: State in which Grant Level 2 is provided to PCI Agent Level 2 when PCI Bus ownership is being held elsewhere.</p> <p>0x12: State in which Grant Level 2 is provided to PCI Agent Level 2 when PCI Bus ownership is not being held elsewhere.</p> <p>0x13: The agent that was provided Grant Level 2 exists in this state. If there is bus ownership, the PCI Bus Arbiter transfers bus ownership to another agent.</p> <p>When FSM=0, the FSM=1 description is replaced as follows: A→W, B→X, C→Y, D→Z, Level 2→N/A.</p>	R

Figure 10.4.28 PCI Bus Arbiter Current State Register (2/2)

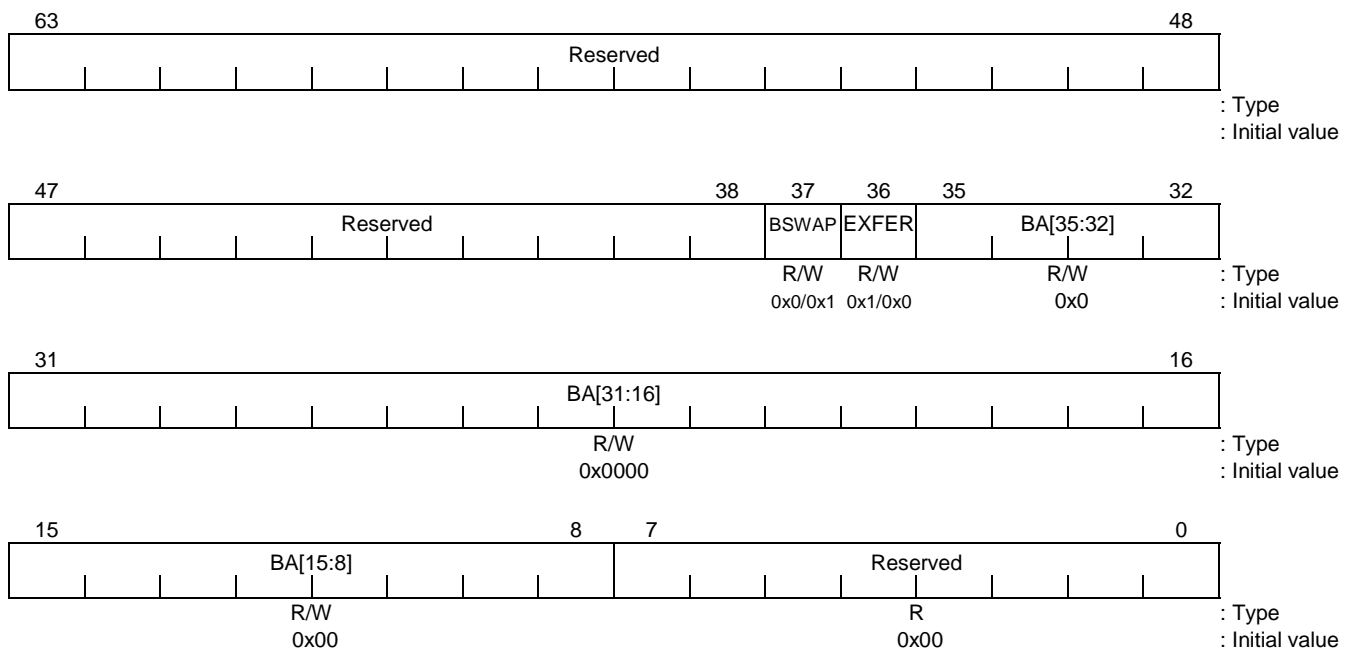
10.4.31 G2P Memory Space 0 G-Bus Base Address Register (G2PM0GBASE) 0xD120



Bit	Mnemonic	Field Name	Description	Read/Write
63:38		Reserved		—
37	BSWAP	Byte Swap	Byte Swap Disable (Default: Little Endian Mode: 0x1; Big Endian Mode: 0x0) Sets the byte swapping of Memory Space 0. 1: Do not perform byte swapping. 0: Perform byte swapping. Please use the default state in most situations. If this bit is changed to “1” when in the Big Endian Mode, the byte order of transfer to Memory Space 0 through DWORD (32-bit) access will not change.	R/W
36	EXFER	Endian Transfer	Endian Transfer (Default: Little Endian Mode: 0x0; Big Endian Mode: 0x1) Sets the Endian Transfer of Memory Space 0. 1: Performs Endian Transfer. 0: Does not perform Endian Transfer. Please use the default state.	R/W
35:8	BA[35:8]	Base Address	Base Address (Default: 0x0_0000_00) Sets the G-Bus base bus address of Memory Space 0 for initiator access. Can set the base address in 256-byte units.	R/W
7:0		Reserved		R

Figure 10.4.29 G2P Memory Space 0 G-Bus Base Address Register

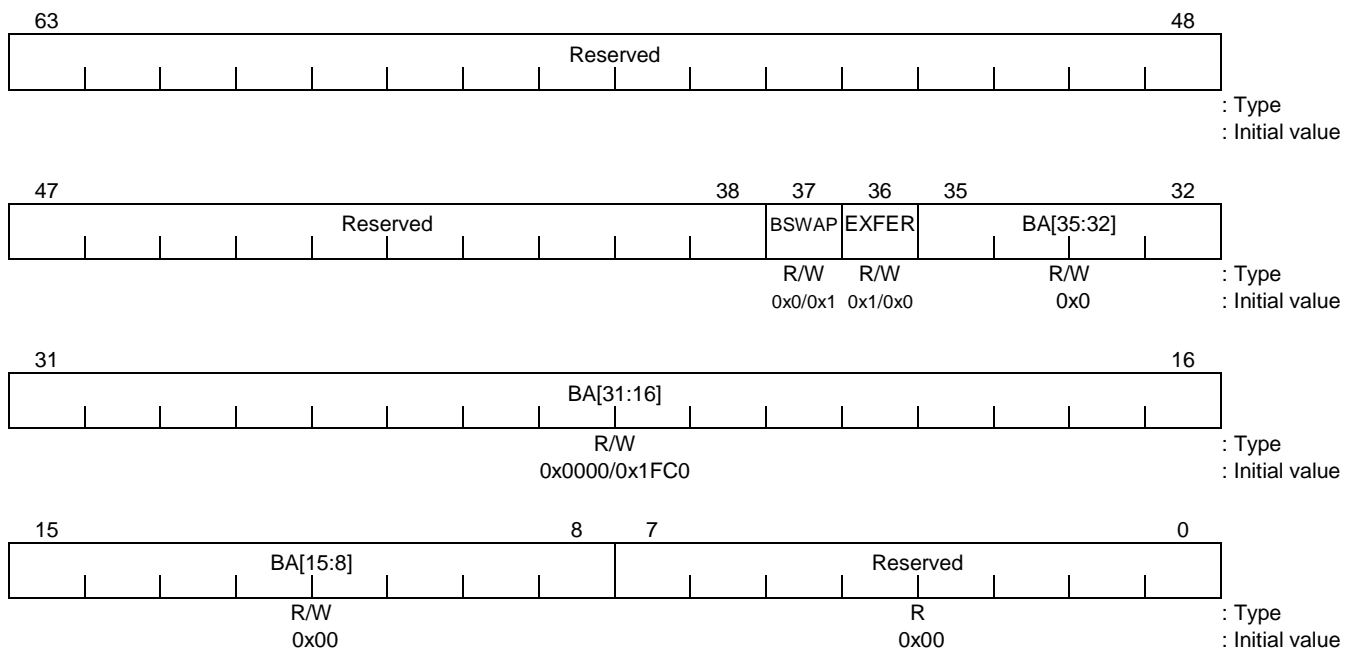
10.4.32 G2P Memory Space 1 G-Bus Base Address Register (G2PM1GBASE) 0xD128



Bit	Mnemonic	Field Name	Description	Read/Write
63:38		Reserved		—
37	BSWAP	Byte Swap	Byte Swap Disable (Default: Little Endian Mode: 0x1; Big Endian Mode: 0x0) Sets the byte swapping of Memory Space 1. 1: Do not perform byte swapping. 0: Perform byte swapping. Please use the default state in most situations. If this bit is changed to “1” when in the Big Endian Mode, the byte order of transfer to Memory Space 0 through DWORD (32-bit) access will not change.	R/W
36	EXFER	Endian Transfer	Endian Transfer (Default: Little Endian Mode: 0x0; Big Endian Mode: 0x1) Sets the Endian Transfer of Memory Space 1. 1: Performs Endian Transfer. 0: Does not perform Endian Transfer. Please use the default state.	R/W
35:8	BA[35:8]	Memory Space Base Address 1	Base Address (Default: 0x0_0000_00) Sets the G-Bus base bus address of Memory Space 1 for initiator access. Can set the base address in 256-byte units.	R/W
7:0		Reserved		R

Figure 10.4.30 G2P Memory Space 1 G-Bus Base Address Register

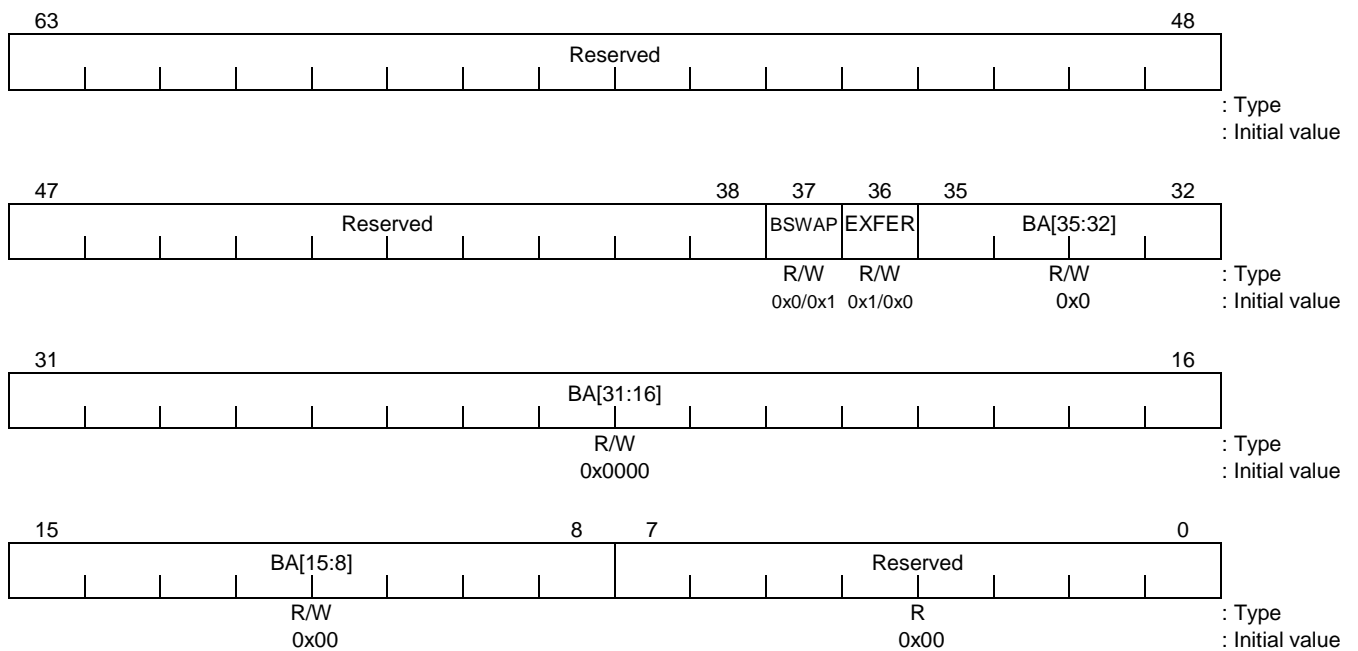
10.4.33 G2P Memory Space 2 G-Bus Base Address Register (G2PM2GBASE) 0xD130



Bit	Mnemonic	Field Name	Description	Read/Write
63:38		Reserved		—
37	BSWAP	Byte Swap	Byte Swap Disable (Default: Little Endian Mode: 0x1; Big Endian Mode: 0x0) Sets the byte swapping of Memory Space 0. 1: Do not perform byte swapping. 0: Perform byte swapping. Please use the default state in most situations. If this bit is changed to “1” when in the Big Endian Mode, the byte order of transfer to Memory Space 0 through DWORD (32-bit) access will not change.	R/W
36	EXFER	Endian Transfer	Endian Transfer (Default: Little Endian Mode: 0x0; Big Endian Mode: 0x1) Sets the Endian Transfer of Memory Space 0. 1: Performs Endian Transfer. 0: Does not perform Endian Transfer. Please use the default state.	R/W
35:8	BA[35:8]	Base Address	Base Address (Default: Normal Mode: 0x0_0000_00; PCI Boot Mode: 0x0_1FC0_00) Sets the G-Bus base bus address of Memory Space 2 for initiator access. Can set the base address in 256-byte units.	R/W
7:0		Reserved		R

Figure 10.4.31 G2P Memory Space 2 G-Bus Base Address Register

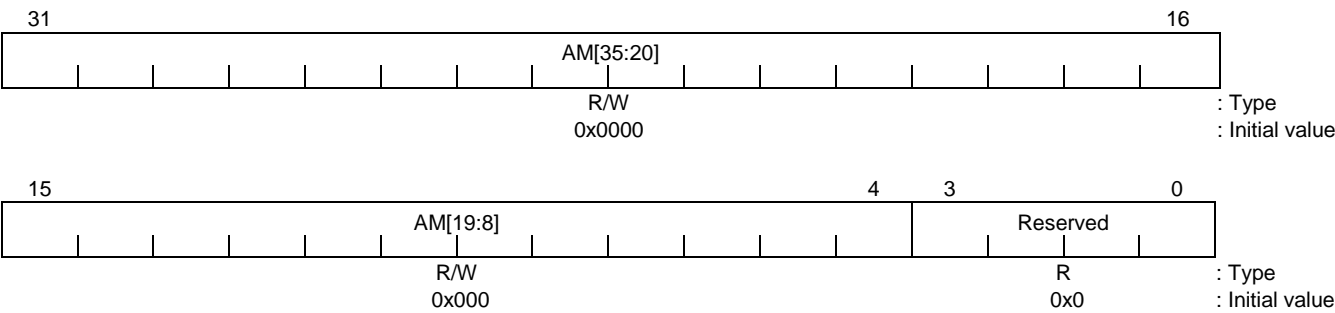
10.4.34 G2P I/O Space G-Bus Base Address Register (G2PIOGBASE) 0xD138



Bit	Mnemonic	Field Name	Description	Read/Write
63:38		Reserved		—
37	BSWAP	Byte Swap	Byte Swap Disable (Default: Little Endian Mode: 0x1; Big Endian Mode: 0x0) Sets the byte swapping of the I/O space. 1: Do not perform byte swapping. 0: Perform byte swapping. Please use the default state in most situations. If this bit is changed to “1” when in the Big Endian Mode, the byte order of transfer to the I/O Memory Space through DWORD (32-bit) access will not change.	R/W
36	EXFER	Endian Transfer	Endian Transfer (Default: Little Endian Mode: 0x0; Big Endian Mode: 0x1) Sets the Endian Transfer of the I/O Space. 1: Performs Endian Transfer. 0: Does not perform Endian Transfer. Please use the default state.	R/W
35:8	BA[35:8]	Base Address	Base Address (Default: 0x0_0000_00) Sets the G-Bus base bus address of the I/O Memory Space for initiator access. Can set the base address in 256-byte units.	R/W
7:0		Reserved		R

Figure 10.4.32 G2P I/O Space G-Bus Address Register

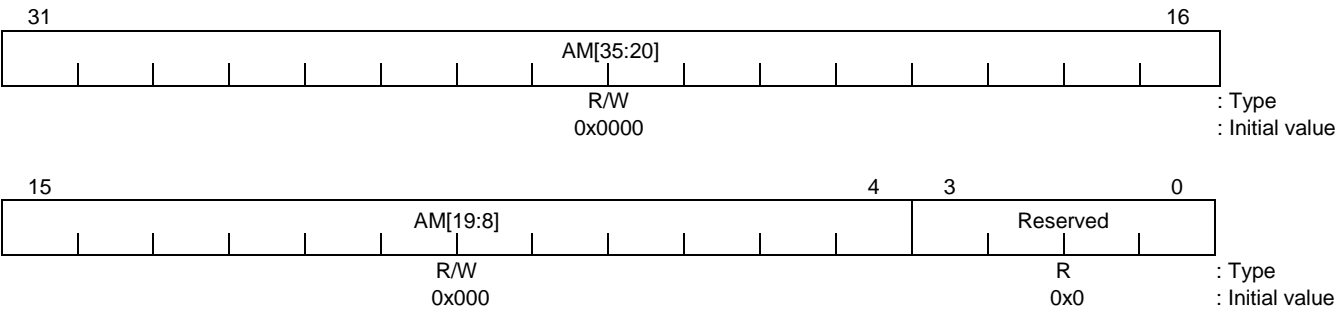
10.4.35 G2P Memory Space 0 Address Mask Register (G2PM0MASK) 0xD140



Bit	Mnemonic	Field Name	Description	Read/Write
31:4	AM[35:8]	Address Mask	G-Bus to PCI-Bus Address Mask (Default: 0x0_0000_00) Sets the bits to be subject to address comparison. See 10.3.4 for more information. When setting a memory space size of 256 MB (0x1000_0000) for example, the value becomes 0x00FF_FFF0.	R/W
3:0		Reserved		R

Figure 10.4.33 G2P Memory Space 0 Address Mask Register

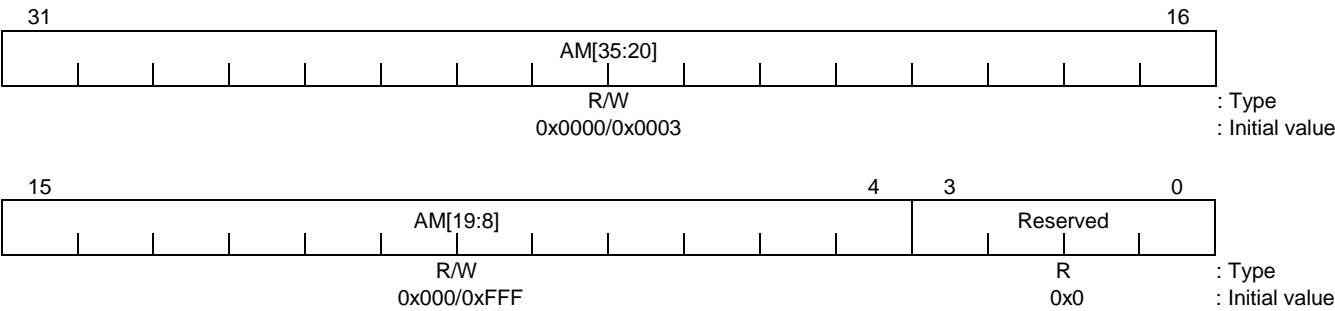
10.4.36 G2P Memory Space 1 Address Mask Register (G2PM1MASK) 0xD144



Bit	Mnemonic	Field Name	Description	Read/Write
31:4	AM[35:8]	Address Mask	G-Bus to PCI-Bus Address Mask (Default: 0x0_0000_00) Sets the bits to be subject to address comparison. See 10.3.4 for more information. When setting a memory space size of 256 MB (0x1000_0000) for example, the value becomes 0x00FF_FFF0.	R/W
3:0		Reserved		R

Figure 10.4.34 G2P Memory Space 1 Address Mask Register

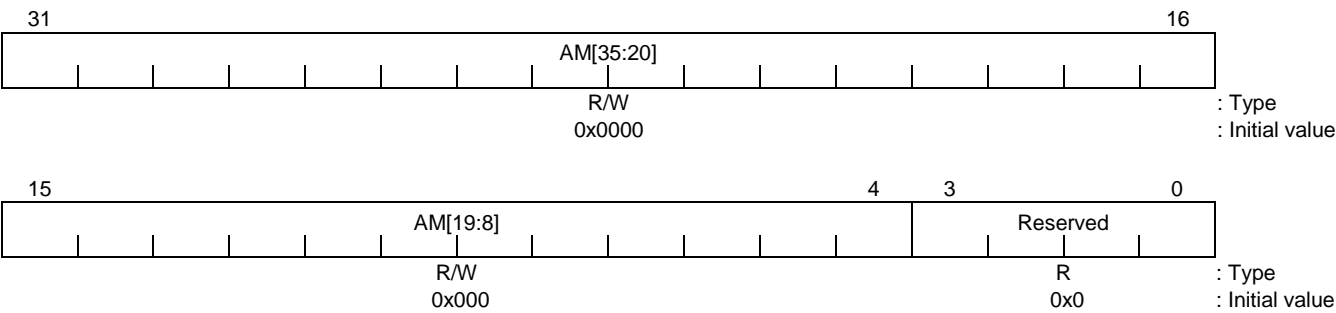
10.4.37 G2P Memory Space 2 Address Mask Register (G2PM2MASK) 0xD148



Bit	Mnemonic	Field Name	Description	Read/Write
31:4	AM[35:8]	Address Mask	G-Bus to PCI-Bus Address Mask (Default: 0x0_0000_00) (Default: Normal Mode: 0x0_0000_00; PCI Boot Mode: 0x0_003F_FF) Sets the bits to be subject to address comparison. See 10.3.4 for more information. When setting a memory space size of 256 MB (0x1000_0000) for example, the value becomes 0x00FF_FFF0.	R/W
3:0		Reserved		R

Figure 10.4.35 G2P Memory Space 2 Address Mask Register

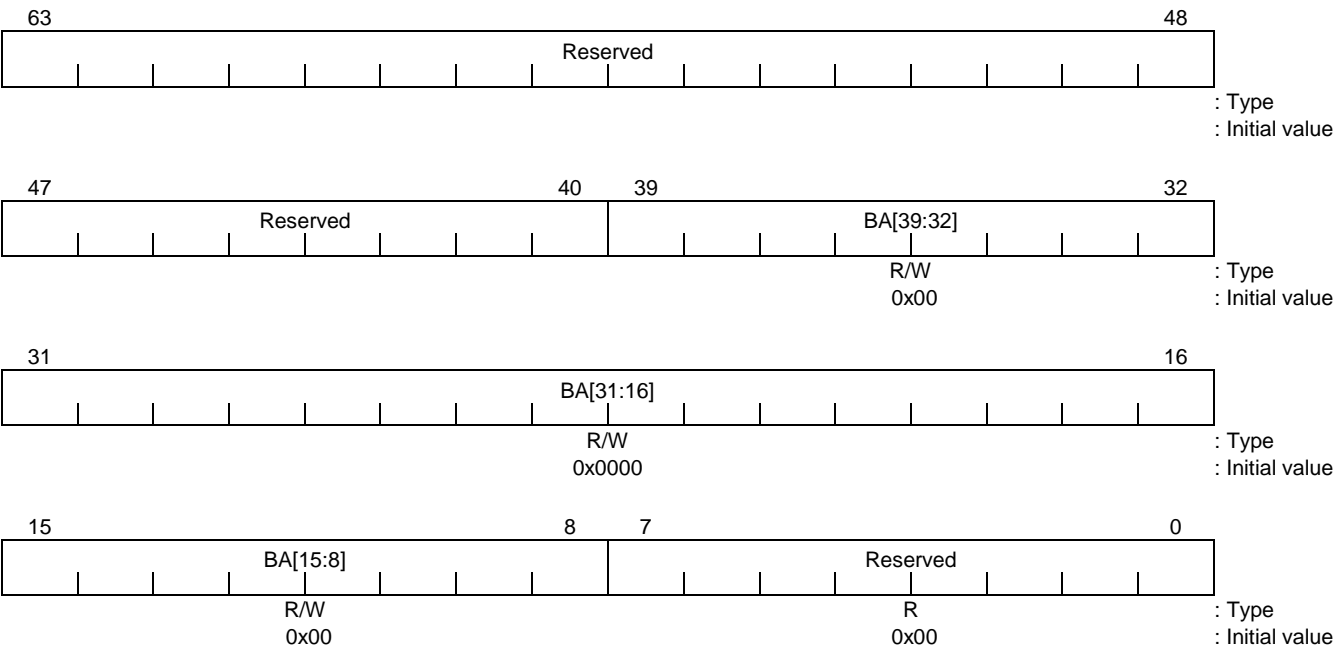
10.4.38 G2P I/O Space Address Mask Register (G2PIOMASK) 0xD14C



Bits	Mnemonic	Field Name	Description	Read/Write
31:4	AM[35:8]	Address Mask	G-Bus to PCI-Bus Address Mask (Default: 0x0_0000_00) Sets the bits to be subject to address comparison. See 10.3.4 for more information. When setting a memory space size of 256 MB (0x0000_0100) for example, the value becomes 0x0000_0000.	R/W
3:0		Reserved		R

Figure 10.4.36 G2P I/O Space Address Mask Register

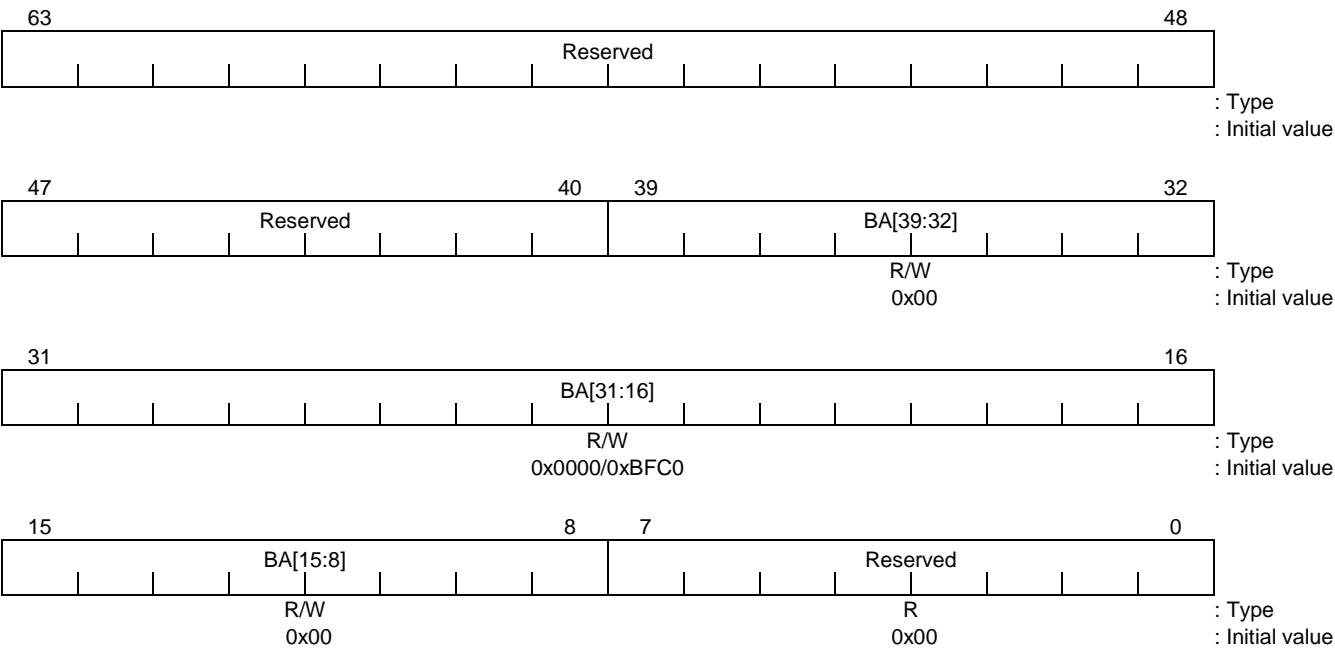
10.4.39 G2P Memory Space 0 PCI Base Address Register (G2PM0PBASE) 0xD150



Bits	Mnemonic	Field Name	Register	Read/Write
63:40		Reserved		—
39:8	BA[39:8]	Base Address	Base Address (Default: 0x00_0000_00) Sets the PCI Base address of Memory Space 0 for initiator access. Can set the base address in 256-Byte units.	R/W
7:0		Reserved		R

Figure 10.4.37 G2P Memory Space 0 G-Bus Base Address Register

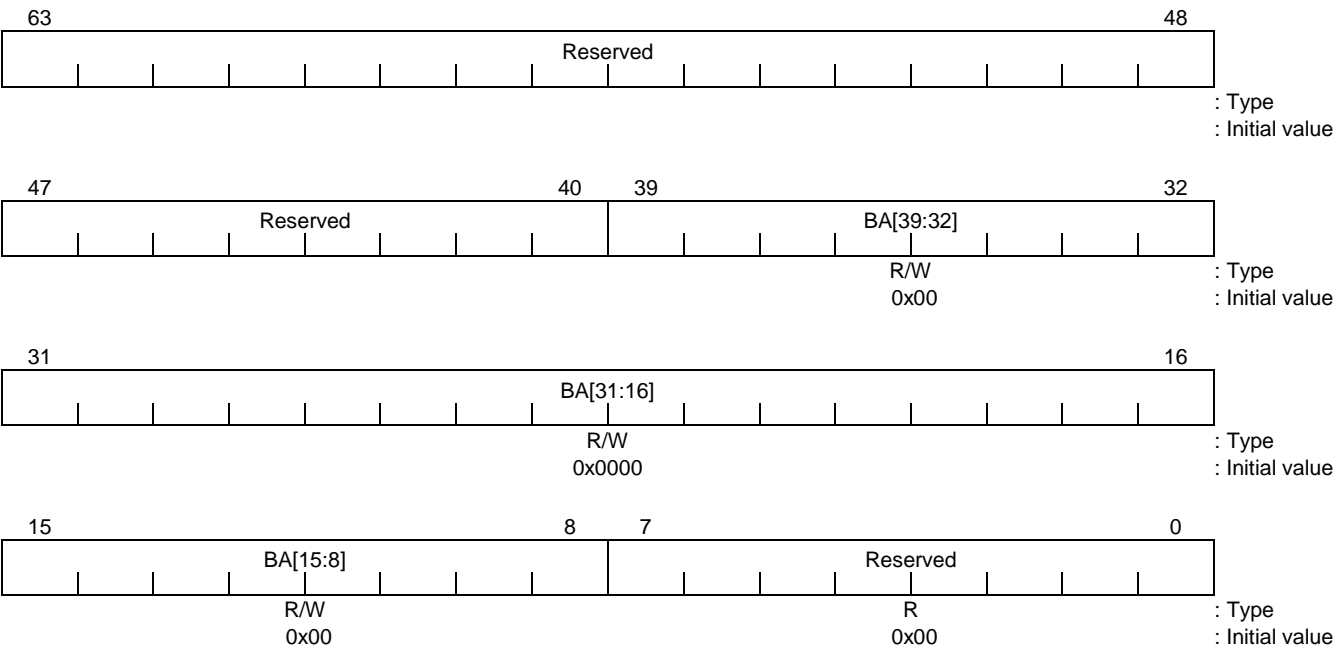
10.4.40 G2P Memory Space 1 PCI Base Address Register (G2PM1PBASE) 0xD158



Bit	Mnemonic	Field Name	Description	Read/Write
63:40		Reserved		—
39:8	BA[39:8]	Base Address	Base Address (Default: 0x00_0000_00) Sets the PCI Base address of Memory Space 1 for initiator access. Can set the base address in 256-Byte units.	R/W
7:0		Reserved		R

Figure 10.4.38 G2P Memory Space 1 G-Bus Base Address Register

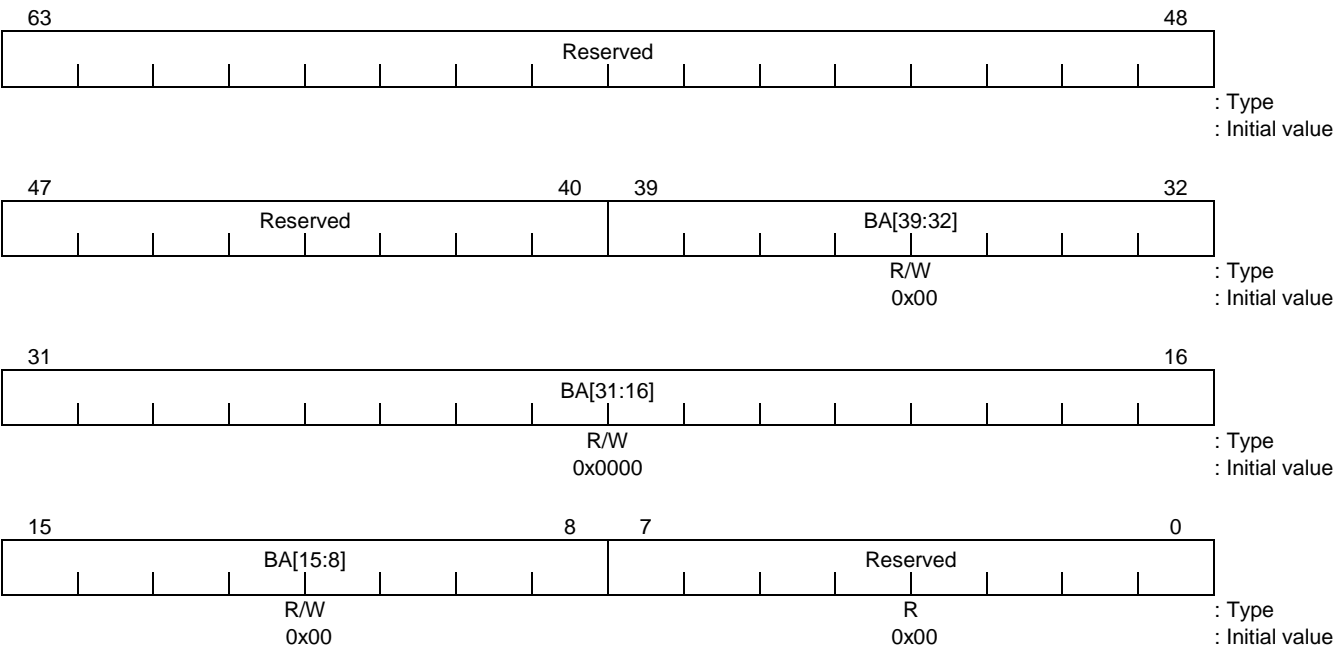
10.4.41 G2P Memory Space 2 PCI Base Address Register (G2PM2PBASE) 0xD160



Bits	Mnemonic	Field Name	Description	Read/Write
63:40		Reserved		—
39:8	BA[39:8]	Base Address	Base Address (Default: 0x00_0000_00) Sets the PCI Base address of Memory Space 2 for initiator access. Can set the base address in 256-Byte units.	R/W
7:0		Reserved		R

Figure 10.4.39 G2P Memory Space 2 G-Bus Base Address Register

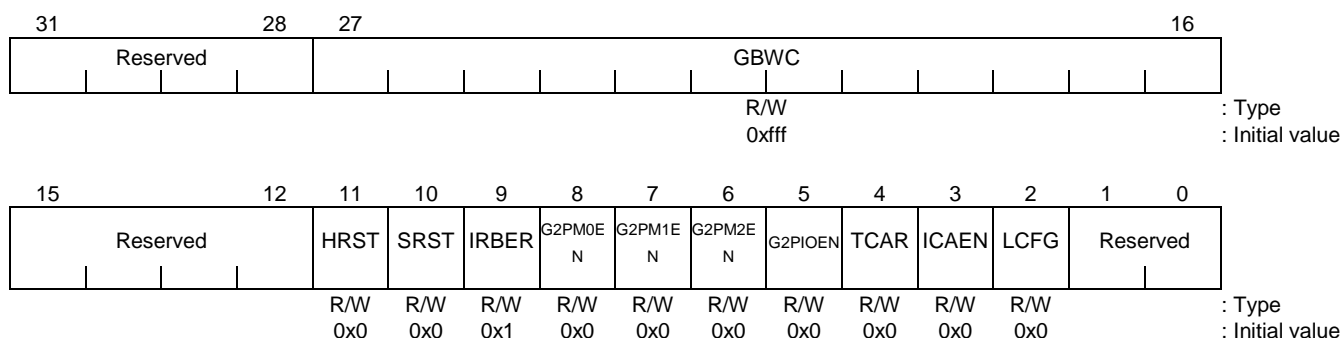
10.4.42 G2P I/O Space PCI Base Address Register (G2PIOPBASE) 0xD168



Bits	Mnemonic	Field Name	Description	Read/Write
63:40		Reserved		—
39:8	BA[39:8]	Base Address	Base Address (Default: 0x00_0000_00) Sets the PCI Base address of the I/O Space for initiator access. Can set the base address in 256-Byte units.	R/W
7:0		Reserved		R

Figure 10.4.40 G2P I/O Space G-Bus Address Register

10.4.43 PCI Controller Configuration Register (PCICCFG) 0xD170



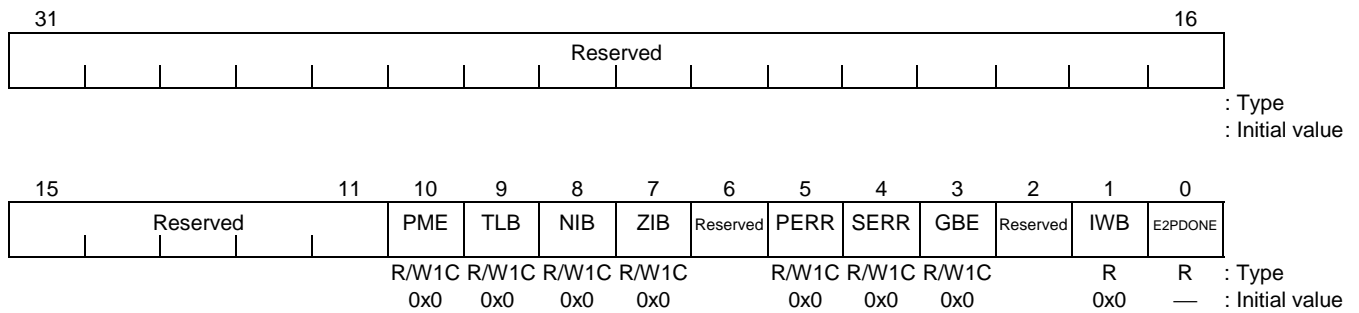
Bit	Mnemonic	Field Name	Description	Read/Write
31:28		Reserved		—
27:16	GBWC	G-Bus Wait Counter Setting	<p>G Bus Wait Counter (Default: 0xFFFF)</p> <p>Sets the Retry response counter at the G-Bus during a PCI initiator Read transaction.</p> <p>When the initiator Read access cycle exceeds the setting of this counter, a Retry response is sent to the G-Bus and the G-Bus is released. PCI Read operation continues. This counter uses the G-Bus clock (GBUSCLK) when operating.</p> <p>When 0x000 is set, a Retry response is not sent to the G-Bus by a long response cycle count.</p>	R/W
15:12		Reserved		—
11	HRST	Hardware Reset	<p>Hard Reset (Default: 0x0)</p> <p>Performs PCI Controller hardware reset control. EEPROM reloading is also performed. This bit is automatically cleared when Reset ends. This is a diagnostic function.</p> <p>The PCI Controller cannot be accessed for 32 G-Bus clock cycles after this bit is set.</p> <p>1: Perform a hardware reset on the PCI Controller. 0: Do not perform a hardware reset on the PCI Controller.</p>	R/W
10	SRST	Software Reset	<p>Soft Reset (Default: 0x0)</p> <p>Performs PCI Controller software reset control. Data is also reloaded to the Configuration Space Register from EEPROM or from the Configuration Data Register. Please set this bit after the EEPROM Load End bit (PCICSTATUS.E2PDONE) is set. Also, please use the software to clear this bit at least four PCI Bus Clock cycles after Reset.</p> <p>Other registers of the PCI Controller cannot be accessed while this bit is set.</p> <p>This bit differs from the Hardware Reset bit (HRST). The following register values are not initialized.</p> <ul style="list-style-type: none"> G2P Status Register (G2PSTATUS) PCI Bus Arbiter Status Register (PBASTATUS) PCI Controller Status Register (PCICSTATUS) Software Reset bit (PCICCFG.SRST) Load Configuration Register bit (PCICCFG.LCFG) <p>1: The PCI Controller is reset by the software. 0: The PCI Controller is not reset by the software.</p>	R/W

Figure 10.4.41 PCI Controller Configuration Register (1/2)

Bit	Mnemonic	Field Name	Description	Read/Write
9	IRBER	Bus Error Response Setting During Initiator Read	<p>Initiator Read Bus Error Response (Default: 0x1)</p> <p>Bus error responses on the G-Bus are controlled when the following phenomena indicated by the PCI Status, Command Register (PICSTATUS) and the G2P Status Register (G2PSTATUS) occur during initiator Read access.</p> <p>Detected Parity Error (PCISTATUS.DPE) Received Master Abort (PCISTATUS.RMA) Received Target Abort (PCISTATUS.RTA) Initiator Detected TRDY Time Out Error (G2PSTATUS.IDTTOE) Initiator Detected Retry Time Out Error (G2PSTATUS.IDRTOE)</p> <p>1: Responds with a Bus error on the G-Bus. 0: Does not respond with a Bus error on the G-Bus. (Normally terminates the Read transaction on the G-Bus. Read data is invalid.)</p>	R/W
8	G2PM0EN	Initiator Memory Space 0 Enable	<p>Initiator Memory Space 0 Enable (Default: 0x0)</p> <p>Controls PCI initiator access to Memory Space 0.</p> <p>1: Memory Space 0 is valid. 0: Memory Space 0 is invalid.</p>	R/W
7	G2PM1EN	Initiator Memory Space 1 Enable	<p>Initiator Memory Space 1 Enable (Default: 0x0)</p> <p>Controls PCI initiator access to Memory Space 1.</p> <p>1: Memory Space 1 is valid. 0: Memory Space 1 is invalid.</p>	R/W
6	G2PM2EN	Initiator Memory Space 2 Enable	<p>Initiator Memory Space 2 Enable (Default: Normal Mode: 0x0; PCI Boot Mode: 0x1)</p> <p>Controls PCI initiator access to Memory Space 2.</p> <p>1: Memory Space 2 is valid. 0: Memory Space 2 is invalid.</p>	R/W
5	G2PIOEN	Initiator I/O Space Enable	<p>Initiator I/O Space Enable (Default: 0x0)</p> <p>Controls PCI initiator access to the I/O Space..</p> <p>1: I/O Space is valid. 0: I/O Space is invalid.</p>	R/W
4	TCAR	Target Configuration Access Ready	<p>Target Configuration Access Ready (Default: 0x0/0x1)</p> <p>Specifies whether to accept PCI access as a target.</p> <p>PCI controller receives a target access, when this bit is 1 and PCISTATUS.E2PDONE bit is 1.</p> <p>Configuration access from the PCI Bus can be accepted during PCI Boot up after initialization from EEPROM or after each initialization ends. Please use the software to set this bit after initialization ends. Retry response to PCI configuration access is performed until this bit is set.</p> <p>This bit becomes "1" only when in the PCI Boot Mode and the Satellite Mode. Operation when this bit is set to "1" then reset to "0" is not defined.</p> <p>1: Responds to PCI target access. 0: Performs a Retry response to PCI target access.</p>	R/W
3	ICAEN	Initiator Configuration Access Enable	<p>Initiator Configuration Access Enable (Default: 0x1)</p> <p>Controls initiator PCI configuration access using the G2P Configuration Address Register (G2PCFGADRS) and the G2P Configuration Data Register (G2PCFGDATA). This is a diagnostic function.</p> <p>1: Initiator configuration access is possible. 0: Initiator configuration access is not possible.</p>	R/W
2	LCFG	Load Configuration Data Register	<p>Load PCI Configuration Data Register (Default: 0x0)</p> <p>When a software reset is performed on this bit using the Software Reset bit (PCICFG.SRST) when this bit is already set, data is loaded to the Configuration Space Register from the Configuration Data 0/1/2/3 Register.</p> <p>1: Load from the Configuration Data 0/1/2/3 Register. 0: Load from EEPROM.</p>	R/W
1:0		Reserved		—

Figure 10.4.41 PCI Controller Configuration Register (2/2)

10.4.44 PCI Controller Status Register (PCICSTATUS) 0xD174



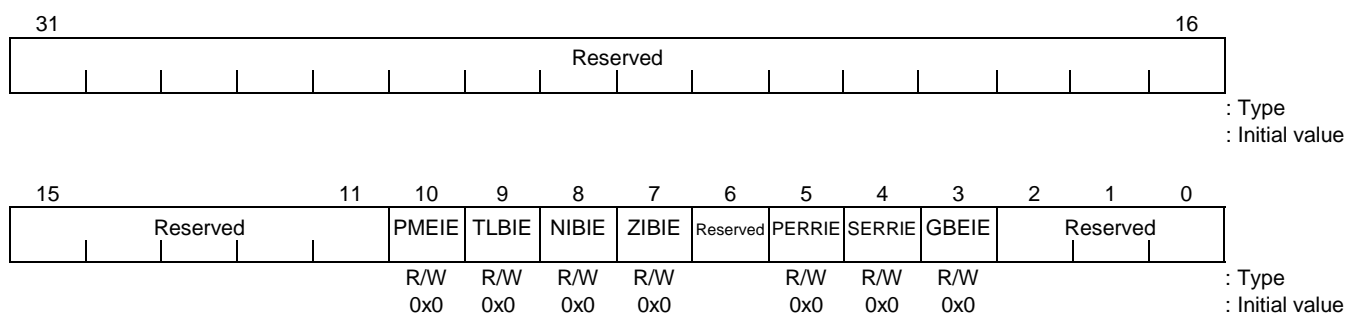
Bit	Mnemonic	Field Name	Description	Read/Write
31:11		Reserved		—
10	PME	PME Detect	PME Detect (Default: 0x0) When the PCI Controller is in the Host mode, this bit indicates that assertion of the PME* signal was detected. 1: Indicates that assertion of the PME* signal was detected. 0: Indicates that assertion of the PME* signal was not detected.	R/W1C
9	TLB	Long Burst Transfer Detect	Too Long Burst Detect (Default: 0x0) Indicates that a Burst transfer by the on-chip DMA Controller exceeding 8 DWORDs was detected. 1: Indicates that a Burst transfer exceeding 8 DWORDs was detected. 0: Indicates that no Burst transfer exceeding 8 DWORDs was detected.	R/W1C
8	NIB	Negative Increment Burst Detect	Negative Increment Burst Detect (Default: 0x0) Indicates that Burst transfer by the on-chip DMA Controller in the negative direction was detected. 1: Indicates that a Burst transfer in the negative direction was detected. 0: Indicates that no Burst transfer in the negative direction was detected.	R/W1C
7	ZIB	Zero Increment Burst Detect	Zero Increment Burst Detect (Default: 0x0) Indicates that Burst transfer by the on-chip DMA Controller without an address increment was detected. 1: Indicates that a Burst transfer without an address increment was detected. 0: Indicates that no Burst transfer without an address increment was detected.	R/W1C
6		Reserved		—
5	PERR	PERR* Detected	PERR* Occurred (Default: 0x0) Indicates that the Parity Error signal (PERR*) was asserted. This bit is a monitor status bit that records assertion of the PERR* signal even if the TX4927 is not accessing PCI. 1: Indicates that the PERR* signal was asserted. 0: Indicates that the PERR* signal was not asserted.	R/W1C
4	SERR	SERR* Detected	SERR* Occurred (Default: 0x0) Indicates that the System Error signal (SERR*) was asserted. This bit is a monitor status bit that records assertion of the SERR* signal even if the TX4927 is not accessing PCI. 1: Indicates that the SERR* signal was asserted. 0: Indicates that the SERR* signal was not asserted.	R/W1C
3	GBE	G-Bus Error Detect	G-Bus Error Detect (Default: 0x0) Indicates that a G-Bus Error occurred in the G-Bus Master cycle of the PCI Controller. This error is indicated when a timeout occurs on the G-Bus. This bit is only set by Master cycle Bus Errors. 1: Indicates that a G-Bus Error was detected. 0: Indicates that no G-Bus Error was detected.	R/W1C

Figure 10.4.42 PCI Controller Status Register (1/2)

Bit	Mnemonic	Field Name	Description	Read/Write
2		Reserved		—
1	IWB	Initiator Write Busy	<p>Initiator Write Busy (Busy: 0x0)</p> <p>Indicates that a Write cycle was in progress when a Write cycle to the PCI Bus was executed.</p> <p>While a Write cycle is in progress, no error status to that Write cycle is reflected. Therefore, this bit is used to confirm the status when it changes from “1” to “0” after the Write cycle ends.</p> <p>1: Indicates that a Write cycle is in progress. 0: Indicates that no Write cycle is in progress.</p>	R
0	E2PDONE	EEPROM Load Done	<p>EEPROM Load Done (Default--)</p> <p>When using EEPROM, this bit indicates that data loading from EEPROM is complete. This bit is set to “1” when the internal process ends even if no EEPROM is connected.</p> <p>1: Indicates that data loading from EEPROM is complete. 0: Indicates that data loading from EEPROM is not complete.</p>	R

Figure 10.4.42 PCI Controller Status Register (2/2)

10.4.45 PCI Controller Interrupt Mask Register (PCICMASK) 0xD178



Bit	Mnemonic	Field Name	Description	Read/Write
31:11		Reserved		—
10	PMEIE	PME Detect Interrupt Enable	PME* Signal Interrupt Enable (Default: 0x0) When in the Host mode, this bit generates an interrupt when input of the PME* signal is detected. 1: Generates an interrupt. 0: Does not generate an interrupt.	R/W
9	TLBIE	Long Burst Transfer Detect Interrupt	Too Long Burst Interrupt Enable (Default: 0x0) This bit generates an interrupt when a Burst transfer by the on-chip DMA Controller exceeding 8 DWORDs was detected. 1: Generates an interrupt. 0: Does not generate an interrupt	R/W
8	NIBIE	Negative Increment Burst Transfer Detect Interrupt Enable	Negative Increment Burst Interrupt Enable (Default: 0x0) This bit generates an interrupt when a negative direction Burst transfer by the on-chip DMA Controller is detected. 1: Generates an interrupt. 0: Does not generate an interrupt.	R/W
7	ZIBIE	Zero Increment Burst Transfer Detect Interrupt Enable	Zero Increment Burst Interrupt Enable (Default: 0x0) This bit generates an interrupt when a Burst transfer by the on-chip DMA Controller without an address increment is detected. 1: Generates an interrupt. 0: Does not generate an interrupt.	R/W
6		Reserved		—
5	PERRIE	PERR* Detect Interrupt Enable	PERR* Interrupt Enable (Default: 0x0) This bit generates an interrupt when the Parity Error signal (PERR*) is asserted. 1: Generates an interrupt. 0: Does not generate an interrupt.	R/W
4	SERRIE	SERR* Detect Interrupt Enable	SERR* Interrupt Enable (Default: 0x0) This bit generates an interrupt when the System Error signal (SERR*) is asserted. 1: Generates an interrupt. 0: Does not generate an interrupt.	R/W
3	GBEIE	G-Bus Bus Error Detect Interrupt Enable	G-Bus Bus Error Interrupt Enable (Default: 0x0) This bit generates an interrupt when a Bus Error is asserted while the PCI Controller is the G-Bus Master. 1: Generates an interrupt. 0: Does not generate an interrupt.	R/W
2:0		Reserved		—

Figure 10.4.43 PCI Controller Interrupt Mask Register

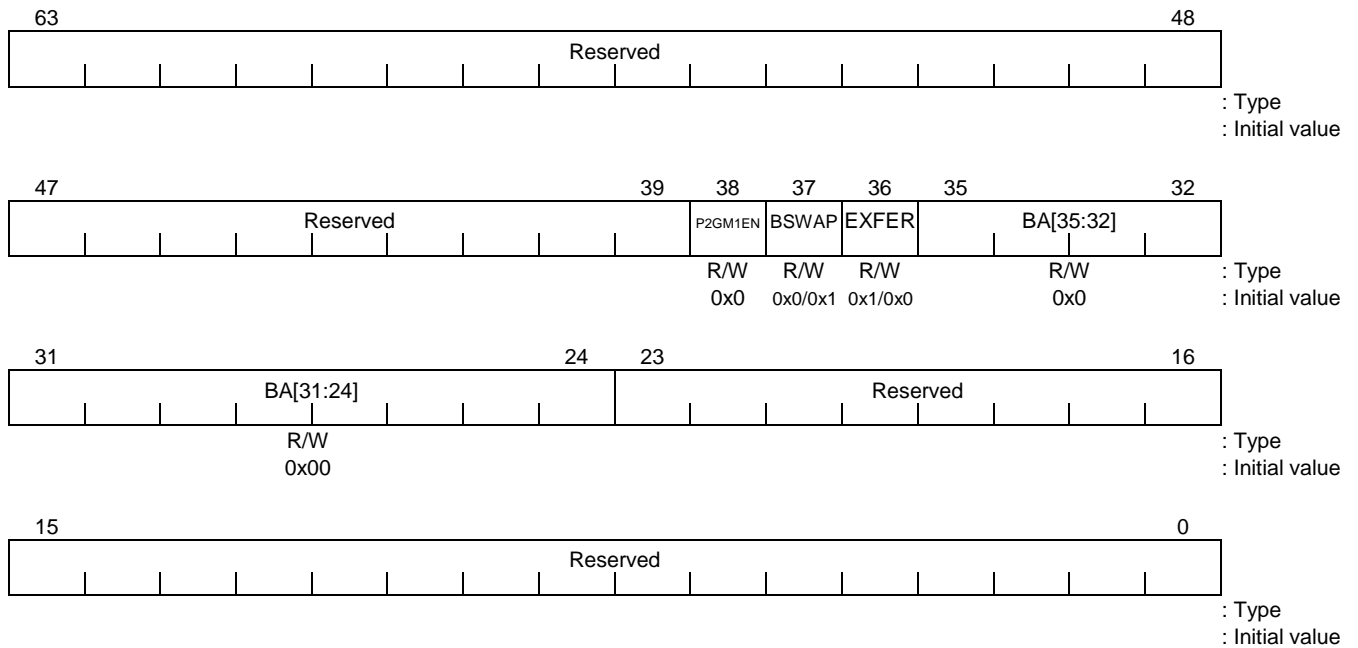
10.4.46 P2G Memory Space 0 G-Bus Base Address Register (P2GM0GBASE) 0xD180



Bit	Mnemonic	Field Name	Description	Read/Write
63:39		Reserved		—
38	P2GM0EN	Memory Space 0 Enable	Target Memory Space 0 Enable (Default: 0x0) Controls whether Memory Space 0 for target access is valid or invalid. When this bit is set to invalid, Writes to the Memory Space 0 Lower Base Address Register or the Memory Space 0 Upper Base Address Register of the PCI Configuration Register become invalid. Also, “0” is returned to Reads as a response. 1: Validates Memory Space 0 for target access. 0: Invalidates Memory Space 0 for target access.	R/W
37	BSWAP	Byte Swap	Byte Swap Disable (Default: Little Endian Mode: 0x1; Big Endian Mode: 0x0) Sets the byte swapping of Memory Space 0 for target access.. 1: Do not perform byte swapping. 0: Perform byte swapping. Please use the default state in most situations. If this bit is changed to “1” when in the Big Endian Mode, the byte order of transfer to Memory Space 0 through DWORD (32-bit) access will not change.	R/W
36	EXFER	Endian Transfer	Endian Transfer (Default: Little Endian Mode: 0x0; Big Endian Mode: 0x1) Sets the Endian Transfer of Memory Space 0 for target access. 1: Performs Endian Transfer. 0: Does not perform Endian Transfer. Please use the default state.	R/W
35:29	BA[35:29]	Base Address	Base Address 0 (Default: 0x000) Sets the G-Bus base bus address of Memory Space 0 for target access. Can set the base address in 512-MB units.	R/W
28:0		Reserved		—

Figure 10.4.44 P2G Memory Space 0 G-Bus Base Address Register

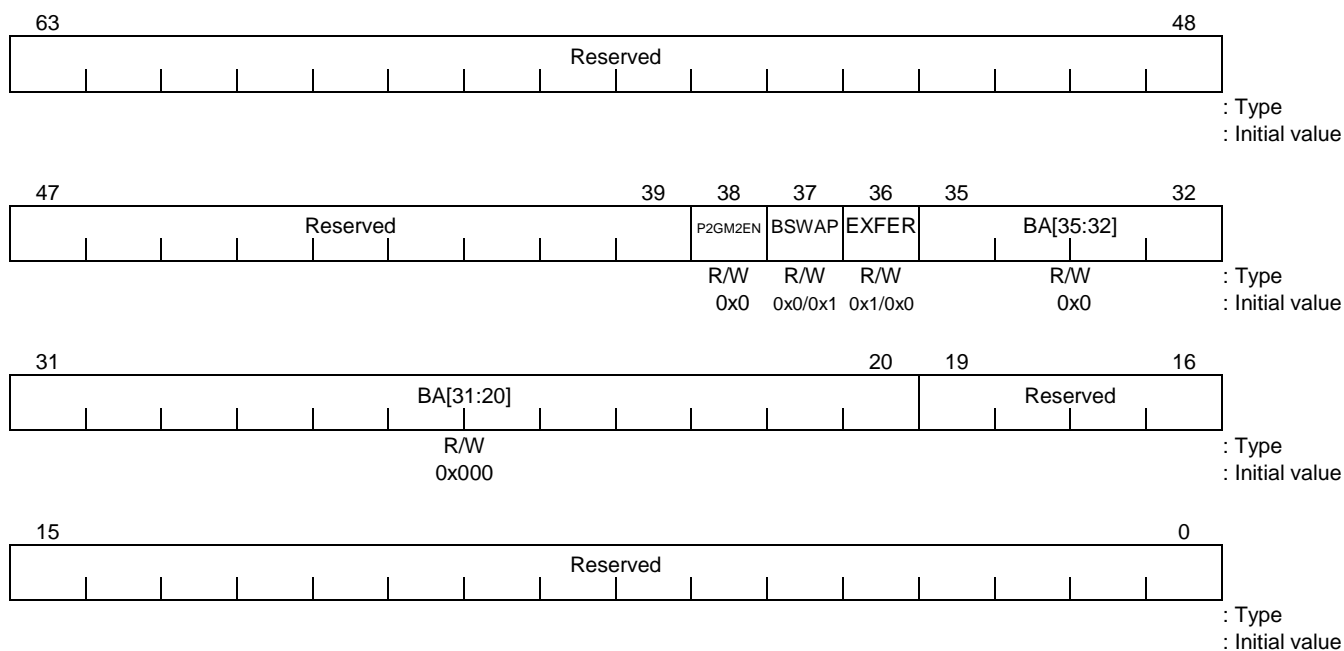
10.4.47 P2G Memory Space 1 G-Bus Base Address Register (P2GM1GBASE) 0xD188



Bit	Mnemonic	Field Name	Description	Read/Write
63:39		Reserved		—
38	P2GM1EN	Memory Space 1 Enable	Target Memory Space 1 Enable (Default: 0x0) Controls whether Memory Space 1 for target access is valid or invalid. When this bit is set to invalid, Writes to the Memory Space 1 Lower Base Address Register or the Memory Space 1 Upper Base Address Register of the PCI Configuration Register become invalid. Also, “1” is returned to Reads as a response. 1: Validates Memory Space 1 for target access. 0: Invalidates Memory Space 1 for target access.	R/W
37	BSWAP	Byte Swap	Byte Swap Disable (Default: Little Endian Mode: 0x1; Big Endian Mode: 0x0) Sets the byte swapping of Memory Space 1 for target access. 1: Do not perform byte swapping. 0: Perform byte swapping. Please use the default state in most situations. If this bit is changed to “1” when in the Big Endian Mode, the byte order of transfer to Memory Space 0 through DWORD (32-bit) access will not change.	R/W
36	EXFER	Endian Transfer	Endian Transfer (Default: Little Endian Mode: 0x0; Big Endian Mode: 0x1) Sets the Endian Transfer of Memory Space 1 for target access. 1: Performs Endian Transfer. 0: Does not perform Endian Transfer. Please use the default state.	R/W
35:24	BA[35:24]	Memory Space Base Address 1	Base Address 0 (Default: 0x0_0000_00) Sets the G-Bus base bus address of Memory Space 1 for target access. Can set the base address in 16-MB units.	R/W
23:0		Reserved		—

Figure 10.4.45 P2G Memory Space 1 G-Bus Base Address Register

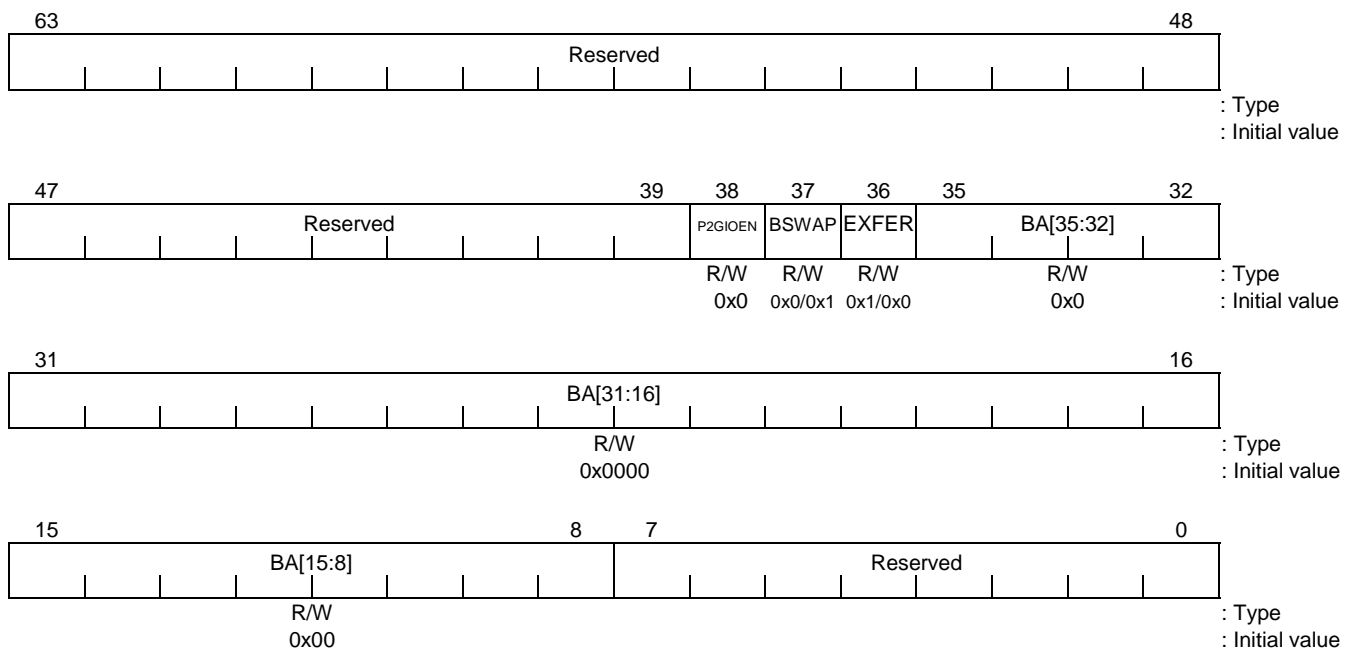
10.4.48 P2G Memory Space 2 G-Bus Base Address Register (P2GM2GBASE) 0xD190



Bit	Mnemonic	Field Name	Description	Read/Write
63:39		Reserved		—
38	P2GM2EN	Memory Space 2 Enable	Target Memory Space 2 Enable (Default: 0x0) Controls whether Memory Space 2 for target access is valid or invalid. When this bit is set to invalid, Writes to the Memory Space 2 Lower Base Address Register or the Memory Space 2 Upper Base Address Register of the PCI Configuration Register become invalid. Also, “0” is returned to Reads as a response. 1: Validates Memory Space 2 for target access. 0: Invalidates Memory Space 2 for target access.	R/W
37	BSWAP	Byte Swap	Byte Swap Disable (Default: Little Endian Mode: 0x1; Big Endian Mode: 0x0) Sets the byte swapping of Memory Space 2 for target access. 1: Do not perform byte swapping. 0: Perform byte swapping. Please use the default state in most situations. If this bit is changed to “1” when in the Big Endian Mode, the byte order of transfer to Memory Space 2 through DWORD (32-bit) access will not change.	R/W
36	EXFER	Endian Transfer	Endian Transfer (Default: Little Endian Mode: 0x0; Big Endian Mode: 0x1) Sets the Endian Transfer of Memory Space 2 for target access. 1: Performs Endian Transfer. 0: Does not perform Endian Transfer. Please use the default state.	R/W
35:20	BA[35:20]	Memory Space Base Address 2	Base Address 2 (Default: 0x000) Sets the G-Bus base bus address of Memory Space 2 for target access. Can set the base address in 1-MB units.	R/W
19:0		Reserved		—

Figure 10.4.46 P2G Memory Space 2 G-Bus Base Address Register

10.4.49 P2G I/O Space G-Bus Base Address Register (P2GIOGBASE) 0xD198

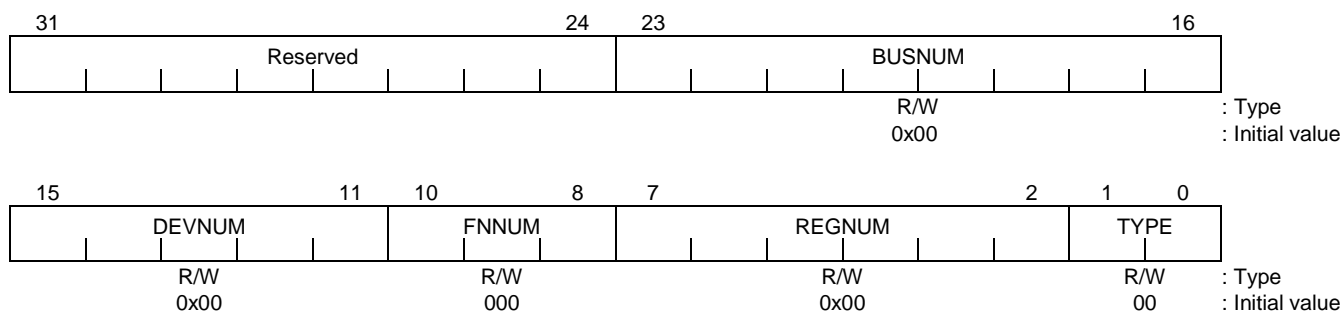


Bit	Mnemonic	Field Name	Description	Read/Write
63:39		Reserved		—
38	P2GIOEN	I/O Space Enable	Target I/O Space Enable (Default: 0x0) Controls whether the I/O Space for target access is valid or invalid. When this bit is set to invalid, Writes to the I/O Space Base Address Register of the PCI Configuration Register become invalid. Also, "0" is returned to Reads as a response. 1: Validates I/O Space for target access. 0: Invalidates I/O Space for target access.	R/W
37	BSWAP	Byte Swap	Byte Swap Disable (Default: Little Endian Mode: 0x1; Big Endian Mode: 0x0) Sets the byte swapping of the I/O Space for target access. 1: Do not perform byte swapping. 0: Perform byte swapping. Please use the default state in most situations. If this bit is changed to "1" when in the Big Endian Mode, the byte order of transfer to the I/O Space through DWORD (32-bit) access will not change.	R/W
36	EXFER	Endian Transfer	Endian Transfer (Default: Little Endian Mode: 0x0; Big Endian Mode: 0x1) Sets the Endian Transfer of the I/O Space for target access. 1: Performs Endian Transfer. 0: Does not perform Endian Transfer. Please use the default state.	R/W
35:8	BA[35:8]	Memory Space Base Address 2	Base Address 2 (Default: 0x000) Sets the G-Bus base bus address of the I/O Space for target access. Can set the base address in 256-byte units.	R/W
7:1		Reserved		—

Figure 10.4.47 P2G I/O Space G-Bus Base Address Register

10.4.50 G2P Configuration Address Register(G2PCFGADRS) 0xD1A0

The operation of any access to this register is undefined when the PCI Controller is in the Satellite mode.



Bit	Mnemonic	Field Name	Description	Read/Write
31:24		Reserved		—
23:16	BUSNUM	Bus Number	Bus Number (Default: 0x00) Indicates the target PCI Bus Number (one of 256).	R/W
15:11	DEVNUM	Device Number	Device Number (Default: 0x00) This field is used to identify the target physical device number. (This is one number out of 32 devices. 21 of these 32 devices are used.) When in the address phase of Type 0 configuration access, AD[31:11] of the upper 21 address lines are used as the IDSEL signal. 0x00: Use AD [11] as IDSEL. 0x01: Use AD [12] as IDSEL. 0x02: Use AD [13] as IDSEL. : : 0x13: Use AD [30] as IDSEL. 0x14: Use AD [31] as IDSEL. 0x15 - 0x1F: Reserved	R/W
10:8	FNNUM	Function Number	Function Number (Default: 000) This field is used to identify the target logic function number (one out of 8).	R/W
7:2	REGNUM	Register Number	Register Number (Default: 0x00) This field is used to identify the DWORD (one out of 64) inside the Configuration Space of the target function	R/W
1:0	TYPE	Type	Type (Default: 00) This field is used to identify the address type in the address phase of the target function configuration cycle. 0x0: Type 0 configuration (Use the AD[31:11] signal as the IDSEL signal.) 0x1: Type 1 configuration (Output all bits unchanged as the address to the AD[] signal.)	R/W

Figure 10.4.48 G2P Configuration Address Register

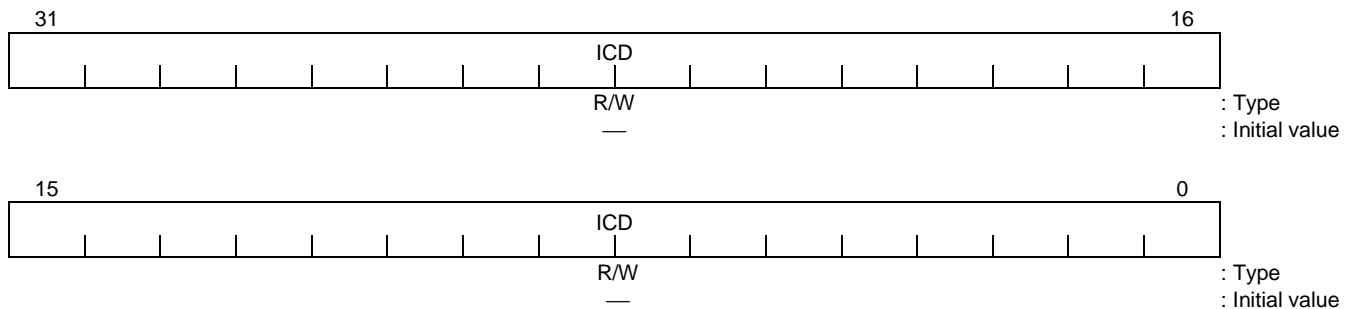
10.4.51 G2P Configuration Data Register (G2PCFGDATA) 0xD1A4

This is the only register that supports Byte access and 16-bit Word access. The upper address bit of the PCI Configuration Space is specified by the G2P Configuration Address Register (G2PCFGADRS). The lower two bits of the address are specified by the lower two bits of the offset address in this register as shown in Figure 10.4.2.

The operation of any access to this register is undefined when the PCI Controller is in the Satellite mode.

Table 10.4.2 PCI Configuration Space Access Address

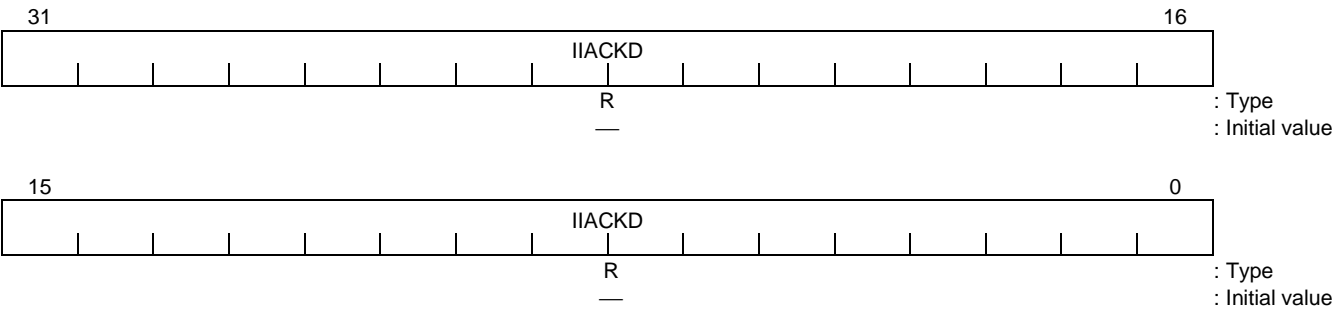
Access Size	Configuration Space Address [1:0]	Offset Address	
		Little Endian Mode	Big Endian Mode
32-bit	00	0xD1A4	0xD1A4
16-bit	00	0xD1A4	0xD1A6
	10	0xD1A6	0xD1A4
8-bit	00	0xD1A4	0xD1A7
	01	0xD1A5	0xD1A6
	10	0xD1A6	0xD1A5
	11	0xD1A7	0xD1A4



Bits	Mnemonic	Field Name	Description	Read/Write
31:0	ICD	Initiator Configuration Data	Initiator Configuration Data Register (Default--) This is a data port that is used when performing initiator PCI configuration access. PCI configuration Read or Write transactions are issued when this register is read to or written from.	R/W

Figure 10.4.49 G2P Configuration Data Register

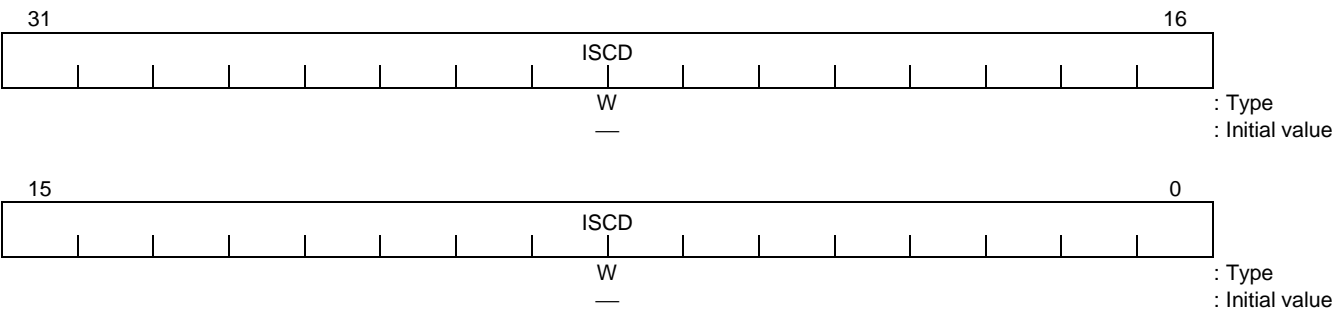
10.4.52 G2P Interrupt Acknowledge Data Register (G2PINTACK) 0xD1C8



Bits	Mnemonic	Field Name	Description	Read/Write
31:0	IIACKD	Initiator Interrupt Acknowledge Address Port	Initiator Interrupt Acknowledge Address Port (Default--) An Interrupt Acknowledge cycle is generated on the PCI Bus when this register is read. The data that is returned by this Read transaction becomes the Interrupt Acknowledge data.	R

Figure 10.4.50 G2P Interrupt Acknowledge Data Register

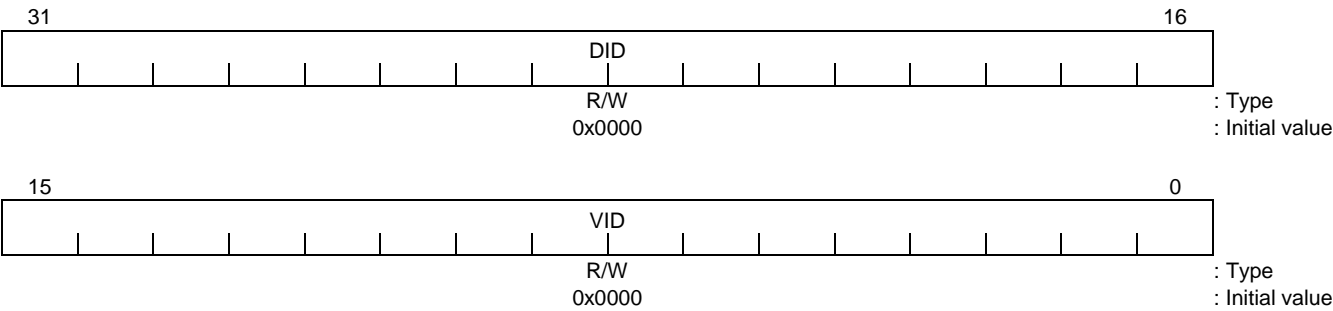
10.4.53 G2P Special Cycle Data Register (G2PSPC) 0xD1CC



Bits	Mnemonic	Field Name	Description	Read/Write
31:0	ISCD	Initiator Special Cycle Data Port	Initiator Special Cycle Data Port (Default--) When this register is written to, Special Cycles are generated on the PCI Bus depending on the data that is written.	W

Figure 10.4.51 G2P Special Cycle Data Register

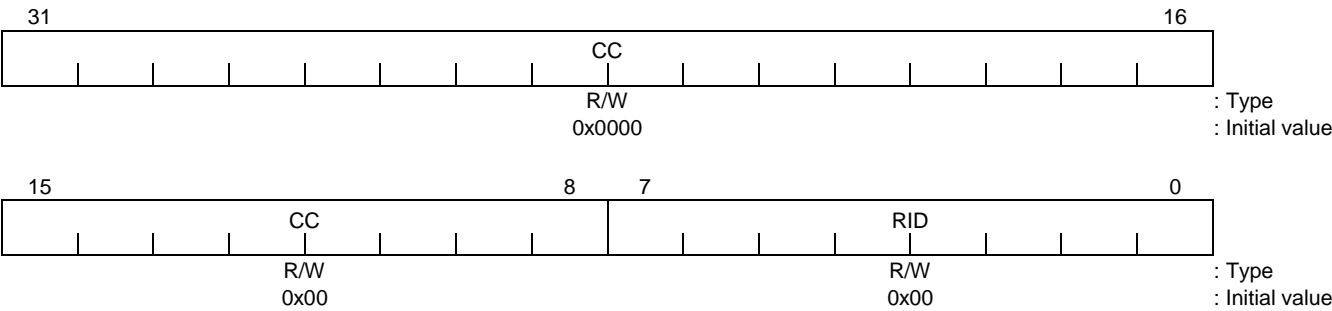
10.4.54 Configuration Data 0 Register (PCICDATA0) 0xD1D0



Bits	Mnemonic	Field Name	Description	Read/Write
31:16	DID	Device ID	Device ID (Default: 0x0000) This is the data loaded in the Device ID Register of the PCI Configuration Space.	R/W
15:0	VID	Vendor ID	Vendor ID (Default: 0x0000) This is the data loaded in the Vendor ID Register of the PCI Configuration Space.	R/W

Figure 10.4.52 ID Register

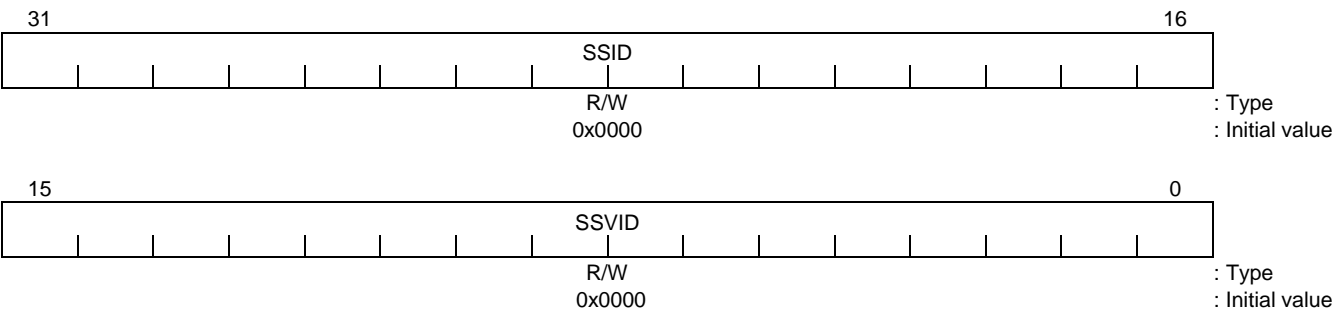
10.4.55 Configuration Data 1 Register (PCICDATA1) 0xD1D4



Bis	Mnemonic	Field Name	Description	Read/Write
31:8	CC	Class Code	Class Code (Default: 0x000000) This is the data loaded in the Class Code Register of the PCI Configuration Space.	R/W
7:0	RID	Revision ID	Revision ID (Default: 0x00) This is the data loaded in the Revision ID Register of the PCI Configuration Space.	R/W

Figure 10.4.53 Class Code/Revision ID Register

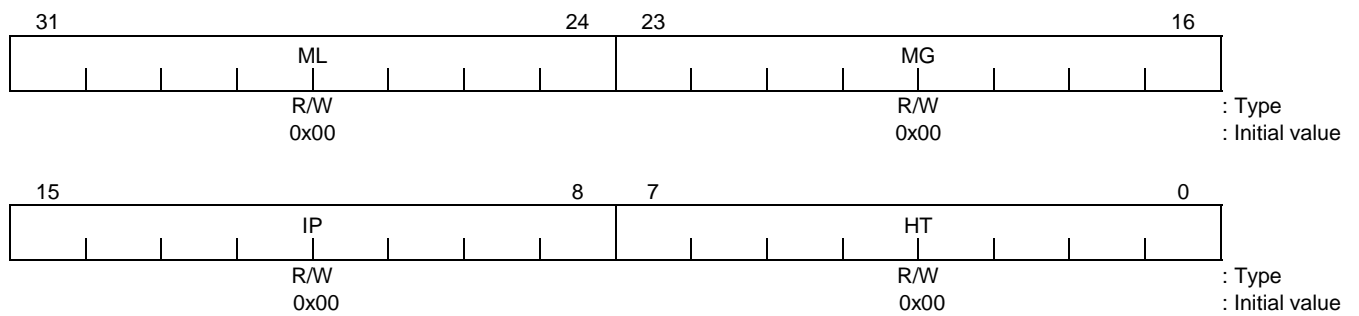
10.4.56 Configuration Data 2 Register (PCICDATA2) 0xD1D8



Bits	Mnemonic	Field Name	Description	Read/Write
31:16	SSID	Sub System ID	Subsystem ID (Default: 0x0000) This is the data loaded in the Sub System ID Register of the PCI Configuration space.	R/W
15:0	SSVID	Sub System Vendor ID	Subsystem Vendor ID (Default: 0x0000) This is the data loaded in the Sub System Vendor ID Register of the PCI Configuration space.	R/W

Figure 10.4.54 Sub System ID Register

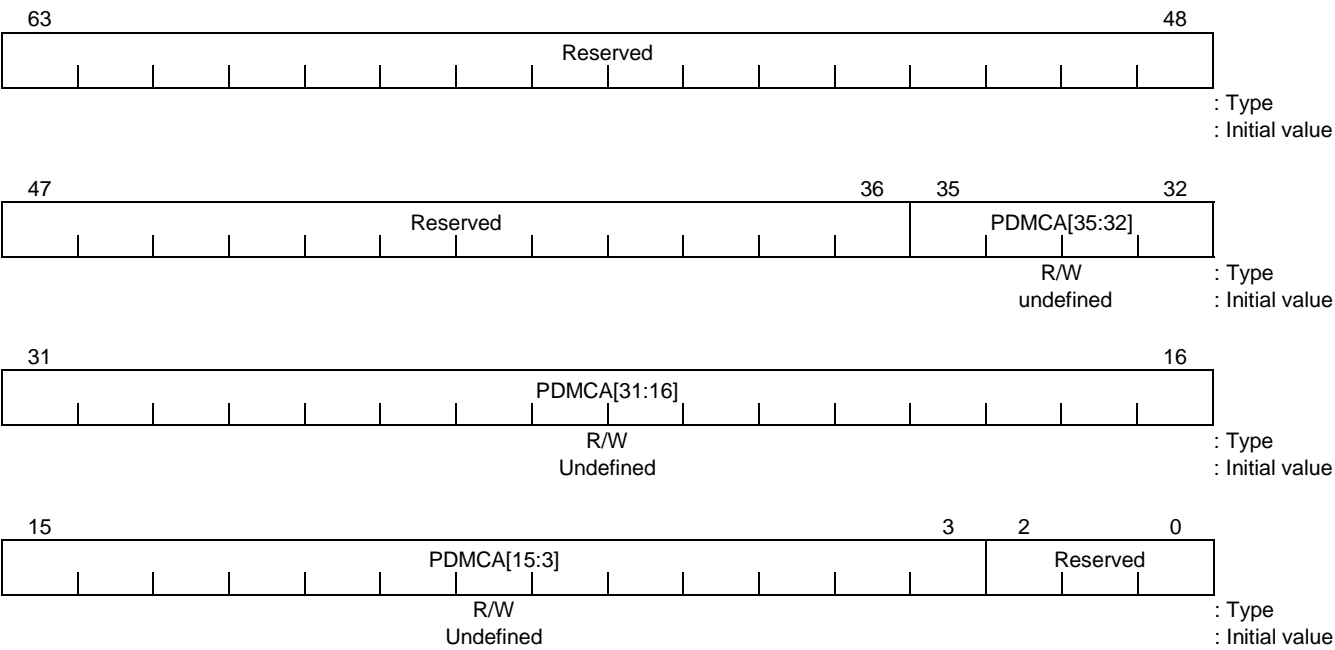
10.4.57 Configuration Data 3 Register (PCICDATA3) 0xD1DC



Bits	Mnemonic	Field Name	Description	Read/Write
31:24	ML	Maximum Latency	Max_Lat (Maximum Latency) (Default: 0x00) This is the data loaded in the Max_Lat Register of the PCI Configuration Space.	R/W
23:16	MG	Minimum Grant	Min_Gnt (Minimum Grant) (Default: 0x00) This is the data loaded in the Min_Gnt Register of the PCI Configuration Space.	R/W
15:8	IP	Interrupt Pin	Interrupt Pin (Default: 0x00) This is the data loaded in the Interrupt Pin Register of the PCI Configuration Space.	R/W
7:0	HT	Header Type	Header Type (Default: 0x00) This is the data loaded in the Header Type Register of the PCI Configuration Space.	R/W

Figure 10.4.55 PCI Configuration 2 Register

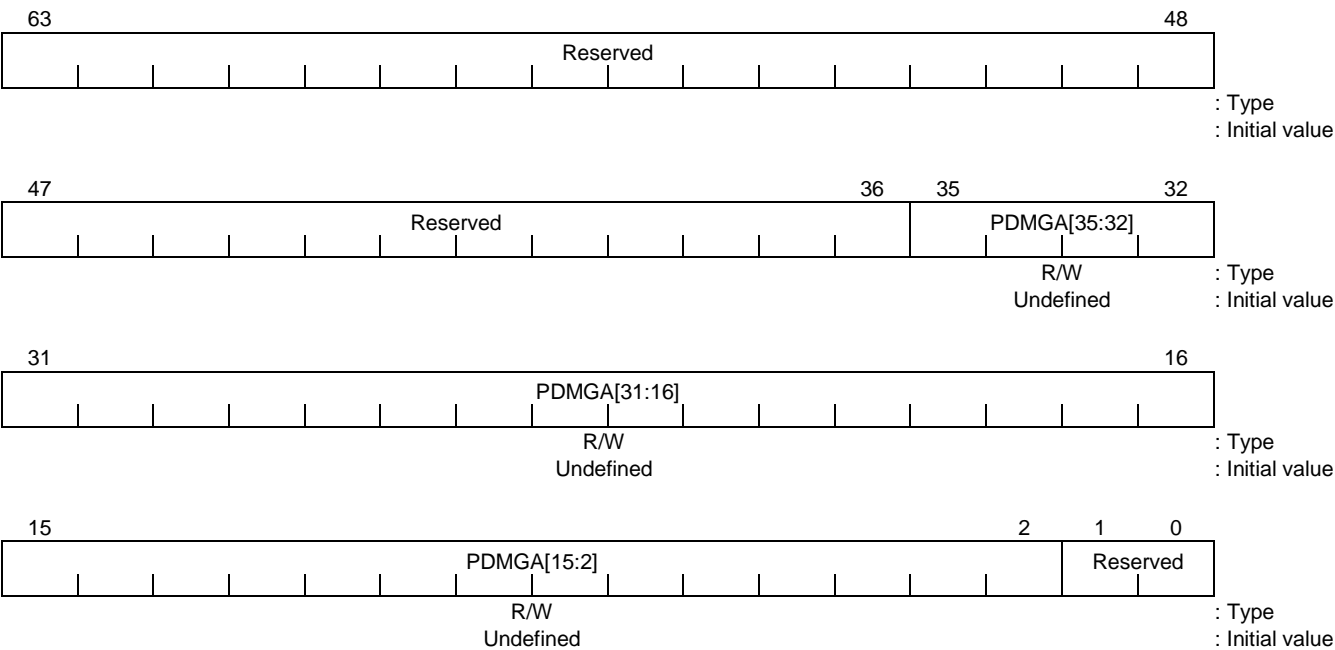
10.4.58 PDMAC Chain Address Register (PDMCA) 0xD200



Bits	Mnemonic	Field Name	Description	Read/Write
63:36		Reserved		—
35:3	PDMCA	Chain Address	PDMAC Chain Address (Default is undefined) The address of the next PDMAC Data Command Descriptor to be read is specified by a G-Bus physical address on a 64-bit address boundary. This register value is held without being affected by a Reset. 0 value judgement is performed when the lower 32 bits of this register are rewritten. DMA transfer is automatically initiated if the result is not "0".	R/W
2:0		Reserved		—

Figure 10.4.56 PDMAC Chain Address Register

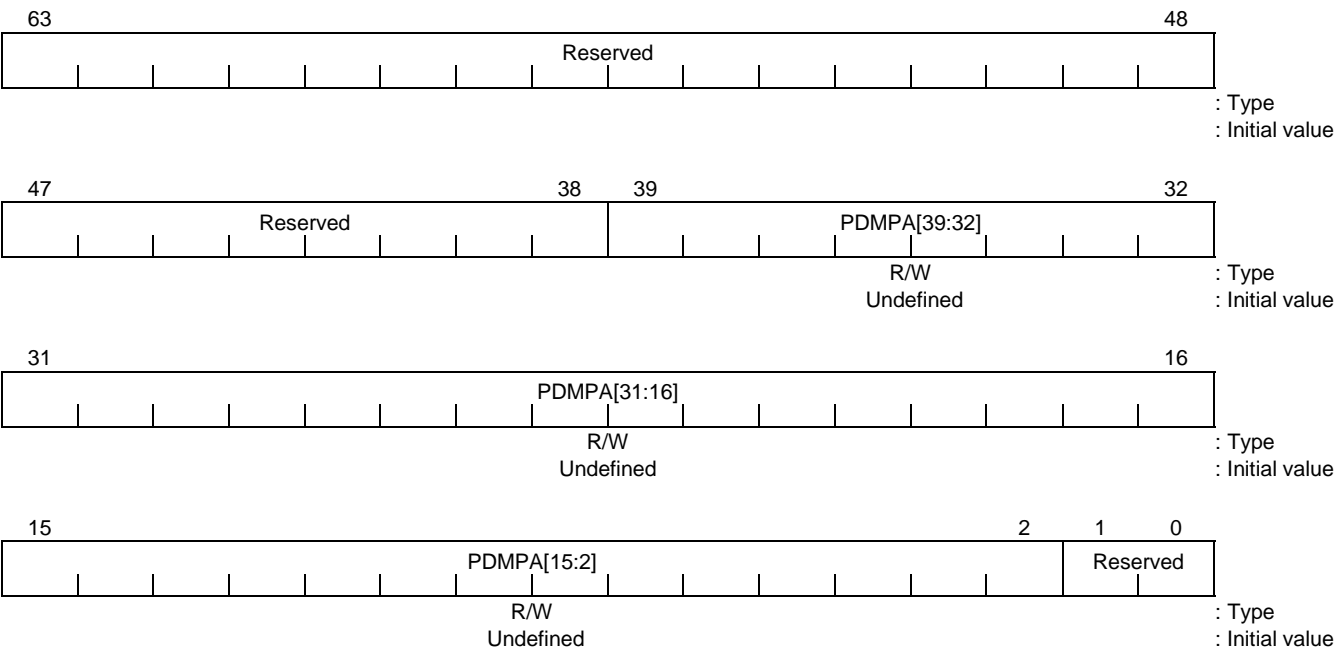
10.4.59 PDMAC G-Bus Address Register (PDMGA) 0xD208



Bits	Mnemonic	Field Name	Description	Read/Write
63:36		Reserved		—
35:2	PDMGA	G-Bus Address	PDMAC G-Bus Address (Default is undefined) The G-Bus DMA transfer address is specified by a G-Bus physical address on a 32-bit address boundary. This register value is used for G-Bus Read access during DMA transfer from the G-Bus to the PCI Bus, or it is used for G-Bus Write access during DMA transfer from the PCI Bus to the G-Bus. This register value is held without being affected by a Reset.	R/W
1:0		Reserved		—

Figure 10.4.57 G-Bus Address Register

10.4.60 PDMAC PCI Bus Address Register (PDMPA) 0xD210

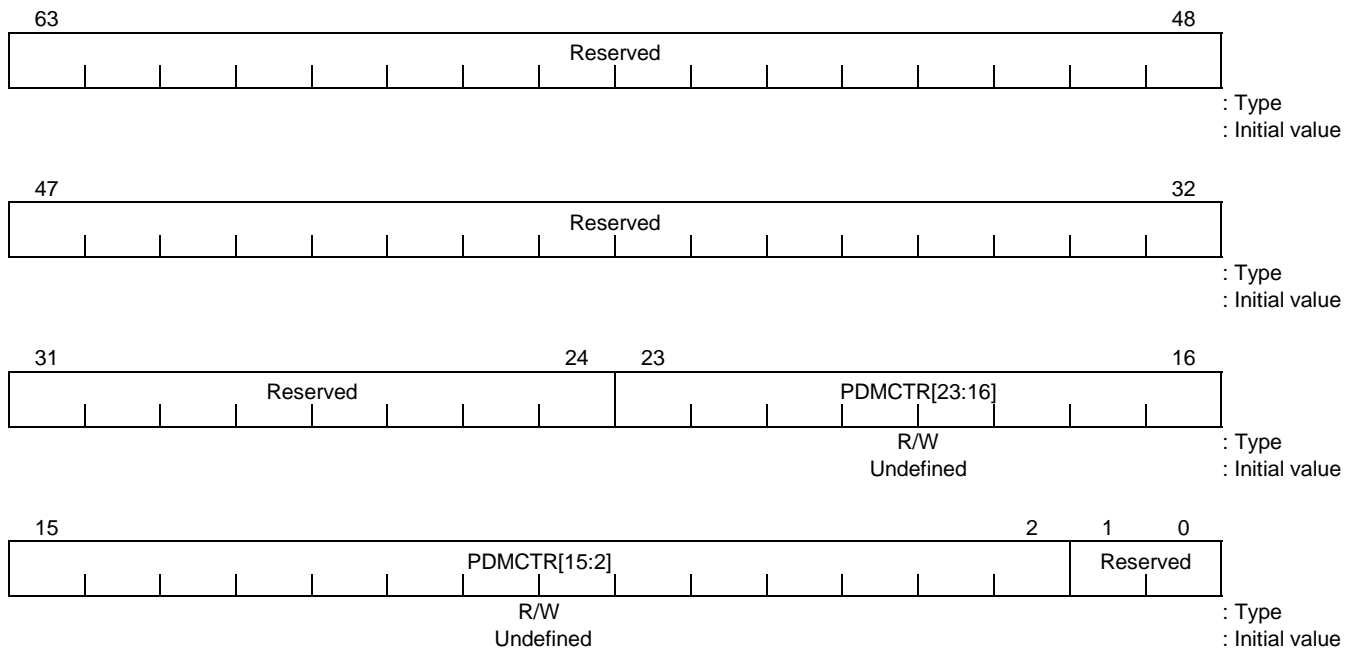


Bits	Mnemonic	Field Name	Description	Read/Write
63:38		Reserved		—
39:2	PDMPA	PCI Bus Address	PDMAC PCI-Bus Address (Default is undefined) The PCI Bus DMA transfer address is specified by a PCI Bus physical address on a 32-bit address boundary. This register value is held without being affected by a Reset. Note: This register value is used for PCI Bus Write access during DMA transfer from the G-Bus to the PCI Bus, or it is used for PCI Bus Read access during DMA transfer from the PCI Bus to the G-Bus.	R/W
1:0		Reserved		—

Figure 10.4.58 PCI Bus Address Register

10.4.61 PDMAC Count Register (PDMCTR)

0xD218

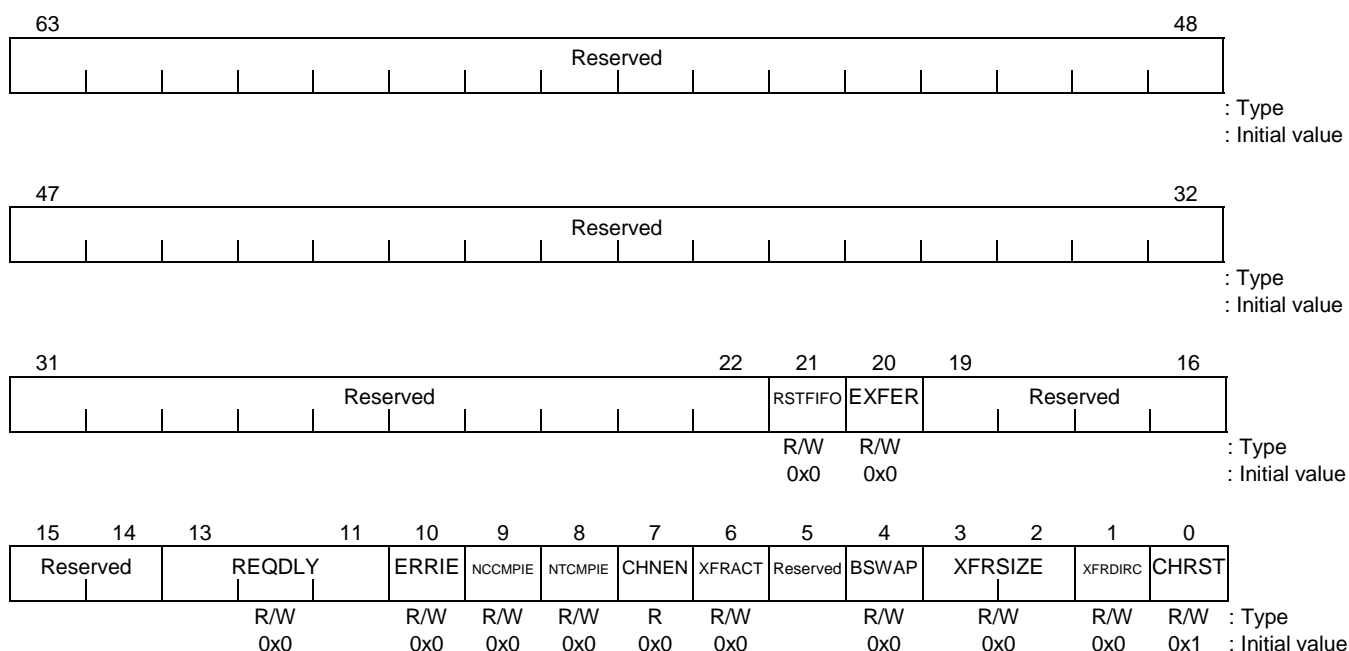


Bits	Mnemonic	Field Name	Description	Read/Write
63:24		Reserved		—
23:2	PDMCTR	Transfer Byte Count	PDMAC Transfer Count (Default is undefined) Sets an uncoded 24-bit transfer byte count in 32-bit word units. Also, the setting of this register must always be a multiple of the transfer size specified inside the PDMAC Control Register. No data transfer is performed if a count of "0" is set. This byte count value is calculated from the transferred byte size as the PDMAC performs a DMA transfer. This register value is held without being affected by a Reset.	R/W
1:0		Reserved		—

Figure 10.4.59 Count Register

10.4.62 PDMAC Control Register (PDMCFG)

0xD220



Bit	Mnemonic	Field Name	Description	Read/Write
63:22		Reserved		—
21	RSTFIFO	Reset FIFO	Reset FIFO (Default: 0x0) Initializes the Read pointer and Write pointer to the FIFO in the PDMAC, and sets the FIFO hold count to "0". Please use the software to clear this bit when it is set. This is a function for a diagnosis. Usually, it is not used. 1: Performs FIFO reset. 0: Does not perform FIFO reset.	R/W
20	EXFER	Endian Transfer	Endian Transfer (Default: 0x0) Specifies whether to perform Endian transfer. Please use the default as is. Set up EXFER as follows according to a Endian setup of G-Bus. 1: G-Bus in Little Endian 0: G-Bus in Big Endian	R/W
19:14		Reserved		—
13:11	REQDLY	Request Delay Time	Request Delay (Default: 0x0) G-Bus transactions for DMA transfer must be performed separated at least by the interval this field specifies. 000: Continuously try to perform G-Bus transfer. 001: 16 G-Bus clocks 010: 32 G-Bus clocks 011: 64 G-Bus clocks 100: 128 G-Bus clocks 101: 256 G-Bus clocks 110: 512 G-Bus clocks 111: 1024 G-Bus clocks	R/W
10	ERRIE	Error Detect Interrupt Enable	Interrupt Enable on Error (Default: 0x0) 1: PDMAC generates an error during error detection. 0: PDMAC does not generate an error during error detection.	R/W
9	NCCMPIE	Normal Chain Complete Interrupt Enable	Interrupt Enable on Chain Done (Default: 0x0) 1: PDMAC generates an interrupt when the current chain is complete. 0: PDMAC does not generate an interrupt when the current chain is complete.	R/W

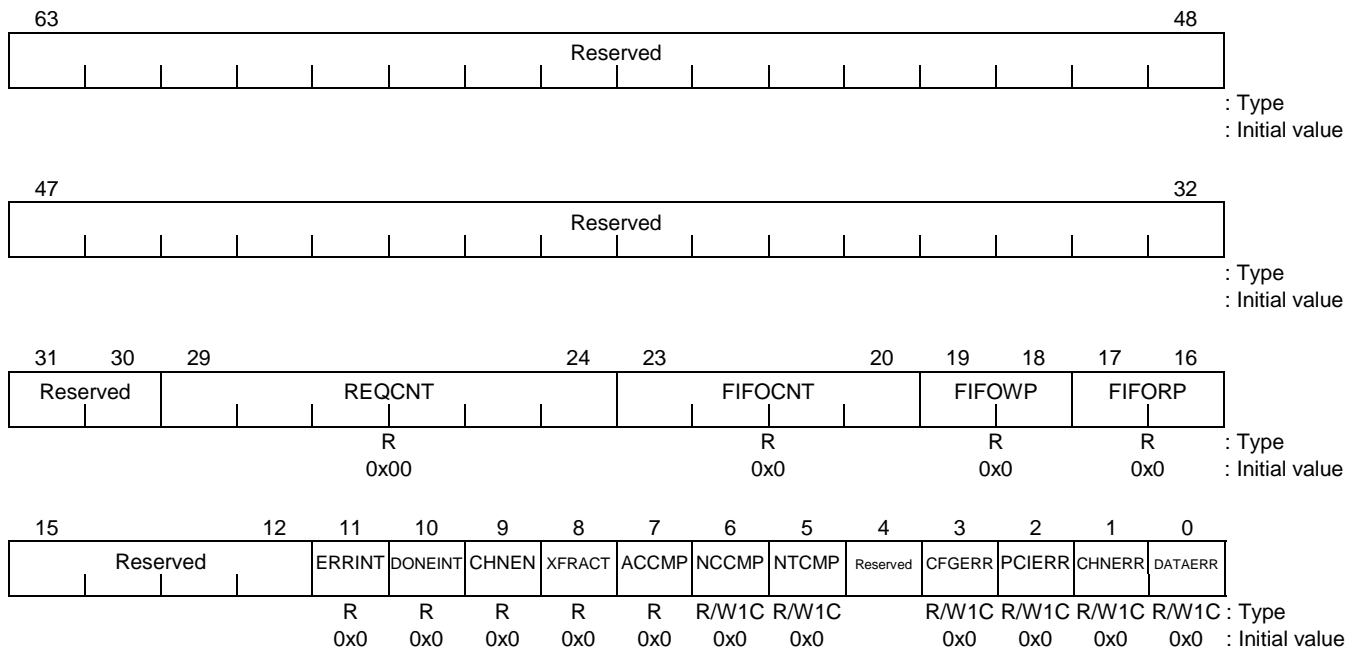
Figure 10.4.60 PDMAC Control Register (1/2)

Bit	Mnemonic	Field Name	Description	Read/Write
8	NTCMPIE	Normal Data Transfer Complete Interrupt Enable	Interrupt Enable on Transfer Done (Default: 0x0) 1: PDMAC generates an interrupt when the current data transfer is complete. 0: PDMAC does not generate an interrupt when the current data transfer is complete.	R/W
7	CHNEN	Chain Enable	Chain Enable (Default: 0x0) (Read Only) When the current data transfer is complete, this field reads the next data command Descriptor from the address indicated by the PDMAC Chain Address Register then indicates whether to continue the transfer or not. This bit is only set to "1" when either a CPU Write process or a Descriptor Read process sets a value other than "0" in the PDMAC Chain Address Register. This bit is cleared to "0" if either the Channel Reset bit is set, or "0" is set in the PDMAC Chain Address Register by a CPU Write or a Descriptor Read process. The above 0 value judgement is not performed when the TX49/H2 core stores the upper 32 bits in the PDMAC Chain Address Register. 1: Reads the next data command Descriptor. 0: Does not read the next data command Descriptor.	R
6	XFRACT	Transfer Active	Transfer Active (Default: 0x0) Specifies whether to perform DMA transfer or not. Setting this bit after setting the appropriate value in the register group initiates DMA data transfer. This bit is not set if the PDMAC Count Register value is "0" and the Chain Enable bit is cleared when "1" is written to this bit. Even when a value other than "0" is written to the Chain Address Register, "1" is set to this bit and DMA transfer automatically starts. The above 0 value judgement is not performed when the TX49/H2 core stores the upper 32 bits in the PDMAC Chain Address Register. Data transfer will be stopped after a short delay if this bit is cleared while the data transfer is in progress. This bit is automatically cleared to "0" either when data transfer ends normally or is stopped by an error. Never clear XFRACT by software, because it stops guaranteeing a normal operation. 1: Perform data transfer. 0: Do not perform data transfer.	R/W
5		Reserved		—
4	BSWAP	Byte Swap Within DWORD	Swap Bytes in DWORD (Default: 0x0) Specifies whether to perform 32-bit data byte swapping. Please leave this bit at "0" for normal usage. Setting this bit when in the Big Endian mode executes data transfer so the byte order of the 32-bit data on the PCI Bus (which is Little Endian) does not change. 1: Swap the byte order of each 32-bit DWORD data, then transfer. 0: Transfer without swapping the byte order of each 32-bit DWORD data.	R/W
3:2	XFRSIZE	Transfer Size	Transfer Size (Default: 0x0) Specifies the data transfer size in one G-Bus transaction on the G-Bus. 00: 1 DWORD (32-bit) 01: 1 QWORD (64-bit) 10: 4 QWORD (Burst transfer) 11: Reserved	R/W
1	XFRDIRC	Transfer Direction	Transfer Direction (Default: 0x0) Specifies the DMA data transfer direction. 1: Transfers data from the G-Bus to the PCI Bus. 0: Transfers data from the PCI Bus to the G-Bus.	R/W
0	CHRST	Channel Reset	Channel Reset (Default: 0x1) Resets the DMA channel. This bit must be cleared by the software in advance so the channel can start the data transfer. This reset function is not supported when PDMAC is in operation. Ensure that the Transfer Active (XFRACT) bit in the PDMSTATUS register is cleared prior to resetting the DMA channel. For chained DMA, also ensure either the Abnormal Chain Complete (ACCOMP) or Normal Chain Complete (NCCMP) bit in the PDMSTATUS register is set. 1: All logic and State Machines are reset. 0: The channel becomes valid.	R/W

Figure 10.4.60 PDMAC Control Register (2/2)

10.4.63 PDMAC Status Register (PDMSTATUS)

0xD228



Bit	Mnemonic	Field Name	Description	Read/Write
63:30		Reserved		—
29:24	REQCNT	Request Delay Time Counter	Request Delay Counter (Default: 0x00) This field indicates the request delay time counter value as $16 \times n$ when the 6-bit value of this field is n .	R
23:20	FIFOCNT	FIFO Hold Count	FIFO Valid Entry Count (Default: 0x0) This field indicates the number of bytes that was written in the FIFO but not yet read. This is a diagnostic function.	R
19:18	FIFOWP	FIFO Write Pointer	FIFO Write Pointer (Default: 0x0) This field indicates the next Write position in the FIFO. This is a diagnostic function.	R
17:16	FIFORP	FIFO Read Pointer	FIFO Read Pointer (Default: 0x0) This field indicates the next Read position in the FIFO. This is a diagnostic function.	R
15:12		Reserved		—
11	ERRINT	Error Interrupt Status	Error Interrupt Status (Default: 0x0) Indicates whether to signal an error interrupt. 1: An error interrupt request exists. 0: No error interrupt request exists.	R
10	DONEINT	Normal Transfer Complete Interrupt Status	Normal Transfer Complete Interrupt Status (Default: 0x0) Indicates whether a Normal Transfer Complete Interrupt is signaled. This bit becomes "1" when either the Normal Chain Complete bit (NCCMP) is set and the Normal Chain Complete Interrupt Enable bit (NCCMPIE) is set, or when the Normal Data Transfer Complete bit (NTCMP) is set and the Normal Data Transfer Complete Interrupt Enable bit (NTCMPPIE) is set. 1: A Normal Transfer Complete Interrupt request exists. 0: No Normal Transfer Complete Interrupt request exists.	R
9	CHNEN	Chain Enable	Chain Enable (Default: 0x0) This bit is a copy of the Chain Enable bit in the PDMAC Control Register.	R

Figure 10.4.61 Status Register (1/2)

Bit	Mnemonic	Field Name	Description	Read/Write
8	XFRACT	Transfer Active	Transfer Active (Default: 0x0) This bit is a copy of the Transfer Active bit in the PDMAC Control Register.	R
7	ACCMP	Abnormal Chain Completion	Abnormal Chain Complete (Default: 0x0) 1: Indicates that the Chain transfer ended in an error state. In other words, this reflects an OR operation of the PDMAC Status Register bits [3:0]. 0: Indicates that no error has occurred in the Chain transfer since the previous error bit was cleared. Note: Bits [3:0] of the PDMAC Status Register must be cleared in order to clear this bit.	R
6	NCCMP	Normal Chain Completion	Normal Chain Complete (Default: 0x0) 1: Indicates that the Chain transfer ended in the Normal state. 0: Indicates that Chain transfer has not ended since this bit was previously cleared.	R/W1C
5	NTCMP	Normal Data Transfer Complete	Normal Data Transfer Complete (Default: 0x0) 1: Indicates that the data transfer specified by the PDMAC Register ended in the Normal state. 0: Indicates that data transfer has not ended since this bit was previously cleared.	R/W1C
4		Reserved		—
3	CFGERR	Configuration Error	Configuration Error (Default: 0x0) 1: Indicates that either the current setting of the control portion in the Control Register and the Address/Count Register are not consistent with each other or the PDMAC stipulation is not being obeyed. DMA transfer stops. 0: Indicates that the current setting of the control portion in the Control Register can be tolerated.	R/W1C
2	PCIERR	PCI Fatal Error	PCI Fatal Error (Default: 0x0) 1: Indicates that an error was signaled on the PCI Bus during the Chain process. 0: Indicates that no error has been signaled on the PCI Bus since this bit was previously cleared.	R/W1C
1	CHNERR	G-Bus Chain Error	G-Bus Chain Bus Error (Default: 0x0) 1: Indicates that a G-Bus error occurred during the Chain process. DMA transfer stops. 0: Indicates that no G-Bus error has occurred during the Chain process since this bit was cleared.	R/W1C
0	DATAERR	G-Bus Data Error	G-Bus Data Bus Error (Default: 0x0) 1: Indicates that a G-Bus error occurred during the data transfer process. DMA transfer stops. 0: Indicates that no G-Bus error has occurred during the data transfer process since this bit was cleared.	R/W1C

Figure 10.4.61 Status Register (2/2)

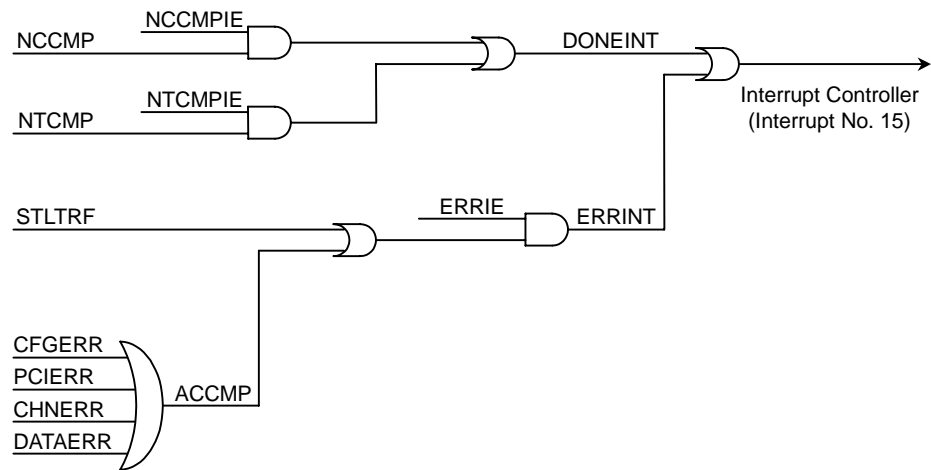


Figure 10.4.62 PDMAC Interrupt Signaling

10.5 PCI Configuration Space Register

The PCI Configuration Space Register is accessed using PCI Configuration cycles by way of an external PCI host device only when in the Satellite mode. Table 10.5.1 lists registers contained within the PCI Configuration Space Register. The registers in the table with a shaded background are those whose values can be rewritten using EEPROM. (See 10.3.14.)

Registers at addresses 0x00 through 0x41 can use the corresponding PCI Controller Control Register to access from the TX49/H2 core when in the Host mode. Please refer to the explanation of the corresponding PCI Controller Control registers for more information about these registers. This section only describes the registers that are accessed from the PCI Configuration Space.

Also, it is possible to read some of the fields in the Status Register and PMCSR register from the Satellite Mode PCI Status Register.

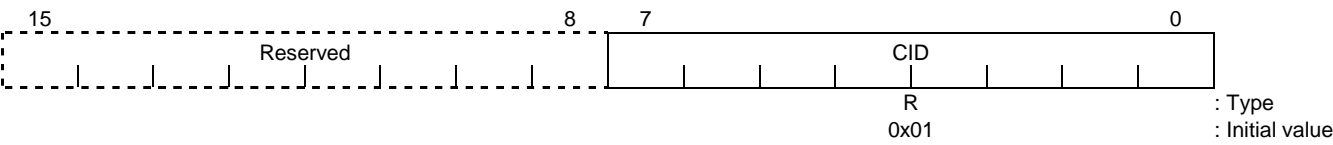
Please refer to the PCI Bus Specifications for more information on the PCI Configuration Register.

Table 10.5.1 PCI Configuration Space Register

Address	3116		150		Corresponding Register
00h	Device ID			Vendor ID	PCIID
04h	Status			Command	PCISTATUS
08h	Class Code			Revision ID	PCICCREV
0Ch	BIST	Header Type	Latency Timer	Cache Line Size	PCICFG1
10h	Memory Space 0 Lower Base Address				P2GM0PLBASE
14h	Memory Space 0 Upper Base Address				P2GM0PUBASE
18h	Memory Space 1 Lower Base Address				P2GM1PLBASE
1Ch	Memory Space 1 Upper Base Address				P2GM1PUBASE
20h	Memory Space 2 Base Address				P2GM2PBASE
24h	I/O Space Base Address				P2GIOPBASE
28h	Reserved				—
2Ch	Subsystem ID		Subsystem Vendor ID		PCISID
30h	Reserved				—
34h	Reserved			Capabilities Pointer (Cap_Ptr)	PCICAPPTR
38h	Reserved				—
3Ch	Max_Lat	Min_Gnt	Interrupt Pin	Interrupt Line	PCICFG2
40h	Reserved		Retry Timeout Value	TRDY Timeout Value	G2PTOCNT
44h-DBh	Reserved				—
DCh	Power Management Capabilities (PMC)		Next Item Ptr (Next_Item_Ptr)	Capability ID (Cap_ID)	—
E0h	Reserved	Reserved	Power Management Control/Status Register (PMCSR)		—
E4h-FFh	Reserved				—

10.5.1 Capability ID Register (Cap_ID)

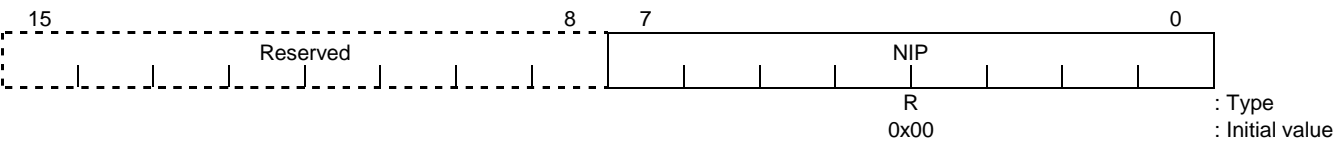
0xDC



Bits	Mnemonic	Field Name	Description	Read/Write
15:8		Reserved		—
7:0	CID	Capability ID	Capability ID (Default: 0x01) Indicates that a list is the link list of the Power Management Register.	R

Figure 10.5.1 Capability ID Register

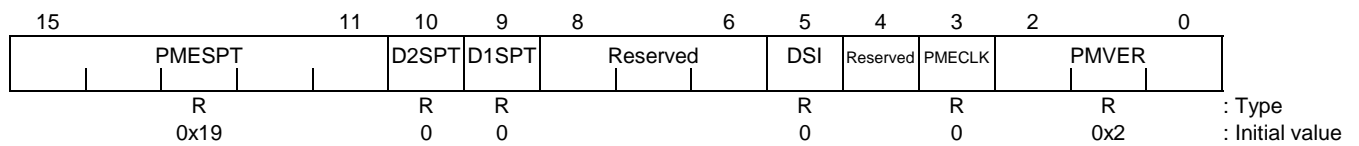
10.5.2 Next Item Pointer Register (Next_Item_Ptr) 0xDD



Bits	Mnemonic	Field Name	Description	Read/Write
15:8		Reserved		—
7:0	NIP	Next Item Pointer	Next Item Pointer (Default: 0x0) This is the Next Item pointer. Indicates the end of a list.	R

Figure 10.5.2 Next Item Pointer Register

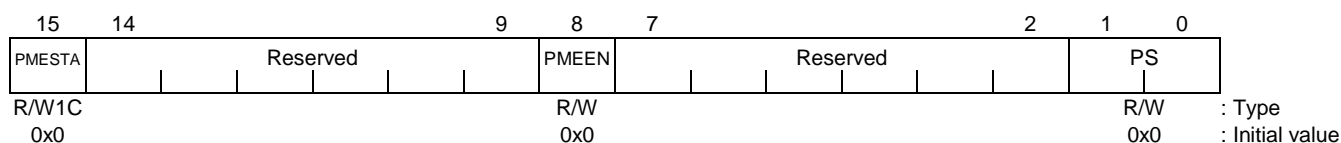
10.5.3 Power Management Capability Register (PMC) 0xDE



Bit	Mnemonic	Field Name	Description	Read/Write
15:11	PMESPT	PME Output Support	PME_ Support (Fixed Value: 0x09) Indicates that the PME* signal can be output from the state where the bit is set to "1". Bit 15: Can output the PME* signal from the D3cold state. Bit 14: Can output the PME* signal from the D3hot state. Bit 13: Can output the PME* signal from the D2 state. Bit 12: Can output the PME* signal from the D1 state. Bit 11: Can output the PME* signal from the D0 state. Note: With the TX4927 PCI Controller, it is possible to output the PME* signal from the D0 and the D3hot states.	R
10	D2SPT	D2 Support	D2_ Support (Fixed Value: 0) 0: Indicates that the D2 state is not supported.	R
9	D1SPT	D1 Support	D1_ Support (Fixed Value: 0) 0: Indicates that the D1 state is not supported.	R
8:6		Reserved		—
5	DSI	DSI	DSI (Fixed Value: 0) 0: Indicates that Device Specific Initialization is not required.	R
4		Reserved		—
3	PMECLK	PME Clock	PME Clock (Fixed Value: 0) 0: Indicates that the PCI Clock is not required to assert the PME* signal.	R
2:0	PMVER	Power Management I/F Version	Version (Fixed Value: 0x2) 2: Indicates compliance with "PCI Power Management Interface Specification" Version 1.1.	R

Figure 10.5.3 PMC Register

10.5.4 Power Management Control/Status Register (PMCSR) 0xE0



Bit	Mnemonic	Field Name	Description	Read/Write
15	PMESTA	PME Status	PME_Status (Default: 0x0) Indicates the existence of a PME (Power Management Event) . 1: There is a PME. 0: There is no PME. The value of this bit becomes "1" when Writing a "1" to the PME bit (P2GCFG.PME) of the P2G Configuration Register. This bit is cleared when the Host Bridge writes a "1". It is possible to signal a PME* Clear Interrupt at this time.	R/W1C
14:9		Reserved		—
8	PMEEN	PME Enable	PME_En (Default: 0x0) Sets PME* signal assertion to enable or disable. 1: Enables assertion of the PME* signal. 0: Disables assertion of the PME* signal. The PME_En set bit of the P2G Status Register (P2GSTATUS.PMEES) is set when this bit is set. At this time, it is possible to signal the PME_En set interrupt.	R/W
7:2		Reserved		—
1:0	PS	Power State	PowerState (Default: 0x0) Sets the Power Management state. The Power Management State Change bit (P2GSTATUS.PMSC) of the P2G Status Register is set when the value of this field is changed. It also becomes possible to generate a Power State Change Interrupt at this time. The TX4927 can read the value of this field from the PowerState field (PCISSTATUS.PS) of the Satellite Mode PCI Status Register. 00b: D0 (no change) 01b: D1 :Reserved 10b: D2 :Reserved 11b: D3hot	R/W

Figure 10.5.4 PMCSR Register

11. Serial I/O Port

11.1 Features

The TX4927 asynchronous Serial I/O (SIO) interface has two full duplex UART channels (SIO0 and SIO1). SIO has the following features.

- (1) Full duplex transmission (simultaneous transmission and reception)
- (2) On-chip baud rate generator
- (3) Modem flow control (CTS/RTS)
- (4) FIFO
 - Transmit FIFO: 8 bits \times 8 stages
 - Reception FIFO: 13 bits \times 16 stages (data: 8 bits, status: 5 bits)
- (5) Supports DMA transfer
- (6) Supports multi-controller systems
 - Supports Master/Slave operation

11.2 Block Diagram

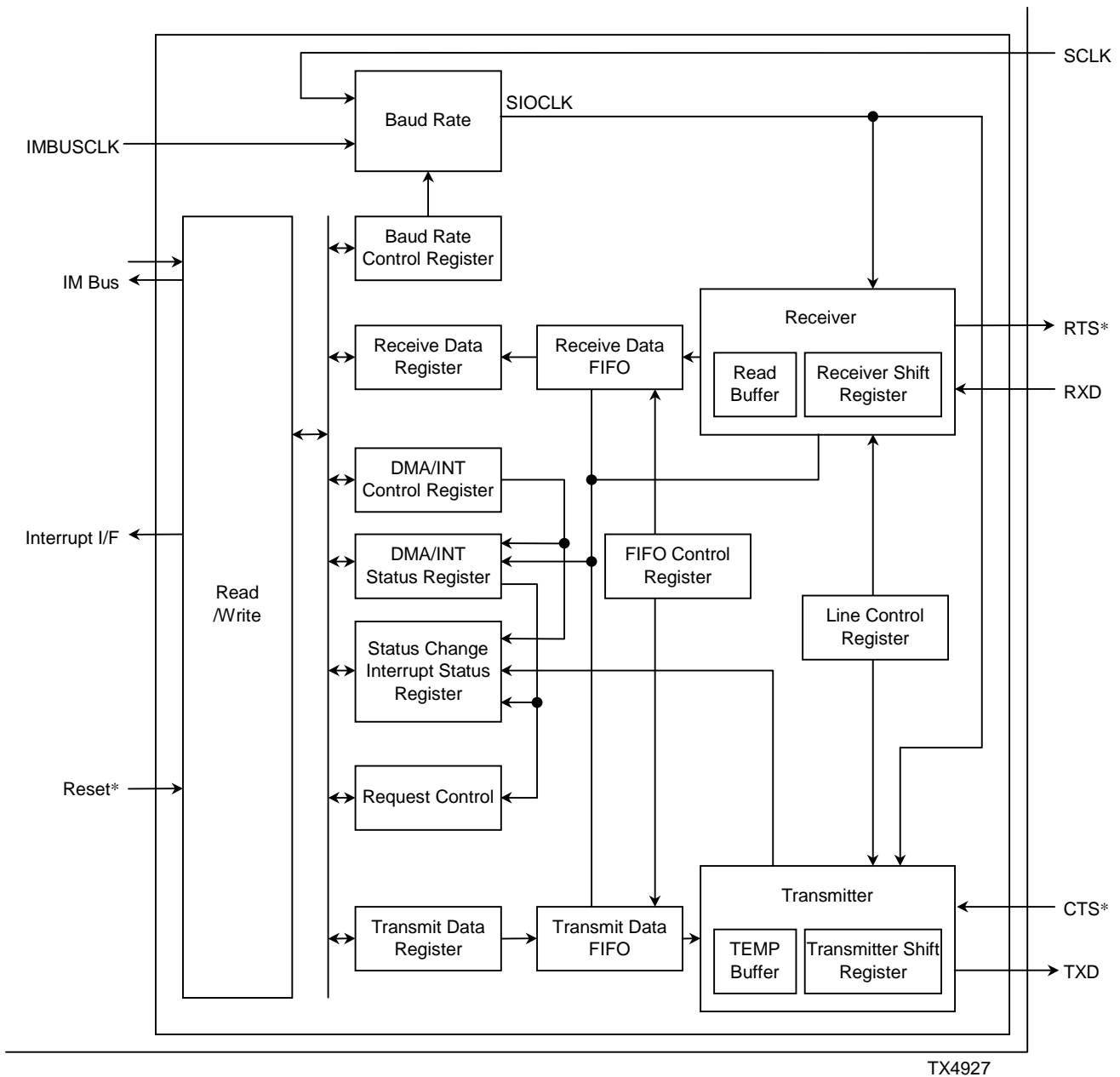


Figure 11.2.1 SIO Internal Block Diagram

11.3 Detailed Explanation

11.3.1 Overview

During reception, serial data that are input as an RXD signal from an external source are converted into parallel data, then are stored in the Receive FIFO buffer. Parallel data stored in the FIFO buffer are fetched by either CPU or DMA transfer.

During transmission, parallel data written to the Transmit FIFO buffer by CPU or DMA transfer are converted into serial data, then are output as a TXD signal.

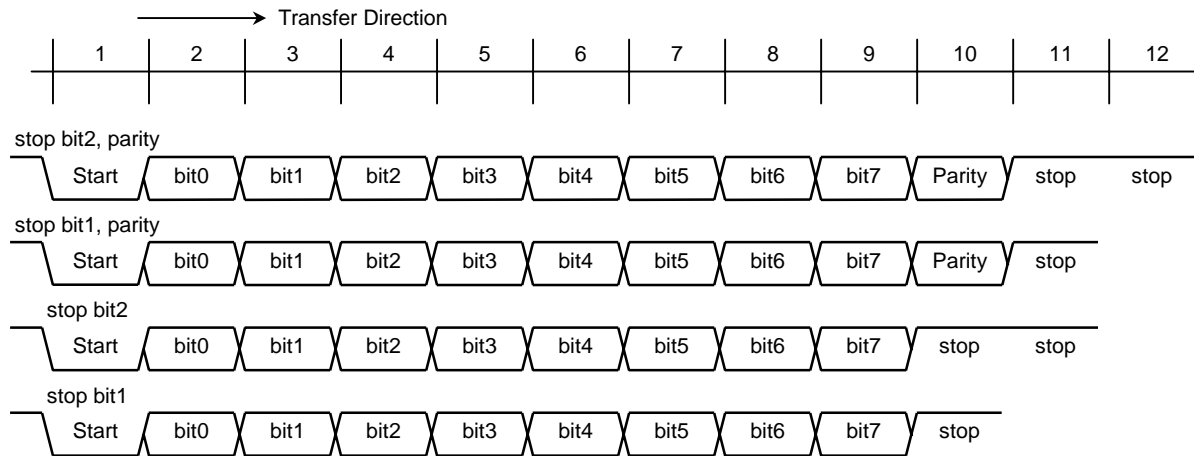
11.3.2 Data Format

The TX4927 SIO can use the following data formats.

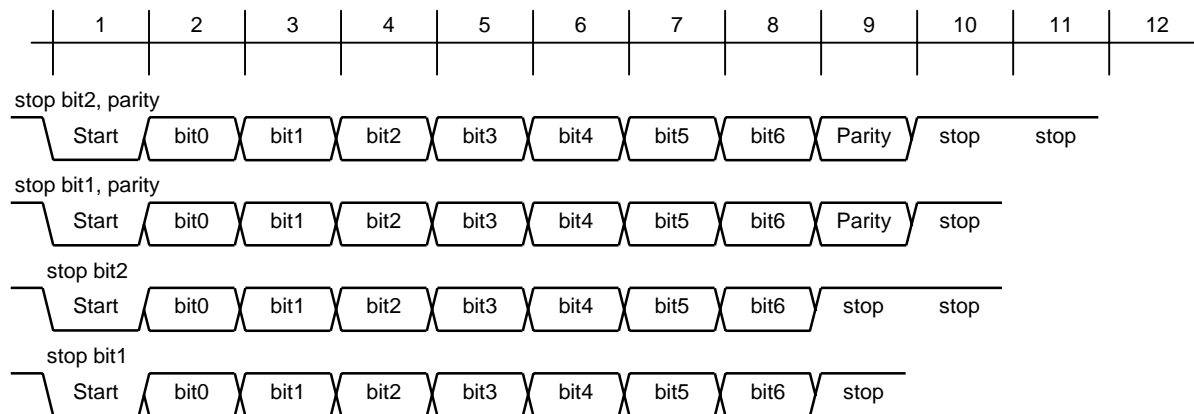
Data Length	: 8/7 bits
Stop Bit	: 1/2 bits
Parity Bit	: Yes/No
Parity Format	: Even/Odd
Start Bit	: Fixed to 1 bit

Figure 11.3.1 illustrates the data frame when making each setting.

8-bit Data



7-bit Data

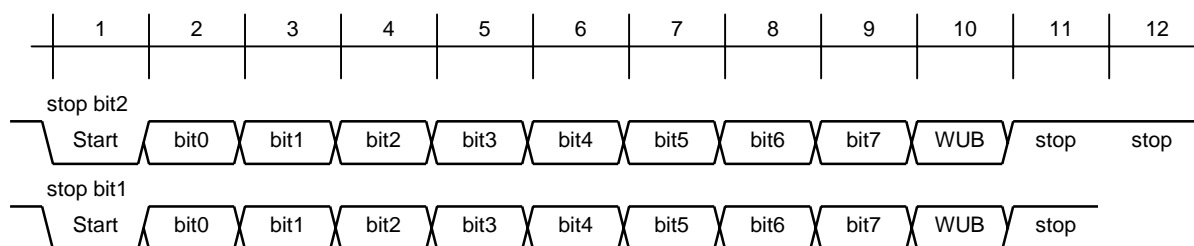


8-bit Data Multi-Control System

WUB = Wake Up bit

1: Address (ID) Frame

0: Data Frame



7-bit Data Multi-Control System

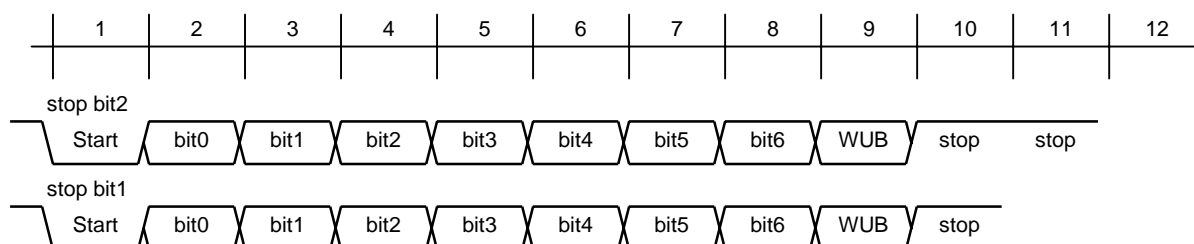


Figure 11.3.1 Data Frame Configuration

11.3.3 Serial Clock Generator

Generates the Serial Clock (SIOCLK). SIOCLK determines the serial transfer rate and has a frequency that is 16× the baud rate. One of the following can be selected as the source for the Serial Clock (SIOCLK).

- Internal System Clock (IMBUSCLK)
- External Clock Input (SCLK)
- Baud rate generator circuit output

The IMBUSCLK frequency can be selected from frequencies that are 1/2, 1/2.5, 1/3, or 1/4 the frequency of the CPU clock. The maximum frequency tolerance of the external clock input (SCLK) is 45% the frequency of IMBUSCLK. For example, if IMBUSCLK = 50 MHz, then set SCLK to 22.5 MHz or less.

The baud rate generator is a circuit that divides these clock signals according to the following formula.

$$\text{Baud Rate} = \frac{fc}{\text{Prescalar} \times \text{Divisor} \times 16}$$

- fc : Clock frequency of IMBUSCLK or an external clock input (SCLK)
- Prescalar Value: 2, 8, 32, 128
- Divide Value: 1, 2, 3,...255

Table 11.3.1 shows example settings of divide values relative to representative baud rates.

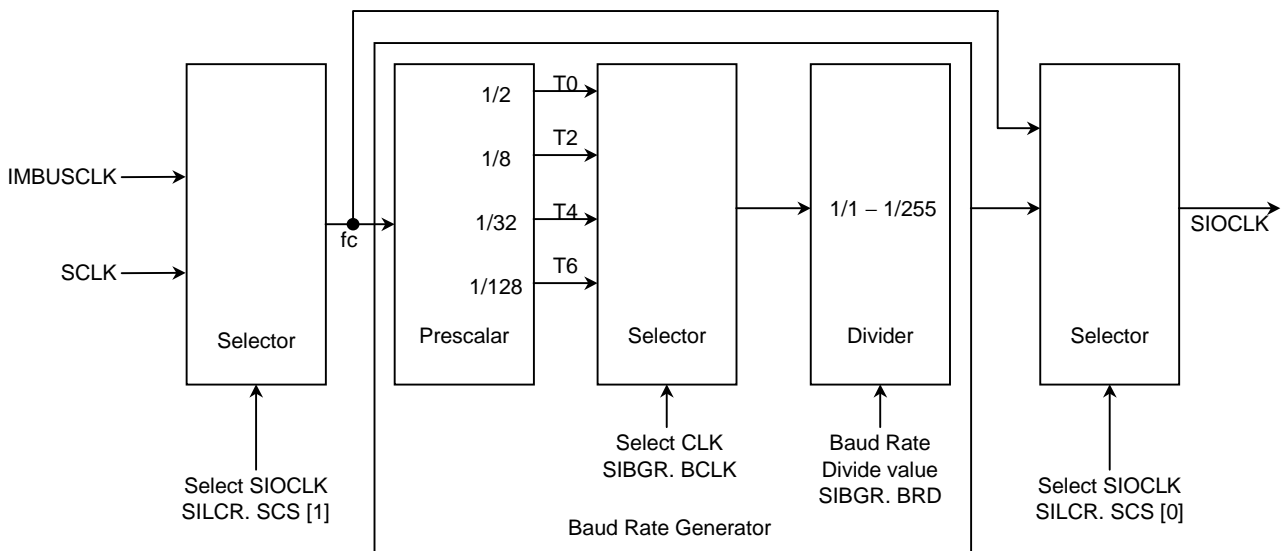


Figure 11.3.2 Baud Rate Generator and SIOCLK Generator

It is possible to correctly receive data if the error of the baud rate set by this controller is within 3.12 % of the target baud rate (communication baud rate).

Table 11.3.1 Example Divide Value Settings (and error [%] from target baud rate value)

fc [MHz]		kbps	Prescalar Value (SIBGR.BLCK) and Divide Value (SIBGR.BRD)			
			2	8	32	128
IMBUS CLK	50	0.11				222 (−0.02 %)
		0.15				163 (−0.15 %)
		0.30				81 (0.47 %)
		0.60			163 (−0.15 %)	41 (−0.76 %)
		1.20			81 (0.47 %)	20 (1.73 %)
		2.40		163 (−0.15 %)	41 (−0.76 %)	10 (1.73 %)
		4.80		81 (0.47 %)	20 (1.73 %)	5 (1.73 %)
		9.60	163 (−0.15 %)	41 (−0.76 %)	10 (1.73 %)	
		14.40	109 (−0.45 %)	27 (0.47 %)	7 (−3.12 %)	
		19.20	81 (0.47 %)	20 (1.73 %)	5 (1.73 %)	
		28.80	54 (0.47 %)	14 (−3.12 %)		
		38.40	41 (−0.76 %)	10 (1.73 %)		
		57.60	27 (0.47 %)	7 (−3.12 %)		
		76.80	20 (1.73 %)	5 (1.73 %)		
		115.20	14 (−3.12 %)			
	41.667	0.11				185 (−0.02 %)
		0.15				136 (−0.27 %)
		0.30				68 (−0.27 %)
		0.60			136 (−0.27 %)	34 (−0.27 %)
		1.20			68 (−0.27 %)	17 (−0.27 %)
		2.40		136 (−0.27 %)	34 (−0.27 %)	
		4.80		68 (−0.27 %)	17 (−0.27 %)	
		9.60	136 (−0.27 %)	34 (−0.27 %)		
		14.40	90 (0.47 %)	23 (−1.71 %)		
		19.20	68 (−0.27 %)	17 (−0.27 %)		
		28.80	45 (0.47 %)	11 (2.75 %)		
		38.40	34 (−0.27 %)			
		57.60	23 (−1.71 %)			
		76.80	17 (−0.27 %)			
		115.20	11 (2.75 %)			
SCLK	7.3728	0.11			131 (−0.07 %)	33 (−0.83 %)
		0.15			96 (0.00 %)	24 (0.00 %)
		0.30			48 (0.00 %)	12 (0.00 %)
		0.60		96 (0.00 %)	24 (0.00 %)	6 (0.00 %)
		1.20		48 (0.00 %)	12 (0.00 %)	3 (0.00 %)
		2.40	96 (0.00 %)	24 (0.00 %)	6 (0.00 %)	
		4.80	48 (0.00 %)	12 (0.00 %)	3 (0.00 %)	
		9.60	24 (0.00 %)	6 (0.00 %)		
		14.40	16 (0.00 %)	4 (0.00 %)	1 (0.00 %)	
		19.20	12 (0.00 %)	3 (0.00 %)		
		28.80	8 (0.00 %)	2 (0.00 %)		
		38.40	6 (0.00 %)			
		57.60	4 (0.00 %)	1 (0.00 %)		
		76.80	3 (0.00 %)			
		115.20	2 (0.00 %)			

11.3.4 Data Reception

When the Serial Data Reception Disable bit (RSDE) of the Flow Control Register (SIFLCRn) is set to “0”, reception operation starts after the RXD signal start bit is detected. Start bits are detected when the RXD signal transitions from the High state to the Low state. Therefore, the RXD signal is not interpreted as a start bit if it is Low when the Serial Data Reception Disable bit is set to “0”.

The received data are stored in the Receive FIFO. The Reception Data Full bit (RDIS) of the DMA/Interrupt Status Register (SIDISRn) is set if the byte count of the stored reception data exceeds the value set by the Receive FIFO Request Trigger Level field (RDIL) of the FIFO Control Register (SIFCRn).

An interrupt is signaled when the Reception Data Interrupt Enable bit (RIE) of the DMA/Interrupt Control Register (SIDICRn) is set. The received data can be read from the Receive FIFO Data Register (SIRFIFOn).

In addition, DMA transfer is initiated when the Reception Data DMA Enable bit (RDE) of the DMA/Interrupt Control Register (SIDICRn) is set.

11.3.5 Data Transmission

Data stored in the Transmission Data FIFO are transmitted when the Serial Data Transmission Disable bit (TSDE) of the Flow Control Register (SIFLCRn) is set to “0”.

If the available space in the Transmit FIFO is greater than the byte count set by the Transmit FIFO Request Trigger Level (TDIL) of the Control Register (SIFCRn), the transmission data empty bit (TDIS) of the DMA/Interrupt Status Register (SIDISRn) is set.

An interrupt is signaled when the Transmission Data Interrupt Enable bit (TIE) of the DMA/Interrupt Control Register (SIDICRn) is set.

In addition, DMA transfer is initiated when the Transmission Data DMA Enable bit (TDE) of the DMA/Interrupt Control Register (SIDICRn) is set.

11.3.6 DMA Transfer

The DMA Request Select field (INTDMA[7:0]) of the Pin Configuration Register (PCFG) can be used to allocate DMA channels for each reception and transmission channel in the following manner.

SIO Channel 1 Reception	DMA Channel 0
SIO Channel 1 Transmission	DMA Channel 1
SIO Channel 0 Reception	DMA Channel 2
SIO Channel 0 Transmission	DMA Channel 3

Set the DMA Channel Control Register of the DMA Controller as described below.

DMA Request Polarity	Low Active	DMCCRn.ACKPOL = 0
DMA Acknowledge Polarity	Low Active	DMCCRn.REQPOL = 0
Request Detection	Level Detection	DMCCRn.EGREQ = 0
Transfer Size	1 Byte	DMCCRn.XFSZ = 000b
Transfer Address Mode	Dual	DMCCRn.SNGAD = 0

In the case of transmission channels, the address of the Transmit FIFO Register (SITFIFO_n) is set in the DMAC Destination Address Register (DMDAR_n). In the case of reception channels, the address of the Receive FIFO Register (SIRFIFO_n) is set in the DMAC Source Address Register (DMSAR_n). Please set the addresses specified in “11.4.8 Transmit FIFO Register” and “11.4.9 Receive FIFO Register” since the set address differs depending on the Endian mode.

11.3.7 Flow Control

SIO supports hardware flow control that uses the RTS*/CTS* signal.

The CTS* (Clear to Send) input signal indicates that data can be received from the reception side when it is Low. Setting the Transmission Enable Select bit (TES) of the Flow Control Register (SIFLCR_n) makes transmission flow control that uses the CTS* signal more effective.

It is also possible to generate status change interrupts by changing the state of the CTS* signal. The conditions in which interrupts are generated can be selected by the CTSS Active Condition field of the DMA/Interrupt Control Register (SIDICR_n).

Setting the RTS* (Request to Send) output signal to High requests the transmission side to pause transmission. Transmission resumes when the reception side becomes ready and the RTS* signal is set to Low.

Setting the Reception Enable Select bit (RCS) of the flow Control Register (SIFLCR_n) makes reception flow control that uses the RTS* signal more effective. The RTS* signal pin status becomes High when data of the byte count set by the RTS Active Trigger Level field (RTSTL) of the Flow Control Register (SIFLCR_n) accumulates in the Receive FIFO. The RTS* signal can also be made High by setting the RTS Software Control bit (RTSSC) of the Flow Control Register (SIFLCR_n). Setting this bit requests the transmission side to pause transmission.

11.3.8 Reception Data Status

Status data such as the following is also stored in the Receive FIFO.

- **Overflow error**
An overflow error is generated if all 16-stage Receive FIFO buffers become full and more data is transferred to the Reception Read buffer. When this occurs, the Overflow Status bit is set by the last stage of the Receive FIFO.
- **Parity error**
A parity error is generated when a parity error is detected in the reception data.
- **Framing error**
A framing error is generated when “0” is detected at the first stop bit of the reception data.
- **Break reception**
A break is detected when a framing error occurs in the reception data and all data in a single frame are “0”. When this occurs, 2 frames (2 Bytes) of 0x00 data are stored in the Receive FIFO.

The Reception Error Interrupt bit (SIDISR.ERI) of the DMA/Interrupt Status Register (SIDISR_n) is set when one of the following errors is detected: an overflow error, a parity error, or a framing error. An interrupt is signaled if the Reception Error Interrupt Enable bit of the DMA/Interrupt Control Register (SIDICR_n) is set.

The Receive Break bit (RBRKD) and the Receiving Break bit (RBRKD) of the Status Change Interrupt Status Register (SISCISR) is set when a break is detected. The Receive Break bit (RBRKD) remains set until it is cleared by the software. The Receiving Break bit (RBRKD) is automatically cleared when a frame is received that is not a break.

The status of the next reception data to be read is set to the Overrun Error bit (UOER), Parity Error bit (UPER), Framing Error bit (UFER), and the Receive Break bit (RBRKD). Each of these statuses is updated when reception data is read from the Receive FIFO Register (SIRFIFO_n).

During DMA transfer, an error is signaled and DMA transfer stops with error data remaining in the Receive FIFO if either an error (Framing Error, Parity Error, or Overrun Error) or a Reception time out (TOUT) is detected. If a Reception Error occurs during DMA transfer, use the Receive FIFO Reset bit (RFRST) of the FIFO Control Register (SIFCR_n) to clear the Receive FIFO. However, a software reset will be required if a reception overrun error has occurred. Refer to “11.3.10 Software Reset” for more information.

11.3.9 Reception Time Out

A Reception time out is detected and the Reception Time Out bit (TOUT) of the DMA/Interrupt Status Register (SIDISR) is set under the following conditions.

- Non-DMA transfer mode (SIDICR_n.RDE = 0):
When at least 1 Byte of reception data exists in the Receive FIFO and the data reception time for the 2 frames (2 Bytes) after the last reception has elapsed
- DMA transfer mode (SIDICR_n.RDE = 1):
When the data reception time for the 2 frames (2 Bytes) after the last reception has elapsed regardless of whether reception data exists in the Receive FIFO

11.3.10 Software Reset

It is necessary to reset the FIFO and perform a software reset in the following situations.

1. After transmission data is set in FIFO, etc., transmission started but stopped before its completion
2. An overrun occurred during data reception

Software reset is performed by setting the Software Reset bit (SWRST) of the FIFO Control Register (SIFCR). This bit automatically returns to “0” after initialization is complete. This bit must be set again since all SIO registers are initialized by software resets.

11.3.11 Error Detection/Interrupt Signaling

An interrupt is signaled if an error or an interrupt cause is detected, the corresponding status bit is set and the corresponding Interrupt Enable bit is set.

The following figure shows the relationship between the status bit for each interrupt cause and each interrupt enable bit. Please refer to the explanation for each status bit for more information about each interrupt cause.

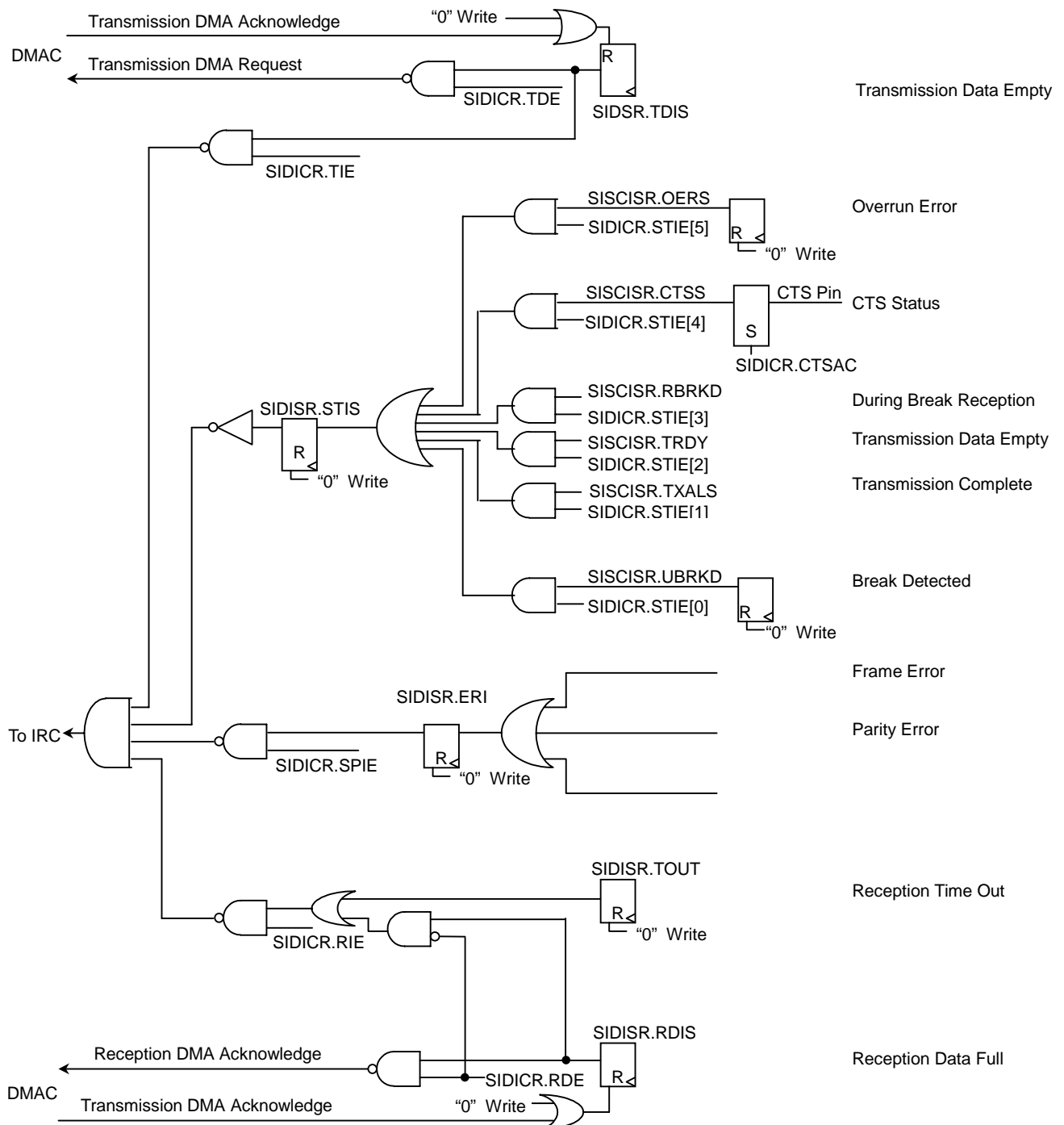


Figure 11.3.3 Relationship Between Interrupt Status Bits and Interrupt Signals

11.3.12 Multi-Controller System

The Multi-Controller System consists of one Master Controller, and multiple Slave Controllers as shown below in Figure 11.3.4.

In the case of the Multi-Controller System, the Master Controller transmits an address (ID) frame to all Slave Controllers, then transmits and receives data with the selected Slave Controller. Slave Controllers that were not selected will ignore this data.

Data frames whose data frame Wake Up bits (WUB) are “1” are handled as address (ID) frames. Data frames whose Wake Up bit (WUB) is “0” are handled as data frames.

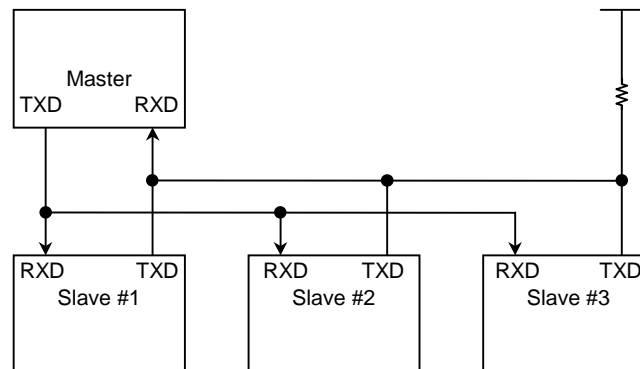


Figure 11.3.4 Example Configuration of Multi-Controller System

The data transfer procedure for the Multi-Controller System is as follows.

- (1) The Master and Slave Controllers set the Mode field (UMODE) of the Line Control Register (SILCR) to “10” or “11” to set the Multi-Controller System mode. Also, the Slave Controller sets the open drain enable bit (UODE) of the Line Control Register (SILCR), setting the TXD output signal to open drain output.
- (2) The Slave Controller sets the Reception Wake Up bit (RWUB) of the Line Control Register (SILCR), making it possible to receive address (ID) frames from the Master Controller.
- (3) The Master Controller sets the Transmission Wake Up bit (TWUB) of the Line Control Register (SILCR), and transmits the address (ID) of the selected Slave Controller. This causes the address (ID) frame to be transmitted. The Reception after Address Transmission Wake Up bit (RWUB) is cleared, enabling reception of data frames.
- (4) Since the Reception Wake Up bit (RWUB) is set, the Slave Controller generates an interrupt to the CPU by receiving an address (ID) frame. The CPU compares its own address (ID) and the received data together. If they do not match, the Reception Wake Up bit (RWUB) is cleared, making data frame reception possible.
- (5) The Master Controller and the selected Slave Controller clear the Transmission Wake Up bit (TWUB) of the Line Control Register (SILCR), then set the mode that transmits data frames.
- (6) Transmit/Receive data between the Master Controller and the selected Slave Controller. Then, Slave Controllers that were not selected ignore data frames since the Reception Wake Up bit (RWUB) is still set.

11.4 Registers

With the exception of DMA access to the Transmit FIFO Register or the Receive FIFO Register, please use Word access when accessing register in the Serial I/O Port.

Table 11.4.1 SIO Registers

Offset Address	Mnemonic	Register Name
SIO0 (Channel 0)		
0xF300	SILCR0	Line Control Register 0
0xF304	SIDICR0	DMA/Interrupt Control Register 0
0xF308	SIDISR0	DMA/Interrupt Status Register 0
0xF30C	SISCISR0	Status Change Interrupt Status Register 0
0xF310	SIFCR0	FIFO Control Register 0
0xF314	SIFLCR0	Flow Control Register 0
0xF318	SIBGR0	Baud Rate Control Register 0
0xF31C	SITFIFO0	Transmit FIFO Register 0
0xF320	SIRFIFO0	Receive FIFO Register 0
SIO1 (Channel 1)		
0xF400	SILCR1	Line Control Register 1
0xF404	SIDICR1	DMA/Interrupt Control Register 1
0xF408	SIDISR1	DMA/Interrupt Status Register 1
0xF40C	SISCISR1	Status Change Interrupt Status Register 1
0xF410	SIFCR1	FIFO Control Register 1
0xF414	SIFLCR1	Flow Control Register 1
0xF418	SIBGR1	Baud Rate Control Register 1
0xF41C	SITFIFO1	Transmit FIFO Register 1
0xF420	SIRFIFO1	Receive FIFO Register 1

11.4.1 Line Control Register 0 (SILCR0) 0xF300 (Ch. 0)
Line Control Register 1 (SILCR1) 0xF400 (Ch. 1)

These registers specify the format of asynchronous transmission/reception data.

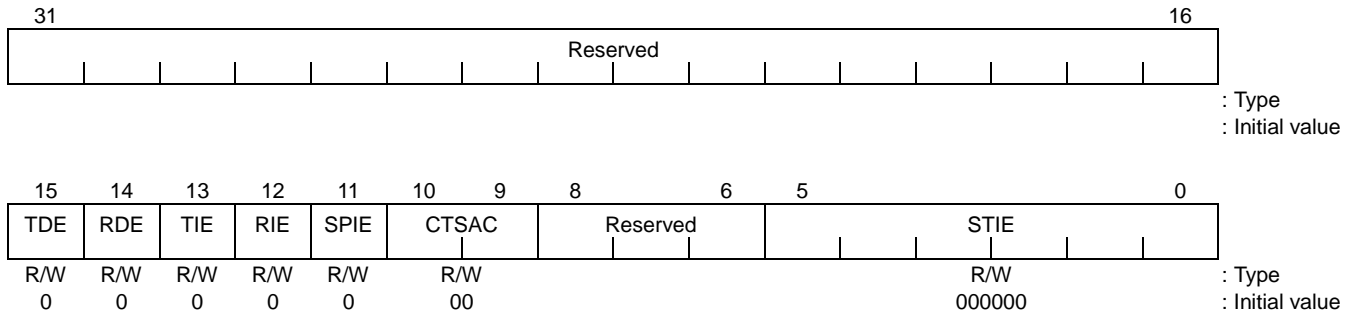


Bit	Mnemonic	Field Name	Description	Read/Write
31:16		Reserved		—
15	RWUB	Receive Wake Up Bit	Wake Up Bit for Receive (Default: 0) When in the Multi-Controller System mode, this field selects whether to receive address (ID) frames whose Wake Up bits (WUB) are "1" or to receive data frames whose Wake Up bits (WUB) are "0". This value is undefined when not in the Multi-Controller System mode. 0: Receive data frames. 1: Receive address (ID) frames.	R/W
14	TWUB	Transmit Wake Up Bit	Wake Up Bit for Transmit (Default: 1) When in the Multi-Controller System mode, this field specifies the Wake Up bit (WUB). This value is undefined when not in the Multi-Controller System mode. 0: Data frame transfer (WUB = 0) 1: Address (ID) frame transfer (WUB = 1)	R/W
13	UODE	Open Drain Enable	TXD Open Drain Enable (Default: 0) This field selects the output mode of the TXD signal. When in the Multi-Controller System mode, the Slave Controller must set the TXD signal to Open Drain. 0: Totem pole output 1: Open drain output	R/W
12:7		Reserved		—
6:5	SCS	Clock Select	SIO Clock Select (Default: 00) This field selects the serial transfer clock. The clock frequency that is the serial transfer clock divided by 16 becomes the baud rate (bps). 00: Internal clock (IMBUSCLK) 01: Baud rate generator output that divided IMBUSCLK 10: External clock (SCLK) 11: Baud rate generator output that divided SCLK	R/W
4	UEPS	Even Parity Select	UART Even Parity Select (Default: 0) This field selects the parity mode. 0: Odd parity 1: Even parity	R/W
3	UPEN	Parity Check Enable	UART Parity Enable (Default: 0) This field selects whether to perform the parity check. This bit must be cleared in multidrop systems (i.e., when the UMODE field is 10 or 11.) 0: Disable the parity check 1: Enable the parity check	R/W
2	USBL	Stop Bit Length	UART Stop Bit Length (Default: 0) This field specifies the stop bit length. 0: 1 bit 1: 2 bit	R/W
1:0	UMODE	Mode	UART Mode (Default: 00) This field sets the data frame mode. 00: 8-bit data length 01: 7-bit data length 10: Multi-Controller 8-bit data length 11: Multi-Controller 7-bit data length	R/W

Figure 11.4.1 Line Control Register

11.4.2 DMA/Interrupt Control Register 0 (SIDICR0) 0xF304 (Ch. 0)
 DMA/Interrupt Control Register 1 (SIDICR1) 0xF404 (Ch. 1)

These registers use either DMA or interrupts to execute the Host Interface.



Bit	Mnemonic	Field Name	Description	Read/Write
31:16		Reserved		—
15	TDE	Transmit DMA Transfer Enable	Transmit DMA Enable (Default: 0) This field sets whether to use DMA in the method for writing transmission data to the Transmit FIFO. 0: Do not use DMA. 1: Use DMA.	R/W
14	RDE	Receive DMA Transfer Enable	Receive DMA Enable (Default: 0) This field sets whether to use DMA in the method for reading reception data from the Receive FIFO. 0: Do not use DMA. 1: Use DMA.	R/W
13	TIE	Transmit Data Empty Interrupt Enable	Transmit Data Empty Interrupt Enable (Default: 0) When there is open space in the Transmit FIFO, this field sets whether to signal an interrupt. Set "0" when in the DMA Transmit mode (TDE = 1). 0: Do not signal an interrupt when there is open space in the Transmit FIFO. 1: Signal an interrupt when there is open space in the Transmit FIFO.	R/W
12	RIE	Reception Data Full Interrupt Enable	Receive Data Full Interrupt Enable (Default: 0) This field sets whether to signal interrupts when reception data is full (SIDISRn.RDIS = 1) or a reception time out (SIDISRn.TOUT = 1) occurs. Set to "0" when in the DMA Receive mode (RDE = 1). 0: Do not signal interrupts when reception data is full/reception time out occurred. 1: Signal interrupts when reception data is full/reception time out occurred.	R/W
11	SPIE	Reception Error Interrupt Enable	Receive Data Error Interrupt Enable (Default: 0) This field sets whether to signal interrupts when a reception error (Frame Error, Parity Error, Overrun Error) occurs (SIDISR.ERI = 1). 0: Do not signal reception error interrupts. 1: Signal reception error interrupts.	R/W
10:9	CTSAC	CTSS Active Condition	CTSS Active Condition (Default: 00) This field specifies status change interrupt request conditions using the CTS Status (CTSS) of the Status Change Interrupt Status Register. 00: Do not detect CTS signal changes. 01: Rising edge of the CTS pin 10: Falling edge of the CTS pin 11: Both edges of the CTS pin	R/W
8:6		Reserved		—

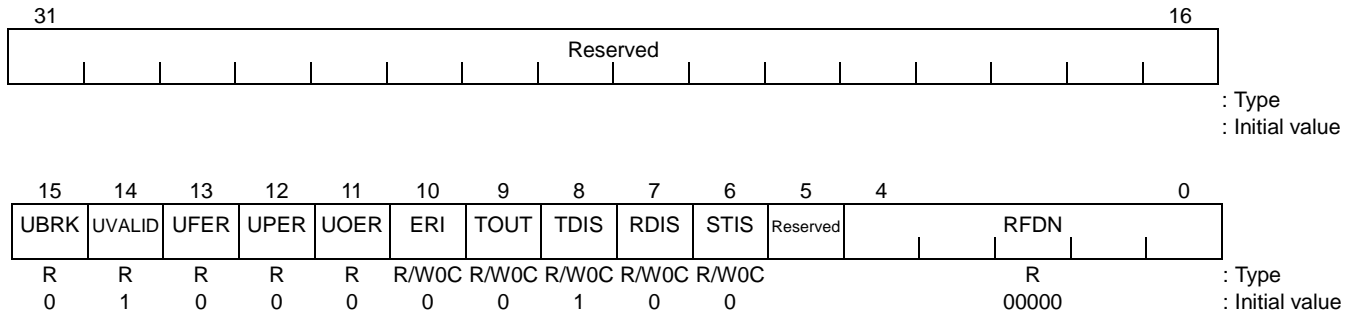
Figure 11.4.2 DMA/Interrupt Control Register (1/2)

Bit	Mnemonic	Field Name	Description	Read/Write
5:0	STIE	Status Change Interrupt Enable	<p>Status Change Interrupt Enable (Default: 0x00)</p> <p>This field sets the set conditions of the Status Change bit (STIS) of the DMA/Interrupt Status Register (SIDISR). The condition is selected depending on which bit of the Status Change Interrupt Status Register (SISCISR) is set. (Multiple selections are possible.)</p> <p>An SIO interrupt is asserted when STIC is "1".</p> <p>000000: Do not detect status changes.</p> <p>1*****: Set "1" to STIS when the Overrun bit (OERS) is "1".</p> <p>*1****: Set "1" to STIS when a change occurs in a condition set by the CTSS Active Condition field (CTSAC) in the CTS Status bit (CTSS).</p> <p>**1***: Set "1" to STIS when the Break bit (RBRKD) becomes "1".</p> <p>***1**: Set "1" to STIS when the Transmit Data Empty bit (TRDY) becomes "1".</p> <p>****1*: Set "1" to STIS when the Transmission Complete bit (TXALS) becomes "1".</p> <p>*****1: Set "1" to STIS when the Break Detection bit (UBRKD) becomes "1".</p>	R/W

Figure 11.4.2 DMA/Interrupt Control Register (2/2)

11.4.3 DMA/Interrupt Status Register 0 (SIDISR0) 0xF308 (Ch. 0)
 DMA/Interrupt Status Register 1 (SIDISR1) 0xF408 (Ch. 1)

These registers indicate the DMA or interrupt status information.



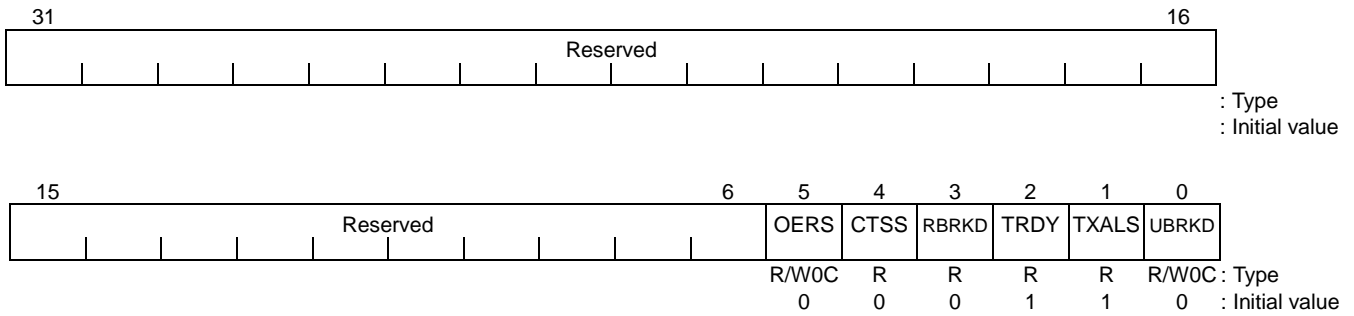
Bit	Mnemonic	Field Name	Description	Read/Write
31:16		Reserved		—
15	UBRK	Receive Break	UART Break (Default: 0) This field indicates the break reception status of the next data in the Receive FIFO to be read. Reading the Receive FIFO Register (SIRFIFO) updates the status. 0: No breaks 1: Detect breaks	R
14	UVALID	Receive FIFO Available Status	UART Available Data (Default: 1) This field indicates whether or not data exists in the Receive FIFO (SIRFIFO). 0: Data exists in the Receive FIFO. 1: No data exists in the Receive FIFO.	R
13	UFER	Frame Error	UART Frame Error (Default: 0) This field indicates the frame error status of the next data in the Receive FIFO to be read. Reading the Receive FIFO Register (SIRFIFO) updates the status. 0: There are no frame errors. 1: There are frame errors.	R
12	UPER	Parity Error	UART Parity Error (Default: 0) This field indicates the parity error status of the next data in the Receive FIFO to be read. Reading the Receive FIFO Register (SIRFIFO) updates the status. 0: There are no parity errors. 1: There are parity errors.	R
11	UOER	Overrun Error	UART Overrun Error (Default: 0) This register indicates the overrun status of the next data in the Receive FIFO to be read. Reading the Receive FIFO Register (SIRFIFO) updates the status. 0: There are no overrun errors. 1: There are overrun errors.	R
10	ERI	Reception Error Interrupt	Receive Data Error Interrupt (Default: 0) This bit is immediately set to "1" when a reception error (Frame Error, Parity Error, or Overrun Error) is detected.	R/W0C
9	TOUT	Reception Time Out	Time Out (Default: 0) This bit is set to "1" when a reception time out occurs.	R/W0C
8	TDIS	Transmission Data Empty	Transmit DMA/Interrupt Status (Default: 1) This bit is set when available space of the amount set by the Transmit FIFO Request Trigger Level (TDIL) of the FIFO Control Register (SIFCR) exists in the Transmit FIFO.	R/W0C
7	RDIS	Reception Data Full	Receive DMA/Interrupt Status (Default: 0) This bit is set when valid data of the amount set by the Receive FIFO Request Trigger Level (RDIL) of the FIFO Control register (SIFCR) is stored in the Receive FIFO.	R/W0C

Figure 11.4.3 DMA/Interrupt Status Register (1/2)

Bit	Mnemonic	Field Name	Description	Read/Write
6	STIS	Status Change	Status Change Interrupt Status (Default: 0) This bit is set when at least one of the interrupt statuses selected by the Status Change Interrupt Condition field (STIE) of the DMA/Interrupt Control Register (SIDICR) becomes "1".	R/W0C
5		Reserved		—
4:0	RFDN	Reception Data Stage Status	Receive FIFO Data Number (Default: 00000) This field indicates how many stages of reception data remain in the Receive FIFO (0 – 16 stages).	R

Figure 11.4.3 DMA/Interrupt Status Register (2/2)

11.4.4 Status Change Interrupt Status Register 0 (SISCISR0) 0xF30C (Ch. 0)
 Status Change Interrupt Status Register 1 (SISCISR1) 0xF40C (Ch. 1)

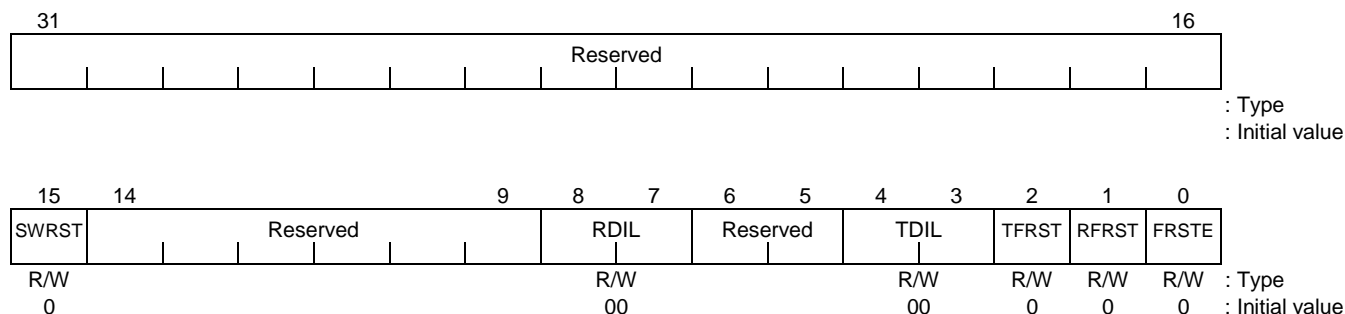


Bit	Mnemonic	Field Name	Description	Read/Write
31:6	—	Reserved	—	—
5	OERS	Overrun Error	Overrun Error Status (Default: 0) This bit is immediately set to “1” when an overrun error is detected. This bit is cleared when a “0” is written.	R/W0C
4	CTSS	CTS Status	CTS Terminal Status (Default: 0) This field indicates the status of the CTS signal. 1: The CTS signal is High. 0: The CTS signal is Low.	R
3	RBRKD	Receiving Break	Receive Break (Default: 0) This bit is set when a break is detected. This bit is automatically cleared when a frame that is not a break is received. 1: Current status is Break. 0: Current status is not Break.	R
2	TRDY	Transmission Data Empty	Transmit Ready (Default: 1) This bit is set to “1” if at least one stage in the Transmit FIFO is free.	R
1	TXALS	Transmission Complete	Transmit All Sent (Default: 1) This bit is set to “1” if the Transmit FIFO and all transmission shift registers are empty.	R
0	UBRKD	Break Detected	UART Break Detect (Default: 0) This bit is set when a break is detected. Once set, this bit remains set until cleared by writing a “0” to it.	R/W0C

Figure 11.4.4 Status Change Interrupt Status Register

11.4.5 FIFO Control Register 0 (SIFCR0) 0xF310 (Ch. 0) FIFO Control Register 1 (SIFCR1) 0xF410 (Ch. 1)

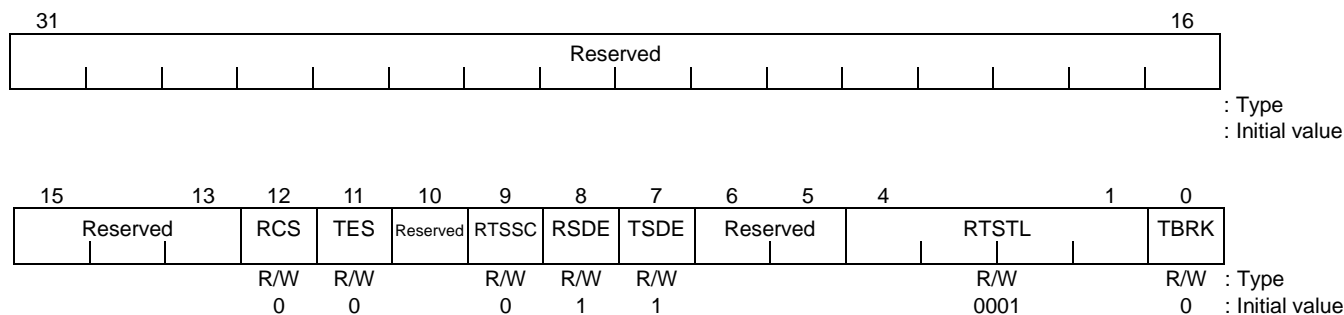
These registers set control of the Transmit/Receive FIFO buffer.



Bit	Mnemonic	Field Name	Description	Read/Write
31:16	—	Reserved	—	—
15	SWRST	Software Reset	Software Reset (Default: 0) This field performs SIO resets except for the FIFOs. Setting this bit to “1” initiates the reset. Set registers are also initialized. This bit returns to “0” when initialization is complete. 0: Normal operation 1: SIO software reset	R/W
14:9	—	Reserved	—	—
8:7	RDIL	Receive FIFO Request Trigger Level	Receive FIFO DMA/Interrupt Trigger Level (Default: 00) This register sets the level for reception data transfer from the Receive FIFO. 00: 1 Byte 01: 4 Bytes 10: 8 Bytes 11: 12 Bytes	R/W
6:5	—	Reserved	—	—
4:3	TDIL	Transmit FIFO Request Trigger Level	Transmit FIFO DMA/Interrupt Trigger Level (Default: 00) This register sets the level for transmission data transfer to the Transmit FIFO. 00: 1 Byte 01: 4 Bytes 10: 8 Bytes 11: Setting disabled	R/W
2	TFRST	Transmit FIFO Reset	Transmit FIFO Reset (Default: 0) The Transmit FIFO buffer is reset when this bit is set. This bit is valid when the FIFO Reset Enable bit (FRSTE) is set. Cancel reset by using the software to clear this bit. 0: During operation 1: Reset Transmit FIFO	R/W
1	RFRST	Receive FIFO Reset	Receive FIFO Reset (Default: 0) The Receive FIFO buffer is reset when this bit is set. This bit is valid when the FIFO Reset Enable bit (FRSTE) is set. Cancel reset by using the software to clear this bit. 0: During operation 1: Reset Receive FIFO	R/W
0	FRSTE	FIFO Reset Enable	FIFO Reset Enable (Default: 0) This field is the Reset Enable for the Transmit/Receive FIFO buffer. The FIFO is reset by combining the Transmit FIFO Reset bit (TFRST) and Receive FIFO Reset bit (RFRST). 0: During operation 1: Reset Enable	R/W

Figure 11.4.5 FIFO Control Register

11.4.6 Flow Control Register 0 (SIFLCR0) 0xF314 (Ch. 0)
Flow Control Register 1 (SIFLCR1) 0xF414 (Ch. 1)



Bit	Mnemonic	Field Name	Description	Read/Write
31:13		Reserved		—
12	RCS	RTS Signal Control Select	RTS Control Select (Default: 0) This field sets the reception flow control using RTS output signals. 0: Disable flow control using RTS signals. 1: Enable flow control using RTS signals.	R/W
11	TES	CTS Signal Control Select	CTS Control Select (Default: 0) This field sets the transmission flow control using CTS input signals. 0: Disable flow control using CTS signals. 1: Enable flow control using CTS signals.	R/W
10		Reserved		—
9	RTSSC	RTS Software Control	RTS Software Control (Default: 0) This register is used for software control of RTS output signals. 0: Set the RTS signal to Low (can receive data). 1: Sets the RTS signal to High (transmission pause request)	R/W
8	RSDE	Serial Data Reception Disable	Receive Serial Data Disable (Default: 1) This is the Serial Data Disable bit. When this bit is cleared, data reception starts after the start bit is detected. The RTS signal will not become High even if this bit is cleared. 0: Enable (can receive data) 1: Disable (halt reception)	R/W
7	TSDE	Serial Data Transmit Disable	Transmit Serial Data Disable (Default: 1) This is the Serial Data Transmission Disable bit. When this bit is cleared, data transmission starts. When set, transmission stops after completing transmission of the current frame. 0: Enable (can transmit data) 1: Disable (halt transmission)	R/W
6:5		Reserved		—
4:1	RTSTL	RTS Active Trigger Level	RTS Trigger Level (Default: 0001) The RTS hardware control assert level is set by the reception data stage count of the Receive FIFO. 0000: Disable setting 0001: 1 : 1111: 15	R/W
0	TBRK	Break Transmission	Break Transmit (Default: 0) Transmits a break. The TXD signal is Low while TBRK is set to "1". 0: Disable (clear break) 1: Enable (transmit break)	R/W

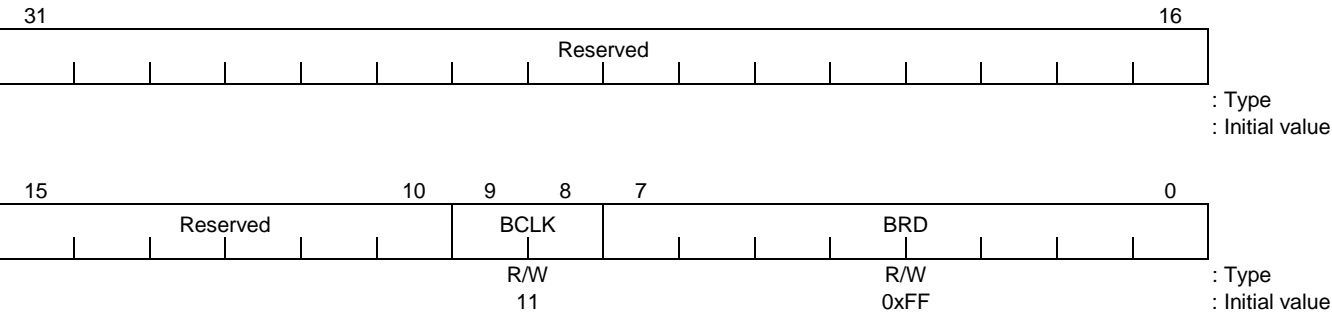
Figure 11.4.6 Flow Control Register

11.4.7

Baud Rate Control Register 0 (SIBGR0)
Baud Rate Control Register 1 (SIBGR1)

0xF318 (Ch. 0)
0xF418 (Ch. 1)

These registers select the clock that is provided to the baud rate generator and set the divide value.



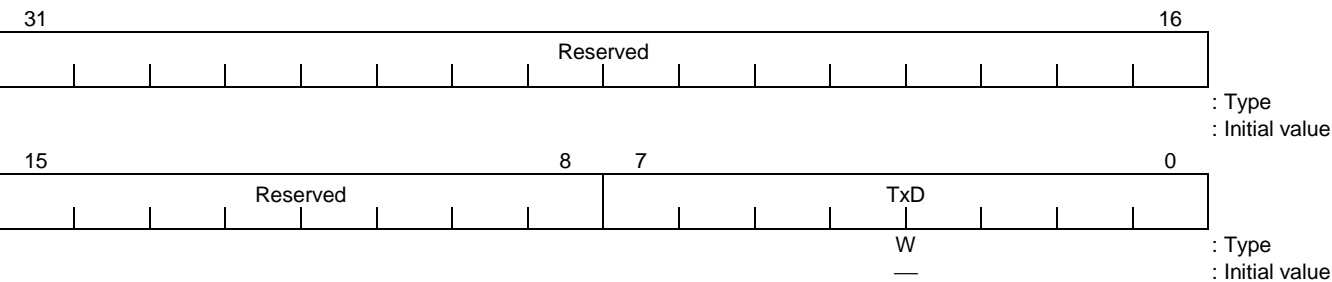
Bit	Mnemonic	Field Name	Description	Read/Write
31:10		Reserved		—
9:8	BCLK	Baud Rate Generator Clock	Baud Rate Generator Clock (Default: 11) This field sets the input clock for the baud rate generator. 00: Select prescalar output T0 (IMBUSCLK/2) 01: Select prescalar output T2 (IMBUSCLK/8) 10: Select prescalar output T4 (IMBUSCLK/32) 11: Select prescalar output T6 (IMBUSCLK/128)	R/W
7:0	BRD	Baud Rate Divide Value	Baud Rate Divide Value (Default: 0xFF) This field set divide value BRG of the baud rate generator. This value is expressed as a binary value.	R/W

Figure 11.4.7 Baud Rate Control Register

11.4.8 Transmit FIFO Register 0 (SITFIFO0) 0xF31C (Ch. 0)
Transmit FIFO Register 1 (SITFIFO1) 0xF41C (Ch. 1)

When using the DMA Controller to perform DMA transmission, set the following addresses in the Destination Address Register (DMDARn) of the DMA Controller according to the Endian Mode bit (DMCCRn.LE) setting of the DMA Controller.

- Little Endian: 0xF31C (Ch.0), 0xF41C (Ch.1)
- Big Endian: 0xF31F (Ch.0), 0xF41F (Ch.1)



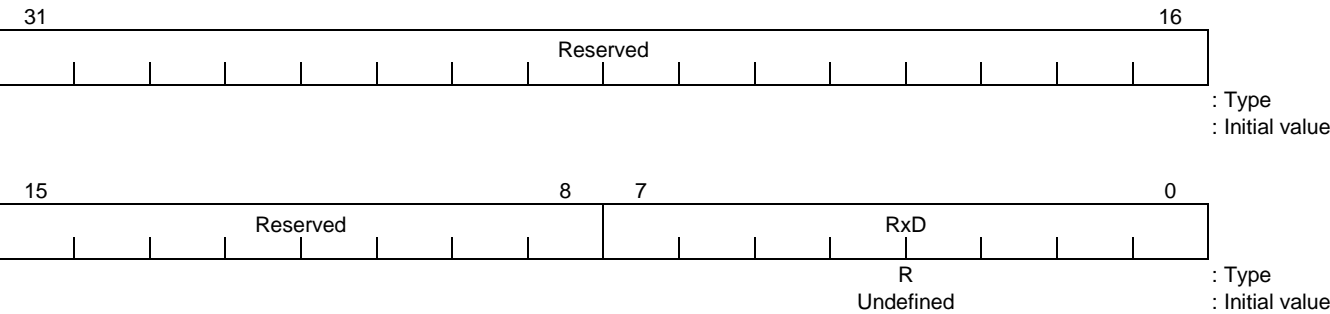
Bit	Mnemonic	Field Name	Description	Read/Write
31:8		Reserved		—
7:0	TxD	Transmission Data	Transmit Data Data written to this register are written to the Transmit FIFO.	W

Figure 11.4.8 Transmit FIFO Register

11.4.9 Receive FIFO Register 0 (SIRFIFO0) 0xF320 (Ch. 0)
Receive FIFO Register 1 (SIRFIFO1) 0xF420 (Ch. 1)

When using the DMA Controller to perform DMA transmission, set the following addresses in the Destination Address Register (DMDARn) of the DMA Controller according to the Endian Mode bit (DMCCRn.LE) setting of the DMA Controller.

- Little Endian: 0xF320 (Ch.0), 0xF420 (Ch.1)
- Big Endian: 0xF323 (Ch.0), 0xF423 (Ch.1)



Bit	Mnemonic	Field Name	Description	Read/Write
31:8		Reserved		—
7:0	RxD	Reception Data	Receive Data This field reads reception data from the Receive FIFO. Reading this register updates the Reception Data Status.	R

Figure 11.4.9 Receive FIFO Register

12. Timer/Counter

12.1 Features

The TX4927 has an on-chip 3-channel timer/counter.

- 32-bit Up Counter: 3 Channels
- Interval Timer Mode (Channel 0, 1, 2)
- Pulse Generator Mode (Channel 0, 1)
- Watchdog Timer Mode (Channel 2)
- Timer Output Signal (TIMER[1:0]) $\times 2$
- Counter Input Signal (TCLK): $\times 1$
- Watchdog Timer Reset Output (WDRST*): $\times 1$

12.2 Block Diagram

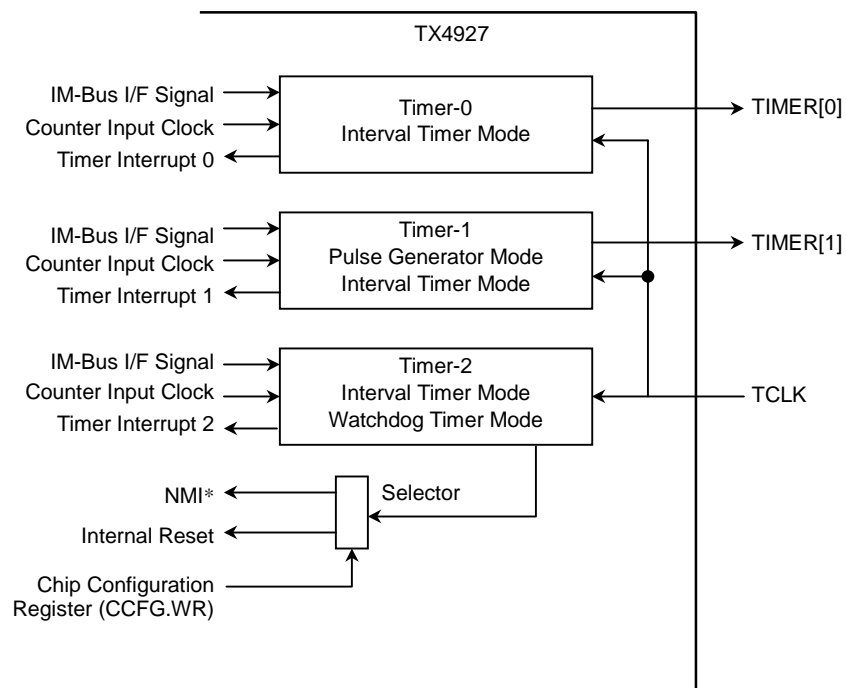


Figure 12.2.1 Connecting Timer Module Inside the TX4927

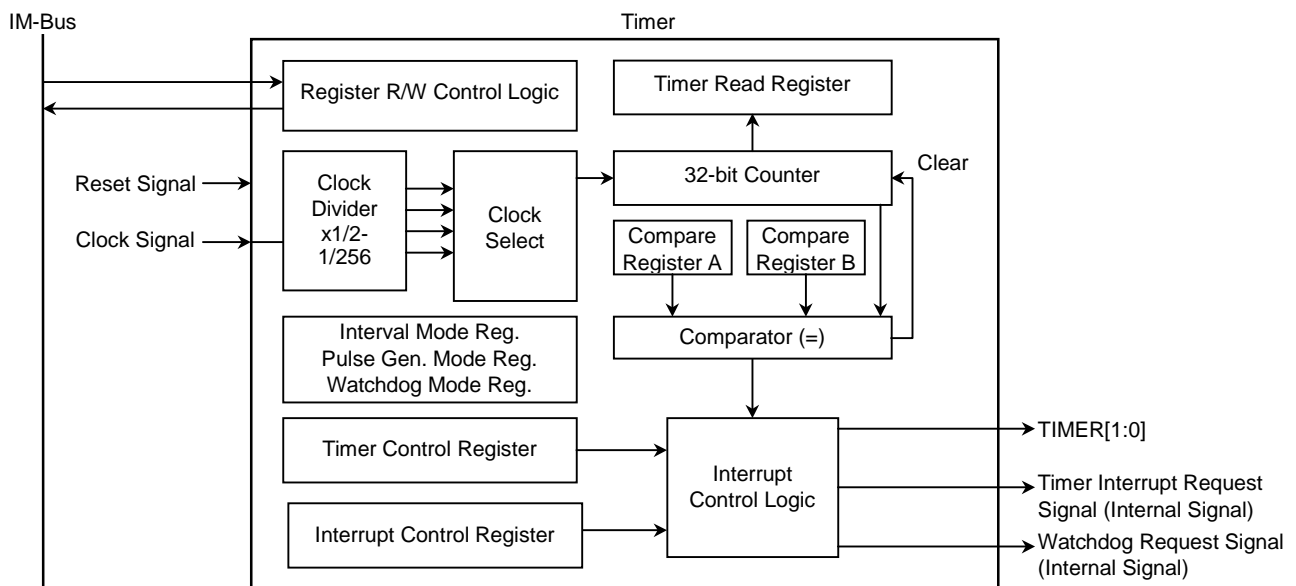


Figure 12.2.2 Timer Internal Block Diagram

12.3 Detailed Explanation

12.3.1 Overview

The TX4927 has an on-chip 3-channel 32-bit timer/counter. Each channel supports the following modes.

(1) Interval Timer Mode (Timer 0, 1, 2)

This mode periodically generates interrupts.

(2) Pulse Generator Mode (Timer 0, 1)

This is the pulse signal output mode.

(3) Watchdog Timer Mode (Timer 2)

This mode is used to monitor system abnormalities.

12.3.2 Counter Clock

The clock used for counting can be set to a frequency that is 1/2, 1/4, 1/8, 1/16, 1/32, 1/64, 1/128, or 1/256 of the internal clock (IMBUSCLK) frequency, or can be selected from nine counter input signal (TCLK) types. Divide Register n (TMCCDR n) and the Counter Clock Select bit (TMTCR n .CCS) are used to select the counter clock. In this situation, IMBUSCLK is the internal clock signal which is the G-Bus clock divided by 2. See “Chapter 6 Clocks” for more information.

The counter input signal (TCLK) is used by three channels. Using TCLK makes it possible to count external events. The External Clock Edge bit (TMTCR n .ECES) can be used to select the clock rising/falling count.

Set the TCLK clock frequency to 45% or less of IMBUSCLK (TCLK = 22.5 MHz or less when IMBUSCLK = 50 MHz). The following table shows example count times when using 50 MHz IMBUSCLK.

Table 12.3.1 Divide Value and Count (IMBUSCLK = 50 MHz)

Divide Rate	TMCCDR n . CCD	Counter Clock Frequency (Hz)	Resolution (ns)	Max. Set Time (sec.)	TMCPRA n Value for 1 sec.
2	000	25.0 M	40.00	171.80	25000000
4	001	12.5 M	80.00	343.60	12500000
8	010	6.25 M	160.00	687.19	6250000
16	011	3.125 M	320.00	1374.39	3125000
32	100	1.5625 M	640.00	2748.78	1562500
64	101	781.25 K	1280.00	5497.56	781250
128	110	390.625 K	2560.00	10995.12	390625
256	111	195.3125 K	5120.00	21990.23	195313

12.3.3 Counter

Each channel has an independent 32-bit counter. Set the Timer Count Enable bit (TMTCRn.TCE) and the 32-bit counter will start counting.

Clear the Timer Count Enable bit to stop the counter. If the Counter Reset Enable bit (TMTCRn.CRE) is set, then the counter will be cleared also. The Watchdog Timer Disable bit (TMWTRM2.WDIS) must be set in order to stop and clear this counter when in the Watch Dog Timer mode.

Also, reading the Timer Read Register (TMTRR) makes it possible to fetch the counter value.

12.3.4 Interval Timer Mode

The Interval Timer mode is used to periodically generate interrupts. Setting the Timer Mode field (TMTCRn.TMODE) of the Timer Control Register to “00” sets the timer to the Interval Timer mode. This mode can be used by all timers.

When the count value matches the value of Compare Register A (TMCPRAn), the Interval Timer TMCPR Status bit (TMTISRn.TIIS) of the Timer Interrupt Status Register is set. When the Interval Timer Interrupt Enable bit (TMITMRn.TIIE) of the Interval Timer Mode Register is set, timer interrupts occur. When a “0” is written to the Interval Timer TMCPR Status bit (TMTISRn.TIIS), TIIS is cleared and timer interrupts stop.

If the Timer Zero Clear Enable bit (TMITMRn.TZCE) is set, the counter is cleared to 0 if the count value matches the Compare Register A (TMCPRAn) value. Count operation stops when the Timer Zero Clear Enable bit (TMITMRn.TZCE) is cleared.

The level of the TIMER[1:0] output signal stays in the initial state (Low) in this mode. Output is undefined when changing from the Pulse Generator mode to this mode. Figure 12.3.1 shows an outline of the count operation and generation of interrupts when in the Interval Timer mode and Figure 12.3.2 shows the operation when using an external input clock.

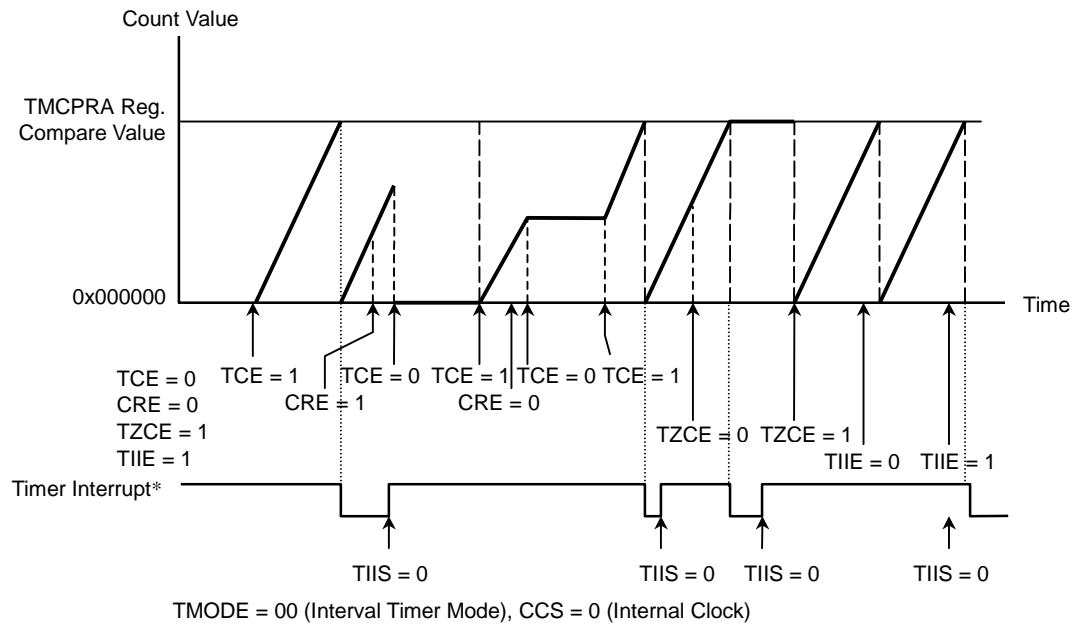


Figure 12.3.1 Operation Example of Interval Timer (Using Internal Clock)

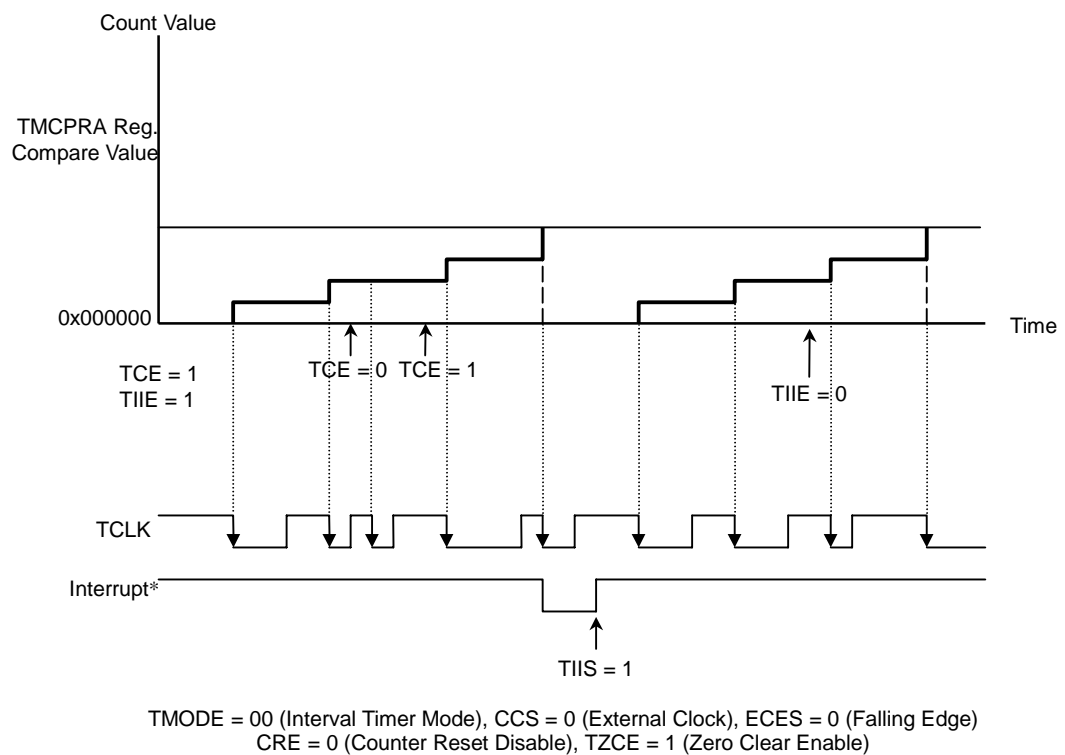


Figure 12.3.2 Operation Example of the Interval Timer (External Input Clock: Rising Edge Operation)

12.3.5 Pulse Generator Mode

When in the Pulse Generator mode, use Compare Register A (TMCPRAn) and Compare Register B (TMCPRBn) to output a particular period and particular duty square wave to the TIMER[n] signal. Setting the Timer Mode field (TMTCRn.TMODE) of the Timer Control Register to “01” sets the timer to the Pulse Generator mode. Timer 0 and Timer 1 can be used, but Timer 2 cannot.

The initial state of the TIMER[n] signal can be set by the Flip Flop Default bit (TMPGMRn.FFI) of the Pulse Generator Mode Register.

The TIMER[n] output signal reverses when the counter value matches the value set in Compare Register A (TMCPRAn). The TIMER[n] output signal reverse again, clearing the counter when the counter continues counting and the value set in Compare Register B (TMCPRBn) and the counter value match. Consequently, a value greater than that in Compare Register A (TMCPRAn) must not be set in Compare Register B (TMCPRBn).

Interrupts can be generated in the Pulse Generator mode as well. However, this is not standard practice.

The Pulse Generator TMCPRa Status bit (TMTISRn.TPIAS) of the Timer Interrupt Status Register is set when the count value matches the value of Compare Register A (TMCPRAn). Timer interrupts are generated when the TMCPRa Interrupt Enable bit (TMPGMRn.TPIAE) of the Pulse Generator Mode Register is set.

Similarly, the Pulse Generator TMCPRB Status bit (TMTISRn.TPIBS) of the Timer Interrupt Status Register is set when the count value matches the value of Compare Register B (TMCPRBn). Timer interrupts are generated when the TMCPRB Interrupt Enable bit (TMPGMRn.TPIBE) of the Pulse Generator Mode Register is set.

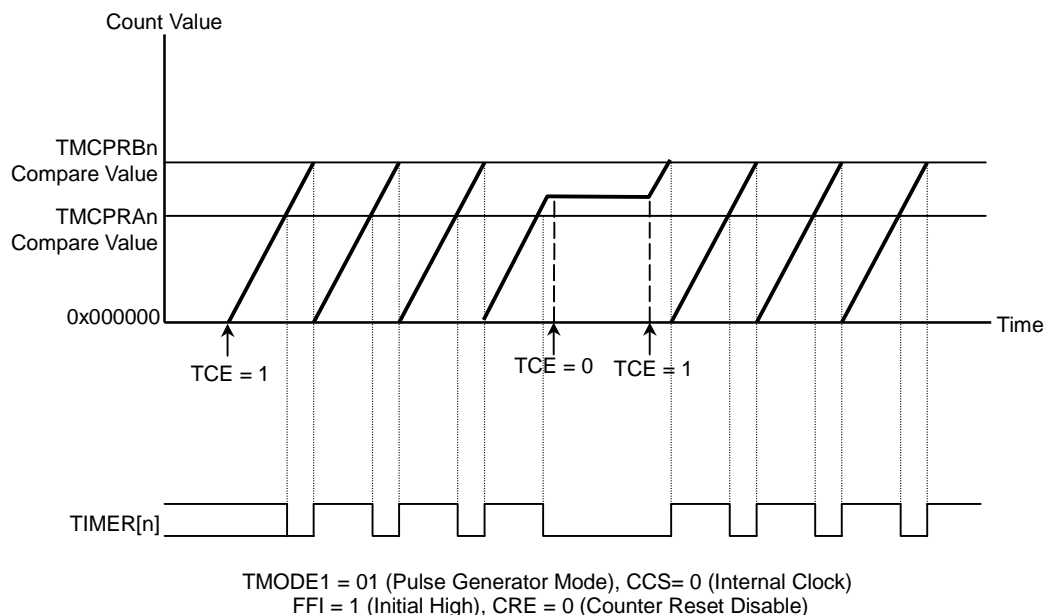


Figure 12.3.3 Operation Example of the Pulse Generator Mode

12.3.6 Watchdog Timer Mode

The Watchdog Timer mode is used to monitor system anomalies. The software periodically clears the counter and judges an anomaly to exist if the counter is not cleared within a specified period of time. Then, either the TX4927 is internally reset or an NMI is signaled to the TX49/H2 core. Set the Timer mode field (TMTCR2.TMODE) of the Timer Control Register to “10” to set the timer to the Watchdog Timer mode. This mode can only be used by Timer 2.

Use the Watchdog Reset bit (WR) of the Chip Configuration Register (CCFG) to select whether to perform an internal reset or signal an NMI. Set this bit to “1” to select Watchdog Reset, or set it to “0” to select NMI Signaling.

When the timer count reaches the value programmed in Compare Register A (TMCPRA2), the Watchdog Timer TMCPRA Match Status bit in the Timer Interrupt Status Register (TMTISR2.TWIS) is set. Either the watchdog timer reset or NMI is issued if the Timer Watchdog Enable bit in the Watchdog Timer Mode Register (TMWTMR2.TWIE) is set.

When the watchdog timer reset is selected, the Watchdog Reset Status bit in the Chip Configuration Register (CCFG.WDRST) is set. If the Watchdog Reset External Output bit in the Chip Configuration Register (CCFG.WDREXEN) is cleared, the entire TX4927 is initialized but the configuration registers. If the CCFG.WDREXEN bit is set, the WDRST* signal is asserted and remains asserted until the RESET* signal is asserted.

There are three ways of stopping NMI signaling from being performed.

1. Clear the Watchdog Timer Interrupt Status bit (TMTISR2.TWIS) of the timer Interrupt Status Register.
2. Clear the counter by writing “1” to the Watchdog Timer Clear bit (TMWTMR2.TWC) of the Watchdog Timer Mode Register.
3. Clear the Watchdog Timer Interrupt Enable bit (TMWTMR2.TWIE) while the Watchdog Timer Disable bit (TMWTMR2.WDIS) is still set.

It is possible to stop the counter when in the Watchdog Timer mode by clearing the Timer Counter Enable bit (TMTCR2.TCE) of the Timer Control Register while the Watchdog Timer Disable bit (TMWTMR2.WDIS) of the Watchdog Timer Mode Register is set to “1”.

It is also possible to stop the counter by clearing the Counter Clock Divide Cycle Enable bit (TMTCR2.CCDE) of the Timer Control Register when the internal clock is being used as the counter clock.

It is not possible to directly write “0” to the Watchdog Timer Disable bit (TMWTMR2.WDIS). There are two ways to clear this bit.

1. Clear the Watchdog Timer Interrupt Enable bit (TMWTMR2.WDIS)
2. Clear the Timer Counter Enable bit (TMTCR2.TCE) of the Timer Control Register

In Watchdog Timer mode, the TIMER[1:0] outputs remain at logic high.

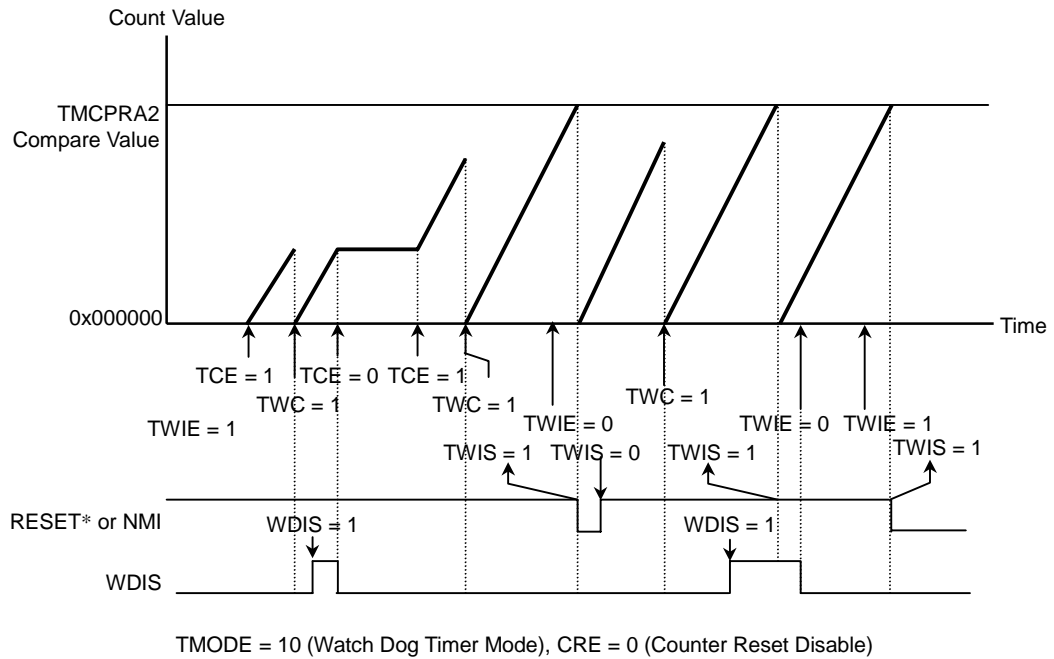


Figure 12.3.4 Operation Example of the Watchdog Timer Mode

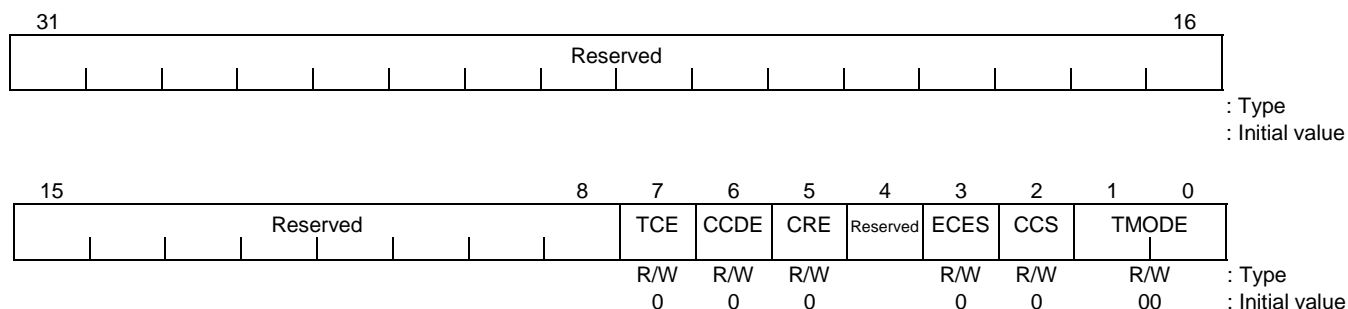
12.4 Registers

Table 12.4.1 Timer Register List

Offset Address	Register Symbol	Register Name
Time 0 (TMR0)		
0xF000	TMTCR0	Timer Control Register 0
0xF004	TMTISR0	Timer Interrupt Status Register 0
0xF008	TMCPRA0	Compare Register A 0
0xF00C	TMCPRB0	Compare Register B 0
0xF010	TMITMR0	Interval Timer Mode Register 0
0xF020	TMCCDR0	Divide Cycle Register 0
0xF030	TMPGMR0	Pulse Generator Mode Register 0
0xF040	TMWTCR0	(Reserved)
0xF0F0	TMTRR0	Timer Read Register 0
Timer 1 (TMR1)		
0xF100	TMTCR1	Timer Control Register 1
0xF104	TMTISR1	Timer Interrupt Status Register 1
0xF108	TMCPRA1	Compare Register A 1
0xF10C	TMCPRB1	Compare Register B 1
0xF110	TMITMR1	Interval Timer Mode Register 1
0xF120	TMCCDR1	Divide Cycle Register 1
0xF130	TMPGMR1	Pulse Generator Mode Register 1
0xF140	TMWTCR1	(Reserved)
0xF1F0	TMTRR1	Timer Read Register 1
Timer 2 (TMR2)		
0xF200	TMTCR2	Timer Control Register 2
0xF204	TMTISR2	Timer Interrupt Status Register 2
0xF208	TMCPRA2	Compare Register A 2
0xF20C	TMCPRB2	(Reserved)
0xF210	TMITMR2	Interval Timer Mode Register 2
0xF220	TMCCDR2	Divide Cycle Register 2
0xF230	TMPGMR2	(Reserved)
0xF240	TMWTCR2	Watchdog Timer Mode Register 2
0xF2F0	TMTRR2	Timer Read Register 2

12.4.1 Timer Control Register n (TMTCR n)

TMTCR0 0xF000
TMTCR1 0xF100
TMTCR2 0xF200



Bit	Mnemonic	Field Name	Description	Read/Write
31:8		Reserved		—
7	TCE	Timer Counter Enable	<p>Timer Count Enable (Default: 0)</p> <p>This field controls whether the counter runs or stops.</p> <p>When in the Watchdog mode, counter operation only stops when the Watchdog Timer Disable bit (TMWTMR2.WDIS) of the Watchdog Timer Mode Register is set. When the Watchdog Timer Disable bit is cleared, the value of this Timer Count Enable bit becomes "0", but the count continues.</p> <p>0: Stop counter (the counter is also cleared to "0" when CRE = 1)</p> <p>1: Counter operation</p>	R/W
6	CCDE	Counter Clock Divider Enable	<p>Counter Clock Divide Enable (Default: 0)</p> <p>This bit enables the divide operation of the internal clock (IMBUSCLK). The counter stops if this bit is set to "0" when the internal bus clock is in use.</p> <p>0: Disable</p> <p>1: Enable</p>	R/W
5	CRE	Counter Reset Enable	<p>Counter Reset Enable (Default: 0)</p> <p>This bit controls the counter reset when the TCE bit was used to stop the counter.</p> <p>1: Stop and reset the counter to "0" when the TCE bit is cleared to "0".</p> <p>0: Only stop the counter when the TCE bit is cleared to "0".</p>	R/W
4		Reserved		—
3	ECES	External Clock Edge Select	<p>External Clock Edge Select (Default: 0)</p> <p>This bit specifies the counter operation edge when using the counter input signal (TCLK).</p> <p>0: Falling edge of the counter input signal (TCLK)</p> <p>1: Rising edge of the counter input signal (TCLK)</p>	R/W
2	CCS	Counter Clock Select	<p>Counter Clock Select (Default: 0)</p> <p>This bit specifies the timer clock.</p> <p>0: Internal clock (IMBUSCLK)</p> <p>1: External input clock (TCLK)</p>	R/W
1:0	TMODE	Timer Mode	<p>Timer Mode (Default: 00)</p> <p>This bit specifies the timer operation mode.</p> <p>11: Reserved</p> <p>10: Watchdog Timer mode (Timer 2), Reserved (Timer 0, 1)</p> <p>01: Pulse Generator mode (Timer 0, 1), Reserved (Timer 2)</p> <p>00: Interval Timer mode</p>	R/W

Figure 12.4.1 Timer Control Register

12.4.2 Timer Interrupt Status Register n (TMTISR n)

TMTISR0 0xF004

TMTISR1 0xF104

TMTISR2 0xF204

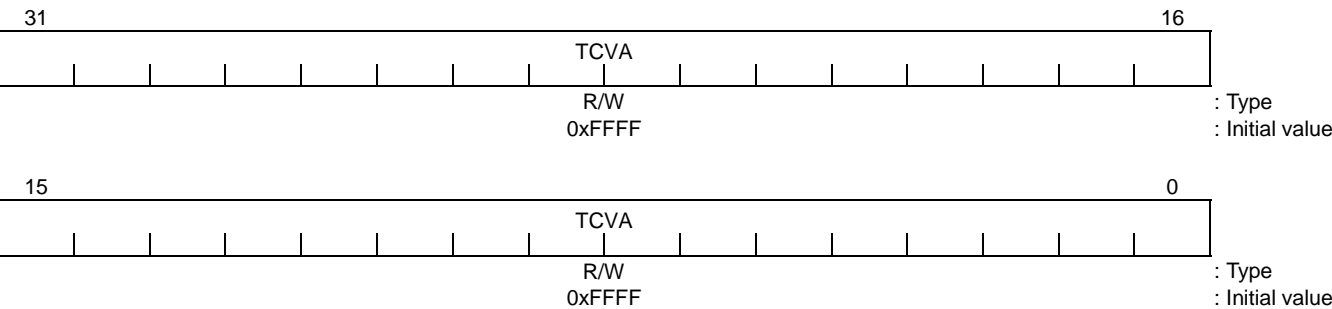


Bit	Mnemonic	Field Name	Description	Read/Write
31:4		Reserved		—
3	TWIS	Watchdog Timer Status	<p>Watchdog Timer TMCPRA Match Status (Default: 0) (This bit is Reserved in the case of the TMTISR0 Register and the TMTISR1 Register.)</p> <p>When in the Watchdog Timer mode, this bit is set when the counter value matches Compare Register 2 (TMCPRA2). This bit is cleared by writing a “0” to it.</p> <p><u>During Read</u> 0: Did not match the Compare Register 1: Matched the Compare Register</p> <p><u>During Write</u> 0: Negate interrupt 1: Invalid</p>	R/W0C
2	TPIBS	Pulse Generator TMCPRB Status	<p>Pulse Generator TMCPRB Match Status (Default: 0) (This bit is Reserved in the case of the TMTISR2 Register.)</p> <p>When in the Pulse Generator mode, this bit is set when the counter value matches Compare Register Bn (TMCPRBn). This bit is cleared by writing a “0” to it.</p> <p><u>During Read</u> 0: Did not match the Compare Register 1: Matched the Compare Register</p> <p><u>During Write</u> 0: Clear 1: Invalid</p>	R/W0C
1	TPIAS	Pulse Generator TMCPRA Status	<p>Pulse Generator TMCPRA Match Status (Default: 0) (This bit is Reserved in the case of the TMTISR2 Register.)</p> <p>When in the Pulse Generator mode, this bit is set when the counter value matches Compare Register A n (TMCPRAn). This bit is cleared by writing a “0” to it.</p> <p><u>During Read</u> 0: Did not match the Compare Register 1: Matched the Compare Register</p> <p><u>During Write</u> 0: Clear 1: Invalid</p>	R/W0C
0	TIIS	Interval Timer TMCPRA Status	<p>Interval Timer TMCPRA Match Status (Default: 0)</p> <p>When in the Interval Timer mode, this bit is set when the counter value matches Compare Register A n (TMCPRAn). This bit is cleared by writing a “0” to it.</p> <p><u>During Read</u> 0: Did not match the Compare Register 1: Matched the Compare Register</p> <p><u>During Write</u> 0: Clear 1: Invalid</p>	R/W0C

Figure 12.4.2 Timer Interrupt Status Register

12.4.3 Compare Register An (TMCPRA_n)

TMCPRA0 0xF008
TMCPRA1 0xF108
TMCPRA2 0xF208

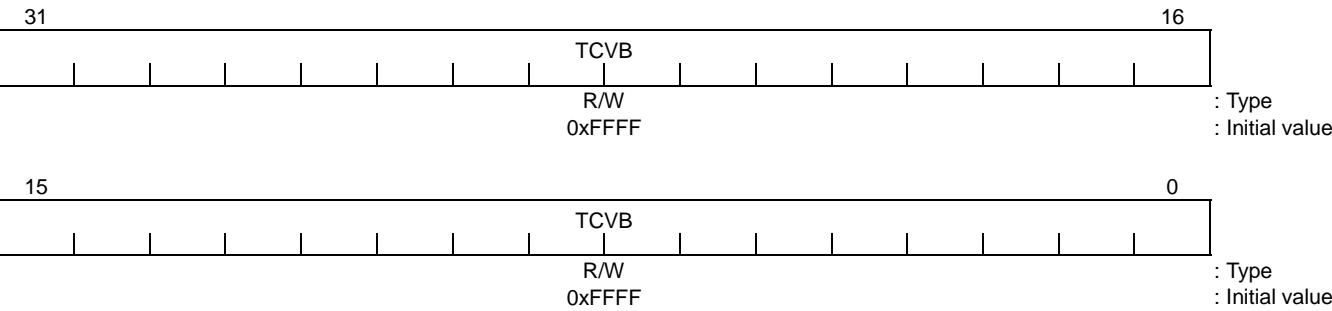


Bits	Mnemonic	Field Name	Description	Read/Write
31:0	TCVA	Timer Compare Register A	Timer Compare Value A (Default: 0xFFFFFFFF) Sets the timer compare value as a 32-bit value. This register can be used in all modes.	R/W

Figure 12.4.3 Compare Register A

12.4.4 Compare Register Bn (TMCPRBn)

TMCPRB0 0xF00C
TMCPRB1 0xF10C



Bits	Mnemonic	Field Name	Description	Read/Write
31:0	TCVB	Timer Compare Value B	Timer Compare Value B (Default: 0xFFFFFFFF) Sets the timer compare value as a 32-bit value. This register can only be used when in the Pulse Generator mode. Please set a value greater than that in Compare Register A.	R/W

Figure 12.4.4 Compare Register B

12.4.5 Interval Timer Mode Register *n* (TMITMR*n*)

TMITMR0 0xF010
TMITMR1 0xF110
TMITMR2 0xF210

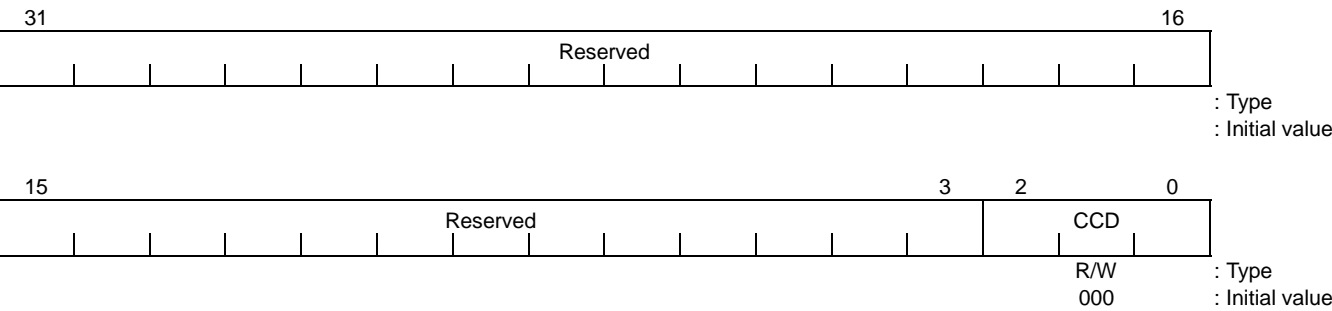


Bit	Mnemonic	Field Name	Description	Read/Write
31:16		Reserved		—
15	TIE	Interval Timer Interrupt Enable	Timer Interval Interrupt Enable (Default: 0) Sets Interval Timer TMCPRA Interrupt Enable/Disable. 0: Disable (mask) 1: Enable	R/W
14:1		Reserved		—
0	TZCE	Interval Timer Clear Enable	Interval Timer Zero Clear Enable (Default: 0) This bit specifies whether or not to clear the counter to “0” after the count value matches Compare Register A. Count stops at this value if it is not cleared. 0: Do not clear 1: Clear	R/W

Figure 12.4.5 Interval Timer Mode Register

12.4.6 Divide Register *n* (TMCCDR*n*)

TMCCDR0 0xF020
TMCCDR1 0xF120
TMCCDR2 0xF220



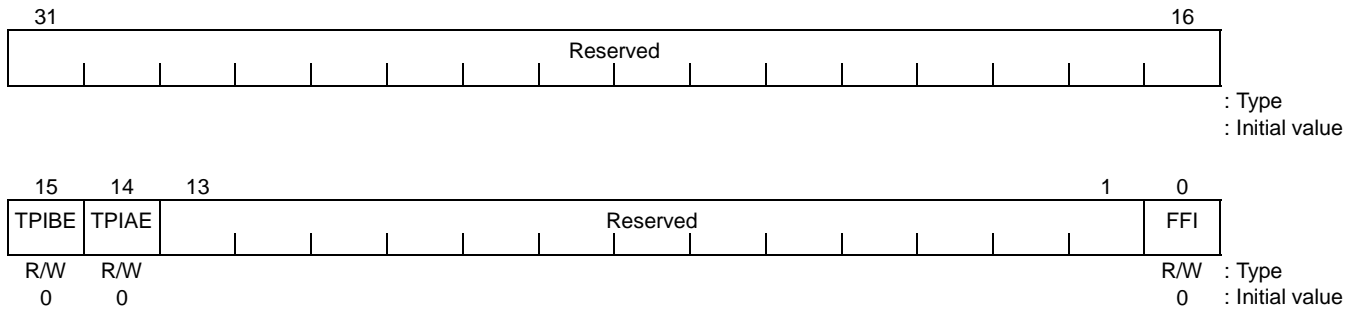
Bits	Mnemonic	Field Name	Description	Read/Write
31:3		Reserved		—
2:0	CCD	Counter Clock Divide Value	Counter Clock Divide (Default: 000) These bits specify the divide value when using the internal clock (IMBUSCLK) as the counter input clock source. The binary value <i>n</i> is divided by 2 ^{<i>n</i>+1} . 000: Divide by 2 ¹ (f/2) 001: Divide by 2 ² (f/4) 010: Divide by 2 ³ (f/8) 011: Divide by 2 ⁴ (f/16) 100: Divide by 2 ⁵ (f/32) 101: Divide by 2 ⁶ (f/64) 110: Divide by 2 ⁷ (f/128) 111: Divide by 2 ⁸ (f/256)	R/W

Figure 12.4.6 Divide Register

12.4.7 Pulse Generator Mode Register n (TMPGMR n)

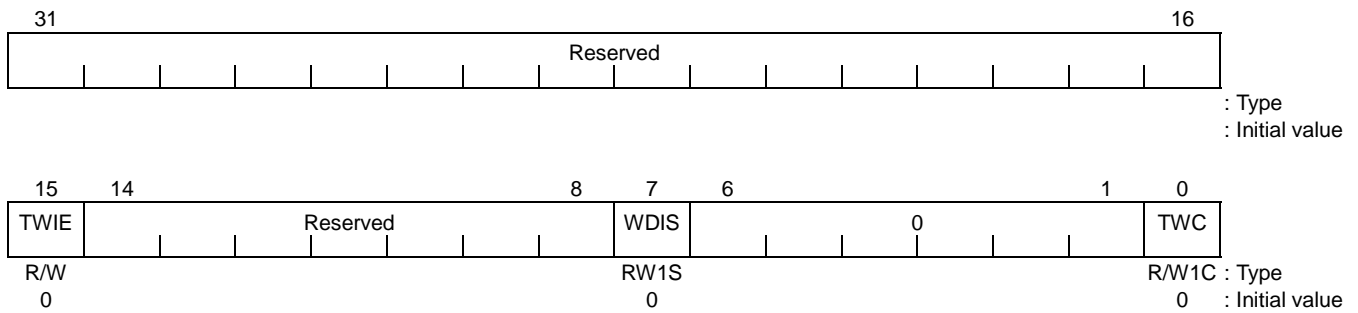
TMPGMR0 0xF000

TMPGMR1 0xF130



Bit	Mnemonic	Field Name	Description	Read/Write
31:16		Reserved		—
15	TPIBE	TMCPRB Interrupt Enable	Timer Pulse Generator Interrupt by TMCPRB Enable (Default: 0) When in the Pulse Generator mode, this bit sets Interrupt Enable/Disable for when TMCPRB and the counter value match. 0: Mask 1: Do not mask	R/W
14	TPIAE	TMCPRA Interrupt Enable	Timer Pulse Generator Interrupt by TMCPRA Enable (Default: 0) When in the Pulse Generator mode, this bit sets Interrupt Enable/Disable for when TMCPRA and the counter value match. 0: Mask 1: Do not mask	R/W
13:1		Reserved		—
0	FFI	Flip Flop Default	Initial TIMER Output Level (Default: 0) This bit specifies the TIMER[n] signal default when in the Pulse Generator mode. 0: Low 1: High	R/W

Figure 12.4.7 Pulse Generator Mode Register

12.4.8 Watchdog Timer Mode Register n (TMWTMR n) TMWTMR2 0xF240

Bit	Mnemonic	Field Name	Description	Read/Write
31:16		Reserved		—
15	TWIE	Watchdog Timer Signaling Enable	Timer Watchdog Enable (Default: 0) This bit sets NMI signaling enable/disable either when in the Watchdog Timer mode or during a reset. This bit cannot be cleared when the Watchdog Timer Disable bit (WDIS) is "0". 0: Disable (mask) 1: Enable	R/W
14:8		Reserved		—
7	WDIS	Watchdog Timer Disable	Watchdog Timer Disable (Default: 0) Only when this bit is set can the counter be stopped by clearing the Watchdog Timer Signaling Enable bit (TWIE) or by clearing the Timer Counter Enable bit (TMTCR2.TCE) of the Timer Control Register. Writing "0" to this bit is not valid. This bit can be cleared in either of the following ways. Clear the Watchdog Timer Interrupt Enable bit (TMWTMR2.TWIE). Clear the Timer Counter Enable bit (TMTCR2.TCE) of the Timer Control Register.	R/W1S
6:1		Reserved		—
0	TWC	Watchdog Timer Clear	Watchdog Timer Clear (Default: 0) Setting this bit to "1" clears the counter. Writing "0" to this bit is not valid. This bit is always read as "0".	R/W1C

Figure 12.4.8 Watchdog Timer Mode Register

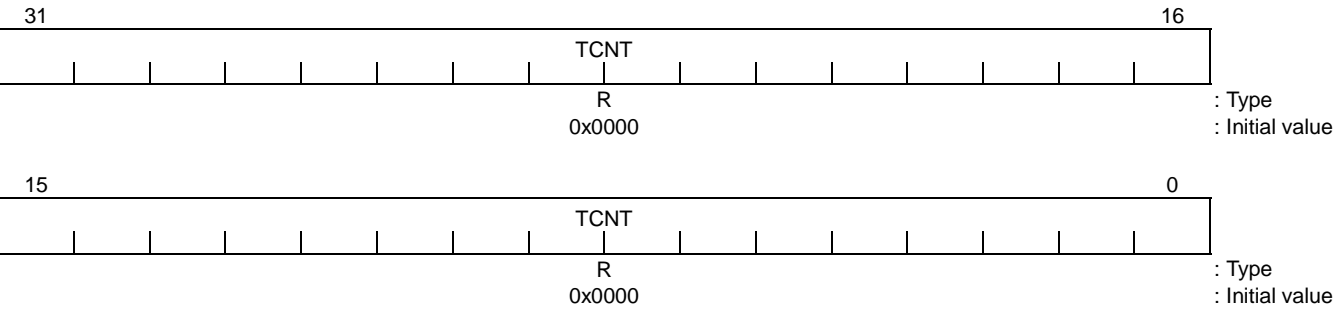
12.4.9 Timer Read Register *n* (TMTRR*n*)

0xF0F0

TMTRR0 0xF0F0

TMTRR1 0xF1F0

TMTRR2 0xF2F0



Bits	Mnemonic	Field Name	Description	Read/Write
31:0	TCNT	Timer Counter	Timer Counter (Default: 0x00000000) This Read Only register is a 32-bit counter. Operation when this register is written to is undefined.	R

Figure 12.4.9 Timer Read Register 0

13. Parallel I/O Port

13.1 Characteristics

The TX4927 on-chip Parallel I/O port (PIO) is a 16-bit general-purpose parallel port. The input/output direction and the port type during output (totem pole output/open drain output) can be set for each bit.

13.2 Block Diagram

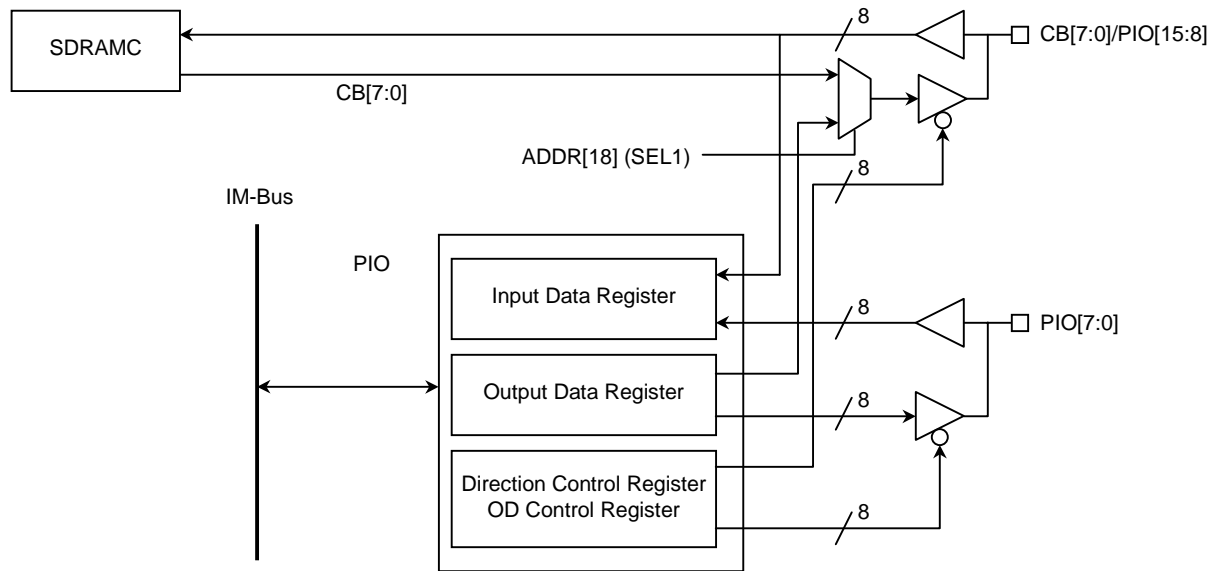


Figure 13.2.1 Parallel I/O Block Diagram

13.3 Detailed Description

13.3.1 Selecting PIO Pins

Of the 16-bit PIO signals, signals PIO[15:8] can be used in combination with 8-bit ECC check bit signals. The configuration signal (ADDR[18]) at boot up determines which function will be used. See 3.3 Configuration Signals for more information.

13.3.2 General-purpose Parallel Port

The four following registers are used to control the PIO port.

- PIO Output Data Register (PIODO)
- PIO Input Data Register (PIODI)
- PIO Direction Control Register (PIODIR)
- PIO Open Drain Control Register (PIOOD)

PIO signals can be selected by the PIO Direction Control Register (PIODIR) for each bit as either input or output.

Signals selected as output signals output the values written into the PIO Data Output Register (PIODO). The PIO Open Drain Control Register (PIOOD) can select whether each bit is either an open drain output or a totem pole output.

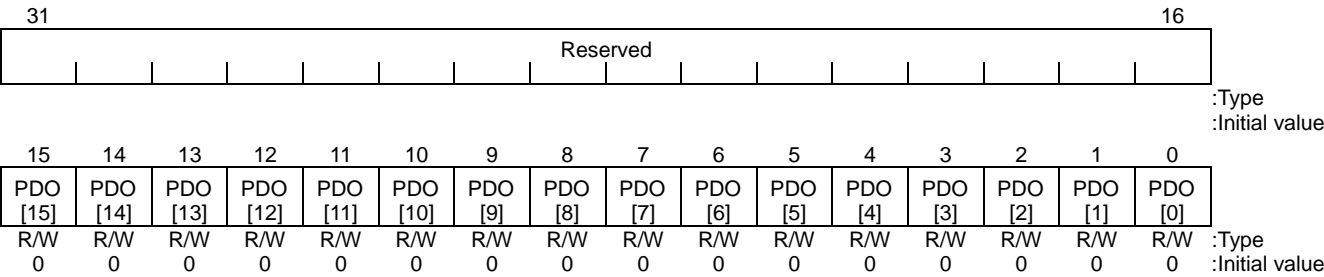
PIO signal status is indicated by the PIO Data Input Register. This register can be read out at any time regardless of the pin direction settings.

13.4 Registers

Table 13.4.1 PIO Register Map

Offset Address	Mnemonic	Register Name
0xF500	PIODO	Output Data Register
0xF504	PIODI	Input Data Register
0xF508	PIODIR	Direction Control Register
0xF50C	PIOOD	Open Drain Control Register

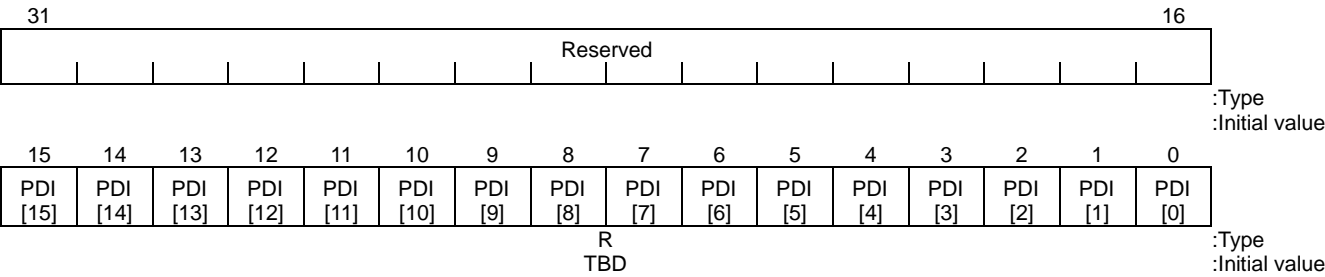
13.4.1 PIO Output Data Register (PIODO) 0xF500



Bit	Mnemonic	Field Name	Description	Read/Write
31:16		Reserved		—
15:0	PDO [15:0]	Data Out	Port Data Output [15:0] (Initial value:0x0000) Data that is output to the PIO pin (PIO [15:0]).	R/W

Figure 13.4.1 PIO Output Data Register

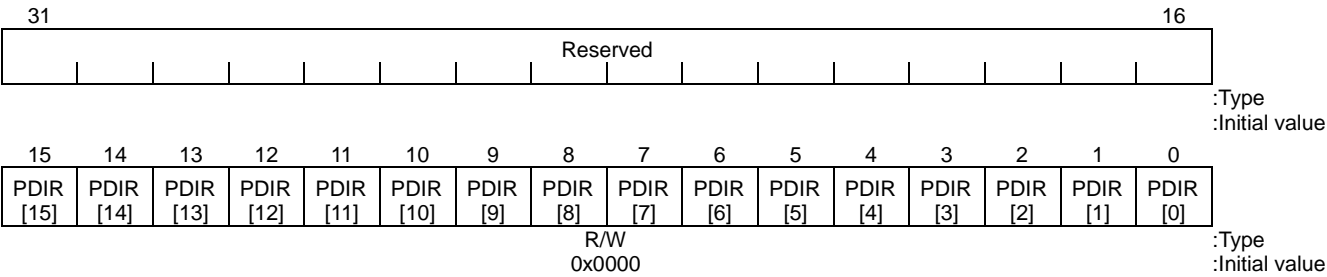
13.4.2 PIO Input Data Register (PIODI) 0xF504



Bit	Mnemonic	Field Name	Description	
31:16		Reserved		—
15:0	PDI [15:0]	Data In	Port Data Input [15:0] (Initial value:TBD) Data that is input to the PIO pin (PIO [15:0]).	R

Figure 13.4.2 PIO Input Data Register

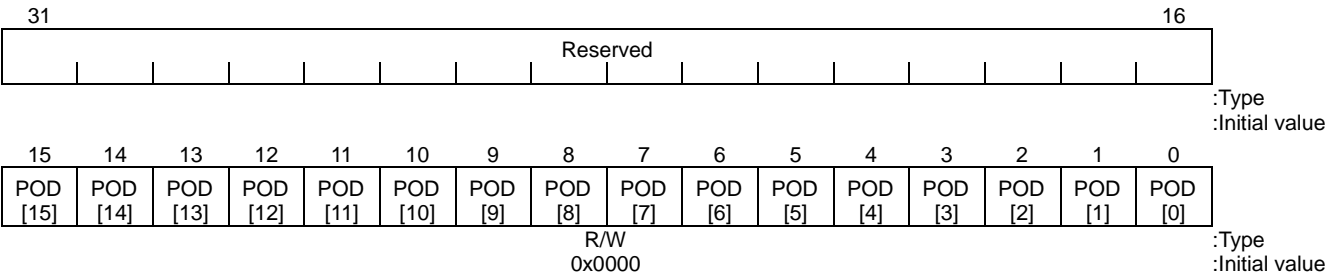
13.4.3 PIO Direction Control Register (PIODIR) 0xF508



Bit	Mnemonic	Field Name	Description	Read/Write
31:16		Reserved		—
15:0	PDIR [15:0]	Direction Control	Port Direction Control [15:0] (Initial value: 0x0000) Sets the I/O direction of the PIO pin (PIO [15:0]). 0: Input (Reset) 1: Output	R/W

Figure 13.4.3 PIO Direction Control Register

13.4.4 PIO Open Drain Control Register (XPI00D) 0xE50C



Bit	Mnemonic	Field Name	Description	Read/Write
31:16		Reserved		—
15:0	POD [15:0]	Open Drain Control	Port Open Drain Control [15:0] (Initial value: 0x0000) Sets whether to use the PIO pin (PIO [15:0]) as an open drain. 0: Open drain (Reset) 1: Totem pole	R/W

Figure 13.4.4 PIO Open Drain Control Register

14. AC-link Controller

14.1 Features

ACLC, AC-link controller module can be connected to audio and/or modem CODECs described in the “Audio CODEC ’97 Revision 2.1” (AC’97) defined by Intel and can operate them. Refer to the following Web site for more information regarding the AC’97 specification.

<http://developer.intel.com/ial/scalableplatforms/audio/>

Its features are summarized as follows.

- Up to two CODECs are supported.
- AC’97 compliant CODEC register access protocol is supported.
- CODEC register access completion is recognized by polling or interrupt.
- Recording and playback of 16-bit PCM Left&Right channels are supported.
- Recording can be selected from PCM L&R or Mic.
- Playback of 16-bit Surround, Center, and LFE channels is supported.
- Variable Rate Audio recording is supported.
- Variable Rate Audio playback is supported.
- Line 1 and GPIO slots for Modem CODEC are supported.
- AC-link low-power mode, wake-up, and warm-reset are supported
- Sample-data I/O via DMA transfer is supported.

14.2 Configuration

Figure 14.2.1 illustrates the ACLC configuration.

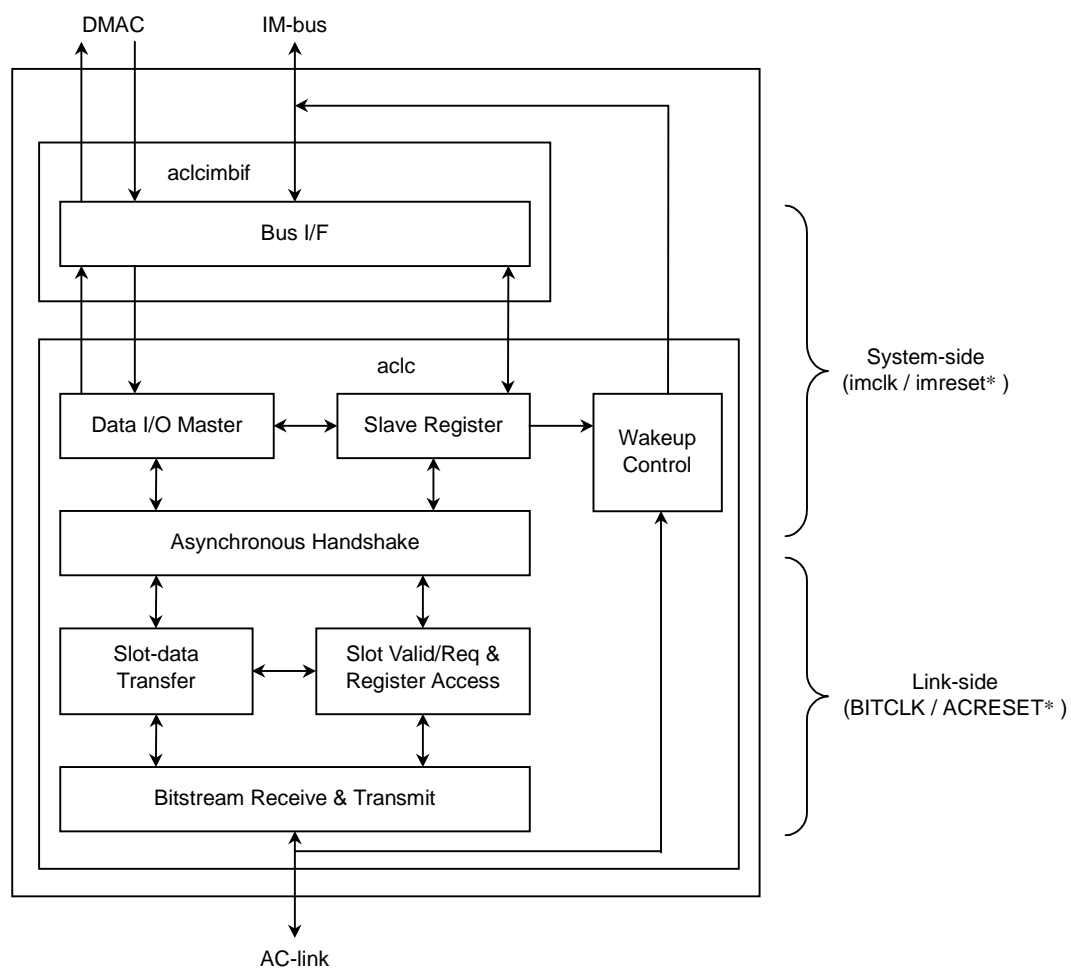


Figure 14.2.1 ACLC Module Configuration

14.3 Functional Description

ACLC provides four mechanisms to operate AC'97-compliant CODEC(s):

- AC-link status control (start-up and low-power mode)
- CODEC register access
- Sample-data transmission and reception
- GPIO operation

This section first describes the CODEC connection, chip configuration, and overall usage-flow. Then AC-link start-up sequence and the other mechanisms will be described. Using low-power mode comes last.

14.3.1 CODEC Connection

The ACLC module has two SDIN (named as SDATA_IN in the AC'97 specification) signals and supports up to two CODECs to be connected. This section shows some system configuration diagrams for typical usages. Note that the diagrams shown here is intended to provide conceptual understanding and some components may be necessary on the actual circuit board to ensure proper electrical signals. The diagrams assume CODECs compliant with the CODEC ID strapping recommendation described in the section D.5.2 of the AC'97 revision 2.1 specification.

14.3.1.1 Stereo Audio and Optional Modem Connection

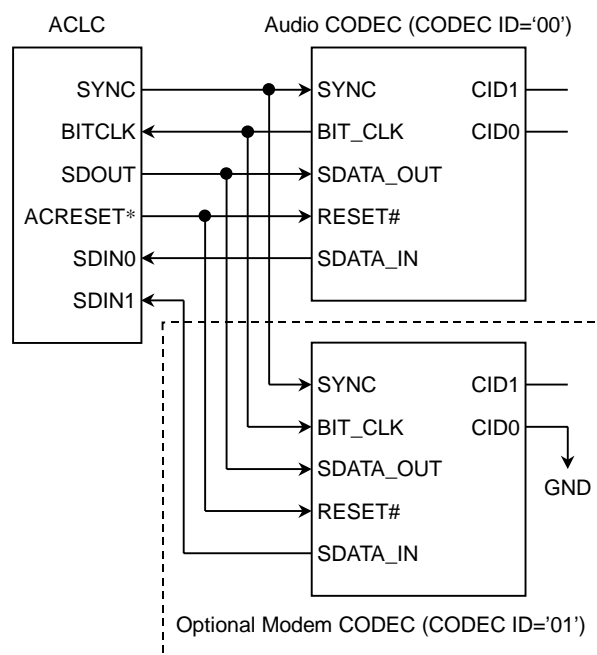


Figure 14.3.1 Stereo Audio and Optional Modem Connection Diagram

14.3.1.2 5.1 Channel Audio Connection

This sample assumes one CODEC with four DACs mapped to stereo front (3&4) and stereo rear (7&8) slots, and another CODEC with two DACs mapped to center (6) and LFE (9) slots.

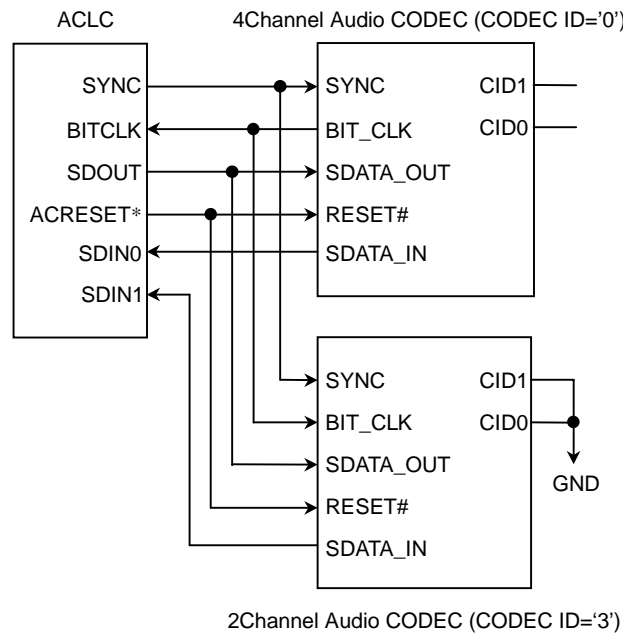


Figure 14.3.2 5.1 Channel Audio Connection Diagram

14.3.2 Boot Configuration

To utilize ACLC, the CPU must boot up with ACLC enabled by setting Pin Configuration Register's Shared Pin Select2 via the boot configuration. Refer to the sections 3.2 and 5.2.3 for the detail of the boot configuration.

14.3.3 Usage Flow

This section outlines a process flow when using the AC'97 connected to ACLC. Refer to the subsequent sections for the details of each operation performed in this process flow. The diagrams below describe the audio playback and recording processes. The modem transmission and reception can be done in a similar way.

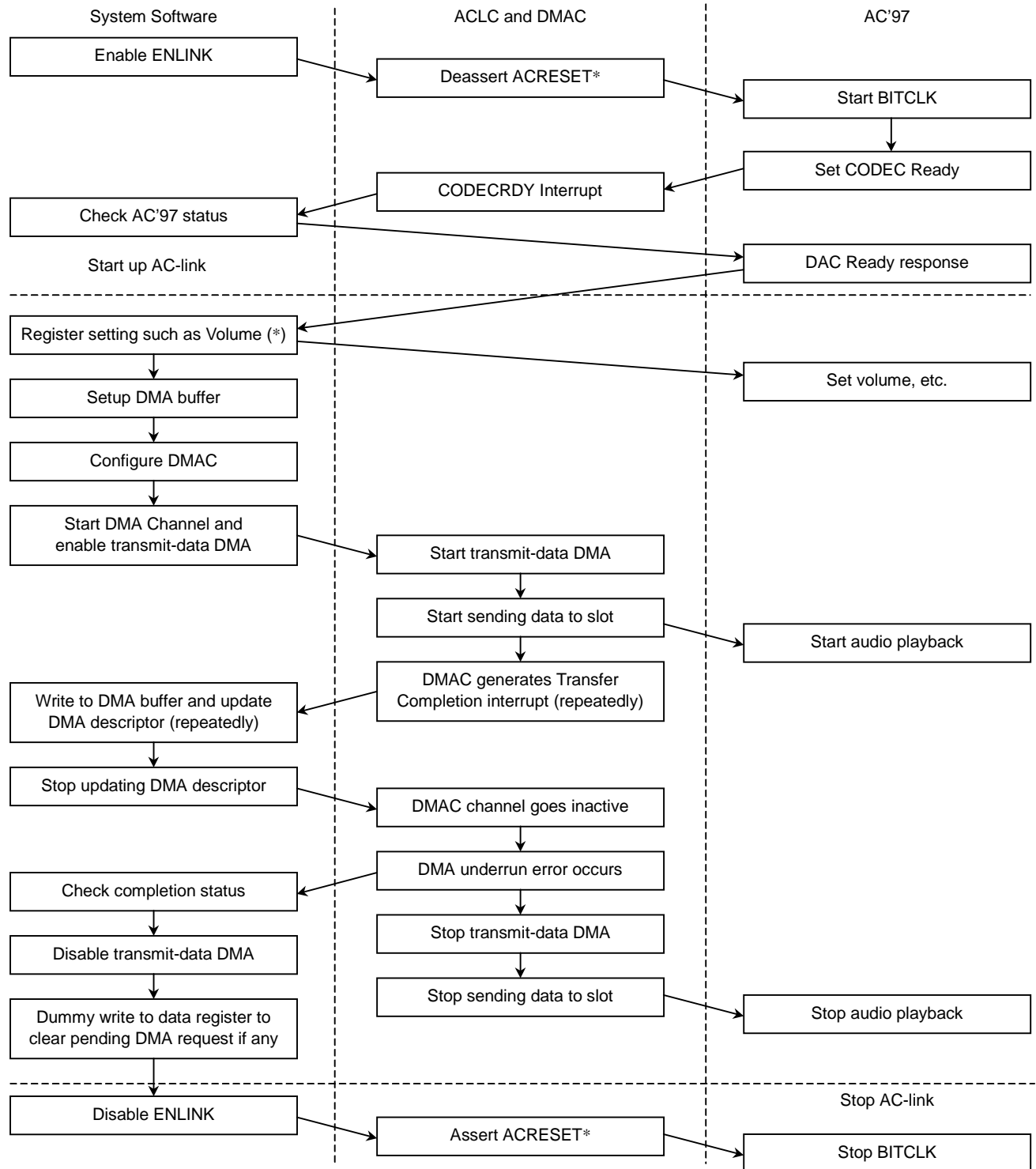
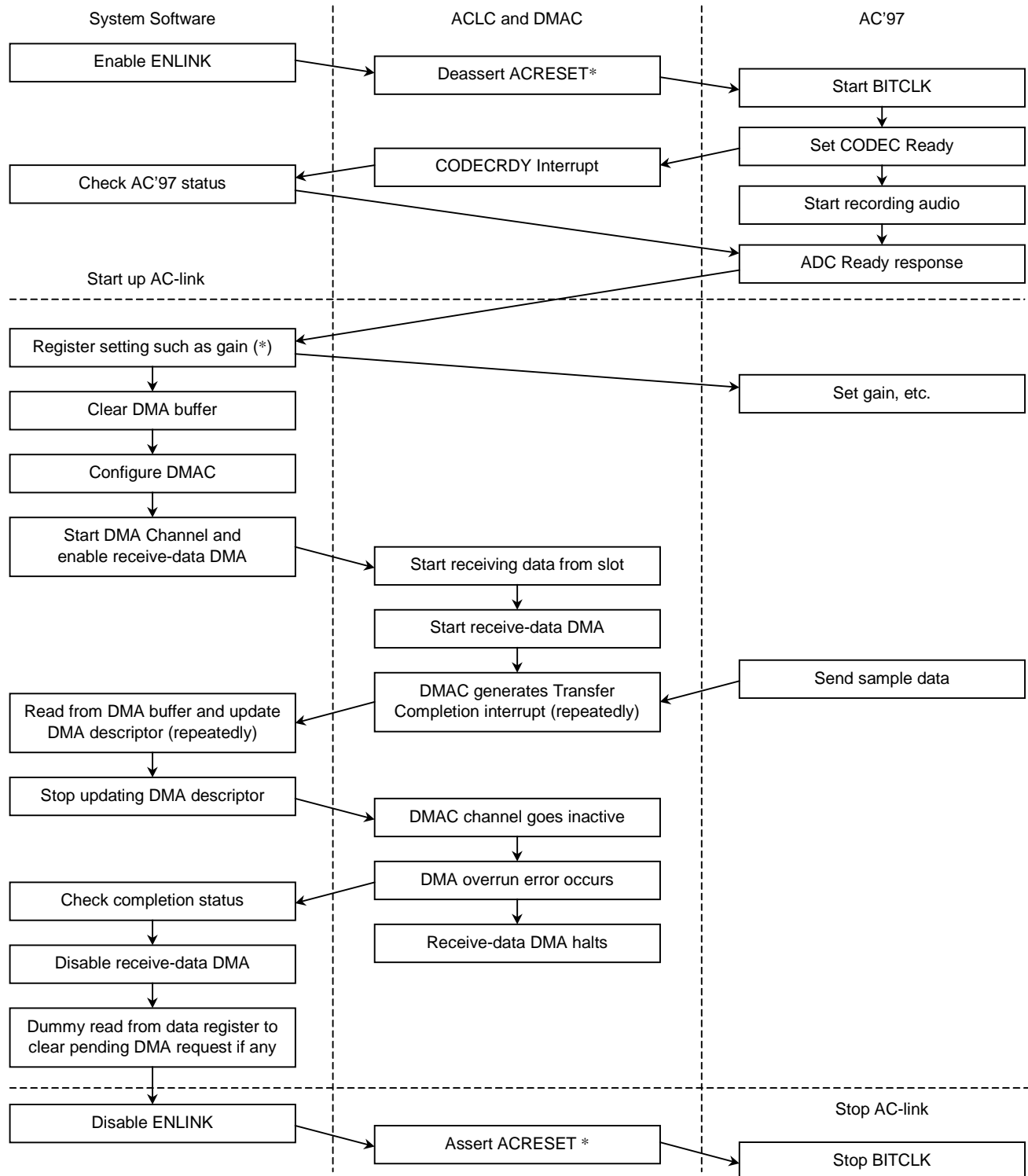


Figure 14.3.3 Audio Playback Process Flow



(*) Register settings such as gain can be made during data recording

Figure 14.3.4 Audio Recording Process Flow

14.3.4 AC-link Start Up

Figure 14.3.5 shows the conceptual sequence of AC-link start-up.

The ACLC Control Enable Register's Enable AC-link bit is used to deassert/assert the **ACRESET*** signal to the link side (including AC-link). This bit defaults to '0', so the CPU asserts the **ACRESET*** signal when it boots up.

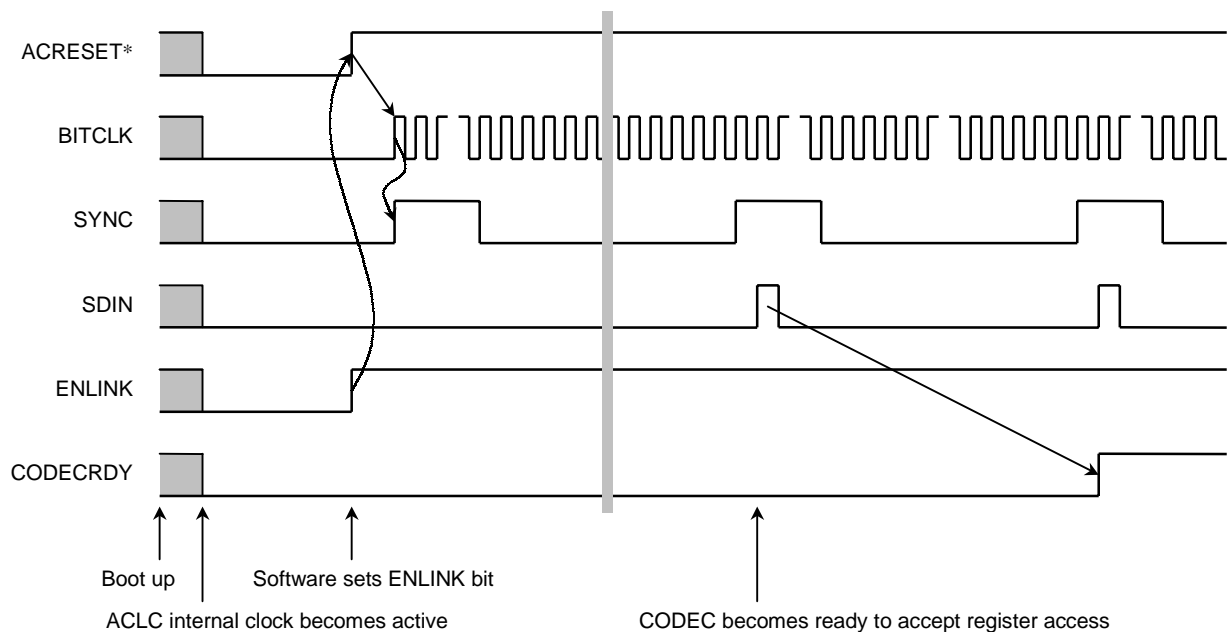
The AC'97 specification requires that the reset assertion period is 1 μ s or longer. The software is responsible for controlling the length of this period.

The AC'97 specification also requires that the primary CODEC stops the AC-link clock (**BITCLK**) signal during the period from **ACRESET*** signal assertion to 162.8ns after **ACRESET*** signal deassertion. ACLC assumes the primary CODEC meet this requirement.

Deasserting the link-side reset makes the primary CODEC start driving the **BITCLK** signal. When the **BITCLK** signal is provided, ACLC starts the **SYNC** signal output, which indicates the start of the AC-link frame, and starts the frame-length counting.

When a CODEC becomes ready to receive access to its own register, the CODEC sets the "CODEC Ready" bit of the Tag slot. When ACLC detects that this bit has been set, the ACLC Interrupt Status Register (**ACINTSTS**)'s **CODEC[1:0] Ready (CODEC[1:0]RDY)** bit is set. The system software is able to recognize the readiness of the CODEC(s) by detecting this event by way of either polling or interrupt.

In case of 5.1 channel audio connection example (Figure 14.3.2), because the secondary CODEC is connected to the **SDIN1** signal of ACLC, the software must watch **ACINTSTS.CODEC1RDY** bit to determine the CODEC's readiness for the register access.



Note: The number of **BITCLK** cycles relative to other signals is not to scale.

Figure 14.3.5 Cold Reset and CODEC Ready Recognition

14.3.5 CODEC Register Access

By accessing registers in the CODEC, the system software is able to detect or control the CODEC state. This section describes how to read and write CODEC registers via ACLC. For details about AC'97 register set and proper sequence to operate CODEC, refer to the AC'97 specification and target CODEC datasheet.

It takes several frame periods for a read or write access to complete. Taking this into account, ACLC is equipped with a function for reporting CODEC register access completion as status-change or interrupt.

In order to read an AC'97 register, write the access destination CODEC ID and register address in ACLC CODEC Register Access Register (ACREGACC) with its CODECRD bit set to "1". After the ACLC Interrupt Status Register (ACINTSTS)'s REGACC Ready (REGACCRDY) bit is set, the software is able to get the data returned from the AC'97 by reading the ACREGACC register and issue another access.

In order to write to an AC'97 register, write the access destination CODEC ID, register address, and the data in ACLC's ACREGACC register with ACREGACC.CODECRD bit set to "0". After the ACINTSTS.REGACCRDY bit has been set, the software is able to issue another access.

In case of 5.1 channel audio connection example (Figure 14.3.2), because the secondary CODEC has CODEC ID of '3', the software must write '3' into ACREGACC.CODECID field when it issues secondary CODEC register access.

14.3.6 Sample-data Transmission and Reception

This section describes the mechanism for transmission and reception of PCM audio and modem wave-data. An overview is described first. The DMA (Direct Memory Access) operation, error detection and recovery procedure follow. A special case using slot activation control is described last.

14.3.6.1 Overview

Figure 14.3.6 and Figure 14.3.7 show conceptual views of the sample-data transmission and reception mechanisms.

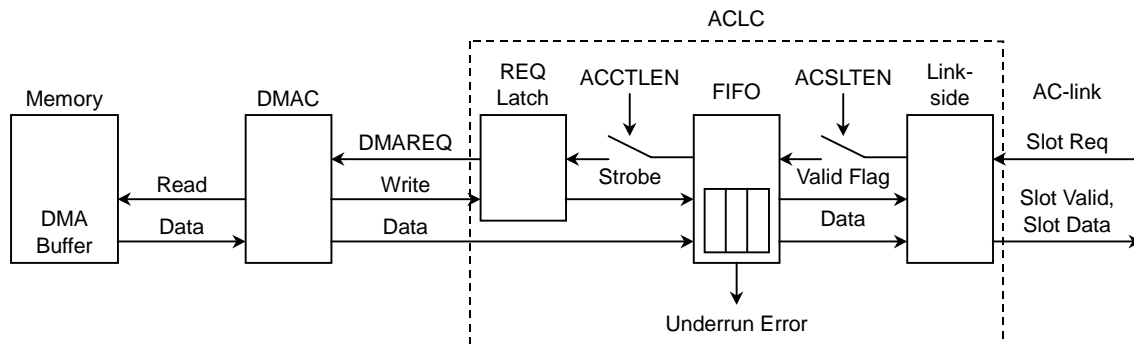


Figure 14.3.6 Sample-data Transmission Mechanism

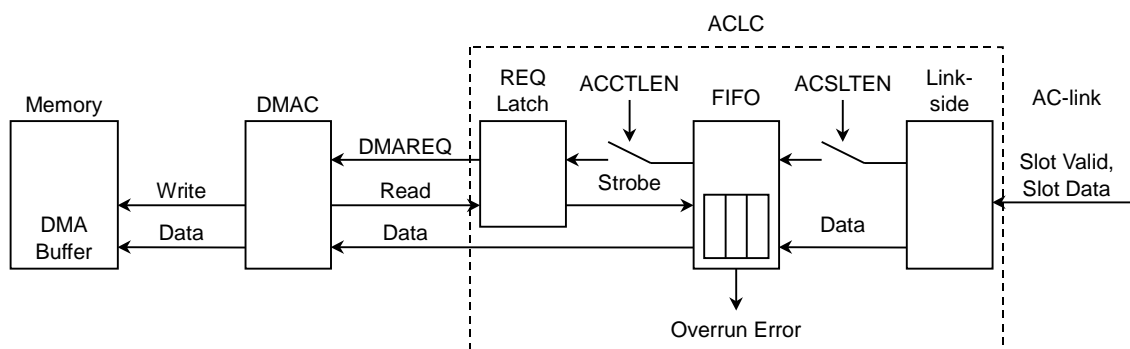


Figure 14.3.7 Sample-data Reception Mechanism

The CODEC requests ACLC to transmit and receive sample-data via 'slot-request' and 'slot-valid' bit-fields on the SDIN signal of AC-link.

For transmission, ACLC transmits the data with 'slot-valid' tag set. For reception, ACLC captures the slot-data.

Transmission or reception through each stream can be independently activated or deactivated under control of ACLC Slot Enable Register (ACSLTEN).

ACLC is equipped with a separate FIFO for each data-stream. The data to transmit is prefetched from memory to FIFO through DMA. The received data is buffered on FIFO and then stored to memory through DMA. In this stage, each DMA is independently activated or deactivated under control of ACLC Control Enable Register (ACCTLEN).

14.3.6.2 DMA Channel Mapping

ACLC uses four DMA request channels. These DMA channels are allocated to four out of seven data-streams, or slots, on the AC-link frame, according to ACLC DMA Channel Selection Register (ACDMASEL) setting as shown in Table 14.3.1. The pin configuration register allocates these DMA channels of ACLC to the DMAC (DMA controller) channels according to Pin Configuration Register (PCFG)'s DMA Request Selection (DMASEL[7:0]) bits as described in section 5.1.3.

Table 14.3.1 DMA Channel Mapping Modes

AC-link Slot Number	ACDMASEL			
	0	1	2	3
PCM L&R out (3&4)	ACLC ch0	ACLC ch0	ACLC ch0	ACLC ch0
Surround L&R out (7&8)		ACLC ch1	ACLC ch1	ACLC ch1
Center out (6)			ACLC ch2	
LFE out (9)			ACLC ch3	ACLC ch3
PCM L&R in (3&4) or Mic in (6)	ACLC ch1			ACLC ch2
Modem Line1 out (5)	ACLC ch2	ACLC ch2		
Modem Line 1 in (5)	ACLC ch3	ACLC ch3		

14.3.6.3 Sample-data Format

ACLC transmits/receives 16 bits per sample for each data slot shown in Table 14.3.1. The data resides on the first 16 bits of the 20 bits assigned to each slot on AC-link. Each sample-data register allows access by word (32-bit) unit only. Therefore the DMA count must be a multiple of word. Note that the transmit-data DMA count also must be the FIFO depth (refer to ***) or more for a reason described later.

For audio PCM front and surround streams, every data-word is loaded with a couple of left and right samples. For audio MIC stream, valid data is loaded in the same field as the left sample while the other field is filled with '0'. For audio center, LFE, and modem line 1 streams, two consecutive samples are packed into every word.

The data format at the sample-data register is arranged so that the data format on the DMA buffer follows the rules below.

- Each sample data is put in the byte order in which the CPU operates (big- or little-endian).
- Samples are put in the time-sequential order at increasing addresses on memory.
- For a DMA channel which couples left and right samples, each left sample precedes the corresponding right sample.

Refer to the sections 14.4.16 and later for the register format.

Figures below show the format of DMA buffer for each type of DMA channel. #0, #1, ... means the sample's sequential number for the AC-link slot. Subscript 'L' means lower 8-bit of each sample and subscript 'H' means upper 8-bit.

Table 14.3.2 Front and Surround DMA Buffer Format in Little-endian Mode

Address offset	+0	+1	+2	+3
+0	Left#0 _L	Left#0 _H	Right#0 _L	Right#0 _H
+4	Left#1 _L	Left#1 _H	Right#1 _L	Right#1 _H
+8	Left#2 _L	Left#2 _H	Right#2 _L	Right#2 _H
:	:	:	:	:

Table 14.3.3 Center, LFE, and Modem DMA Buffer Format in Little-endian Mode

Address offset	+0	+1	+2	+3
+0	#0 _L	#0 _H	#1 _L	#1 _H
+4	#2 _L	#2 _H	#3 _L	#3 _H
+8	#4 _L	#4 _H	#5 _L	#5 _H
:	:	:	:	:

Table 14.3.4 Mic DMA Buffer Format in Little-endian Mode

Address offset	+0	+1	+2	+3
+0	#0 _L	#0 _H	0	0
+4	#1 _L	#1 _H	0	0
+8	#2 _L	#2 _H	0	0
:	:	:	:	:

Table 14.3.5 Front and Surround DMA Buffer Format in Big-endian Mode

Address offset	+0	+1	+2	+3
+0	Left#0 _H	Left#0 _L	Right#0 _H	Right#0 _L
+4	Left#1 _H	Left#1 _L	Right#1 _H	Right#1 _L
+8	Left#2 _H	Left#2 _L	Right#2 _H	Right#2 _L
:	:	:	:	:

Table 14.3.6 Center, LFE, and Modem DMA Buffer Format in Big-endian Mode

Address offset	+0	+1	+2	+3
+0	#0 _H	#0 _L	#1 _H	#1 _L
+4	#2 _H	#2 _L	#3 _H	#3 _L
+8	#4 _H	#4 _L	#5 _H	#5 _L
:	:	:	:	:

Table 14.3.7 Mic DMA Buffer Format in Big-endian Mode

Address offset	+0	+1	+2	+3
z	#0 _H	#0 _L	0	0
+4	#1 _H	#1 _L	0	0
+8	#2 _H	#2 _L	0	0
:	:	:	:	:

14.3.6.4 DMA Operation

When ACLC's REQ latch (refer to Figure 14.3.6 and Figure 14.3.7) needs to read or write sample-data, it issues a DMA request. When DMAC acknowledges the request by performing write- or read-access to the ACLC sample-data register, ACLC deasserts the request. Therefore, the software must properly set up DMAC so that the source or destination points to the corresponding sample-data register for the DMA channel.

Setup the DMA Channel Control Registers (DMCCRn) in DMAC as follows.

Immediate chain	Enable	DMCCRn.IMMCHN = 1 [Note]
DMA request polarity	Low-active	DMCCRn.REQPOL = 0
DMA acknowledge polarity	Low-active	DMCCRn.ACKPOL = 0
Request sense	Level-sensitive	DMCCRn.EGREQ = 0
Sample chain	1 word	DMCCRn.SMPCHN = 1
Transfer size	1 word	DMCCRn.XFSZ = 010b
Transfer address mode	Dual	DMCCRn.SNGAD = 0

Note: Use this setting when DMA chain operation is utilized

For a transmission channel, assign the address of ACLC Audio PCM Output/Surround/Center/LFE/Modem Output Register (ACAUDO/SURR/CENT/LFE/MODODAT) to the DMAC destination address register (DMDARn). For a reception channel, assign the address of ACLC Audio input/Modem Input Register (ACAUDI/MODIDAT) to the DMAC source address register (DMSARn).

When any DMA request is pending, the REQ latch will not deasserted the request until the corresponding sample-data register is accessed. Just unsetting ACLC Control Enable Register (ACCTLEN)'s DMA Enable (xxxxDMA) bit corresponding to the DMA will not clear the REQ latch.

The procedure to continuously push or pull the sample-data stream through the chain DMA operation follows the DMAC specification. Refer to section 8.3.10 for this respect.

14.3.6.5 Sample-data FIFO

For a transmission stream, as long as ACLC Control Enable Register (ACCTLEN) allows that transmission and the FIFO has any room to fill data in, the FIFO issues a request via the REQ latch. On the other side, when a transmission FIFO receives a data-request from the link-side, it provides data with valid-flag set if it has any valid data. If it has no valid data, it responds with valid-flag unset and an underrun error bit is set.

At the transmit-data DMA start-up, until the FIFO becomes full, it responds to the link-side with valid-flag unset, in order to maximize the buffering effect. Therefore, the DMA size must be the FIFO depth or more.

Table 14.3.8 Transmission FIFO Depth

Data-stream	FIFO Depth (Word)
PCM L&R out	3
Surround L&R out	3
Center out	2
LFE out	2
Modem Line 1 out	1

The link-side drives the slot-valid bit and slot-data on AC-link. When underrun occurs, these bits are driven to all '0'.

For a reception stream, as long as the FIFO has any valid data, the FIFO issues a request via the REQ latch. On the other side, when ACCTLEN allows that reception and the link-side issues a data strobe, the FIFO stores the valid data. If the FIFO is full when it receives a data strobe, the data is discarded and an overrun error bit is set.

14.3.6.6 Error Detection and Recovery

In most usages, since the CODEC continuously requests sample-data transmission and reception, after DMA is finished, underrun and overrun will occur. The procedure described below allows the software to determine whether an error has occurred during DMA operation.

The software sets ACLC Control Enable Register (ACCTLEN)'s Error Halt Enable (xxxxEHLT) bit before it starts a DMA channel. After it starts the DMA channel, it waits until ACLC Interrupt Status Register (ACINTSTS)'s Underrun or Overrun Error (xxxxERR) bit is set. When the event is detected, the software checks DMA Channel Control Register (DMCCRN)'s Transfer Active (XFACT) bit and ACLC DMA Request Status Register (ACDMASTS)'s Request (xxxxDMA) bit and determines the DMA completion status as follows.

Table 14.3.9 DMA Completion Status Determination

DMCCRN.XFACT	ACDMASTS.xxxxDMA	Completion Status
Inactive	Pending	No Error during DMA
Inactive	Not Pending	Underrun or Overrun
Active	*	Underrun or Overrun

To recover from error, disable and enable the stream via ACCTLEN, and restart the DMA.

14.3.6.7 Slot Activation Control

In case ACLC is required to begin transmission or reception of multiple streams at the same time, slot activation control will be useful. To use this feature, the software must deactivate the relevant streams first, enable ACLC Control Enable Register (ACCTLEN), make sure the transmission FIFO becomes full by checking ACLC FIFO Status Register (ACFIFOSTS)'s Full (xxxxFULL) bit, and finally enable ACLC Slot Enable Register (ACSLTEN). This procedure assures that all the reception streams are activated at a frame and all the transmission streams begin to respond to the slot-request bits of that frame.

Note that access to ACSLTEN and ACLC Slot Disable Register (ACSLTDIS) needs special care to synchronize with the link-side. Refer to the register description for detail.

Since operating ACCTLEN register and DMAC without touching ACSLTEN is sufficient for most usages, the initial ACSLTEN value enables all the transmission and reception through the slots by default.

14.3.6.8 Variable Rate Limitation

To improve compatibility with existing AC'97 CODECs and controllers on the market, ACLC combines sample-data for the slots 3 and 4 into one DMA channel, and similarly for the slots 7 and 8. This feature effectively considers that the slot request bit from the CODEC for slot 4 shall be always same (in tandem) as for slot 3 for each frame, and similarly for the slots 7 and 8. ACLC also considers that the slot valid bit from the CODEC for slot 4 shall be always same (in tandem) as for slot 3 for each frame.

14.3.7 GPIO Operation

ACLC supports the slot 12 for the MC'97 (Modem Codec) GPIO.

The slot 12 is shadowed in the ACLC GPI Data Register (ACGPIDAT) and ACLC GPO Data Register (ACGPODAT) in the following way:

- ACLC copies the slot 12 input data into the ACGPIDAT register, if the slot 12 input is marked by the CODEC as valid in the AC-link frame period.
- ACLC generates the slot 12 output data from the ACGPODAT register and mark it as valid, if the slot 12 is required from the CODEC in the previous AC-link frame.

This shadowing function is enabled as long as ACSLTEN allows.

The bit 0 of the slot 12 is defined as 'GPIO_INT' and can cause ACLC to request an interrupt.

14.3.8 Interrupt

ACLC generate two kinds of interrupt to the interrupt controller as below.

- ACLC Interrupt

Logical OR of all the valid bits of ACLC Interrupt Masked Status Register (ACINTMSTS) is connected. Refer to the section 14.4.5.

- ACLCPME Interrupt

This interrupt shows the wake-up from CODEC in AC-link low-power mode.

Refer to the description for ACLC Control Enable Register (ACCTLEN)'s Wake-up Enable (WAKEUP) bit in section 14.4.1.

14.3.9 AC-link Low-power Mode

The AC'97 specification makes provision for saving power during system suspension by powering-down both the controller and CODEC except the minimum circuit to detect modem RING/Caller-ID event and wake up the system. AC'97 CODEC is required to go into the low-power mode when they receive a special register-write access. In this mode, the AC-link controller must drive all output signals to low level to allow the CODEC digital I/O power cut.

ACLC provides 'AC-link low-power mode' setting. When this mode is enabled by ACLC Control Enable Register (ACCTLEN)'s Enable AC-link Low-power Mode (LOWPWR) bit, all the output signals except the ACRESET* signal to the AC-link are forced to low level.

The AC-link will be reactivated out of the low-power mode when the SYNC signal is driven high for 1 μ s or longer by the AC-link controller while the BITCLK signal is inactive. The software is responsible for controlling the length of this period.

ACLC also provides the 'wake-up' function. While this function is enabled by ACCTLEN Register's Enable Wake-up (WAKEUP) bit, high-level input at any SDIN[x] signal will force ACLCPME interrupt assertion.

When ACLCPME interrupt is recognized, the software must disable the low-power mode and assert warm reset to the AC-link via ACCTLEN Register's Enable Warm Reset (WRESET) bit. After the warm reset is deasserted, the CODEC will start providing the BITCLK signal, and then ACLC will generate the SYNC signal for usual AC-link frames.

Refer to section B.5.1 of AC'97 specification revision 2.1 for the power-down and wake-up sequence in AC-link power-down mode.

14.4 Registers

The base address for the ACLC registers is described in section 4.2. Only word (32-bit) accesses are allowed. These registers return to their initial values when the module gets reset by power-on or configuration-register operation. The 'Disable AC-link' operation initializes the ACREGACC, ACGPIDAT, ACGPODAT, and ACSLTEN registers while keeping the other registers.

Do not access any location which is not mentioned in this section.

All the register bits marked as 'Reserved' are reserved. The value of the reserved bit when read is undefined. When any register is written, write to the reserved bit(s) the same value as the previous value read.

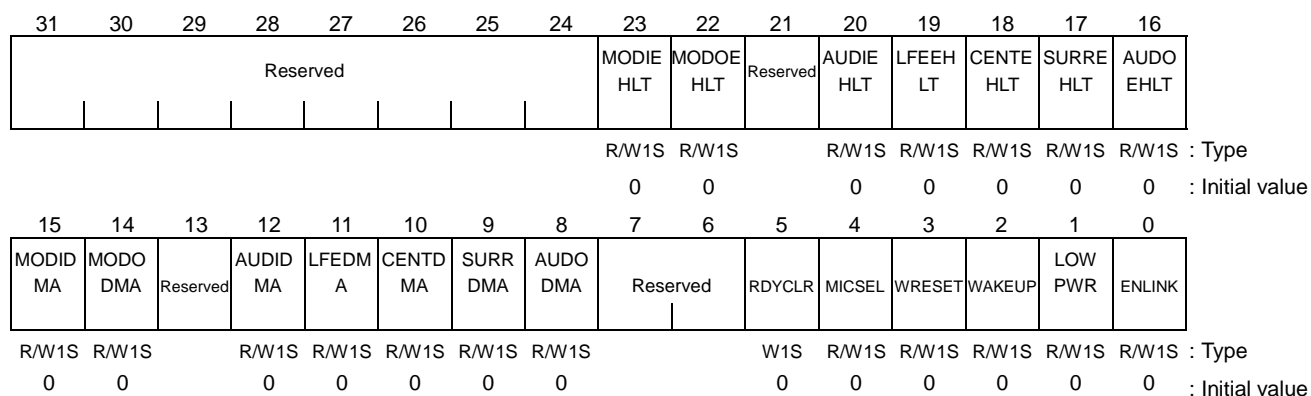
Table 14.4.1 ACLC Registers

Address	Mnemonic	Register Name	Type	Initial Value
0xF700	ACCTLEN	ACLC Control Enable Register	R/W1S	0x00000000
0xF704	ACCTLDIS	ACLC Control Disable Register	W1C	—
0xF708	ACREGACC	ACLC CODEC Register Access Register	R/W	0x00000000
0xF710	ACINTSTS	ACLC Interrupt Status Register	R/W1C	0x00000010
0xF714	ACINTMSTS	ACLC Interrupt Masked Status Register	R	0x00000000
0xF718	ACINTEN	ACLC Interrupt Enable Register	R/W1S	0x00000000
0xF71C	ACINTDIS	ACLC Interrupt Disable Register	W1C	—
0xF720	ACSEMAPH	ACLC Semaphore Register	RS/WC	0x00000000
0xF740	ACGPIDAT	ACLC GPI Data Register	R	0x00000000
0xF744	ACGPODAT	ACLC GPO Data Register	R/W	0x00000000
0xF748	ACSLTEN	ACLC Slot Enable Register	R/W1S	0x000003DF
0xF74C	ACSLTDIS	ACLC Slot Disable Register	W1C	—
0xF750	ACFIFOSTS	ACLC FIFO Status Register	R	0x00000000
0xF780	ACDMASTS	ACLC DMA Request Status Register	R	0x00000000
0xF784	ACDMASEL	ACLC DMA Channel Selection Register	R/W	0x00000000
0xF7A0	ACAUDODAT	ACLC Audio PCM Output Data Register	W	—
0xF7A4	ACSURRDAT	ACLC Surround Data Register	W	—
0xF7A8	ACCENTDAT	ACLC Center Data Register	W	—
0xF7AC	ACLFEDAT	ACLC LFE Data Register	W	—
0xF7B8	ACMODODAT	ACLC Modem Output Data Register	W	—
0xF7B0	ACAUDIDAT	ACLC Audio PCM Input Data Register	R	0xFFFFFFFF
0xF7BC	ACMODIDAT	ACLC Modem Input Data Register	R	0xFFFFFFFF
0xF7FC	ACREVID	ACLC Revision ID Register	R	0x00000203

14.4.1 ACLC Control Enable Register

0xF700

This register is used to check the setting of various ACLC features and to enable them.



Bit	Mnemonic	Field Name	Description	Read/Write
31:24	—	Reserved		—
23		Enable Modem Receive-data DMA Error Halt	MODIEHLT: Enable Modem Receive-data DMA Error Halt. R 0: Indicates that MODIDMA error halt is disabled. 1: Indicates that MODIDMA error halt is enabled. W1S 0: No effect 1: Enables MODIDMA error halt. When MODIDMA overrun occurs, subsequent DMA will not be issued.	R/W1S
22	MODOEHLT	Enable Modem Transmit-data DMA Error Halt	MODOEHLT: Enable Modem Transmit-data DMA Error Halt. R 0: Indicates that MODODMA error halt is disabled. 1: Indicates that MODODMA error halt is enabled. W1S 0: No effect 1: Enables MODODMA error halt. When MODODMA underrun occurs, subsequent DMA will not be issued.	R/W1S
21	—	Reserved		—
20	AUDIEHLT	Enable Audio Receive-data DMA Error Halt	AUDIEHLT: Enable Audio Receive-data DMA Error Halt. R 0: Indicates that AUDIDMA error halt is disabled. 1: Indicates that AUDIDMA error halt is enabled. W1S 0: No effect 1: Enables AUDIDMA error halt. When AUDIDMA overrun occurs, subsequent DMA request will not be issued.	R/W1S
19	LFEELT	Enable Audio LFE Transmit-data DMA Error Halt	LFEELT: Enable Audio LFE Transmit-data DMA Error Halt. R 0: Indicates that LFEDMA error halt is disabled. 1: Indicates that LFEDMA error halt is enabled. W1S 0: No effect 1: Enables LFEDMA error halt. When LFEDMA underrun occurs, subsequent DMA request will not be issued.	R/W1S
18	CENTEHLT	Enable Audio Center Transmit-data DMA Error Halt	CENTEHLT: Enable Audio Center Transmit-data DMA Error Halt. R 0: Indicates that CENTDMA error halt is disabled. 1: Indicates that CENTDMA error halt is enabled. W1S 0: No effect 1: Enables CENTDMA error halt. When CENTDMA underrun occurs, subsequent DMA request will not be issued.	R/W1S

Figure 14.4.1 ACCTLEN Register (1/3)

Bit	Mnemonic	Field Name	Description	Read/Write
17	SURREHLT	Enable Audio Surround L&R Transmit-data DMA Error Halt	<p>SURREHLT: Enable Audio Surround L&R Transmit-data DMA Error Halt.</p> <p>R 0: Indicates that SURRDMA error halt is disabled. 1: Indicates that SURRDMA error halt is enabled.</p> <p>W1S 0: No effect 1: Enables SURRDMA error halt. When SURRDMA underrun occurs, subsequent DMA request will not be issued.</p>	R/W1S
16	AUDOEHLT	Enable Audio PCM L&R Transmit-data DMA Error Halt	<p>AUDOEHLT: Enable Audio PCM L&R Transmit-data DMA Error Halt.</p> <p>R 0: Indicates that AUDODMA error halt is disabled. 1: Indicates that AUDODMA error halt is enabled.</p> <p>W1S 0: No effect 1: Enables AUDODMA error halt. When AUDODMA underrun occurs, subsequent DMA request will not be issued.</p>	R/W1S
15	MODIDMA	Enable Modem Receive-data DMA	<p>MODIDMA: Enable Modem Receive-data DMA.</p> <p>R 0: Indicates that modem receive-data DMA is disabled. 1: Indicates that modem receive-data DMA is enabled.</p> <p>W1S 0: No effect 1: Enables modem receive-data DMA.</p>	R/W1S
14	MODODMA	Enable Modem Transmit-data DMA	<p>MODODMA: Enable Modem Transmit-data DMA.</p> <p>R 0: Indicates that modem transmit-data DMA is disabled. 1: Indicates that modem transmit-data DMA is enabled.</p> <p>W1S 0: No effect 1: Enables modem transmit-data DMA. [Note: DMA size must be internal FIFO depth or more.]</p>	R/W1S
13	—	Reserved		—
12	AUDIDMA	Enable Audio Receive-data DMA	<p>AUDIDMA: Enable Audio Receive-data DMA.</p> <p>R 0: Indicates that audio receive-data DMA is disabled. 1: Indicates that audio receive-data DMA is enabled.</p> <p>W1S 0: No effect 1: Enables audio receive-data DMA.</p>	R/W1S
11	LFEDMA	Enable Audio LFE Transmit-data DMA	<p>LFEDMA: Enable Audio LFE Transmit-data DMA.</p> <p>R 0: Indicates that audio LFE transmit-data DMA is disabled. 1: Indicates that audio LFE transmit-data DMA is enabled.</p> <p>W1S 0: No effect 1: Enables audio LFE transmit-data DMA. [Note: DMA size must be internal FIFO depth or more.]</p>	R/W1S
10	CENTDMA	Enable Audio Center Transmit- data DMA	<p>CENTDMA: Enable Audio Center Transmit-data DMA.</p> <p>R 0: Indicates that audio Center transmit-data DMA is disabled. 1: Indicates that audio Center transmit-data DMA is enabled.</p> <p>W1S 0: No effect 1: Enables audio Center transmit-data DMA. [Note: DMA size must be internal FIFO depth or more.]</p>	R/W1S
9	SURRDMA	Enable Audio Surround L&R Transmit-data DMA	<p>SURRDMA: Enable Audio Surround L&R Transmit-data DMA.</p> <p>R 0: Indicates that audio Surround L&R transmit-data DMA is disabled. 1: Indicates that audio Surround L&R transmit-data DMA is enabled.</p> <p>W1S 0: No effect 1: Enables audio Surround L&R transmit-data DMA. [Note: DMA size must be internal FIFO depth or more.]</p>	R/W1S
8	AUDODMA	Enable Audio PCM L&R Transmit-data DMA	<p>AUDODMA: Enable Audio PCM L&R Transmit-data DMA.</p> <p>R 0: Indicates that audio PCM L&R transmit-data DMA is disabled. 1: Indicates that audio PCM L&R transmit-data DMA is enabled.</p> <p>W1S 0: No effect 1: Enables audio PCM L&R transmit-data DMA. [Note: DMA size must be internal FIFO depth or more.]</p>	R/W1S

Figure 14.4.1 ACCTLEN Register (2/3)

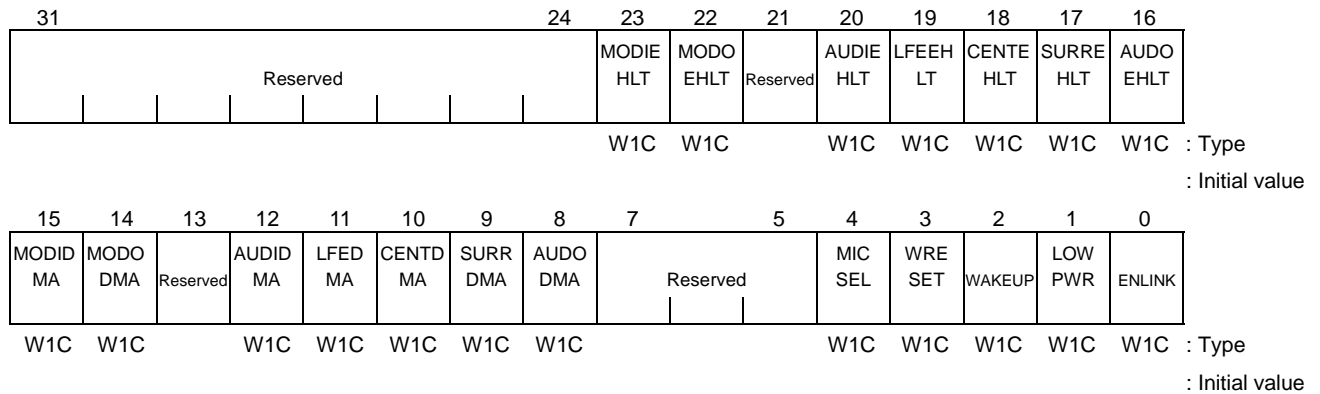
Bit	Mnemonic	Field Name	Description	Read/Write
7:6	—	Reserved		—
5	RDYCLR	Clear CODEC Ready Bit	RDYCLR: Clear CODEC Ready Bit W1C 0: No effect 1: Clear CODEC[1:0] ready bits [Note: This bit should only be written to reevaluate the CODEC ready status after power-down command is sent to CODEC.]	W1S
4	MICSEL	MIC Selection	MICSEL: MIC Selection. R 0: Indicates that PCM L&R (Slot 3&4) is selected for audio reception. 1: Indicates that MIC (Slot 6) is selected for audio reception. W1S 0: No effect 1: Selects MIC (Slot 6) for audio reception.	R/W1S
3	WRESET	Assert Warm Reset	WRESET: Assert Warm Reset. R 0: Indicates that warm reset is not asserted. 1: Indicates that warm reset is asserted. W1S 0: No effect 1: Asserts warm reset. [Note 1: Do not assert warm reset during normal operation.] [Note 2: The software must guarantee the warm reset assertion time meets the AC'97 specification (1.0 μ s or more).]	R/W1S
2	WAKEUP	Enable Wake-up	WAKEUP: Enable Wake-up. R 0: Indicates that wake-up from low-power mode is disabled. 1: Indicates that wake-up from low-power mode is enabled. While any SDIN signal is driven high, ACLC asserts ACLCPME interrupt request to the interrupt controller. W1S 0: No effect 1: Enables wake-up from low-power mode. [Note: Do not enable wake-up during normal operation.]	R/W1S
1	LOWPWR	Enable AC-link low-power mode	LOWPWR: Enable AC-link Low-power Mode. R 0: SYNC and SDOUT signals are not forced to low. 1: SYNC and SDOUT signals are forced to low. W1S 0: No effect 1: Forces SYNC and SDOUT signals low. [Note: Do not enable AC-link low-power mode during normal operation.]	R/W1S
0	ENLINK	Enable AC-link	ENLINK: Enable AC-link. R 0: Indicates that the ACRESET* signal to AC-link is asserted. 1: Indicates that the ACRESET* signal to AC-link is not asserted. W1S 0: No effect 1: Deasserts the ACRESET* signal to AC-link [Note: The software must guarantee the ACRESET* signal assertion time meets the AC'97 specification (1.0 μ s or more).]	R/W1S

Figure 14.4.1 ACCTLEN Register (3/3)

14.4.2 ACLC Control Disable Register

0xF704

This register is used to disable various ACLC features.



Bit	Mnemonic	Field Name	Description	Read/Write
31:24	—	Reserved		—
23	MODIEHLT	Disable Modem Receive-data DMA Error Halt	MODIEHLT: Disable Modem Receive-data DMA Error Halt. W1C 0: No effect 1: Disables MODIDMA error halt. MODIDMA request(s) will continue to be issued even after MODIDMA overrun occurs.	W1C
22	MODEHLT	Disable Modem Transmit-data DMA Error Halt	MODEHLT: Disable Modem Transmit-data DMA Error Halt. W1C 0: No effect 1: Disables MODODMA error halt. MODODMA request(s) will continue to be issued even after MODODMA underrun occurs.	W1C
21		Reserved		—
20	AUDIEHLT	Disable Audio Receive-data DMA Error Halt	AUDIEHLT: Disable Audio Receive-data DMA Error Halt. W1C 0: No effect 1: Disables AUDIDMA error halt. AUDIDMA request(s) will continue to be issued even after AUDIDMA overrun occurs.	W1C
19	LFEEHLT	Disable Audio LFE Transmit-data DMA Error Halt	LFEEHLT: Disable Audio LFE Transmit-data DMA Error Halt. W1C 0: No effect 1: Disables LFEDMA error halt. LFEDMA request(s) will continue to be issued even after LFEDMA underrun occurs.	W1C
18	CENTEHLT	Disable Audio Center Transmit-data DMA Error Halt	CENTEHLT: Disable Audio Center Transmit-data DMA Error Halt. W1C 0: No effect 1: Disables CENTDMA error halt. CENTDMA request(s) will continue to be issued even after CENTDMA underrun occurs.	W1C
17	SURREHLT	Disable Audio Surround L&R Transmit-data DMA Error Halt	SURREHLT: Disable Audio Surround L&R Transmit-data DMA Error Halt. W1C 0: No effect 1: Disables SURRDMA error halt. SURRDMA request(s) will continue to be issued even after SURRDMA underrun occurs.	W1C
16	AUDOEHLT	Disable Audio PCM L&R Transmit-data DMA Error Halt	AUDOEHLT: Disable Audio PCM L&R Transmit-data DMA Error Halt. W1C 0: No effect 1: Disables AUDODMA error halt. AUDODMA request(s) will continue to be issued even after AUDODMA underrun occurs.	W1C
15	MODIDMA	Disable Modem Receive-data DMA	MODIDMA: Disable Modem Receive-data DMA. W1C 0: No effect 1: Disables modem receive-data DMA.	W1C
14	MODODMA	Disable Modem Transmit-data DMA	MODODMA: Disable Modem Transmit-data DMA. W1C 0: No effect 1: Disables modem transmit-data DMA.	W1C

Figure 14.4.2 ACCTLDIS Register (1/2)

Bit	Mnemonic	Field Name	Description	Read/Write
13		Reserved		—
12		—	AUDIDMA: Disable Audio Receive-data DMA. W1C 0: No effect 1: Disables audio receive-data DMA.	W1C
11		—	LFEDMA: Disable Audio LFE Transmit-data DMA. W1C 0: No effect 1: Disables audio LFE transmit-data DMA.	W1C
10		—	CENTDMA: Disable Audio Center Transmit-data DMA. W1C 0: No effect 1: Disables audio Center transmit-data DMA.	W1C
9		—	SURRDMA: Disable Audio Surround L&R Transmit-data DMA. W1C 0: No effect 1: Disables audio Surround L&R transmit-data DMA.	W1C
8		—	AUDODMA: Disable Audio PCM L&R Transmit-data DMA. W1C 0: No effect 1: Disables audio PCM L&R transmit-data DMA.	W1C
7:5		Reserved		—
4		—	MICSEL: MIC Selection W1C 0: No effect 1: Selects PCM L&R (Slot 3&4) for audio reception	W1C
3		—	WRESET: Deassert Warm Reset. W1C 0: No effect 1: Deasserts warm reset. [Note: The software must guarantee the warm reset assertion time meets the AC'97 specification (1.0 μ s or more).]	W1C
2		—	WAKEUP: Disable Wake-up. W1C 0: No effect 1: Disables wake-up from low-power mode.	W1C
1		—	LOWPWR: Disable AC-link Low-power Mode. W1C 0: No effect 1: Releases SYNC and SDOUT signals from low.	W1C
0		—	ENLINK: Disable AC-link. W1C 0: No effect 1: Asserts the ACRESET* signal to AC-link. [Note: The software must guarantee the ACRESET* signal assertion time meets the AC'97 specification (1.0 μ s or more).]	W1C

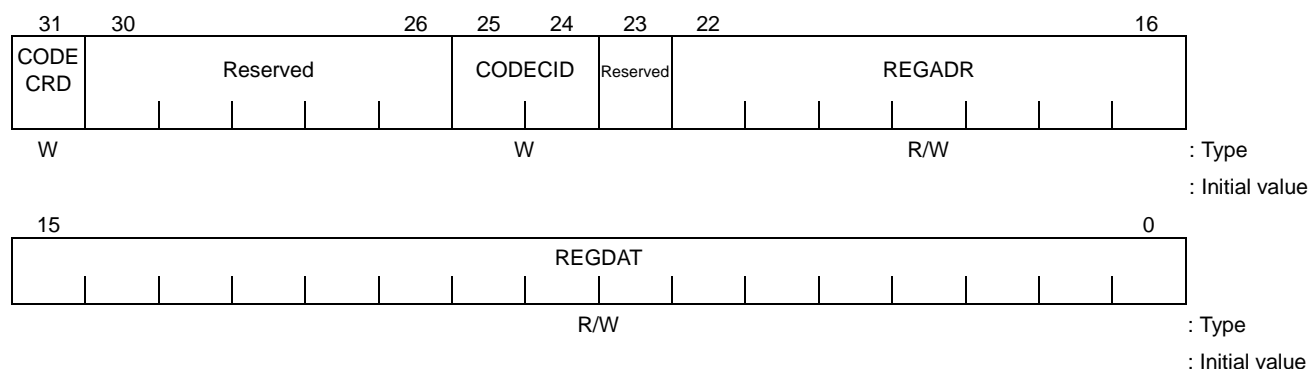
Figure 14.4.2 ACCTLDIS Register (2/2)

Clear xxxxDMA bits in ACCTLEN to “0” by using this register to disable transmit/receive-data DMA and to stop transmission/reception by the AC-link. Note that if these bits are cleared while output-slot data is flowing in the FIFO, ACLC may output a wrong data as the last sample. This behavior will not occur if the software waits for data-flow completion by detecting underrun before it disables the corresponding slot.

14.4.3 ACLC CODEC Register Access Register

0xF708

CODEC registers can be accessed through this register.



Bit	Mnemonic	Field Name	Description	Read/Write
31	CODECRD	AC'97 register read access	CODECRD: AC'97 register read access W 0: Indicates a write access. 1: Indicates a read access.	W
30:26	—	Reserved		—
25:24	CODECID	AC'97 CODEC ID	CODECID: AC'97 CODEC ID W Specifies the CODEC ID of the read/write access destination. The values "0" through "3" can be specified as the CODEC ID, but the number of CODECs actually supported depends on the configuration.	W
23	—	Reserved		—
22:16	REGADR	AC'97 register address	REGADR: AC'97 register address R Read address. Valid address can be read after read access is complete. W Specifies the read/write access destination address.	R/W
15:0	REGDAT	AC'97 register data	REGDAT: AC'97 register data R Read data. Valid data can be read after read access is complete. W Write data.	R/W

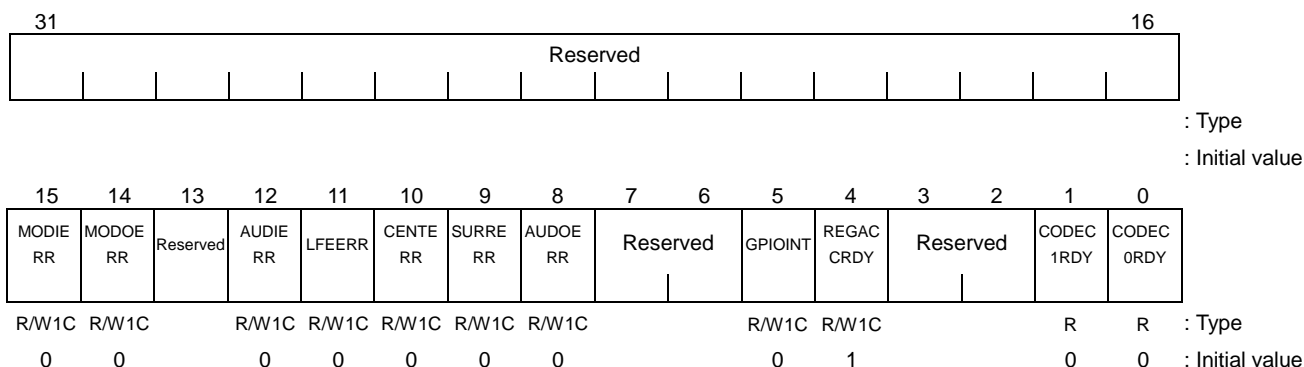
Figure 14.4.3 ACREGACC

This register must not be read from or written to until access completion is reported through the ACINTSTS register.

14.4.4 ACLC Interrupt Status Register

0xF710

This register shows various kinds of AC-link and ACLC status.



Bit	Mnemonic	Field Name	Description	Read/Write
31:16	—	Reserved		—
15	MODIERR	Modem Receive-data DMA Overrun	MODIERR: Modem Receive-data DMA Overrun R 1: Indicates that the modem receive-data DMA overrun. W1C This bit is cleared when "1" is written to it.	R/W1C
14	MODOERR	Modem Transmit-data DMA Underrun	MODOERR: Modem Transmit-data DMA Underrun R 1: Indicates that the modem transmit-data DMA underrun. W1C This bit is cleared when "1" is written to it.	R/W1C
13	—	Reserved		—
12	AUDIERR	Audio Receive-data DMA Overrun	AUDIERR: Audio Receive-data DMA Overrun R 1: Indicates that the audio receive-data DMA overrun. W1C This bit is cleared when "1" is written to it.	R/W1C
11	LFEERR	Audio LFE Transmit-data DMA Underrun	LFEERR: Audio LFE Transmit-data DMA Underrun R 1: Indicates that the audio LFE transmit-data DMA underrun. W1C This bit is cleared when "1" is written to it.	R/W1C
10	CENTERR	Audio Center Transmit-data DMA Underrun	CENTERR: Audio Center Transmit-data DMA Underrun R 1: Indicates that the audio center transmit-data DMA underrun. W1C This bit is cleared when "1" is written to it.	R/W1C
9	SURRERR	Audio Surround L&R Transmit-data DMA Underrun	SURRERR: Audio Surround L&R Transmit-data DMA Underrun R 1: Indicates that the audio surround L&R transmit-data DMA underrun. W1C This bit is cleared when "1" is written to it.	R/W1C
8	AUDOERR	Audio PCM L&R Transmit-data DMA Underrun	AUDOERR: Audio PCM L&R Transmit-data DMA Underrun R 1: Indicates that the audio PCM L&R transmit-data DMA underrun. W1C This bit is cleared when "1" is written to it.	R/W1C
7:6	—	Reserved		—
5	GPIoint	GPIO Interrupt	GPIoint: GPIO Interrupt R 1: Indicates that the incoming slot 12 bit[0] is '1' (the modem CODEC GPIO interrupt). W1C This bit is cleared if "1" is written to it while the incoming slot 12 bit[0] is '0'.	R/W1C

Figure 14.4.4 ACINTSTS Register (1/2)

Bit	Mnemonic	Field Name	Description	Read/Write
4	REGACCRDY	ACREGACC Ready	<p>REGACCRDY: ACREGACC Ready</p> <p>R 1: Indicates that the ACREGACC register is ready to get the value (in case the previous operation was a read access) and to initiate another R/W access to an AC'97 register.</p> <p>The result of reading or writing to the ACREGACC register before the completion notification is undefined.</p> <p>This bit is cleared if "1" is written to it.</p> <p>W1C This bit automatically becomes '0' when the ACREGACC register is written.</p>	R/W1C
3:2	—	Reserved		—
1	CODEC1RDY	CODEC1 Ready	<p>CODEC1RDY: CODEC1 Ready</p> <p>R 1: Indicates that the CODEC Ready bit of SDIN1 Slot0 is set.</p>	R
0	CODEC0RDY	CODEC0 Ready	<p>CODEC0RDY: CODEC0 Ready</p> <p>R 1: Indicates that the CODEC Ready bit of SDIN0 Slot0 is set.</p>	R

Figure 14.4.4 ACINTSTS Register (2/2)

14.4.5 ACLC Interrupt Masked Status Register 0xF714

Every bit in this register is configured as follows:

$$\text{ACINTMSTS} = \text{ACINTSTS} \& \text{ACINTEN}$$

Bit placement is the same as for the ACINTSTS register. The logical OR of all bits in this register is used as ACLC interrupt request to the interrupt controller.

14.4.6 ACLC Interrupt Enable Register 0xF718

Interrupt request enable (R/W1S). Bit placement is the same as for the ACINTSTS register. Its initial value is all '0'. When a value is written to this register, the bit in the position where "1" was written is set to "1."

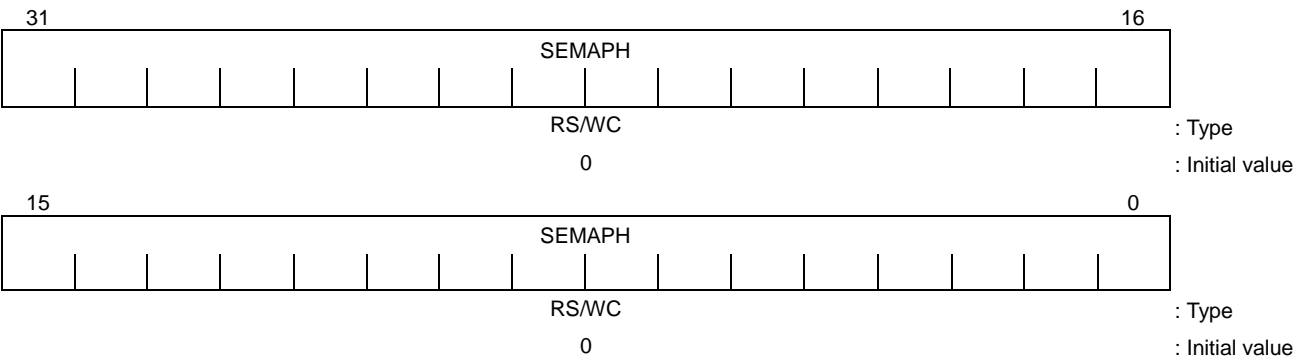
14.4.7 ACLC Interrupt Disable Register 0xF71C

Interrupt request enable clear (W1C). Bit placement is the same as for the ACINTSTS register. When a value is written to this register, the ACINTEN register bit in the position where a "1" was written is cleared to "0."

14.4.8 ACLC Semaphore Register

0xF720

This register is used for mutual exclusion control for resource.



Bit	Mnemonic	Field Name	Description	Read/Write
31:0	SEMAPH	Semaphore flag	SEMAPH: Semaphore flag. RS 0: Indicates that the semaphore is unlocked. The read operation to this register will atomically set the bit[0] to lock the semaphore. 1: Indicates that the semaphore is locked. WC x: Writing any value to this register clears the bit[0] to release the semaphore.	RS/WC

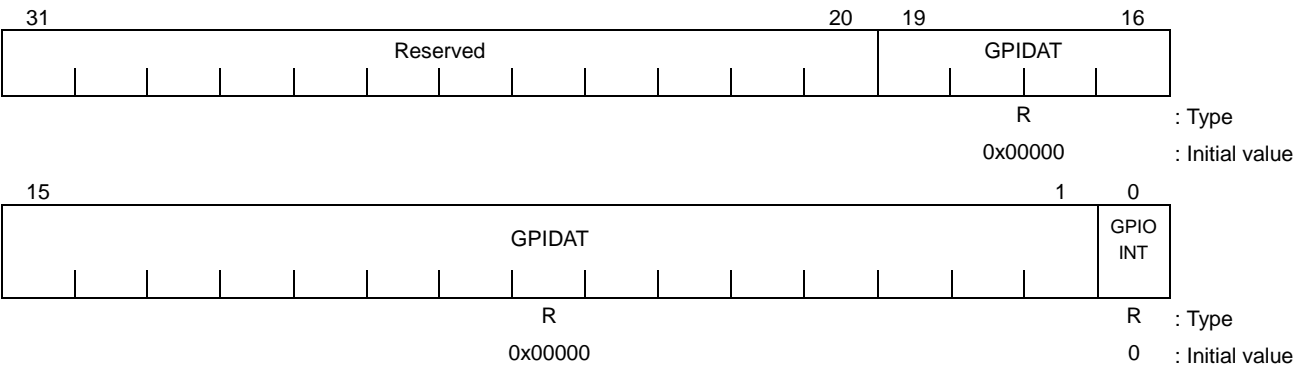
Figure 14.4.5 ACSEMAPH Register

This register is provided primarily for the mutual exclusion between the audio and modem drivers to share the common resources of ACLC, such as the ACREGACC register and the link-control bits in the ACCTLEN/DIS register.

14.4.9 ACLC GPI Data Register

0xF740

This register shows GPIO (slot 12) input data.



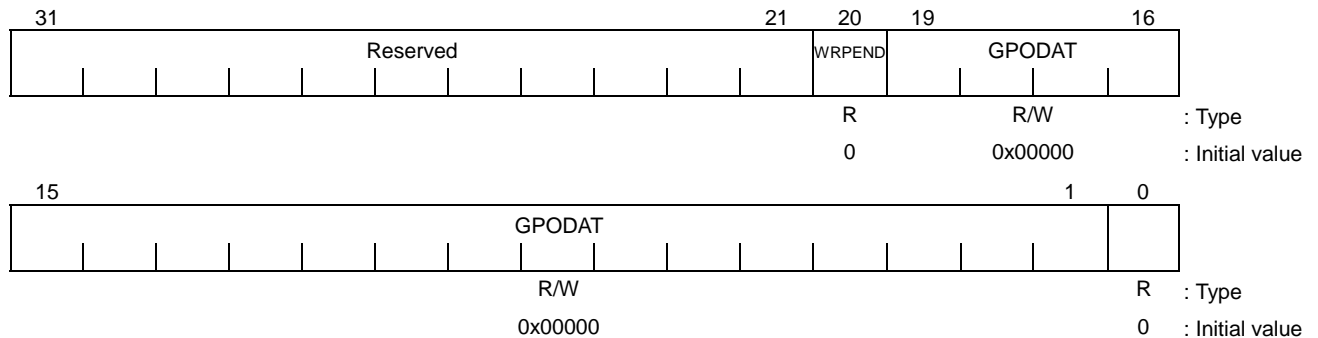
Bit	Mnemonic	Field Name	Description	Read/Write
31:20	—	Reserved		—
19:1	GPIDAT	GPIO-In data	GPIDAT: GPIO-In data R Read data. The incoming slot 12 bits[19:1] are shadowed here.	R
0	GPIOINT	GPIO Interrupt Indication	GPIOINT: GPIO Interrupt Indication R GPIO Interrupt. The incoming slot 12 bit[0] is shadowed here.	R

Figure 14.4.6 ACGPIDAT Register

14.4.10 ACLC GPO Data Register

0xF744

This register specifies GPIO (slot 12) output data.



Bit	Mnemonic	Field Name	Description	Read/Write
31:20	—	Reserved		—
20	WRPEND	Write Pending	WRPEND: Write Pending R 0: Indicates that the previous write operation is complete and the ACGPODAT register is ready to be written. 1: Indicates that the previous write operation is not complete and the ACGPODAT register is not yet ready to be written.	R
19:1	GPODAT	GPIO-Out data	GPODAT: GPIO-Out data R Reads back the value previously written to this field. W Writes data to the outgoing slot 12 bits[19:1].	R/W
0	—	—	R Reads always '0'.	R

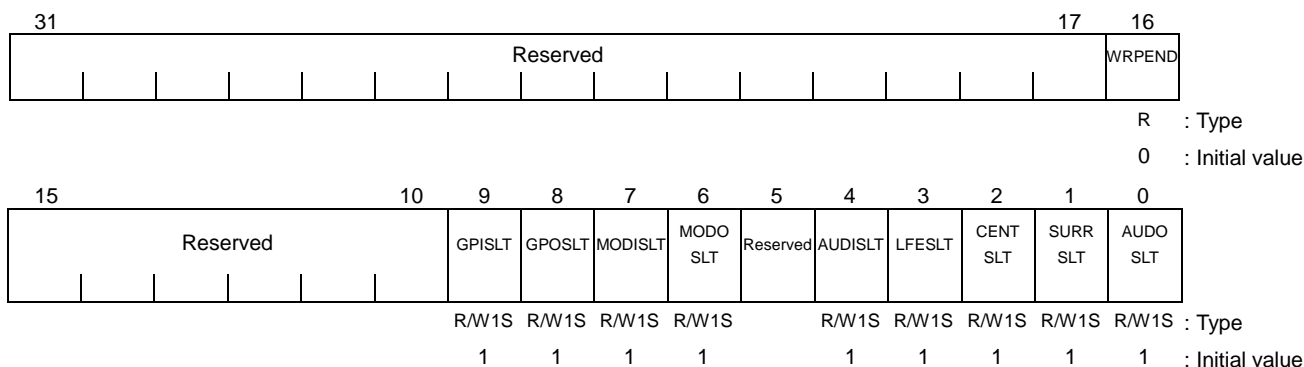
Figure 14.4.7 ACGPODAT Register

Writing a value into this register needs several BITCLK cycles to take effect. The software must guarantee that no write access be executed until the previous write access takes effect (completes), by reading the ACGPODAT.WRPEND bit prior to writing this register. If it is set for a long time, the BITCLK signal on the AC-link is probably inactive for whatever reason.

14.4.11 ACLC Slot Enable Register

0xF748

This register enables independently the AC-link slot data streams.



Bit	Mnemonic	Field Name	Description	Read/Write
31:17	—	Reserved		—
16	WRPEND	Write Pending	WRPEND: Write Pending R 0: Indicates that the previous write operation is complete and the ACSLTEN and ACSLTDIS registers are ready to be accessed. 1: Indicates that the previous write operation is not complete and the ACSLTEN and ACSLTEDIS registers are not yet ready to be accessed.	R
15:10	—	Reserved		—
9	GPISLT	Enable GPI slot reception	GPISLT: Enable GPI slot reception. R 0: Indicates that GPI slot reception is disabled. 1: Indicates that GPI slot reception is enabled. W1S 0: No effect 1: Enables GPI slot reception.	R/W1S
8	GPOSLT	Enable GPO Slot transmission	GPOSLT: Enable GPO Slot transmission. R 0: Indicates that GPO slot transmission is disabled. 1: Indicates that GPO slot transmission is enabled. W1S 0: No effect 1: Enables GPO slot transmission.	R/W1S
7	MODISLT	Enable Modem slot reception	MODISLT: Enable Modem slot reception. R 0: Indicates that modem slot reception is disabled. 1: Indicates that modem slot reception is enabled. W1S 0: No effect 1: Enables modem slot reception.	R/W1S
6	MODOSLT	Enable Modem slot transmission	MODOSLT: Enable Modem slot transmission. R 0: Indicates that modem slot transmission is disabled. 1: Indicates that modem slot transmission is enabled. W1S 0: No effect 1: Enables modem slot transmission.	R/W1S
5	—	Reserved		—

Figure 14.4.8 ACSLTEN Register (1/2)

Bit	Mnemonic	Field Name	Description	Read/Write
4	AUDISLT	Enable Audio slot reception	AUDISLT: Enable Audio slot reception. R 0: Indicates that audio slot reception is disabled. 1: Indicates that audio slot reception is enabled. W1S 0: No effect 1: Enables audio slot reception.	R/W1S
3	LFESLT	Enable Audio LFE slot transmission	LFESLT: Enable Audio LFE slot transmission. R 0: Indicates that audio LFE slot transmission is disabled. 1: Indicates that audio LFE slot transmission is enabled. W1S 0: No effect 1: Enables audio LFE slot transmission.	R/W1S
2	CENTSLT	Enable Audio Center slot transmission	CENTSLT: Enable Audio Center slot transmission. R 0: Indicates that audio Center slot transmission is disabled. 1: Indicates that audio Center slot transmission is enabled. W1S 0: No effect 1: Enables audio Center slot transmission.	R/W1S
1	SURRSLT	Enable Audio Surround L&R slot transmission	SURRSLT: Enable Audio Surround L&R slot transmission. R 0: Indicates that audio Surround L&R slot transmission is disabled. 1: Indicates that audio Surround L&R slot transmission is enabled. W1S 0: No effect 1: Enables audio Surround L&R slot transmission.	R/W1S
0	AUDOSLT	Enable Audio PCM L&R slot transmission	AUDOSLT: Enable Audio PCM L&R slot transmission. R 0: Indicates that audio PCM L&R Slot transmission is disabled. 1: Indicates that audio PCM L&R Slot transmission is enabled. W1S 0: No effect 1: Enables audio PCM L&R slot transmission.	R/W1S

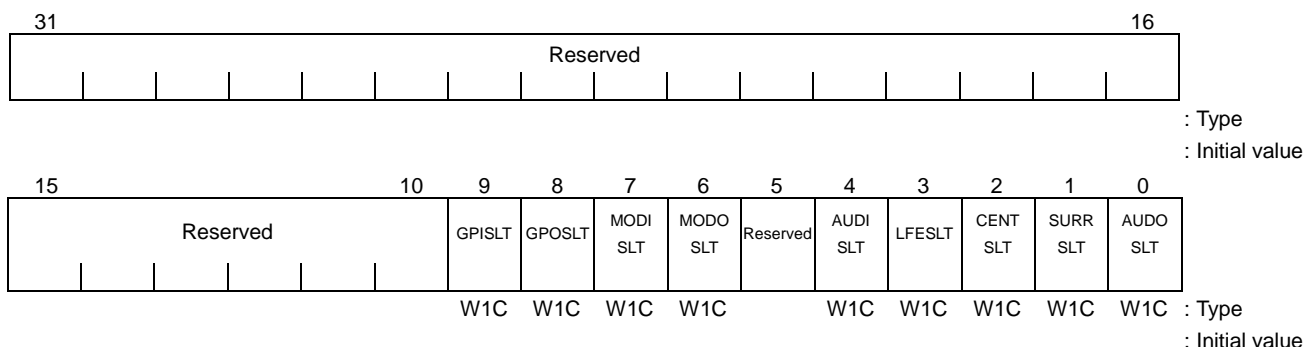
Figure 14.4.8 ACSLTEN Register (2/2)

Writing a value into this register needs several BITCLK cycles to take effect. The software must guarantee that no write access be executed until the previous write access takes effect (completes), by reading the ACSLTEN.WRPEND bit prior to writing this register. If it is set for a long time, the BITCLK signal on the AC-link is probably inactive for whatever reason.

14.4.12 ACLC Slot Disable Register

0xF74C

This register disables independently the AC-link slot data streams.



Bit	Mnemonic	Field Name	Description	Read/Write
31:10	—	Reserved		—
9	GPISLT	Disable GPI slot reception	GPISLT: Disable GPI slot reception. W1C 0: No effect 1: Disables GPI slot reception.	W1C
8	GPOSLT	Disable GPO Slot transmission	GPOSLT: Disable GPO Slot transmission. W1C 0: No effect 1: Disables GPO slot transmission.	W1C
7	MODISLT	Disable Modem slot reception	MODISLT: Disable Modem slot reception. W1C 0: No effect 1: Disables modem slot reception.	W1C
6	MODOSLT	Disable Modem slot transmission	MODOSLT: Disable Modem slot transmission. W1C 0: No effect 1: Disables modem slot transmission.	W1C
5	—	Reserved		—
4	AUDISLT	Disable Audio slot reception	AUDISLT: Disable Audio slot reception. W1C 0: No effect 1: Disables audio slot reception.	W1C
3	LFESLT	Disable Audio LFE slot transmission	LFESLT: Disable Audio LFE slot transmission. W1C 0: No effect 1: Disables audio LFE slot transmission.	W1C
2	CENTSLT	Disable Audio Center slot transmission	CENTSLT: Disable Audio Center slot transmission. W1C 0: No effect 1: Disables audio Center slot transmission.	W1C
1	SURRSLT	Disable Audio Surround L&R slot transmission	SURRSLT: Disable Audio Surround L&R slot transmission. W1C 0: No effect 1: Disables audio Surround L&R slot transmission.	W1C
0	AUDOSLT	Disable Audio PCM L&R slot transmission	AUDOSLT: Disable Audio PCM L&R slot transmission. W1C 0: No effect 1: Disables audio PCM L&R slot transmission.	W1C

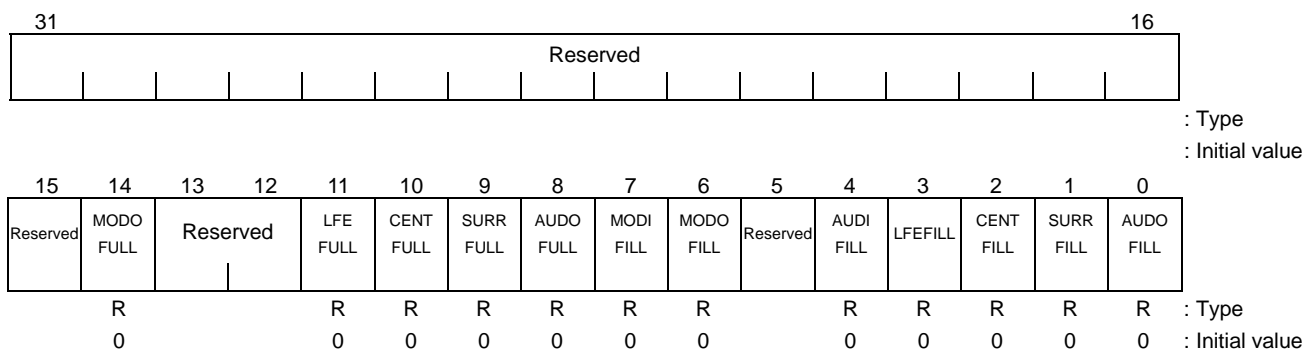
Figure 14.4.9 ACSLTDIS Register

Writing a value into this register needs several BITCLK cycles to take effect. The software must guarantee that no write access be executed until the previous write access takes effect (completes), by reading the ACSLTEN.WRPEND bit prior to writing this register. If it is set for a long time, the BITCLK signal on the AC-link is probably inactive for whatever reason.

14.4.13 ACLC FIFO Status Register

0xF750

This register indicates the AC-link slot data FIFO status.



Bit	Mnemonic	Field Name	Description	Read/Write
31:15	—	Reserved		—
14	MODOFULL	Modem Transmit-data Full	MODOFULL: Modem Transmit-data Full. R 0: Indicates modem transmit-data FIFO is not full. 1: Indicates modem transmit-data FIFO is full.	R
13:12	Reserved	Reserved		—
11	LFEFULL	Audio LFE Transmit-data Full	LFEFULL: Audio LFE Transmit-data Full. R 0: Indicates audio LFE transmit-data FIFO is not full. 1: Indicates audio LFE transmit-data FIFO is full.	R
10	CENTFULL	Audio Center Transmit-data Full	CENTFULL: Audio Center Transmit-data Full. R 0: Indicates audio Center transmit-data FIFO is not full 1: Indicates audio Center transmit-data FIFO is full.	R
9	SURRFULL	Audio Surround L&R Transmit-data Full	SURRFULL: Audio Surround L&R Transmit-data Full. R 0: Indicates audio Surround L&R transmit-data FIFO is not full. 1: Indicates audio Surround L&R transmit-data FIFO is full.	R
8	AUDOFULL	Audio PCM L&R Transmit-data Full	AUDOFULL: Audio PCM L&R Transmit-data Full. R 0: Indicates audio PCM L&R transmit-data FIFO is not full. 1: Indicates audio PCM L&R transmit-data FIFO is full.	R
7	MODIFILL	Modem Receive-data Filled	MODIFILL: Modem Receive-data Filled. R 0: Indicates modem receive-data FIFO is empty. 1: Indicates modem receive-data FIFO is not empty.	R
6	MODOFILL	Modem Transmit-data Filled	MODOFILL: Modem Transmit-data Filled. R 0: Indicates modem transmit-data FIFO is empty. 1: Indicates modem transmit-data FIFO is not empty.	R
5	—	Reserved		—
4	AUDIFILL	Audio Receive-data Filled	AUDIFILL: Audio Receive-data Filled. R 0: Indicates audio receive-data FIFO is empty. 1: Indicates audio receive-data FIFO is not empty.	R
3	LFEFILL	Audio LFE Transmit-data Filled	LFEFILL: Audio LFE Transmit-data Filled. R 0: Indicates audio LFE transmit-data FIFO is empty. 1: Indicates audio LFE transmit-data FIFO is not empty.	R

Figure 14.4.10 ACFIFOSTS Register (1/2)

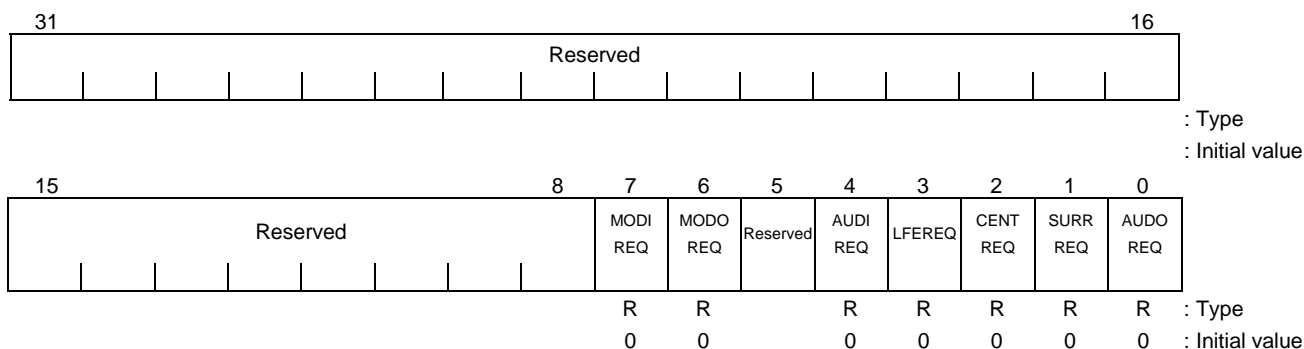
Bit	Mnemonic	Field Name	Description	Read/Write
2	CENTFILL	Audio Center Transmit-data Filled	CENTFILL: Audio Center Transmit-data Filled. R 0: Indicates audio Center transmit-data FIFO is empty. 1: Indicates audio Center transmit-data FIFO is not empty.	R
1	SURRFILL	Audio Surround L&R Transmit-data Filled	SURRFILL: Audio Surround L&R Transmit-data Filled. R 0: Indicates audio Surround L&R transmit-data FIFO is empty. 1: Indicates audio Surround L&R transmit-data FIFO is not empty.	R
0	AUDOFILL	Audio PCM L&R Transmit-data Filled	AUDOFILL: Audio PCM L&R Transmit-data Filled. R 0: Indicates audio PCM L&R transmit-data FIFO is empty. 1: Indicates audio PCM L&R transmit-data FIFO is not empty	R

Figure 14.4.10 ACFIFOSTS Register (2/2)

14.4.14 ACLC DMA Request Status Register

0xF780

This register indicates the AC-link slot data DMA request status.



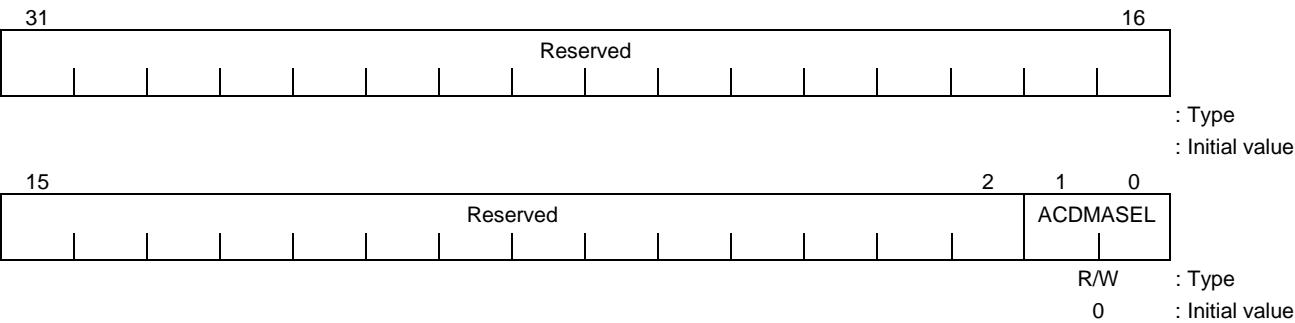
Bit	Mnemonic	Field Name	Description	Read/Write
31:8	—	Reserved		—
7	MODIREQ	Modem Data Reception Request	MODIREQ: Modem Data Reception Request R 0: No request is pending. 1: Request is pending.	R
6	MODOREQ	Modem Data Transmission Request	MODOREQ: Modem Data Transmission Request R 0: No request is pending. 1: Request is pending.	R
5	—	Reserved		—
4	AUDIREQ	Audio Data Reception Request	AUDIREQ: Audio Data Reception Request R 0: No request is pending. 1: Request is pending.	R
3	LFEREQ	Audio LFE Data Transmission Request	LFEREQ: Audio LFE Data Transmission Request R 0: No request is pending. 1: Request is pending.	R
2	CENTREQ	Audio Center Data Transmission Request	CENTREQ: Audio Center Data Transmission Request R 0: No request is pending. 1: Request is pending.	R
1	SURRREQ	Audio Surround L&R Data Transmission Request	SURRREQ: Audio Surround L&R Data Transmission Request R 0: No request is pending. 1: Request is pending.	R
0	AUDOREQ	Audio PCM L&R Data Transmission Request	AUDOREQ: Audio PCM L&R Data Transmission Request R 0: No request is pending. 1: Request is pending.	R

Figure 14.4.11 ACDMASTS Register

This read-only register shows if any DMA request is pending for each data I/O channel. A DMA request can be pending after the software deactivates the DMAC channel or disables DMA by ACCTLDIS register bit to complete DMA operation. In this case, write or read the sample data register (ACAUDODAT and others) to clear the DMA request.

14.4.15 ACLC DMA Channel Selection Register 0xF784

This register is used to select and check the channel allocation for AC-link slot data DMA.



Bit	Mnemonic	Field Name	Description	Read/Write
31:2	—	Reserved		—
1:0	ACDMASEL	DMA Channel Selection	ACDMASEL: DMA Channel Selection W ACDMASEL: DMA Channel Selection 0: PCM L&R out, Audio in, and Modem out&in. 1: PCM L&R out, Surround L&R out, and Modem out&in. 2: PCM L&R out, Surround L&R out, Center out, and LFE out. 3: PCM L&R out, Surround L&R out, Center out, and Audio in.	R/W

Figure 14.4.12 ACDMASEL Register

This register selects DMA channel mapping mode. The software is recommended to make sure no DMA request is pending before changing this register value.

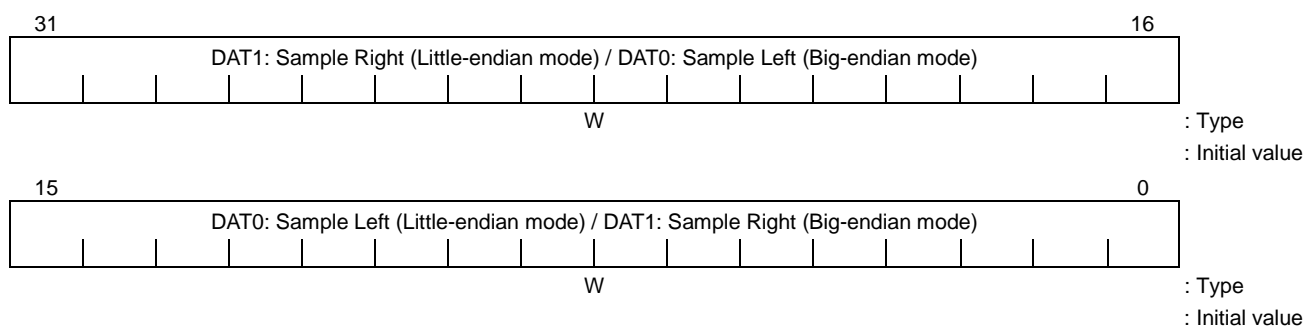
14.4.16 ACLC Audio PCM Output Data Register

0xF7A0

ACLC Surround Data Register

0xF7A4

These registers are used to write audio PCM and surround L&R output data.

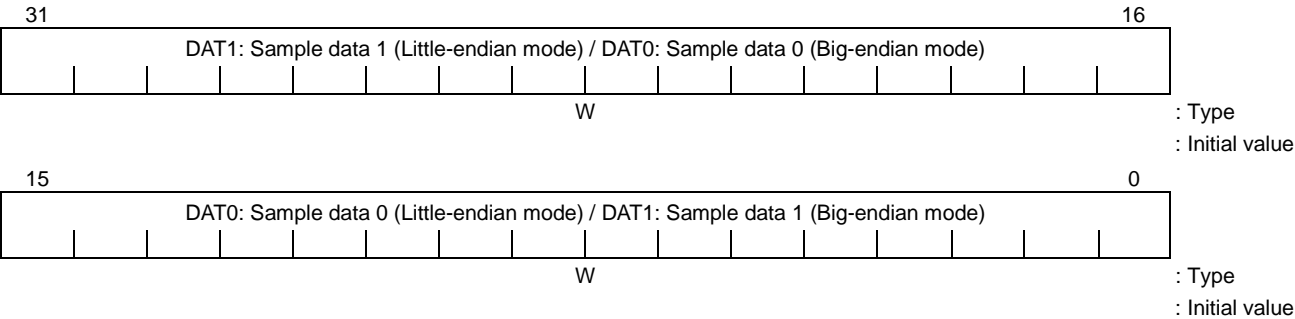


Bit	Mnemonic	Field Name	Description			Read/Write
31:16	—	—	W	DAT1: Sample Right	DAT0: Sample Left	W
15:0	—	—	W	DAT0: Sample Left	Left DAT1: Sample Right	W

Figure 14.4.13 ACAUDODAT/ACSURRDAT Register

14.4.17 ACLC Center Data Register	0xF7A8
ACLC LFE Data Register	0xF7AC
ACLC Modem Output Data Register	0xF7B8

This registers are used to write audio center, LFE, and modem output data.

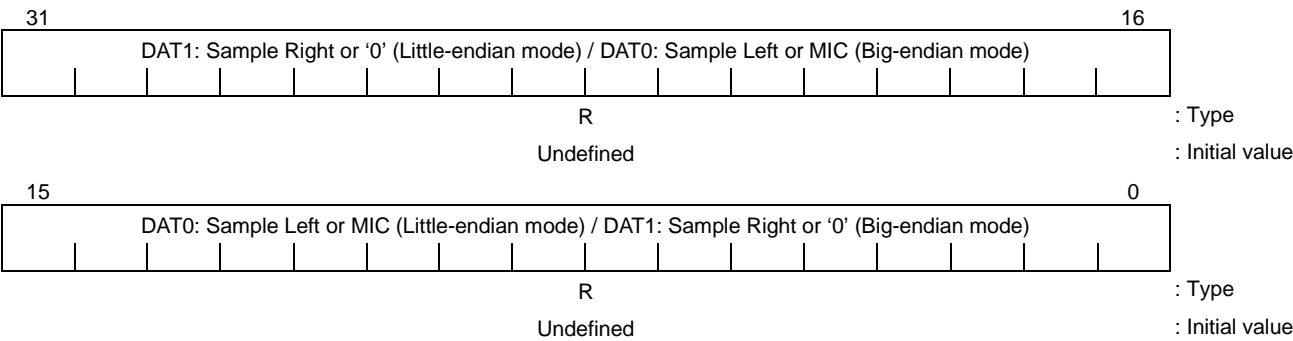


Bit	Mnemonic	Field Name	Description		Read/Write
31:16	—	—	W	DAT1: Sample data 1 DAT0: Sample data 0	W
15:0	—	—	W	DAT0: Sample data 0 DAT1: Sample data 1	W

Figure 14.4.14 ACCENDAT/ACLFEDAT/ACMODODAT Register

14.4.18 ACLC Audio PCM Input Data Register 0xF7B0

This register is used to read audio PCM input data.



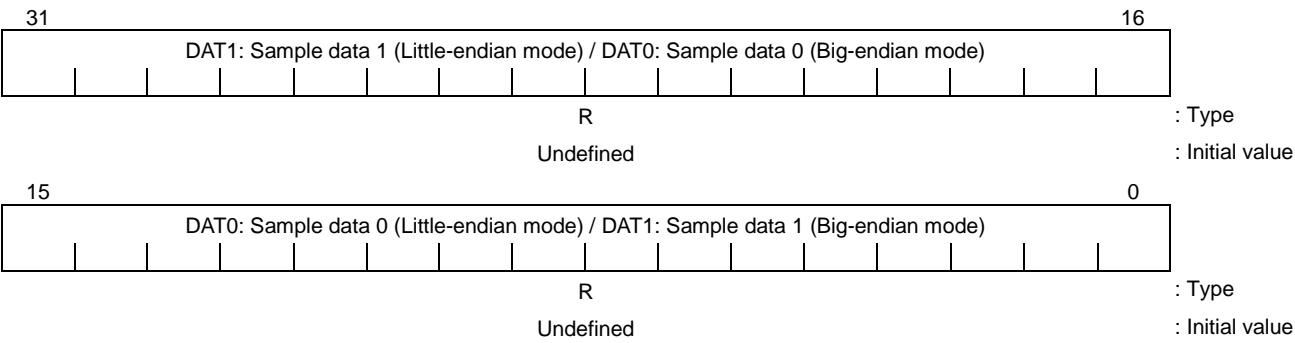
Bit	Mnemonic	Field Name	Description			Read/Write
31:16	—	—	R	DAT1: Sample Right or '0'	DAT0: Sample Left or MIC	R
15:0	—	—	R	DAT0: Sample Left or MIC	DAT1: Sample Right or '0'	R

Figure 14.4.15 ACAUDIDAT Register

14.4.19 ACLC Modem Input Data Register

0xF7BC

This register is used to read modem input data.



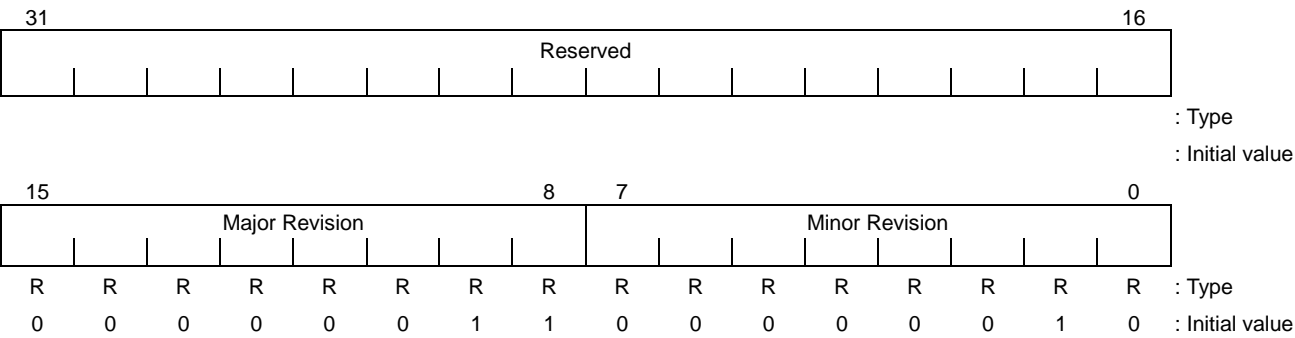
Bit	Mnemonic	Field Name	Description		Read/Write
31:16	—	—	R	DAT1: Sample data 1 DAT0: Sample data 0	R
15:0	—	—	R	DAT0: Sample data 0 DAT1: Sample data 1	R

Figure 14.4.16 ACMODIDAT Register

14.4.20 ACLC Revision ID Register

0xF7FC

This register is used to read ACLC module 's revision ID.



Bit	Mnemonic	Field Name	Description	Read/Write
31:16	—	Reserved		—
15:8	—	—	R Major Revision Contact Toshiba technical staff for an explanation of the revision value.	R
7:0	—	—	R Minor Revision Contact Toshiba technical staff for an explanation of the revision value.	R

Figure 14.4.17 ACREVID Register

This read-only register shows the revision of ACLC module. Note that this number is not related to the AC'97 specification revision.

15. Interrupt Controller

15.1 Characteristics

The TX4927 on-chip Interrupt Controller (IRC) receives interrupt requests from the TX4927 on-chip peripheral circuitry as well as external interrupt requests then generates interrupt requests to the TX49/H2 processor core.

Also, the Interrupt Controller has a 16-bit flag register that generates interrupt requests to either external devices or to the TX49/H2 core.

The Interrupt Controller has the following characteristics.

- Supports interrupts from 18 types of on-chip peripheral circuits and a maximum of 6 external interrupt signal inputs
- Sets 8 priority interrupt levels for each interrupt input
- Can select either edge detection or level detection for each external interrupt when in the interrupt detection mode
- As a flag register used for interrupt requests, the Interrupt Controller contains a 16-bit readable/writeable register and can issue interrupt requests to external devices as well as to the TX49/H2 core (IRC interrupt).

15.2 Block Diagram

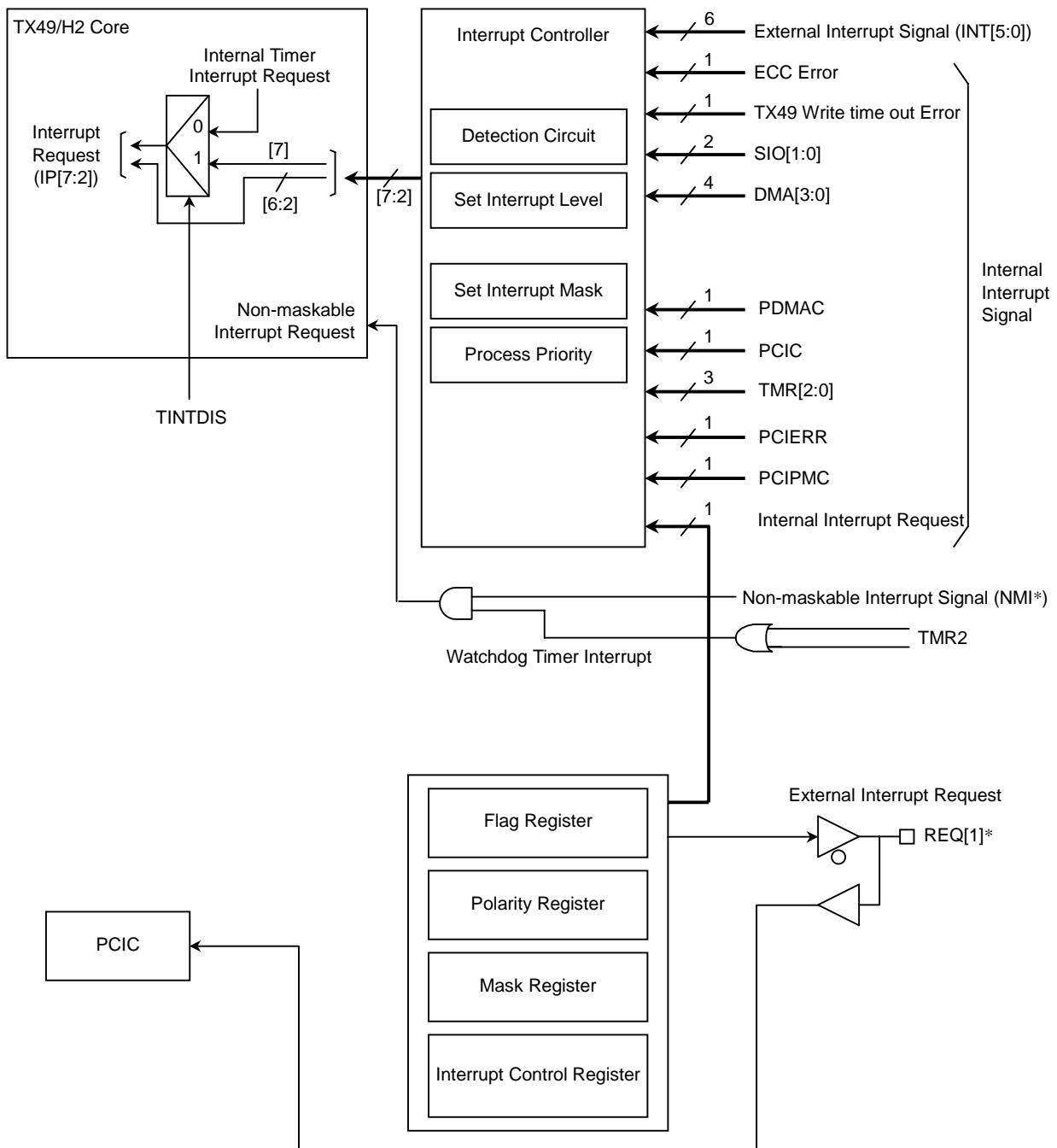


Figure 15.2.1 Interrupt Controller Outline

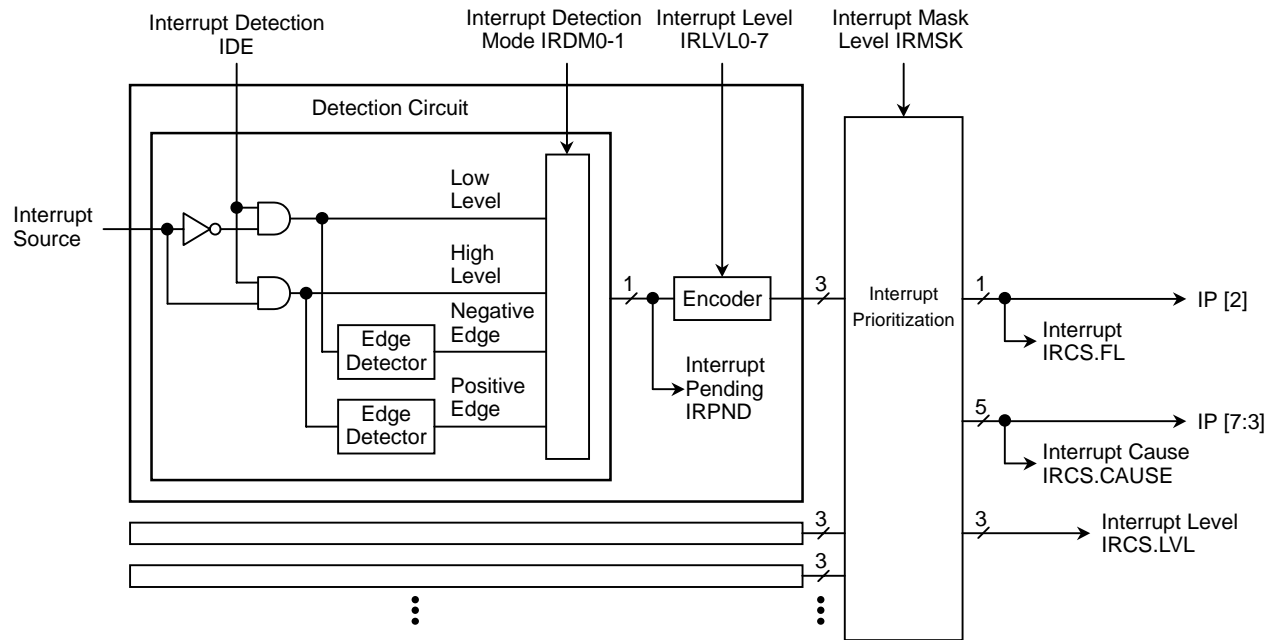


Figure 15.2.2 Internal Block Diagram of Interrupt Controller

15.3 Detailed Explanation

15.3.1 Interrupt sources

The TX4927 has as interrupt sources interrupts from 18 types of on-chip peripheral circuits and 6 external interrupt signals.

Table 15.3.1 lists the interrupt sources. Signals with the lower interrupt number have the higher priority. The priorities are explained below in item. 15.3.4

Table 15.3.1 Interrupt Sources and Priorities

Priority	Interrupt Number	Interrupt Source
High	0	SDRAM ECC Error (Internal)
	1	TX49 Write Timeout Error (Internal)
	2	INT[0] (External)
	3	INT[1] (External)
	4	INT[2] (External)
	5	INT[3] (External)
	6	INT[4] (External)
	7	INT[5] (External)
	8	SIO0 (Internal)
	9	SIO1 (Internal)
	10	DMA0 (Internal)
	11	DMA1 (Internal)
	12	DMA2 (Internal)
	13	DMA3 (Internal)
	14	IRC (Internal)
	15	PDMAC (Internal)
	16	PCIC (Internal)
	17	TMR0 (Internal)
	18	TMR1 (Internal)
	19	TMR2 (Internal)
	20-21	(Reserved)
	22	PCIERR (Internal)
	23	PCIPMC (Internal)
Low	24-31	(Reserved)

In addition to the above, the TX49/H2 core has a TX49/H2 core internal timer interrupt and two software interrupts, but these interrupts are directly reported to the TX49/H2 core independently of this Interrupt Controller. Please refer to the 64-bit TX System RISC TX49/H2 Core Architecture Manual for more information.

15.3.2 Interrupt request detection

In order to perform interrupt detection, each register of the Interrupt Controller is initialized, then the IDE bit of the Interrupt Detection Enable Register (IRDEN) is set to “1.” All interrupts detected by the Interrupt Controller are masked when this bit is cleared.

It is possible to set each interrupt factor detection mode using Interrupt Detection Mode Register 0 (IRDM0) and Interrupt Detection Mode Register 1 (IRDM1). There are four detection modes: Low level, High level, falling edge, and rising edge.

The detected interrupt factors can be read out from the Interrupt Pending Register (IRPND).

15.3.3 Interrupt level assigning

Interrupt levels from 0 to 7 are assigned to each detected interrupt using the Interrupt Level Register (IRLVL0-7). Interrupt level 7 is the highest priority and interrupt level 0 is the lowest priority. Level 0 interrupts will be masked. (Table 15.3.2).

The priorities set by these interrupt levels will be given higher priority than the priorities provided for each interrupt source indicated in Table 15.3.1.

Table 15.3.2 Interrupt Levels

Priority	Interrupt Level (IRLVLn.ILm)
High	111
	110
	101
	100
	011
	010
Low	001
Mask	000

15.3.4 Interrupt priority assigning

When multiple interrupt requests exist, the Interrupt Controller selects the interrupt with the highest priority according to the priority level and interrupt number. Interrupt factors with an interrupt level lower than the interrupt level specified by the Interrupt Mask Level Register (IRMSK) will be excluded (masked).

When the interrupt with the highest priority is selected, then the interrupt number of that interrupt is set in the interrupt factor field (CAUSE) of the Interrupt Current Status Register (IRCS), the interrupt level is set in the Interrupt Level field (LVL), and the Interrupt Flag bit (IF) is set.

Priorities are assigned as follows.

- When interrupt levels differ, the interrupt with the higher interrupt level has priority (Table 15.3.2)
- When multiple interrupts with the same interrupt level are simultaneously detected, the interrupt with the smaller interrupt number has priority (Table 15.3.1).

In addition, the interrupt priority assignments are reevaluated under the following conditions. At this time, the interrupt with the highest priority is selected and the Interrupt Factor field (CAUSE) and Interrupt Level field (LVL) of the Interrupt Current Status Register (IRCS) are set again.

- When an interrupt request with a higher interrupt level than that of the currently selected interrupt is detected. However, when the interrupt levels are equal, the Interrupt Level field (LVL) does not change even if the interrupt number is small.
- When the interrupt level (IRLVLn.ILm) of the currently selected interrupt changes to a value smaller than the current setting.
- When the currently selected interrupt is cleared (refer to 15.3.6 Clearing interrupt requests).

15.3.5 Interrupt notification

When the interrupt with the highest priority is selected, then the interrupt factor is reported to the Interrupt Current Status Register (IRCS) and an interrupt is reported to the TX49/H2 core.

The TX49/H2 core distinguishes interrupt factors using the IP field (IP[7:2]) of the Cause Register. The interrupt notification from the Interrupt Controller is reflected in the IP[2] bit. The Interrupt Handler uses the IP[2] bit to judge whether or not there are interrupts from this Interrupt Controller and uses the Interrupt Current Status Register (IRCS) to determine the interrupt cause.

The Interrupt Factor field (IRCS.CAUSE) value is reflected in the remaining bits of the IP field. Since bit IP[7] is also being used for notification of TX49/H2 CPU core internal timer interrupts, the contents specified by IP[7] differ according to whether internal timer interrupts are set to valid (TINTDIS=0) or invalid (TINTDIS=1), as indicated Table 15.3.3.

TINTDIS is the value that is set from DATA[7] at the timing when the RESET* signal is deasserted. See the explanation “3.3 Configuration Signals” for more information.

Table 15.3.3 Interrupt Notification to IP[7:2] of the CP0 Cause Register

TINTDIS	IP[7]	IP[6:3]	IP[2]
0 (Internal Timer Interrupts: Valid)	Internal Timer Interrupt Notification	IRCS.CAUSE[3:0]	IRCS.IF
1 (Internal Timer Interrupts: Invalid)	IRCS.CAUSE[4:0]		IRCS.IF

15.3.6 Clearing interrupt requests

Interrupt requests are cleared according to the following process.

- When the detection mode is set to the High level or Low level:
Operation is performed to deassert the request of a source that is asserting an interrupt request.
- When the detection mode is set to Rising edge or Falling edge
Edge detection requests are cleared by first specifying the interrupt source of the interrupt request to be cleared in the Edge Detection Clear Source field (EDCS0 or EDCS1) of the Interrupt Edge Detection Clear Register (IREDC) then writing the resulting value when the corresponding Edge Detection Clear Enable bit (EDCE0 or EDCE1) is set to “1.”

15.3.7 Interrupt requests

It is possible to make interrupt requests to external devices and interrupt requests (IRC interrupts) to the TX49/H2 core by using a 16-bit interrupt request flag register. REQ[1]* signals are used as interrupt output signals. Consequently, external interrupt requests can only be used when in the PCI External Arbiter mode. Also, internal interrupt requests are assigned to interrupt number 13 of the Interrupt Controller (IRC).

The following six registers set the interrupts.

- Interrupt Request Flag Register (IRFLAG0, IRFLAG1)
- Interrupt Request Polarity Control Register (IRPOL)
- Interrupt Request Mask Register (IRMASKINT, IRMASKEXT)
- Interrupt Request Control Register (IRRCNT)

The following formulas derive the interrupt generation conditions:

Internal interrupt request =

$$(((IRFLAG[15:0] \wedge IRPOL[15:0]) \& IRMASKINT[15:0])) \wedge IRRCNT.INTPOL$$

External interrupt request =

$$(((IRFLAG[15:0] \wedge IRPOL[15:0]) \& IRMASKEXT[15:0])) \wedge IRRCNT.EXTPOL$$

In the above formulas, “ \wedge ” indicates Exclusive OR operations and “ $\&$ ” indicates reduction operators that perform an OR operation on all bits.

Also, the External Interrupt OD Control bit (IRRCNT.OD) of the Interrupt Request Control Register can select whether the external interrupt supply signal is open drain output or totem pole output.

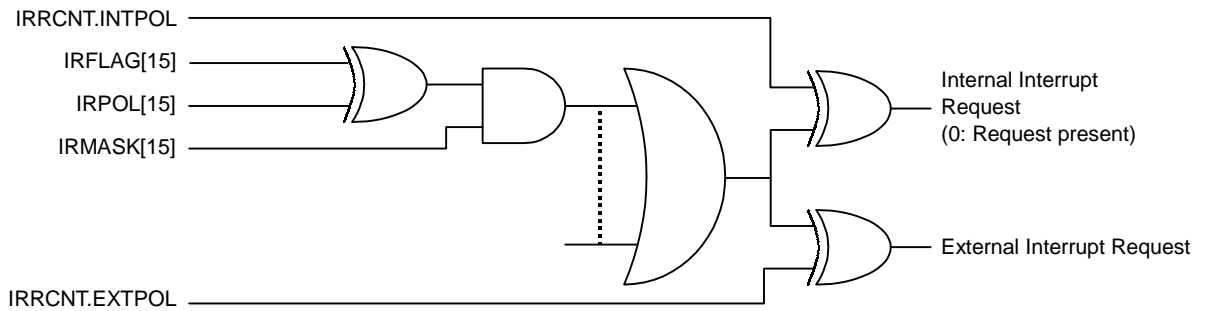


Figure 15.3.1 External Interrupt Request Logic

There are two flag registers: Flag Register 0 (IRFLAG0), and Flag Register 1 (IRFLAG1). These registers have two different Write methods. Accordingly, Writes to one register are reflects in the other.

Either “0” or “1” can be written to Flag Register 0

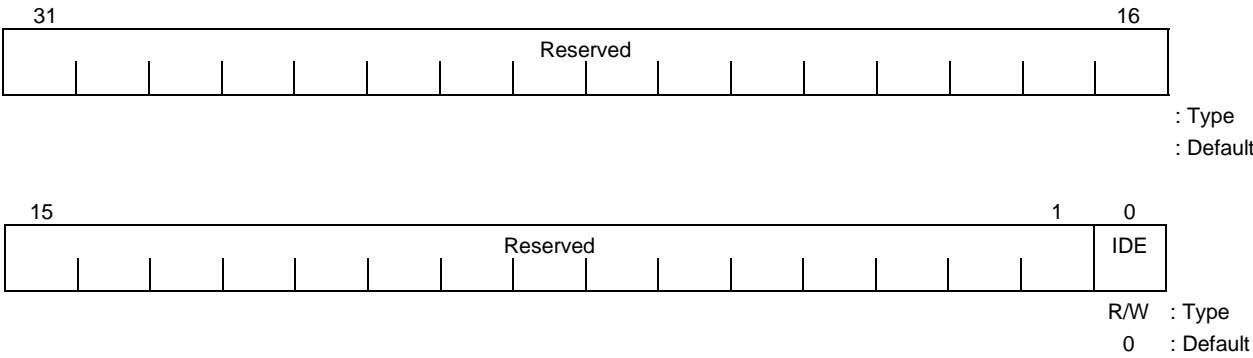
In the case of Flag Register 1 however, “1” can be written from the TX49/H2 core, but “0” cannot be written. On the other hand, bits that wrote “1” are cleared to “0” in the case of access from a device other than the TX49/H2 core (access from an external PCI device for example). The bit value at this time will not change even if “0” is written. This register sends interrupt notification from the TX49/H2 core to external devices. External devices can be used in applications that clear these interrupt notifications.

15.4 Registers

Table 15.4.1 Interrupt Control Registers

Address	Register	Register Name
0xF600	IRDEN	Interrupt Detection Enable Register
0xF604	IRDM0	Interrupt Detection Mode Register 0
0xF608	IRDM1	Interrupt Detection Mode Register 1
0xF610	IRLVL0	Interrupt Level Register 0
0xF614	IRLVL1	Interrupt Level Register 1
0xF618	IRLVL2	Interrupt Level Register 2
0xF61C	IRLVL3	Interrupt Level Register 3
0xF620	IRLVL4	Interrupt Level Register 4
0xF624	IRLVL5	Interrupt Level Register 5
0xF628	IRLVL6	Interrupt Level Register 6
0xF62C	IRLVL7	Interrupt Level Register 7
0xF640	IRMSK	Interrupt Mask Register
0xF660	IREDC	Interrupt Edge Detection Clear Register
0xF680	IRPND	Interrupt Pending Register
0xF6A0	IRCS	Interrupt Current Status Register
0xF510	IRFLAG0	Interrupt Request Flag Register 0
0xF514	IRFLAG1	Interrupt Request Flag Register 1
0xF518	IRPOL	Interrupt Request Polarity Control Register
0xF51C	IRRCNT	Interrupt Request Control Register
0xF520	IRMASKINT	Interrupt Request Internal Interrupt Mask Register
0xF524	IRMASKEXT	Interrupt Request External Interrupt Mask Register

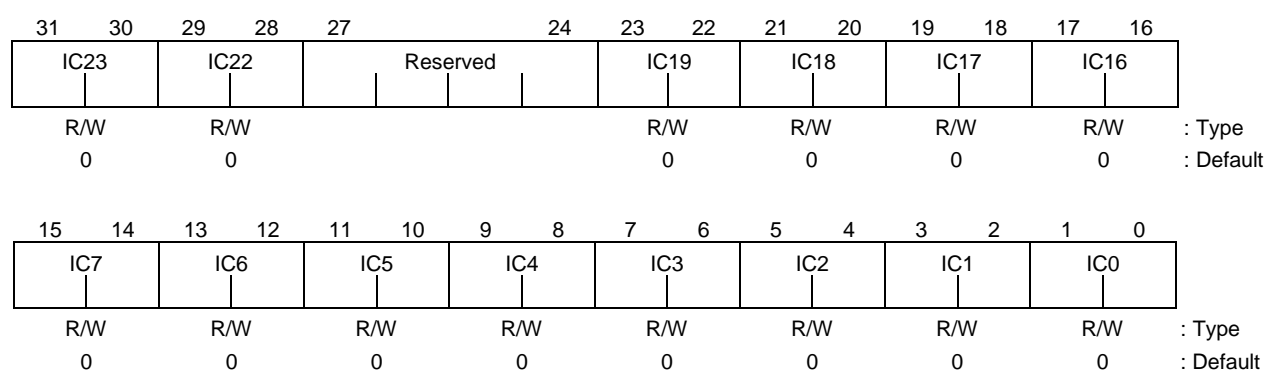
15.4.1 Interrupt Detection Enable Register (IRDEN) 0xF600



Bit(s)	Mnemonic	Field Name	Explanation	Read/Write
31:1	—	—	Reserved	—
0	IDE	Interrupt Control Enable	Interrupt Detection Enable (Default: 0) Enables interrupt detection. 0: Stop interrupt detection. 1: Start interrupt detection	R/W

Figure 15.4.1 Interrupt Detection Enable Register

15.4.2 Interrupt Detection Mode Register 0 (IRDM0) 0xF604



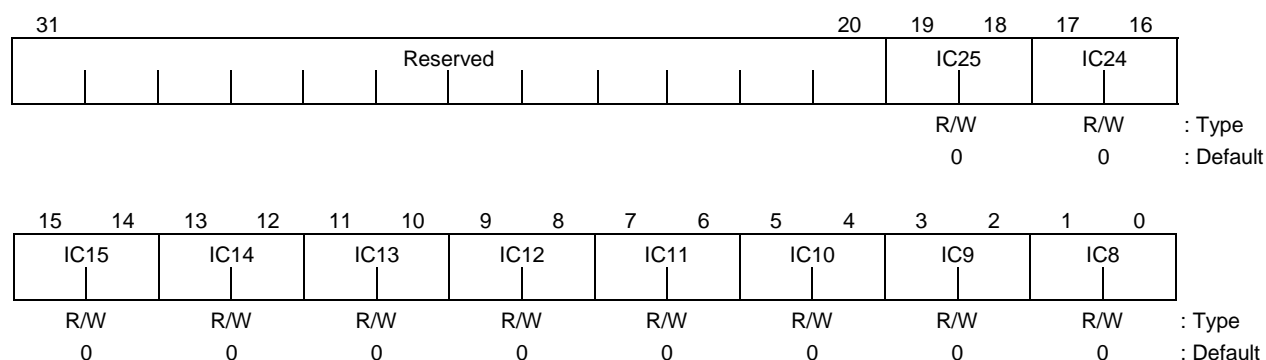
Bits	Mnemonic	Field Name	Explanation	Read/Write
31:30	IC23	Interrupt Source Control 23	Interrupt Source Control 23 (Default: 00) These bits specify the active state of PCIPMC interrupts. 00: Low level active 01: Disable 10: Disable 11: Disable	R/W
29:28	IC22	Interrupt Source Control 22	Interrupt Source Control 22 (Default: 00) These bits specify the active state of PCIERR interrupts. 00: Low level active 01: Disable 10: Disable 11: Disable	R/W
27:24	—	—	Reserved	—
23:22	IC19	Interrupt Source Control 19	Interrupt Source Control 19 (Default: 00) These bits specify the active state of TMR[2] interrupts. 00: Low level active 01: Disable 10: Disable 11: Disable	R/W
21:20	IC18	Interrupt Source Control 18	Interrupt Source Control 18 (Default: 00) These bits specify the active state of TMR[1] interrupts. 00: Low level active 01: Disable 10: Disable 11: Disable	R/W
19:18	IC17	Interrupt Source Control 17	Interrupt Source Control 17 (Default: 00) These bits specify the active state of TMR[0] interrupts. 00: Low level active 01: Disable 10: Disable 11: Disable	R/W
17:16	IC16	Interrupt Source Control 16	Interrupt Source Control 16 (Default: 00) These bits specify the active state of PCIC interrupts. 00: Low level active 01: Disable 10: Disable 11: Disable	R/W

Figure 15.4.2 Interrupt Detection Mode Register 0 (1/2)

Bits	Mnemonic	Field Name	Explanation	Read/Write
15:14	IC7	Interrupt Source Control 7	Interrupt Source Control 7 (Default: 00) These bits specify the active state of external INT[5] interrupts. 00: Low level active 01: High level active 10: Falling edge active 11: Rising edge active	R/W
13:12	IC6	Interrupt Source Control 6	Interrupt Source Control 6 (Default: 00) These bits specify the active state of external INT[4] interrupts. 00: Low level active 01: High level active 10: Falling edge active 11: Rising edge active	R/W
11:10	IC5	Interrupt Source Control 5	Interrupt Source Control 5 (Default: 00) These bits specify the active state of external INT[3] interrupts. 00: Low level active 01: High level active 10: Falling edge active 11: Rising edge active	R/W
9:8	IC4	Interrupt Source Control 4	Interrupt Source Control 4 (Default: 00) These bits specify the active state of external INT[2] interrupts. 00: Low level active 01: High level active 10: Falling edge active 11: Rising edge active	R/W
7:6	IC3	Interrupt Source Control 3	Interrupt Source Control 3 (Default: 00) These bits specify the active state of external INT[1] interrupts. 00: Low level active 01: High level active 10: Falling edge active 11: Rising edge active	R/W
5:4	IC2	Interrupt Source Control 2	Interrupt Source Control 2 (Default: 00) These bits specify the active state of external INT[0] interrupts. 00: Low level active 01: High level active 10: Falling edge active 11: Rising edge active	R/W
3:2	IC1	Interrupt Source Control 1	Interrupt Source Control 1 (Default: 00) These bits specify the active state of TX49 Write Timeout Error interrupts. 00: Low level active 01: Disable 10: Disable 11: Disable	R/W
1:0	IC0	Interrupt Source Control 0	Interrupt Source Control 0 (Default: 00) These bits specify the active state of ECC Error interrupts. 00: Low level active 01: Disable 10: Disable 11: Disable	R/W

Figure 15.4.2 Interrupt Detection Mode Register 0 (2/2)

15.4.3 Interrupt Detection Mode Register 1 (IRDM1) 0xF608



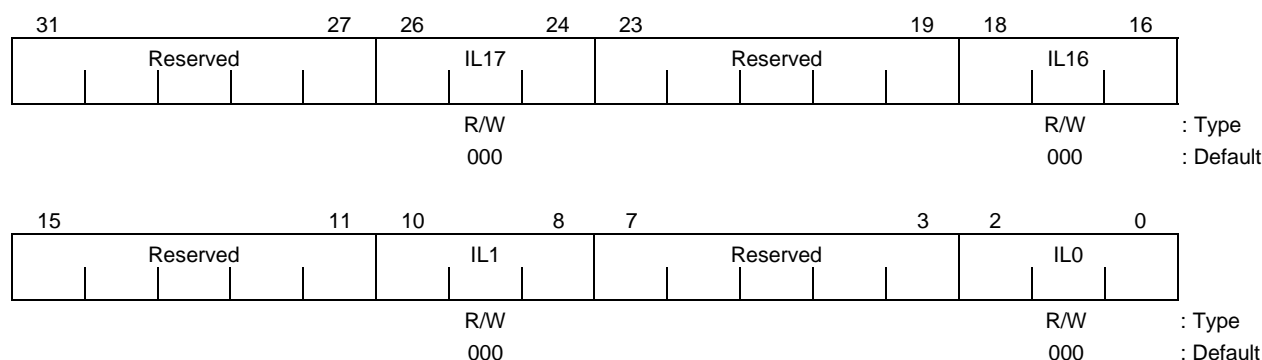
Bit	Mnemonic	Field Name	Explanation	Read/Write
31:20	—	—	Reserved	—
19:18	IC25	Interrupt Source Control 26	Interrupt Source Control 25 (Default: 00, R/W) These bits specify the active state of ACLCPME interrupts. 00: Low level active 01: Disable 10: Disable 11: Disable	R/W
17:16	IC24	Interrupt Source Control 24	Interrupt Source Control 24 (Default: 00, R/W) These bits specify the active state of ACLC interrupts. 00: Low level active 01: Disable 10: Disable 11: Disable	R/W
15:14	IC15	Interrupt Source Control 15	Interrupt Source Control 15 (Default: 00) These bits specify the active state of PDMAC interrupts. 00: Low level active 01: Disable 10: Disable 11: Disable	R/W
13:12	IC14	Interrupt Source Control 14	Interrupt Source Control 14 (Default: 00) These bits specify the active state of IRC interrupts. 00: Low level active 01: Disable 10: Disable 11: Disable	R/W
11:10	IC13	Interrupt Source Control 13	Interrupt Source Control 13 (Default: 00) These bits specify the active state of DMA [3] interrupts. 00: Low level active 01: Disable 10: Disable 11: Disable	R/W
9:8	IC12	Interrupt Source Control 12	Interrupt Source Control 12 (Default: 00) These bits specify the active state of DMA [2] interrupts. 00: Low level active 01: Disable 10: Disable 11: Disable	R/W

Figure 15.4.3 Interrupt Detection Mode Register 1 (1/2)

Bit	Mnemonic	Field Name	Explanation	Read/Write
7:6	IC11	Interrupt Source Control 11	Interrupt Source Control 11 (Default: 00) These bits specify the active state of DMA [1] interrupts. 00: Low level active 01: Disable 10: Disable 11: Disable	R/W
5:4	IC10	Interrupt Source Control 10	Interrupt Source Control 10 (Default: 00) These bits specify the active state of DMA[0] interrupts. 00: Low level active 01: Disable 10: Disable 11: Disable	R/W
3:2	IC9	Interrupt Source Control 9	Interrupt Source Control 9 (Default: 00) These bits specify the active state of SIO[1] interrupts. 00: Low level active 01: Disable 10: Disable 11: Disable	R/W
1:0	IC8	Interrupt Source Control 8	Interrupt Source Control 8 (Default: 00) These bits specify the active state of SIO[0] interrupts. 00: Low level active 01: Disable 10: Disable 11: Disable	R/W

Figure 15.4.3 Interrupt Detection Mode Register 1 (2/2)

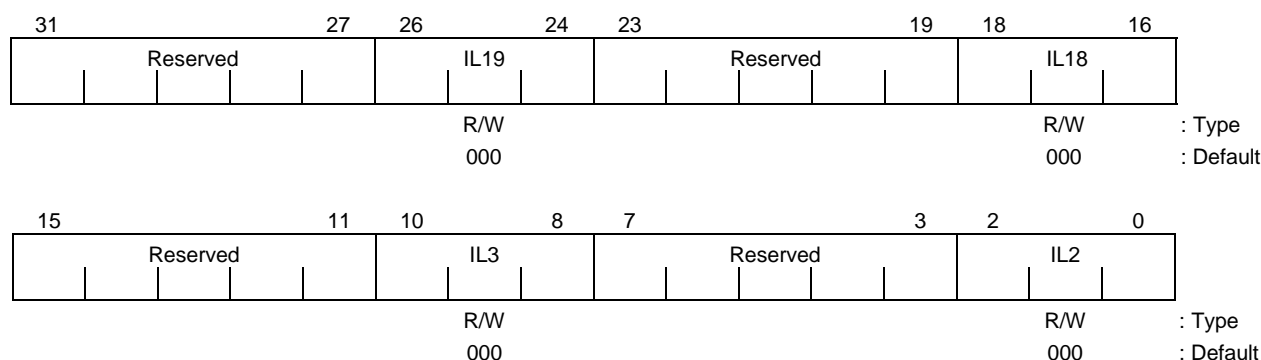
15.4.4 Interrupt Level Register 0 (IRLVL0) 0xF610



Bit	Mnemonic	Field Name	Explanation	Read/Write
31:27	—	—	Reserved	—
26:24	IL17	Interrupt Level 17	Interrupt Level of INT [17] (Default: 000) These bits specify the interrupt level of [TMR [0] 000: Interrupt Level 0 (Interrupt disable) 001: Interrupt level 1 010: Interrupt level 2 011: Interrupt level 3 100: Interrupt level 4 101: Interrupt level 5 110: Interrupt level 6 111: Interrupt level 7	R/W
23:19	—	—	Reserved	—
18:16	IL16	Interrupt Level 16	Interrupt Level of INT [16] (Default: 000) These bits specify the interrupt level of PCIC interrupts. 000: Interrupt level 0 (Interrupt disable) 001: Interrupt level 1 010: Interrupt level 2 011: Interrupt level 3 100: Interrupt level 4 101: Interrupt level 5 110: Interrupt level 6 111: Interrupt level 7	R/W
15:11	—	—	Reserved	—
10:8	IL1	Interrupt Level 1	Interrupt Level of INT [1] (Default: 000) These bits specify the interrupt level for TX49 Write Timeout Error interrupts. 000: Interrupt level 0 (Interrupt disable) 001: Interrupt level 1 010: Interrupt level 2 011: Interrupt level 3 100: Interrupt level 4 101: Interrupt level 5 110: Interrupt level 6 111: Interrupt level 7	R/W
7:3	—	—	Reserved	—
2:0	IL0	Interrupt Level 0	Interrupt Level of INT [0] (Default: 000) These bits specify the interrupt level of ECC Error interrupts. 000: Interrupt level 0 (Interrupt disable) 001: Interrupt level 1 010: Interrupt level 2 011: Interrupt level 3 100: Interrupt level 4 101: Interrupt level 5 110: Interrupt level 6 111: Interrupt level 7	R/W

Figure 15.4.4 Interrupt Level Register 0

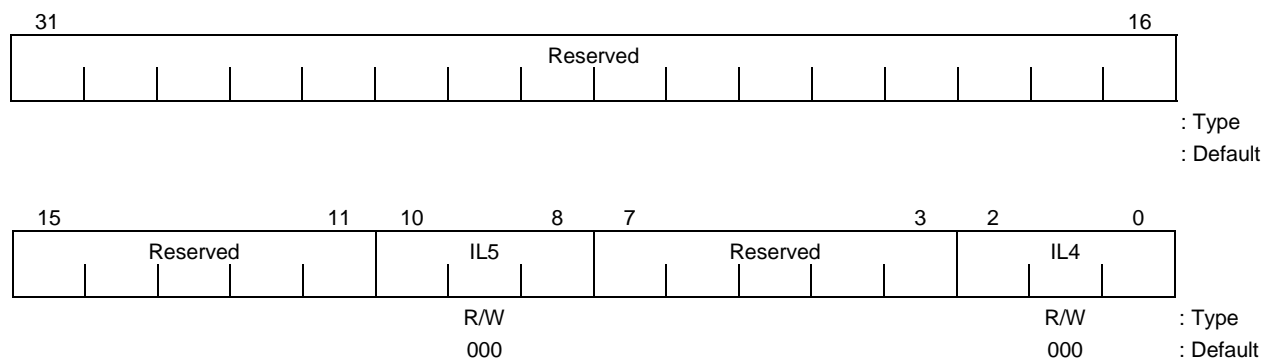
15.4.5 Interrupt Level Register (IRLVL1) 0xF614



Bit	Mnemonic	Field Name	Explanation	Read/Write
31:27	—	—	Reserved	—
26:24	IL19	Interrupt Level 19	Interrupt Level of INT [19] (Default: 000) These bits specify the interrupt level of TMR [2]. 000: Interrupt level 0 (Interrupt disable) 001: Interrupt level 1 010: Interrupt level 2 011: Interrupt level 3 100: Interrupt level 4 101: Interrupt level 5 110: Interrupt level 6 111: Interrupt level 7	R/W
23:19	—	—	Reserved	—
18:16	IL18	Interrupt Level 18	Interrupt Level of INT [18] (Default: 000) These bits specify the interrupt level of TMR[1]. 000: Interrupt level 0 (Interrupt disable) 001: Interrupt level 1 010: Interrupt level 2 011: Interrupt level 3 100: Interrupt level 4 101: Interrupt level 5 110: Interrupt level 6 111: Interrupt level 7	R/W
15:11	—	—	Reserved	—
10:8	IL3	Interrupt Level 3	Interrupt Level of INT [3] (Default: 000) These bits specify the interrupt level of external INT[1]. 000: Interrupt level 0 (Interrupt disable) 001: Interrupt level 1 010: Interrupt level 2 011: Interrupt level 3 100: Interrupt level 4 101: Interrupt level 5 110: Interrupt level 6 111: Interrupt level 7	R/W
7:3	—	—	Reserved	—
2:0	IL2	Interrupt Level 2	Interrupt Level of INT [2] (Default: 000) These bits specify the interrupt level of external INT[0]. 000: Interrupt level 0 (Interrupt disable) 001: Interrupt level 1 010: Interrupt level 2 011: Interrupt level 3 100: Interrupt level 4 101: Interrupt level 5 110: Interrupt level 6 111: Interrupt level 7	R/W

Figure 15.4.5 Interrupt Level Register 1

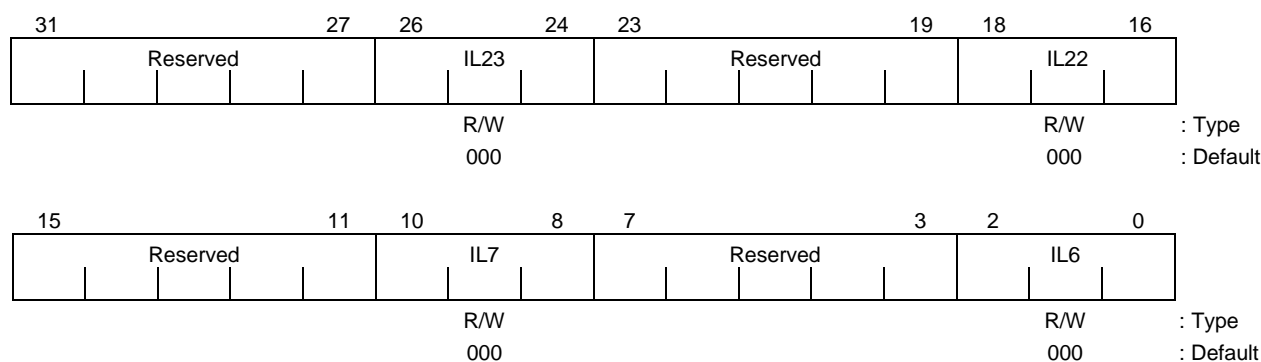
15.4.6 Interrupt Level Register 2 (IRLVL2) 0xF618



Bit	Mnemonic	Field Name	Explanation	Read/Write
31:11	—	—	Reserved	—
10:8	IL5	Interrupt Level 5	Interrupt Level of INT [5] (Default: 000) These bits specify the interrupt level of external INT[3]. 000: Interrupt level 0 (Interrupt disable) 001: Interrupt level 1 010: Interrupt level 2 011: Interrupt level 3 100: Interrupt level 4 101: Interrupt level 5 110: Interrupt level 6 111: Interrupt level 7	R/W
7:3	—	—	Reserved	—
2:0	IL4	Interrupt Level 4	Interrupt Level of INT [4] (Default: 000) These bits specify the interrupt level of external INT[2]. 000: Interrupt level 0 (Interrupt disable) 001: Interrupt level 1 010: Interrupt level 2 011: Interrupt level 3 100: Interrupt level 4 101: Interrupt level 5 110: Interrupt level 6 111: Interrupt level 7	R/W

Figure 15.4.6 Interrupt Level Register 2

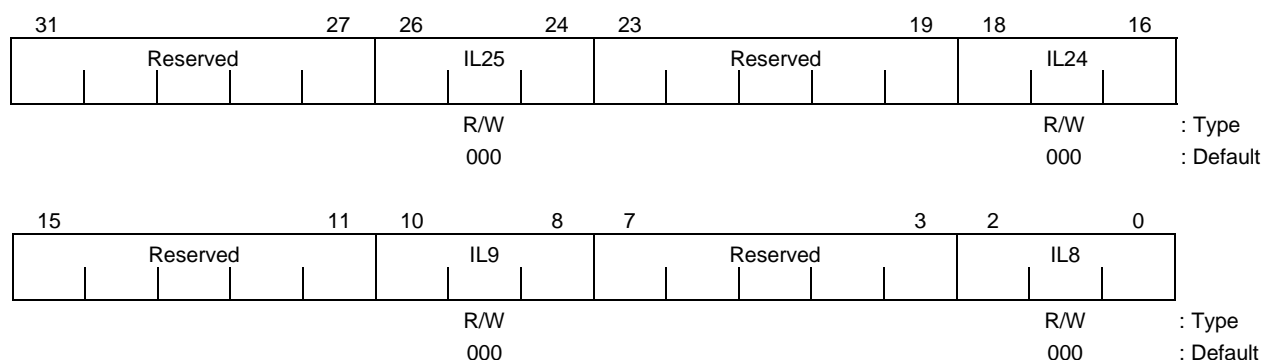
15.4.7 Interrupt Level Register 3 (IRLVL3) 0xF61C



Bit	Mnemonic	Field Name	Explanation	Read/Write
31:27	—	—	Reserved	—
26:24	IL23	Interrupt Level 23	Interrupt Level of INT [23] (Default: 000) These bits specify the interrupt level of PCIPMC interrupts. 000: Interrupt level 0 (Interrupt disabled) 001: Interrupt level 1 010: Interrupt level 2 011: Interrupt level 3 100: Interrupt level 4 101: Interrupt level 5 110: Interrupt level 6 111: Interrupt level 7	R/W
23:19	—	—	Reserved	—
18:16	IL22	Interrupt Level 22	Interrupt Level of INT [22] (Default: 000) These bits specify the interrupt level of PCIERR interrupts. 000: Interrupt level 0 (Interrupt disabled) 001: Interrupt level 1 010: Interrupt level 2 011: Interrupt level 3 100: Interrupt level 4 101: Interrupt level 5 110: Interrupt level 6 111: Interrupt level 7	R/W
15:11	—	—	Reserved	—
10:8	IL7	Interrupt level 7	Interrupt Level of INT [7] (Default: 000) These bits specify the interrupt level of external INT[4] interrupts. 000: Interrupt level 0 (Interrupt disabled) 001: Interrupt level 1 010: Interrupt level 2 011: Interrupt level 3 100: Interrupt level 4 101: Interrupt level 5 110: Interrupt level 6 111: Interrupt level 7	R/W
7:3	—	—	Reserved	—
2:0	IL6	Interrupt level 6	Interrupt Level of INT [6] (Default: 000) These bits specify the interrupt level of external INT[3] interrupts. 000: Interrupt level 0 (Interrupt disabled) 001: Interrupt level 1 010: Interrupt level 2 011: Interrupt level 3 100: Interrupt level 4 101: Interrupt level 5 110: Interrupt level 6 111: Interrupt level 7	R/W

Figure 15.4.7 Interrupt Level Register 3

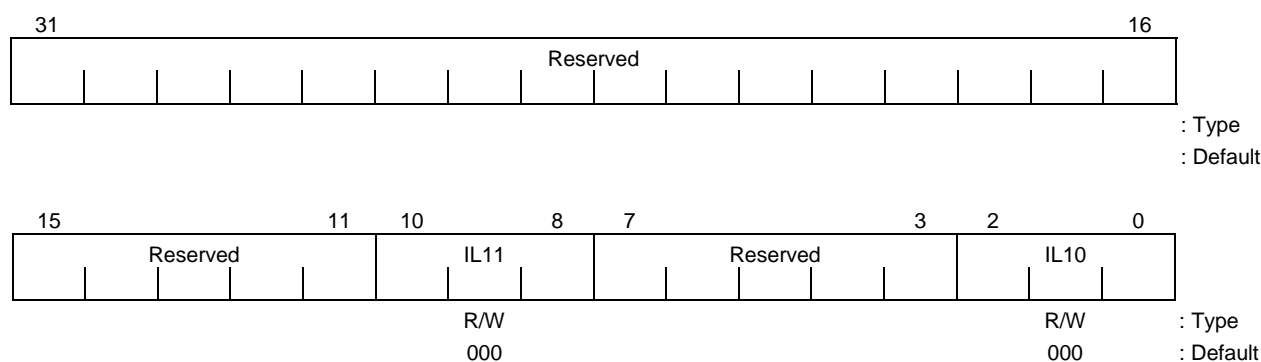
15.4.8 Interrupt Level Register 4 (IRLVL4) 0xF620



Bit	Mnemonic	Field Name	Explanation	Read/Write
31:27	—	—	Reserved	—
26:24	IL25	Interrupt level 25	Interrupt Level of INT [25] (Default: 000, R/W) These bits specify the interrupt level of ACLCPME interrupts. 000: Interrupt level 0 (Interrupt disabled) 001: Interrupt level 1 010: Interrupt level 2 011: Interrupt level 3 100: Interrupt level 4 101: Interrupt level 5 110: Interrupt level 6 111: Interrupt level 7	R/W
23:19	—	—	Reserved	—
18:16	IL24	Interrupt level 24	Interrupt Level of INT [24] (Default: 000, R/W) These bits specify the interrupt level of ACLC interrupts. 000: Interrupt level 0 (Interrupt disabled) 001: Interrupt level 1 010: Interrupt level 2 011: Interrupt level 3 100: Interrupt level 4 101: Interrupt level 5 110: Interrupt level 6 111: Interrupt level 7	R/W
15:11	—	—	Reserved	—
10:8	IL9	Interrupt level 9	Interrupt Level of INT [9] (Default: 000) These bits specify the interrupt level of SIO [1] interrupts. 000: Interrupt level 0 (Interrupt disabled) 001: Interrupt level 1 010: Interrupt level 2 011: Interrupt level 3 100: Interrupt level 4 101: Interrupt level 5 110: Interrupt level 6 111: Interrupt level 7	R/W
7:3	—	—	Reserved	—
2:0	IL8	Interrupt level 8	Interrupt Level of INT [8] (Default: 000) These bits specify the interrupt level of SIO [0] interrupts. 000: Interrupt level 0 (Interrupt disabled) 001: Interrupt level 1 010: Interrupt level 2 011: Interrupt level 3 100: Interrupt level 4 101: Interrupt level 5 110: Interrupt level 6 111: Interrupt level 7	R/W

Figure 15.4.8 Interrupt Level Register 4

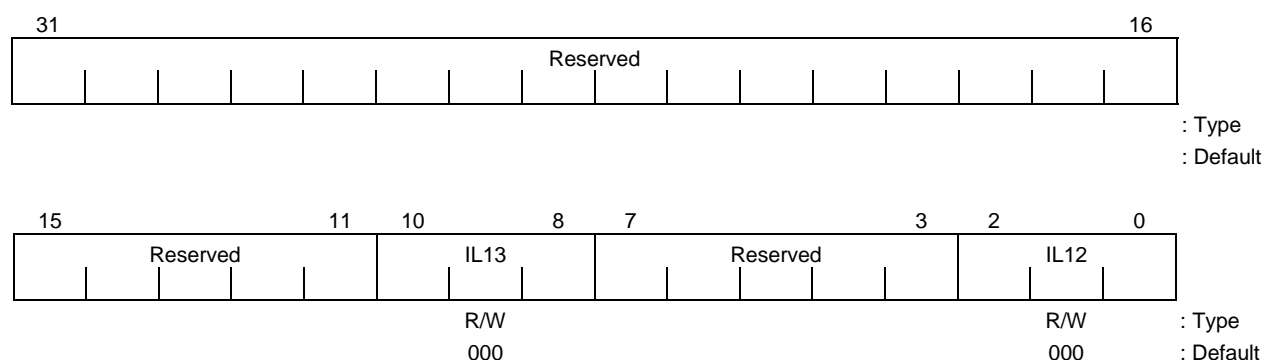
15.4.9 Interrupt Level Register 5 (IRLVL5) 0xF624



Bit	Mnemonic	Field Name	Explanation	Read/Write
31:11	—	—	Reserved	—
10:8	IL11	Interrupt level 11	Interrupt Level of INT [11] (Default: 000) These bits specify the interrupt level of DMA [1] interrupts. 000: Interrupt level 0 (Interrupt disabled) 001: Interrupt level 1 010: Interrupt level 2 011: Interrupt level 3 100: Interrupt level 4 101: Interrupt level 5 110: Interrupt level 6 111: Interrupt level 7	R/W
7:3	—	—	Reserved	—
2:0	IL10	Interrupt Level 10	Interrupt Level of INT [10] (Default: 000) These bits specify the interrupt level of DMA [0] interrupts. 000: Interrupt level 0 (Interrupt disabled) 001: Interrupt level 1 010: Interrupt level 2 011: Interrupt level 3 100: Interrupt level 4 101: Interrupt level 5 110: Interrupt level 6 111: Interrupt level 7	R/W

Figure 15.4.9 Interrupt Level Register 5

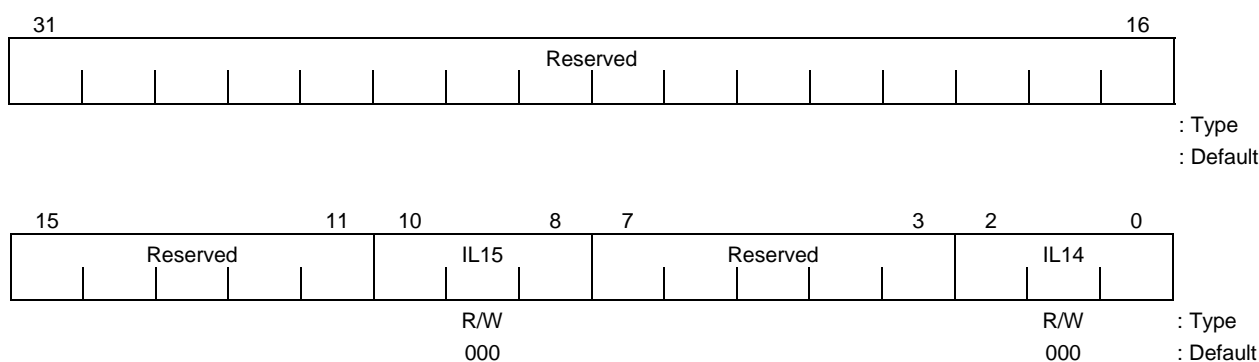
15.4.10 Interrupt Level Register 6 (IRLVL6) 0xF628



Bit	Mnemonic	Field Name	Explanation	Read/Write
31:11	—	—	Reserved	—
10:8	IL13	Interrupt level 13	Interrupt Level of INT [13] (Default: 000) These bits specify the interrupt level of DMA [3] interrupts. 000: Interrupt level 0 (Interrupt disabled) 001: Interrupt level 1 010: Interrupt level 2 011: Interrupt level 3 100: Interrupt level 4 101: Interrupt level 5 110: Interrupt level 6 111: Interrupt level 7	R/W
7:3	—	—	Reserved	—
2:0	IL12	Interrupt level 12	Interrupt Level of INT [12] (Default: 000) These bits specify the interrupt level of DMA [2] interrupts. 000: Interrupt level 0 (Interrupt disable) 001: Interrupt level 1 010: Interrupt level 2 011: Interrupt level 3 100: Interrupt level 4 101: Interrupt level 5 110: Interrupt level 6 111: Interrupt level 7	R/W

Figure 15.4.10 Interrupt Level Register 6

15.4.11 Interrupt Level Register 7 (IRLVL7) 0xF62C



Bit	Mnemonic	Field Name	Explanation	Read/Write
31:11	—	—	Reserved	—
10:8	IL15	Interrupt level 15	Interrupt Level of INT [15] (Default: 000) These bits specify the interrupt level of PDMAC interrupts. 000: Interrupt level 0 (Interrupt disabled) 001: Interrupt level 1 010: Interrupt level 2 011: Interrupt level 3 100: Interrupt level 4 101: Interrupt level 5 110: Interrupt level 6 111: Interrupt level 7	R/W
7:3	—	—	Reserved	—
2:0	IL14	Interrupt Level 14	Interrupt Level of INT [14] (Default: 000) These bits specify the interrupt level of IRC interrupts. 000: Interrupt level 0 (Interrupt disabled) 001: Interrupt level 1 010: Interrupt level 2 011: Interrupt level 3 100: Interrupt level 4 101: Interrupt level 5 110: Interrupt level 6 111: Interrupt level 7	R/W

Figure 15.4.11 Interrupt Level Register 7

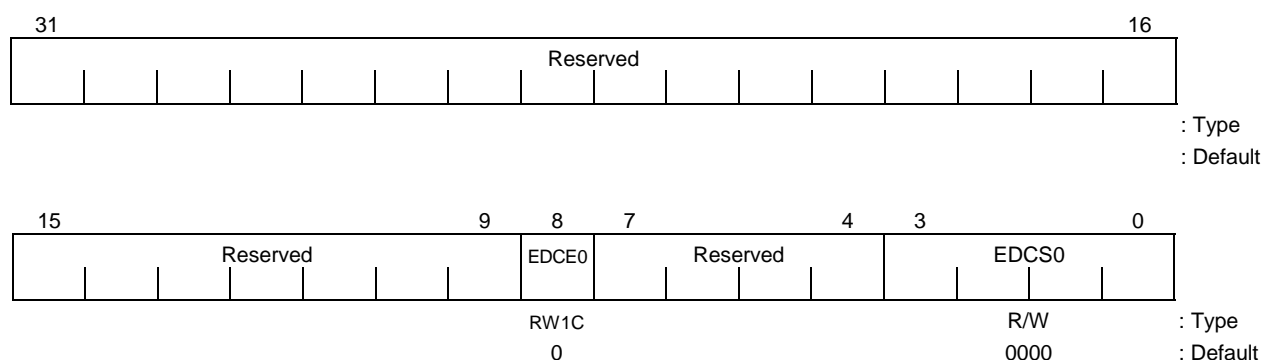
15.4.12 Interrupt Mask Level Register (IRMSK) 0xF640



Bit	Mnemonic	Field Name	Explanation	Read/Write
31:3	—	—	Reserved	—
2:0	IML	Interrupt Mask Level	Interrupt Mask Level (Default: 000) These bits specify the interrupt mask level. Masks interrupts with a mask level lower than the set mask level. 000: Interrupt mask level 0 (No interrupts masked) 001: Interrupt mask level 1 (Levels 2-7 enabled) 010: Interrupt mask level 2 (Levels 3-7 enabled) 011: Interrupt mask level 3 (Levels 4-7 enabled) 100: Interrupt mask level 4 (Levels 5-7 enabled) 101: Interrupt mask level 5 (Levels 6-7 enabled) 110: Interrupt mask level 6 (Level 7 enabled) 111: Interrupt mask level 7 (Interrupts disabled)	R/W

Figure 15.4.12 Interrupt Mask Register

15.4.13 Interrupt Edge Detection Clear Register (IREDC) 0xF660



Bit	Mnemonic	Field Name	Explanation	Read/Write
31:9	—	—	Reserved	—
8	EDCE0	Edge Detection Clear Enable 0	Edge Detection Clear Enable 0 (Default: 0) Clears edge detection of interrupts specified by the EDCS0 field. 0: Does not clear. 1: Clears. Value always becomes "0" when this bit is read.	R/W1C
7:4	—	—	Reserved	—
3:0	EDCS0	Edge Detection Clear Source 0	Edge Detection Clear Source 0 (Default: 0x0) These bits specify the interrupt source to be cleared. 1111: PDMAC interrupt 1110: IRC interrupt 1101: DMA [3] interrupt 1100: DMA [2] interrupt 1011: DMA [1] interrupts 1010: DMA [0] interrupt 1001: SIO [1] interrupt 1000: SIO [0] interrupt 0111: External INT [5] interrupt 0110: External INT [4] interrupt 0101: External INT [3] interrupt 0100: External INT [2] interrupt 0011: External INT [1] interrupt 0010: External INT [0] interrupt 0001: TX49 Write Timeout Error interrupt 0000: ECC Error interrupt	R/W

Figure 15.4.13 Interrupt Status Control Register

15.4.14 Interrupt Pending Register (IRPND) 0xF680

Indicates the status of each interrupt request regardless of the IRLVL 7-0 and IRMSK value.

31						26	25	24	23	22	21	20	19	18	17	16
Reserved						IS25	IS24	IS23	IS22	Reserved		IS19	IS18	IS17	IS16	
						R	R	R	R			R	R	R	R	: Type
						0	0	0	0			0	0	0	0	: Default
15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0	
IS15	IS14	IS13	IS12	IS11	IS10	IS9	IS8	IS7	IS6	IS5	IS4	IS3	IS2	IS1	IS0	
R	R	R	R	R	R	R	R	R	R	R	R	R	R	R	R	: Type
0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	: Default

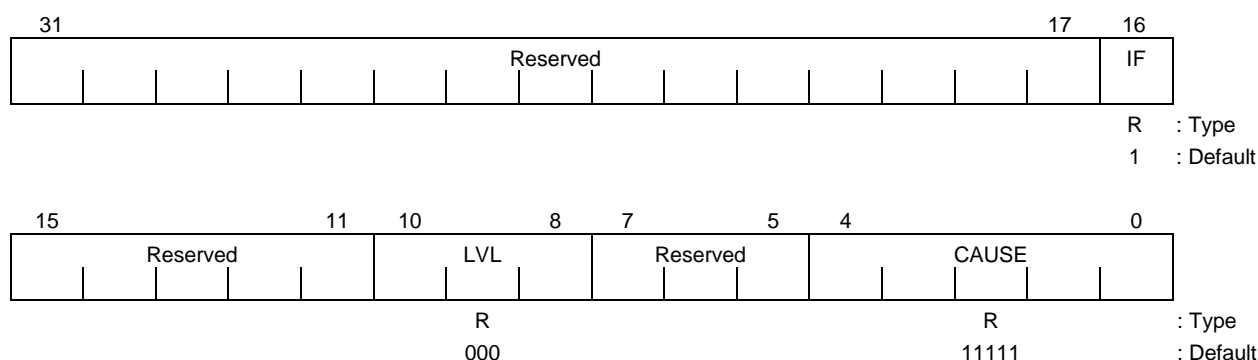
Bit	Mnemonic	Field Name	Explanation	Read/Write
31:26	—	—	Reserved	—
25	IS25	Interrupt Status 25	IRINTREQ [25] Status (Default: 0, R) This bit indicates the ACLCPME interrupt status. 1: Interrupt requests 0: No interrupt requests	R
24	IS24	Interrupt Status 24	IRINTREQ [24] Status (Default: 0, R) This bit indicates the ACLC interrupt status. 1: Interrupt requests 0: No interrupt requests	R
23	IS23	Interrupt Status 23	IRINTREQ [23] status This bit indicates the PCIPMC interrupt status 1: Interrupt requests 0: No interrupt requests	R
22	IS22	Interrupt Status 22	IRINTREQ [22] status This bit indicates the PCIERR error status. 1: Interrupt requests 0: No interrupt requests	R
21:20	—	—	Reserved	—
19	IS19	Interrupt Status 19	IRINTREQ [19] status This bit indicates the TMR [2] interrupt status. 1: Interrupt requests 0: No interrupt requests	R
18	IS18	Interrupt Status 18	IRINTREQ [18] status This bit indicates the TMR [1] interrupt status. 1: Interrupt requests 0: No interrupt requests	R
17	IS17	Interrupt Status 17	IRINTREQ [17] status This bit indicates the TMR[0] interrupt status 1: Interrupt requests 0: No interrupt requests	R
16	IS16	Interrupt Status 16	IRINTREQ [16] status This bit indicates the PCIC interrupt status 1: Interrupt requests 0: No interrupt requests	R
15	IS15	Interrupt Status 15	IRINTREQ [15] status This bit indicates the PDMAC interrupt status. 1: Interrupt requests 0: No interrupt requests	R
14	IS14	Interrupt Status 14	IRINTREQ [14] status This bit indicates the IRC interrupt status 1: Interrupt requests 0: No interrupt requests	R

Figure 15.4.14 Interrupt Source Status Register (1/2)

Bit	Mnemonic	Field Name	Explanation	Read/Write
13	IS13	Interrupt Status 13	IRINTREQ [13] status This bit indicates the DMA [3] interrupt status 1: Interrupt requests 0: No interrupt requests	R
12	IS12	Interrupt Status 12	IRINTREQ [12] status This bit indicates the status of DMA [2] interrupts. 1: Interrupt requests 0: No interrupt requests	R
11	IS11	Interrupt Status 11	IRINTREQ [11] status This bit indicates the status of DMA [1] interrupts. 1: Interrupt requests 0: No interrupts requests	R
10	IS10	Interrupt Status 10	IRINTREQ [10] status This bit indicates the status of DMA [0] interrupts. 1: Interrupt requests 0: No interrupt requests	R
9	IS9	Interrupt Status 9	IRINTREQ [9] status This bit indicates the status of SIO [1] interrupts. 1: Interrupt requests 0: No interrupt requests	R
8	IS8	Interrupt Status 8	IRINTREQ [8] status This bit indicates the status of SIO [0] interrupts. 1: Interrupt requests 0: No interrupt requests	R
7	IS7	Interrupt Status 7	IRINTREQ [7] status This bit indicates the status of external INT [5] interrupts. 1: Interrupt requests 0: No interrupt requests	R
6	IS6	Interrupt Status 6	IRINTREQ [6] status This bit indicates the status of external INT [4] interrupts. 1: Interrupt requests 0: No interrupt requests	R
5	IS5	Interrupt Status 5	IRINTREQ [5] status This bit indicates the status of external INT [3] interrupts. 1: Interrupt requests 0: No interrupt requests	R
4	IS4	Interrupt Status 4	IRINTREQ [4] status This bit indicates the status of external INT [2] interrupts. 1: Interrupt requests 0: No interrupt requests	R
3	IS3	Interrupt Status 3	IRINTREQ [3] status This bit indicates the status of external INT [1] interrupts. 1: Interrupt requests 0: No interrupt requests	R
2	IS2	Interrupt Status 2	IRINTREQ [2] status This bit indicates the status of external INT [0] interrupts. 1: Interrupt requests 0: No interrupt requests	R
1	IS1	Interrupt Status 1	IRINTREQ [1] status This bit indicates the status of TX49 Write Timeout Error interrupts. 1: Interrupt requests 0: No interrupt requests	R
0	IS0	Interrupt Status 0	IRINTREQ [0] status This bit indicates the status of ECC Error interrupts. 1: Interrupt requests 0: No interrupt requests	R

Figure 15.4.14 Interrupt Source Status Register (2/2)

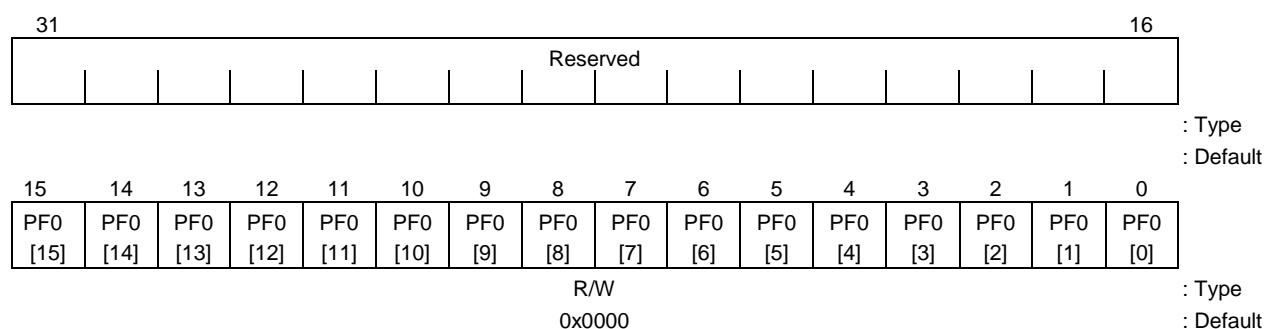
15.4.15 Interrupt Current Status Register (IRCS) 0xF6A0



Bit	Mnemonic	Field Name	Explanation	Read/Write
31:17	—	—	Reserved	—
16	IF	Interrupt Flag	Interrupt Flag (Default: 1) This bit indicates the interrupt generation status. 0: Interrupt requests have been generated. 1: Interrupt requests have not been generated	R
15:11	—	—	Reserved	—
10:8	LVL	Interrupt Level	Interrupt Level (Default: 000) These bits specify the level of the interrupt request that was reported to the TX49/H2 core. 000: Interrupt level 0 001: Interrupt level 1 : : 111: Interrupt level 7	R
7:5	—	—	Reserved	—
4:0	CAUSE	Interrupt Cause	Interrupt Cause (Default: 0x1F) These bits specify the interrupt cause that was reported to the TX49/H2 core. 00000: ECC Error 00001: TX49 Write Timeout Error 00010: External INT [0] interrupt 00011: External INT [1] interrupt 00100: External INT [2] interrupt 00101: External INT [3] interrupt 00110: External INT [4] interrupt 00111: External INT [5] interrupt 01000: SIO [0] interrupt 01001: SIO [1] interrupt 01010: DMA [0] interrupt 01011: DMA [1] interrupt 01100: DMA [2] interrupt 01101: DMA [3] interrupt 01110: IRC interrupt 01111: PDMAC interrupt 10000: PCIC interrupt 10001: TMR [0] interrupt 10010: TMR [1] interrupt 10011: TMR [2] interrupt 10100: (Reserved) 10101: (Reserved) 10110: PCIERR interrupt 10111: PCIPMC interrupt 11000 ~ 11111: (Reserved)	R

Figure 15.4.15 Interrupt Current Status Register

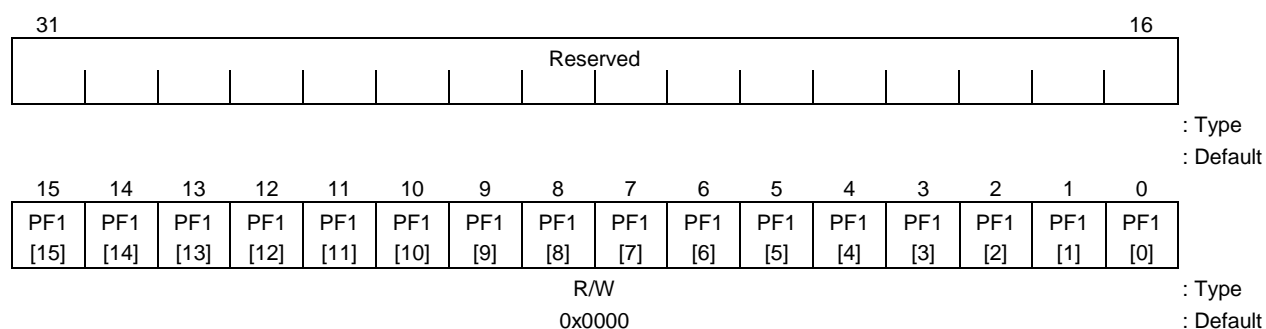
15.4.16 Interrupt Request Flag Register 0 (IRFLAG0) 0xF510



Bit	Mnemonic	Field Name	Explanation	Read/Write
31:16	—	—	Reserved	—
15:0	PF0 [15:0]	Flag 0	Interrupt Request Flag 0 [15:0] (Default: 0x0000) Changes made to this register are reflected in Flag Register 1 also since they are the same registers. The bits in this field accept writes of both 1s and 0s.	R/W

Figure 15.4.16 Interrupt Request Flag Register 0

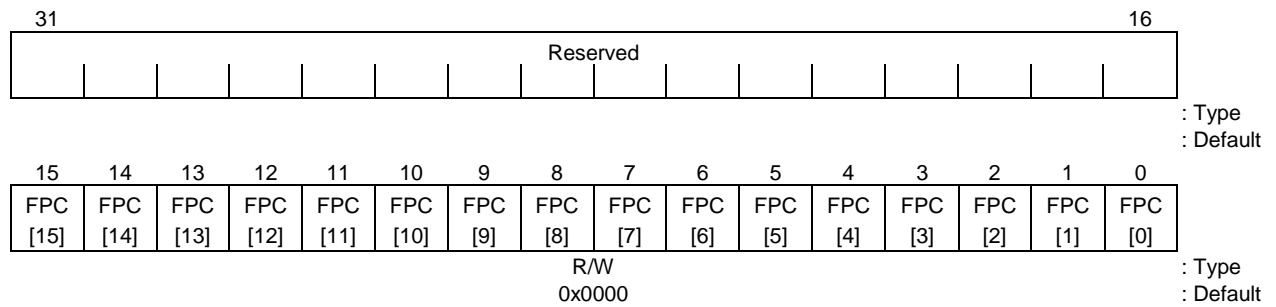
15.4.17 Interrupt Request Flag Register 1 (IRFLAG1) 0xF514



Bit	Mnemonic	Field Name	Explanation	Read/Write
31:16	—	—	Reserved	—
15:0	PF1 [15:0]	Flag 1	Interrupt Request Flag 1 [15:0] (Default: 0x0000) Changes made to this register are reflected in Flag Register 0 also since they are the same registers. Both “0” and “1” can be written to Flag Register 0. Writes to Flag Register 1 operate as follows: Write Write from the TX49/H2 core 1: Set the flag bit 0: No change Write from other devices (DMAC, PCIC) 1: Clear the flag bit 0: No change Read: Read the flag bit	R/W

Figure 15.4.17 Interrupt Request Flag Register 1

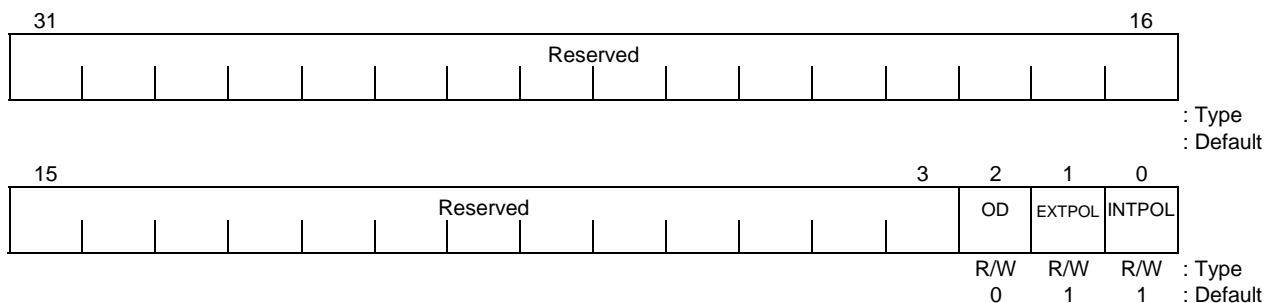
15.4.18 Interrupt Request Polarity Control Register (IRPOL) 0xF518



Bit	Mnemonic	Field Name	Explanation	Read/Write															
31:16	—	—	Reserved	—															
15:0	FPC [15:0]	Flag Polarity Control	Flag Polarity Control [15:0] (Default: 0x0000) These bits specify the polarity of the flag bit that generated the interrupt. An interrupt request is generated when the XOR of the FPC bit and the flag bit is “1.” <table><tr><td>Flag bit (PF)</td><td>FPC bit</td><td>Interrupt request</td></tr><tr><td>0</td><td>0</td><td>No</td></tr><tr><td>0</td><td>1</td><td>Yes</td></tr><tr><td>1</td><td>0</td><td>Yes</td></tr><tr><td>1</td><td>1</td><td>No</td></tr></table>	Flag bit (PF)	FPC bit	Interrupt request	0	0	No	0	1	Yes	1	0	Yes	1	1	No	R/W
Flag bit (PF)	FPC bit	Interrupt request																	
0	0	No																	
0	1	Yes																	
1	0	Yes																	
1	1	No																	

Figure 15.4.18 Interrupt Requests Polarity Control Register

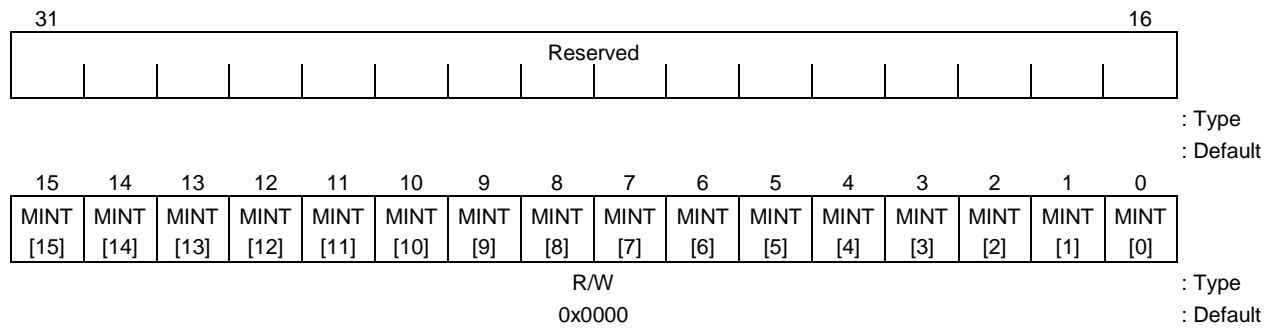
15.4.19 Interrupt Request Control Register (IRRCNT) 0xF51C



Bit	Mnemonic	Field Name	Explanation	Read/Write
31:3	—	—	Reserved	—
2	OD	External Interrupt OD Control	External Interrupt Open Drain Control (Default: 0) This bit specifies whether to make the external interrupt signal (IRC[2]*) an open drain pin or not. 0: Open drain (reset) 1: Totem pole	R/W
1	EXTPOL	External Interrupt Request Polarity Control	External Interrupt Polarity Control (Default: 1) This bit specifies the polarity of external interrupt requests. 0: Do not reverse polarity of interrupt requests. 1: Reverse polarity of interrupt requests	R/W
0	INTPOL	Internal Interrupt Request Polarity Control	Internal Interrupt Polarity Control (Default: 1) This bit specifies the polarity of internal interrupt requests. 0: Do not reverse polarity of interrupt requests. 1: Reverse polarity of interrupt requests	R/W

Figure 15.4.19 Interrupt Request Control Register

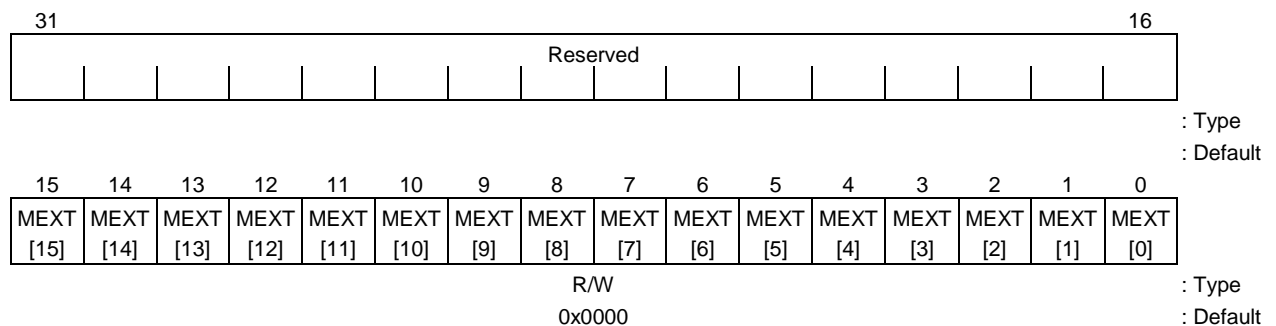
15.4.20 Interrupt Request Internal Interrupt Mask Register (IRMASKINT) 0xF520



Bit	Mnemonic	Field Name	Explanation	Read/Write
31:16	—	—	Reserved	—
15:0	MINT [15:0]	Internal Request Mask	Internal Interrupt Mask (Default: 0x0000) These bits specify whether to use the corresponding flag bit as an internal interrupt cause. Interrupt causes are masked when this bit is "0." 0: Mask (Reset) 1: Do not mask	R/W

Figure 15.4.20 Interrupt Request Internal Interrupt Mask Register

15.4.21 Interrupt Request External Interrupt Mask Register (IRMASKEXT) 0xF524



Bit	Mnemonic	Field Name	Explanation	Read/Write
31:16	—	—	Reserved	—
15:0	MEXT [15:0]	External Request Mask	External Interrupt Mask (Default: 0x0000) These bits specify whether to use the corresponding flag bit as an external interrupt cause. Interrupt causes are masked when this bit is "0." 0: Mask (reset) 1: Do not mask	R/W

Figure 15.4.21 Interrupt Request External Interrupt Mask Register

16. Extended EJTAG Interface

16.1 Extended EJTAG Interface

The TX4927 Extended EJTAG (Enhanced Joint Test Action Group) Interface provides two real-time debugging functions. One is the IEEE1149.1 standard compliant JTAG Boundary Scan Test, and the other is the Debugging Support Unit (DSU) that is built into the TX49/H2 core.

JTAG Boundary Scan Test

- IEEE1149.1 compatible TAP Controller
- Supports the following five instructions: EXTEST, SAMPLE/PRELOAD, IDCODE, BYPASS, HIGHZ

Real-time Debugging

- Real-time debugging using an emulation probe (made by Corelis or YDC)
- Execution control (run, break, step, register/memory access)
- Real-time PC tracing

Please contact your local Toshiba Sales representative for more information regarding how to connect the emulation probe.

The two functions of the Extended EJTAG Interface operate in one of two modes.

PC Trace Mode

- Execution control (run, pause, access single steps, access internal register/system memory)
- JTAG Boundary Scan Test

Real-time Mode

- Real-time PC tracing

Refer to Section 3.1.11 for more information regarding signals used with the Extended EJTAG Interface.

Table 16.1.1 EJTAG Interface Function and Operation Code

PC Tracing Mode	Off	On
JTAG Boundary Scan	Boundary Scan Test	—
Real-time Debugging	Execution Control	Real-time PC Tracing

16.2 JTAG Boundary Scan Test

16.2.1 JTAG Controller and Register

The Extended EJTAG Interface contains a JTAG Controller (TAP Controller) and a Control Register. This section explains only those portions that are unique to the TX4927. Please refer to the TX49/H2 Core Architecture Manual for all other portion not covered here. Please contact your local Toshiba Sales representative for more information regarding the required BSD files when performing the JTAG Boundary Scan Test.

- Instruction Register (Refer to 16.2.2)
- Data Register
 - Boundary Scan Register (Refer to 16.2.3)
 - Bypass Register
 - Device ID Register (Refer to 16.2.4)
 - JTAG Address Register
 - JTAG Data Register
 - JTAG Control Register
 - EJTAG Mount Register
- Test Access Port Controller (TAP Controller) (Refer to 16.3)

16.2.2 Instruction Register

The JTAG Instruction Register consists of an 8-bit shift register. This register is used for selecting either one or both of the test to be performed and the Test Data Register to be accessed. The Data Register is selected according to the instruction code in Table 16.2.1. Refer to the TX49/H2 Core Architecture Manual for more information regarding each instruction.

Table 16.2.1 Bit Configuration of JTAG Instruction Register

Instruction Code MSB → LSB	Instruction	Selected Data Register
00000000 (0x00)	EXTEST	Boundary Scan Register
00000001 (0x01)	SAMPLE/PRELOAD	Boundary Scan Register
00000010 (0x02)	Reserved	Reserved
00000011 (0x03)	IDCODE	Device ID Register
00000100 - 00001111	Reserved	Reserved
00010000 (0x10)	HIGHZ	Bypass Register
00010001 - 01111111	Reserved	Reserved
10000000 - 11111110	Refer to the TX49/H2 Core Architecture Manual	
11111111 (0xFF)	BYPASS	Bypass Register

Figure 16.2.1 shows the format of the Instruction Register.

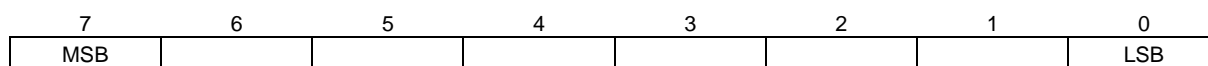


Figure 16.2.1 Instruction Register

The instruction code is shifted to the Instruction Register starting from the Least Significant Bit.

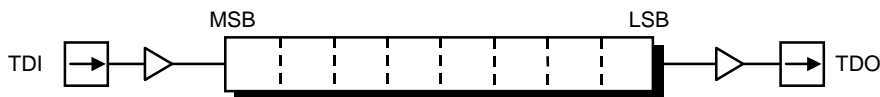


Figure 16.2.2 Shift Direction of the Instruction Register

16.2.3 Boundary Scan Register

The Boundary Scan Register contains a single 256-bit shift register to which all TX4927 I/O signals except for power supply, TDI, TCK, TDO, TMS, TRST*, and TEST[4]* are connected. Figure 16.2.3 shows the bits of the Boundary Scan Register.

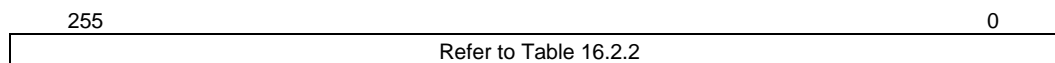


Figure 16.2.3 Boundary Scan Register

Table 16.2.2 shows the scan sequence of 256 signals starting from TDI and ending with TDO.

TDI input is fetched to the Least Significant Bit (LSB) of the Boundary Scan Register and the Most Significant Bit (MSB) of the Boundary Scan Register is sent from the TDO output.

Table 16.2.2 shows the boundary scan sequence relative to the processor signals.

Table 16.2.2 TX4927 Processor JTAG Scan Sequence (1/2)

JTAG Scan Sequence	Signal Name	JTAG Scan Sequence	Signal Name	JTAG Scan Sequence	Signal Name
	TDI	53	DATA[45]	106	CB[6]
1	PIO[3]	54	DATA[13]	107	DATA[16]
2	PIO[4]	55	DATA[9]	108	DQM[2]
3	PIO[5]	56	DATA[14]	109	SDCS[3]*
4	PIO[6]	57	DATA[44]	110	DATA[18]
5	TIMER[1]	58	DATA[40]	111	DATA[49]
6	PIO[7]	59	DATA[15]	112	CB[7]
7	TIMER[0]	60	DATA[46]	113	CB[2]
8	NMI*	61	DATA[42]	114	DATA[17]
9	INT[0]	62	DATA[12]	115	DQM[7]
10	RXD[0]	63	CB[0]	116	DATA[19]
11	TCLK	64	DATA[47]	117	DATA[51]
12	INT[1]	65	CB[4]	118	CB[3]
13	INT[2]	66	CB[1]	119	DATA[48]
14	INT[3]	67	DQM[0]	120	DATA[20]
15	INT[4]	68	CB[5]	121	DATA[50]
16	INT[5]	69	CAS*	122	DATA[52]
17	CTS[0]*	70	WE*	123	DATA[21]
18	RXD[1]	71	DQM[4]	124	DATA[23]
19	CTS[1]*	72	SDCS[0]*	125	DATA[53]
20	RTS[0]*	73	DQM[1]	126	DATA[22]
21	RTS[1]*	74	DQM[5]	127	DATA[54]
22	TXD[0]	75	SDCS[1]*	128	DATA[55]
23	TXD[1]	76	RAS*	129	DATA[25]
24	HALTDOZE	77	ADDR[0]	130	DATA[24]
25	SCLK	78	ADDR[3]	131	DATA[56]
26	TEST[0]*	79	ADDR[1]	132	DATA[57]
27	RESET*	80	ADDR[2]	133	DATA[26]
28	TEST[1]*	81	ADDR[4]	134	DATA[58]
29	SYSCLK	82	ADDR[5]	135	DATA[28]
30	OE*	83	ADDR[6]	136	DATA[27]
31	WDRST*	84	ADDR[7]	137	DATA[59]
32	DATA[32]	85	ADDR[8]	138	DATA[60]
33	DATA[0]	86	ADDR[9]	139	DATA[29]
34	DATA[1]	87	ADDR[11]	140	DATA[61]
35	DATA[2]	88	ADDR[10]	141	DATA[30]
36	DATA[35]	89	ADDR[13]	142	DATA[62]
37	DATA[33]	90	ADDR[12]	143	DATA[31]
38	DATA[3]	91	SDCLK[2]	144	MASTERCLK
39	DATA[34]	92	SDCLK[0]	145	CGRESET*
40	DATA[5]	93	SDCLKIN	146	PCICLKIN
41	DATA[36]	94	ADDR[14]	147	PCICLK[5]
42	DATA[38]	95	ADDR[16]	148	DATA[63]
43	DATA[6]	96	ADDR[15]	149	PCICLK[4]
44	DATA[37]	97	ADDR[19]	150	PME*
45	DATA[4]	98	ADDR[18]	151	GNT[3]*
46	DATA[8]	99	SDCLK[3]	152	REQ[3]*
47	DATA[39]	100	SDCS[2]*	153	PCICLK[3]
48	DATA[10]	101	CKE	154	GNT[2]*
49	DATA[41]	102	ADDR[17]	155	REQ[2]*
50	DATA[43]	103	SDCLK[1]	156	PCICLK[2]
51	DATA[7]	104	DQM[3]	157	REQ[0]*
52	DATA[11]	105	DQM[6]	158	PCICLK[1]

Table 16.2.2 TX4927 Processor JTAG Scan Sequence (2/2)

JTAG Scan Sequence	Signal Name	JTAG Scan Sequence	Signal Name	JTAG Scan Sequence	Signal Name
159	GNT[1]*	192	C_BE[1]	225	DCLK
160	REQ[1]*	193	PCIAD[10]	226	EEPROM_DI
161	GNT[0]*	194	PCIAD[13]	227	BWE[1]*
162	PCICLK[0]	195	M66EN	228	BWE[2]*
163	PCIAD[30]	196	PCIAD[15]	229	BWE[0]*
164	PCIAD[24]	197	PCIAD[12]	230	BWE[3]*
165	PCIAD[25]	198	PCIAD[11]	231	DMAACK[0]
166	PCIAD[23]	199	PCIAD[9]	232	DMAREQ[0]
167	PCIAD[29]	200	PCIAD[8]	233	DMAREQ[1]
168	PCIAD[31]	201	C_BE[0]	234	DMAACK[1]
169	PCIAD[26]	202	PCIAD[7]	235	DMAREQ[2]
170	PCIAD[19]	203	PCIAD[4]	236	DMAACK[2]
171	PCIAD[20]	204	PCIAD[6]	237	DMAACK[3]
172	ID_SEL	205	PCIAD[5]	238	CE[4]*
173	PCIAD[27]	206	PCIAD[3]	239	DMAREQ[3]
174	PCIAD[18]	207	PCIAD[1]	240	DMADONE*
175	PCIAD[21]	208	PCIAD[2]	241	CE[3]*
176	PCIAD[28]	209	PCIAD[0]	242	CE[1]*
177	C_BE[3]	210	PCST[0]	243	CE[5]*
178	PCIAD[16]	211	PCST[1]	244	CE[2]*
179	PCIAD[17]	212	PCST[2]	245	CE[0]*
180	TRDY*	213	PCST[3]	246	CE[7]*
181	PCIAD[22]	214	EEPROM_CS	247	CE[6]*
182	C_BE[2]	215	PCST[4]	248	ACE*
183	FRAME*	216	PCST[5]	249	SWE*
184	DEVSEL*	217	PCST[8]	250	PIO[0]
185	IRDY*	218	PCST[7]	251	BUSSPRT*
186	STOP*	219	PCST[6]	252	ACK*
187	LOCK*	220	EEPROM_SK	253	SD[1]
188	SERR*	221	EEPROM_DO	254	BYPASSPLL*
189	PCIAD[14]	222	TPC[3]	255	PIO[1]
190	PERR*	223	TPC[2]	256	PIO[2]
191	PAR	224	TPC[1]		TDO

16.2.4 Device ID Register

The Device ID Register is a 32-bit shift register. This register is used for reading the ID code that expresses the IC manufacturer, part number, and version from the IC and sending it to a serial device. The following figure shows the configuration of the Device ID Register.

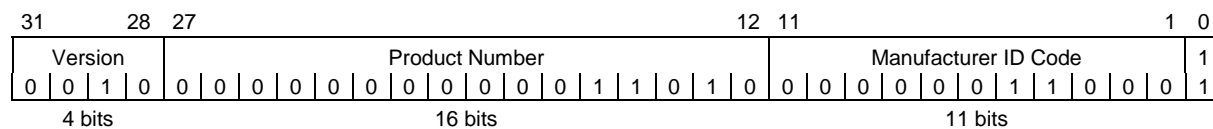


Figure 16.2.4 Device ID Register

The device ID code for the TX4927 is 0x4001A031. However, the four top bits of the Version field may be changed. The device ID code is shifted out from the Least Significant Bit.



Figure 16.2.5 Shift Direction of the Device ID Register

16.3 Initializing the Extended EJTAG Interface

The Extended EJTAG Interface is not reset by asserting the RESET* signal. Operation of the TX49/H2 core is not guaranteed if the Extended EJTAG Interface is not reset. This interface is initialized by either of the following methods.

- Assert the TRST* signal.
- After clearing the processor reset, set the TMS input to High for five consecutive rising edges of the TCK input. The reset state is maintained if TMS is able to maintain the High state.

The above methods must be performed while the MASTERCLK signal is being input. Also, externally fix the TRST* signal to GND when not using an emulation probe. The G-Bus Time Out Detection function is disabled when the TRST* signal is deasserted. (Refer to Section 5.1.1.)

17. Electrical Characteristics

17.1 Absolute Maximum Ratings (*1)

Parameter	Symbol	Rating	Unit
Supply Voltage (I/O)	$V_{CCIOMax}$	-0.3 to 3.9	V
Supply Voltage (Core)	$V_{CCIntMax}$	-0.3 to 3.0	V
Input Voltage (*2)	V_{IN}	-0.3 to $V_{CCIO} + 0.3V$	V
Storage Temperature	T_{STG}	-40 to +125	°C

(*1) Maximum ratings are limiting values of operating and environmental conditions which should not be exceeded under the worst possible conditions. The equipment manufacturer should design so that no maximum rating value is exceeded. Exposure to conditions beyond those listed above may cause permanent damage to the device or affect device reliability, which could increase potential risks of personal injury due to IC blowup and/or burning.

(*2) $V_{CCIO} + 0.3 V$ must not exceed the maximum rating of $V_{CCIOMax}$.

17.2 Recommended Operating Conditions (*3)

Parameter		Symbol	Condition	Min.	Max.	Unit
Supply Voltage	I/O	V_{CCIO}		3.1	3.5	V
	Core	V_{CCInt}		1.4	1.6	V
Operating Temperature (Case)		T_C		0	70	°C

(*3) These are the recommended operating conditions. Proper device operation outside of these conditions is not guaranteed. Exposure to conditions beyond those listed above for extended periods of time could affect device reliability. The equipment manufacturer should design so that no recommended operating condition is exceeded.

17.3 DC Electrical Characteristics

17.3.1 Non-PCI Interface Pins

($T_c = 0$ to 70°C , $V_{CCIO} = 3.3\text{V} \pm 0.2\text{V}$, $V_{CCInt} = 1.5\text{V} \pm 0.1\text{V}$, $V_{SS} = 0\text{V}$)

Parameter	Symbol	Condition	Min.	Max.	Unit
Low-Level Input Voltage	V_{IL1}	(1)	-0.3	0.8	V
High-Level Input Voltage	V_{IH1}	(1)	2.0	$V_{CCIO} + 0.3$	V
Low-Level Output Current	I_{OL1}	(2) $V_{OL} = 0.4\text{ V}$	8	—	mA
	I_{OL2}	(3) $V_{OL} = 0.4\text{ V}$	4	—	mA
Low-Level Output Current	I_{OL3}	(4) $V_{OL} = 0.4\text{ V}$	16	—	mA
	I_{OL4}	(5) $V_{OL} = 0.4\text{ V}$	8	—	mA
High-Level Output Current	I_{OH1}	(2) $V_{OH} = 2.4\text{ V}$	—	-8	mA
	I_{OH2}	(3) $V_{OH} = 2.4\text{ V}$	—	-4	mA
High-Level Output Current	I_{OH3}	(4) $V_{OH} = 2.4\text{ V}$	—	-16	mA
	I_{OH4}	(5) $V_{OH} = 2.4\text{ V}$	—	-8	mA
Low-Level Input Leakage Current	I_{IL1}	(6) $V_{IN}=V_{SS}$	-10	10	μA
	I_{IL2}	(7) $V_{IN}=V_{SS}$	-200	-10	μA
High-Level Input Leakage Current	I_{IH1}	(8) $V_{IN}=V_{CCIO}$	-10	10	μA
	I_{IH2}	(9) $V_{IN}=V_{CCIO}$	10	200	μA
Hi-Z Output Leakage Current	I_{OZ}	(10)	-10	10	μA
Total Supply Current	I_{DDInt}	Core: 200 MHz;		600	mA
	I_{DDIO}	GBUSCLK: Half frequency		400	mA

- (1) All input pins and all bidirectional pins in input mode, except the PCI Interface pins
- (2) ACE*, ACK*, BUSSPRT*, BWE[3:0]*, CE[7:0]*, DMAACK[3:0], DMADONE*, EEPROM_CS, EEPROM_DO, EEPROM_SK, HALTDOZE, PIO[7:0], RTS[1:0], SWE*, SYSCLK, TIMER[1:0], TXD[1:0]
- (3) DCLK, PCST[8:0], TDO, TPC[3:1]
- (4) ADDR[19:0], CAS*, CB[7:0], CKE, DATA[63:0], DQM[7:0], OE*, RAS*, SDCLK[3:0], SDCLKIN, SDCS[3:0]*, WE* and WE* when configured with a 16-mA drive strength
- (5) ADDR[19:0], CAS*, CB[7:0], CKE, DATA[63:0], DQM[7:0], OE*, RAS*, SDCLK[3:0], SDCLKIN, SDCS[3:0]*, WE* and WE* when configured with a 8-mA drive strength
- (6) EEPROM_DI, CGRESET*, RESET*, TRST*, BYPASSPLL*, MASTERCLK, DMADONE*, PIO[7:0], SDCLKIN
- (7) CTS[1:0]*, DMAREQ[3:0], RXD[1:0], SCLK, TCLK, INT[5:0], TCK, TDI, TEST[4:0]*, TMS, ACK*, CB[7:0], DATA[63:0], ADDR[19:0], NMI*
- (8) All pins listed in (6) and (7) above, except TRST*
- (9) TRST*
- (10) TXD[1:0]

17.3.2 PCI Interface Pins

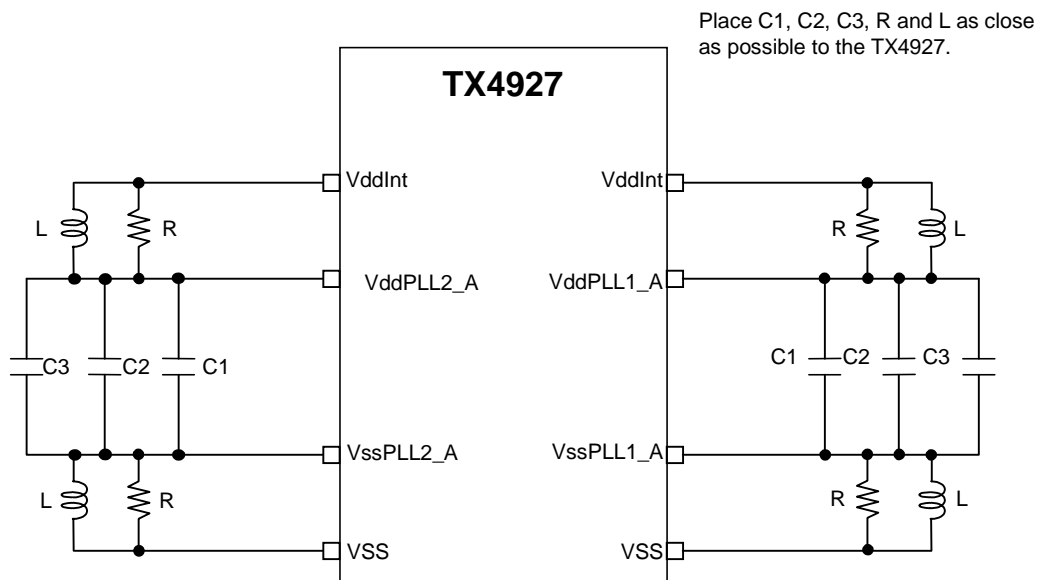
(T_c = 0 to 70°C, V_{CCIO} = 3.3V ± 0.2V, V_{CCInt} = 1.5V ± 0.1V, V_{SS} = 0V)

Parameter	Symbol	Condition	Min.	Max.	Unit
Low-Level Input Voltage	V _{ILPCI}	(1)	-0.5	0.9	V
High-Level Input Voltage	V _{IHPCI}	(1)	1.8	V _{CCIO} + 0.3	V
High-Level Output Voltage	V _{OHPCI}	(2) I _{OUT} = -500 μA	V _{CCIO} × 0.9	—	V
Low-Level Output Voltage	V _{OLPCI}	(2) I _{OUT} = 1500 μA	—	V _{CCIO} × 0.1	V
Input Leakage Current	I _{IHPCI}	(1) 0 < V _{IN} < V _{CCIO}	-10	10	μA
	I _{ILPCI}		-10	10	μA
Hi-Z Output Leakage Current	I _{ozpci}	(3)	-10	10	μA

- (1) ID_SEL, PCICLKIN, C_BE[3:0], DEVSEL*, FRAME*, GNT[3:0]*, IRDY*, M66EN, PAR, PCIAD[31:0], PERR*, REQ[3:0], SERR*, STOP*, TRDY*
- (2) All the PCI Interface pins except ID_SEL, LOCK* and PCICLKIN
- (3) PME*

17.4 PLL Power Supply

17.4.1 PLL Filter Circuit Example



Parameter	Symbol	Recommended Value	Unit
Resistors	R	5.6	Ω
Inductance	L	2.2	μH
Capacitors	C1	1	nF
	C2	82	nF
	C3	10	μF
VddInt/VddPLL		1.5 ± 0.1	V

Note: These values are for guidance only.

Figure 17.4.1 PLL Filter

17.5 AC Electrical Characteristics

17.5.1 MASTERCLK Timing

($T_c = 0$ to 70°C , $V_{CCIO} = 3.3\text{ V} \pm 0.2\text{ V}$, $V_{CCInt} = 1.5\text{ V} \pm 0.1\text{ V}$, $V_{SS} = 0\text{ V}$)

Parameter	Symbol	Condition	Min.	Max.	Unit
MASTERCLK Period	t_{MCP}	Boot configuration ADDR[2] = H	10	80	ns
		Boot configuration ADDR[2] = L	40	320	ns
MASTERCLK Frequency ^(*)	f_{MCK}	Boot configuration ADDR[2] = H	12.5	100	MHz
		Boot configuration ADDR[2] = L	3.125	25	MHz
MASTERCLK High Pulse Width	t_{MCH}		3	—	ns
MASTERCLK Low Pulse Width	t_{MCL}		3	—	ns
CPUCLK Frequency	f_{CPU}		50	200	MHz
MASTERCLK Rise Time	t_{MCR}		—	2	ns
MASTERCLK Fall Time	t_{MCF}		—	2	ns

(*) Correct operation of the TX4927 is only guaranteed when the power supply is stable and the PLL satisfies its stabilization time (t_{MCP_PLL}) and remains enabled.

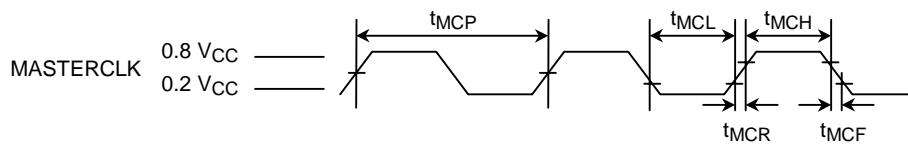


Figure 17.5.1 MASTERCLK Timing Diagram

17.5.2 Power-On Timing

($T_c = 0$ to 70°C , $V_{CCIO} = 3.3\text{ V} \pm 0.2\text{ V}$, $V_{CCInt} = 1.5\text{ V} \pm 0.1\text{ V}$, $V_{SS} = 0\text{ V}$)

Parameter	Symbol	Condition	Min.	Max.	Unit
PLL Stabilization Time	t_{MCP_PLL}		10		ms
CGRSET* Period	t_{MCK_PLL}		1		ms
RESET* Period	t_{MCH_PLL}		1	—	ms

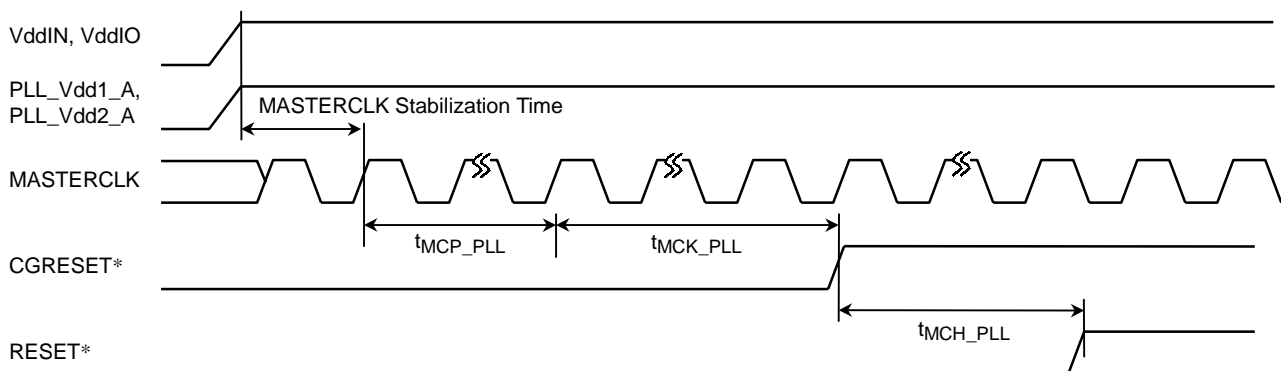


Figure 17.5.2 Power-On-Reset Timing

17.5.3 SDRAM Interface Timing

($T_c = 0$ to 70°C , $V_{CCIO} = 3.3\text{ V} \pm 0.2\text{ V}$, $V_{CCInt} = 1.5\text{ V} \pm 0.1\text{ V}$, $V_{SS} = 0\text{ V}$, $C_L = 150\text{ pF}$)

Parameter	Symbol	Condition	Min.	Max.	Unit
SDCLK[3:0] Cycle Time	t_{CYC_SDCLK}	$C_L=50\text{ pF}$, When configured with a 16-mA output buffer	10	—	ns
SDCLK[3:0] High Pulse Width	t_{HIGH_SDCLK}	$C_L=50\text{ pF}$, When configured with a 16-mA output buffer	3	—	ns
SDCLK[3:0] Low Pulse Width	t_{LOW_SDCLK}	$C_L=50\text{ pF}$, When configured with a 16-mA output buffer	3	—	ns
SDCLKIN Input Skew	t_{BP}	Non-bypass mode	0	4.0	ns
SDCLK[3:0] High to ADDR[19:5] Valid	t_{VAL_ADDR1}	$C_L=150\text{ pF}$, 16-mA output buffer *1)	1.5	6.5	ns
SDCLK[3:0] High to SDCS[3:0]* Asserted	t_{VAL_SDCS}	$C_L=100\text{ pF}$, 16-mA output buffer	1.5	6.5	ns
SDCLK[3:0] High to RAS* asserted	t_{VAL_RAS}	$C_L=150\text{ pF}$, 16-mA output buffer *1)	1.5	6.5	ns
SDCLK[3:0] High to CAS* asserted	t_{VAL_CAS}	$C_L=150\text{ pF}$, 16-mA output buffer *3)	1.5	6.5	ns
SDCLK[3:0] High to WE* Asserted	t_{VAL_WE}	$C_L=150\text{ pF}$, 16-mA output buffer *3)	1.5	6.5	ns
SDCLK[3:0] High to CKE Asserted	t_{VAL_CKE}	$C_L=150\text{ pF}$, 16-mA output buffer	1.5	6.5	ns
SDCLK[3:0] High to DQM[7:0] Asserted	t_{VAL_DQM}	$C_L=50\text{ pF}$, 16-mA output buffer *2)	1.5	6.5	ns
SDCLK[3:0] to DATA[63:0] (High To Low, Low To High)	t_{VAL_DATA1}	$C_L=50\text{ pF}$, 16-mA output buffer *2)	1.5	6.5	ns
SDCLK[3:0] to DATA[63:0] (Hi-Z to Valid)	$t_{VAL_DATA1ZV}$	$C_L=50\text{ pF}$, 16-mA output buffer *2)	1.5	6.5	ns
SDCLK[3:0] to DATA[63:0] (Valid to Hi-Z)	$t_{VAL_DATA1VZ}$	$C_L=50\text{ pF}$, 16-mA output buffer *2)	1.5	6.5	ns
DATA[63:0] Input Setup Time	t_{SU_DATA1B}	Bypass mode	4.0	—	ns
DATA[63:0] Input Hold Time	t_{HO_DATA1B}	Bypass mode	0.5	—	ns
DATA[63:0] Input Setup Time	$t_{SU_DATA1NB}$	Non-bypass mode	1.5	—	ns
DATA[63:0] Input Hold Time	$t_{HO_DATA1NB}$	Non-bypass mode	1.0	—	ns

(*1) If the DA bit in the SDCTR register is set (i.e., $t_{DA} = 1\text{ tCK}$), these signals will be 2-cycle signals.

(*2) If the SWB bit in the SDCTR register is set (i.e., $t_{SWB} = 2\text{ tCK}$), these signals will be 2-cycle signals.

(*3) 2-cycle signal

For a description of the 2-cycle operation, refer to Chapter 9, *SDRAM Controller*.

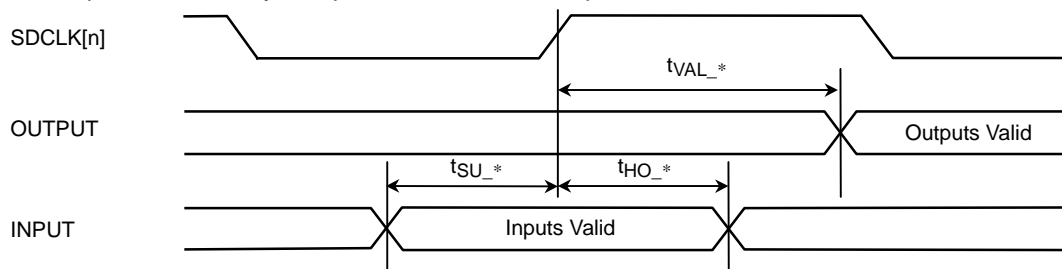


Figure 17.5.3 Output Signal and Bypass-Mode Input Signal Timing (with Reference to SDCLK)

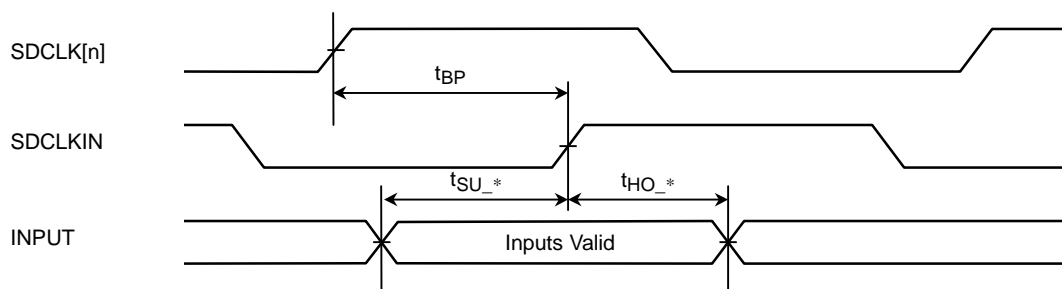


Figure 17.5.4 Non-Bypass-Mode Input Signal Timing (with Reference to SDCLK)

17.5.4 External Bus Interface Timing

(T_c = 0 to 70°C, V_{CCIO} = 3.3 V ± 0.2 V, V_{CCInt} = 1.5 V ± 0.1 V, V_{SS} = 0 V)

Parameter	Symbol	Condition	Min.	Max.	Unit
SYSCLK Cycle Time	t _{CYC_SYSCLK}	C _L =50 pF, Fixed as an 8-mA output buffer	10	—	ns
SYSCLK High Pulse Width	t _{HIGH_SYSCLK}	C _L =50 pF, Fixed as an 8-mA output buffer	4	—	ns
SYSCLK Low Pulse Width	t _{LOW_SYSCLK}	C _L =50 pF, Fixed as an 8-mA output buffer	4	—	ns
SYSCLK High to ADDR[19:5] Valid	t _{VAL_ADDR2}	C _L =150 pF, When configured with a 16-mA output buffer	1.5	6.5	ns
SYSCLK High to CE[7:0]* Asserted	t _{VAL_CE}	C _L =50 pF, Fixed as an 8-mA output buffer	1.5	8.5	ns
SYSCLK High to OE* Asserted	t _{VAL_OE}	C _L =50 pF, Fixed as an 8-mA output buffer	1.5	8.5	ns
SYSCLK High to SWE* Asserted	t _{VAL_SWE}	C _L =50 pF, Fixed as an 8-mA output buffer	1.5	8.5	ns
SYSCLK High to CE[3:0]* Asserted	t _{VAL_BWE}	C _L =50 pF, Fixed as an 8-mA output buffer	1.5	8.5	ns
SYSCLK High to ACE* Asserted	t _{VAL_ACE}	C _L =50 pF, Fixed as an 8-mA output buffer	1.5	8.5	ns
SYSCLK High to BUSSPRT* Asserted	t _{VAL_DQM}	C _L =50 pF, Fixed as an 8-mA output buffer	1.5	8.5	ns
SYSCLK High to DATA[63:0] (High to Low, Low to High)	t _{VAL_BUS}	C _L =50 pF, When configured with a 16-mA output buffer	1.5	6.5 *1)	ns
SYSCLK High to DATA[31:0] (Hi-Z to Valid)	t _{VAL_DATA2V}	C _L =50 pF, When configured with a 16-mA output buffer	1.5	8.5	ns
SYSCLK High to DATA[31:0] (Valid to Hi-Z)	t _{VAL_DATA2VZ}	C _L =50 pF, When configured with a 16-mA output buffer	1.5	8.5	ns
DATA[31:0] Input Setup Time	t _{SU_DATA2}		6.0	—	ns
DATA[31:0] Input Hold Time	t _{HO_DATA2}		0.5	—	ns
SYSCLK High to ACK* (High to Low, Low to High)	t _{VAL_ACK}	C _L =50 pF, Fixed as an 8-mA output buffer	1.5	8.5	ns
SYSCLK High to ACK* (Hi-Z to Valid)	t _{VAL_ACKZV}	C _L =50 pF, Fixed as an 8-mA output buffer	1.5	8.5	ns
SYSCLK High to ACK* (Valid to Hi-Z)	t _{VAL_ACKVZ}	C _L =50 pF, Fixed as an 8-mA output buffer	1.5	8.5	ns
ACK* Input Setup Time	t _{SU_ACK}		6.0	—	ns
ACK* Input Hold Time	t _{HO_ACK}		0.5	—	ns

(*1) When the external bus speed is programmed to one-third of the full frequency, t_{VAL_BUS} is equal to (GBUSCLK period + 6.5) ns. The external bus speed can be selected with the SP bit in the EBCCRN register located within the External Bus Controller.

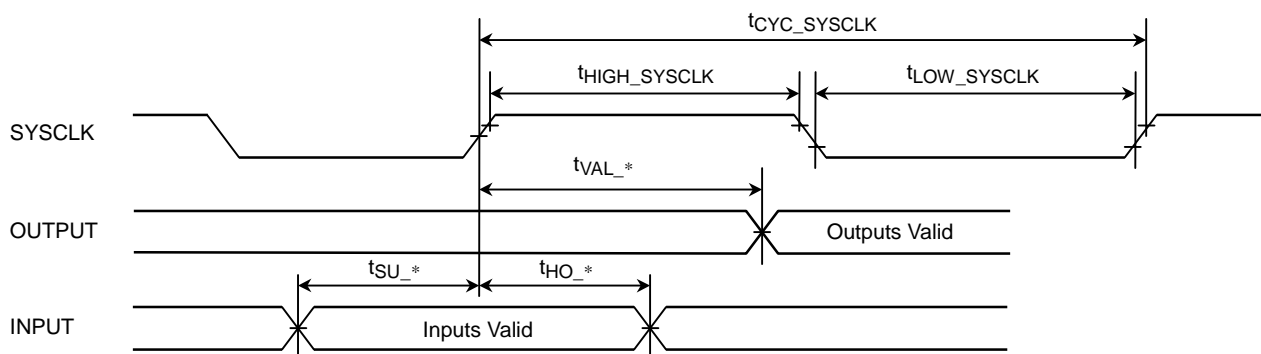


Figure 17.5.5 External Bus Interface Timing

17.5.5 PCI Interface Timing (66 MHz)

(T_c = 0 to 70°C, V_{CCIO} = 3.3 V ± 0.2 V, V_{CCInt} = 1.5 V ± 0.1 V, V_{SS} = 0 V)

Parameter	Symbol	Condition	Min.	Max.	Unit
PCICLKIN Cycle Time (66 MHz)	t _{CYC66}		15	30	ns
PCICLKIN High Time (66 MHz)	t _{HIGH66}		6	—	ns
PCICLKIN Low Time (66 MHz)	t _{LOW66}		6	—	ns
PCICLKIN Slew Rate (66 MHz)	t _{SLEW66}		1.5	4	V/ns
PCICLK[5:0] Cycle Time	t _{CYC066}	C _L =50 pF	15	30	ns
PCICLK[5:0] High Time (66 MHz)	t _{HIGH066}	C _L =50 pF	6	—	ns
PCICLK[5:0] Low Time (66 MHz)	t _{LOW066}	C _L =50 pF	6	—	ns
PCICLK[5:0] Skew (66 MHz)	t _{SKEW}	C _L =50 pF, point-to-point connection	0	TBD	ns
PCI Output Valid Delay ^{(*)1}	t _{VAL66}	C _L =30 pF	2	8	ns
PCI Input Setup Time ^{(*)2}	t _{SU66}		3	—	ns
PCI Input Hold Time ^{(*)2}	t _{HO66}		0.5	—	ns
Output Valid Delay – ID_SEL, REQ[0]*, GNT[3:0]*	t _{VALPP66}	C _L =30 pF, point-to-point connection	2	8	ns
Input Setup Time – ID_SEL, REQ[0]*, GNT[3:0]*	t _{SUPP66}	point-to-point connection	5	—	ns
Input Hold Time – ID_SEL, REQ[0]*, GNT[3:0]*	t _{HOPP66}	point-to-point connection	0	—	ns

(*)1 PCIAD[31:0], C_BE[3:0], PAR, FRAME*, IRDY*, TRDY*, STOP*, DEVSEL*, PERR*, SERR*, M66EN, PME*

(*)2 PCIAD[31:0], C_BE[3:0], PAR, FRAME*, IRDY*, TRDY*, STOP*, DEVSEL*, PERR*, SERR*, M66EN, PME*, LOCK*, ID_SEL

17.5.6 PCI Interface Timing (33 MHz)

(T_c = 0 to 70°C, V_{CCIO} = 3.3 V ± 0.2 V, V_{CCInt} = 1.5 V ± 0.1 V, V_{SS} = 0 V)

Parameter	Symbol	Condition	Min.	Max.	Unit
PCICLKIN Cycle Time (33 MHz)	t _{CYC33}		30	40	ns
PCICLKIN High Time (33 MHz)	t _{HIGH33}		11	—	ns
PCICLKIN Low Time (33 MHz)	t _{LOW33}		11	—	ns
PCICLKIN Slew Rate (33 MHz)	t _{SLEW33}		1	4	V/ns
PCICLK[5:0] Cycle Time (33 MHz)	t _{CYC33}	C _L =70 pF	30	40	ns
PCICLK[5:0] High Time (33 MHz)	t _{HIGH33}	C _L =70 pF	11	—	ns
PCICLK[5:0] Low Time (33 MHz)	t _{LOW33}	C _L =70 pF	11	—	ns
PCICLK[5:0] Skew (33 MHz)	t _{SKEW}	C _L =70 pF, point-to-point connection	0	TBD	ns
PCI Output Valid Delay ^{(*)1}	t _{VAL33}	C _L =70 pF	2	11	ns
PCI Input Setup Time ^{(*)2}	t _{SU33}		7	—	ns
PCI Input Hold Time ^{(*)2}	t _{HO33}		0.5	—	ns
Output Valid Delay – ID_SEL, REQ[0]*, GNT[3:0]*	t _{VALPP33}	C _L =70 pF, point-to-point connection	2	12	ns
Input Setup Time – ID_SEL, REQ[0]*, GNT[3:0]*	t _{SUPP33}	point-to-point connection	10	—	ns
Input Hold Time – ID_SEL, REQ[0]*, GNT[3:0]*	t _{HOPP33}	point-to-point connection	0	—	ns

(*)1 PCIAD[31:0], C_BE[3:0], PAR, FRAME*, IRDY*, TRDY*, STOP*, DEVSEL*, PERR*, SERR*, M66EN, PME*

(*)2 PCIAD[31:0], C_BE[3:0], PAR, FRAME*, IRDY*, TRDY*, STOP*, DEVSEL*, PERR*, SERR*, M66EN, PME*, LOCK*, ID_SEL

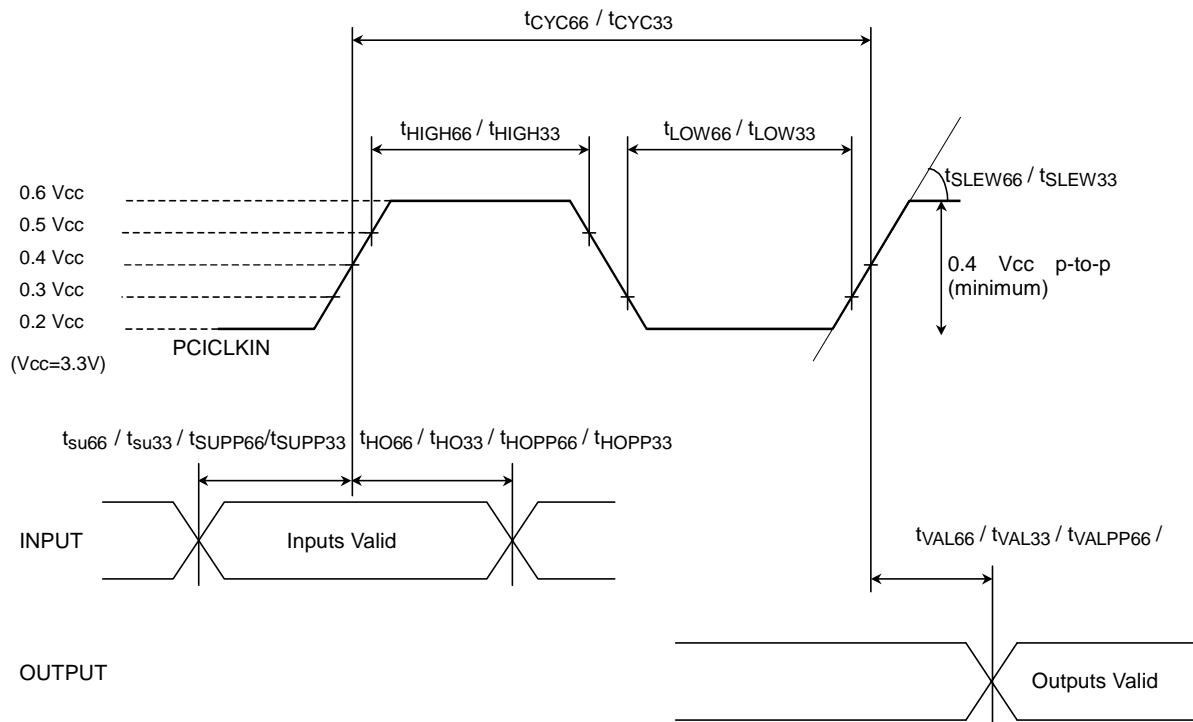


Figure 17.5.6 PCI Interface Timing (3.3 V)

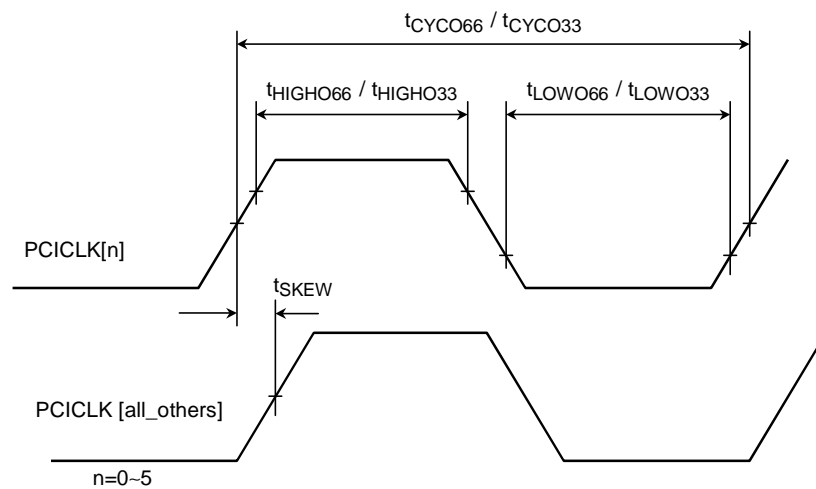


Figure 17.5.7 PCI Clock Skew

17.5.7 PCI EEPROM Interface Timing

($T_c = 0$ to 70°C , $V_{CCIO} = 3.3\text{ V} \pm 0.2\text{ V}$, $V_{CCInt} = 1.5\text{ V} \pm 0.1\text{ V}$, $V_{SS} = 0\text{ V}$)

Parameter	Symbol	Condition	Min.	Max.	Unit
EEPROM_SK High Time	$t_{\text{HIGH_EPSK}}$	$C_L = 50\text{ pF}$	500	—	ns
EEPROM_SK Low Time	$t_{\text{LOW_EPSK}}$	$C_L = 50\text{ pF}$	500	—	ns
EEPROM_DO Output Valid Delay ^(*)	$t_{\text{VAL_EPDO}}$	$C_L = 50\text{ pF}$	—	100	ns
EEPROM_DI Input Setup Time	$t_{\text{SU_EPDI}}$		100	—	ns
EEPROM_DI Input Hold Time	$t_{\text{HO_EPDI}}$		100	—	ns
EEPROM_CS Output Valid Delay	$t_{\text{VAL_EPCS}}$	$C_L = 50\text{ pF}$	100	—	ns

(*) The TX4927 controls the EEPROM control signals in synchronization with the falling edge of EEPROM_SK. Because the EEPROM operates with the rising edge of EEPROM_SK, EEPROM_DO has no minimum timing constraint.

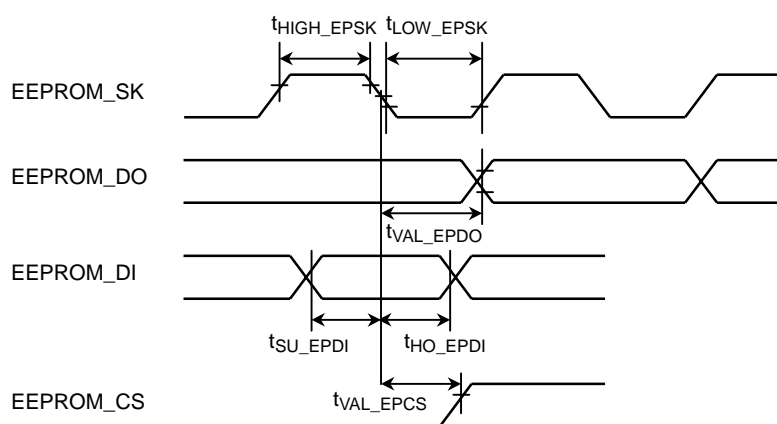


Figure 17.5.8 PCI EEPROM Interface Timing

17.5.8 DMA Interface Timing

(T_c = 0 to 70°C, V_{CCIO} = 3.3 V ± 0.2 V, V_{CCInt} = 1.5 V ± 0.1 V, V_{SS} = 0 V)

Parameter	Symbol	Condition	Min.	Max.	Unit
SYSCLK High to DMADONE* Asserted	t _{VAL_DONE}	C _L =50 pF With reference to SYSCLK (C _L =50 pF)	—	12	ns
DMADONE* Width Asserted	t _{PW_DONE}	Boot configuration ADDR[2]=H	t _{MCP} × 1.1	—	ns
		Boot configuration ADDR[2]=L	1/4 × t _{MCP} × 1.1	—	ns

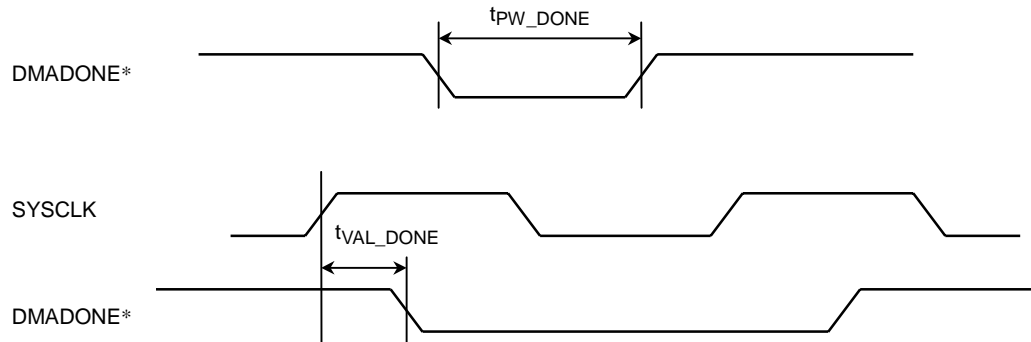


Figure 17.5.9 DMA Interface Timing

17.5.9 Interrupt Interface Timing

(T_c = 0 to 70°C, V_{CCIO} = 3.3 V ± 0.2 V, V_{CCInt} = 1.5 V ± 0.1 V, V_{SS} = 0 V)

Parameter	Symbol	Condition	Min.	Max.	Unit
INT Input Pulse Width	t _{PW_INT}	Boot configuration ADDR[2]=H	2 × t _{MCP} × 1.1	—	ns
		Boot configuration ADDR[2]=L	1/2 × t _{MCP} × 1.1	—	ns
NMI Input Pulse Width	t _{PW_NMI}	Boot configuration ADDR[2]=H	t _{MCP} × 1.1	—	ns
		Boot configuration ADDR[2]=L	1/4 × t _{MCP} × 1.1	—	ns

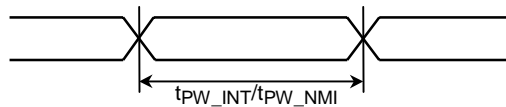


Figure 17.5.10 INT/NMI Interface Timing

17.5.10 SIO Interface Timing

($T_c = 0$ to 70°C , $V_{CCIO} = 3.3\text{ V} \pm 0.2\text{ V}$, $V_{CCInt} = 1.5\text{ V} \pm 0.1\text{ V}$, $V_{SS} = 0\text{ V}$)

Parameter	Symbol	Condition	Min.	Max.	Unit
SCLK Cycle Time	$f_{\text{CYC_SCLK}}$	Boot configuration ADDR[2]=H	$4 \times t_{\text{MCP}} \times 1.1$	—	ns
		Boot configuration ADDR[2]=L	$t_{\text{MCP}} \times 1.1$	—	ns
SCLK Frequency	f_{SCLK}	Boot configuration ADDR[2]=H	—	$1/2 \times f_{\text{MCK}} \times 0.45$	MHz
		Boot configuration ADDR[2]=L	—	$2 \times f_{\text{MCK}} \times 0.45$	MHz
SCLK High Time	$t_{\text{HIGH_SCLK}}$	Boot configuration ADDR[2]=H	$2 \times t_{\text{MCP}} \times 1.1$	—	ns
		Boot configuration ADDR[2]=L	$1/2 \times t_{\text{MCP}} \times 1.1$	—	ns
SCLK Low Time	$t_{\text{LOW_SCLK}}$	Boot configuration ADDR[2]=H	$2 \times t_{\text{MCP}} \times 1.1$	—	ns
		Boot configuration ADDR[2]=L	$1/2 \times t_{\text{MCP}} \times 1.1$	—	ns

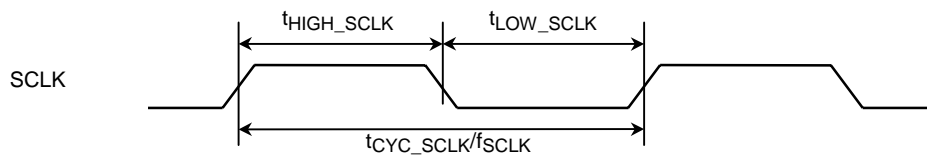


Figure 17.5.11 SIO Interface Timing

17.5.11 Timer Interface Timing

($T_c = 0$ to 70°C , $V_{CCIO} = 3.3\text{ V} \pm 0.2\text{ V}$, $V_{CCInt} = 1.5\text{ V} \pm 0.1\text{ V}$, $V_{SS} = 0\text{ V}$)

Parameter	Symbol	Condition	Min.	Max.	Unit
TCLK Cycle Time	$f_{\text{CYC_TCLK}}$	Boot configuration ADDR[2]=H	$4 \times t_{\text{MCP}} \times 1.1$	—	ns
		Boot configuration ADDR[2]=L	$t_{\text{MCP}} \times 1.1$	—	ns
TCLK Frequency	f_{TCLK}	Boot configuration ADDR[2]=H	—	$1/2 \times f_{\text{MCK}} \times 0.45$	MHz
		Boot configuration ADDR[2]=L	—	$2 \times f_{\text{MCK}} \times 0.45$	MHz
TCLK High Time	$t_{\text{HIGH_TCLK}}$	Boot configuration ADDR[2]=H	$2 \times t_{\text{MCP}} \times 1.1$	—	ns
		Boot configuration ADDR[2]=L	$1/2 \times t_{\text{MCP}} \times 1.1$	—	ns
TCLK Low Time	$t_{\text{LOW_TCLK}}$	Boot configuration ADDR[2]=H	$2 \times t_{\text{MCP}} \times 1.1$	—	ns
		Boot configuration ADDR[2]=L	$1/2 \times t_{\text{MCP}} \times 1.1$	—	ns

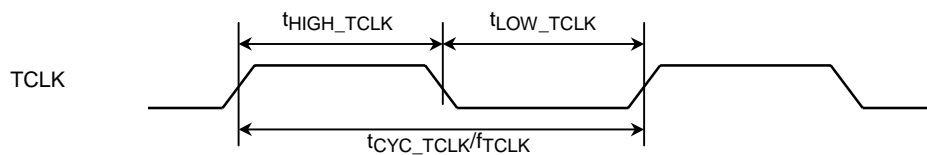


Figure 17.5.12 Timer Interface Timing

17.5.12 PIO Interface Timing

($T_c = 0$ to 70°C , $V_{CCIO} = 3.3\text{ V} \pm 0.2\text{ V}$, $V_{CCInt} = 1.5\text{ V} \pm 0.1\text{ V}$, $V_{SS} = 0\text{ V}$)

Parameter	Symbol	Condition	Min.	Max.	Unit
MASTERCLK High to PIO[15:0] Valid	t_{VAL_PIO}	With reference to IMBUSCLK ($C_L=50\text{ pF}$)	—	10	ns
PIO[15:0] Input Setup Time	t_{SU_PIO}	With reference to IMBUSCLK	12	—	ns
PIO[15:0] Input Hold Time	t_{HO_PIO}	With reference to IMBUSCLK	0	—	ns

(*1) IMBUSCLK is an internal signal. For details, see Chapter 6, *Clocks*.

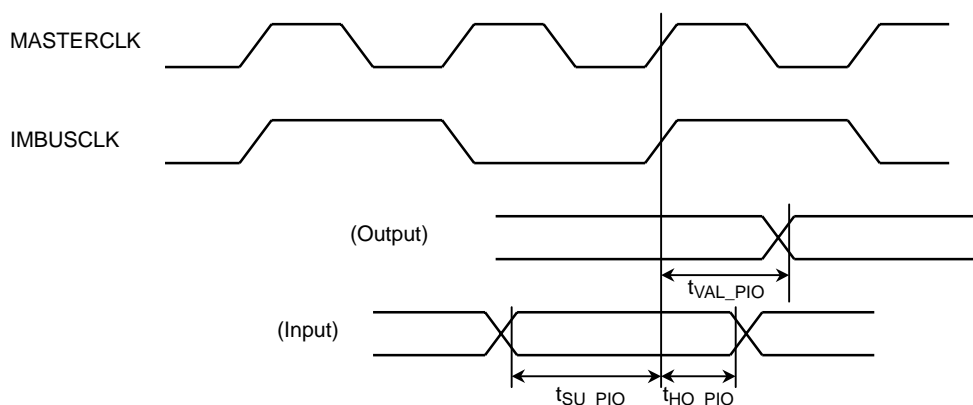


Figure 17.5.13 PIO Interface Timing

17.5.13 AC-link Interface Timing

($T_c = 0$ to 70°C , $V_{CCIO} = 3.3\text{ V} \pm 0.2\text{ V}$, $V_{CCInt} = 1.5\text{ V} \pm 0.1\text{ V}$, $V_{SS} = 0\text{ V}$)

Parameter	Symbol	Condition	Min.	Max.	Unit
BITCLK High Time	t_{HIGH_BCLK}		36	45	ns
BITCLK Low Time	t_{LOW_BCLK}		36	45	ns
SYNC Output Valid Delay	t_{VAL_SYNC}	With reference to BITCLK, $C_L=55\text{ pF}$	—	15	ns
SDOUT Output Valid Delay	t_{VAL_SDOUT}	With reference to BITCLK, $C_L=55\text{ pF}$	—	15	ns
SDIN[1:0] Input Setup Time	t_{SU_SDIN}	With reference to BITCLK	10	—	ns
SDIN[1:0] Input Hold Time	t_{HO_SDIN}	With reference to BITCLK	10	—	ns

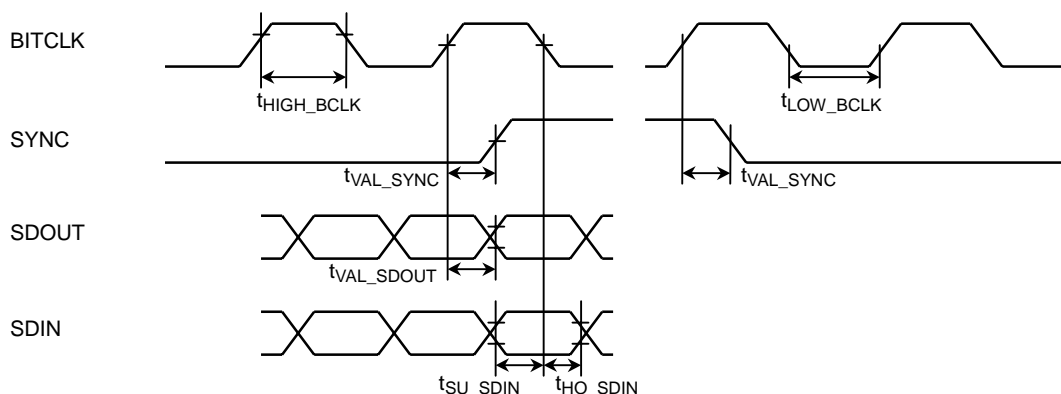


Figure 17.5.14 AC-link Interface Timing

18. Pinout and Package Information

18.1 Pinout Diagram

Figure 18.1.1 shows the TX4927 pinout. Table 18.1.1 provides a pin cross reference by pin number. Table 18.1.2 provides a pin cross reference by pin name.

	A	B	C	D	E	F	G	H	J	K	L	M	N
26	C_BE[2]	VSS	PCIAD [16]	PCIAD [18]	PCIAD [19]	PCIAD [23]	PCIAD [24]	PCICLK [0]	PCICLK [1]	PCICLK [2]	PCICLK [3]	PCICLK [4]	PCICLK [5]
25	IRDY*	FRAME*	PCIAD [17]	VddIO	PCIAD [20]	VddIO	PCIAD [25]	VddIO	GNT[0]*	REQ[0]*	GNT[2]*	GNT[3]*	DATA[63]
24	VddIO	STOP*	DEVSEL*	TRDY*	PCIAD [21]	ID_SEL	PCIAD [26]	PCIAD [29]	PCIAD [30]	GNT[1]*	REQ[2]*	REQ[3]*	VSS
23	VSS	PERR*	LOCK*	VddIN	PCIAD [22]	C_BE[3]	PCIAD [27]	VddIN	VSS	VddIN	VSS	VddIO	VddIO
22	PCIAD [15]	C_BE[1]	PAR	SERR*	VSS	VddIO	PCIAD [28]	VSS	PCIAD [31]	VSS	REQ[1]*	VSS	PME*
21	PCIAD [11]	PCIAD [12]	PCIAD [13]	VddIO	PCIAD [14]	TOP View							
20	C_BE[0]	PCIAD[8]	PCIAD[9]	M66EN	PCIAD [10]								
19	PCIAD[5]	PCIAD[6]	PCIAD[7]	VddIO	VSS								
18	PCIAD[2]	PCIAD[3]	VddIO	PCIAD[4]	VSS								
17	PCST[0]	PCIAD[0]	PCIAD[1]	VddIN	VSS								
16	PCST[3]	PCST[2]	PCST[1]	VddIO	TRST*								
15	EEPROM_CS	PCST[5]	PCST[4]	VddIN	VSS								
14	EEPROM_SK	PCST[8]	PCST[7]	VddIO	PCST[6]								
13	VSS	TDO	TPC[3]	TPC[2]	TPC[1]								
12	EEPROM_DO	DCLK	TMS	VddIO	VSS								
11	EEPROM_DI	TCK	TDI	DMAACK [0]	DMAREQ [0]								
10	BWE[1]*	BWE[2]*	BWE[3]*	VddIN	VSS								
9	BWE[0]*	DMAREQ [1]	VddIO	VSS	DMADONE*								
8	DMAACK [1]	DMAREQ [2]	DMAREQ [3]	VddIN	VSS								
7	DMAACK [2]	DMAACK [3]	CE[1]*	CE[0]*	VddIO								
6	CE[4]*	CE[3]*	CE[2]*	VSS	SDIN[1]								
5	CE[5]*	VddIO	ACE*	BYPASSPLL*	VSS	VddIN	VddIN	VSS	RXD[1]	VSS	TEST[1]*	VSS	VddIO
4	CE[7]*	CE[6]*	ACK*	VddIN	VddIO	NMI*	RXD[0]	VddIO	CTS[1]*	VddIN	TEST[2]*	VddIN	VSS
3	SWE*	BUSSPRT*	VddIO	PIO[6]	TIMER[1]	INT[0]	INT[3]	CTS[0]*	RTS[1]*	HALTDOZE	TEST[3]*	VddIO	DATA[0]
2	PIO[0]	PIO[2]	PIO[4]	VSS	TIMER[0]	INT[1]	INT[4]	RTS[0]*	TXD[1]	TEST[0]*	TEST[4]*	WDRST*	DATA[32]
1	PIO[1]	PIO[3]	PIO[5]	PIO[7]	TCLK	INT[2]	INT[5]	TXD[0]	SCLK	RESET*	SYSCLK	OE*	DATA[1]

Figure 18.1.1 Pinout Diagram (1/2)

P	R	T	U	V	W	Y	AA	AB	AC	AD	AE	AF	
PCICLKIN	MASTERC LK	VSS	VSS	DATA[29]	DATA[59]	DATA[58]	DATA[56]	VSS	DATA[22]	DATA[21]	VddIO	VSS	26
PLL2VSS _A	PLL1VSS _A	DATA[31]	DATA[61]	DATA[60]	DATA[27]	DATA[26]	DATA[24]	DATA[54]	DATA[53]	DATA[52]	DATA[20]	DATA[51]	25
PLL2VDD _A	PLL1VDD _A	VddIO	VddIO	VSS	VSS	DATA[57]	DATA[55]	VSS	VSS	DATA[50]	VddIO	DATA[19]	24
CGRESET*	VddIN	DATA[62]	VddIN	DATA[28]	VddIO	DATA[25]	VSS	VddIO	VddIN	VSS	VSS	VddIO	23
VddIN	VSS	DATA[30]	VSS	VddIO	VSS	VddIO	DATA[23]	VSS	DATA[48]	DATA[17]	DATA[49]	DATA[18]	22
TOP View								CB[3]	VSS	CB[7]	VddIO	DATA[16]	21
								DQM[7]	CB[2]	VSS	CB[6]	VddIO	20
								VSS	VddIN	VSS	DQM[3]	SDCLK[1]	19
								SDCS[3]*	DQM[2]	DQM[6]	VSS	VSS	18
								VSS	VddIN	CKE	SDCS[2]*	SDCLK[3]	17
								ADDR[17]	VddIO	ADDR[18]	ADDR[19]	VSS	16
								VSS	VddIO	ADDR[15]	ADDR[16]	SDCLKIN	15
								VSS	VddIO	ADDR[14]	VSS	SDCLK[0]	14
								VSS	VddIO	ADDR[12]	ADDR[13]	SDCLK[2]	13
								VSS	VddIN	ADDR[10]	VSS	ADDR[11]	12
								ADDR[7]	ADDR[8]	VSS	ADDR[9]	VddIO	11
								VSS	VddIN	ADDR[5]	ADDR[6]	VSS	10
								ADDR[3]	VddIO	VSS	ADDR[4]	VddIO	9
								VSS	VddIO	VSS	ADDR[1]	ADDR[2]	8
								VddIO	SDCS[0]*	SDCS[1]*	RAS*	ADDR[0]	7
								DQM[0]	VSS	DQM[4]	DQM[1]	DQM[5]	6
VddIO	VSS	DATA[4]	VSS	DATA[7]	VSS	DATA[40]	DATA[42]	VSS	VddIO	VSS	WE*	VSS	5
VSS	VddIO	VddIO	VddIN	VddIO	VddIN	DATA[9]	VSS	DATA[12]	VddIN	VSS	CB[5]	CAS*	4
DATA[33]	DATA[34]	DATA[36]	DATA[37]	VddIO	VSS	VSS	VddIO	DATA[44]	VSS	CB[0]	CB[4]	CB[1]	3
VSS	DATA[3]	DATA[5]	DATA[6]	VSS	DATA[39]	DATA[41]	DATA[11]	DATA[13]	VSS	DATA[46]	VddIO	DATA[47]	2
DATA[2]	DATA[35]	VSS	DATA[38]	VSS	DATA[8]	DATA[10]	DATA[43]	DATA[45]	DATA[14]	VddIO	DATA[15]	VSS	1

Figure 18.1.1 Pinout Diagram (2/2)

Table 18.1.1 Pin Cross Reference by Pin Number (1/2)

Pin Number	Pin Name	Pin Number	Pin Name	Pin Number	Pin Name	Pin Number	Pin Name	Pin Number	Pin Name
A1	PIO[1]	B17	PCIAD[0]	D7	CE[0]*	E23	PCIAD[22]	J25	GNT[0]*
A2	PIO[0]	B18	PCIAD[3]	D8	VddIN	E24	PCIAD[21]	J26	PCICLK[1]
A3	SWE*	B19	PCIAD[6]	D9	VSS	E25	PCIAD[20]	K1	RESET*
A4	CE[7]*	B20	PCIAD[8]	D10	VddIN	E26	PCIAD[19]	K2	TEST[0]*
A5	CE[5]*	B21	PCIAD[12]	D11	DMAACK[0]	F1	INT[2]	K3	HALTDOZE
A6	CE[4]*	B22	C_BE[1]	D12	VddIO	F2	INT[1]	K4	VddIN
A7	DMAACK[2]	B23	PERR*	D13	TPC[2]	F3	INT[0]	K5	VSS
A8	DMAACK[1]	B24	STOP*	D14	VddIO	F4	NMI*	K22	VSS
A9	BWE[0]*	B25	FRAME*	D15	VddIN	F5	VddIN	K23	VddIN
A10	BWE[1]*	B26	VSS	D16	VddIO	F22	VddIO	K24	GNT[1]*
A11	EEPROM_DI	C1	PIO[5]	D17	VddIN	F23	C_BE[3]	K25	REQ[0]*
A12	EEPROM_DO	C2	PIO[4]	D18	PCIAD[4]	F24	ID_SEL	K26	PCICLK[2]
A13	VSS	C3	VddIO	D19	VddIO	F25	VddIO	L1	SYSClk
A14	EEPROM_SK	C4	ACK*	D20	M66EN	F26	PCIAD[23]	L2	TEST[4]*
A15	EEPROM_CS	C5	ACE*	D21	VddIO	G1	INT[5]	L3	TEST[3]*
A16	PCST[3]	C6	CE[2]*	D22	SERR*	G2	INT[4]	L4	TEST[2]*
A17	PCST[0]	C7	CE[1]*	D23	VddIN	G3	INT[3]	L5	TEST[1]*
A18	PCIAD[2]	C8	DMAREQ[3]	D24	TRDY*	G4	RXD[0]	L22	REQ[1]*
A19	PCIAD[5]	C9	VddIO	D25	VddIO	G5	VddIN	L23	VSS
A20	C_BE[0]	C10	BWE[3]*	D26	PCIAD[18]	G22	PCIAD[28]	L24	REQ[2]*
A21	PCIAD[11]	C11	TDI	E1	TCLK	G23	PCIAD[27]	L25	GNT[2]*
A22	PCIAD[15]	C12	TMS	E2	TIMER[0]	G24	PCIAD[26]	L26	PCICLK[3]
A23	VSS	C13	TPC[3]	E3	TIMER[1]	G25	PCIAD[25]	M1	OE*
A24	VddIO	C14	PCST[7]	E4	VddIO	G26	PCIAD[24]	M2	WDRST*
A25	IRDY*	C15	PCST[4]	E5	VSS	H1	TXD[0]	M3	VddIO
A26	C_BE[2]	C16	PCST[1]	E6	SDIN[1]	H2	RTS[0]*	M4	VddIN
B1	PIO[3]	C17	PCIAD[1]	E7	VddIO	H3	CTS[0]*	M5	VSS
B2	PIO[2]	C18	VddIO	E8	VSS	H4	VddIO	M22	VSS
B3	BUSSPRT*	C19	PCIAD[7]	E9	DMADONE*	H5	VSS	M23	VddIO
B4	CE[6]*	C20	PCIAD[9]	E10	VSS	H22	VSS	M24	REQ[3]*
B5	VddIO	C21	PCIAD[13]	E11	DMAREQ[0]	H23	VddIN	M25	GNT[3]*
B6	CE[3]*	C22	PAR	E12	VSS	H24	PCIAD[29]	M26	PCICLK[4]
B7	DMAACK[3]	C23	LOCK*	E13	TPC[1]	H25	VddIO	N1	DATA[1]
B8	DMAREQ[2]	C24	DEVSEL*	E14	PCST[6]	H26	PCICLK[0]	N2	DATA[32]
B9	DMAREQ[1]	C25	PCIAD[17]	E15	VSS	J1	SCLK	N3	DATA[0]
B10	BWE[2]*	C26	PCIAD[16]	E16	TRST*	J2	TXD[1]	N4	VSS
B11	TCK	D1	PIO[7]	E17	VSS	J3	RTS[1]*	N5	VddIO
B12	DCLK	D2	VSS	E18	VSS	J4	CTS[1]*	N22	PME*
B13	TDO	D3	PIO[6]	E19	VSS	J5	RXD[1]	N23	VddIO
B14	PCST[8]	D4	VddIN	E20	PCIAD[10]	J22	PCIAD[31]	N24	VSS
B15	PCST[5]	D5	BYPASSPLL*	E21	PCIAD[14]	J23	VSS	N25	DATA[63]
B16	PCST[2]	D6	VSS	E22	VSS	J24	PCIAD[30]	N26	PCICLK[5]

Table 18.1.1 Pin Cross Reference by Pin Number (2/2)

Pin Number	Pin Name	Pin Number	Pin Name	Pin Number	Pin Name	Pin Number	Pin Name	Pin Number	Pin Name
P1	DATA[2]	V3	VddIO	AB5	VSS	AC21	VSS	AE11	ADDR[9]
P2	VSS	V4	VddIO	AB6	DQM[0]	AC22	DATA[48]	AE12	VSS
P3	DATA[33]	V5	DATA[7]	AB7	VddIO	AC23	VddIN	AE13	ADDR[13]
P4	VSS	V22	VddIO	AB8	VSS	AC24	VSS	AE14	VSS
P5	VddIO	V23	DATA[28]	AB9	ADDR[3]	AC25	DATA[53]	AE15	ADDR[16]
P22	VddIN	V24	VSS	AB10	VSS	AC26	DATA[22]	AE16	ADDR[19]
P23	CGRESET*	V25	DATA[60]	AB11	ADDR[7]	AD1	VddIO	AE17	SDCS[2]*
P24	PLL2VDD_A	V26	DATA[29]	AB12	VSS	AD2	DATA[46]	AE18	VSS
P25	PLL2VSS_A	W1	DATA[8]	AB13	VSS	AD3	CB[0]	AE19	DQM[3]
P26	PCICLKIN	W2	DATA[39]	AB14	VSS	AD4	VSS	AE20	CB[6]
R1	DATA[35]	W3	VSS	AB15	VSS	AD5	VSS	AE21	VddIO
R2	DATA[3]	W4	VddIN	AB16	ADDR[17]	AD6	DQM[4]	AE22	DATA[49]
R3	DATA[34]	W5	VSS	AB17	VSS	AD7	SDCS[1]*	AE23	VSS
R4	VddIO	W22	VSS	AB18	SDCS[3]*	AD8	VSS	AE24	VddIO
R5	VSS	W23	VddIO	AB19	VSS	AD9	VSS	AE25	DATA[20]
R22	VSS	W24	VSS	AB20	DQM[7]	AD10	ADDR[5]	AE26	VddIO
R23	VddIN	W25	DATA[27]	AB21	CB[3]	AD11	VSS	AF1	VSS
R24	PLL1VDD_A	W26	DATA[59]	AB22	VSS	AD12	ADDR[10]	AF2	DATA[47]
R25	PLL1VSS_A	Y1	DATA[10]	AB23	VddIO	AD13	ADDR[12]	AF3	CB[1]
R26	MASTERCLK	Y2	DATA[41]	AB24	VSS	AD14	ADDR[14]	AF4	CAS*
T1	VSS	Y3	VSS	AB25	DATA[54]	AD15	ADDR[15]	AF5	VSS
T2	DATA[5]	Y4	DATA[9]	AB26	VSS	AD16	ADDR[18]	AF6	DQM[5]
T3	DATA[36]	Y5	DATA[40]	AC1	DATA[14]	AD17	CKE	AF7	ADDR[0]
T4	VddIO	Y22	VddIO	AC2	VSS	AD18	DQM[6]	AF8	ADDR[2]
T5	DATA[4]	Y23	DATA[25]	AC3	VSS	AD19	VSS	AF9	VddIO
T22	DATA[30]	Y24	DATA[57]	AC4	VddIN	AD20	VSS	AF10	VSS
T23	DATA[62]	Y25	DATA[26]	AC5	VddIO	AD21	CB[7]	AF11	VddIO
T24	VddIO	Y26	DATA[58]	AC6	VSS	AD22	DATA[17]	AF12	ADDR[11]
T25	DATA[31]	AA1	DATA[43]	AC7	SDCS[0]*	AD23	VSS	AF13	SDCLK[2]
T26	VSS	AA2	DATA[11]	AC8	VddIO	AD24	DATA[50]	AF14	SDCLK[0]
U1	DATA[38]	AA3	VddIO	AC9	VddIO	AD25	DATA[52]	AF15	SDCLKIN
U2	DATA[6]	AA4	VSS	AC10	VddIN	AD26	DATA[21]	AF16	VSS
U3	DATA[37]	AA5	DATA[42]	AC11	ADDR[8]	AE1	DATA[15]	AF17	SDCLK[3]
U4	VddIN	AA22	DATA[23]	AC12	VddIN	AE2	VddIO	AF18	VSS
U5	VSS	AA23	VSS	AC13	VddIO	AE3	CB[4]	AF19	SDCLK[1]
U22	VSS	AA24	DATA[55]	AC14	VddIO	AE4	CB[5]	AF20	VddIO
U23	VddIN	AA25	DATA[24]	AC15	VddIO	AE5	WE*	AF21	DATA[16]
U24	VddIO	AA26	DATA[56]	AC16	VddIO	AE6	DQM[1]	AF22	DATA[18]
U25	DATA[61]	AB1	DATA[45]	AC17	VddIN	AE7	RAS*	AF23	VddIO
U26	VSS	AB2	DATA[13]	AC18	DQM[2]	AE8	ADDR[1]	AF24	DATA[19]
V1	VSS	AB3	DATA[44]	AC19	VddIN	AE9	ADDR[4]	AF25	DATA[51]
V2	VSS	AB4	DATA[12]	AC20	CB[2]	AE10	ADDR[6]	AF26	VSS

Table 18.1.2 Pin Cross Reference by Pin Name (1/2)

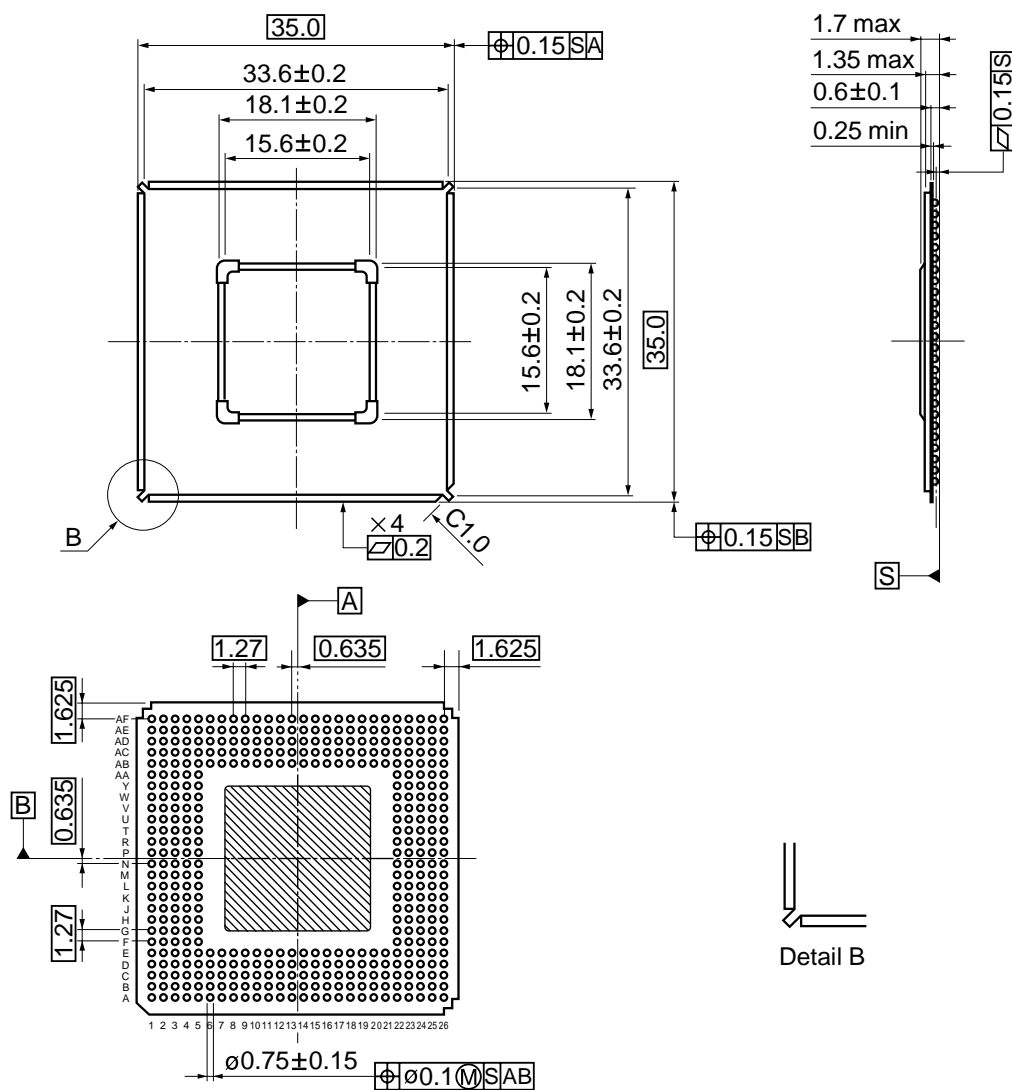
Pin Number	Pin Name	Pin Number	Pin Name	Pin Number	Pin Name	Pin Number	Pin Name	Pin Number	Pin Name
C5	ACE*	A5	CE[5]*	T22	DATA[30]	B9	DMAREQ[1]	C19	PCIAD[7]
C4	ACK*	B4	CE[6]*	T25	DATA[31]	B8	DMAREQ[2]	B20	PCIAD[8]
AF7	ADDR[0]	A4	CE[7]*	N2	DATA[32]	C8	DMAREQ[3]	C20	PCIAD[9]
AE8	ADDR[1]	P23	CGRESET*	P3	DATA[33]	AB6	DQM[0]	E20	PCIAD[10]
AF8	ADDR[2]	AD17	CKE	R3	DATA[34]	AE6	DQM[1]	A21	PCIAD[11]
AB9	ADDR[3]	K1	RESET*	R1	DATA[35]	AC18	DQM[2]	B21	PCIAD[12]
AE9	ADDR[4]	H3	CTS[0]*	T3	DATA[36]	AE19	DQM[3]	C21	PCIAD[13]
AD10	ADDR[5]	J4	CTS[1]*	U3	DATA[37]	AD6	DQM[4]	E21	PCIAD[14]
AE10	ADDR[6]	A20	C_BE[0]	U1	DATA[38]	AF6	DQM[5]	A22	PCIAD[15]
AB11	ADDR[7]	B22	C_BE[1]	W2	DATA[39]	AD18	DQM[6]	C26	PCIAD[16]
AC11	ADDR[8]	A26	C_BE[2]	Y5	DATA[40]	AB20	DQM[7]	C25	PCIAD[17]
AE11	ADDR[9]	F23	C_BE[3]	Y2	DATA[41]	A15	EEPROM_CS	D26	PCIAD[18]
AD12	ADDR[10]	N3	DATA[0]	AA5	DATA[42]	A11	EEPROM_DI	E26	PCIAD[19]
AF12	ADDR[11]	N1	DATA[1]	AA1	DATA[43]	A12	EEPROM_DO	E25	PCIAD[20]
AD13	ADDR[12]	P1	DATA[2]	AB3	DATA[44]	A14	EEPROM_SK	E24	PCIAD[21]
AE13	ADDR[13]	R2	DATA[3]	AB1	DATA[45]	B25	FRAME*	E23	PCIAD[22]
AD14	ADDR[14]	T5	DATA[4]	AD2	DATA[46]	J25	GNT[0]*	F26	PCIAD[23]
AD15	ADDR[15]	T2	DATA[5]	AF2	DATA[47]	K24	GNT[1]*	G26	PCIAD[24]
AE15	ADDR[16]	U2	DATA[6]	AC22	DATA[48]	L25	GNT[2]*	G25	PCIAD[25]
AB16	ADDR[17]	V5	DATA[7]	AE22	DATA[49]	M25	GNT[3]*	G24	PCIAD[26]
AD16	ADDR[18]	W1	DATA[8]	AD24	DATA[50]	K3	HALTDOZE	G23	PCIAD[27]
AE16	ADDR[19]	Y4	DATA[9]	AF25	DATA[51]	F24	ID_SEL	G22	PCIAD[28]
B3	BUSSPRT*	Y1	DATA[10]	AD25	DATA[52]	F3	INT[0]	H24	PCIAD[29]
A9	BWE[0]*	AA2	DATA[11]	AC25	DATA[53]	F2	INT[1]	J24	PCIAD[30]
A10	BWE[1]*	AB4	DATA[12]	AB25	DATA[54]	F1	INT[2]	J22	PCIAD[31]
B10	BWE[2]*	AB2	DATA[13]	AA24	DATA[55]	G3	INT[3]	P26	PCICLKIN
C10	BWE[3]*	AC1	DATA[14]	AA26	DATA[56]	G2	INT[4]	H26	PCICLK[0]
D5	BYPASSPLL*	AE1	DATA[15]	Y24	DATA[57]	G1	INT[5]	J26	PCICLK[1]
AF4	CAS*	AF21	DATA[16]	Y26	DATA[58]	A25	IRDY*	K26	PCICLK[2]
AD3	CB[0]	AD22	DATA[17]	W26	DATA[59]	C23	LOCK*	L26	PCICLK[3]
AF3	CB[1]	AF22	DATA[18]	V25	DATA[60]	D20	M66EN	M26	PCICLK[4]
AC20	CB[2]	AF24	DATA[19]	U25	DATA[61]	R26	MASTERCLK	N26	PCICLK[5]
AB21	CB[3]	AE25	DATA[20]	T23	DATA[62]	F4	NMI*	A17	PCST[0]
AE3	CB[4]	AD26	DATA[21]	N25	DATA[63]	M1	OE*	C16	PCST[1]
AE4	CB[5]	AC26	DATA[22]	B12	DCLK	C22	PAR	B16	PCST[2]
AE20	CB[6]	AA22	DATA[23]	C24	DEVSEL*	B17	PCIAD[0]	A16	PCST[3]
AD21	CB[7]	AA25	DATA[24]	D11	DMAACK[0]	C17	PCIAD[1]	C15	PCST[4]
D7	CE[0]*	Y23	DATA[25]	A8	DMAACK[1]	A18	PCIAD[2]	B15	PCST[5]
C7	CE[1]*	Y25	DATA[26]	A7	DMAACK[2]	B18	PCIAD[3]	E14	PCST[6]
C6	CE[2]*	W25	DATA[27]	B7	DMAACK[3]	D18	PCIAD[4]	C14	PCST[7]
B6	CE[3]*	V23	DATA[28]	E9	DMADONE*	A19	PCIAD[5]	B14	PCST[8]
A6	CE[4]*	V26	DATA[29]	E11	DMAREQ[0]	B19	PCIAD[6]	B23	PERR*

Table 18.1.2 Pin Cross Reference by Pin Name (2/2)

Pin Number	Pin Name	Pin Number	Pin Name	Pin Number	Pin Name	Pin Number	Pin Name	Pin Number	Pin Name
A2	PIO[0]	L5	TEST[1]*	R5	VSS	AE14	VSS	D25	VddIO
A1	PIO[1]	L4	TEST[2]*	T1	VSS	AE18	VSS	E4	VddIO
B2	PIO[2]	L3	TEST[3]*	T26	VSS	AE23	VSS	E7	VddIO
B1	PIO[3]	L2	TEST[4]*	U22	VSS	AF1	VSS	F22	VddIO
C2	PIO[4]	E2	TIMER[0]	U26	VSS	AF10	VSS	F25	VddIO
C1	PIO[5]	E3	TIMER[1]	U5	VSS	AF16	VSS	H25	VddIO
D3	PIO[6]	C12	TMS	V1	VSS	AF18	VSS	H4	VddIO
D1	PIO[7]	E13	TPC[1]	V2	VSS	AF26	VSS	M23	VddIO
R24	PLL1VDD_A	D13	TPC[2]	V24	VSS	AF5	VSS	M3	VddIO
R25	PLL1VSS_A	C13	TPC[3]	W22	VSS	D10	VddIN	N23	VddIO
P24	PLL2VDD_A	D24	TRDY*	W24	VSS	D15	VddIN	N5	VddIO
P25	PLL2VSS_A	E16	TRST*	W3	VSS	D17	VddIN	P5	VddIO
N22	PME*	H1	TXD[0]	W5	VSS	D23	VddIN	R4	VddIO
AE7	RAS*	J2	TXD[1]	Y3	VSS	D4	VddIN	T24	VddIO
K25	REQ[0]*	A13	VSS	AA23	VSS	D8	VddIN	T4	VddIO
L22	REQ[1]*	A23	VSS	AA4	VSS	F5	VddIN	U24	VddIO
L24	REQ[2]*	B26	VSS	AB10	VSS	G5	VddIN	V22	VddIO
M24	REQ[3]*	D2	VSS	AB12	VSS	H23	VddIN	V3	VddIO
H2	RTS[0]*	D6	VSS	AB13	VSS	K23	VddIN	V4	VddIO
J3	RTS[1]*	D9	VSS	AB14	VSS	K4	VddIN	W23	VddIO
G4	RXD[0]	E10	VSS	AB15	VSS	M4	VddIN	Y22	VddIO
J5	RXD[1]	E12	VSS	AB17	VSS	P22	VddIN	AA3	VddIO
J1	SCLK	E15	VSS	AB19	VSS	R23	VddIN	AB23	VddIO
AF15	SDCLKIN	E17	VSS	AB22	VSS	U23	VddIN	AB7	VddIO
AF14	SDCLK[0]	E18	VSS	AB24	VSS	U4	VddIN	AC13	VddIO
AF19	SDCLK[1]	E19	VSS	AB26	VSS	W4	VddIN	AC14	VddIO
AF13	SDCLK[2]	E22	VSS	AB5	VSS	AC10	VddIN	AC15	VddIO
AF17	SDCLK[3]	E5	VSS	AB8	VSS	AC12	VddIN	AC16	VddIO
AC7	SDCS[0]*	E8	VSS	AC2	VSS	AC17	VddIN	AC5	VddIO
AD7	SDCS[1]*	H22	VSS	AC21	VSS	AC19	VddIN	AC8	VddIO
AE17	SDCS[2]*	H5	VSS	AC24	VSS	AC23	VddIN	AC9	VddIO
AB18	SDCS[3]*	J23	VSS	AC3	VSS	AC4	VddIN	AD1	VddIO
E6	SDIN[1]	K22	VSS	AC6	VSS	A24	VddIO	AE2	VddIO
D22	SERR*	K5	VSS	AD11	VSS	B5	VddIO	AE21	VddIO
B24	STOP*	L23	VSS	AD19	VSS	C18	VddIO	AE24	VddIO
A3	SWE*	M22	VSS	AD20	VSS	C3	VddIO	AE26	VddIO
L1	SYSClk	M5	VSS	AD23	VSS	C9	VddIO	AF11	VddIO
B11	TCK	N24	VSS	AD4	VSS	D12	VddIO	AF20	VddIO
E1	TCLK	N4	VSS	AD5	VSS	D14	VddIO	AF23	VddIO
C11	TDI	P2	VSS	AD8	VSS	D16	VddIO	AF9	VddIO
B13	TDO	P4	VSS	AD9	VSS	D19	VddIO	M2	WDRST*
K2	TEST[0]*	R22	VSS	AE12	VSS	D21	VddIO	AE5	WE*

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Unit: mm



Appendix A TX49/H2 Core Supplement

This section explains items that are unique to the TX4927 of the TX49/H2 Core. Please refer to the “64-bit TX System RISC TX49/H2 Core Architecture User’s Manual” for more information regarding the TX49/H2 Core.

A.1 Processor ID

PRId Register values of the TX4927 TX49/H2 Core are as follows.

Processor Revision Identifier Register: 0x0000 2D22

FPU Implementation/Revision Register (FCR0): 0x0000 2D21

These values may be changed at a later date. Please contact the Toshiba Engineering Department for the most recent information.

A.2 Interrupts

Interrupt signalling of the on-chip interrupt controller is reflected in bit IP[2] of the Cause Register in the TX49/H2 Core. In addition, interrupt causes are reflected in other bits of the IP field. Please refer to Section “15.3.5 Interrupt signalling” for more information.

A.3 Bus Snoop

The Bus Snoop function is not used with the TX4927 due to restrictions of the Bus Snoop specification.

A.4 Halt/Doze mode

The Doze mode is not necessary when the Bus Snoop function is not used. Please use the Halt mode, which further reduces power consumption. Clearing the HALT bit of the Config Register makes it possible to shift to the Halt mode by executing the WAIT instruction.

A.5 Memory access order

The TX49/H2 Core has a 4-stage Write buffer, the PCI Bus Bridge (PCI Controller) has 4 stages for initiator access, and has a 2-stage Post Write buffer (Write buffer) for target access.

When data enters the Write buffer of the TX49/H2 Core, Cache Refill Read operations that do not match the address of that data after the Write is issued may be issued to the internal bus (G-Bus) before the Write. Other accesses are issued in order.

Executing the SYNC instruction guarantees that bus access invoked by a load/store instruction previously executed will be complete on the internal bus.

The PCI Bus Bridge is issued by the issue destination bus in the order all bus accesses are issued on the issue source bus. Please refer to “10.3.6 Post Write Function” for more information regarding methods for guaranteeing the completion of Write transactions of the Post Write Buffer.

